

DSP16410C Digital Signal Processor

1 Introduction

This addendum contains information specific to the DSP16410C. The DSP16410C is pin-compatible and functionally identical to the DSP16410B. However, the DSP16410C provides higher speed operation and lower power dissipation than the DSP16410B. This document describes the differences between the DSP16410B and the DSP16410C. It should be used as a supplement to the *DSP16410B Digital Signal Processor Data Sheet (DS01-070WTEC)*.

2 Features

- High performance:
 - Up to 800 million MACS per second at 200 MHz
- Low power:
 - 1.575 V internal supply for power efficiency
 - 3.3 V I/O pin supply for compatibility
- Changes from the DSP16410B to the DSP16410C:
 - Maximum processor speed has changed from 185 MHz to 200 MHz
 - Nominal internal supply voltage changed from 1.8 V to 1.575 V
 - New JTAGID register settings for both cores

3 Device Identification

The DSP16410C has different JTAG identification numbers for each core. These identifiers are different from those of the DSP16410B and can be accessed through the JTAG port of each core. Table 1 lists the JTAG identification numbers for each core of the DSP16410C.

Table 1. Device Identifiers

Identifier	DSP16410B	DSP16410C
JTAG0 JTAGID	0x2c81403b	0x4c81403b
JTAG1 JTAGID	0x3c81403b	0x5c81403b

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4 Notation Conventions

The following notation conventions apply to this data addendum:

lower-case	Registers that are directly writable or readable by DSP16410 core instructions are lower-case.
UPPER-CASE	Device flags, I/O pins, control register fields, and registers that are not directly writable or readable by DSP16410 core instructions are upper-case.
boldface	Register names and DSP16410 core instructions are printed in boldface when used in text descriptions.
<i>italics</i>	Documentation variables that are replaced are printed in italics.
<code>courier</code>	DSP16410 program examples or C-language representations are printed in courier font.

[]

Square brackets enclose a range of numbers that represents multiple bits in a single register or bus. The range of numbers is delimited by a colon. For example, **imux**[11:10] are bits 11 and 10 of the program-accessible **imux** register.

< >

Angle brackets enclose a list of items delimited by commas or a range of items delimited by a dash (—), one of which is selected if used in an instruction. For example, **SADD**<0—3> represents the four memory-mapped registers **SADD0**, **SADD1**, **SADD2**, and **SADD3**, and the general instruction **aTE**<h,l> = **RB** can be replaced with **a0h = timer0**.

5 Ball Grid Array Information

5.1 208-Ball PBGA Package

Figure 1 illustrates the ball assignment for the 208-ball PBGA package. This view is from the top of the package. The ball assignment for the DSP16410C is compatible with that of the DSP16410B.

	1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16	
A	VDD2	ED5	ED7	ED9	ED11	ED15	ED17	VSS	VDD1	ED26	ED30	ERWN1	VSS	EION	EA1	VDD2	A
B	ED3	VDD1	ED6	ED8	VSS	ED14	ED16	ED20	ED25	ED27	ED31	EROMN	ERAMN	EA0	VDD1	EA3	B
C	ED2	ED1	ED4	ED10	ED12	VDD1	ED18	ED21	ED24	VDD2	ED29	ERWN0	VDD2	EA2	EA4	EA5	C
D	VSS	ED0	VDD2	VDD1	ED13	VDD2	ED19	ED22	ED23	VSS	ED28	EACKN	VDD1	EA8	EA7	EA6	D
E	EREQN	ERDY	ESIZE	EXM									EA11	EA10	VSS	EA9	E
F	TDO0	ERTYPE	TRST0N	TCK0									VDD2	VDD1	EA12	EA13	F
G	TDI0	TMS0	VDD2	VSS			VSS	VSS	VSS	VSS			EA17	EA16	EA14	EA15	G
H	VDD1A	CKI	VSS1A	RSTN			VSS	VSS	VSS	VSS			ESEG1	ESEG0	EA18	VSS	H
J	VSS	INT2	INT3	TRAP			VSS	VSS	VSS	VSS			ESEG2	ESEG3	VDD1	ECKO	J
K	SICK0	SIFS0	INT0	INT1			VSS	VSS	VSS	VSS			VSS	VDD2	TMS1	TDI1	K
L	SOCK0	SOFS0	VDD1	VDD2									TCK1	TRST1N	SOD1	TDO1	L
M	SOD0	VSS	SID0	SCK0									SID1	SCK1	SOCK1	SOFS1	M
N	IO0BIT5	IO0BIT4	IO0BIT6	VDD1	PD10	PD6	VSS	PD1	PD0	PRDY	VDD2	PCSN	VDD1	VDD2	SIFS1	VSS	N
P	IO0BIT3	IO0BIT2	IO0BIT0	VDD2	PD11	PD7	VDD2	PD2	POBE	PINT	VDD1	PADD3	PADD1	IO1BIT2	IO1BIT0	SICK1	P
R	IO0BIT1	VDD1	EYMODE	PD14	PD13	PD9	PD5	VDD1	PIBF	PODS	PRWN	VSS	PADD0	IO1BIT4	VDD1	IO1BIT1	R
T	VDD2	VSS	PD15	VSS	PD12	PD8	PD4	PD3	VSS	PRDYMD	PIDS	PADD2	IO1BIT6	IO1BIT5	IO1BIT3	VDD2	T

Figure 1. 208-Ball PBGA Package Ball Grid Array Assignments (See-Through Top View)

5 Ball Grid Array Information (continued)

5.1 208-Ball PBGA Package (continued)

Table 2 describes the PBGA ball assignments sorted by symbol for the 208-ball package. For each signal or power/ground connection, this table lists the PBGA coordinate, the symbol name, the type (I = input, O = output, I/O = input/output, O/Z = 3-state output, P = power, G = ground), and description. Inputs and bidirectional pins do not maintain full CMOS levels when not driven. They must be pulled to VDD2 or VSS through the appropriate pull up/down resistor (refer to Section 7.1). An unused external SEMI data bus (ED[31:0]) can be statically configured as outputs by asserting the EYMODE pin. At full CMOS levels, no significant dc current is drawn.

Table 2. 208-Ball PBGA Ball Assignments Sorted Alphabetically by Symbol

Symbol	208-Ball PBGA Coordinate	Type	Description
CKI	H2	I	External Clock Input.
EA[18:0]	H15, G13, G14, G16, G15, F16, F15, E13, E14, E16, D14, D15, D16, C16, C15, B16, C14, A15, B14	O	External Address Bus, Bits 18—0.
EACKN	D12	O	External Device Acknowledge for External Memory Interface (negative assertion).
ECKO	J16	O	Programmable Clock Output.
ED[31:0]	B11, A11, C11, D11, B10, A10, B9, C9, D9, D8, C8, B8, D7, C7, A7, B7, A6, B6, D5, C5, A5, C4, A4, B4, A3, B3, A2, C3, B1, C1, C2, D2	I/O	External Memory Data Bus, Bits 31—0.
EION	A14	O	Enable for External I/O (negative assertion).
ERAMN	B13	O	External RAM Enable (negative assertion).
ERDY	E2	I	External Memory Device Ready.
EREQN	E1	I	External Device Request for EMI Interface (negative assertion).
EROMN	B12	O	Enable for External ROM (negative assertion).
ERTYPE	F2	I	EROM Type Control: If 0, asynchronous SRAM mode. If 1, synchronous SRAM mode.
ERWN0	C12	O	Read/Write, Bit 0 (negative assertion).
ERWN1	A12	O	Read/Write, Bit 1 (negative assertion).
ESEG[3:0]	J14, J13, H13, H14	O	External Segment Address, Bits 3—0.
ESIZE	E3	I	External Memory Bus Size Control: If 0, 16-bit external interface. If 1, 32-bit external interface.
EXM	E4	I	External Boot-up Control for CORE0.
EYMODE	R3	I	External Data Bus Mode Configuration Pin.
INT[3:0]	J3, J2, K4, K3	I	External Interrupt Requests 3—0.
IO0BIT[6:0]	N3, N1, N2, P1, P2, R1, P3	I/O	BIO0 Status/Control, Bits 6—0.
IO1BIT[6:0]	T13, T14, R14, T15, P14, R16, P15	I/O	BIO1 Status/Control, Bits 6—0.
PADD[3:0]	P12, T12, P13, R13	I	PIU Address, Bits 3—0.
PCSN	N12	I	PIU Chip Select (negative assertion).
PD[15:0]	T3, R4, R5, T5, P5, N5, R6, T6, P6, N6, R7, T7, T8, P8, N8, N9	I/O	PIU Data Bus, Bits 15—0.
PIBF	R9	O	PIU Input Buffer Full Flag.
PIDS	T11	I	PIU Input Data Strobe.
PINT	P10	O	PIU Interrupt Request to Host.

5 Ball Grid Array Information (continued)

5.1 208-Ball PBGA Package (continued)

Table 2. 208-Ball PBGA Ball Assignments Sorted Alphabetically by Symbol (continued)

Symbol	208-Ball PBGA Coordinate	Type	Description
POBE	P9	O	PIU Output Buffer Empty Flag.
PODS	R10	I	PIU Output Data Strobe.
PRDY	N10	O	PIU Host Ready.
PRDYMD	T10	I	PRDY Mode.
PRWN	R11	I	PIU Read/Write (negative assertion).
RSTN	H4	I	Device Reset (negative assertion).
SCK0	M4	I	External Clock for SIU0 Active Generator.
SCK1	M14	I	External Clock for SIU1 Active Generator.
SICK0	K1	I/O	SIU0 Input Clock.
SICK1	P16	I/O	SIU1 Input Clock.
SID0	M3	I	SIU0 Input Data.
SID1	M13	I	SIU1 Input Data.
SIFS0	K2	I/O	SIU0 Input Frame Sync.
SIFS1	N15	I/O	SIU1 Input Frame Sync.
SOCK0	L1	I/O	SIU0 Output Clock.
SOCK1	M15	I/O	SIU1 Output Clock.
SOD0	M1	O/Z	SIU0 Output Data.
SOD1	L15	O/Z	SIU1 Output Data.
SOFS0	L2	I/O	SIU0 Output Frame Sync.
SOFS1	M16	I/O	SIU1 Output Frame Sync.
TCK0	F4	I	JTAG Test Clock for CORE0.
TCK1	L13	I	JTAG Test Clock for CORE1.
TDI0	G1	I	JTAG Test Data Input for CORE0.
TDI1	K16	I	JTAG Test Data Input for CORE1.
TDO0	F1	O	JTAG Test Data Output for CORE0.
TDO1	L16	O	JTAG Test Data Output for CORE1.
TMS0	G2	I	JTAG Test Mode Select for CORE0.
TMS1	K15	I	JTAG Test Mode Select for CORE1.
TRAP	J4	I/O	TRAP/Breakpoint Indication.
TRST0N	F3	I	JTAG TAP Controller Reset for CORE0 (negative assertion).
TRST1N	L14	I	JTAG TAP Controller Reset for CORE1 (negative assertion).
VDD1	A9, B2, B15, C6, D4, D13, F14, J15, L3, N4, N13, P11, R2, R8, R15	P	Power Supply for Internal Circuitry.
VDD1A	H1	P	Power Supply for PLL Circuitry.
VDD2	A1, A16, C13, D3, D6, F13, G3, K14, L4, N11, N14, P4, P7, T1, T16, C10	P	Power Supply for External Circuitry (I/O).
VSS	A13, A8, B5, D1, D10, E15, G7, G8, G9, G10, G4, H7, H8, H9, H10, H16, J1, J7, J8, J9, J10, K7, K8, K9, K10, K13, M2, N7, N16, R12, T2, T4, T9	G	Ground.
VSS1A	H3	G	Ground for PLL Circuitry.

5 Ball Grid Array Information (continued)

5.2 256-Ball EBGA Package

Figure 2 illustrates the ball assignment for the 256-ball EBGA package. This view is from the top of the package. The ball assignment for the DSP16410C is compatible with that of the DSP16410B.

	1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16	17	18	19	20	
A	VSS	VDD2	EION	ERWN1	VSS	VSS	VDD2	ED27	ED25	ED23	VDD2	VSS	VSS	ED15	VDD2	VSS	ED9	ED5	VDD2	VSS	A
B	VDD2	VSS	EA2	ERAMN	ERWN0	ED30	NC	ED28	ED26	ED22	ED20	ED18	ED17	ED14	NC	ED11	ED7	VDD1	VSS	VDD2	B
C	EA4	EA3	VSS	EA1	VDD1	EACKN	VDD1	ED29	VDD1	VDD1	ED21	ED19	ED16	ED13	ED12	ED8	NC	VSS	ED4	ED1	C
D	EA8	EA6	VDD1	NC	EA0	EROMN	ED31	VDD2	VDD1	ED24	VDD2	VDD1	VDD1	VDD2	ED10	ED6	NC	ED3	ED0	EREQN	D
E	VSS	EA10	EA7	EA5													ED2	VDD1	ESIZE	VSS	E
F	VDD2	NC	EA11	EA9													ERDY	EXM	TDO0	VSS	F
G	VDD1	EA13	EA12	VDD2													ERTYPE	VDD1	NC	VDD2	G
H	VSS	EA16	EA15	EA14													VDD2	TRST0N	TCK0	TMS0	H
J	VSS	VDD1	EA18	EA17													TDI0	VDD1A	CKI	VSS1A	J
K	VDD2	ESEG0	NC	VDD2													RSTN	INT3	VDD1	TRAP	K
L	ESEG2	ESEG1	VDD1	ESEG3													VDD2	INT2	INT1	VDD2	L
M	ECKO	TDI1	VDD1	VDD1													SICK0	INT0	SIFS0	VSS	M
N	TMS1	TCK1	TRST1N	VDD2													SOFS0	SOCK0	VDD1	VSS	N
P	VDD2	NC	VDD1	SOD1													VDD2	SOD0	SID0	SCK0	P
R	VSS	TDO1	SID1	SOCK1													IO0BIT4	IO0BIT6	NC	VDD2	R
T	VSS	SCK1	VDD1	IO1BIT0													VDD1	IO0BIT2	IO0BIT5	VSS	T
U	SOFS1	SIFS1	IO1BIT1	NC	IO1BIT4	PADD1	VDD2	VDD1	VDD1	VDD2	PD2	VDD1	VDD2	PD9	PD13	EYMODE	NC	NC	IO0BIT1	IO0BIT3	U
V	SICK1	IO1BIT2	VSS	NC	IO1BIT6	PADD3	PCSN	PODS	PRDY	POBE	VDD1	VDD1	PD7	VDD1	PD10	VDD1	VSS	VSS	NC	NC	V
W	VDD2	VSS	VDD1	IO1BIT5	PADD2	NC	PRWN	PRDYMD	PINT	PIBF	PD0	PD4	PD6	NC	PD8	PD11	PD14	IO0BIT0	VSS	VDD2	W
Y	VSS	VDD2	IO1BIT3	PADD0	VSS	VDD2	PIDS	VSS	VSS	VDD2	PD1	PD3	PD5	VDD2	VSS	VSS	PD12	PD15	VDD2	VSS	Y

Figure 2. 256-Ball EBGA Package Ball Grid Array Assignments (See-Through Top View)

5 Ball Grid Array Information (continued)

5.2 256-Ball EBGA Package (continued)

Table 3 describes the EBGA ball assignments sorted by symbol for the 256-ball package. For each signal or power/ground connection, this table lists the EBGA coordinate, the symbol name, the type (I = input, O = output, I/O = input/output, O/Z = 3-state output, P = power, G = ground), and description. Inputs and bidirectional pins do not maintain full CMOS levels when not driven. They must be pulled to V_{DD2} or V_{SS} through the appropriate pull up/down resistor (refer to Section 7.1). An unused external SEMI data bus (ED[31:0]) can be statically configured as outputs by asserting the EYMODE pin. At full CMOS levels, no significant dc current is drawn.

Table 3. 256-Ball EBGA Ball Assignments Sorted Alphabetically by Symbol

Symbol	PBGA Coordinate	Type	Description
CKI	J19	I	External Clock Input.
EA[18:0]	B3, C1, C2, C4, D1, D2, D5, E2, E3, E4, F3, F4, G2, G3, H2, H3, H4, J3, J4	O	External Address Bus, Bits 18—0.
EACKN	C6	O	External Device Acknowledge for External Memory Interface (negative assertion).
ECKO	M1	O	Programmable Clock Output.
ED[31:0]	A8, A9, A10, A14, A17, A18, B6, B8, B9, B10, B11, B12, B13, B14, B16, B17, C8, C11, C12, C13, C14, C15, C16, C19, C20, D7, D10, D15, D16, D18, D19, E17	I/O	External Memory Data Bus, Bits 31—0.
EION	A3	O	Enable for External I/O (negative assertion).
ERAMN	B4	O	External RAM Enable (negative assertion).
ERDY	F17	I	External Memory Device Ready.
EREQN	D20	I	External Device Request for EMI Interface (negative assertion).
EROMN	D6	O	Enable for External ROM (negative assertion).
ERTYPE	G17	I	EROM Type Control: If 0, asynchronous SRAM mode. If 1, synchronous SRAM mode.
ERWN0	B5	O	Read/Write, Bit 0 (negative assertion).
ERWN1	A4	O	Read/Write, Bit 1 (negative assertion).
ESEG[3:0]	K2, L1, L2, L4	O	External Segment Address, Bits 3—0.
ESIZE	E19	I	External Memory Bus Size Control: If 0, 16-bit external interface. If 1, 32-bit external interface.
EXM	F18	I	External Boot-up Control for CORE0.
EYMODE	U16	I	External Data Bus Mode Configuration Pin.
INT[3:0]	K18, L18, L19, M18	I	External Interrupt Requests 3—0.
IO0BIT[6:0]	R17, R18, T18, T19, U19, U20, W18	I/O	BIO0 Status/Control, Bits 6—0.
IO1BIT[6:0]	T4, U3, U5, V2, V5, W4, Y3	I/O	BIO1 Status/Control, Bits 6—0.
PADD[3:0]	U6, V6, W5, Y4	I	PIU Address, Bits 3—0.
PCSN	V7	I	PIU Chip Select (negative assertion).
PD[15:0]	U11, U14, U15, V13, V15, W11, W12, W13, W15, W16, W17, Y11, Y12, Y13, Y17, Y18	I/O	PIU Data Bus, Bits 15—0.
PIBF	W10	O	PIU Input Buffer Full Flag.
PIDS	Y7	I	PIU Input Data Strobe.
PINT	W9	O	PIU Interrupt Request To Host.

5 Ball Grid Array Information (continued)

5.2 256-Ball EBGA Package (continued)

Table 3. 256-Ball EBGA Ball Assignments Sorted Alphabetically by Symbol (continued)

Symbol	PBGA Coordinate	Type	Description
POBE	V10	O	PIU Output Buffer Empty Flag.
PODS	V8	I	PIU Output Data Strobe.
PRDY	V9	O	PIU Host Ready.
PRDYMD	W8	I	PRDY Mode.
PRWN	W7	I	PIU Read/Write (negative assertion).
RSTN	K17	I	Device Reset (negative assertion).
SCK0	P20	I	External Clock for SIU0 Active Generator.
SCK1	T2	I	External Clock for SIU1 Active Generator.
SICK0	M17	I/O	SIU0 Input Clock.
SICK1	V1	I/O	SIU1 Input Clock.
SID0	P19	I	SIU0 Input Data.
SID1	R3	I	SIU1 Input Data.
SIFS0	M19	I/O	SIU0 Input Frame Sync.
SIFS1	U2	I/O	SIU1 Input Frame Sync.
SOCK0	N18	I/O	SIU0 Output Clock.
SOCK1	R4	I/O	SIU1 Output Clock.
SOD0	P18	O/Z	SIU0 Output Data.
SOD1	P4	O/Z	SIU1 Output Data.
SOFS0	N17	I/O	SIU0 Output Frame Sync.
SOFS1	U1	I/O	SIU1 Output Frame Sync.
TCK0	H19	I	JTAG Test Clock for CORE0.
TCK1	N2	I	JTAG Test Clock for CORE1.
TDI0	J17	I	JTAG Test Data Input for CORE0.
TDI1	M2	I	JTAG Test Data Input for CORE1.
TDO0	F19	O	JTAG Test Data Output for CORE0.
TDO1	R2	O	JTAG Test Data Output for CORE1.
TMS0	H20	I	JTAG Test Mode Select for CORE0.
TMS1	N1	I	JTAG Test Mode Select for CORE1.
TRAP	K20	I/O	TRAP/Breakpoint Indication.
TRST0N	H18	I	JTAG TAP Controller Reset for CORE0 (negative assertion).
TRST1N	N3	I	JTAG TAP Controller Reset for CORE1 (negative assertion).
VDD1	B18, C5, C7, C9, C10, D3, D9, D12, D13, E18, G1, G18, J2, K19, L3, M3, M4, N19, P3, T3, T17, U8, U9, U12, V11, V12, V14, V16, W3	P	Power Supply for Internal Circuitry.
VDD1A	J18	P	Power Supply for PLL Circuitry.
VDD2	A2, A7, A11, A15, A19, B1, B20, D8, D11, D14, F1, G4, G20, H17, K1, K4, L17, L20, N4, P1, P17, R20, U7, U10, U13, W1, W20, Y2, Y6, Y10, Y14, Y19	P	Power Supply for External Circuitry (I/O).

5 Ball Grid Array Information (continued)

5.2 256-Ball EBGA Package (continued)

Table 3. 256-Ball EBGA Ball Assignments Sorted Alphabetically by Symbol (continued)

Symbol	PBGA Coordinate	Type	Description
VSS	A1, A5, A6, A12, A13, A16, A20, B2, B19, C3, C18, E1, E20, F20, H1, J1, M20, N20, R1, T1, T20, V3, V17, V18, W2, W19, Y1, Y5, Y8, Y9, Y15, Y16, Y20	G	Ground.
VSS1A	J20	G	Ground for PLL Circuitry.
NC	B7, B15, C17, D4, D17, F2, G19, K3, P2, R19, U4, U17, U18, V4, V19, V20, W6, W14	—	Not Connected. Tie externally to ground.

6 Device Characteristics

6.1 Absolute Maximum Ratings

Stresses in excess of the absolute maximum ratings can cause permanent damage to the device. These are absolute stress ratings only. Functional operation of the device is not implied at these or any other conditions in excess of those given in the operational sections of the data sheet. Exposure to absolute maximum ratings for extended periods can adversely affect device reliability.

External leads can be bonded and soldered safely at temperatures of up to 220 °C.

Table 4. Absolute Maximum Ratings for Supply Pins

Parameter	Min	Max	Unit
Voltage on VDD1 with Respect to Ground	-0.5	1.8	V
Voltage on VDD1A with Respect to Ground	-0.5	1.8	V
Voltage on VDD2 with Respect to Ground	-0.5	4.0	V
Voltage Range on Any Signal Pin	VSS - 0.3	VDD2 + 0.3 4.0	V
Junction Temperature (T _J)	-40	125	°C
Storage Temperature Range	-40	150	°C

6.2 Handling Precautions

All MOS devices must be handled with certain precautions to avoid damage due to the accumulation of static charge. Although input protection circuitry has been incorporated into the devices to minimize the effect of this static buildup, proper precautions should be taken to avoid exposure to electrostatic discharge during handling and mounting. Agere Systems Inc. employs a human-body model for ESD-susceptibility testing. Since the failure voltage of electronic devices is dependent on the current, voltage, and hence, the resistance and capacitance, it is important that standard values be employed to establish a reference by which to compare test data. Values of 100 pF and 1500 Ω are the most common and are the values used in the Agere human-body model test circuit. The breakdown voltage for the DSP16410C is greater than 1000 V.

6 Device Characteristics (continued)

6.3 Recommended Operating Conditions

Table 5. Recommended Operating Conditions

Maximum Internal Clock (CLK) Frequency	Minimum Internal Clock (CLK) Period T	Junction Temperature T _J (°C)		Supply Voltage V _{DD1} , V _{DD1A} (V)		Supply Voltage V _{DD2} (V)	
		Min	Max	Min	Max	Min	Max
200 MHz	5.0 ns	-40	120	1.5	1.65	3.0	3.6

The ratio of the instruction cycle rate to the input clock frequency is 1:1 without the PLL and ((M + 2)/((D + 2) * f(OD))):1 with the PLL selected. **The maximum input clock (CKI pin) frequency when the PLL is not selected as the device clock source is 50 MHz. The maximum input clock frequency is 40 MHz when the PLL is selected.**

6.3.1 Package Thermal Considerations

The maximum allowable ambient temperature, T_{AMAX}, is dependent upon the device power dissipation and is determined by the following equation:

$$T_{AMAX} = T_{JMAX} - P_{MAX} \times \Theta_{JA}$$

Where P_{MAX} is the maximum device power dissipation for the application, T_{JMAX} is the maximum device junction temperature specified in Table 6, and Θ_{JA} is the maximum thermal resistance in still-air-ambient specified in Table 6. See Section 7.3 for information on determining the maximum device power dissipation.

Table 6. Package Thermal Considerations

Device Package	Parameter	Value	Unit
208 PBGA	Maximum Junction Temperature (T _{JMAX})	120	°C
208 PBGA	Maximum Thermal Resistance in Still-Air-Ambient (Θ_{JA})	27	°C/W
256 EBGA	Maximum Junction Temperature (T _{JMAX})	120	°C
256 EBGA	Maximum Thermal Resistance in Still-Air-Ambient (Θ_{JA})	15	°C/W

WARNING: Due to package thermal constraints, proper precautions in the user's application should be taken to avoid exceeding the maximum junction temperature of 120 °C. Otherwise, the device performance and reliability is adversely affected.

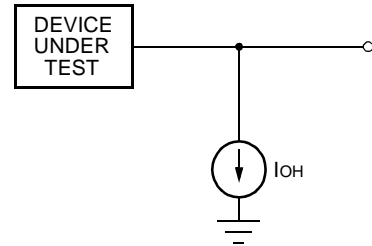
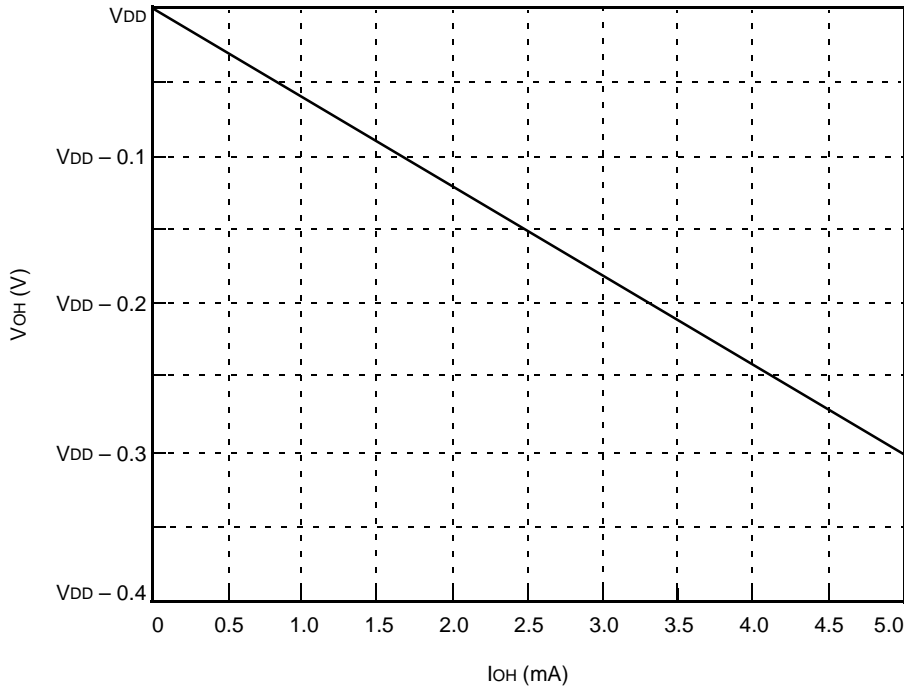
7 Electrical Characteristics and Requirements

Electrical characteristics refer to the behavior of the device under specified conditions. Electrical requirements refer to conditions imposed on the user for proper operation of the device. The parameters in Table 7 are valid for the conditions described in Section 6.3, on page 14.

Table 7. Electrical Characteristics and Requirements

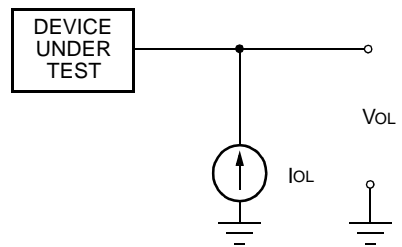
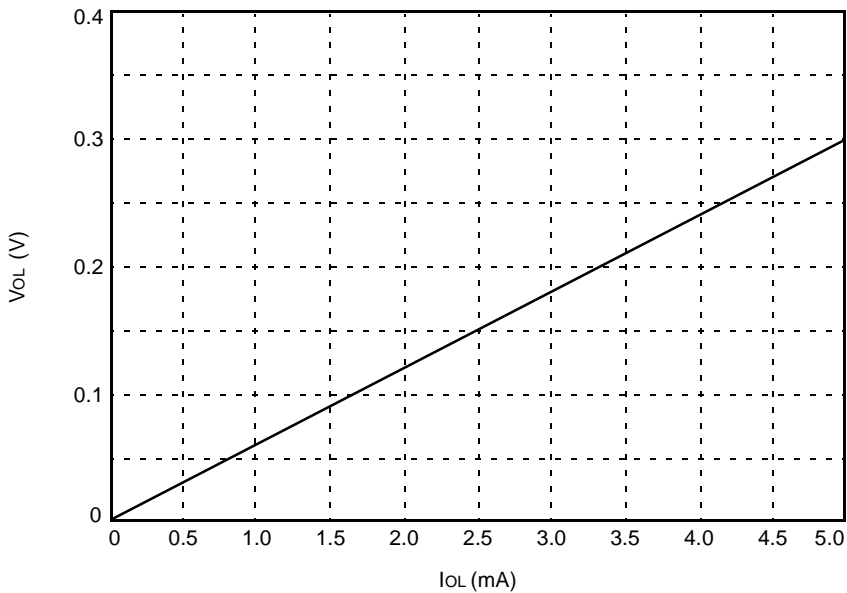
Parameter	Symbol	Min	Max	Unit
Input Voltage: Low High	V_{IL} V_{IH}	-0.3 $0.7 \times V_{DD2}$	$0.3 \times V_{DD2}$ $V_{DD2} + 0.3$	V V
Input Current (except TMS0, TMS1, TDI0, TDI1, TRST0N, TRST1N): Low ($V_{IL} = 0\text{ V}$, $V_{DD2} = 3.6\text{ V}$) High ($V_{IH} = 3.6\text{ V}$, $V_{DD2} = 3.6\text{ V}$)	I_{IL} I_{IH}	-5 —	— 5	μA μA
Input Current (TMS0, TMS1, TDI0, TDI1, TRST0N, TRST1N): Low ($V_{IL} = 0\text{ V}$, $V_{DD2} = 3.6\text{ V}$) High ($V_{IH} = 3.6\text{ V}$, $V_{DD2} = 3.6\text{ V}$)	I_{iL} I_{iH}	-100 —	— 5	μA μA
Output Low Voltage: Low ($I_{OL} = 2.0\text{ mA}$) Low ($I_{OL} = 50\ \mu\text{A}$)	V_{OL} V_{OL}	— —	0.4 0.2	V V
Output High Voltage: High ($I_{OH} = -2.0\text{ mA}$) High ($I_{OH} = -50\ \mu\text{A}$)	V_{OH} V_{OH}	$V_{DD2} - 0.7$ $V_{DD2} - 0.2$	— —	V V
Output 3-State Current: Low ($V_{DD2} = 3.6\text{ V}$, $V_{IL} = 0\text{ V}$) High ($V_{DD2} = 3.6\text{ V}$, $V_{IH} = 3.6\text{ V}$)	I_{OZL} I_{OZH}	-10 —	— 10	μA μA
Input Capacitance	CI	—	5	pF

7 Electrical Characteristics and Requirements (continued)



5-4007(C).a

Figure 3. Plot of V_{OH} vs. I_{OH} Under Typical Operating Conditions



5-4008(C).b

Figure 4. Plot of V_{OL} vs. I_{OL} Under Typical Operating Conditions

7 Electrical Characteristics and Requirements (continued)

7.1 Maintenance of Valid Logic Levels for Bidirectional Signals and Unused Inputs

The DSP16410C does not include any internal circuitry to maintain valid logic levels on input pins or on bidirectional pins that are not driven. For correct device operation and low static power dissipation, valid CMOS levels must be applied to all input and bidirectional pins. Failure to ensure full CMOS levels (V_{IL} or V_{IH}) on pins that are not driven (including floating data busses) may result in high static power consumption and possible device failure.

Any unused input pin must be pulled up to the I/O pin supply (V_{DD2}) or pulled down to V_{SS} according to the functional requirements of the pin. The pin can be pulled up or down directly or through a 10 k Ω resistor.

Any unused bidirectional pin statically configured as an input should be pulled to V_{DD2} or V_{SS} through a 10 k Ω resistor. Any bidirectional pin that is dynamically configured, such as the SEMI or PIU data busses, should be tied to V_{DD2} or V_{SS} through a pull-up/down resistor that supports the performance of the circuit. The value of the resistor should be selected to avoid exceeding the dc voltage and current characteristics of any device attached to the pin.

If the SEMI interface is unused in the system, the EYMODE pin should be connected to V_{DD2} to force the internal data bus transceivers to always be in the output mode. This avoids the need to add 32 pull-up resistors to ED[31:0]. If the SEMI interface is used in the system, the EYMODE pin must be connected to V_{SS} and pull-up or pull-down resistors must be added to ED[31:0] as described below.

The value of the pull-up resistors used on the SEMI data bus depends on the programmed bus width, 32-bit or 16-bit, as determined by the ESIZE pin. It is recommended that any 16-bit peripheral that is connected to the external memory interface of the DSP16410C use the upper 16 bits of the data bus (ED[31:16]). This is required if the external memory interface is configured as a 16-bit interface. For the following configurations, 10 k Ω pull-up or pull-down resistors can be used on the external data bus:

- 32-bit SEMI with no 16-bit peripherals
- 32-bit SEMI with 16-bit peripherals connected to ED[31:16]
- 16-bit interface (ED[31:16] only)

If the DSP16410C's external memory interface is configured for 32-bit operation with 16-bit peripherals on the lower half of the external data bus (ED[15:0]), the external data bus (ED[31:0]) should have 2 k Ω pull-up or pull-down resistors to meet the rise or fall time requirements of the DSP16410C*.

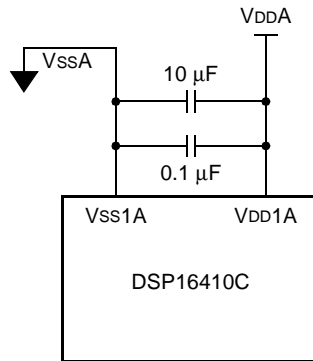
The different requirements for the size of the pull-up/pull-down resistors arise from the manner in which SEMI treats 16-bit accesses if the interface is configured for 32-bit operation. If configured as a 32-bit interface and a 16-bit read is performed to a device on the upper half of the data bus, the SEMI latches the value on the upper 16 bits internally onto the lower 16 bits. This ensures that the lower half of the data bus sees valid logic levels both in this case and also if the bus is operated as a 16-bit bus. However, if a 16-bit read operation is performed (on a 32-bit bus) to a 16-bit peripheral on the lower 16 bits, no data is latched onto the upper 16 bits, resulting in the upper half of the bus floating. In this case the smaller pull-up resistors ensure the floating data bits transition to a valid logic level fast enough to avoid metastability problems when the inputs are latched by the SEMI.

* The 2 k Ω resistor value assumes a bus loading of 30 pF and also ensures I_{OL} is not violated.

7 Electrical Characteristics and Requirements (continued)

7.2 Analog Power Supply Decoupling

Bypass and decoupling capacitors (0.01 μF , 10 μF) should be placed between the analog supply pin (V_{DD1A}) and analog ground (V_{SS1A}). These capacitors should be placed as close to the V_{DD1A} pin as possible. This minimizes ground bounce and supply noise to ensure reliable operation. Refer to Figure 5.



5-8896.a (F)

Figure 5. Analog Supply Bypass and Decoupling Capacitors

7 Electrical Characteristics and Requirements (continued)

7.3 Power Dissipation

The total device power dissipation is comprised of two components:

- The contribution from the VDD1 and VDD1A supplies, referred to as internal power dissipation.
- The contribution from the VDD2 supply, referred to as I/O power dissipation.

The next two sections specify power dissipation for each component.

7.3.1 Internal Power Dissipation

Internal power dissipation is highly dependent on operating voltage, core program activity, internal peripheral activity, and CLK frequency. Table 8 lists the DSP16410C typical internal power dissipation contribution for various conditions. The following conditions are assumed for all cases:

- VDD1 and VDD1A are both 1.575 V.
- All memory accesses by the cores and the DMAU are to internal memory.
- SIU0 and SIU1 are operating at 30 MHz in loopback mode. An external device drives the SICK<0—1> and SOCK<0—1> input pins at 30 MHz, and SIU<0—1> are programmed to select passive input clocks (ICKA field (SCON10[2]) and OCKA field (SCON10[6]) are cleared) and internal loopback (SIOLB field (SCON10[8]) is set).
- The PLL is enabled and selected as the source of the internal clock, CLK. Table 8 specifies the internal power dissipation for the following values of CLK: 185 MHz and 200 MHz.

Table 8. Typical Internal Power Dissipation at 1.575 V

Condition			Internal Power Dissipation (W)	
Type	Core Operation	DMAU Activity	185 MHz	200 MHz
Low-power Standby	The AWAIT field (alf[15]) is set in both cores.	The DMAU is operating the MMT4 channel to continuously transfer data.	0.24	0.26
Typical	Both cores repetitively execute a 20-tap FIR filter [†] .		0.76	0.82
Worst Case [‡]	Both cores execute worst-case instructions with worst-case data patterns.	The DMAU is operating all six channels (SWT<0—3> and MMT<4—5>) to continuously transfer data.	1.37	1.48

[†] To optimize execution speed, the cores each execute the inner loop of the filter from cache and perform a double-word data access every cycle from separate modules of TPRAM.

[‡] This is an artificial condition that is unlikely to occur for an extended period of time in an actual application because the cores are not performing any I/O servicing. In an actual application, the cores perform I/O servicing that changes program flow and lowers the power dissipation.

The internal power dissipation for the low-power standby and typical operating modes described in Table 8 is representative of actual applications. The worst-case internal power dissipation occurs under an artificial condition that is unlikely to occur for an extended period of time in an actual application. This worst-case power should be used for the calculation of maximum ambient operating temperature (T_{AMAX}) defined in Section 6.3.1. This value should also be used for worst-case system power supply design for VDD1 and VDD1A.

7 Electrical Characteristics and Requirements (continued)

7.3 Power Dissipation (continued)

7.3.2 I/O Power Dissipation

I/O power dissipation is highly dependent on operating voltage, I/O loading, and I/O signal frequency. It can be estimated as:

$$C_L \cdot V_{DD2}^2 \cdot f$$

where C_L is the load capacitance, V_{DD2} is the I/O supply voltage, and f is the frequency of output signal.

Table 9 lists the estimated typical I/O power dissipation contribution for each output and I/O pin for a typical application under specific conditions. The following conditions are assumed for all cases:

- V_{DD2} is 3.3 V.
- The load capacitance for each output and I/O pin is 30 pF.

For applications with values of C_L , V_{DD2} , or f that differ from those assumed for Table 9, the above formula can be used to adjust the I/O power dissipation values in the table.

Table 9. Typical I/O Power Dissipation at 3.3 V

Internal Peripheral	Pin(s)	Type	No. of Pins	Signal Frequency (MHz)	I/O Power Dissipation (mW)	
					185 MHz	200 MHz
SEMI [†]	ED[31:0]	I/O [‡]	32	CLK/4	242	261
	ERWN[1:0]	O	2	CLK/4	15	16.2
	EA0	O	1	CLK/8	7.6	8.1
	EA[18:1]	O	18	CLK/4	273	294
	ESEG[3:0]	O	4	CLK/4	60	65.9
	EROMN	O	1	CLK/12	5.1	5.4
	ERAMN	O	1	CLK/12	5.1	5.4
	EION	O	1	CLK/12	5.1	5.4
	ECKO	O	1	CLK/2	30.2	32
BIO<0—1>	IO<0—1>BIT[6:0]	O [§]	14	1	4.6	4.6
PIU	PD[15:0]	I/O [‡]	16	30	78.5	78.5
	PINT	O	1	1	0.33	0.33
	PIBF	O	1	30	9.8	9.8
	POBE	O	1	30	9.8	9.8
	PRDY	O	1	30	9.8	9.8
SIU<0—1>	SICK<0—1>	O	2	8	5.2	5.2
	SOCK<0—1>	O	2	8	5.2	5.2
	SOD<0—1>	O	2	8	5.2	5.2
	SIFS<0—1>	O	2	0.03	0.019	0.019
	SOFS<0—1>	O	2	0.03	0.019	0.019

[†] Assumptions: the SEMI is configured for a 32-bit external data bus (the ESIZE pin is high). The contribution from the EACKN pin is negligible.

[‡] Assumption: the pins switch from input to output at a 50% duty cycle.

[§] Assumption: the corresponding core has configured these pins as outputs.

7 Electrical Characteristics and Requirements (continued)

7.3 Power Dissipation (continued)

7.3.2 I/O Power Dissipation (continued)

Power dissipation due to the input buffers is highly dependent upon the input voltage level. At full CMOS levels, essentially no dc current is drawn. However, for levels between the power supply rails, especially at or near the threshold of $V_{DD2}/2$, high current can flow. See Section 7.1 for more information.

WARNING: The device needs to be clocked for at least six CKI cycles during reset after powerup. Otherwise, high currents might flow.

7.4 Power Supply Sequencing Issues

The DSP16410B requires two supply voltages. The use of dual voltages reduces internal device power consumption while supporting standard 3.3 V external interfaces. The external (I/O) power supply voltage is V_{DD2} , the internal supply voltage is V_{DD1} , and the internal analog supply voltage is V_{DD1A} . V_{DD1} and V_{DD1A} are typically generated by the same power supply, with V_{DD1A} receiving enhanced filtering near the device. In the discussion that follows, V_{DD1} and V_{DD1A} are assumed to rise and fall together, and are collectively referred to as V_{DD1} throughout the remainder of this section.

Power supply design is a system issue. Section 7.4.1 describes the recommended power supply sequencing specifications to avoid inducing latch-up or large currents that may reduce the long term life of the device. Section 7.4.2 discusses external power sequence protection circuits that may be used to meet the recommendations discussed in Section 7.4.1.

7.4.1 Supply Sequencing Recommendations

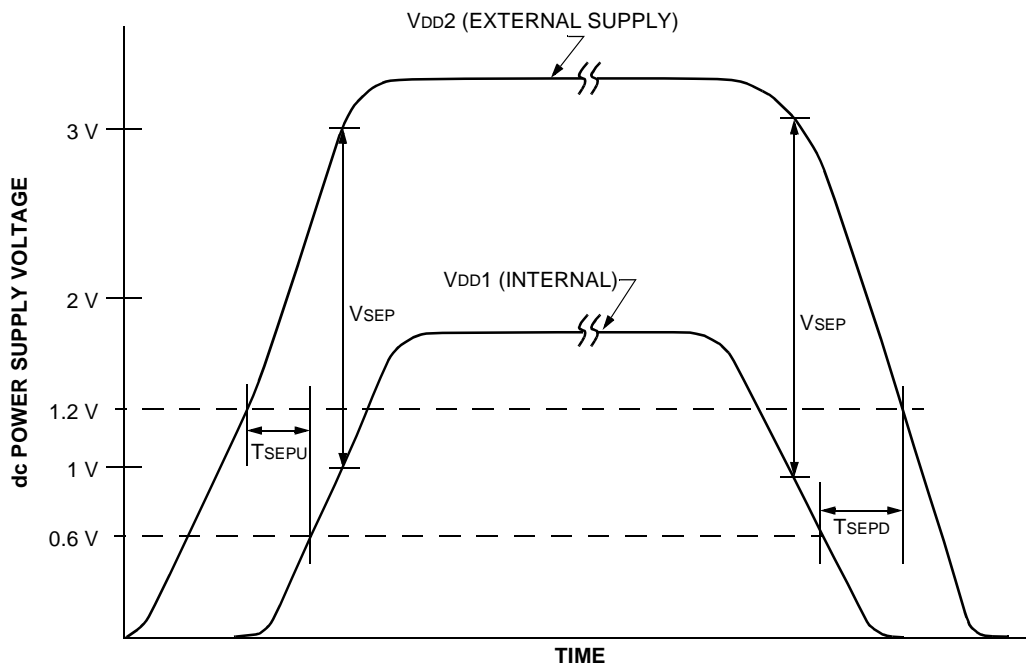
Control of powerup and powerdown sequences is recommended to address the following key issues. See Figure 6 and Table 10, on page 22 for definitions of the terms V_{SEP} , T_{SEPU} , and T_{SEPD} .

1. If the internal supply voltage (V_{DD1}) exceeds the external supply voltage (V_{DD2}) by a specified amount, large currents may flow through on-chip ESD structures that may reduce the long term life of the device or induce latch-up. The difference between the internal and external supply voltages is defined as V_{SEP} . It is recommended that the value of V_{SEP} specified in Table 10 be met during device powerup and device powerdown. External components may be required to ensure this specification is met (see Section 7.4.2).
2. During powerup, if the external supply voltage (V_{DD2}) exceeds a specified voltage (1.2 V) and the internal supply voltage (V_{DD1}) does not reach a specified voltage (0.6 V) within a specified time interval (T_{SEPU}), large currents may flow through the I/O buffer transistors. This is because the I/O buffer transistors are powered by V_{DD2} but their control transistors powered by V_{DD1} are not at valid logic levels. If the requirement for T_{SEPU} cannot be met, external components are recommended (see Section 7.4.2).
3. During powerdown, if the internal supply voltage (V_{DD1}) falls below a specified voltage (0.6 V) and the external supply voltage (V_{DD2}) does not fall below a specified voltage (1.2 V) within a specified time interval (T_{SEPD}), large currents may flow through the I/O buffer transistors. This is because the control transistors (powered by V_{DD1}) for the I/O buffer transistors are no longer at valid logic levels while the I/O buffer transistors remain powered by V_{DD2} . If the requirement for T_{SEPD} cannot be met, external components are recommended (see Section 7.4.2).

7 Electrical Characteristics and Requirements (continued)

7.4 Power Supply Sequencing Issues (continued)

7.4.1 Supply Sequencing Recommendations (continued)



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Figure 6. Power Supply Sequencing Recommendations

Table 10. Power Sequencing Recommendations

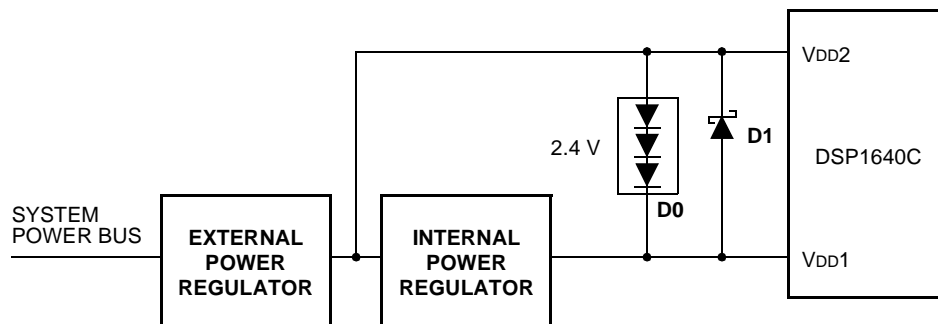
Parameter	Value	Description
VSEP	$-0.6 \text{ V} < VSEP$	Difference between VDD2 and VDD1 supplies. $VSEP = VDD2 - VDD1$. VSEP constraint must be satisfied for the entire duration of power-on and power-off supply ramp.
TSEPU	$0 \leq TSEPU < 50 \text{ ms}$	Time after VDD2 supply reaches 1.2 V and before VDD1 supplies reach 0.6 V.
TSEPD	$0 \leq TSEPD < 100 \text{ ms}$	Time after VDD1 supplies reach 0.6 V and before VDD2 reaches 1.2 V.

7 Electrical Characteristics and Requirements (continued)

7.4 Power Supply Sequencing Issues (continued)

7.4.2 External Power Sequence Protection Circuits

This section discusses external power sequence protection circuits which may be used to meet the recommendations discussed in Section 7.4.1. For the purpose of this discussion, the dual supply configuration of Figure 7 will be used. The recommendations for this series supply system apply to parallel supply configurations where a common power bus simultaneously controls both the internal and external supplies.



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Figure 7. Power Supply Example

Figure 7 illustrates a typical supply configuration. The external power regulator provides power to the internal power regulator.

Use of schottky diode D1 to bootstrap the VDD2 supply from the VDD1 supply is recommended. D1 ensures that the VSEP recommendation is met during device powerdown and powerup. In addition, D1 protects the DSP16410C from damage in the event of an external power regulator failure.

Diode network D0, which may be a series of diodes or a single zener diode, bootstraps the VDD1 supply. After VDD2 is a fixed voltage above VDD1 (2.4 V as determined by D0), the VDD2 supply will power VDD1 until D0 is cut off as VDD1 achieves its operating voltage. If TSEPU/TSEPD recommendations are met, D0 is not required. Since D0 protects the DSP16410C from damage in the event of an internal supply failure and reduces TSEPU, use of D0 is recommended. To ensure D0 cutoff during normal system operation, D0's forward voltage (V_F) should be 2.4 V. D0 should be selected to ensure a minimum VDD1 of 0.8 V under DSP load.

8 Timing Characteristics and Requirements

Timing characteristics refer to the behavior of the device under specified conditions. Timing requirements refer to conditions imposed on the user for proper operation of the device. All timing data is valid for the following conditions:

$T_J = -40\text{ }^\circ\text{C}$ to $+120\text{ }^\circ\text{C}$ (See Section 6.3, on page 14).

$V_{DD2} = 3.3\text{ V} \pm 0.3\text{ V}$, $V_{SS} = 0\text{ V}$ (See Section 6.3, on page 14).

Capacitance load on outputs (C_L) = 30 pF.

Output characteristics can be derated as a function of load capacitance (C_L).

All outputs: $0.025\text{ ns/pF} \leq dt/dC_L \leq 0.07\text{ ns/pF}$ for $10 \leq C_L \leq 100\text{ pF}$.

For example, if the actual load capacitance on an output pin is 20 pF instead of 30 pF, the maximum derating for a rising edge is $(20 - 30)\text{ pF} \times 0.07\text{ ns/pF} = 0.7\text{ ns}$ **less** than the specified rise time or delay that includes a rise time. The minimum derating for the same 20 pF load would be $(20 - 30)\text{ pF} \times 0.025\text{ ns/pF} = 0.25\text{ ns}$.

Test conditions for inputs:

- Rise and fall times of 4 ns or less.
- Timing reference levels for CKI, RSTN, TRST0N, TRST1N, TCK0, and TCK1 are V_{IH} and V_{IL} .
- Timing reference level for all other inputs is V_M . (See Table 11.)
- Test conditions for outputs (unless noted otherwise):
- $C_{LOAD} = 30\text{ pF}$.
- Timing reference levels for ECKO are V_{OH} and V_{OL} .
- Timing reference level for all other outputs is V_M .
- 3-state delays measured to the high-impedance state of the output driver.

Unless otherwise noted, ECKO in the timing diagrams is the free-running CLK (**ECON1**[1:0] = 1).



5-8215 (F)

Figure 8. Reference Voltage Level for Timing Characteristics and Requirements for Inputs and Outputs

Table 11. Reference Voltage Level for Timing Characteristics and Requirements for Inputs and Outputs

Abbreviated Reference	Parameter	Value	Unit
V_M	Reference Voltage Level for Timing Characteristics and Requirements for Inputs and Outputs	1.5	V

8 Timing Characteristics and Requirements (continued)

8.1 Phase-Lock Loop

Table 12. PLL Requirements

Parameter	Symbol	Min	Max	Unit
VCO Frequency Range (VDD1A = 1.575 V)	f _{VCO}	200	500	MHz
Input Jitter at CKI	—	—	200	ps-rms
PLL Lock Time	t _L	—	0.5	ms
CKI Frequency with PLL Enabled	f _{CKI}	6	40	MHz
CKI Frequency with PLL Disabled	f _{CKI}	0	50	MHz
f _{CKI} /(D [†] + 2)	—	3	20	MHz

† D is the PLL input divider and is defined by pllfrq[13:9].

8.2 Wake-Up Latency

Table 13 specifies the wake-up latency for the low-power standby mode. The wake-up latency is the delay between exiting low-power standby mode and resumption of normal execution.

Table 13. Wake-Up Latency

Condition		Wake-Up Latency	
		(PLL Deselected [†] During Normal Execution)	(PLL Enabled [‡] and Selected [†] During Normal Execution)
Low-power Standby Mode (AWAIT (alf[15]) = 1)	PLL Disabled [‡] During Standby	3T [§]	3T [§] + t _L ^{††}
	PLL Enabled [‡] During Standby	3T [§]	3T [§]

† The PLL is deselected if the PLLSEL field (pllcon[0]) is cleared, which is the default after reset. The PLL is selected if the PLLSEL field (pllcon[0]) is set.

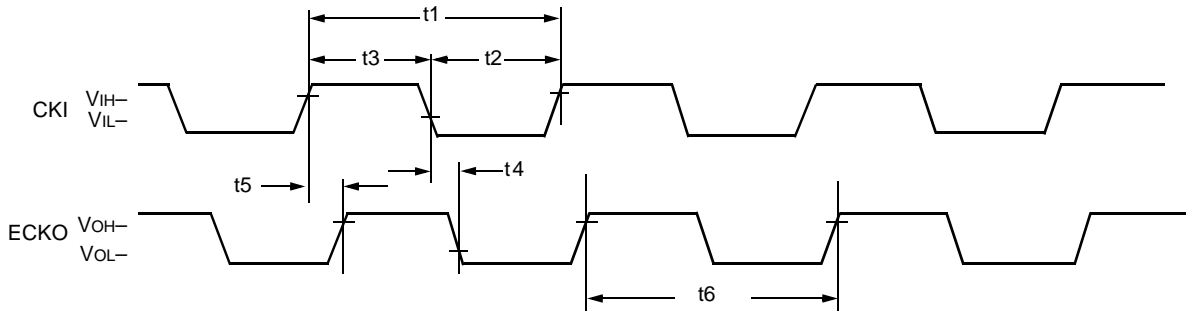
‡ The PLL is disabled (powered down) if the PLEN field (pllcon[1]) is cleared, which is the default after reset. The PLL is enabled (powered up) if the PLEN field (pllcon[1]) is set.

§ T = CLK clock cycle (f_{CLK} = f_{CKI} if PLL deselected; f_{CLK} = f_{CKI} * ((M + 2)/((D + 2) * f(OD))) if PLL enabled and selected).

†† t_L = PLL lock-in time (see Table 12).

8 Timing Characteristics and Requirements (continued)

8.3 DSP Clock Generation



5-4009(F).i

Figure 9. I/O Clock Timing Diagram

Table 14. Timing Requirements for Input Clock

Abbreviated Reference	Parameter	Min	Max	Unit
t_1^\dagger	Clock In Period (high to high)	20	— [‡]	ns
t_2	Clock In Low Time (low to high)	10	—	ns
t_3	Clock In High Time (high to low)	10	—	ns

[†] For timing requirements shown, it is assumed that CKI (not the PLL output) is selected as internal clock source. If the PLL is selected as the internal clock source, the minimum required CKI period is 25 ns and the maximum required CKI period is 167 ns.

[‡] Device is fully static, t_1 is tested at 100 ns input clock option, and memory hold time is tested at 0.1 s.

Table 15. Timing Characteristics for Input Clock and Output Clock

Abbreviated Reference	Parameter	Min	Max	Unit
t_4	Clock Out High Delay (low to low)	—	10	ns
t_5	Clock Out Low Delay (high to high)	—	10	ns
t_6	Clock Out Period (high to high)	T^\dagger	—	ns

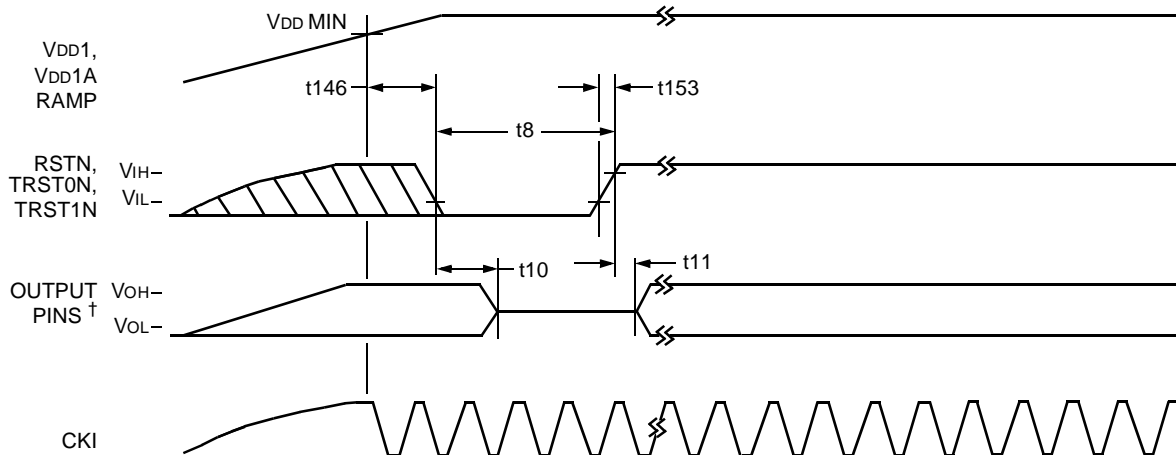
[†] T = internal clock period (CLK).

8 Timing Characteristics and Requirements (continued)

8.4 Reset Circuit

The DSP16410C has three external reset pins: RSTN, TRST0N, TRST1N. At initial powerup or if any supply voltage (V_{DD1} , V_{DD1A} , or V_{DD2}) falls below $V_{DD\ MIN}^*$, a device reset is required and RSTN, TRST0N, TRST1N must be asserted simultaneously to initialize the device.

Note: The TRST0N and TRST1N pins must be asserted even if the JTAG controller is not used by the application.



5-4010(F).r

† When both INT0 and RSTN are asserted, all output and bidirectional pins (except TDO, which 3-states by JTAG control) are put in a 3-state condition. With RSTN asserted and INT0 not asserted, EION, ERAMN, EROMN, EACKN, ERWN0, and ERWN1 outputs are driven high. EA[18:0], ESEG[3:0], and ECKO are driven low.

Figure 10. Powerup and Device Reset Timing Diagram

Table 16. Timing Requirements for Powerup and Device Reset

Abbreviated Reference	Parameter	Min	Max	Unit
t8	RSTN, TRST0N, and TRST1N Reset Pulse (low to high)	$7T^\dagger$	—	ns
t146	V_{DD1} , V_{DD1A} MIN to RSTN, TRST0N, and TRST1N Low	$2T^\dagger$	—	ns
t153	RSTN, TRST0N, and TRST1N Rise (low to high)	—	60	ns

† T = internal clock period (CKI).

Table 17. Timing Characteristics for Device Reset

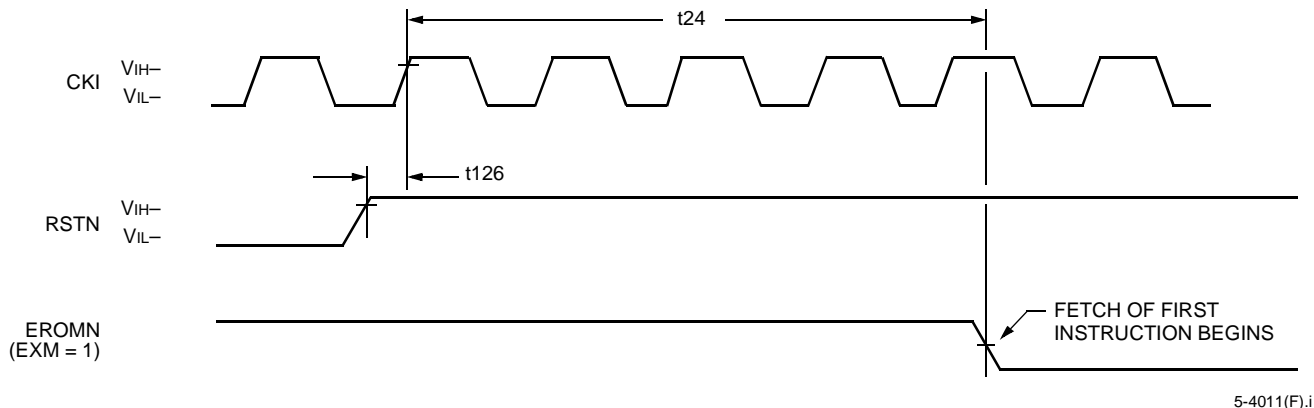
Abbreviated Reference	Parameter	Min	Max	Unit
t10	RSTN Disable Time (low to 3-state)	—	50	ns
t11	RSTN Enable Time (high to valid)	—	50	ns

Note: The device needs to be clocked for at least six CKI cycles during reset after powerup. Otherwise, high currents may flow.

* See Table 5 on page 14.

8 Timing Characteristics and Requirements (continued)

8.5 Reset Synchronization



Note: See Section 8.9 for timing characteristics of the EROMN pin.

Figure 11. Reset Synchronization Timing

Table 18. Timing Requirements for Reset Synchronization Timing

Abbreviated Reference	Parameter	Min	Max	Unit
t126	Reset Setup (high to high)	3	$T/2 - 1^\dagger$	ns
t24	CKI to Enable Valid	$4T + 0.5$	$4T + 4$	ns

\dagger T = internal clock period (CKI).

8 Timing Characteristics and Requirements (continued)

8.6 JTAG

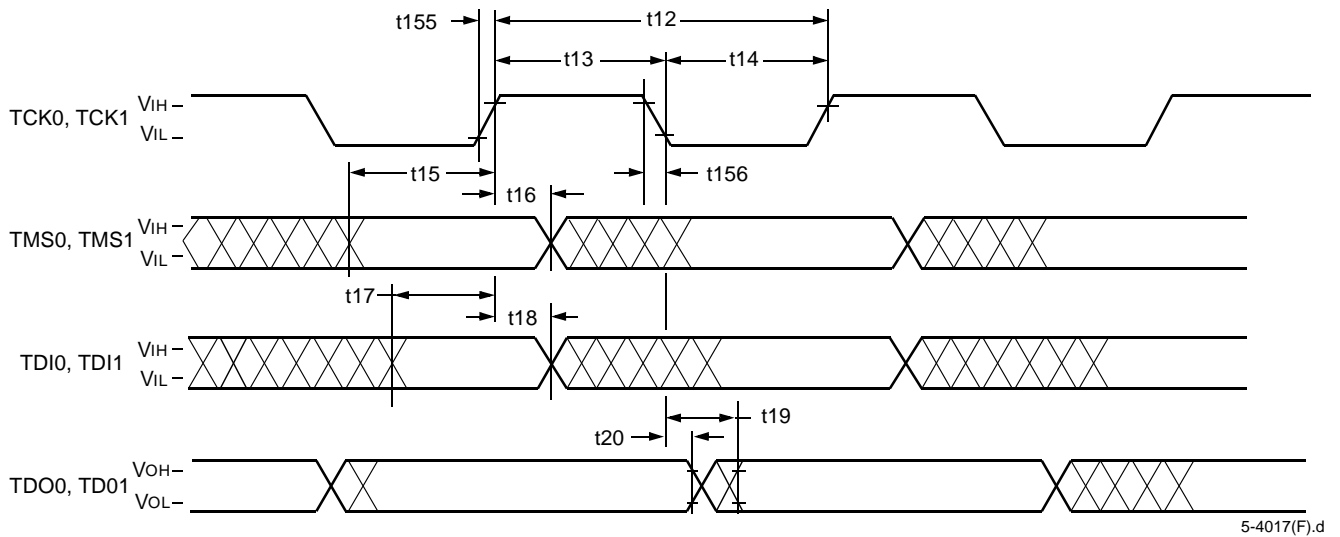


Figure 12. JTAG I/O Timing Diagram

Table 19. Timing Requirements for JTAG I/O

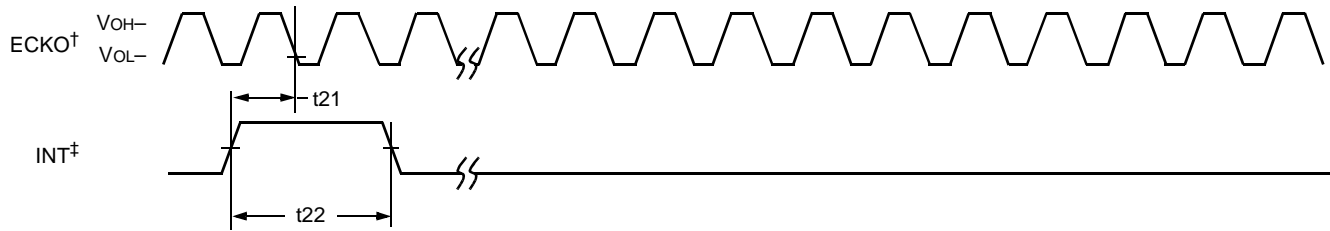
Abbreviated Reference	Parameter	Min	Max	Unit
t12	TCK Period (high to high)	50	—	ns
t13	TCK High Time (high to low)	22.5	—	ns
t14	TCK Low Time (low to high)	22.5	—	ns
t155	TCK Rise Transition Time (low to high)	0.6	—	V/ns
t156	TCK Fall Transition Time (high to low)	0.6	—	V/ns
t15	TMS Setup Time (valid to high)	7.5	—	ns
t16	TMS Hold Time (high to invalid)	5	—	ns
t17	TDI Setup Time (valid to high)	7.5	—	ns
t18	TDI Hold Time (high to invalid)	5	—	ns

Table 20. Timing Characteristics for JTAG I/O

Abbreviated Reference	Parameter	Min	Max	Unit
t19	TDO Delay (low to valid)	—	15	ns
t20	TDO Hold (low to invalid)	0	—	ns

8 Timing Characteristics and Requirements (continued)

8.7 Interrupt and Trap



5-4018(F).g

† ECKO is free-running.
‡ INT is one of INT[3:0] or TRAP.

Figure 13. Interrupt and Trap Timing Diagram

Table 21. Timing Requirements for Interrupt and Trap

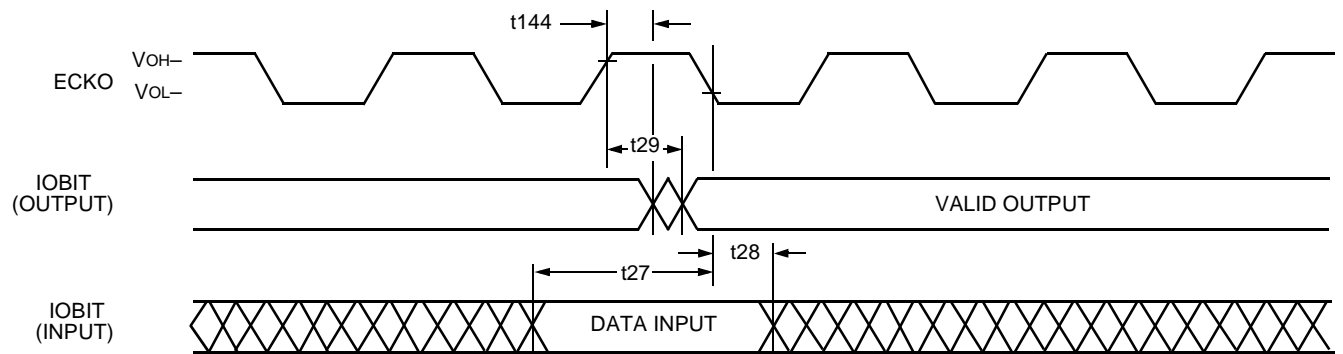
Note: Interrupt is asserted during an interruptible instruction and no other pending interrupts.

Abbreviated Reference	Parameter	Min	Max	Unit
t21	Interrupt Setup (high to low)	8	—	ns
t22	INT/TRAP Assertion Time (high to low)	2T†	—	ns

† T = internal clock period (CLK).

8 Timing Characteristics and Requirements (continued)

8.8 Bit I/O



5-4019(F).c

Figure 14. Write Outputs Followed by Read Inputs (cbit = IMMEDIATE; a1 = sbit) Timing Characteristics

Table 22. Timing Requirements for BIO Input Read

Abbreviated Reference	Parameter	Min	Max	Unit
t27	IOBIT Input Setup Time (valid to low)	10	—	ns
t28	IOBIT Input Hold Time (low to invalid)	0	—	ns

Table 23. Timing Characteristics for BIO Output

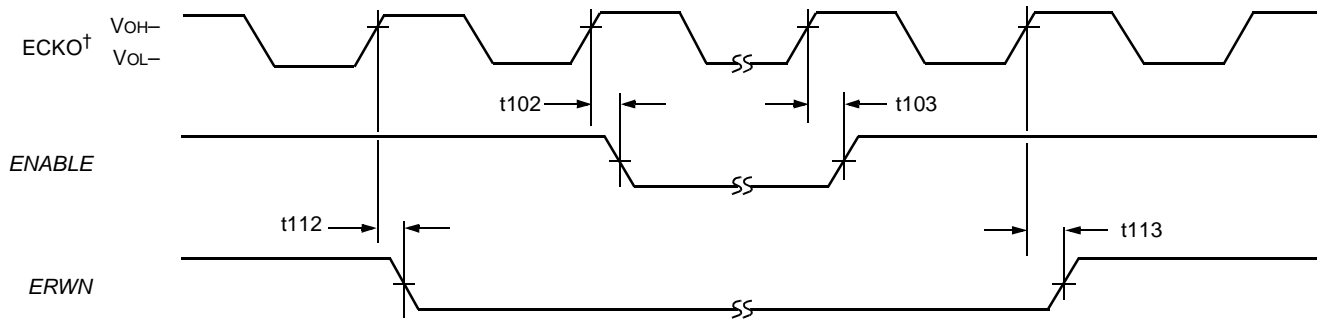
Abbreviated Reference	Parameter	Min	Max	Unit
t29	IOBIT Output Valid Time (high to valid)	—	9	ns
t144	IOBIT Output Hold Time (high to invalid)	1	—	ns

8 Timing Characteristics and Requirements (continued)

8.9 System and External Memory Interface

In the following timing diagrams and associated tables:

- The designation *ENABLE* refers to one of the following pins: EROMN, ERAMN, or EION. The designation *ENABLES* refers to all of the following pins: EROMN, ERAMN, and EION.
- The designation *ERWN* refers to the following:
 - The ERWN0 pin if the external data bus is configured as 16 bits, i.e., if the ESIZE pin is logic low.
 - The ERWN1 and ERWN0 pins if the external data bus is configured as 32 bits, i.e., if the ESIZE pin is logic high.
 - The ERWN1, ERWN0, and EA0 pins if the external data bus is configured as 32 bits, i.e., if the ESIZE pin is logic high, and if the memory access is synchronous.
- The designation *EA* refers to the following:
 - The external address pins EA[18:0] and the external segment address pins ESEG[3:0] if the external data bus is configured as 16 bits, i.e., if the ESIZE pin is logic low.
 - The external address pins EA[18:1] and the external segment address pins ESEG[3:0] if the external data bus is configured as 32 bits, i.e., if the ESIZE pin is logic high.
- The designation *ED* refers to the following:
 - The external data pins ED[31:16] if the external data bus is configured as 16 bits, i.e., if the ESIZE pin is logic low.
 - The external data pins ED[31:0] if the external data bus is configured as 32 bits, i.e., if the ESIZE pin is logic high.
- The designation *ATIME* refers to IATIME (**ECON0**[11:8]) for accesses to the EIO space, YATIME (**ECON0**[7:4]) for accesses to the ERAM space, or XATIME (**ECON0**[3:0]) for accesses to the EROM space.



† ECKO reflects CLK, i.e., **ECON1**[1:0] = 1.

Figure 15. Enable and Write Strobe Transition Timing

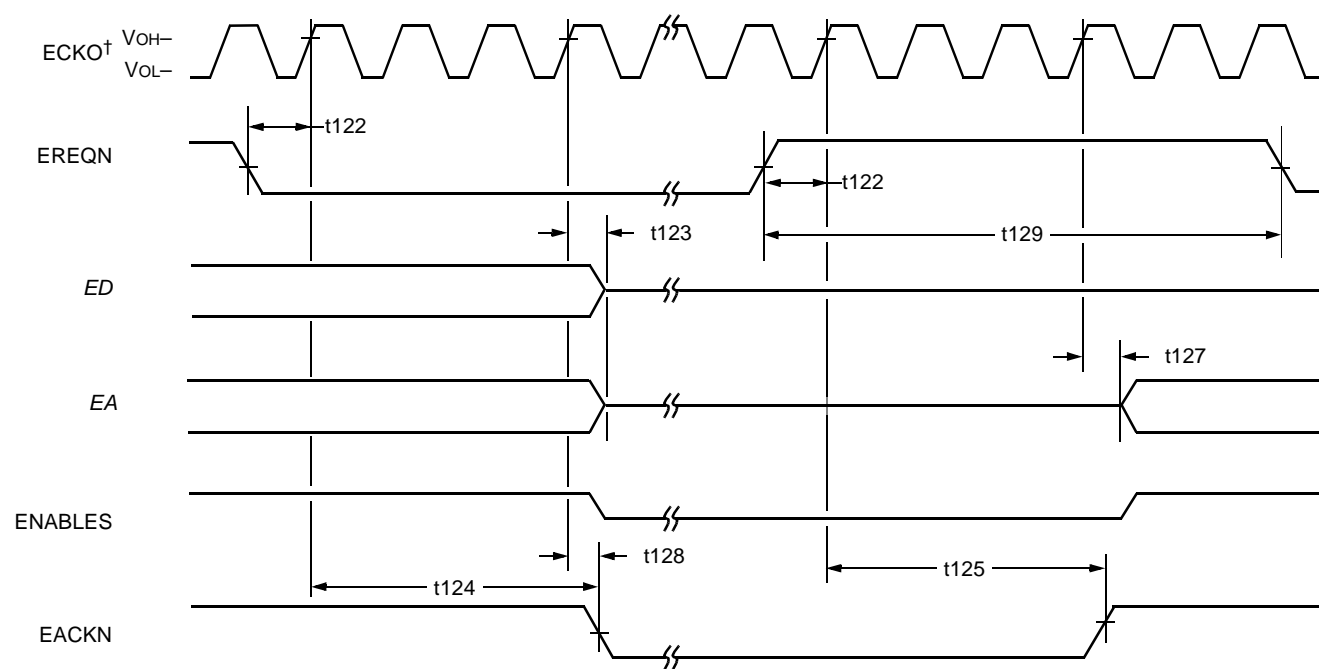
Table 24. Timing Characteristics for Memory Enables and ERWN

Abbreviated Reference	Parameter	Min	Max	Unit
t102	ECKO to <i>ENABLE</i> Active (high to low)	0.5	4	ns
t103	ECKO to <i>ENABLE</i> Inactive (high to high)	0.5	4	ns
t112	ECKO to <i>ERWN</i> Active (high to low)	0.5	4	ns
t113	ECKO to <i>ERWN</i> Inactive (high to high)	0.5	4	ns

8 Timing Characteristics and Requirements (continued)

8.9 System and External Memory Interface (continued)

8.9.1 Asynchronous Interface



† ECKO reflects CLK, i.e., ECON1[1:0] = 1.

Figure 16. Timing Diagram for EREQN and EACKN

Table 25. Timing Requirements for EREQN

Abbreviated Reference	Parameter	Min	Max	Unit
t ₁₂₂	EREQN Setup (low to high or high to high)	5	—	ns
t ₁₂₉	EREQN Deassertion (high to low)	ATIME _{MAX} †	—	ns

† ATIME_{MAX} = the greatest of IATIME(ECON0[11:8]), YATIME (ECON0[7:4]), and XTIME (ECON0[3:0]).

Table 26. Timing Characteristics for EACKN and SEMI Bus Disable

Abbreviated Reference	Parameter	Min	Max	Unit
t ₁₂₃	Memory Bus Disable Delay (high to 3-state)	—	6	ns
t ₁₂₄	EACKN Assertion Delay† (high to low)	4T‡	—	ns
t ₁₂₅	EACKN Deassertion Delay (high to high)	4T‡	4T‡ + 3	ns
t ₁₂₇	Memory Bus Enable Delay (high to active)	5	—	ns
t ₁₂₈	EACKN Delay (high to low)	—	3	ns

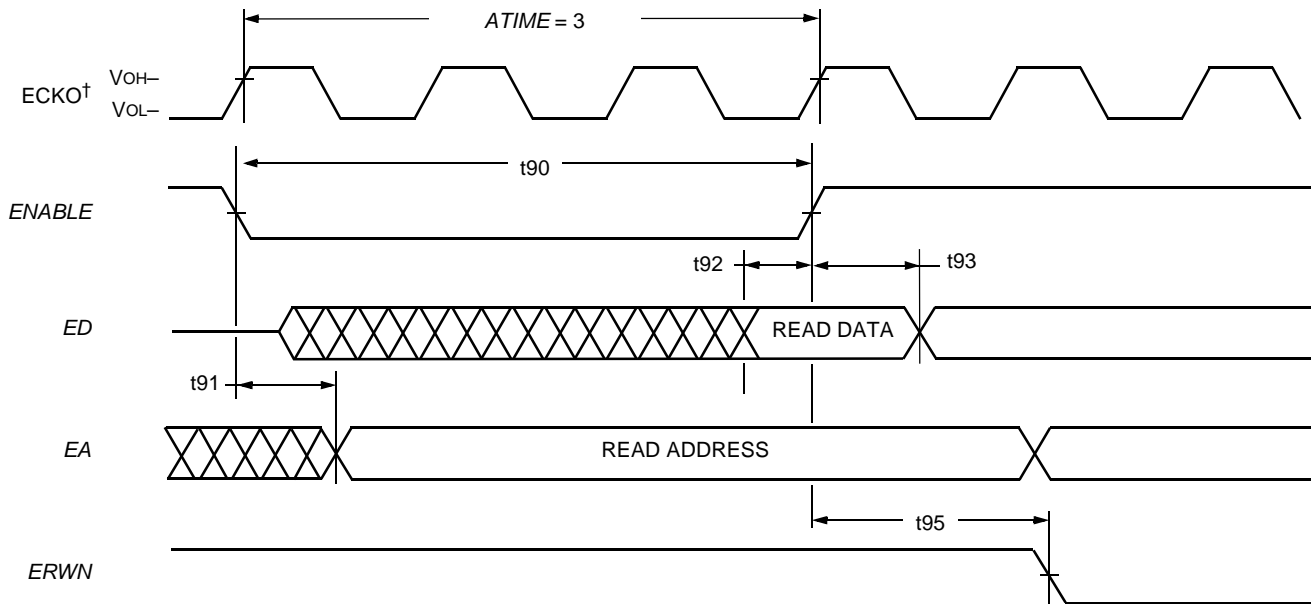
† If any ENABLE is asserted (low) when EREQN is asserted (low), then the delay occurs from the time that ENABLE is deasserted (high). (The SEMI does not acknowledge the request by asserting EACKN until it has completed any pending memory accesses.)

‡ T = internal clock period (CLK).

8 Timing Characteristics and Requirements (continued)

8.9 System and External Memory Interface (continued)

8.9.1 Asynchronous Interface (continued)



† ECKO reflects CLK, i.e., **ECON1**[1:0] = 1.

Figure 17. Asynchronous Read Timing Diagram (RHOLD = 0 and RSETUP = 0)

Table 27. Timing Requirements for Asynchronous Memory Read Operations

Abbreviated Reference	Parameter	Min	Max	Unit
t92	Read Data Setup (valid to <i>ENABLE</i> high)	5	—	ns
t93	Read Data Hold (<i>ENABLE</i> high to invalid)	0	—	ns

Table 28. Timing Characteristics for Asynchronous Memory Read Operations

Abbreviated Reference	Parameter	Min	Max	Unit
t90	<i>ENABLE</i> Width (low to high)	$(T^\dagger \times ATIME) - 3$	—	ns
t91	Address Delay (<i>ENABLE</i> low to valid)	—	$2 - (T^\dagger \times RSETUP^\ddagger)$	ns
t95	<i>ERWN</i> Activation (<i>ENABLE</i> high to <i>ERWN</i> low)	$T^\dagger \times (1 + RHOLD^\S + WSETUP^{\dagger\dagger}) - 3$	—	—

† T = internal clock period (CLK).

‡ RSETUP = **ECON0**[12].

§ RHOLD = **ECON0**[14].

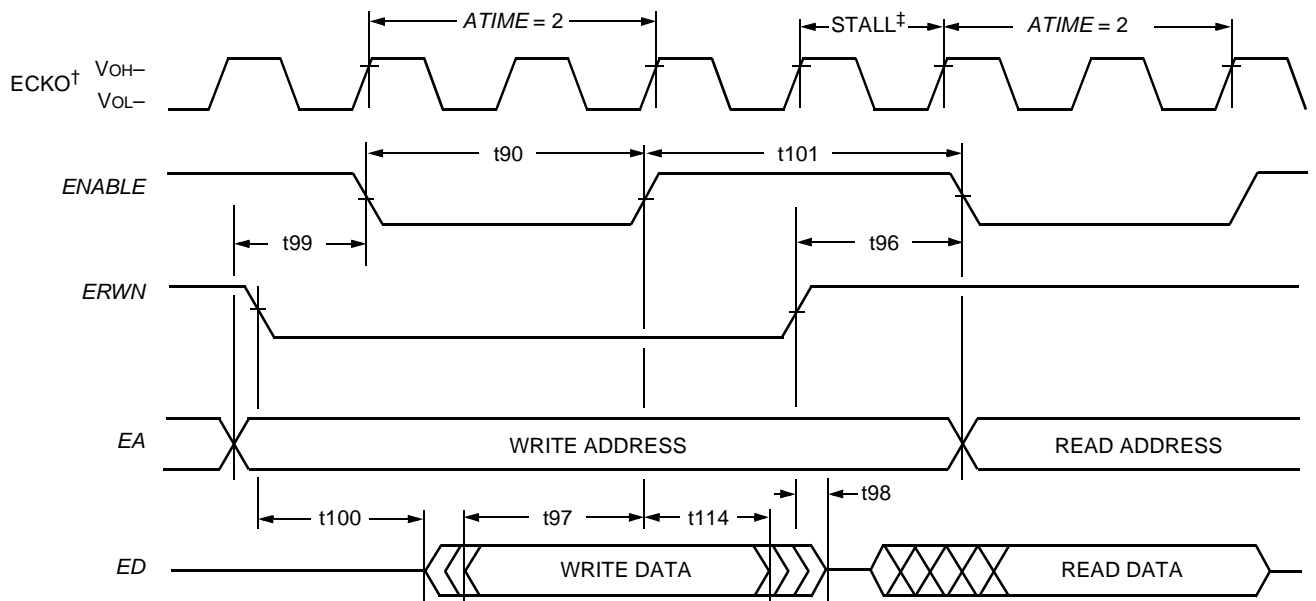
†† WSETUP = **ECON0**[13].

Note: The external memory access time from the assertion of *ENABLE* can be calculated as $t_{90} - (t_{91} + t_{92})$.

8 Timing Characteristics and Requirements (continued)

8.9 System and External Memory Interface (continued)

8.9.1 Asynchronous Interface (continued)



† ECKO reflects CLK, i.e., **ECON1**[1:0] = 1.

‡ The stall cycle is caused by the read following the write.

Figure 18. Asynchronous Write Timing Diagram (WHOLD = 0, WSETUP = 0)

Table 29. Timing Characteristics for Asynchronous Memory Write Operations

Abbreviated Reference	Parameter	Min	Max	Unit
t90	ENABLE Width (low to high)	$(T^\dagger \times ATIME) - 3$	—	ns
t96	Enable Delay (ERWN high to ENABLE low)	$T^\dagger \times (1 + WHOLD^\ddagger + RSETUP^\S) - 3$	—	ns
t97	Write Data Setup (valid to ENABLE high)	$(T^\dagger \times ATIME) - 3$	—	ns
t98	Write Data Deactivation (ERWN high to 3-state)	—	3	ns
t99	Write Address Setup (valid to ENABLE low)	$T^\dagger \times (1 + WSETUP^{\dagger\dagger}) - 3$	—	ns
t100	Write Data Activation (ERWN low to low-Z)	$T^\dagger - 2$	—	ns
t101	Address Hold Time (ENABLE high to invalid)	$T^\dagger \times (1 + WHOLD^\ddagger) - 3$	—	ns
t114	Write Data Hold Time (ENABLE high to invalid)	$T - 3$	—	ns

† T = internal clock period (CLK).

‡ WHOLD = **ECON0**[15].

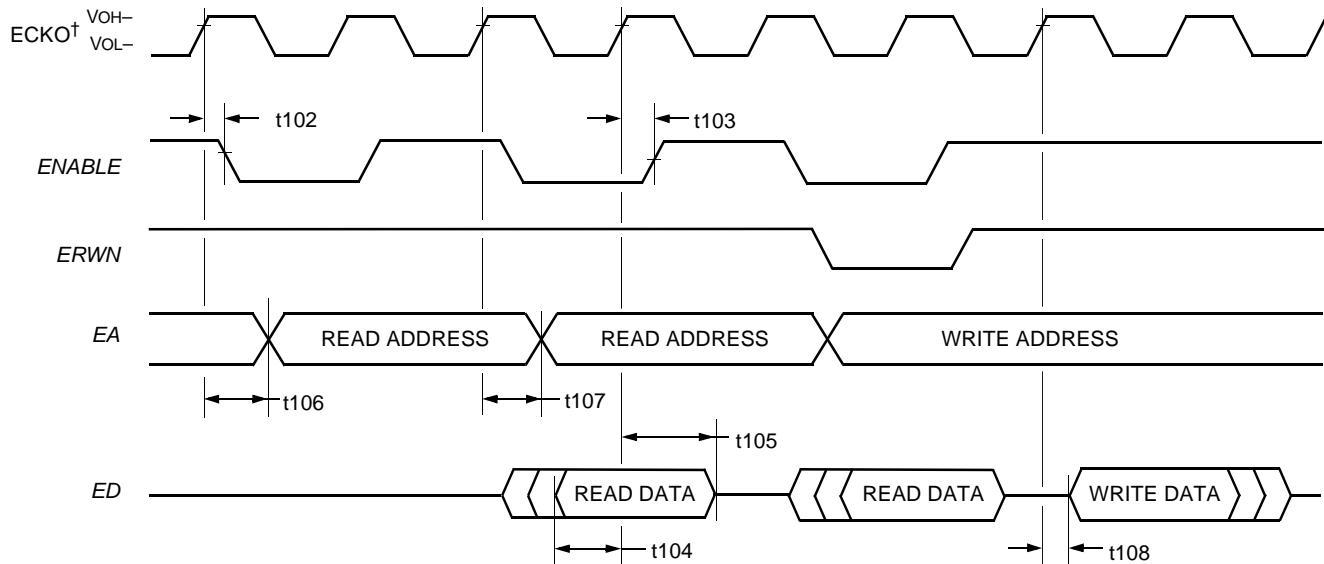
§ RSETUP = **ECON0**[12].

†† WSETUP = **ECON0**[13].

8 Timing Characteristics and Requirements (continued)

8.9 System and External Memory Interface (continued)

8.9.2 Synchronous Interface



† ECKO reflects CLK/2, i.e., ECON1[1:0] = 0.

Figure 19. Synchronous Read Timing Diagram (Read-Read-Write Sequence)

Table 30. Timing Requirements for Synchronous Read Operations

Abbreviated Reference	Parameter	Min	Max	Unit
t104	Read Data Setup (valid to high)	4	—	ns
t105	Read Data Hold (high to invalid)	1	—	ns

Table 31. Timing Characteristics for Synchronous Read Operations

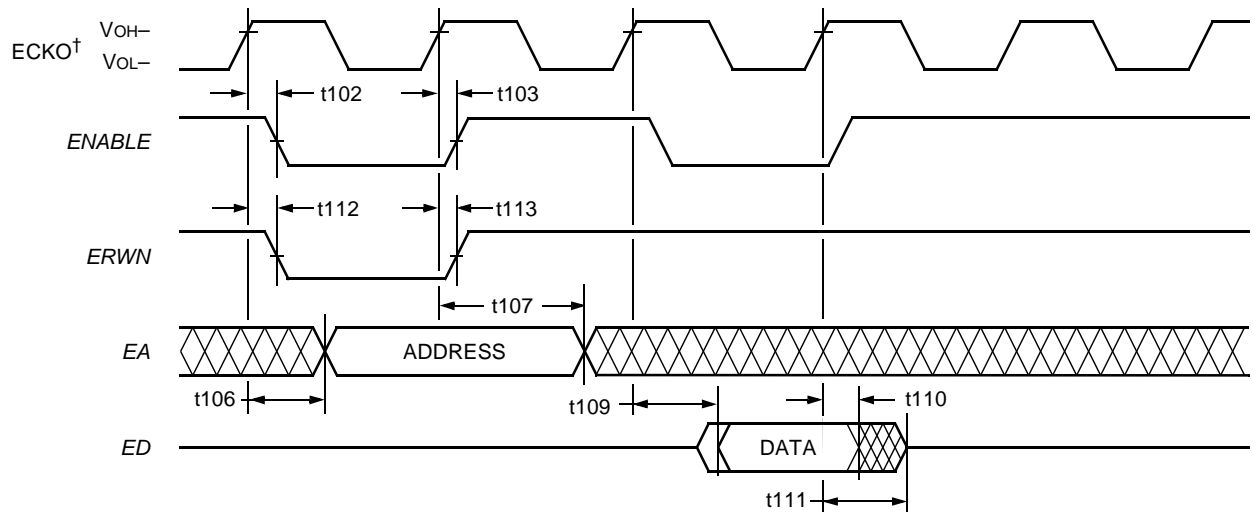
Abbreviated Reference	Parameter	Min	Max	Unit
t102	ECKO to ENABLE Active (high to low)	0.5	4	ns
t103	ECKO to ENABLE Inactive (high to high)	0.5	4	ns
t106	Address Delay (high to valid)	—	2.5	ns
t107	Address Hold (high to invalid)	0.5	—	ns
t108	Write Data Active (high to low-Z)	$T^\dagger - 3$	—	ns

† T = internal clock period (CLK).

8 Timing Characteristics and Requirements (continued)

8.9 System and External Memory Interface (continued)

8.9.2 Synchronous Interface (continued)



† ECKO reflects CLK/2, i.e., **ECON1**[1:0] = 0.

Figure 20. Synchronous Write Timing Diagram

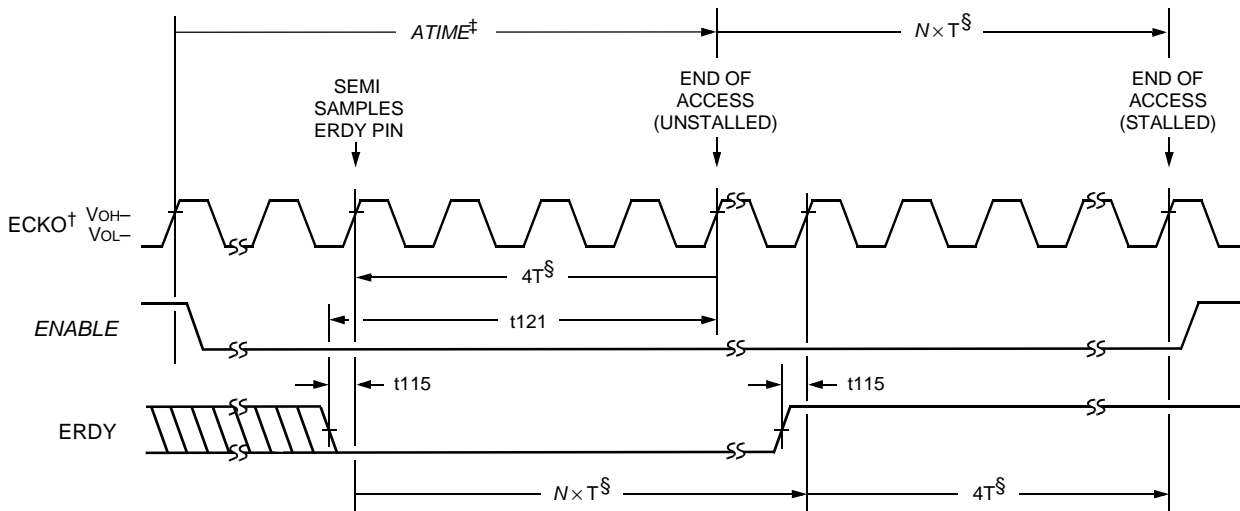
Table 32. Timing Characteristics for Synchronous Write Operations

Abbreviated Reference	Parameter	Min	Max	Unit
t102	ECKO to <i>ENABLE</i> Active (high to low)	0.5	4	ns
t103	ECKO to <i>ENABLE</i> Inactive (high to high)	0.5	4	ns
t106	Address Delay (high to valid)	—	2.5	ns
t107	Address Hold (high to invalid)	0.5	—	ns
t109	Write Data Delay (high to valid)	—	2.5	ns
t110	Write Data Hold (high to invalid)	0.5	—	ns
t111	Write Data Deactivation Delay (high to 3-state)	—	2.5	ns
t112	ECKO to <i>ERWN</i> Active (high to low)	0.5	4	ns
t113	ECKO to <i>ERWN</i> Inactive (high to high)	0.5	4	ns

8 Timing Characteristics and Requirements (continued)

8.9 System and External Memory Interface (continued)

8.9.3 ERDY Interface



† ECKO reflects CLK, i.e., **ECON1**[1:0] = 1.

‡ *ATIME* must be programmed as greater than or equal to five CLK cycles. Otherwise, the SEMI ignores the state of ERDY.

§ T = internal clock period (CLK). N must be greater than or equal to one, i.e., ERDY must be held low for at least one CLK cycle after the SEMI samples ERDY.

Figure 21. ERDY Pin Timing Diagram

As indicated in the drawing, the SEMI:

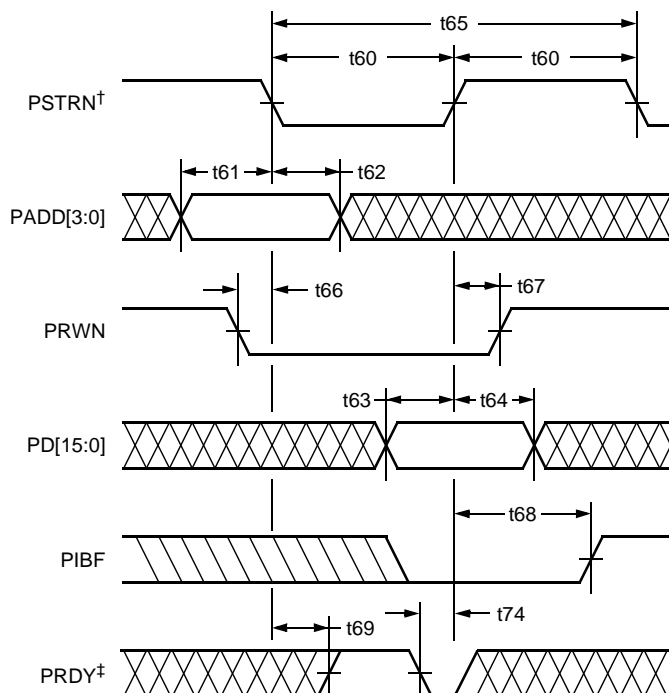
- Samples the state of ERDY at 4T prior to the end of the access (unstalled). (The end of the access (unstalled) occurs at *ATIME* cycles after *ENABLE* goes low.)
- Ignores the state of ERDY before the ERDY sample point.
- Stalls the external memory access by *N* × T cycles, i.e., by the number of cycles that ERDY is held low following the ERDY sample point.

Table 33. Timing Requirements for ERDY Pin

Abbreviated Reference	Parameter	Min	Max	Unit
t ₁₁₅	ERDY Setup to any ECKO (low to high or high to high)	5	—	ns
t ₁₂₁	ERDY Setup to ECKO at End of Unstalled Access (low to high)	4T + 5	—	ns

8 Timing Characteristics and Requirements (continued)

8.10 PIU



5-7850 (F)

† PSTRN is the logical OR of the PCSN input pin with the exclusive NOR of the PIDS and PODS input pins, i.e., $PSTRN = PCSN \mid (\overline{PIDS \wedge PODS})$.

‡ It is assumed that the PRDYMD pin is logic low, configuring the PRDY pin as active-low.

Figure 22. Host Data Write to PDI Timing Diagram

Table 34. Timing Requirements for PIU Data Write Operations

Abbreviated Reference	Parameter	Min	Max	Unit
t60	PSTRN Pulse Width (high to low or low to high)	$\max(2T^\dagger, 15)$	—	ns
t61	PADD Setup Time [‡] (valid to low)	5	—	ns
t62	PADD Hold Time [‡] (low to invalid)	5	—	ns
t63	PD Setup Time [§] (valid to high)	6	—	ns
t64	PD Hold Time [§] (high to invalid)	5	—	ns
t65	PSTRN Request Period (low to low)	$\max(5T^\dagger, 30)$	—	ns
t66	PRWN Setup Time [‡] (low to low)	0	—	ns
t67	PRWN Hold Time [§] (high to high)	0	—	ns
t74	PSTRN Hold (low to high)	1	—	ns

† T is the period of the internal clock (CLK).

‡ Time to the falling edge of PIDS, PODS, or PCSN, whichever occurs last.

§ Time to the rising edge of PIDS, PODS, or PCSN, whichever occurs first.

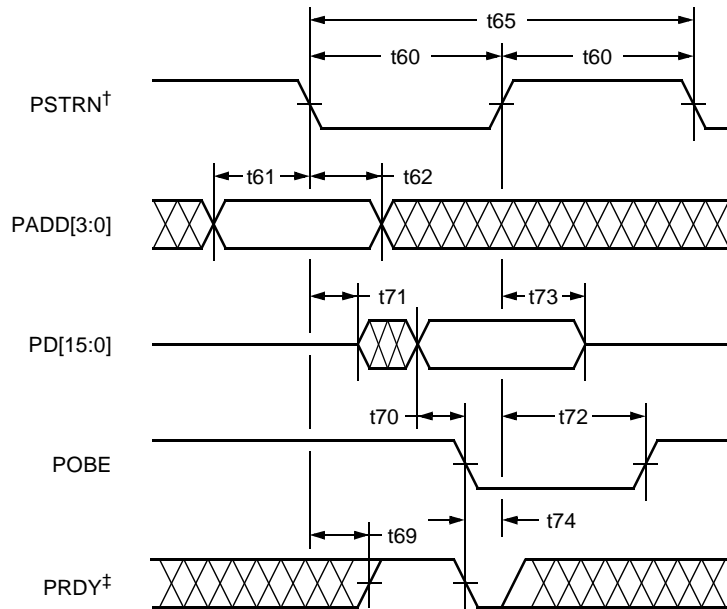
Table 35. Timing Characteristics for PIU Data Write Operations

Abbreviated Reference	Parameter	Min	Max	Unit
t68	PIBF Delay [†] (high to high)	1	12	ns
t69	PRDY Delay (low to valid)	1	12	ns

† Delay from the rising edge of PIDS, PODS, or PCSN, whichever occurs first.

8 Timing Characteristics and Requirements (continued)

8.10 PIU (continued)



5-7851 (F)

† PSTRN is the logical OR of the PCSN input pin with the exclusive NOR of the PIDS and PODS input pins, i.e., $PSTRN = PCSN \mid \overline{(PIDS \wedge PODS)}$.

‡ It is assumed that the PRDYMD pin is logic low, configuring the PRDY pin as active-low.

Figure 23. Host Data Read from PDO Timing Diagram

Table 36. Timing Requirements for PIU Data Read Operations

Abbreviated Reference	Parameter	Min	Max	Unit
t60	PSTRN Pulse Width (high to low or low to high)	$\max(2T^\dagger, 15)$	—	ns
t61	PADD Setup Time [‡] (valid to low)	5	—	ns
t62	PADD Hold Time [‡] (low to invalid)	5	—	ns
t65	PSTRN Request Period (low to low)	$\max(5T^\dagger, 30)$	—	ns
t74	PSTRN Hold (low to high)	1	—	ns

† T is the period of the internal clock (CLK).

‡ Time to the falling edge of PIDS, PODS, or PCSN, whichever occurs last.

Table 37. Timing Characteristics for PIU Data Read Operations

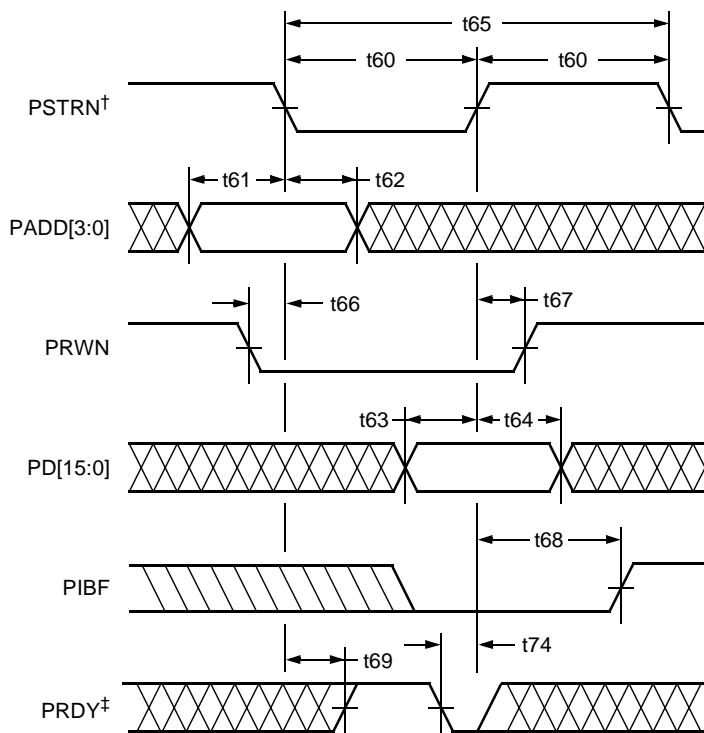
Abbreviated Reference	Parameter	Min	Max	Unit
t69	PRDY Delay (low to valid)	1	12	ns
t70	POBE, PRDY Delays (valid to low)	$T - 3$	T	ns
t71	PD Activation Delay [†] (low to low-Z)	1	6	ns
t72	POBE Delay [‡] (high to high)	1	12	ns
t73	PD Deactivation Delay [‡] (high to 3-state)	1	12	ns

† Delay from the falling edge of PIDS, PODS, or PCSN, whichever occurs last.

‡ Delay from the rising edge of PIDS, PODS, or PCSN, whichever occurs first.

8 Timing Characteristics and Requirements (continued)

8.10 PIU (continued)



5-7850 (F)

† PSTRN is the logical OR of the PCSN input pin with the exclusive NOR of the PIDS and PODS input pins, i.e., $PSTRN = PCSN \mid (\overline{PIDS \wedge PODS})$.

‡ It is assumed that the PRDYMD pin is logic low, configuring the PRDY pin as active-low.

Figure 24. Host Register Write (PAH, PAL, PCON, or HSCRATCH) Timing Diagram

Table 38. Timing Requirements for PIU Register Write Operations

Abbreviated Reference	Parameter	Min	Max	Unit
t60	PSTRN Pulse Width (high to low or low to high)	max (2T [†] , 15)	—	ns
t61	PADD Setup Time [‡] (valid to low)	5	—	ns
t62	PADD Hold Time [‡] (low to invalid)	5	—	ns
t63	PD Setup Time [§] (valid to high)	6	—	ns
t64	PD Hold Time [§] (high to invalid)	5	—	ns
t65	PSTRN Request Period (low to low)	max (5T [†] , 30)	—	ns
t66	PRWN Setup Time [‡] (low to low)	0	—	ns
t67	PRWN Hold Time [§] (high to high)	0	—	ns
t74	PSTRN Hold (low to high)	1	12	ns

† T is the period of the internal clock (CLK).

‡ Time to the falling edge of PIDS, PODS, or PCSN, whichever occurs last.

§ Time to the rising edge of PIDS, PODS, or PCSN, whichever occurs first.

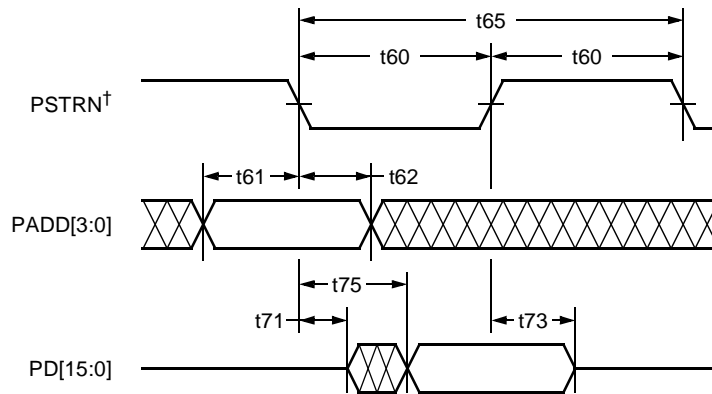
Table 39. Timing Characteristics for PIU Register Write Operations

Abbreviated Reference	Parameter	Min	Max	Unit
t68	PIBF Delay [†] (high to high)	1	12	ns
t69	PRDY Delay (low to valid)	1	12	ns

† Delay from the rising edge of PIDS, PODS, or PCSN, whichever occurs first.

8 Timing Characteristics and Requirements (continued)

8.10 PIU (continued)



5-7853 (F)

† PSTRN is the logical OR of the PCSN input pin with the exclusive NOR of the PIDS and PODS input pins, i.e., $PSTRN = PCSN \mid (\overline{PIDS \wedge PODS})$.

Figure 25. Host Register Read (PAH, PAL, PCON, or DSCRATCH) Timing Diagram

Table 40. Timing Requirements for PIU Register Read Operations

Abbreviated Reference	Parameter	Min	Max	Unit
t60	PSTRN Pulse Width (high to low or low to high)	$\max(2T^\dagger, 15)$	—	ns
t61	PADD Setup Time [‡] (valid to low)	5	—	ns
t62	PADD Hold Time [‡] (low to invalid)	5	—	ns
t65	PSTRN Request Period (low to low)	$\max(5T^\dagger, 30)$	—	ns

† T is the period of the internal clock (CLK).

‡ Time to the falling edge of PIDS, PODS, or PCSN, whichever occurs last.

Table 41. Timing Characteristics for PIU Register Read Operations

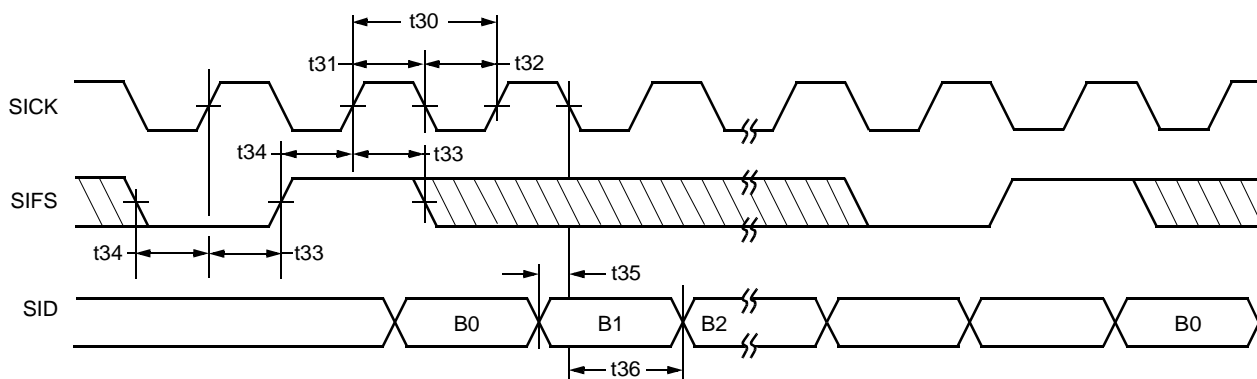
Abbreviated Reference	Parameter	Min	Max	Unit
t71	PD Activation Delay [†] (low to low-Z)	1	6	ns
t73	PD Deactivation Delay [†] (high to 3-state)	1	12	ns
t75	PD Delay [†] (low to valid)	—	16	ns

† Delay from the falling edge of PIDS, PODS, or PCSN, whichever occurs last.

‡ Delay from the rising edge of PIDS, PODS, or PCSN, whichever occurs first.

8 Timing Characteristics and Requirements (continued)

8.11 SIU



5-8033 (F)

Note: It is assumed that the SIU is configured with ICKA(SCON10[2]) = 0 for passive mode input clock, ICKK(SCON10[3]) = 0 for no inversion of SICK, IFSA(SCON10[0]) = 0 for passive mode input frame sync, IFSK(SCON10[1]) = 0 for no inversion of SIFS, IMSB(SCON0[2]) = 0 for LSB-first input, and IFSDLY[1:0](SCON1[9:8]) = 00 for no input frame sync delay.

Figure 26. SIU Passive Frame and Channel Mode Input Timing Diagram

Table 42. Timing Requirements for SIU Passive Frame Mode Input

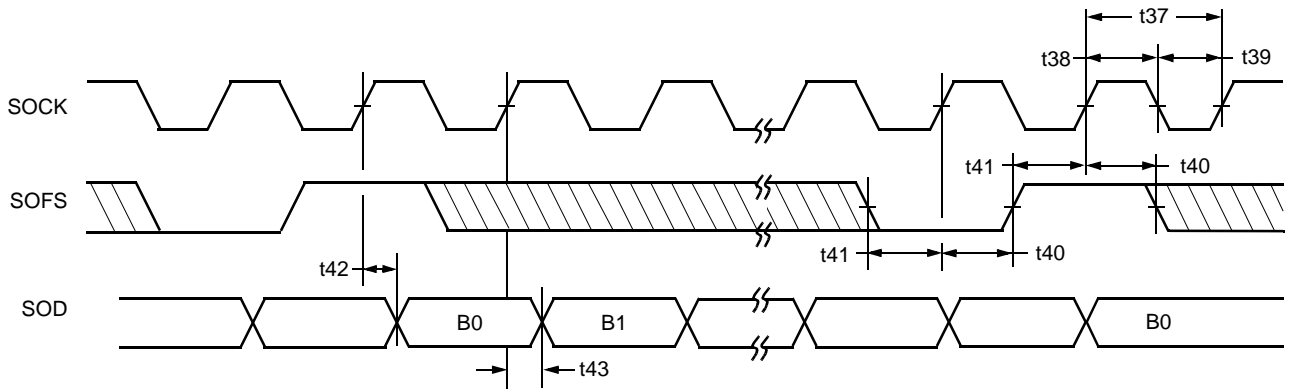
Abbreviated Reference	Parameter	Min	Max	Unit
t30	SICK Bit Clock Period (high to high)	25	—	ns
t31	SICK Bit Clock High Time (high to low)	10	—	ns
t32	SICK Bit Clock Low Time (low to high)	10	—	ns
t33	SIFS Hold Time (high to low or high to high)	10	—	ns
t34	SIFS Setup Time (low to high or high to high)	10	—	ns
t35	SID Setup Time (valid to low)	5	—	ns
t36	SID Hold Time (low to invalid)	8	—	ns

Table 43. Timing Requirements for SIU Passive Channel Mode Input

Abbreviated Reference	Parameter	Min	Max	Unit
t30	SICK Bit Clock Period (high to high)	61.035	—	ns
t31	SICK Bit Clock High Time (high to low)	28	—	ns
t32	SICK Bit Clock Low Time (low to high)	28	—	ns
t33	SIFS Hold Time (high to low or high to high)	10	—	ns
t34	SIFS Setup Time (low to high or high to high)	10	—	ns
t35	SID Setup Time (valid to low)	5	—	ns
t36	SID Hold Time (low to invalid)	8	—	ns

8 Timing Characteristics and Requirements (continued)

8.11 SIU (continued)



5-8034 (F)

Note: It is assumed that the SIU is configured with OCKA(SCON10[6]) = 0 for passive mode output clock, OCKK(SCON10[7]) = 0 for no inversion of SOCK, OFSA(SCON10[4]) = 0 for passive mode output frame sync, OFSK(SCON10[5]) = 0 for no inversion of SOFS, OMSB(SCON0[10]) = 0 for LSB-first output, OFRAME(SCON2[7]) = 1 for frame mode output, and OFSDLY[1:0](SCON2[9:8]) = 00 for no output frame sync delay.

Figure 27. SIU Passive Frame Mode Output Timing Diagram

Table 44. Timing Requirements for SIU Passive Frame Mode Output

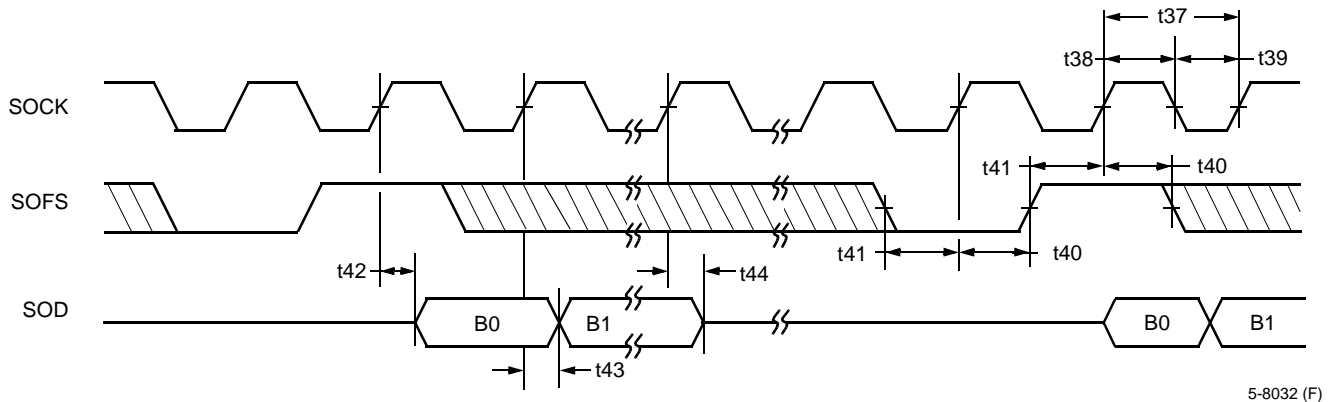
Abbreviated Reference	Parameter	Min	Max	Unit
t37	SOCK Bit Clock Period (high to high)	25	—	ns
t38	SOCK Bit Clock High Time (high to low)	10	—	ns
t39	SOCK Bit Clock Low Time (low to high)	10	—	ns
t40	SOFS Hold Time (high to low or high to high)	10	—	ns
t41	SOFS Setup Time (low to high or high to high)	10	—	ns

Table 45. Timing Characteristics for SIU Passive Frame Mode Output

Abbreviated Reference	Parameter	Min	Max	Unit
t42	SOD Delay (high to valid)	1	16	ns
t43	SOD Hold (high to invalid)	0	4	ns

8 Timing Characteristics and Requirements (continued)

8.11 SIU (continued)



5-8032 (F)

Note: It is assumed that the SIU is configured with $OCCA(\mathbf{SCON10}[6]) = 0$ for passive mode output clock, $OCKK(\mathbf{SCON10}[7]) = 0$ for no inversion of SOCK, $OFSA(\mathbf{SCON10}[4]) = 0$ for passive mode output frame sync, $OFSK(\mathbf{SCON10}[5]) = 0$ for no inversion of SOFS, $OMSB(\mathbf{SCON0}[10]) = 0$ for LSB-first output, $OFAME(\mathbf{SCON2}[7]) = 0$ for channel mode output, and $OFSDLY[1:0](\mathbf{SCON2}[9:8]) = 00$ for no output frame sync delay.

Figure 28. SIU Passive Channel Mode Output Timing Diagram

Table 46. Timing Requirements for SIU Passive Channel Mode Output

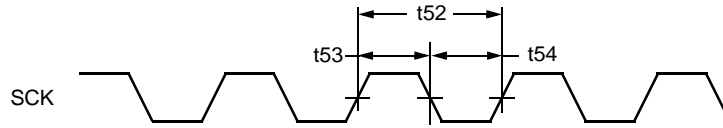
Abbreviated Reference	Parameter	Min	Max	Unit
t37	SOCK Bit Clock Period (high to high)	61.035	—	ns
t38	SOCK Bit Clock High Time (high to low)	28	—	ns
t39	SOCK Bit Clock Low Time (low to high)	28	—	ns
t40	SOFS Hold Time (high to low or high to high)	10	—	ns
t41	SOFS Setup Time (low to high or high to high)	10	—	ns

Table 47. Timing Characteristics for SIU Passive Channel Mode Output

Abbreviated Reference	Parameter	Min	Max	Unit
t42	SOD Delay (high to valid)	1	16	ns
t43	SOD Hold (high to invalid)	0	4	ns
t44	SOD Deactivation Delay (high to 3-state)	—	12	ns

8 Timing Characteristics and Requirements (continued)

8.11 SIU (continued)



5-8037 (F)

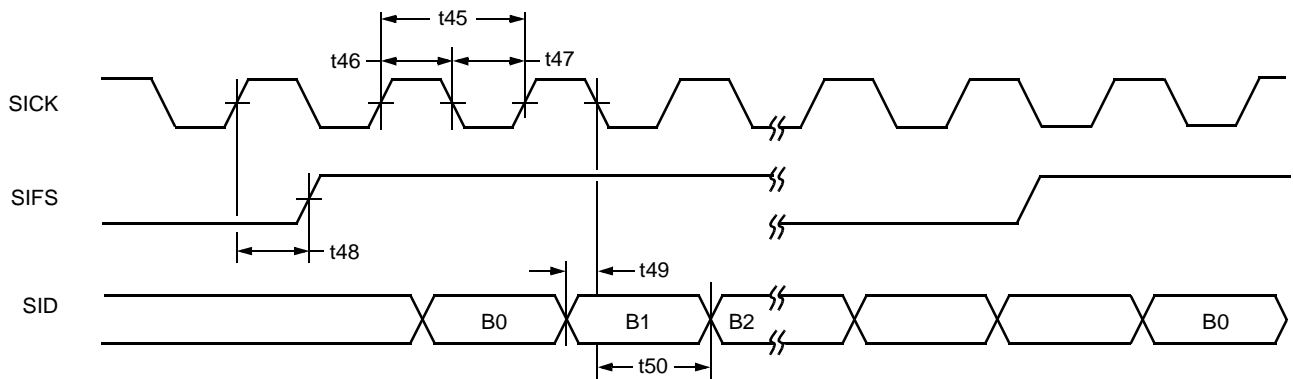
Figure 29. SCK External Clock Source Input Timing Diagram

Table 48. Timing Requirements for SCK External Clock Source

Abbreviated Reference	Parameter	Min	Max	Unit
t52	SCK Bit Clock Period (high to high)	25	—	ns
t53	SCK Bit Clock High Time (high to low)	10	—	ns
t54	SCK Bit Clock Low Time (low to high)	10	—	ns

8 Timing Characteristics and Requirements (continued)

8.11 SIU (continued)



5-8029 (F)

Note: It is assumed that the SIU is configured with ICKA(**SCON10**[2]) = 1 for active mode input clock, ICKK(**SCON10**[3]) = 0 for no inversion of SICK, IFSA(**SCON10**[0]) = 1 for active mode input frame sync, IFSK(**SCON10**[1]) = 0 for no inversion of SIFS, IMSB(**SCON0**[2]) = 0 for LSB-first input, and IFSDLY[1:0](**SCON1**[9:8]) = 00 for no input frame sync delay.

Figure 30. SIU Active Frame and Channel Mode Input Timing Diagram

Table 49. Timing Requirements for SIU Active Frame Mode Input

Abbreviated Reference	Parameter	Min	Max	Unit
t45	SICK Bit Clock Period (high to high)	25 [†]	—	ns
t49	SID Setup Time (valid to low)	9	—	ns
t50	SID Hold Time (low to invalid)	8	—	ns

† The active clock source is programmed as either the internal clock CLK or the SCK pin, depending on the AGEXT field (**SCON12**[12]). The period of SICK is dependent on the period of the active clock source and the programming of the AGCKLIM[7:0] field (**SCON11**[7:0]). The application must ensure that the period of SICK is at least 25 ns.

Table 50. Timing Characteristics for SIU Active Frame Mode Input

Abbreviated Reference	Parameter	Min	Max	Unit
t46	SICK Bit Clock High Time (high to low)	TAGCKH [†] - 3	TAGCKH [†] + 3	ns
t47	SICK Bit Clock Low Time (low to high)	TAGCKL [†] - 3	TAGCKL [†] + 3	ns
t48	SIFS Delay (high to high)	TCKAG [†] - 5	TCKAG [†] + 5	ns

† TAGCKH and TAGCKL are dependent on the programming of the AGCKLIM[7:0] field (**SCON11**[7:0]) and the period of the active clock source. TCKAG is the period of the active clock source. The active clock source is programmed as either the internal clock CLK or the SCK pin, depending on the AGEXT field (**SCON12**[12]).

8 Timing Characteristics and Requirements (continued)

8.11 SIU (continued)

Table 51. Timing Requirements for SIU Active Channel Mode Input

Abbreviated Reference	Parameter	Min	Max	Unit
t45	SICK Bit Clock Period (high to high)	61.035 [†]	—	ns
t49	SID Setup Time (valid to low)	9	—	ns
t50	SID Hold Time (low to invalid)	8	—	ns

† The active clock source is programmed as either the internal clock CLK or the SCK pin, depending on the AGEXT field (**SCON12**[12]). The period of SICK is dependent on the period of the active clock source and the programming of the AGCKLIM[7:0] field (**SCON11**[7:0]). The application must ensure that the period of SICK is at least 61.035 ns.

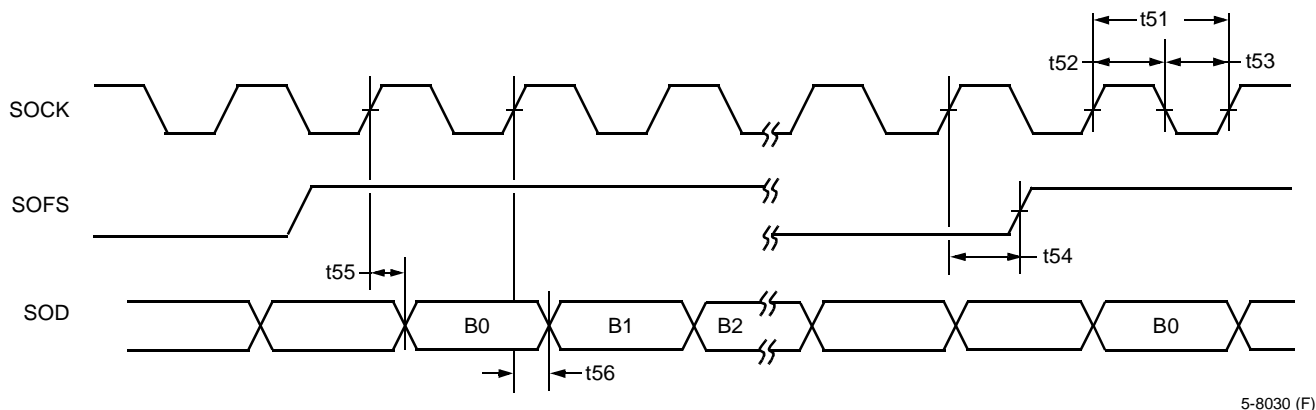
Table 52. Timing Characteristics for SIU Active Channel Mode Input

Abbreviated Reference	Parameter	Min	Max	Unit
t46	SICK Bit Clock High Time (high to low)	TAGCKH [†] – 3	TAGCKH [†] + 3	ns
t47	SICK Bit Clock Low Time (low to high)	TAGCKL [†] – 3	TAGCKL [†] + 3	ns
t48	SIFS Delay (high to high)	TCKAG [†] – 5	TCKAG [†] + 5	ns

† TAGCKH and TAGCKL are dependent on the programming of the AGCKLIM[7:0] field (**SCON11**[7:0]) and the period of the active clock source. TCKAG is the period of the active clock source. The active clock source is programmed as either the internal clock CLK or the SCK pin, depending on the AGEXT field (**SCON12**[12]).

8 Timing Characteristics and Requirements (continued)

8.11 SIU (continued)



5-8030 (F)

Note: It is assumed that the SIU is configured with $OCKA(\mathbf{SCON10}[6]) = 1$ for active mode output clock, $OCKK(\mathbf{SCON10}[7]) = 0$ for no inversion of SOCK, $OFSA(\mathbf{SCON10}[4]) = 1$ for active mode output frame sync, $OFK(\mathbf{SCON10}[5]) = 0$ for no inversion of SOFS, $OMSB(\mathbf{SCON0}[10]) = 0$ for LSB-first output, $OFRAME(\mathbf{SCON2}[7]) = 1$ for frame mode output, and $OFSDLY[1:0](\mathbf{SCON2}[9:8]) = 00$ for no output frame sync delay.

Figure 31. SIU Active Frame Mode Output Timing Diagram

Table 53. Timing Requirements for SIU Active Frame Mode Output

Abbreviated Reference	Parameter	Min	Max	Unit
t51	SOCK Bit Clock Period (high to high)	25 [†]	—	ns

[†] The active clock source is programmed as either the internal clock CLK or the SCK pin, depending on the AGEXT field ($\mathbf{SCON12}[12]$). The period of SOCK is dependent on the period of the active clock source and the programming of the AGCKLIM[7:0] field ($\mathbf{SCON11}[7:0]$). The application must ensure that the period of SOCK is at least 25 ns.

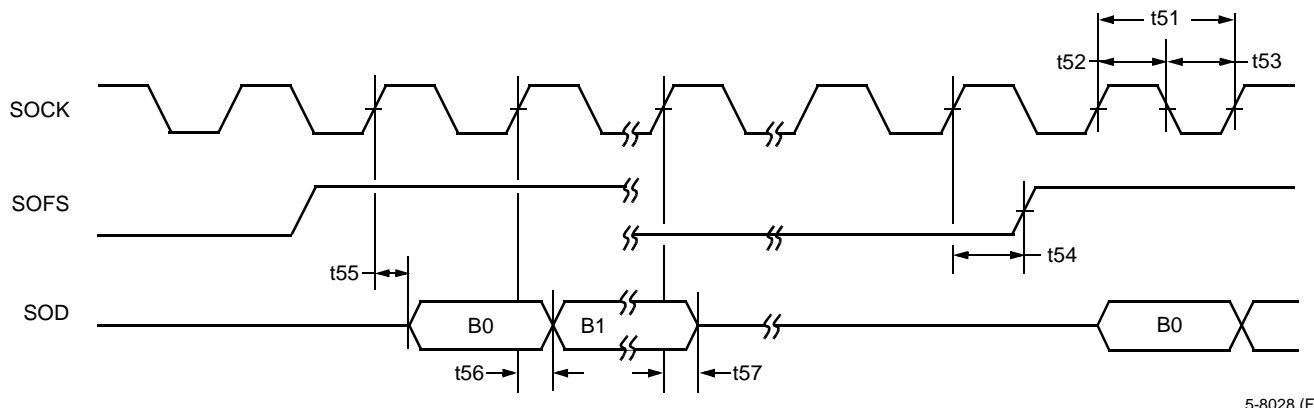
Table 54. Timing Characteristics for SIU Active Frame Mode Output

Abbreviated Reference	Parameter	Min	Max	Unit
t52	SOCK Bit Clock High Time (high to low)	$T_{AGCKH}^{\dagger} - 3$	$T_{AGCKH}^{\dagger} + 3$	ns
t53	SOCK Bit Clock Low Time (low to high)	$T_{AGCKL}^{\dagger} - 3$	$T_{AGCKL}^{\dagger} + 3$	ns
t54	SOFS Delay (high to high)	$T_{CKAG}^{\dagger} - 5$	$T_{CKAG}^{\dagger} + 5$	ns
t55	SOD Data Delay (high to valid)	0	16	ns
t56	SOD Data Hold (high to invalid)	-3	5	ns

[†] T_{AGCKH} and T_{AGCKL} are dependent on the programming of the AGCKLIM[7:0] field ($\mathbf{SCON11}[7:0]$) and the period of the active clock source. T_{CKAG} is the period of the active clock source. The active clock source is programmed as either the internal clock CLK or the SCK pin, depending on the AGEXT field ($\mathbf{SCON12}[12]$).

8 Timing Characteristics and Requirements (continued)

8.11 SIU (continued)



5-8028 (F)

Note: It is assumed that the SIU is configured with $OCKA(\mathbf{SCON10}[6]) = 1$ for active mode output clock, $OCKK(\mathbf{SCON10}[7]) = 0$ for no inversion of SOCK, $OFSA(\mathbf{SCON10}[4]) = 1$ for active mode output frame sync, $OFK(\mathbf{SCON10}[5]) = 0$ for no inversion of SOFS, $OMSB(\mathbf{SCON0}[10]) = 0$ for LSB-first output, $OFRAME(\mathbf{SCON2}[7]) = 1$ for frame mode output, and $OFSDLY[1:0](\mathbf{SCON2}[9:8]) = 00$ for no output frame sync delay.

Figure 32. SIU Active Channel Mode Output Timing Diagram

Table 55. Timing Requirements for SIU Active Channel Mode Output

Abbreviated Reference	Parameter	Min	Max	Unit
t51	SOCK Bit Clock Period (high to high)	61.035 [†]	—	ns

[†] The active clock source is programmed as either the internal clock CLK or the SCK pin, depending on the AGEXT field ($\mathbf{SCON12}[12]$). The period of SOCK is dependent on the period of the active clock source and the programming of the AGCKLIM[7:0] field ($\mathbf{SCON11}[7:0]$). The application must ensure that the period of SOCK is at least 61.035 ns.

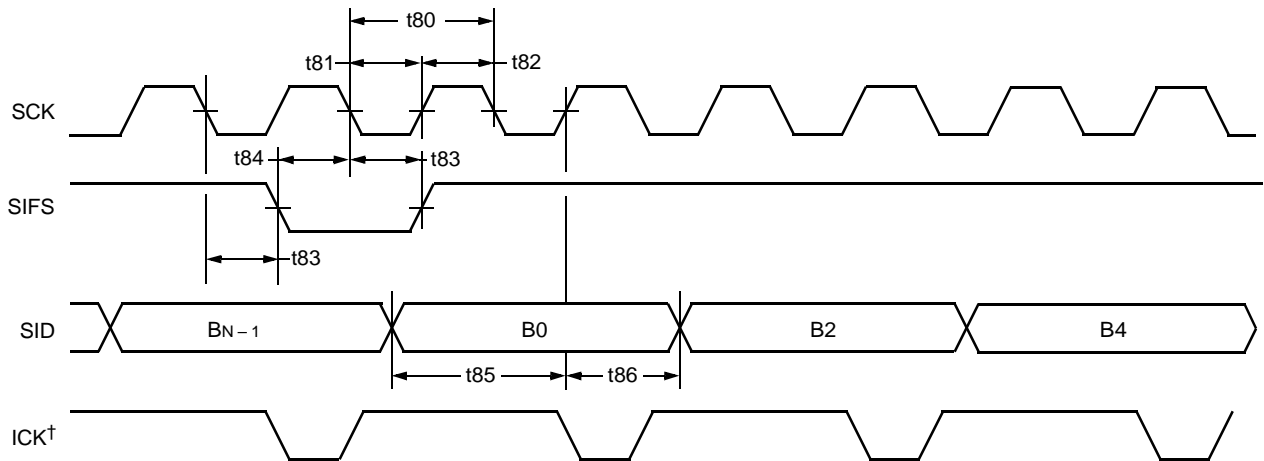
Table 56. Timing Characteristics for SIU Active Channel Mode Output

Abbreviated Reference	Parameter	Min	Max	Unit
t52	SOCK Bit Clock High Time (high to low)	$TAGCKH^{\dagger} - 3$	$TAGCKH^{\dagger} + 3$	ns
t53	SOCK Bit Clock Low Time (low to high)	$TAGCKL^{\dagger} - 3$	$TAGCKL^{\dagger} + 3$	ns
t54	SOFS Delay (high to high)	$TCKAG^{\dagger} - 5$	$TCKAG^{\dagger} + 5$	ns
t55	SOD Data Delay (high to valid)	0	16	ns
t56	SOD Data Hold (high to invalid)	-3	5	ns
t57	SOD Deactivation Delay (high to 3-state)	—	15	

[†] TAGCKH and TAGCKL are dependent on the programming of the AGCKLIM[7:0] field ($\mathbf{SCON11}[7:0]$) and the period of the active clock source. TCKAG is the period of the active clock source. The active clock source is programmed as either the internal clock CLK or the SCK pin, depending on the AGEXT field ($\mathbf{SCON12}[12]$).

8 Timing Characteristics and Requirements (continued)

8.11 SIU (continued)



† ICK is the internal active generated bit clock shown for reference purposes only.

Note: It is assumed that the SIU is configured with ICKA (**SCON10**[2]) = 1 for active mode input clock, I2XDLY (**SCON1**[11]) = 1 for extension of active input bit clock, IFSA (**SCON10**[0]) = 1 and AGSYNC (**SCON12**[14]) = 1 to configure SIFS as an input and to synchronize the active bit clocks and active frame syncs to SIFS, IFSK (**SCON10**[1]) = 1 for inversion of SIFS, IMSB (**SCON0**[2]) = 0 for LSB-first input, IFSDLY[1:0] (**SCON1**[9:8]) = 00 for no input frame sync delay, AGEXT (**SCON12**[12]) = 1 for SCK pin as active clock source, SCKK (**SCON12**[13]) = 1 for inversion of SCK, and AGCKLIM[7:0] (**SCON11**[7:0]) = 1 for an active clock divide ratio of 2.

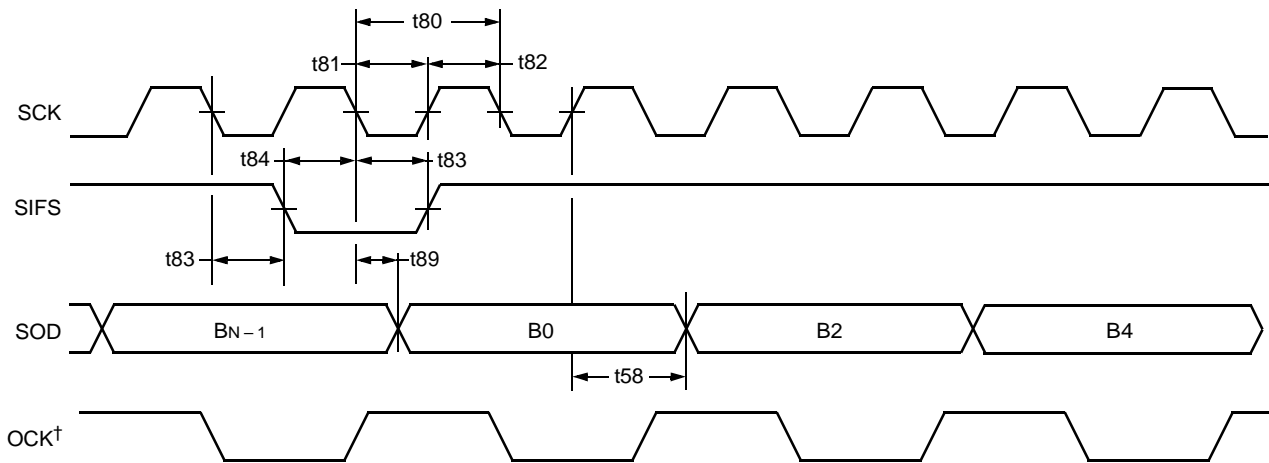
Figure 33. ST-Bus 2x Input Timing Diagram

Table 57. ST-Bus 2x Input Timing Requirements

Abbreviated Reference	Parameter	Min	Max	Unit
t80	SCK Clock Period	60	—	ns
t81	SCK Clock Low Time	30	—	ns
t82	SCK Clock High Time	30	—	ns
t83	Input Frame Sync Hold	30	—	ns
t84	Input Frame Sync Setup	20	—	ns
t85	Input Data Setup	5	—	ns
t86	Input Data Hold	20	—	ns

8 Timing Characteristics and Requirements (continued)

8.11 SIU (continued)



† OCK is the internal active generated bit clock shown for reference purposes only.

Note: It is assumed that the SIU is configured with OCKA (**SCON10**[6]) = 1 for active mode output clock, IFSA(**SCON10**[0]) = 1 and AGSYNC (**SCON12**[14]) = 1 to configure SIFS as an input and to synchronize the active bit clocks and active frame syncs to SIFS, OFSA(**SCON10**[4]) = 1 for active output frame sync, IFSK(**SCON10**[1]) = 1 for inversion of SIFS, OMSB(**SCON0**[10]) = 0 for LSB-first input, OFSDLY[1:0](**SCON2**[9:8]) = 00 for no output frame sync delay, AGEXT (**SCON12**[12]) = 1 for SCK pin as active clock source, SCKK (**SCON12**[13]) = 1 for inversion of SCK, and AGCKLIM[7:0] (**SCON11**[7:0]) = 1 for an active clock divide ratio of 2.

Figure 34. ST-Bus 2x Output Timing Diagram

Table 58. ST-Bus 2x Output Timing Requirements

Abbreviated Reference	Parameter	Min	Max	Unit
t80	SCK Clock Period	60	—	ns
t81	SCK Clock Low Time	30	—	ns
t82	SCK Clock High Time	30	—	ns
t83	Input Frame Sync Hold	30	—	ns
t84	Input Frame Sync Setup	20	—	ns

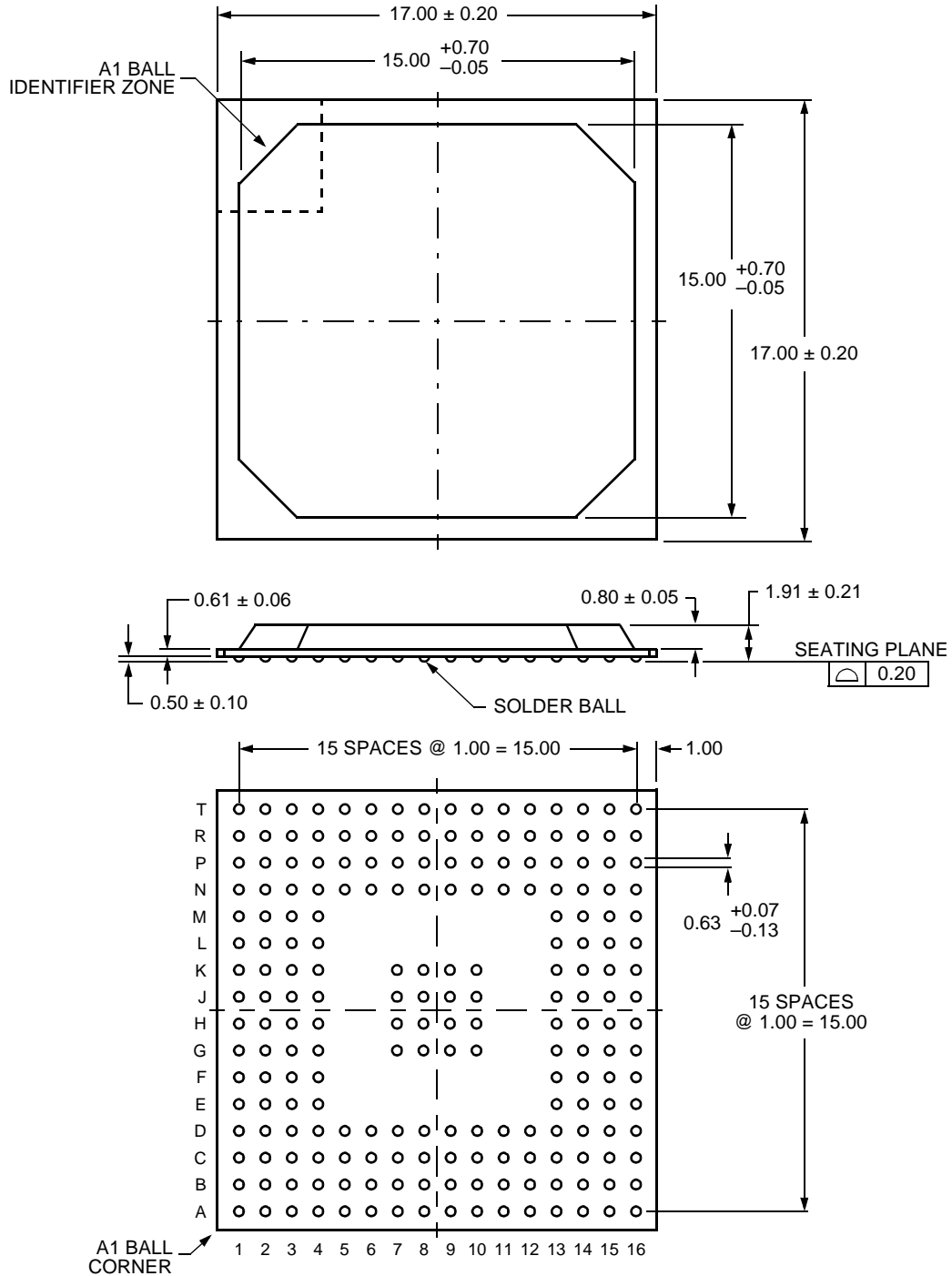
Table 59. ST-Bus 2x Output Timing Characteristics

Abbreviated Reference	Parameter	Min	Max	Unit
t89	Output Data Delay	1	25	ns
t58	Output Data Hold	0	4	ns

9 Package Diagrams

9.1 208-Pin PBGA

All dimensions are in millimeters.

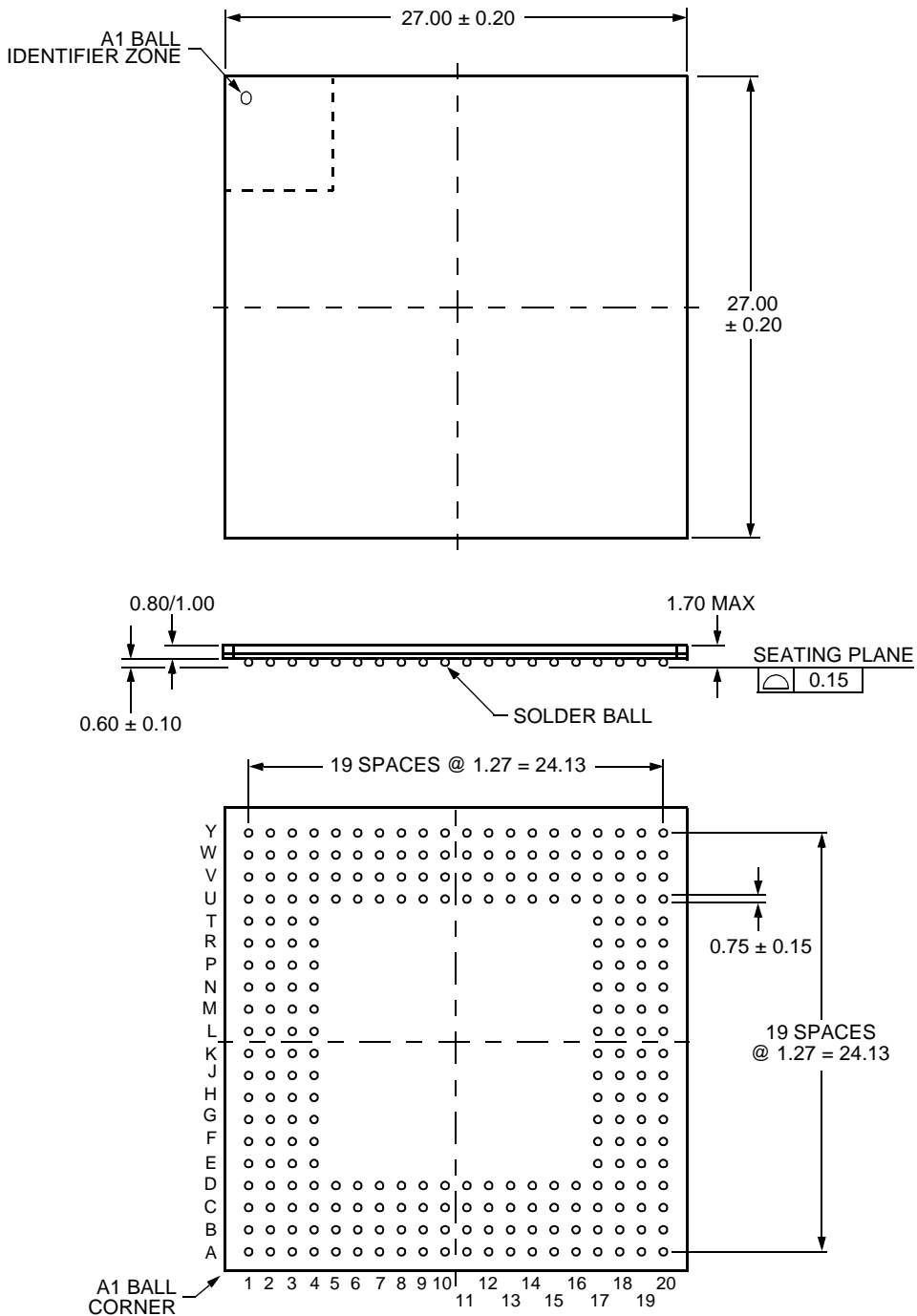


5-7809 (F).b

9 Package Diagrams (continued)

9.2 256-Pin EPGA

All dimensions are in millimeters.



5-5288 (F).a

Notes

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DSP16410B Digital Signal Processor

1 Features

- Twin DSP16000 dual-MAC cores for high throughput:
 - Up to 740 million MACs per second at 185 MHz
 - Supports 16+ channels of speech coding or modem processing
- Low power:
 - 1.8 V internal supply for power efficiency
 - 3.3 V I/O pin supply for compatibility
- 194K x 16 on-chip RAM
- Centralized direct memory access unit (DMAU):
 - Transparent peripheral-to-memory and memory-to-memory transfers
 - Better utilization of DSP MIPS
 - Simplifies management of system data flow
- 16-bit parallel interface unit (PIU) with direct memory access (DMA) provides host access to all DSP memory
- Two enhanced serial I/O units (SIU0 and SIU1) with DMA:
 - Compatible with TDM highways such as T1/E1 and ST-bus
 - Hardware support for μ -law and A-law companding
- Core messaging units (MGU0 and MGU1) for inter-processor communication
- On-chip, programmable, PLL clock synthesizer eliminates need for high-speed clock input
- Two 7-bit control I/O interfaces (BIOs) for increased flexibility and lower system costs
- 32-bit system and external memory interface (SEMI) supports 16-bit or 32-bit synchronous or asynchronous memories
- Two *IEEE*¹ 1149.1 test ports (JTAG boundary scan)
- Full-speed in-circuit emulation hardware for each core with eight address and two data watchpoint units for efficient application development
- Supported by DSP16410B software and hardware development tools
- Two ball grid array package options for small footprint:
 - 208-ball PBGA (17 mm x 17 mm; 1.0 mm ball pitch)
 - 256-ball EBGA (27 mm x 27 mm; 1.27 mm ball pitch)

2 Description

The DSP16410B is a digital signal processor (DSP) optimized for communications infrastructure applications. Large, on-chip memory enables it to be programmed to perform numerous fixed-point signal processing functions, including equalization, channel coding, compression, and speech coding. This is the first Agere wireless product to feature twin DSP16000 dual-MAC DSP cores and enhanced DMA capabilities. Together, these features deliver the performance required for second- and third-generation infrastructure equipment.

The DSP16410B achieves best-in-class signal processing performance while maintaining efficient software code density, low power consumption, and small physical size.

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3 Notation Conventions

The following notation conventions apply to this data sheet. [Table 130 on page 215](#) specifies the notation conventions for the DSP16000 instruction set.

lower-case	Registers that are directly writable or readable by DSP16410B core instructions are lower-case.
UPPER-CASE	Device flags, I/O pins, control register fields, and registers that are not directly writable or readable by DSP16410B core instructions are upper-case.
boldface	Register names and DSP16410B core instructions are printed in boldface when used in text descriptions.
<i>italics</i>	Documentation variables that are replaced are printed in italics.
courier	DSP16410B program examples or C-language representations are printed in courier font.
[]	Square brackets enclose a range of numbers that represents multiple bits in a single register or bus. The range of numbers is delimited by a colon. For example, imux [11:10] are bits 11 and 10 of the program-accessible imux register.
< >	Angle brackets enclose a list of items delimited by commas or a range of items delimited by a dash (—), one of which is selected if used in an instruction. For example, SADD <0—3> represents the four memory-mapped registers SADD0 , SADD1 , SADD2 , and SADD3 , and the general instruction aTE <h,l> = RB can be replaced with a0h = timer0 .

4 Hardware Architecture

4.1 DSP16410B Architectural Overview

The DSP16410B device is a 16-bit fixed-point programmable digital signal processor (DSP). The DSP16410B consists of two DSP16000 cores together with on-chip memory and peripherals. Advanced architectural features with an expanded instruction set deliver a dramatic increase in performance compared to traditional DSP architectures for signal coding algorithms. This increase in performance, together with an efficient design implementation, results in an extremely cost- and power-efficient solution for wireless and multimedia applications.

[Figure 1 on page 15](#) shows a block diagram of the DSP16410B.

4 Hardware Architecture (continued)

4.1 DSP16410B Architectural Overview (continued)

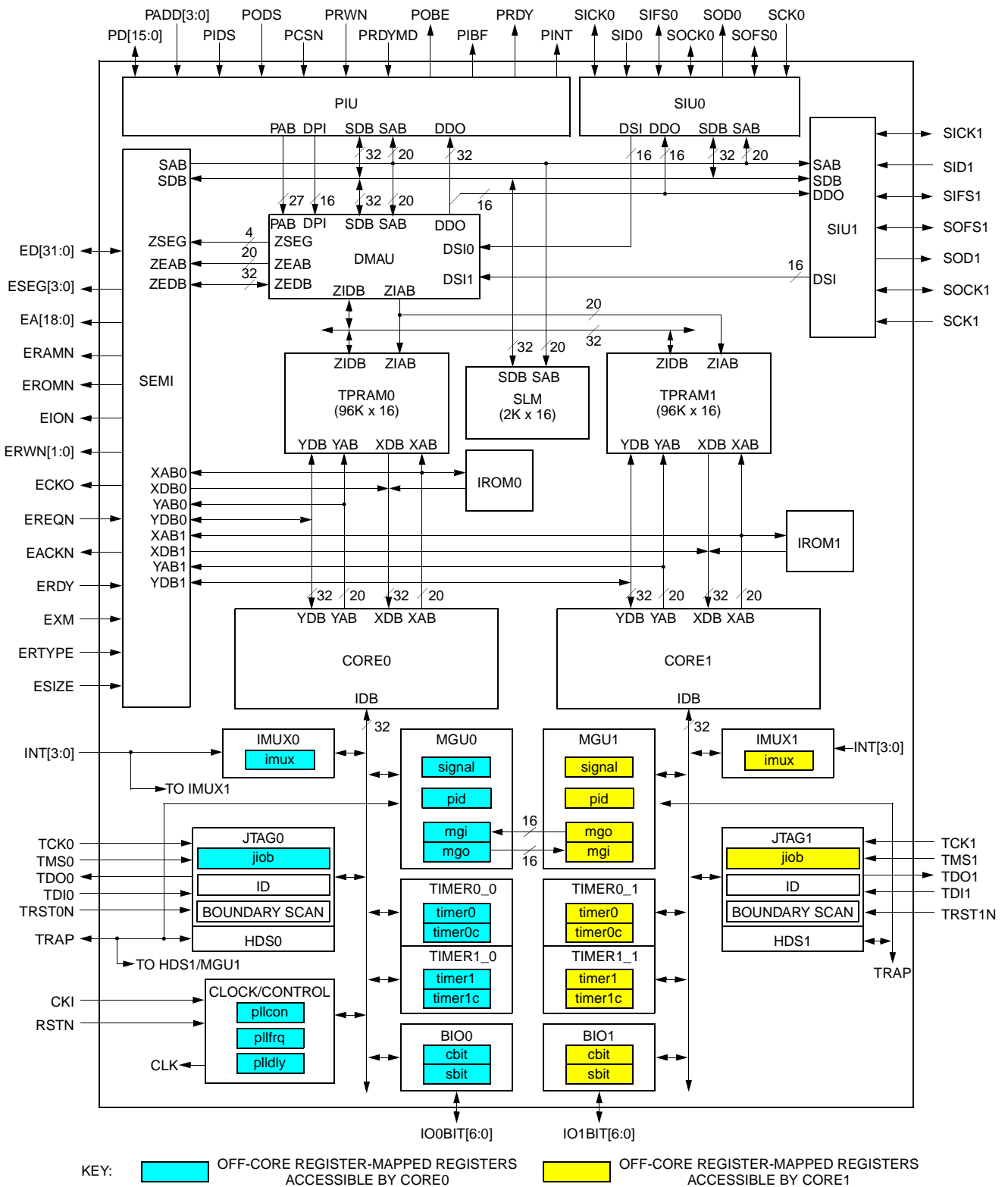


Figure 1. DSP16410B Block Diagram

4 Hardware Architecture (continued)

4.1 DSP16410B Architectural Overview (continued)

Table 1. DSP16410B Block Diagram Legend

Symbol	Description
BIO<0—1>	Bit I/O Units. One for each core.
cbit	16-Bit BIO Control Register.
CLK	Internal Clock Signal.
CORE0	DSP16000 Core—System Master.
CORE1	DSP16000 Core—System Slave.
DDO	DMA Data Out. (For transferring data from DMAU to PIU, SIU0, and SIU1.)
DMAU	Direct Memory Access Unit.
DPI	DMA Parallel In. (For transferring 16-bit data from PIU to DMAU.)
DSI0	DMA Serial Data In Zero. (For transferring data from SIU0 to DMAU.)
DSI1	DMA Serial Data In One. (For transferring data from SIU1 to DMAU.)
HDS<0—1>	Hardware Development Systems. One for each core.
ID	JTAG Port Identification Register Accessible Via the JTAG Port. One for each of the two JTAG<0—1> ports.
IDB	Internal Data Bus. One for each core.
imux	16-Bit IMUX Control Register.
IMUX<0—1>	Interrupt Multiplexers. One for each core; selects ten interrupts from DMAU, SIU0, SIU1, PIU, INT[3:0], TIMER<0—1>, and MGU.
IROM<0—1>	Internal Read-Only Memories (one for each core) for Boot and HDS Code.
jjob	32-Bit JTAG Test Register.
JTAG<0—1>	JTAG Test Ports. One for each core.
ngi	16-Bit Core-to-Core Message Input Register.
mgo	16-Bit Core-to-Core Message Output Register.
MGU<0—1>	Core-to-Core Messaging Unit. One for each core.
PAB	27-Bit Parallel Address Bus. (For DMAU/PIU communications.)
pid	16-Bit Processor ID Register (CORE0: 0x0000; CORE1: 0x0001).
PIU	Parallel Interface Unit. (16-bit parallel host interface.)
pllcon	16-Bit Phase-Lock Loop Control Register.
pllfrq	16-Bit Phase-Lock Loop Frequency Control Register.
plldly	16-Bit Phase-Lock Loop Delay Control Register.
SAB	20-Bit System Address Bus. Address for system bus (S-bus) accesses.
sbit	16-Bit BIO Status/Control Register.
SDB	32-Bit System Data Bus. Data for system bus (S-bus) accesses.
SEMI	System and External Memory Interface.
signal	16-Bit Signal Register for Core-to-Core Communication.
SIU0	Serial Input/Output Unit Zero.
SIU1	Serial Input/Output Unit One.
SLM	2 Kword Shared Local Memory.
timer0	16-Bit Timer Running Count Register for TIMER0.
TIMER0_0	Programmable Timer 0 for CORE0.
TIMER0_1	Programmable Timer 0 for CORE1.
timer0c	16-Bit Timer Control Register for TIMER0.
timer1	16-Bit Timer Running Count Register for TIMER1.
TIMER1_0	Programmable Timer 1 for CORE0.
TIMER1_1	Programmable Timer 1 for CORE1.
timer1c	16-Bit Timer Control Register for TIMER1.

4 Hardware Architecture (continued)

4.1 DSP16410B Architectural Overview (continued)

Table 1. DSP16410B Block Diagram Legend (continued)

Symbol	Description
TPRAM<0—1>	96 Kword Three-Port Random-Access Memories (one for each core). Private code (X), data (Y), and DMA (Z).
XAB<0—1>	20-Bit X-Memory Space Address Bus. One for each core.
XDB<0—1>	32-Bit X-Memory Space Data Bus. One for each core.
YAB<0—1>	20-Bit Y-Memory Space Address Bus. One for each core.
YDB<0—1>	32-Bit Y-Memory Space Data Bus. One for each core.
ZEAB	20-Bit External Z-Memory Space Address Bus. Interfaces DMAU to SEMI.
ZEDB	32-Bit External Z-Memory Space Data Bus. Interfaces DMAU to SEMI.
ZIAB	20-Bit Internal Z-Memory Space Address Bus. Interfaces DMAU to TPRAM0 and TPRAM1.
ZIDB	32-Bit Internal Z-Memory Space Data Bus. Interfaces DMAU to TPRAM0 and TPRAM1.
ZSEG	External Segment Address Bits Associated with ZEAB. Interfaces DMAU to SEMI.

4.1.1 DSP16000 Cores

The two DSP16000 cores (CORE0 and CORE1) are the signal processing engines of the DSP16410B. The DSP16000 is a modified Harvard architecture with separate sets of buses for the instruction/coefficient (X-memory) and data (Y-memory) spaces. Each set of buses has 20 bits of address and 32 bits of data. The core contains data and address arithmetic units and control for on-chip memory and peripherals.

4.1.2 Clock Synthesizer (PLL)

The DSP16410B powers up with an input clock (CKI) as the source for the processor clock (CLK). An on-chip clock synthesizer (PLL) that runs at a frequency multiple of CKI can also be used to generate CLK. The clock synthesizer is deselected and powered down on reset. The selection of the clock source is under software control of CORE0. See [Section 4.17 beginning on page 197](#) for details.

4.1.3 Triport RAMs (TPRAM<0—1>)

Each core has a private block of TPRAM consisting of 96 banks (banks 0—95) of zero wait-state memory. Each bank consists of 1K 16-bit words and has three separate address and data ports: one port to the core's instruction/coefficient (X-memory) space, a second port to the core's data (Y-memory) space, and a third port to the DMA (Z-memory) space. TPRAM0 is accessible by CORE0, TPRAM1 is accessible by CORE1, and both TPRAM0 and TPRAM1 are accessible by the DMAU. TPRAM is organized into even and odd interleaved banks for which each even/odd address pair is a 32-bit wide module (see [Section 4.6](#)

[on page 43](#) for details). The TPRAMs support single-word, aligned double-word, and misaligned double-word accesses.

4.1.4 Shared Local Memory (SLM)

The SLM consists of two banks of memory. Each bank consists of 1K 16-bit words. The SLM can be accessed by both cores and by the DMAU and PIU over the system bus (SAB, SDB). The SLM supports single-word (16-bit) and aligned double-word (32-bit) accesses. Misaligned double-word accesses are not supported. An access to the SLM takes multiple clock cycles to complete, and a core access to the SLM causes the core to incur wait-states. See [Section 4.14.7.1 on page 125](#) for details on system bus performance.

4.1.5 Internal Boot ROMs (IROM<0—1>)

Each core has its own boot ROM that contains a single boot routine and software to support the Agere hardware development system (HDS). The code in IROM0 and IROM1 are identical. See [Section 5 on page 205](#) for details.

4.1.6 Messaging Units (MGU<0—1>)

The DSP16410B provides an MGU for each core: MGU0 for CORE0 and MGU1 for CORE1. The MGUs provide interprocessor (core-to-core) communication and interrupt generation. See [Section 4.8 on page 45](#) for details.

4 Hardware Architecture (continued)

4.1 DSP16410B Architectural Overview (continued)

4.1.7 System and External Memory Interface (SEMI)

The SEMI interfaces both cores and the DMAU to external memory and I/O devices. It interfaces directly to pipelined synchronous *ZBT*¹ SRAMs and asynchronous SRAMs. The SEMI also interfaces the cores and the DMAU to the internal SLM and to memory-mapped registers in the DMAU, PIU, SIU0, and SIU1 via the internal system bus or S-bus (SAB and SDB). See [Section 4.14 beginning on page 99](#) for details.

4.1.8 Bit Input/Output Units (BIO<0—1>)

The DSP16410B provides a BIO unit for each core: BIO0 for CORE0 and BIO1 for CORE1. Each BIO unit provides convenient and efficient monitoring and control of seven individually configurable pins. If configured as outputs, the pins can be individually set, cleared, or toggled. If configured as inputs, individual pins or combinations of pins can be tested for patterns. Flags returned by the BIO can be tested by conditional instructions. See [Section 4.9 on page 49](#) for details.

4.1.9 Timer Units (TIMER0_<0—1> and TIMER1_<0—1>)

The DSP16410B provides two timer units for each core: TIMER0_0 and TIMER1_0 for CORE0 and TIMER0_1 and TIMER1_1 for CORE1. Each timer can be used to provide an interrupt, either single or repetitive, at the expiration of a programmed interval. More than nine orders of magnitude of interval selection are provided. See [Section 4.10 on page 52](#) for more information.

4.1.10 Direct Memory Access Unit (DMAU)

The direct memory access unit (DMAU) manages data transfers in the DSP16410B memory space. Data can be moved between DSP16410B memory and peripherals and between different memory spaces in the DSP16410B. Once initiated, DMAU transfers occur without core intervention. The DMAU supports concurrent core execution and I/O processing. See [Section 4.13 beginning on page 63](#) for details.

4.1.11 Interrupt Multiplexers (IMUX<0—1>)

The DSP16410B provides an interrupt multiplexer unit for each core: IMUX0 for CORE0 and IMUX1 for CORE1. Each IMUX multiplexes the 26 hardware interrupts into the 20 available hardware interrupt requests for each core. See [Section 4.4.2 on page 28](#) for details.

4.1.12 Parallel Interface Unit (PIU)

The parallel interface unit (PIU) is a 16-bit parallel port that provides a host processor direct access to the entire DSP16410B memory system (including memory-mapped peripheral registers). See [Section 4.15 beginning on page 132](#) for details.

4.1.13 Serial Interface Units (SIU<0—1>)

The DSP16410B provides two identical SIUs. Each SIU is a full-duplex, double-buffered serial port with independent input and output frame and bit clock control. Clock and frame signals can be generated externally (passive) or by on-chip clock and frame generation hardware (active). The SIU features multiple-channel TDM mode for ST-bus (1x and 2x compatible) and T1/E1 compatibility. Each SIU is provided a DMAU interface for data transfer to memory (TPRAM0, TPRAM1, SLM, memory-mapped registers, or external memory) without core intervention. See [Section 4.16 beginning on page 151](#) for details.

4.1.14 Test Access Ports (JTAG<0—1>)

The DSP16410B provides a JTAG unit for each core: JTAG0 for CORE0 and JTAG1 for CORE1. See [Section 4.12 on page 56](#) for details.

4.1.15 Hardware Development Systems (HDS<0—1>)

The DSP16410B provides an HDS unit for each core: HDS0 for CORE0 and HDS1 for CORE1. Each HDS is an on-chip hardware module available for debugging assembly-language programs that execute on the DSP16000 core in real-time. The main capability of the HDS is in allowing controlled visibility into the core's state during program execution. The HDS is enhanced with powerful debugging capabilities such as complex breakpointing conditions, multiple data/address watchpoint registers, and an intelligent trace mechanism for recording discontinuities. See [Section 4.11 on page 55](#) for details.

1. *ZBT* and *Zero Bus Turnaround* are trademarks of Integrated Device Technology, Inc., and the architecture is supported by Micron Technology, Inc., and Motorola, Inc.

4 Hardware Architecture (continued)

4.2 DSP16000 Core Architectural Overview

The DSP16410B contains two identical DSP16000 cores. As shown in [Figure 2 on page 21](#), each core consists of four major blocks: system control and cache (SYS), data arithmetic unit (DAU), Y-memory space address arithmetic unit (YAAU), and X-memory space address arithmetic unit (XAAU). Bits within the **auc0** and **auc1** registers configure the DAU mode-controlled operations. See the *DSP16000 Digital Signal Processor Core Information Manual* for a complete description of the DSP16000 core.

4.2.1 System Control and Cache (SYS)

This section consists of the control block and the cache.

The control block provides overall system coordination that is mostly invisible to the user. The control block includes an instruction decoder and sequencer, a pseudorandom sequence generator (PSG), an interrupt and trap handler, a wait-state generator, and low-power standby mode control logic. An interrupt and trap handler provides a user-locatable vector table and three levels of user-assigned interrupt priority.

SYS contains the **alf** register, which is a 16-bit register that contains AWAIT, a power-saving standby mode bit, and peripheral flags. The **inc0** and **inc1** registers are 20-bit interrupt control registers, and **ins** is a 20-bit interrupt status register.

Programs use the instruction cache to store and execute repetitive operations such as those found in an FIR or IIR filter section. The cache can contain up to 31 16-bit and 32-bit instructions. The code in the cache can repeat up to $2^{16} - 1$ times without looping overhead. Operations in the cache that require a coefficient access execute at twice the normal rate because the XAAU and its associated bus are not needed for fetching instructions. The cache greatly reduces the need for writing in-line repetitive code and, therefore, reduces instruction/coefficient memory size requirements. In addition, the use of cache reduces power consumption because it eliminates memory accesses for instruction fetches.

The cache provides a convenient, low-overhead looping structure that is interruptible, savable, and restorable. The cache is addressable in both the X and Y memory spaces. An interrupt or trap handling routine can save and restore **clloop**, **cstate**, **csave**, and the contents of the cache. The **clloop** register controls the cache loop count. The **cstate** register contains the cur-

rent state of the cache. The 32-bit **csave** register holds the opcode of the instruction following the loop instruction in program memory.

4.2.2 Data Arithmetic Unit (DAU)

The DAU is a power-efficient, dual-MAC (multiply/accumulate) parallel-pipelined structure that is tailored to communications applications. It can perform two double-word (32-bit) fetches, two multiplications, and two accumulations in a single instruction cycle. The dual-MAC parallel pipeline begins with two 32-bit registers, **x** and **y**. The pipeline treats the 32-bit registers as four 16-bit signed registers if used as input to two signed 16-bit x 16-bit multipliers. Each multiplier produces a full 32-bit result stored into registers **p0** and **p1**. The DAU can direct the output of each multiplier to a 40-bit ALU or a 40-bit 3-input ADDER. The ALU and ADDER results are each stored in one of eight 40-bit accumulators, **a0** through **a7**. Both the ALU and ADDER include an ACS (add/compare/select) function for Viterbi decoding. The DAU can direct the output of each accumulator to the ALU/ACS, the ADDER/ACS, or a 40-bit BMU (bit manipulation unit).

The ALU implements 2-input addition, subtraction, and various logical operations. The ADDER implements 2-input or 3-input addition and subtraction. To support Viterbi decoding, the ALU and ADDER have a split mode in which two simultaneous 16-bit additions or subtractions are performed. This mode, available in specialized dual-MAC instructions, is used to compute the distance between a received symbol and its estimate.

The ACS provides the add/compare/select function required for Viterbi decoding. This unit provides flags to the traceback encoder for implementing mode-controlled side-effects for ACS operations. The source operands for the ACS are any two accumulators, and results are written back to one of the source accumulators.

The BMU implements barrel-shift, bit-field insertion, bit-field extraction, exponent extraction, normalization, and accumulator shuffling operations. **ar0** through **ar3** are auxiliary registers whose main function is to control BMU operations.

The user can enable overflow saturation to affect the multiplier output and the results of the three arithmetic units. Overflow saturation can also affect an accumulator value as it is transferred to memory or other register. These features accommodate various speech coding standards such as GSM-FR, GSM-HR, and GSM-EFR. Shifting in the arithmetic pipeline occurs at several stages to accommodate various standards for mixed- and double-precision multiplications.

4 Hardware Architecture (continued)

4.2 DSP16000 Core Architectural Overview (continued)

4.2.2 Data Arithmetic Unit (DAU) (continued)

The DAU contains control and status registers **auc0**, **auc1**, **psw0**, **psw1**, **vsw**, and **c0—c2**.

The arithmetic unit control registers **auc0** and **auc1** select or deselect various modes of DAU operation. These modes include scaling of products, saturation on overflow, feedback to the **x** and **y** registers from accumulators **a6** and **a7**, simultaneous loading of **x** and **y** registers with the same value (used for single-cycle squaring), and clearing the low half of registers when loading the high half to facilitate fixed-point operations.

The processor status word registers **psw0** and **psw1** contain flags set by ALU/ACS, ADDER, or BMU operations. They also include information on the current status of the interrupt controller.

The **vsw** register is the Viterbi support word associated with the traceback encoder. The traceback encoder is a specialized block for accelerating Viterbi decoding. The **vsw** controls side-effects for three compare functions: **cmp0()**, **cmp1()**, and **cmp2()**. These instructions are part of the MAC group that utilizes the traceback encoder. The side-effects allow the DAU to store, with no overhead, state information necessary for traceback decoding. Side-effects use the **c1** counter, the **ar0** and **ar1** auxiliary registers, and bits 1 and 0 of **vsw**.

The **c1** and **c0** counters are 16-bit signed registers used to count events such as the number of times the program has executed a sequence of code. The **c2** register is a holding register for counter **c1**. Conditional instructions control these counters and provide a convenient method of program looping.

4.2.3 Y-Memory Space Address Arithmetic Unit (YAAU)

The YAAU supports high-speed, register-indirect, data memory addressing with postincrement of the address register. Eight 20-bit pointer registers (**r0—r7**) store read or write addresses for the data (Y-memory) space. Two sets of 20-bit registers (**rb0** and **re0**; **rb1** and **re1**) define the upper and lower boundaries of two zero-overhead circular buffers for efficient filter implementations. The **j** and **k** registers are two 20-bit signed registers that are used to hold user-defined postincrement values for **r0—r7**. Fixed increments of +1, -1, 0, +2, and -2 are also available. (Postincrement options 0 and -2 are not available for some specialized transfers. See

the *DSP16000 Digital Signal Processor Core Information Manual* for details.)

The YAAU includes a 20-bit stack pointer (**sp**). The data move group includes a set of stack instructions that consists of push, pop, stack-relative, and pipelined stack-relative operations. The addressing mode used for the stack-relative instructions is register-plus-displacement indirect addressing (the displacement is optional). The displacement is specified as either an immediate value as part of the instruction or a value stored in **j** or **k**. The YAAU computes the address by adding the displacement to **sp** and leaves the contents of **sp** unchanged. The data move group also includes instructions with register-plus-displacement indirect addressing for the pointer registers **r0—r6** in addition to **sp**.

The data move group of instructions includes instructions for loading and storing any YAAU register from or to memory or another core register. It also includes instructions for loading any YAAU register with an immediate value stored with the instruction. The pointer arithmetic group of instructions allows adding of an immediate value or the contents of the **j** or **k** register to any YAAU pointer register and storing the result to any YAAU register.

4.2.4 X-Memory Space Address Arithmetic Unit (XAAU)

The XAAU contains registers and an adder that control the sequencing of instructions in the processor. The program counter (**PC**) automatically increments through the instruction space. The interrupt return register **pi**, the subroutine return register **pr**, and the trap return register **ptrap** are automatically loaded with the return address of an interrupt service routine, subroutine, and trap service routine, respectively. High-speed, register-indirect, read-only memory addressing with postincrementing is done with the **pt0** and **pt1** registers. The signed registers **h** and **i** are used to hold a user-defined signed postincrement value. Fixed postincrement values of 0, +1, -1, +2, and -2 are also available. (Postincrement options 0 and -2 are available only if the target of the data transfer is an accumulator. See the *DSP16000 Digital Signal Processor Core Information Manual* for details.)

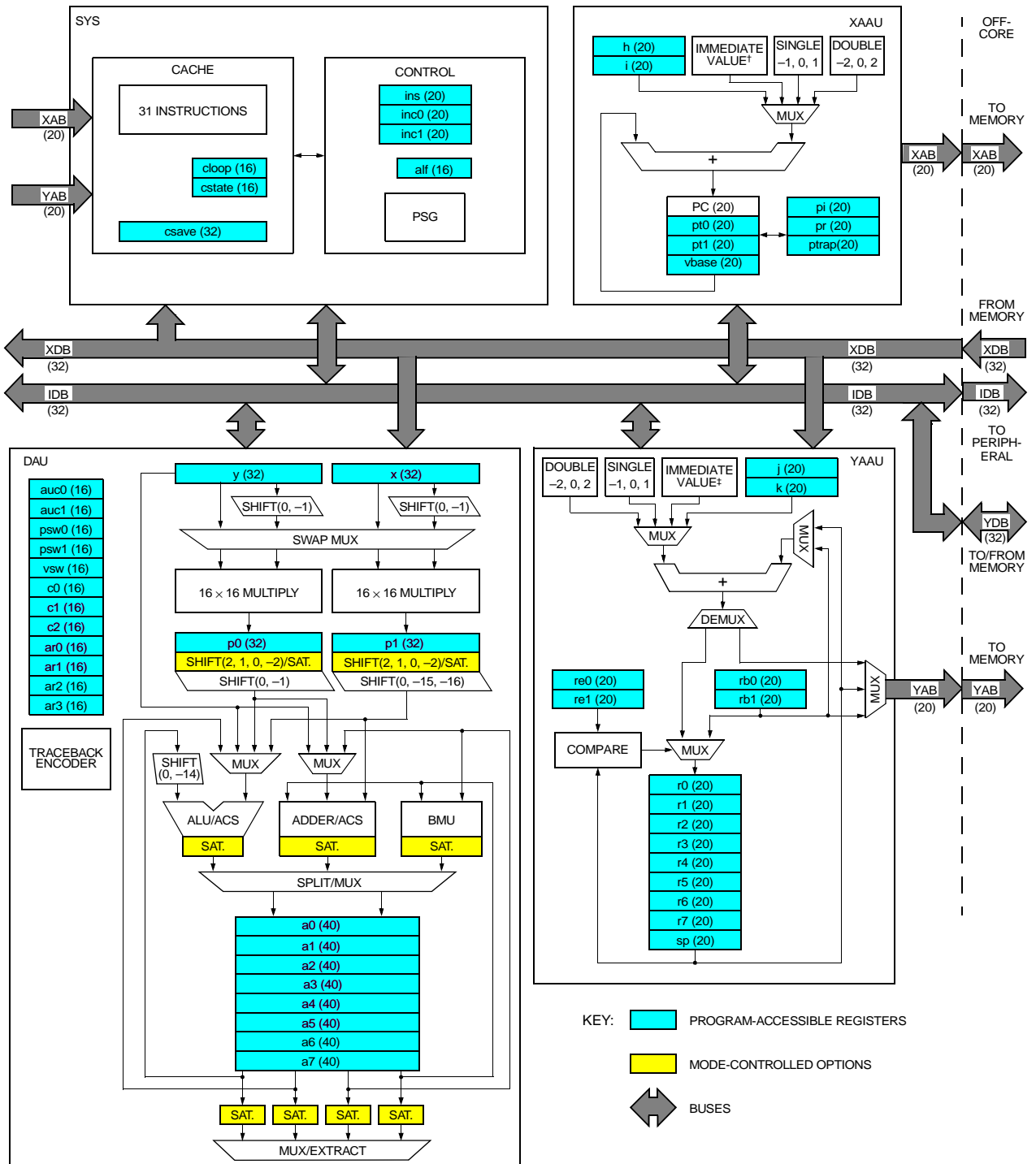
The data move group includes instructions for loading and storing any XAAU register from or to memory or another core register. It also includes instructions for loading any XAAU register with an immediate value stored with the instruction.

vbase is the 20-bit vector base offset register. The user programs this register with the base address of the interrupt and trap vector table.

4 Hardware Architecture (continued)

4.2 DSP16000 Core Architectural Overview (continued)

4.2.5 Core Block Diagram



† Associated with PC-relative branch addressing.

‡ Associated with register-plus-displacement indirect addressing.

Figure 2. DSP16000 Core Block Diagram

4 Hardware Architecture (continued)

4.2 DSP16000 Core Architectural Overview (continued)

4.2.5 Core Block Diagram (continued)

Table 2. DSP16000 Core Block Diagram Legend

Symbol	Name
16 x 16 MULTIPLY	16-Bit x 16-Bit Multiplier.
a0—a7	40-Bit Accumulators 0—7.
ADDER/ACS	3-Input 40-Bit Adder/Subtractor and Add/Compare/Select Function. Used in Viterbi decoding.
alf	16-Bit AWAIT Low-Power and Flags Register.
ALU/ACS	40-Bit Arithmetic Logic Unit and Add/Compare/Select Function. Used in Viterbi decoding.
ar0—ar3	16-Bit Auxiliary Registers 0—3.
auc0, auc1	16-Bit Arithmetic Unit Control Registers.
BMU	40-Bit Manipulation Unit.
c0, c1	16-Bit Counters 0 and 1.
c2	16-Bit Counter Holding Register.
cloop	16-Bit Cache Loop Count Register.
COMPARE	Comparator. Used for circular buffer addressing.
csave	32-Bit Cache Save Register.
cstate	16-Bit Cache State Register.
DAU	Data Arithmetic Unit.
h	20-Bit Pointer Postincrement Register for the X-Memory Space.
i	20-Bit Pointer Postincrement Register for the X-Memory Space.
IDB	32-Bit Internal Data Bus.
inc0, inc1	20-Bit Interrupt Control Registers 0 and 1.
ins	20-Bit Interrupt Status Register.
j	20-Bit Pointer Postincrement/Offset Register for the Y-Memory Space.
k	20-Bit Pointer Postincrement/Offset Register for the Y-Memory Space.
MUX	Multiplexer.
p0, p1	32-Bit Product Registers 0 and 1.
PC	20-Bit Program Counter.
pi	20-Bit Program Interrupt Return Register.
pr	20-Bit Program Return Register.
PSG	Pseudorandom Sequence Generator.
psw0, psw1	16-Bit Processor Status Word Registers 0 and 1.
pt0, pt1	20-Bit Pointers 0 and 1 to X-Memory Space.
ptrap	20-Bit Program Trap Return Register.
r0—r7	20-Bit Pointers 0—7 to Y-Memory Space.
rb0, rb1	20-Bit Circular Buffer Pointers 0 and 1 (begin address).
re0, re1	20-Bit Circular Buffer Pointers 0 and 1 (end address).
SAT	Saturation.
SHIFT	Shifting Operation.
sp	20-Bit Stack Pointer.
SPLIT/MUX	Split/Multiplexer. Routes the appropriate ALU/ACS, BMU, and ADDER/ACS outputs to the appropriate accumulator.
SWAP MUX	Swap Multiplexer. Routes the appropriate data to the appropriate multiplier input.
SYS	System Control and Cache.
vbase	20-Bit Vector Base Offset Register.
vsw	16-Bit Viterbi Support Word. Associated with the traceback encoder.

4 Hardware Architecture (continued)

4.2 DSP16000 Core Architectural Overview (continued)

4.2.5 Core Block Diagram (continued)

Table 2. DSP16000 Core Block Diagram Legend (continued)

Symbol	Name
x	32-Bit Multiplier Input Register.
XAAU	X-Memory Space Address Arithmetic Unit.
XAB	X-Memory Space Address Bus.
XDB	X-Memory Space Data Bus.
y	32-Bit Multiplier Input Register.
YAAU	Y-Memory Space Address Arithmetic Unit.
YAB	Y-Memory Space Address Bus.
YDB	Y-Memory Space Data Bus.

4.3 Device Reset

The DSP16410B has three negative-assertion external reset input pins: RSTN, TRST0N, and TRST1N. RSTN is used to reset both CORE0 and CORE1. The primary function of TRST0N and TRST1N is to reset the JTAG0 and JTAG1 controllers.

4.3.1 Reset After Powerup or Power Interruption

At initial powerup or if power is interrupted, a reset is required and RSTN, TRST0N, and TRST1N must all be asserted (low) simultaneously for at least seven CKI cycles (see [Section 11.4 on page 280](#) for details). The TRST0N and TRST1N pins must be asserted even if the JTAG controllers are not used by the application. Failure to properly reset the device on powerup or after a power interruption can lead to a loss of communication with the DSP16410B pins.

4.3.2 RSTN Pin Reset

The device is properly reset by asserting RSTN (low) for at least seven CKI cycles and then deasserting RSTN. Reset initializes the state of user registers, synchronizes the internal clocks, and initiates code execution. See [Section 6.2.4 beginning on page 246](#) for the values of the user registers after reset.

After RSTN is deasserted, there is a delay of several CKI cycles before the DSP16000 cores begin executing instructions (see [Section 11.5 on page 281](#) for details). The state of the EXM pin on the rising edge of RSTN controls the boot program address for both cores, as described in [Section 5 on page 205](#).

4 Hardware Architecture (continued)

4.3 Device Reset (continued)

4.3.2 RSTN Pin Reset (continued)

Table 3 defines the states of the output and bidirectional pins both during and after reset. It does not include the TDO0 and TDO1 output pins because their state is not affected by RSTN. The state of TDO0 and TDO1 are affected only by the JTAG0 and JTAG1 controllers.

Table 3. State of Device Output and Bidirectional Pins During and After Reset

Type	Pin	Condition	State of Pin During Reset (RSTN = 0)	Initial State of Pin After Reset (RSTN = 1)
Output	PIBF, PINT, PRDY	—	3-state	logic low
	EACKN, EION, ERAMN, EROMN, ERWN0, ERWN1	INT0 = 0 (deasserted)	logic high	initial inactive state
		INT0 = 1 (asserted)	3-state	
	POBE	—	3-state	logic high
	SOD0, SOD1	—	3-state	3-state
	ECKO	INT0 = 0 (deasserted)	logic low	CKI/2
		INT0 = 1 (asserted)	3-state	
	EA[18:0]	INT0 = 0 (deasserted)	logic low	initial inactive state
		INT0 = 1 (asserted)	3-state	
	ESEG[3:0]	INT0 = 0 (deasserted)	logic low	logic low
		INT0 = 1 (asserted)	3-state	
	Bidirectional (Input/Output)	IO0BIT[6:0], IO1BIT[6:0], PD[15:0], SICK0, SICK1, SIFS0, SIFS1, SOCK0, SOCK1, SOFS0, SOFS1, TRAP	—	3-state
EYMODE = 0			3-state	3-state
ED[31:0]		EYMODE = 1	output	output

4.3.3 JTAG Controller Reset

The recommended method of resetting the JTAG controllers is to assert RSTN, TRST0N, and TRST1N low simultaneously. An alternate method is to clock TCK<0,1> through at least five cycles with TMS<0,1> held high. Both methods ensure that the user has control of the device pins. JTAG controller reset places it in the test logic reset (TLR) state and does not initialize user registers, synchronize internal clocks, or initiate code execution unless RSTN is also asserted (see Section 6.2.4 on page 246).

4 Hardware Architecture (continued)

4.4 Interrupts and Traps

Each core in the DSP16410B supports the following interrupts and traps:

- 26 hardware interrupts with three levels of user-assigned priority:
 - 1 core-to-core interrupt.
 - 10 general DMAU interrupts.
 - 1 DMAU interrupt under control of the other core.
 - 4 SIU interrupts.
 - 3 PIU interrupts.
 - 1 MGU interrupt.
 - 2 timer interrupts.
 - 4 external interrupt pins.
- 64 software interrupts for each core, generated by the execution of an **icall IM6** instruction.
- The TRAP pin.
- The core-to-core trap.

Because the DSP16000 core supports a maximum of 20 hardware interrupts and the DSP16410B provides 26 hardware interrupts, each core has an associated programmable interrupt multiplexer (IMUX<0,1>).

The interrupt and trap vectors are in contiguous locations in memory, and the base (starting) address of the vectors is configurable in the core's **vbase** register. Each interrupt and trap source is preassigned to a unique vector offset that differentiates its service routine.

The core must reach an interruptible or trappable state (completion of an interruptible or trappable instruction) before it services an interrupt or trap. If the core services an interrupt or trap, it saves the contents of its program counter (**PC**) and begins executing instructions at the corresponding location in its vector table. For interrupts, the core saves its **PC** in its program interrupt (**pi**) register. For traps, the core saves its **PC** in its program trap (**ptrap**) register. After servicing the interrupt or trap, the servicing routine must return to the interrupted or trapped program by executing an **ireturn** or **return** instruction.

The core's **ins** register (see [Table 8 on page 32](#)) contains a 1-bit status field for each of its hardware interrupts. If a hardware interrupt occurs, the core sets the corresponding **ins** field to indicate that the interrupt is pending. If the core services that interrupt, it clears the corresponding **ins** field. The **psw1** register (see [Table 10 on page 35](#)) includes control and status bits for the core's hardware interrupt logic.

If a hardware interrupt is disabled, the core does not service it. If a hardware interrupt is enabled, the core services it according to its priority. Device reset globally disables hardware interrupts. An application can globally¹ enable or disable hardware interrupts and can individually enable or disable each hardware interrupt. An application globally enables hardware interrupts by executing the **ei** (enable interrupts) instruction and globally disables them by executing the **di** (disable interrupts) instruction. An application can individually enable a hardware interrupt at an assigned priority or individually disable a hardware interrupt by configuring the **inc0** or **inc1** register (see [Table 7 on page 31](#)).

Software interrupts emulate hardware interrupts for the purpose of software testing. The core services software interrupts even if hardware interrupts are globally disabled.

A trap is similar to an interrupt but has the highest possible priority. An application cannot disable traps by executing a **di** instruction or by any other means. Traps do not nest, i.e., a trap service routine (TSR) cannot be interrupted or trapped. A trap does not affect the state of the **psw1** register.

The *DSP16000 Digital Signal Processor Core Information Manual* provides an extensive discussion of interrupts and traps. The remainder of this section describes the interrupts and traps for the DSP16410B.

4.4.1 Hardware Interrupt Logic

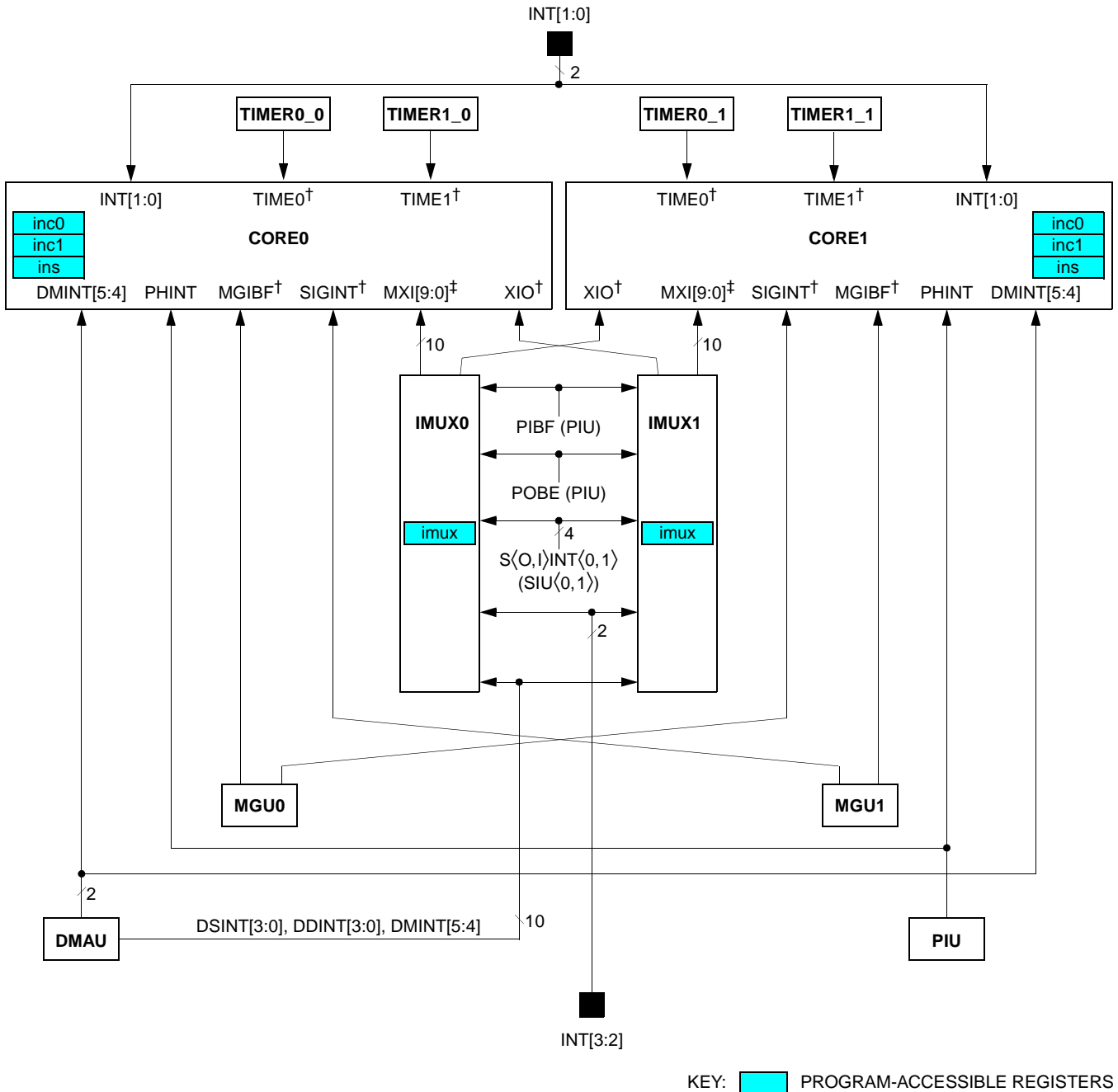
[Figure 3 on page 26](#) illustrates the path of each interrupt from its generating peripheral or pin to the interrupt logic of CORE0 and CORE1. Some of the interrupts connect directly to the cores, and others connect via the IMUX<0,1> block. Some of the interrupts are specific to a core, and some are common to both cores. The programmer can configure IMUX<0,1> using the corresponding **imux** register. The programmer can divide processing of the multiplexed interrupts PIBF, POBE, S<0,1>INT<0,1>, DSINT[3:0], DDINT[3:0], DMINT[5:4], INT[3:2] between CORE0 and CORE1 or cause some of these interrupts to be common to both cores by defining the fields in each core's **imux** register. See [Section 4.4.2 on page 28](#) for details on interrupt multiplexing.

1. A program that runs on one core disables and enables its interrupts independent of the other core.

4 Hardware Architecture (continued)

4.4 Interrupts and Traps (continued)

4.4.1 Hardware Interrupt Logic (continued)



† These interrupts are specific to a core, not common to both cores.

‡ Each of the MXI[9:0] interrupts can be either specific to a core or common to both cores determined by how each interrupt is configured in *imux* (see Table 5 on page 28).

Figure 3. CORE0 and CORE1 Interrupt Logic Block Diagram

4 Hardware Architecture (continued)

4.4 Interrupts and Traps (continued)

4.4.1 Hardware Interrupt Logic (continued)

Table 4 summarizes each hardware interrupt in the DSP16410B, including whether it is internal or external, which module generates it, and a brief description. For details on the operation of each internal interrupt, see the section that describes the corresponding block.

Table 4. Hardware Interrupts

Interrupt	Type	Name	Description
DSINT0	Internal	DMAU Source Interrupt for SWT0 (for SIU0)	Channel SWT0 [†] source (output) interrupt request.
DDINT0	Internal	DMAU Destination Interrupt for SWT0 (for SIU0)	Channel SWT0 [†] destination (input) interrupt request.
DSINT1	Internal	DMAU Source Interrupt for SWT1 (for SIU0)	Channel SWT1 [†] source (output) interrupt request.
DDINT1	Internal	DMAU Destination Interrupt for SWT1 (for SIU0)	Channel SWT1 [†] destination (input) interrupt request.
DSINT2	Internal	DMAU Source Interrupt for SWT2 (for SIU1)	Channel SWT2 [†] source (output) interrupt request.
DDINT2	Internal	DMAU Destination Interrupt for SWT2 (for SIU1)	Channel SWT2 [†] destination (input) interrupt request.
DSINT3	Internal	DMAU Source Interrupt for SWT3 (for SIU1)	Channel SWT3 [†] source (output) interrupt request.
DDINT3	Internal	DMAU Destination Interrupt for SWT3 (for SIU1)	Channel SWT3 [†] destination (input) interrupt request.
DMINT4	Internal	DMAU Interrupt for MMT4	Channel MMT4 [‡] interrupt request.
DMINT5	Internal	DMAU Interrupt for MMT5	Channel MMT5 [‡] interrupt request.
INT[3:0]	External	External Interrupt Requests	An external device has requested service by asserting the corresponding INT[3:0] pin (0-to-1 transition).
MGIBF	Internal	MGU Input Buffer Full	The MGU input buffer (mg i) is full.
PHINT	Internal	PIU Host Interrupt	The host sets the HINT field (PCON [4]).
PIBF	Internal	PIU Input Buffer Full	PDI contains data from a previous host write operation.
POBE	Internal	PIU Output Buffer Empty	The data in PDO has been read by the host.
SIGINT	Internal	Signal Interrupt (Core-to-Core)	The other core sets its signal [0] field.
SIINT0	Internal	SIU0 Input Interrupt	Based on the IINTSEL[1:0] field (SCON10 [12:11]), asserted if: <ul style="list-style-type: none"> ■ Input frame sync detected.
SIINT1	Internal	SIU1 Input Interrupt	<ul style="list-style-type: none"> ■ Input subframe transfer complete. ■ Input channel transfer complete. ■ Input error occurs.
SOINT0	Internal	SIU0 Output Interrupt	Based on the OINTSEL[1:0] field (SCON10 [14:13]): <ul style="list-style-type: none"> ■ Output frame sync detected.
SOINT1	Internal	SIU1 Output Interrupt	<ul style="list-style-type: none"> ■ Output subframe transfer complete. ■ Output channel transfer complete. ■ Output error occurs.
TIME0	Internal	TIMER0 Delay/Interval Reached	TIMER0 has reached zero count.
TIME1	Internal	TIMER1 Delay/Interval Reached	TIMER1 has reached zero count.
XIO	Internal	Core-to-Core DMAU Interrupt	Based on the other core's XIOC[1:0] field: <ul style="list-style-type: none"> ■ Zero (logic low). ■ DMINT4 (MMT4 transfer complete). ■ DMINT5 (MMT5 transfer complete).

[†] An SWT channel is a single-word transfer channel used for both input and output by an SIU. It transfers single words (16 bits).

[‡] An MMT channel is a memory-to-memory channel used by the cores to copy a block from any area of memory to any other area of memory. It transfers single words (16 bits) or double words (32 bits).

4 Hardware Architecture (continued)

4.4 Interrupts and Traps (continued)

4.4.2 Hardware Interrupt Multiplexing

The total number of DSP16410B hardware interrupt sources (26) exceeds the number of interrupt requests supported by the DSP16000 core (20). Therefore, each core includes an interrupt multiplexer block (IMUX) and associated control register (**imux**) to permit the 26 interrupts to be multiplexed into the 20 available hardware interrupt requests. Each core supports ten dedicated interrupt requests. Each core's IMUX block multiplexes the remaining 16 hardware requests into the ten remaining hardware interrupt request lines.

Table 5 describes the **imux** register and Figure 4 on page 29 illustrates the IMUX block.

Table 5. **imux** (Interrupt Multiplex Control) Register

15—14		13—12		11—10		9—8		7	6	5	4	3	2	1	0
XIOC[1:0]		Reserved		IMUX9[1:0]		IMUX8[1:0]		IMUX7	IMUX6	IMUX5	IMUX4	IMUX3	IMUX2	IMUX1	IMUX0
Bit	Field	Controls Multiplexed Interrupt	Value	Interrupt Selected	Description	R/W	Reset Value								
15—14	XIOC[1:0]	XIO	00	0 (logic low)	—	R/W	00								
			01	DMINT4	DMAU interrupt for MMT4.										
			10	DMINT5	DMAU interrupt for MMT5.										
			11	Reserved	Reserved.										
13—12	Reserved	—	0	—	Reserved—write with zero.	R/W	0								
11—10	IMUX9[1:0]	MXI9	00	INT3	Pin.	R/W	00								
			01	POBE	PIU output buffer empty.										
			10	PIBF	PIU input buffer full.										
			11	Reserved	Reserved.										
9—8	IMUX8[1:0]	MXI8	00	INT2	Pin.	R/W	00								
			01	POBE	PIU output buffer empty.										
			10	PIBF	PIU input buffer full.										
			11	Reserved	Reserved.										
7	IMUX7	MXI7	0	SIINT1	SIU1 input interrupt.	R/W	0								
			1	DDINT2	DMAU destination interrupt for SWT2 (SIU1).										
6	IMUX6	MXI6	0	SOINT1	SIU1 output interrupt.	R/W	0								
			1	DSINT2	DMAU source interrupt for SWT2 (SIU1).										
5	IMUX5	MXI5	0	SIINT0	SIU0 input interrupt.	R/W	0								
			1	DDINT0	DMAU destination interrupt for SWT0 (SIU0).										
4	IMUX4	MXI4	0	SOINT0	SIU0 output interrupt.	R/W	0								
			1	DSINT0	DMAU source interrupt for SWT0 (SIU0).										
3	IMUX3	MXI3	0	DDINT2	DMAU destination interrupt for SWT2 (SIU1).	R/W	0								
			1	DDINT3	DMAU destination interrupt for SWT3 (SIU1).										
2	IMUX2	MXI2	0	DSINT2	DMAU source interrupt for SWT2 (SIU1).	R/W	0								
			1	DSINT3	DMAU source interrupt for SWT3 (SIU1).										
1	IMUX1	MXI1	0	DDINT0	DMAU destination interrupt for SWT0 (SIU0).	R/W	0								
			1	DDINT1	DMAU destination interrupt for SWT1 (SIU0).										
0	IMUX0	MXI0	0	DSINT0	DMAU source interrupt for SWT0 (SIU0).	R/W	0								
			1	DSINT1	DMAU source interrupt for SWT1 (SIU0).										

4 Hardware Architecture (continued)

4.4 Interrupts and Traps (continued)

4.4.2 Hardware Interrupt Multiplexing (continued)

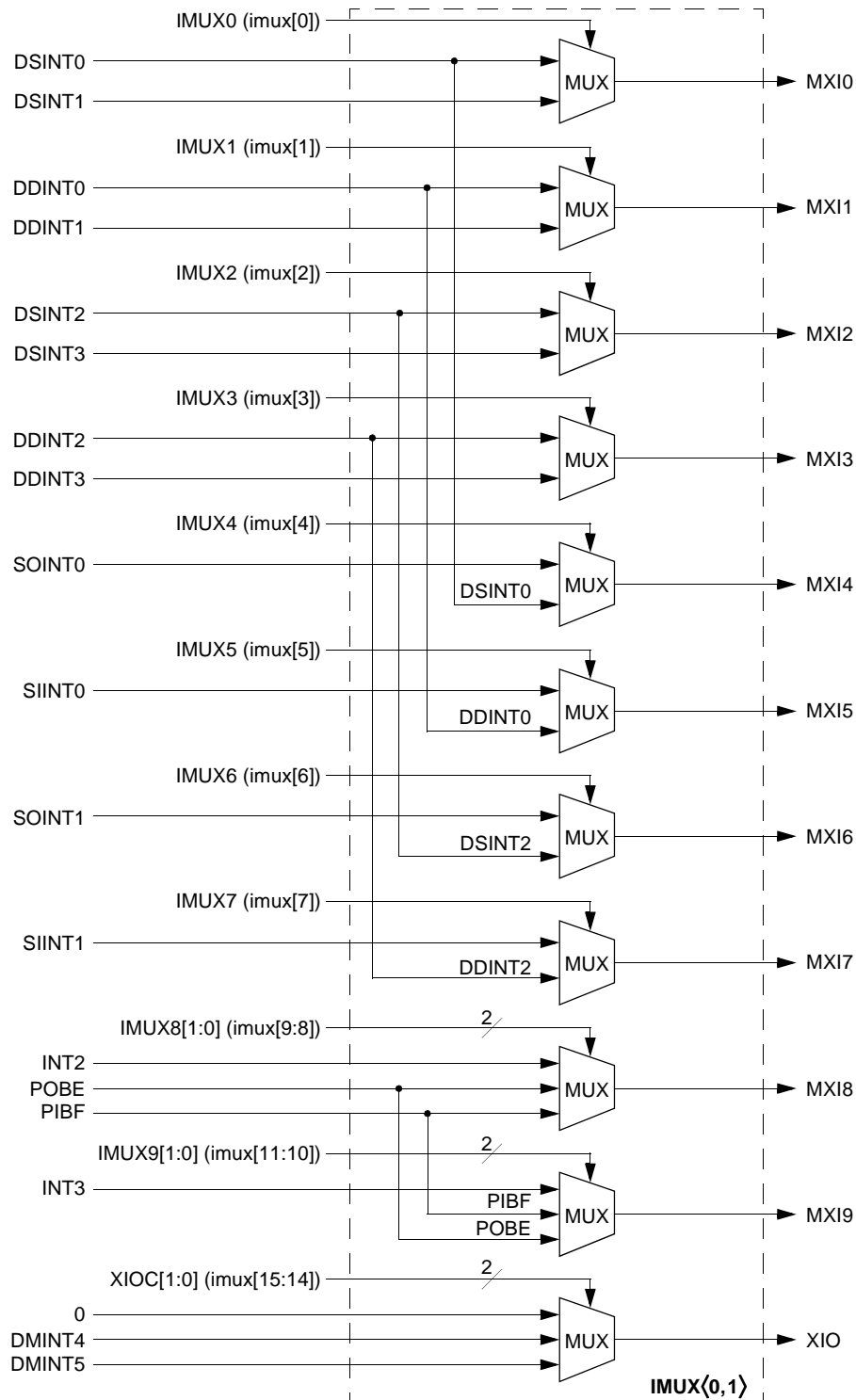


Figure 4. IMUX Block Diagram

4 Hardware Architecture (continued)

4.4 Interrupts and Traps (continued)

4.4.3 Clearing Core Interrupt Requests

Internal hardware interrupt signals are pulses that the core latches into its **ins** register (see [Section 4.4.7 on page 32](#)). Therefore, the user software need not clear the interrupt request. However, in the case of the PIU host interrupt, PHINT, the user software must clear the HINT field (**PCON**[4]) to allow the host to request a subsequent interrupt. See [Section 4.15.7 on page 150](#) for details.

4.4.4 Host Interrupt Output

The DSP16410B provides an interrupt output pin, PINT, that can interrupt a host processor connected to the PIU. A core can assert this pin by setting the PINT field (**PCON**[3]). The host must clear the PINT field to allow a core to request a subsequent interrupt. See [Section 4.15.7 on page 150](#) for details.

4.4.5 Globally Enabling and Disabling Hardware Interrupts

A device reset globally disables interrupts, i.e., the core does not service interrupts by default after reset. The

application must execute an **ei** instruction to globally enable interrupts, i.e., to cause the core to service interrupts that are individually enabled. [Section 4.4.6 on page 31](#) describes individually enabling and disabling interrupts. Executing the **di** instruction globally disables interrupts.

The core automatically globally disables interrupts if it begins servicing an interrupt. Therefore, an interrupt service routine (ISR) cannot be interrupted unless the programmer places an **ei** instruction within the ISR. In other words, interrupt nesting is disabled by default. When the **ireturn** instruction that the programmer must place at the end of the ISR is executed, the core automatically globally re-enables interrupts. Therefore, the programmer does not need to explicitly re-enable interrupts by executing an **ei** instruction before exiting the ISR. To nest interrupts, the programmer must place an **ei** and a **di** instruction within an ISR. See [Section 4.4.11 on page 35](#) for details on nesting.

The one-bit IEN field (**psw1**[14])—see [Table 10 on page 35](#)) is cleared if hardware interrupts are globally disabled. The IEN field is set if interrupts are globally enabled.

[Table 6](#) summarizes global disabling and enabling of hardware interrupts.

Table 6. Global Disabling and Enabling of Hardware Interrupts

Condition	Caused by	Indicated by	Effect
Hardware interrupts globally [†] disabled	<ul style="list-style-type: none"> ■ Device reset ■ Execution of a di instruction ■ The core begins to service an interrupt 	IEN (psw1 [14]) = 0	Core does not service interrupts.
Hardware interrupts globally [†] enabled	<ul style="list-style-type: none"> ■ Execution of an ei instruction ■ Execution of an ireturn instruction 	IEN (psw1 [14]) = 1	Core services individually enabled interrupts.

[†] With the exception of device reset, CORE0 and CORE1 are independent with respect to global disabling and enabling of hardware interrupts.

4 Hardware Architecture (continued)

4.4 Interrupts and Traps (continued)

4.4.6 Individually Enabling, Disabling, and Prioritizing Hardware Interrupts

An application can individually disable a hardware interrupt by clearing both bits of its corresponding 2-bit field in the **inc0** or **inc1** register (see [Table 7](#)). Reset clears the **inc0** and **inc1** registers, individually disabling all hardware interrupts by default. An application can individually enable a hardware interrupt at one of three priority levels by setting one or both bits of its corresponding 2-bit field in the **inc0** or **inc1** register.

The following are the advantages of interrupt prioritization:

- An ISR can service concurrent interrupts according to their priority.
- Interrupt nesting is supported, i.e., an interrupt can interrupt a lower-priority ISR. See [Section 4.4.11 on page 35](#) for details on interrupt nesting.

If multiple concurrent interrupts with the same assigned priority occur, the core first services the interrupt that has its status field in the relative least significant bit location of the **ins** register (see [Table 8 on page 32](#)), i.e., the core first services the interrupt with the lowest vector address (see [Table 9 on page 33](#)).

Note: If interrupts are globally enabled (see [Section 4.4.5 on page 30](#)), an application must not change **inc<0—1>**. Prior to changing **inc<0—1>**, the application must globally disable interrupts by executing a **di** instruction. After changing **inc<0—1>**, the application can globally re-enable interrupts by executing an **ei** instruction.

The following code segment is an example of properly changing **inc<0—1>**:

```
di                // Globally disable interrupts (default after reset).
incl=0x00001     // Enable MGIBF at level 1 priority.
ei                // OK to globally re-enable interrupts.
.
.
.
di                // Before changing incl, first globally disable interrupts.
incl=0           // Disable MGIBF.
ei                // OK to globally re-enable interrupts.
```

Table 7. inc0 and inc1 (Interrupt Control) Registers 0 and 1

	19—18	17—16	15—14	13—12	11—10	9—8	7—6	5—4	3—2	1—0
inc0	INT1[1:0]	INT0[1:0]	DMINT5[1:0]	DMINT4[1:0]	MXI3[1:0]	MXI2[1:0]	MXI1[1:0]	MXI0[1:0]	TIME1[1:0]	TIME0[1:0]
inc1	MXI9[1:0]	MXI8[1:0]	MXI7[1:0]	MXI6[1:0]	MXI5[1:0]	MXI4[1:0]	PHINT[1:0]	XIO[1:0]	SIGINT[1:0]	MGIBF[1:0]

Field	Value	Description	R/W	Reset Value
INT<0—1>[1:0] DMINT<4—5>[1:0] MXI<0—9>[1:0] [†] TIME<0—1>[1:0] PHINT[1:0] XIO[1:0] SIGINT[1:0] MGIBF[1:0]	00	Disable the selected interrupt (no priority).	R/W	00
	01	Enable the selected interrupt at priority 1 (lowest).		
	10	Enable the selected interrupt at priority 2.		
	11	Enable the selected interrupt at priority 3 (highest).		

[†] See [Table 5 on page 28](#) for definition of MXI<0—9> (IMUX<0—9>).

4 Hardware Architecture (continued)

4.4 Interrupts and Traps (continued)

4.4.7 Hardware Interrupt Status

If a hardware interrupt occurs, the core sets the corresponding bit in the **ins** register (Table 8) to indicate that the interrupt is pending. If the core services the interrupt, it clears the **ins** bit. Alternatively, if the application uses interrupt polling (Section 4.4.12 on page 36), the application program must explicitly clear the **ins** bit by writing a 1 to that bit and a 0 to every other **ins** bit. Writing a 0 to an **ins** bit leaves that bit unchanged. A reset clears the **ins** register, indicating that no interrupts are pending.

If a hardware interrupt occurs, the core sets its **ins** bit (i.e., latches the interrupt as pending) regardless of whether the interrupt is enabled or disabled. If a hardware interrupt occurs while it is disabled and the interrupt is later enabled, the core services the interrupt after servicing any other pending interrupts of equal or higher priority.

Note: The DSP16000 core globally disables interrupts when it begins executing instructions in the vector table. If the ISR does not globally enable interrupts by executing **ei** and the same interrupt reoccurs while the core is executing the ISR, the interrupt is not latched into **ins** and is therefore not recognized by the core.

4.4.8 Interrupt and Trap Vector Table

The interrupt and trap vectors for a core are in contiguous locations in memory. The base (starting) address of the vectors is configurable in the core's **vbase** register. Each interrupt and trap source is pre-assigned to a unique vector offset within a 352-word vector table (see Table 9 on page 33). The programmer can place at the vector location an instruction that branches to an interrupt service routine (ISR) or trap service routine (TSR). After servicing the interrupt or trap, the ISR or TSR must return to the interrupted or trapped program by executing an **ireturn** or **treturn** instruction. Alternatively, the programmer can place at the vector location up to four words of instructions that service the interrupt or trap, the last of which must be an **ireturn** or **treturn**.

Table 8. **ins** (Interrupt Status) Register

19	18	17	16	15	14	13	12	11	10
MXI9	MXI8	MXI7	MXI6	MXI5	MXI4	PHINT	XIO	SIGINT	MGIBF
9	8	7	6	5	4	3	2	1	0
INT1	INT0	DMINT5	DMINT4	MXI3	MXI2	MXI1	MXI0	TIME1	TIME0

Field	Value	Description	R/W	Reset Value
MXI<0—9>† PHINT XIO SIGINT MGIBF	0	Read—corresponding interrupt not pending. Write—no effect.	R/Clear	0
INT<0—1> DMINT<4—5> TIME<0—1>	1	Read—corresponding interrupt is pending. Write—clears bit and changes corresponding interrupt status to pending.		

† See Table 5 on page 28 for definition of MXI<0—9> (IMUX<0—9>).

4 Hardware Architecture (continued)

4.4 Interrupts and Traps (continued)

4.4.8 Interrupt and Trap Vector Table (continued)

Table 9. Interrupt and Trap Vector Table

Vector Description	Vector Address [†]		Priority
	Hexadecimal	Decimal	
Reserved	vbase + 0x0	vbase + 0	—
PTRAP [‡]	vbase + 0x4	vbase + 4	6 (Highest)
UTRAP [§]	vbase + 0x8	vbase + 8	5
Reserved	vbase + 0xC	vbase + 12	—
TIME0	vbase + 0x10	vbase + 16	0—3 ^{††}
TIME1	vbase + 0x14	vbase + 20	0—3 ^{††}
MXI0 (DSINT0 or DSINT1 ^{‡‡})	vbase + 0x18	vbase + 24	0—3 ^{††}
MXI1 (DDINT0 or DDINT1 ^{‡‡})	vbase + 0x1C	vbase + 28	0—3 ^{††}
MXI2 (DSINT2 or DSINT3 ^{‡‡})	vbase + 0x20	vbase + 32	0—3 ^{††}
MXI3 (DDINT2 or DDINT3 ^{‡‡})	vbase + 0x24	vbase + 36	0—3 ^{††}
DMINT4	vbase + 0x28	vbase + 40	0—3 ^{††}
DMINT5	vbase + 0x2C	vbase + 44	0—3 ^{††}
INT0	vbase + 0x30	vbase + 48	0—3 ^{††}
INT1	vbase + 0x34	vbase + 52	0—3 ^{††}
MGIBF	vbase + 0x38	vbase + 56	0—3 ^{††}
SIGINT	vbase + 0x3C	vbase + 60	0—3 ^{††}
XIO	vbase + 0x40	vbase + 64	0—3 ^{††}
PHINT	vbase + 0x44	vbase + 68	0—3 ^{††}
MXI4 (SOINT0 or DSINT0 ^{‡‡})	vbase + 0x48	vbase + 72	0—3 ^{††}
MXI5 (SIINT0 or DDINT0 ^{‡‡})	vbase + 0x4C	vbase + 76	0—3 ^{††}
MXI6 (SOINT1 or DSINT2 ^{‡‡})	vbase + 0x50	vbase + 80	0—3 ^{††}
MXI7 (SIINT1 or DDINT2 ^{‡‡})	vbase + 0x54	vbase + 84	0—3 ^{††}
MXI8 (INT2, POBE, or PIBF ^{‡‡})	vbase + 0x58	vbase + 88	0—3 ^{††}
MXI9 (INT3, POBE, or PIBF ^{‡‡})	vbase + 0x5C	vbase + 92	0—3 ^{††}
icall 0^{§§}	vbase + 0x60	vbase + 96	—
icall 1	vbase + 0x64	vbase + 100	—
⋮	⋮	⋮	—
icall 62	vbase + 0x158	vbase + 344	—
icall 63	vbase + 0x15C	vbase + 348	—

[†] **vbase** contains the base address of the 352-word vector table.

[‡] Driven by TRAP pin (see Section 4.4.10 on page 34) or core-to-core trap (see Section 4.8.1 on page 46).

[§] Reserved for HDS.

^{††} The programmer specifies the relative priority levels 0—3 for hardware interrupts via **inc0** and **inc1** (see Table 7 on page 31). Level 0 indicates a disabled interrupt. If multiple concurrent interrupts with the same assigned priority occur, the core first services the interrupt that has its status field in the relative least significant bit location of the **ins** register (see Table 8 on page 32); i.e., the core first services the interrupt with the lowest vector address.

^{‡‡} The choice of interrupt is selected by the **imux** register (see Table 5 on page 28).

^{§§} Reserved for system services.

4 Hardware Architecture (continued)

4.4 Interrupts and Traps (continued)

4.4.9 Software Interrupts

Software interrupts emulate hardware interrupts for the purpose of software testing. A software interrupt is always enabled and has no assigned priority and no corresponding field in the **ins** register. A program causes a software interrupt by executing an **icall IM6** instruction, where IM6 is replaced with 0—63. When a software interrupt is serviced, the core saves the contents of **PC** in the **pi** register and transfers control to the interrupt vector defined in Table 9 on page 33.

CAUTION: If a software interrupt is inserted into an **ISR**, it is explicitly nested in the **ISR** and therefore the **ISR** must be structured for nesting. See Section 4.4.11 on page 35 and the *DSP16000 Digital Signal Processor Core Information Manual* for more information about nesting.

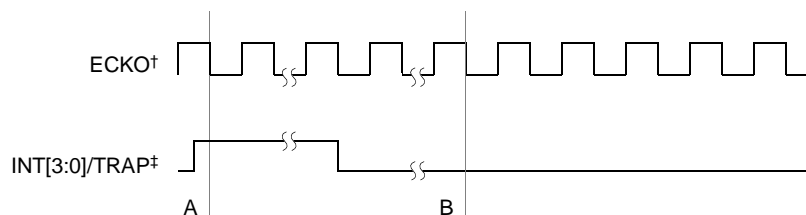
4.4.10 INT[3:0] and TRAP Pins

The DSP16410B provides four positive-assertion edge-detected interrupt pins (INT[3:0]) and a bidirectional positive-assertion edge-detected trap pin (TRAP).

The TRAP pin is used by an application to gain control of both processors for asynchronous event handling, typically for catastrophic error recovery. It is a 3-state bidirectional pin that connects to both cores and both HDS blocks. TRAP is connected directly to both cores via the PTRAP signal. After reset, TRAP is configured as an input; it can be configured as an output under JTAG control to support HDS multiple-device debugging.

Figure 5 is a functional timing diagram for the INT[3:0] and TRAP pins. A low-to-high transition of one of these pins asserts the corresponding interrupt or trap. INT[3:0] or TRAP must be held high for a minimum of two CLK cycles and must be held low for at least two CLK cycles before being reasserted. If INT[3:0] or TRAP is asserted and stays high, the core services the interrupt or trap only once.

A minimum of four cycles¹ after INT[3:0] or PTRAP is asserted, the core services the interrupt or trap by executing instructions starting at the vector location as defined in Table 9 on page 33. In the case of PTRAP, a maximum of three instructions are allowed to execute before the core services the trap.



† ECKO is programmed to be the internal clock CLK (the ECKO[1:0] field (**ECON1**[1:0])—see Table 60 on page 110) is programmed to 1).

‡ The INT[3:0] or TRAP pin must be held high for a minimum of two CLK cycles and must be held low for a minimum of two CLK cycles before being reasserted.

Notes:

- A. The DSP16410B synchronizes INT[3:0] or TRAP on the falling edge of the internal clock CLK.
- B. A minimum four-cycle delay before the core services the interrupt or trap (executes instructions starting at the vector location). For a trap, the core executes a maximum of three instructions before it services the trap.

Figure 5. Functional Timing for INT[3:0] and TRAP

1. The number of cycles depends on the number of wait-states incurred by the interrupted or trapped instruction.

4 Hardware Architecture (continued)

4.4 Interrupts and Traps (continued)

4.4.11 Nesting Interrupts

The **psw1** register (see [Table 10](#)) contains the IPLc[1:0] and IPLp[1:0] fields that are used for interrupt nesting. See the *DSP16000 Digital Signal Processor Core Information Manual* for details on these fields.

Table 10. psw1 (Processor Status Word 1) Register

15		14		13—12		11—10		9—7		6		5—0	
Reserved		IEN		IPLc[1:0]		IPLp[1:0]		Reserved		EPAR		a[7:2]V	
Bit	Field	Value	Description									R/W	Reset Value†
15	Reserved	0	Reserved—write with zero.									R/W	0
14	IEN‡	0	Hardware interrupts are globally disabled.									R	0
		1	Hardware interrupts are globally enabled.										
13—12	IPLc[1:0]	00	Current hardware interrupt priority level is 0; core handles pending interrupts of priority 1, 2, or 3.									R/W	00
		01	Current hardware interrupt priority level is 1; core handles pending interrupts of priority 2 or 3.										
		10	Current hardware interrupt priority level is 2; core handles pending interrupts of priority 3 only.										
		11	Current hardware interrupt priority level is 3; core does not handle any pending interrupts.										
11—10	IPLp[1:0]	00	Previous hardware interrupt priority level§ was 0.									R/W	XX
		01	Previous hardware interrupt priority level§ was 1.										
		10	Previous hardware interrupt priority level§ was 2.										
		11	Previous hardware interrupt priority level§ was 3.										
9—7	Reserved	0	Reserved—write with zero.									R/W	X
6	EPAR	0	Most recent BMU or special function shift result has odd parity.									R/W	X
		1	Most recent BMU or special function shift result has even parity.										
5	a7V	0	The current contents of a7 are not mathematically overflowed.									R/W	X
		1	The current contents of a7 are mathematically overflowed.††										
4	a6V	0	The current contents of a6 are not mathematically overflowed.									R/W	X
		1	The current contents of a6 are mathematically overflowed.††										
3	a5V	0	The current contents of a5 are not mathematically overflowed.									R/W	X
		1	The current contents of a5 are mathematically overflowed.††										
2	a4V	0	The current contents of a4 are not mathematically overflowed.									R/W	X
		1	The current contents of a4 are mathematically overflowed.††										
1	a3V	0	The current contents of a3 are not mathematically overflowed.									R/W	X
		1	The current contents of a3 are mathematically overflowed.††										
0	a2V	0	The current contents of a2 are not mathematically overflowed.									R/W	X
		1	The current contents of a2 are mathematically overflowed.††										

† In this column, X indicates unknown on powerup reset and unaffected on subsequent reset.

‡ The user clears this bit by executing a **di** instruction and sets it by executing an **ei** or **ireturn** instruction. The core clears this bit whenever it begins to service an interrupt.

§ Previous interrupt priority level is the priority level of the interrupt most recently serviced prior to the current interrupt. This field is used for interrupt nesting.

†† The most recent DAU result that was written to that accumulator resulted in mathematical overflow (LMV) with FSAT = 0.

4 Hardware Architecture (continued)

4.4 Interrupts and Traps (continued)

4.4.11 Nesting Interrupts (continued)

The core automatically globally disables interrupts when it begins servicing an interrupt. Therefore, an interrupt service routine (ISR) cannot be interrupted unless the programmer places an **ei** (enable interrupts) instruction within the ISR. In other words, interrupt nesting is disabled by default. To allow nesting, the ISR must perform the following steps before executing an **ei** instruction:

1. Copy the contents of **psw1** and **pi** to memory. This is needed to save the previous interrupt priority level (IPLP) and the interrupt return address in **pi**, which are overwritten by the core if the ISR is interrupted.
2. Copy the contents of **cstate** to memory and then clear **cstate**. This is needed in case the ISR has interrupted a cache loop (**do** or **redo**). If the ISR is interrupted and **cstate** is not cleared, the nested interrupt's **ireturn** instruction will return to the cache instead of to the ISR. See the *DSP16000 Digital Signal Processor Core Information Manual* for details on **cstate** and the cache.

After performing the above steps, the ISR can safely globally enable interrupts by executing an **ei** instruction. After servicing the interrupt and before executing an **ireturn** instruction to return the core to its previous state before the interrupt occurred, the ISR must perform the following steps:

1. Globally disable interrupts via the **di** (disable interrupts) instruction. This is needed to ensure that the restoring step below is not interrupted.
2. Restore **psw1**, **pi**, and **cstate** so that they contain their original values from the beginning of the ISR execution.

After performing the above steps, the ISR can return the core to its previous state by executing an **ireturn** instruction. Executing **ireturn** globally enables interrupts, so it is not necessary for the ISR to explicitly enable interrupts by executing an **ei** instruction before returning.

See the *DSP16000 Digital Signal Processor Core Information Manual* for more detail on interrupt nesting.

4.4.12 Interrupt Polling

If a core disables an interrupt and tests its **ins** field, it can poll that interrupt instead of automatically servicing it. This procedure, however, costs in the amount of code that must be written and executed to replace what the DSP16000 core does by design.

The programmer can poll an interrupt source by checking its pending status in **ins**. The program can clear an interrupt and change its status from pending to not pending by writing a 1 to its corresponding **ins** field. This clears the field and leaves the remaining fields of **ins** unchanged. The example code segment below polls the MGU input buffer full (MGIBF):

```
poll:      a0=ins                // Copy ins register contents to a0.
          a0=a0&0x00000400    // Mask out all but bit 10.
          if eq goto poll     // If bit 10 is zero, then MGIBF not pending.
          ...                 // Interrupt is now pending -- service it.
          ins=0x00400         // Clear MGIBF; don't change other interrupts.
```

4 Hardware Architecture (continued)

4.5 Memory Maps

The DSP16000 core is a modified Harvard architecture with separate program and data memory spaces (X-memory space and Y-memory space). The core differentiates between the X- and Y-memory spaces by the addressing unit used for the access (XAAU vs. YAAU) and not by the physical memory accessed. The core accesses its X-memory space via its 20-bit X address bus (XAB) and 32-bit X data bus (XDB). The core accesses its Y-memory space via its 20-bit Y address bus (YAB) and 32-bit Y data bus (YDB).

The DMAU accesses private internal memory (TPRAM $\langle 0-1 \rangle$) via its 20-bit internal Z address bus (ZIAB) and 32-bit internal Z data bus (ZIDB) and shared external memory¹ (EIO and ERAM) via its 20-bit external Z address bus (ZEAB) and 32-bit external Z data bus (ZEDB).

Although DSP16410B memory is 16-bit word-addressable, data or instruction widths can be either 16 bits or 32 bits and applications can access the memories 32 bits at a time.

Table 11 summarizes the components of the DSP16410B memory. The table specifies the name and size of each component, whether it is internal or external, whether it is private to a core or shared by both cores, and in which memory space(s) it resides. The five memory spaces are CORE0's X-memory space, CORE0's Y-memory space, CORE1's X-memory space, CORE1's Y-memory space, and the DMAU's Z-memory space.

Table 11. DSP16410B Memory Components

Type	Memory Component	Size	CORE0		CORE1		DMAU Z-Memory Space [†]
			X-Memory Space	Y-Memory Space [†]	X-Memory Space	Y-Memory Space [†]	
Private Internal	TPRAM0	96 Kwords	✓	✓			✓
	CACHE0	62 words	✓	✓			
	IROM0	4 Kwords	✓				
	TPRAM1	96 Kwords			✓	✓	✓
	CACHE1	62 words			✓	✓	
	IROM1	4 Kwords			✓		
Shared Internal	Internal I/O [‡]	128 Kwords		✓		✓	✓
Shared External	EIO	128 Kwords		✓		✓	✓
	ERAM	512 Kwords		✓		✓	✓
	EROM	512 Kwords	✓		✓		

[†] Assumes that WEROM is 0 for normal operation. If WEROM is 1, ERAM is replaced by EROM in the memory space, allowing the normally read-only EROM section to be written. WEROM is discussed in detail in Section 4.5.3 on page 38.

[‡] The internal I/O section consists of 2 Kwords of SLM and memory-mapped registers in the SEMI, DMAU, PIU, SIU0, and SIU1 blocks. Only a small portion of the 128 Kwords reserved for internal I/O is actually populated with memory or registers.

The remainder of this section consists of the following:

- Section 4.5.1, Private Internal Memory, on page 38.
- Section 4.5.2, Shared Internal I/O, on page 38.
- Section 4.5.3, Shared External I/O and Memory, on page 38.
- Section 4.5.4, X-Memory Map, on page 39.
- Section 4.5.5, Y-Memory Maps, on page 40.
- Section 4.5.6, Z-Memory Maps, on page 41.
- Section 4.5.7, Internal I/O Detailed Memory Map, on page 42.

1. ZEAB and ZEDB connect to EIO and ERAM through the SEMI.

4 Hardware Architecture (continued)

4.5 Memory Maps (continued)

4.5.1 Private Internal Memory

Each core has its own private internal memories for program and data storage. CORE0 has IROM0, CACHE0, and TPRAM0. CORE1 has IROM1, CACHE1, and TPRAM1. A core cannot directly access the other core's private memory. However, the DMAU can access both TPRAM0 and TPRAM1 and can move data between these two memories to facilitate core-to-core communication (see [Section 4.8 on page 45](#)).

TPRAM is described in more detail in [Section 4.6 on page 43](#). Cache memory is described in detail in the *DSP16000 Digital Signal Processor Core Information Manual*. IROM contains boot and HDS code and is described in [Section 5 on page 205](#).

4.5.2 Shared Internal I/O

The 128 Kword internal I/O memory component is accessible by both cores in their Y-memory spaces and by the DMAU in its Z-memory space. Any access to this memory component is made over the system bus and is arbitrated by the SEMI. The internal shared I/O memory component consists of:

- 2 Kwords of shared local memory (SLM). SLM can be used for core-to-core communication (see [Section 4.8 on page 45](#)). SLM is described in [Section 4.1.4 on page 17](#).
- Memory-mapped control and data registers within the following peripherals:
 - DMAU
 - SEMI
 - PIU
 - SIU0
 - SIU1

Only a small portion of the 128 Kwords reserved for internal I/O is actually populated with memory or registers. Any access to the internal I/O memory component takes multiple cycles to complete. DSP core or DMAU writes take a minimum of two CLK cycles to complete. DSP core or DMAU reads take a minimum of five CLK cycles to complete.

4.5.3 Shared External I/O and Memory

External I/O and memory consists of three shared components: EIO, ERAM, and EROM. EIO and ERAM are accessible in the Y-memory spaces of both cores and also in the DMAU's Z-memory space. EROM is normally read-only and accessible only in the X-memory spaces of both cores. If the programmer sets the WEROM field in the memory-mapped **ECON1** register (see [Table 60 on page 110](#)), EROM takes the place of ERAM in the Y-memory spaces of both cores and in the DMAU's Z-memory space (see [Section 4.5.5 on page 40](#) and [Section 4.5.6 on page 41](#) for details). This allows the EROM component to be written for program downloads to external X memory.

The physical size of the EIO, ERAM, and EROM components can be expanded from the sizes defined in [Table 11 on page 37](#) by employing the ESEG[3:0] pins. The external memory system can use ESEG[3:0] in either of the following ways:

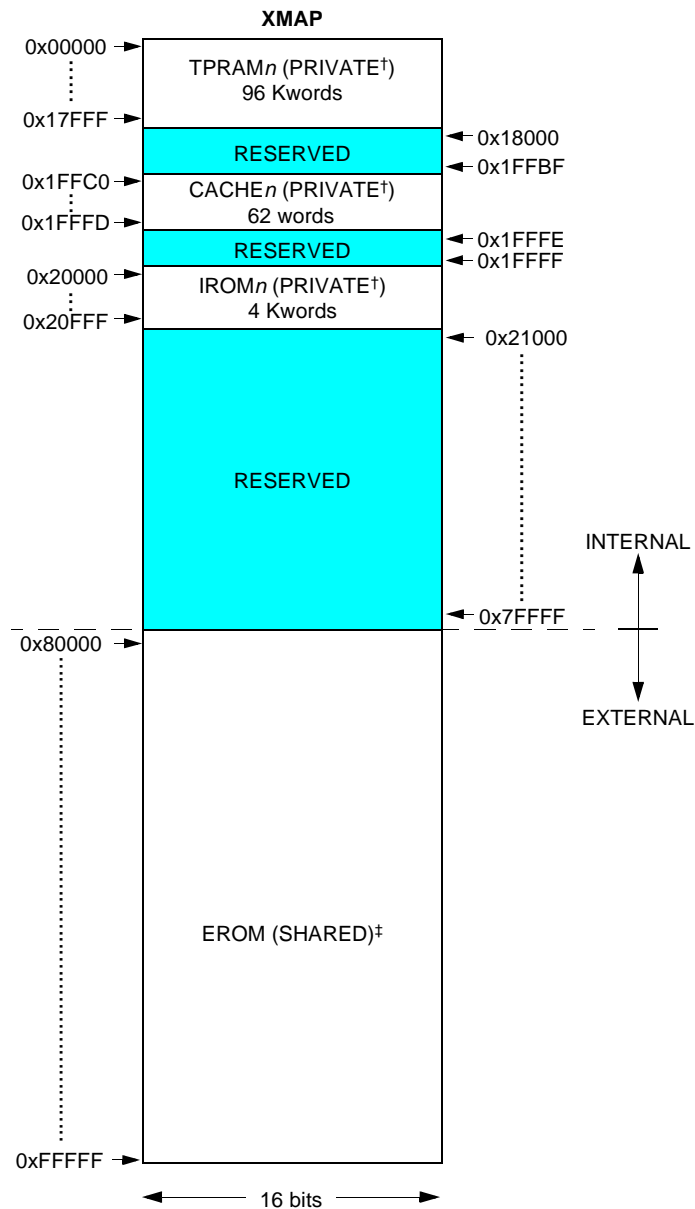
1. ESEG[3:0] can be interpreted by the external memory system as four separate decoded address enable signals. Each ESEG[3:0] pin individually selects one of four segments for each memory component. This results in four glueless 512 Kword (1 Mbyte) ERAM segments, four glueless 512 Kword (1 Mbyte) EROM segments, and four glueless 128 Kword (256 KB) EIO segments.
2. ESEG[3:0] can be interpreted by the external memory system as an extension of the address bus, i.e., the ESEG[3:0] pins can be concatenated with the EAB[18:0] pins to form a 23-bit address. This results in one glueless 8 Mword (16 Mbytes) ERAM segment, one glueless 8 Mword (16 Mbytes) EROM segment, and one glueless 2 Mword (4 Mbytes) EIO segment.

See [Section 4.14.1.4 on page 105](#) for details on configuring the ESEG[3:0] pins.

4 Hardware Architecture (continued)

4.5 Memory Maps (continued)

4.5.4 X-Memory Map



[†] n is 0 for CORE0 or 1 for CORE1. Private memory can be accessed by the core with which it is associated. TPRAM0, CACHE0, and IROM0 cannot be accessed directly by CORE1. TPRAM1, CACHE1, and IROM1 cannot be accessed directly by CORE0. Both TPRAM0 and TPRAM1 can be accessed by the DMAU and PIU.

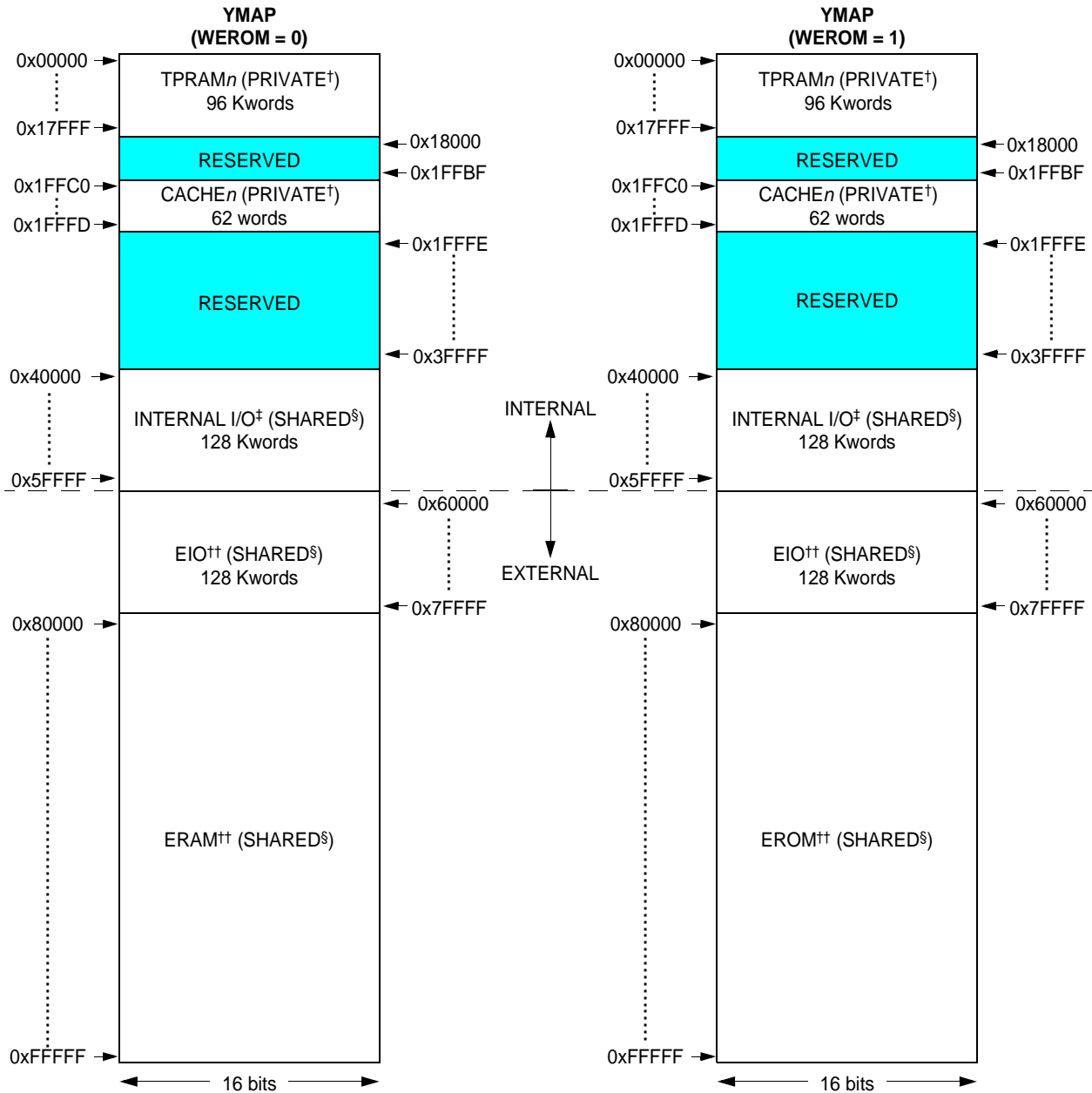
[‡] EROM can be configured as four glueless 512 Kword (1 Mbyte) segments or one 8 Mword (16 Mbytes) segment. See [Section 4.14.4.3 beginning on page 111](#) for details. EROM is shared, i.e., it is accessible by both CORE0 and CORE1, and it is also accessible by the DMAU and the PIU.

Figure 6. X-Memory Map

4 Hardware Architecture (continued)

4.5 Memory Maps (continued)

4.5.5 Y-Memory Maps



† n is 0 for CORE0 or 1 for CORE1. Private memory can be accessed by the core with which it is associated. TPRAM0, CACHE0, and IROM0 cannot be accessed directly by CORE1. TPRAM1, CACHE1, and IROM1 cannot be accessed directly by CORE0. Both TPRAM0 and TPRAM1 can be accessed by the DMAU and PIU.

‡ Internal I/O consists of shared local memory (SLM) and internal memory-mapped registers.

§ A shared memory space is accessible by both CORE0 and CORE1, and is also accessible by the DMAU and the PIU.

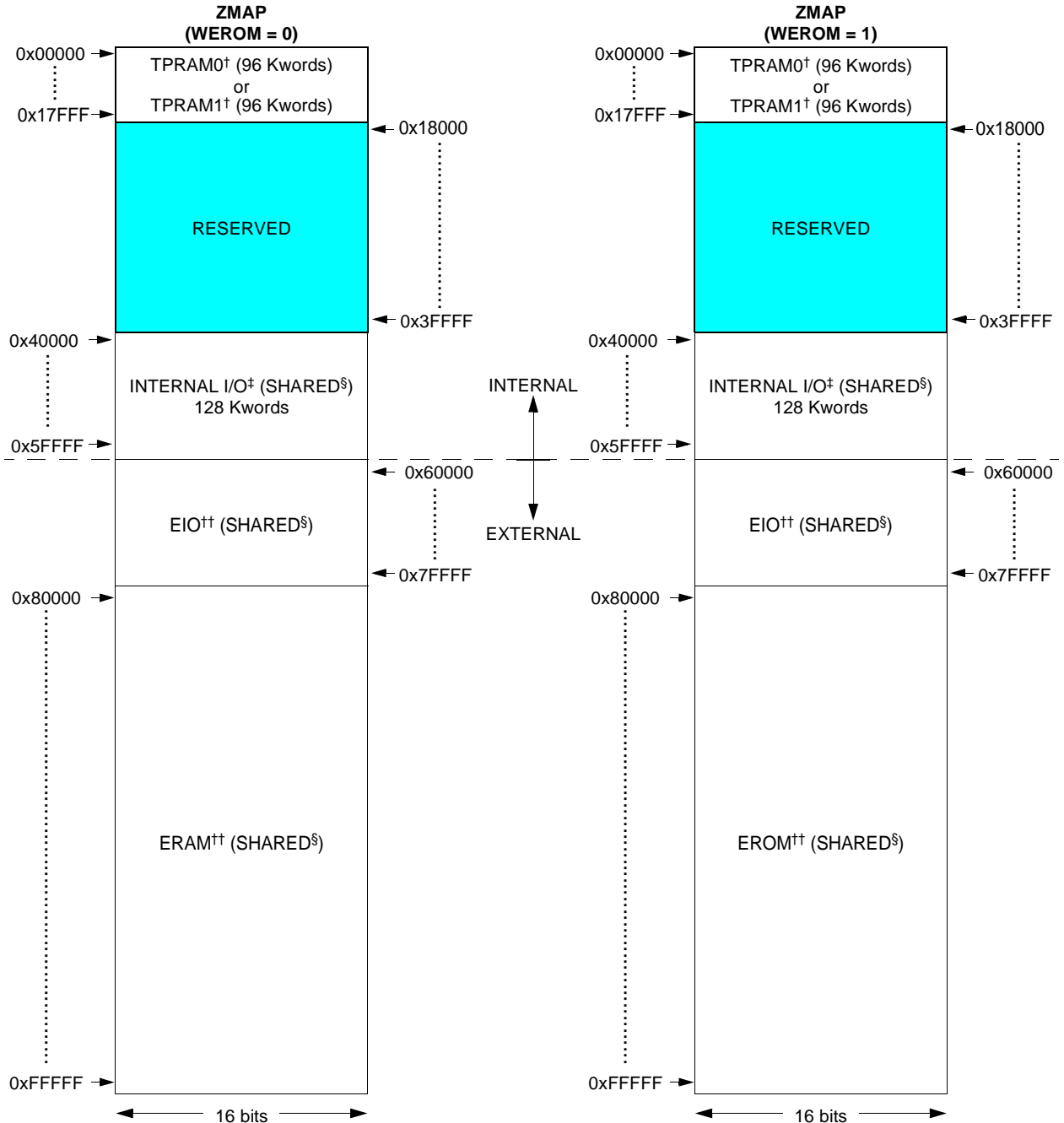
†† EROM and ERAM can each be configured as four glueless 512 Kword (1 Mbyte) segments or one 8 Mword (16 Mbytes) segment. EIO can be configured as four glueless 128 Kword (256 Mbytes) segments or one glueless 2 Mword (4 Mbytes) segment. (See Section 4.14.4.3 beginning on page 111 for details.)

Figure 7. Y-Memory Maps

4 Hardware Architecture (continued)

4.5 Memory Maps (continued)

4.5.6 Z-Memory Maps



† The CMP[2:0] field in the DMAU address register (**SADD** \langle 0–5 \rangle or **DADD** \langle 0–5 \rangle)—Table 37 on page 76 or in the parallel address register (**PA**)—Table 78 on page 135 selects either TPRAM0 or TPRAM1.

‡ Internal I/O consists of shared local memory (SLM) and internal memory-mapped registers.

§ A shared memory space is accessible by both CORE0 and CORE1, and is also accessible by the DMAU and the PIU.

†† EROM and ERAM can each be configured as four glueless 512 Kword (1 Mbyte) segments or one 8 Mword (16 Mbytes) segment. EIO can be configured as four glueless 128 Kword (256 Mbytes) segments or one glueless 2 Mword (4 Mbytes) segment. (See Section 4.14.4.3 beginning on page 111 for details.)

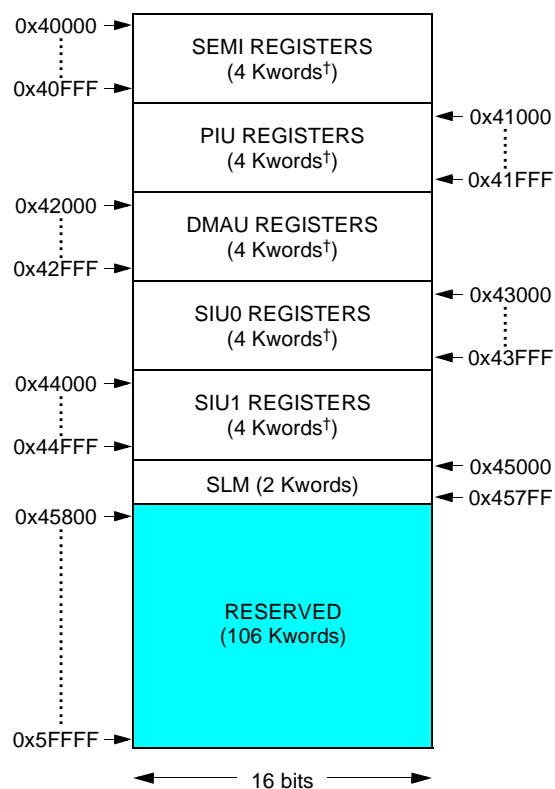
Figure 8. Z-Memory Maps

4 Hardware Architecture (continued)

4.5 Memory Maps (continued)

4.5.7 Internal I/O Detailed Memory Map

Figure 9 is a detailed view of the 128 Kword internal I/O memory component shown in Figures 7 and 8. It consists of a 4 Kword block for the memory-mapped registers of each peripheral and a 2 Kword block for the SLM. The internal I/O memory component is directly accessible by both cores and by the DMAU and PIU. The SEMI controls access to the internal I/O memory component, which is subject to wait-state and contention penalties. The SEMI permits only 16-bit and aligned 32-bit accesses to the internal I/O memory component. The SEMI does **not** permit misaligned 32-bit accesses (double-word accesses with an odd address) for the internal I/O memory component because they produce undefined results. An access to the internal I/O memory component takes multiple clock cycles to complete and a core access to the internal I/O memory component causes that core to incur wait-states. See Section 4.14.7.1 on page 125 for details on system bus performance.



† Although 4 Kwords are reserved for the memory-mapped registers of each peripheral, not all of the 4 Kwords are actually used.

Figure 9. Internal I/O Memory Map

The memory-mapped registers located in their associated peripherals are each mapped to an even address. The sizes of these registers are 16 bits, 20 bits, or 32 bits. A register that is 20 bits or 32 bits must be accessed as an aligned double word. A register that is 16 bits can be accessed as a single word with an even address or as an aligned double word. If a register that is 16 bits or 20 bits is accessed as a double word, the contents of the register are right-justified. Section 6.2.2 on page 228 details the memory-mapped registers.

4 Hardware Architecture (continued)

4.6 Triport Random-Access Memory (TPRAM)

Each core has a private block TPRAM (TPRAM0 and TPRAM1) each consisting of 96 banks (banks 0—95) of zero wait-state memory. Each bank consists of 1K 16-bit words and has three separate address and data ports—one port to the core's instruction/coefficient (X-memory) space, a second port to the core's data (Y-memory) space, and a third port to the DMAU's (Z-memory) space. TPRAM is organized into even and odd interleaved banks for which each even/odd address pair is a 32-bit wide module as illustrated in Figure 10. The core's data buses (XDB and YDB) and the DMAU's data bus (ZIDB) are each 32 bits wide, and therefore 32-bit data in the TPRAM with an aligned (even) address can be accessed in a single cycle. Typically, a misaligned double word is accessed in two cycles.

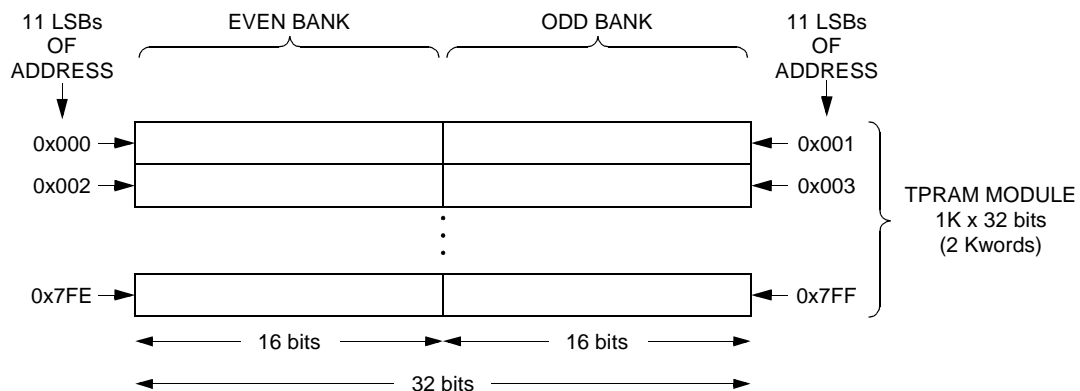


Figure 10. Interleaved Internal TPRAM

Figure 11 illustrates an example arrangement of single words (16 bits) and double words (32 bits) in memory. It also illustrates an aligned double word and a misaligned double word. See the *DSP16000 Digital Signal Processor Core Information Manual* for details on word alignment and misalignment wait-states.

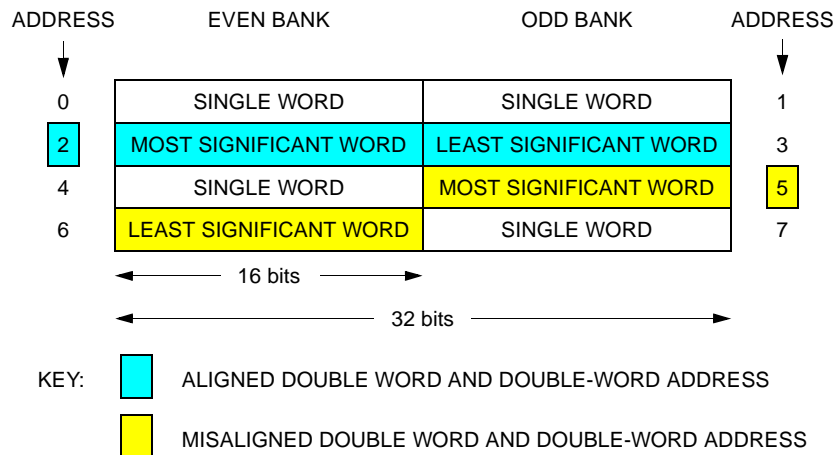


Figure 11. Example Memory Arrangement

4 Hardware Architecture (continued)

4.6 Triport Random-Access Memory (TPRAM) (continued)

The core's X and Y ports and the DMAU's Z port can access separate modules within a TPRAM simultaneously with no wait-states incurred by the core. If the same module of TPRAM is accessed from multiple ports simultaneously, the TPRAM automatically sequences the accesses in the following priority order: X port (instruction/coefficient), Y port (data), then Z port (DMAU). This sequencing can cause the core to incur a conflict wait-state. Because the core must complete any consecutive accesses to a module of TPRAM before the DMAU can access that module, the DMAU can be blocked from accessing that module for a significant number of cycles.

4.7 Shared Local Memory (SLM)

Each core, the DMAU, and the PIU can access SLM (shared local memory) through the SEMI and the system buses (SAB and SDB). SLM is a 2 Kword block located in the internal I/O memory component. SLM supports both 16-bit and aligned 32-bit accesses, but not 32-bit misaligned accesses.

The SEMI controls access to the SLM, which is subject to wait-state and contention penalties—see [Section 4.14.7.1 on page 125](#) for details. Because access to the SLM is subject to wait-state and contention penalties, it is not an efficient method for transferring large blocks of data between the cores. (An efficient method is to use the DMAU memory-to-memory (MMT) channel.)

4 Hardware Architecture (continued)

4.8 Interprocessor Communication

Effective interprocessor (core-to-core) communication requires synchronization and access to required data.

The following hardware mechanisms support access synchronization:

- The MGU provides core-to-core interrupts and traps.
- The MGU provides message buffer interrupts and flags.
- DMAU interrupts.

The following mechanisms support data access:

- The MGU can control the occurrence of a synchronizing event (interrupt/trap) for information/status transfer.
- The MGU provides data transfer through its full-duplex message buffers (**mgi** and **mgo**).
- The DMAU can copy data from one core's TPRAM to the other core's TPRAM.
- Cores can directly share data in external memory (ERAM, EROM, or EIO spaces).
- Cores can directly share data in the SLM.

Figure 12 illustrates the interprocessor communication logic provided by MGU0 and MGU1.

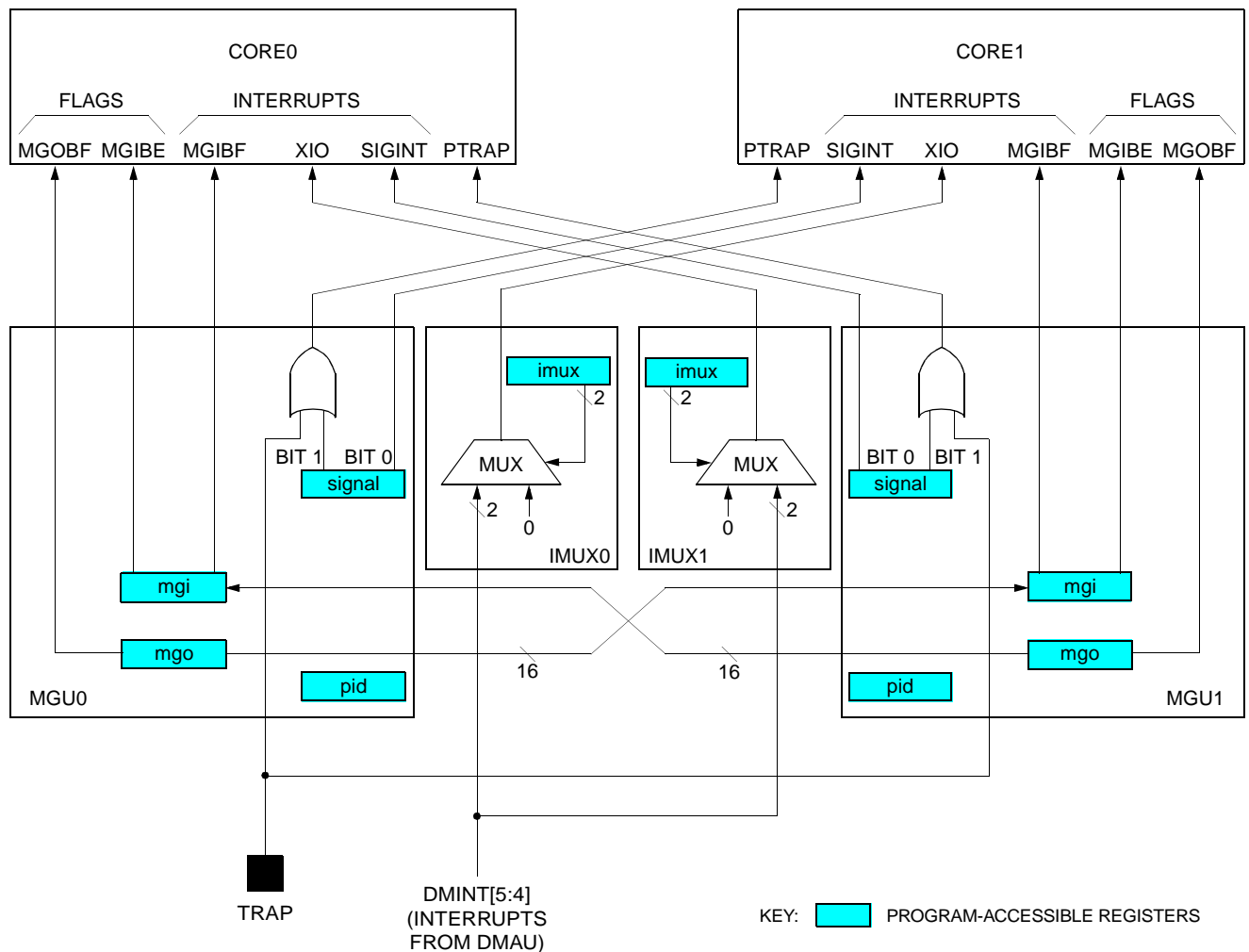


Figure 12. Interprocessor Communication Logic in MGU0 and MGU1

4 Hardware Architecture (continued)

4.8 Interprocessor Communication (continued)

Note: Sharing data directly through external memory (ERAM, EROM, or EIO spaces) or the SLM is the least efficient means of interprocessor communication involving large blocks of data. It is more efficient to perform block memory-to-memory moves using a DMAU MMT channel. See [Section 4.7 on page 44](#) for details on SLM and [Section 4.5.3 on page 38](#) for details on ERAM, EROM, or EIO.

4.8.1 Core-to-Core Interrupts and Traps

Software executing on one core can interrupt the other core by writing a 1 to its own MGU **signal** register bit 0 ([Table 12](#)). This causes the assertion of the other core's SIGINT interrupt signal.

The code segment below illustrates the code running on one core to assert the SIGINT interrupt of the other core:

```
signal=1 // interrupt other core
```

Software executing on one core can trap the other core by writing a 1 to its own **signal** register bit 1. This causes the assertion of the other core's PTRAP. As shown in [Figure 12 on page 45](#), the signal register bit 1 is logically ORed with the TRAP pin and the result is input to the other core's PTRAP signal. (See [Section 4.4.10 on page 34](#) for more information on PTRAP). See the code segment below:

```
signal=2 // trap other core
```

To ensure correct operation, the execution of the **signal** register write instruction must be followed by the execution of any instruction other than another **signal** register write instruction.

Table 12. signal Register

			15—11	1	0
			Reserved	SIGTRAP	SIGINT
Bit	Field	Value	Description	R/W	Reset Value
15—11	Reserved	0	Reserved—write with zero.	W	0
1	SIGTRAP	0	No effect.	W	0
		1	Trap the other core by asserting its PTRAP signal.		
0	SIGINT	0	No effect.	W	0
		1	Interrupt the other core by asserting its SIGINT interrupt.		

Note: If the program sets the SIGTRAP or SIGINT field, the MGU automatically clears the field after asserting the trap or interrupt. Therefore, the program must not explicitly clear the field.

4.8.2 Message Buffer Data Exchange

Each core can use its MGU message buffers to transmit and receive status information to and from the other core. A core can send a message to another core by writing to its own 16-bit output message register **mgo**. A core can receive a message from another core by reading its own 16-bit input message register **mgi**.

If the transmitting core writes **mgo**, the following steps occur:

1. After two instruction cycles of latency, the transmitting core's message output buffer full (MGOBF) condition flag is set.
2. After an additional two instruction cycles of latency:
 - The DSP16410B copies the contents of the transmitting core's **mgo** to the receiving core's input message register **mgi**.
 - The DSP16410B clears the receiving core's message input buffer empty (MGIBE) condition flag.
 - The DSP16410B asserts the receiving core's message input buffer full (MGIBF) interrupt.

4 Hardware Architecture (continued)

4.8 Interprocessor Communication (continued)

4.8.2 Message Buffer Data Exchange (continued)

The receiving core can use interrupts or polling to detect the presence of an incoming message. When the receiving core reads **mgi**, the following steps occur:

1. After one instruction cycle of latency, the DSP16410B sets the receiving core's MGIBE flag.
2. After an additional instruction cycle of latency, the DSP16410B clears the transmitting core's MGOBF flag.

4.8.2.1 Message Buffer Write Protocol

To ensure an older message has been processed by the receiving core, the transmitting core must not write a new message to **mgo** until its MGOBF flag is cleared. The example code segment below is executed by the transmitting core:

```
if mgobf goto .    // Wait for old message
                  // to be read.
mgo=*r0++         // Write new message.
```

4.8.2.2 Message Buffer Read Protocol

The receiving core can detect an incoming message by enabling the MGIBF interrupt in the **inc1** register (Table 149 on page 238). The following is an example of a simple interrupt service routine for the receiving core:

```
ISR:  *r0++=mgi    // Read new message and
                  // clear MGIBF.
      ireturn
```

As an alternative to the interrupt-directed message buffer read protocol described above, the receiving core can poll its MGIBE flag for the arrival of a new message. The example code segment below is executed by the receiving core:

```
if mgibe goto .    // Wait for new
                  // message.
*r0++=mgi         // Read new message.
```

The DSP16410B can operate a full-duplex communication channel between CORE0 and CORE1 with each core using its own **mgi** and **mgo** registers and its own MGOBF and MGIBE flags. Table 13 illustrates two code segments for a full-duplex data exchange of *N* words between CORE0 and CORE1. This segment exchanges two words (one input, one output) between the two cores every 17 CLK cycles.

Table 13. Full-Duplex Data Transfer Code Through Core-to-Core Message Buffer

CORE0 Message Buffer Transfer Code	CORE1 Message Buffer Transfer Code
<pre>c0=1-N xfer: if mgobf goto . mgo=*r0++ //Write message to //CORE1 and set MGOBF. //4 cycles latency //until CORE1's MGIBE //is cleared. if mgibe goto . //Wait for CORE1 //message to arrive. *r1++=mgi //Read CORE1 message //and clear CORE1's //MGOBF. if c0lt goto xfer</pre>	<pre>c0=1-N xfer: if mgobf goto . mgo=*r1++ //Write message to //CORE0 and set MGOBF. //4 cycles latency //until CORE0's MGIBE //is cleared. if mgibe goto . //Wait for CORE0 //message to arrive. *r0++=mgi //Read CORE0 message //and clear CORE0's //MGOBF. if c0lt goto xfer</pre>

4 Hardware Architecture (continued)

4.8 Interprocessor Communication (continued)

4.8.3 DMAU Data Transfer

The most efficient mechanism for synchronously transferring large data blocks between the two cores is through the two DMAU memory-to-memory (MMT) channels, MMT4 and MMT5, described in detail in [Section 4.13.6 beginning on page 89](#). For example, one core uses one MMT channel to transfer data and the other core uses the other channel. In this way, a transmitting core writes a message block via its MMT channel and an interrupt notifies the receiving core after the DMA transfer is complete. [Table 14](#) summarizes the MMT interrupts, DMINT4 and DMINT5, used to synchronize DMAU transfers. Both cores can monitor both DMINT4 and DMINT5.

Table 14. DMAU MMT Channel Interrupts

DMAU Channel	Interrupt	
	Name	Description
MMT4	DMINT4	MMT4 transfer complete.
MMT5	DMINT5	MMT5 transfer complete.

Table 15. DMA Intracore and Intercore Transfers Example

DMAU Channel	Intracore			Intercore (Core-to-Core)			
	Core	Interrupt	imux[XIOC[1:0]]	Transmitting		Receiving	
				Core	imux[XIOC[1:0]]	Core	Interrupt
MMT4	CORE0	DMINT4	0 (CORE1's XIO = 0)	CORE0	1 (CORE1's XIO = DMINT4)	CORE1	XIO (DMINT4)
MMT5	CORE1	DMINT5	0 (CORE0's XIO = 0)	CORE1	2 (CORE0's XIO = DMINT5)	CORE0	XIO (DMINT5)

If an MMT channel is dedicated to intercore transfers and not used for intracore transfers, the transmitting and receiving cores can use the DMINT4 and DMINT5 interrupts directly to synchronize transfers. For example, MMT4 can be dedicated to CORE0-to-CORE1 transfers and MMT5 can be dedicated to CORE1-to-CORE0 transfers. In this case, DMINT4 interrupts CORE1 if a message block from CORE0 is in memory, and likewise, DMINT5 interrupts CORE0 if a message block from CORE1 is in memory.

If an MMT channel is used for both intracore and intercore transfers, DMINT4 or DMINT5 is used for synchronizing intracore transfers and the XIO interrupt is used for synchronizing intercore transfers. Each core programs the XIO interrupt for the other core via its **imux** register ([Table 5 on page 28](#)). The XIOC[1:0] field (**imux**[15:14]) selects XIO for the other core as either zero (XIOC[1:0] = 0), DMINT4 (XIOC[1:0] = 1), or DMINT5 (XIOC[1:0] = 2).

[Table 15](#) illustrates an example configuration for intracore and intercore transfers via DMA. This example assigns CORE0 to MMT4 and CORE1 to MMT5.

If a core uses an MMT channel for intracore transfers, i.e., not for transfers with the other core, it must first program its XIOC[1:0] field (**imux**[15:14]) to zero. This prevents the MMT interrupt from disturbing the other core via its XIO interrupt. The core must enable the corresponding MMT interrupt (DMINT4 or DMINT5) in its **inc0** register ([Table 149 on page 238](#)).

If a core uses its MMT channel for intercore transfers, i.e., for transmitting to the other core, it must first program its XIOC[1:0] field (**imux**[15:14]) to either 1 or 2 (DMINT4 or DMINT5). The receiving core must enable its XIO interrupt in its **inc1** register ([Table 149 on page 238](#)). The transmitting core must disable the corresponding MMT interrupt (DMINT4 or DMINT5) in its own **inc0** register.

4 Hardware Architecture (continued)

4.9 Bit Input/Output Units (BIO<0—1>)

The DSP16410B has two bit I/O units, BIO0 for CORE0 and BIO1 for CORE1. Each BIO unit connects to seven bidirectional pins, IO0BIT[6:0] for BIO0 and IO1BIT[6:0] for BIO1. User software running in CORE0 controls and monitors BIO0 via its **sbit** and **cbit** registers. User software running in CORE1 controls and monitors BIO1 via its **sbit** and **cbit** registers. The software can:

- Individually configure each pin as an input or output.
- Read the current state of the pins.
- Test the combined state of input pins.
- Individually set, clear, or toggle output pins.

The DIREC[6:0] field (**sbit**[14:8]—see Table 16) controls the direction of the corresponding IO<0,1>BIT[6:0] pin—a logic 0 configures the pin as an input or a logic 1 configures it as an output. Reset clears the DIREC[6:0] field, configuring all BIO pins as inputs by default. The read-only VALUE[6:0] field (**sbit**[6:0]) contains the current state of the corresponding pin, regardless of whether the pin is configured as an input or output.

The **cbit** register (Table 17 on page 50) contains two 7-bit fields, MODE[6:0]/MASK[6:0] and DATA[6:0]/PAT[6:0]. The meaning of the individual bits in these fields, MODE[n]/MASK[n] and DATA[n]/PAT[n], is based on whether the corresponding IO<0,1>BIT[n] pin is configured as an input or an

output. If IO<0,1>BIT[n] is configured as an input, the fields are MASK[n] and PAT[n]. If IO<0,1>BIT[n] is configured as an output, the fields are MODE[n] and DATA[n]. Table 18 on page 51 summarizes the function of the MODE[6:0]/MASK[6:0] and DATA[6:0]/PAT[6:0] fields.

If the software configures an IO<0,1>BIT[n] pin as an output and:

- If the software clears MODE[n] and clears DATA[n], the BIO<0,1> drives the pin low.
- If the software clears MODE[n] and sets DATA[n], the BIO<0,1> drives the pin high.
- If the software sets MODE[n] and clears DATA[n], the BIO does not change the state of the pin.
- If the software sets MODE[n] and sets DATA[n], the BIO<0,1> toggles (inverts) the state of the pin.

If an IO<0,1>BIT[n] pin is configured as an input and the software sets MASK[n], the BIO<0,1> tests the state of the pin by comparing it to the PAT[n] (pattern) field. BIO<0,1> sets or clears its flags based on the result of the comparison of all its tested inputs:

- ALLT (all true) is set if all of the tested inputs match the test pattern.
- ALLF (all false) is set if all of the tested inputs do not match the test pattern.
- SOMET (some true) is set if some or all of the tested inputs match the test pattern.
- SOMEF (some false) is set if some or all of the tested inputs do not match the test pattern.

Table 16. **sbit** (BIO Status/Control) Register

15		14—8		7		6—0	
Reserved		DIREC[6:0]		Reserved		VALUE[6:0]	
Bit	Field	Value	Description			R/W	Reset Value†
15	Reserved	0	Reserved—write with zero.			R/W	0
14—8	DIREC[6:0] (Controls direction of pins)	0	Configure the corresponding IO<0,1>BIT[6:0] pin as an input.			R/W	0
		1	Configure the corresponding IO<0,1>BIT[6:0] pin as an output.				
7	Reserved	—	Reserved.			R	X
6—0	VALUE[6:0]‡ (Current value of pins)	0	The current state of the corresponding IO<0,1>BIT[6:0] pin is logic 0.			R	P§
		1	The current state of the corresponding IO<0,1>BIT[6:0] pin is logic 1.				

† For this column, X indicates unknown on powerup reset and unaffected on subsequent reset.

‡ This field is read-only—writing the VALUE[6:0] field of **sbit** has no effect. If the user software toggles a bit in the DIREC[6:0] field, there is a latency of one cycle until the VALUE[6:0] field reflects the current state of the corresponding IO<0,1>BIT[6:0] pin. If an IO<0,1>BIT[6:0] pin is configured as an output (DIREC[6:0] = 1) and the user software writes **cbit** to change the state of the pin, there is a latency of two cycles until the VALUE[6:0] field reflects the current state of the corresponding IO<0,1>BIT[6:0] output pin.

§ The IO<0,1>BIT[6:0] pins are configured as inputs after reset. If external circuitry does not drive an IO<0,1>BIT[n] pin, the VALUE[n] field is undefined after reset.

4 Hardware Architecture (continued)

4.9 Bit Input/Output Units (BIO<0—1>) (continued)

Table 17. cbit (BIO Control) Register

15		14—8		7		6—0	
Reserved		MODE[6:0]/MASK[6:0]		Reserved		DATA[6:0]/PAT[6:0]	
Bit	Field	Value	Description			R/W	Reset Value
15	Reserved	0	Reserved—write with zero.			R/W	0
14—8	MODE[6:0] (outputs [†])	0	The BIO drives the corresponding IO<0,1>BIT[6:0] output pin to the corresponding value in DATA[6:0].			R/W	0
		1	<ul style="list-style-type: none"> ■ If the corresponding DATA[6:0] field is 0, the BIO does not change the state of the corresponding IO<0,1>BIT[6:0] output pin. ■ If the corresponding DATA[6:0] field is 1, the BIO toggles (inverts) the state of the corresponding IO<0,1>BIT[6:0] output pin. 				
	MASK[6:0] (inputs [†])	0	The BIO does not test the state of the corresponding IO<0,1>BIT[6:0] input pin to determine the state of the BIO flags [‡] .				
		1	The BIO compares the state of the corresponding IO<0,1>BIT[6:0] input pin to the corresponding value in the PAT[6:0] field to determine the state of the BIO flags [‡] —true if pin matches or false if pin doesn't match.				
7	Reserved	0	Reserved—write with zero.			R/W	0
6—0	DATA[6:0] (outputs [†])	0	<ul style="list-style-type: none"> ■ If the corresponding MODE[6:0] field is 0, the BIO drives the corresponding IO<0,1>BIT[6:0] output pin to logic 0. ■ If the corresponding MODE[6:0] field is 1, the BIO does not change the state of the corresponding IO<0,1>BIT[6:0] output pin. 			R/W	0
		1	<ul style="list-style-type: none"> ■ If the corresponding MODE[6:0] field is 0, the BIO drives the corresponding IO<0,1>BIT[6:0] output pin to logic 1. ■ If the corresponding MODE[6:0] field is 1, the BIO toggles (inverts) the state of the corresponding IO<0,1>BIT[6:0] output pin. 				
	PAT[6:0] (inputs [†])	0	If the corresponding MASK[6:0] field is 1, the BIO tests the state of the corresponding IO<0,1>BIT[6:0] input pin to determine the state of the BIO flags [‡] —true if pin is logic 0 or false if pin is logic 1.				
		1	If the corresponding MASK[6:0] field is 1, the BIO tests the state of the corresponding IO<0,1>BIT[6:0] input pin to determine the state of the BIO flags [‡] —true if pin is logic 1 or false if pin is logic 0.				

† An IO<0,1>BIT[6:0] pin is configured as an output if the corresponding DIREC[6:0] field (**sbit**[14:8]) has been set by the user software. An IO<0,1>BIT[6:0] pin is configured as an input if the corresponding DIREC[6:0] field has been cleared by the user software or by device reset.

‡ The BIO flags are ALLT, ALLF, SOMET, and SOMEF. See Table 19 on page 51 for details on BIO flags.

If all the IO<0,1>BIT[6:0] pins are configured as outputs or if the MASK[n] field is cleared for all pins that are configured as inputs, the BIO<0,1> sets the ALLT and ALLF flags and clears the SOMET and SOMEF flags.

Table 19 on page 51 summarizes the BIO flags, which software can test with conditional instructions (see Table 134 on page 223). Software can test, save, or restore the state of the flags by reading or writing the **alf** register (see Table 140 on page 232). As illustrated in Table 19 on page 51, ALLT is the logical inverse of SOMEF and ALLF is the logical inverse of SOMET.

If an IO<0,1>BIT[n] pin is configured as an input and the software writes **cbit** to change the MASK[n] or

PAT[n] field, there is a latency of two cycles until the DSP16410B updates the BIO flags to reflect the change. The following code segment illustrates this latency by the use of the two **nop** instructions:

```

sbit=0           // All pins are inputs.
cbit=0           // Test no inputs.
...
cbit=0x0302     // Test IOBIT[1:0].
2*nop           // Any 2 instructions.
if allt goto OK // Branch if IOBIT1...
                // is 1 and IOBIT0 is 0.
    
```

4 Hardware Architecture (continued)

4.9 Bit Input/Output Units ($\text{IO}\langle 0,1 \rangle$) (continued)

If an $\text{IO}\langle 0,1 \rangle\text{BIT}[n]$ pin is configured as an output and the software writes **cbit** to change the state of the pin, there is a latency of one cycle until the DSP16410B changes the state of the pin and a latency of an additional cycle until the $\text{VALUE}[n]$ field (**sbit**[6:0]) reflects the change. The use of two **nop** instructions in the following code segment illustrates this latency:

```
sbit=0x1000      // IOBIT4 is an output.
cbit=0x0010      // Drive IOBIT4 high.
nop              // IOBIT4 goes high.
nop              // VALUE4 is updated.
a0h=sbit         // Bit 4 of a0h is 1.
```

If the software writes **sbit** to change an $\text{IO}\langle 0,1 \rangle\text{BIT}[n]$ pin from an input to an output or from an output to an input, there is a latency of one cycle before the $\text{VALUE}[n]$ field of **sbit** is updated to reflect the state of the pin. If the software writes **sbit** to change an $\text{IO}\langle 0,1 \rangle\text{BIT}[n]$ pin from an output to an input and back to an output, the BIO drives the pin with its original output value.

The following code segment illustrates the latency described in the previous paragraph:

```
sbit=0x0F00      // IOBIT[3:0] - output.
cbit=0x000A      // IOBIT[3:0] = 1010
                  // ...after 1 cycle.
cbit=0x0101      // Toggle IOBIT0...
                  // IOBIT[3:0] = 1011
                  // ...after 1 cycle.
sbit=0           // IOBIT[3:0] - input.
sbit=0x0F00      // IOBIT[3:0] - output.
                  // IOBIT[3:0] = 1011
                  // ...after 0 cycles.
nop              // Any instruction.
a0h=sbit         // a0h[3:0] = 1011.
```

Table 18. BIO Operations

DIREC[n] [†]	MODE[n]/ MASK[n] [†]	DATA[n]/ PAT[n] [†]	BIO Action
1 (Output)	0	0	Clear $\text{IO}\langle 0,1 \rangle\text{BIT}[n]$.
		1	Set $\text{IO}\langle 0,1 \rangle\text{BIT}[n]$.
	1	0	Do not change $\text{IO}\langle 0,1 \rangle\text{BIT}[n]$.
		1	Toggle $\text{IO}\langle 0,1 \rangle\text{BIT}[n]$.
0 (Input)	0	X	Do not test [‡] $\text{IO}\langle 0,1 \rangle\text{BIT}[n]$.
		0	Test [‡] $\text{IO}\langle 0,1 \rangle\text{BIT}[n]$ for logic zero.
	1	Test [‡] $\text{IO}\langle 0,1 \rangle\text{BIT}[n]$ for logic one.	

[†] $0 \leq n \leq 6$.

[‡] The BIO tests the state of input pins to determine the states of the BIO flags. See Table 19 for details on the BIO flags.

Table 19. BIO Flags

Condition		ALLT (alf[0])	ALLF (alf[1])	SOMET (alf[2])	SOMEF (alf[3])
All or some of the $\text{IO}\langle 0,1 \rangle\text{BIT}[6:0]$ pins are configured as inputs. [†]	All tested inputs match the pattern. [‡]	1	0	1	0
	All tested inputs do not match the pattern. [§]	0	1	0	1
	Some (but not all) of the tested inputs match the pattern. ^{††}	0	0	1	1
	All of the inputs are not tested. ^{‡‡}	1	1	0	0
All $\text{IO}\langle 0,1 \rangle\text{BIT}[6:0]$ pins are configured as outputs. ^{§§}		1	1	0	0

[†] For at least one pin $\text{IO}\langle 0,1 \rangle\text{BIT}[n]$, $\text{DIREC}[n] = 0$.

[‡] For every pin $\text{IO}\langle 0,1 \rangle\text{BIT}[n]$ with $\text{DIREC}[n] = 0$ and $\text{MASK}[n] = 1$, $\text{IO}\langle 0,1 \rangle\text{BIT}[n] = \text{PAT}[n]$.

[§] For every pin $\text{IO}\langle 0,1 \rangle\text{BIT}[n]$ with $\text{DIREC}[n] = 0$ and $\text{MASK}[n] = 1$, $\text{IO}\langle 0,1 \rangle\text{BIT}[n] \neq \text{PAT}[n]$.

^{††} For at least one pin $\text{IO}\langle 0,1 \rangle\text{BIT}[n]$ with $\text{DIREC}[n] = 0$ and $\text{MASK}[n] = 1$, $\text{IO}\langle 0,1 \rangle\text{BIT}[n] = \text{PAT}[n]$, and for at least one pin $\text{IO}\langle 0,1 \rangle\text{BIT}[n]$ with $\text{DIREC}[n] = 0$ and $\text{MASK}[n] = 1$, $\text{IO}\langle 0,1 \rangle\text{BIT}[n] \neq \text{PAT}[n]$.

^{‡‡} For all pins $\text{IO}\langle 0,1 \rangle\text{BIT}[n]$ with $\text{DIREC}[n] = 0$, $\text{MASK}[n] = 0$.

^{§§} $\text{DIREC}[6:0]$ are all ones.

4 Hardware Architecture (continued)

4.10 Timer Units (TIMER0_⟨0—1⟩ and TIMER1_⟨0—1⟩)

The DSP16410B provides two timer units for each core—TIMER0_0 and TIMER1_0 for CORE0 and TIMER0_1 and TIMER1_1 for CORE1. Each TIMER provides a programmable single interval interrupt or a programmable periodic interrupt. Figure 13 on page 53 is a block diagram of a TIMER that contains:

- A 16-bit control register **timer⟨0,1⟩c** (see Table 20 on page 54).
- A running count register **timer⟨0,1⟩** (see Table 21 on page 55) consisting of a 16-bit down counter and a 16-bit period register.
- A prescaler that divides the internal clock (CLK) by one of 16 programmed values in the range 2 to 65536. The prescaler output clock decrements the **timer⟨0,1⟩** down counter. The programmed prescale value and the value written to **timer⟨0,1⟩** determine the interrupt interval or period.

By default after device reset¹, the DSP16410B clears **timer⟨0,1⟩c** and powers up the TIMER. To save power if the TIMER is not in use, the software can set the PWR_DWN field (**timer⟨0,1⟩c**[6]). Until the user software writes to **timer⟨0,1⟩c** and **timer⟨0,1⟩**, the TIMER does not operate or generate interrupts.

Note: The software can read or write **timer⟨0,1⟩** only if the TIMER is powered up (PWR_DWN = 0).

If the software reads **timer⟨0,1⟩**, the value read is the output of the down counter. If the software writes **timer⟨0,1⟩**, the TIMER loads the write value into the down counter and into the period register simultaneously.

The prescaler consists of a 16-bit up counter and a multiplexer controlled by the PRESCALE[3:0] field (**timer⟨0,1⟩c**[3:0]). PRESCALE[3:0] contains a value N that selects the period of the prescaler output clock as:

$$\frac{2^{N+1}}{f_{CLK}}$$

where f_{CLK} is the frequency of the internal clock (see Section 4.17).

To operate the TIMER (i.e., for the prescaler to decrement the **timer⟨0,1⟩** down counter), the user software must perform the following steps.

- Write **timer⟨0,1⟩c** to program its fields as follows:
 - Write 0 to the PWR_DWN field.
 - Write 0 to the RELOAD field (**timer⟨0,1⟩c**[5]) for a single interval interrupt or write 1 to the RELOAD field for periodic interrupts.
 - Write 1 to the COUNT field (**timer⟨0,1⟩c**[4]) to enable the prescaler output clock.
 - Program the PRESCALE[3:0] field to configure the frequency of the prescaler output clock.
- Write a nonzero value to **timer⟨0,1⟩** to enable the down counter input clock.

The software can perform the above steps in either order, and the TIMER starts after the second step.

If the TIMER is operating and the **timer⟨0,1⟩** down counter reaches zero, the TIMER asserts its interrupt request pulse TIME⟨0,1⟩ (see Section 4.4 for details on interrupts). The interval from starting the TIMER to the occurrence of the first interrupt is the following:

$$\frac{\mathbf{timer}\langle 0,1 \rangle \times 2^{N+1}}{f_{CLK}}$$

If the down counter reaches zero and RELOAD is 0, the TIMER disables the input clock to the down counter, causing the down counter to hold its current value of zero. The user software can restart the TIMER by writing a nonzero value to **timer⟨0,1⟩**.

If the down counter reaches zero and RELOAD is 1, a prescale period elapses and the TIMER reloads the down counter from the **timer⟨0,1⟩** period register. Another prescale period elapses and the prescaler decrements the down counter. Therefore, the subsequent interval between periodic interrupts is the following:

$$\frac{(\mathbf{timer}\langle 0,1 \rangle + 1) \times 2^{N+1}}{f_{CLK}}$$

Software can read or write **timer⟨0,1⟩** while the timer is running. If the software writes **timer⟨0,1⟩**, the TIMER loads the write value into the down counter and period register and initializes the prescaler by clearing the 16-bit up counter. Because the TIMER initializes the prescaler if the software writes **timer⟨0,1⟩**, the interval from writing **timer⟨0,1⟩** to decrementing the down counter is one complete prescale period.

Clearing COUNT disables the clock to the prescaler, causing the down counter to hold its current value and the prescaler to retain its current state. If the TIMER remains powered up (PWR_DWN = 0), software can stop and restart the TIMER at any time by clearing and setting COUNT.

1. After device reset, the DSP16410B clears the down counter of **timer⟨0,1⟩** and leaves the period register of **timer⟨0,1⟩** unchanged.

4 Hardware Architecture (continued)

4.10 Timer Units (TIMER0_⟨0—1⟩ and TIMER1_⟨0—1⟩) (continued)

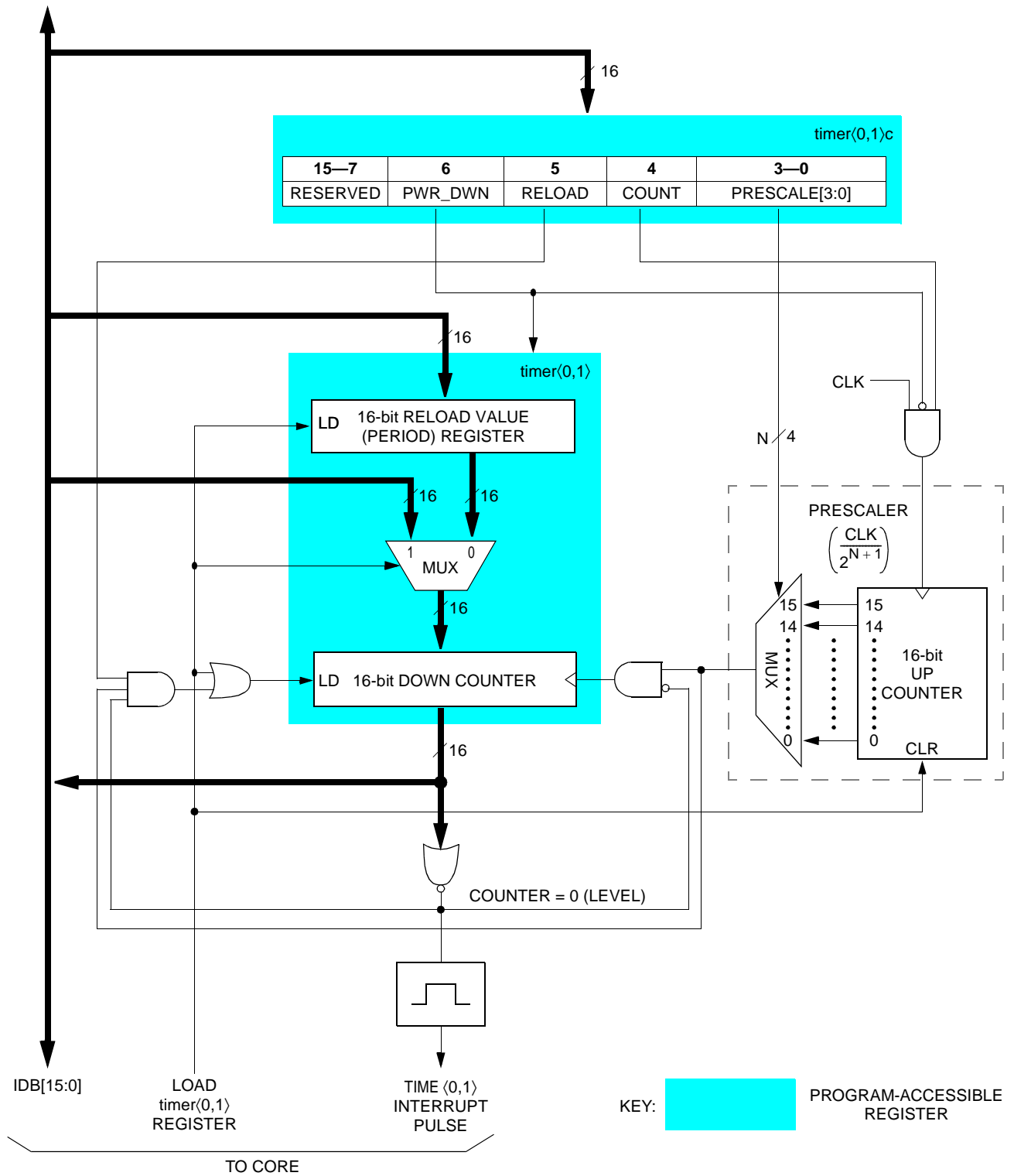


Figure 13. Timer Block Diagram

4 Hardware Architecture (continued)

4.10 Timer Units (TIMER0_⟨0—1⟩ and TIMER1_⟨0—1⟩) (continued)

Table 20. timer⟨0,1⟩c (TIMER⟨0,1⟩ Control) Register

15—7		6	5	4	3—0	
Reserved		PWR_DWN	RELOAD	COUNT	PRESCALE[3:0]	
Bit	Field	Value	Description		R/W	Reset Value
15—7	Reserved	0	Reserved—write with zero.		R/W	0
6	PWR_DWN	0	Power up the timer.		R/W	0
		1	Power down the timer†.			
5	RELOAD	0	Stop decrementing the down counter after it reaches zero.		R/W	0
		1	Automatically reload the down counter from the period register after the counter reaches zero and continue decrementing the counter indefinitely.			
4	COUNT	0	Hold the down counter at its current value, i.e., stop the timer.		R/W	0
		1	Decrement the down counter, i.e., run the timer.			
3—0	PRESCALE[3:0]	0000	Controls the counter prescaler to determine the frequency of the timer, i.e., the frequency of the clock applied to the timer down counter. This frequency is a ratio of the internal clock frequency f _{CLK} .	f _{CLK} /2	R/W	0000
		0001		f _{CLK} /4		
		0010		f _{CLK} /8		
		0011		f _{CLK} /16		
		0100		f _{CLK} /32		
		0101		f _{CLK} /64		
		0110		f _{CLK} /128		
		0111		f _{CLK} /256		
		1000		f _{CLK} /512		
		1001		f _{CLK} /1024		
		1010		f _{CLK} /2048		
		1011		f _{CLK} /4096		
		1100		f _{CLK} /8192		
		1101		f _{CLK} /16384		
		1110		f _{CLK} /32768		
		1111		f _{CLK} /65536		

† If TIMER⟨0,1⟩ is powered down, timer⟨0,1⟩ cannot be read or written. While the timer is powered down, the state of the down counter and period register remain unchanged.

4 Hardware Architecture (continued)

4.10 Timer Units (TIMER0_⟨0—1⟩ and TIMER1_⟨0—1⟩) (continued)

Table 21. timer⟨0,1⟩ (TIMER⟨0,1⟩ Running Count) Register

15—0				
TIMER⟨0,1⟩ Down Counter				
TIMER⟨0,1⟩ Period Register				
Bit	Field†	Description	R/W‡	Reset Value§
15—0	Down Counter	If the COUNT field (timer⟨0,1⟩c[4]) is set, TIMER⟨0,1⟩ decrements this portion of the timer⟨0,1⟩ register every prescale period. When the down counter reaches zero, TIMER⟨0,1⟩ generates an interrupt.	R/W	0
15—0	Period Register	If the COUNT field (timer⟨0,1⟩c[4]) and the RELOAD field (timer⟨0,1⟩c[5]) are both set and the down counter contains zero, TIMER⟨0,1⟩ reloads the down counter with the contents of this portion of the timer⟨0,1⟩ register.	W	X

† If the user program writes to the **timer⟨0,1⟩** register, TIMER⟨0,1⟩ loads the 16-bit write value into the down counter and into the period register simultaneously. If the user program reads the **timer⟨0,1⟩** register, TIMER⟨0,1⟩ returns the current 16-bit value from the down counter.

‡ To read or write the **timer⟨0,1⟩** register, TIMER⟨0,1⟩ must be powered up, i.e., the PWR_DWN field (**timer⟨0,1⟩c[6]**) must be cleared.

§ For this column, X indicates unknown on powerup reset and unaffected on subsequent reset.

4.11 Hardware Development System (HDS⟨0—1⟩)

The DSP16410B provides an on-chip hardware development module for each of the two cores (HDS⟨0—1⟩).

Each HDS is available for debugging assembly-language programs that execute on the DSP16000 core at the core's rated speed. The main capability of the HDS is allowing controlled visibility into the core's state during program execution.

The fundamental steps in debugging an application using the HDS include the following:

1. Setup: Download program code and data into the correct memory regions and set breakpointing conditions.
2. Run: Start execution or single step from a desired starting point (i.e., allow device to run under simulated or real-time conditions).
3. Break: Break program execution on satisfying breakpointing conditions; upload and allow user accessibility to internal state of the device and its pins.
4. Resume: Resume execution (normally or single step) after hitting a breakpoint and finally upload internal state at the end of execution.

A powerful debugging capability of the HDS is the ability to break program execution on complex breakpointing conditions. A complex breakpoint condition, for example, can be an instruction that executes from a particular instruction-address location (or from a partic-

ular instruction-address range such as a subroutine) and accesses a coefficient/data element from a specific memory location (or from a memory region such as inside an array or outside an array). Complex conditions can also be chained to form more complex breakpoint conditions. For example, a complex breakpoint condition can be defined as the back-to-back execution of two different subroutines.

The HDS also provides a debugging feature that allows a number of complex breakpoints to be ignored. The number of breakpoints ignored is programmable by the user.

An intelligent trace mechanism for recording discontinuity points during program execution is also available in the HDS. This mechanism allows unambiguous reconstruction of program flow involving discontinuity points such as gotos, calls, returns, and interrupts. The trace mechanism compresses single-level (non-nested) loops and records them as a single discontinuity. This feature prevents single-level loops from filling up the trace buffers. Also, cache loops do not get registered as discontinuities in the trace buffers. Therefore, two-level loops with inner cache loops are registered as a single discontinuity.

The HDS provides a 32-bit cycle counter for accurate code profiling during program development. The cycle counter records processor CLK cycles between user-defined start and end points. The cycle counter can optionally be used to break program execution after a user-specified number of clock cycles.

4 Hardware Architecture (continued)

4.12 JTAG Test Port (JTAG<0—1>)

The DSP16410B provides an on-chip *IEEE* 1149.1 compliant JTAG port for each of the two cores (JTAG<0—1>). JTAG is an on-chip hardware module that controls the HDS. All communication between the HDS software, running on the host computer, and the on-chip HDS is in a bit-serial manner through the JTAG port. The JTAG port pins consist of test data input, TDI<0—1>, test data output, TDO<0—1>, test mode

select, TMS<0—1>, test clock, TCK<0—1>, and test reset, TRST<0—1>N.

The set of test registers includes the JTAG identification register (ID), the boundary-scan register, and the scannable peripheral registers.

4.12.1 Port Identification

Each JTAG port has a read-only identification register, **ID**, as defined in [Table 22](#). As specified in the table, the contents of the **ID** register for JTAG0 is 0x2C81403B and the contents of the **ID** register for JTAG1 is 0x3C81403B.

Table 22. ID (JTAG Identification) Register

31—28		27—19		18—12		11—0	
DEVICE OPTIONS		ROMCODE		PART ID		AGERE ID	
Bit	Field	Value	Description	R/W	Reset Value		
31—28	DEVICE OPTIONS	0x2	JTAG0—device options.	R	0x2		
		0x3	JTAG1—device options.		0x3		
27—19	ROMCODE	0x190	ROMCODE of device.		0x190		
18—12	PART ID	0x14	Part ID—DSP16410B.		0x14		
11—0	AGERE ID	0x03B	Agere identification.	0x03B			

4 Hardware Architecture (continued)

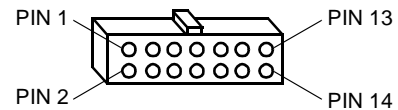
4.12 JTAG Test Port (JTAG<0—1>) (continued)

4.12.2 Emulation Interface Signals to the DSP16410B

For in-circuit emulation and application software debugging, the Agere *TargetView™* Communication System (TCS) provides communication between a host PC and one or more DSP16410B devices. Users of the TCS hardware have the option of using one of three connectors to interface this tool with DSP16410B devices on the target application. The pinouts for these connectors are described in the following three sections.

4.12.2.1 TCS 14-Pin Header

The TCS interface pod provides a 14-pin, dual-row (0.10 in. x 0.10 in.) socket (female) for connection to the user's target hardware. [Figure 14](#) illustrates the pinout of this connector. [Table 23](#) describes the signal names and their relationship to the DSP16410B signals.



5-7333 (F)

Figure 14. TCS 14-Pin Connector

Table 23. TCS 14-Pin Socket Pinout

TCS Pin Number	TCS Signal Name	Description	TCS I/O	DSP16410B Pin Number	DSP16410B Signal Name	DSP16410B I/O
1	TCK	Test clock	O	F4 and L13	TCK0 and TCK1	I
2	NC	No connect	NA	NA	NA	NA
3	Ground	System ground	G	See Section 7 on page 250	VSS	G
4	Ground	System ground	G	See Section 7 on page 250	VSS	G
5	TMS	Test mode select	O	G2 and K15	TMS0 and TMS1	I
6	VTARG	Target I/O voltage	I	See Section 7 on page 250	VDD2	P
7	NC	No connect	NA	NA	NA	NA
8	NC	No connect	NA	NA	NA	NA
9	TDO	Test data output	I	F1 or L16 (not both)	TDO0 or TDO1 (not both)	O
10	TDI	Test data input	O	G1 or K16 (not both)	TDI0 or TDI1 (not both)	I
11	Ground	System ground	G	See Section 7 on page 250	VSS	G
12	Ground	System ground	G	See Section 7 on page 250	VSS	G
13	NC	No connect	NA	NA	NA	NA
14	NC	No connect	NA	NA	NA	NA

4 Hardware Architecture (continued)

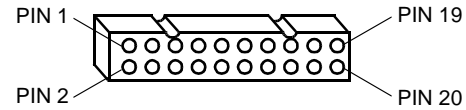
4.12 JTAG Test Port (JTAG<0—1>) (continued)

4.12.2 Emulation Interface Signals to the DSP16410B (continued)

4.12.2.2 JCS 20-Pin Header

The TCS tools provide an interface adapter to convert the 14-pin interface pod to a 20-pin dual-row (0.05 in. x 0.10 in.) socket (female, 3M¹ part number 82020-6006) for connection to the user's target hardware. Figure 15 illustrates the pinout of this

connector. Table 24 describes the signal names and their relationship to the DSP16410B signals. This connector is also compatible with the Agere JTAG communications system (JCS) tools.



5-7334 (F)

Figure 15. JCS 20-Pin Connector

Table 24. JCS 20-Pin Socket Pinout

JCS Pin Number	JCS Signal Name	Description	JCS I/O	DSP16410B Pin Number	DSP16410B Signal Name	DSP16410B I/O
1	NC	No connect	NA	NA	NA	NA
2	Ground	System ground	G	See Section 7 on page 250	VSS	G
3	NC	No connect	NA	NA	NA	NA
4	NC	No connect	NA	NA	NA	NA
5	NC	No connect	NA	NA	NA	NA
6	TMS	Test mode select	O	G2 and K15	TMS0 and TMS1	I
7	Ground	System ground	G	See Section 7 on page 250	VSS	G
8	VTARG	Target I/O voltage	I	See Section 7 on page 250	VDD2	P
9	NC	No connect	NA	NA	NA	NA
10	Ground	System ground	G	See Section 7 on page 250	VSS	G
11	NC	No connect	NA	NA	NA	NA
12	TDI	Test data input	O	G1 or K16 (not both)	TDI0 or TDI1 (not both)	I
13	Ground	System ground	G	See Section 7 on page 250	VSS	G
14	TCK	Test clock	O	F4 and L13	TCK0 and TCK1	I
15	Ground	System ground	G	See Section 7 on page 250	VSS	G
16	TDO	Test data output	I	F1 or L16 (not both)	TDO0 or TDO1 (not both)	O
17	NC	No connect	NA	NA	NA	NA
18	Ground	System ground	G	See Section 7 on page 250	VSS	G
19	NC	No connect	NA	NA	NA	NA
20	NC	No connect	NA	NA	NA	NA

1. 3M is a registered trademark of Minnesota Mining and Manufacturing Company.

4 Hardware Architecture (continued)

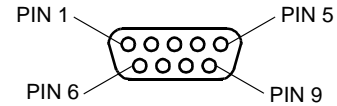
4.12 JTAG Test Port (JTAG<0—1>) (continued)

4.12.2 Emulation Interface Signals to the DSP16410B (continued)

4.12.2.3 HDS 9-Pin, D-Type Connector

The TCS tools also provide an interface adapter to convert the 14-pin interface pod to a 9-pin, subminiature, D-type plug (male) for connection to the user's target hardware. Figure 16 illustrates the pinout of this connector. Table 25 describes the signal names and

their relationship to the DSP16410B signals. This connector is also compatible with the Agere JTAG communications system (JCS) and hardware development system (HDS) tools.



5-7335 (F)

Figure 16. HDS 9-Pin Connector

Table 25. HDS 9-Pin, Subminiature, D-Type Plug Pinout

HDS Pin Number	HDS Signal Name	Description	HDS I/O	DSP16410B Pin Number	DSP16410B Signal Name	DSP16410B I/O
1	Ground	System ground	G	See Section 7 on page 250	VSS	G
2	TCK	Test clock	O	F4 and L13	TCK0 and TCK1	I
3	NC	No connect	NA	NA	NA	NA
4	TMS	Test mode select	O	G2 and K15	TMS0 and TMS1	I
5	Ground	System ground	G	See Section 7 on page 250	VSS	G
6	TDO	Test data output	I	F1 or L16 (not both)	TDO0 or TDO1 (not both)	O
7	TDI	Test data input	O	G1 or K16 (not both)	TDI0 or TDI1 (not both)	I
8	VTARG	Target I/O voltage	I	See Section 7 on page 250	VDD2	P
9	NC	No connect	NA	NA	NA	NA

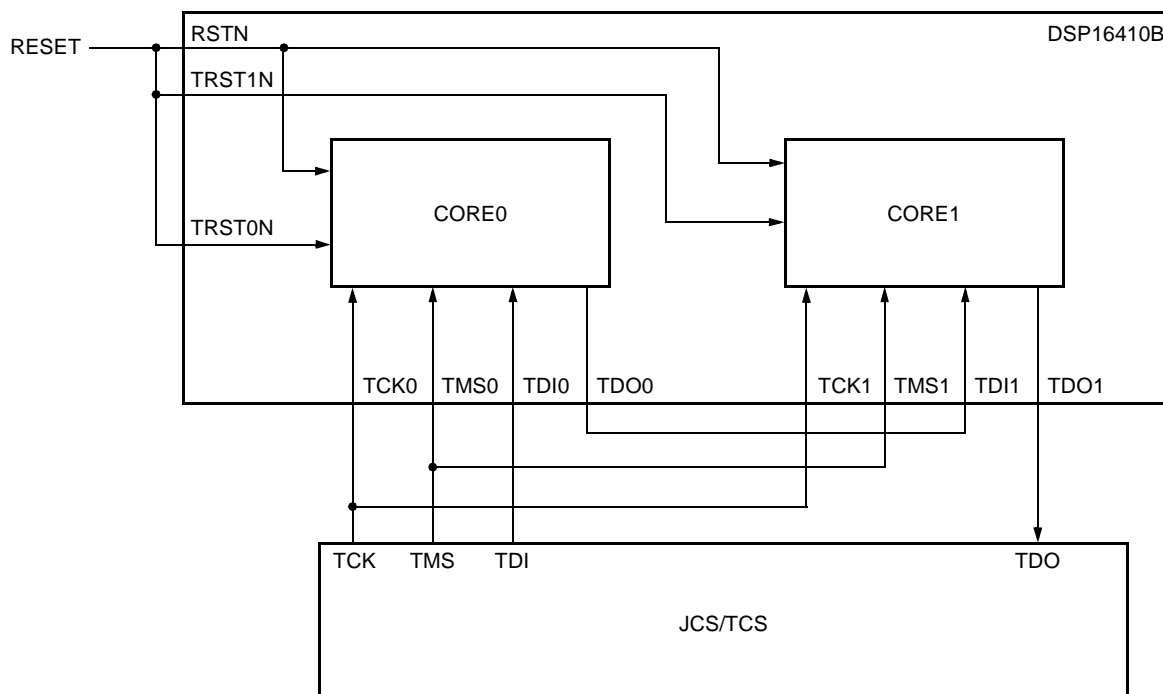
4 Hardware Architecture (continued)

4.12 JTAG Test Port (JTAG<0—1>) (continued)

4.12.3 Multiprocessor JTAG Connections

The DSP16410B has two JTAG ports, one for each DSP16000 core. The user can daisy-chain these ports onto the same scan chain, potentially with other DSP16410B devices, or interface to each JTAG port individually for debugging. If multiple JTAG ports are interfaced together on the same scan chain, TMS and TCK are broadcast to all DSPs in the scan chain. TDI of the first JTAG port in the chain is then connected to

TDI of the TCS connector on the user's board, TDO of the first JTAG port is connected to TDI of the next JTAG port in the chain, and so on. TDO of the last JTAG port in the chain is then tied to TDO of the TCS connector. If more than six JTAG ports are in the same scan chain, TMS and TCK **must** be buffered to ensure compatibility with t155 and t156 (See Table 190 on page 282). In the typical application, the user's board ties the DSP16410B JTAG reset signals, TRST0N and TRST1N, to the device reset, RSTN. Figure 17 illustrates a typical daisy-chain connection between the TCS hardware and the two cores of a single DSP16410B.



Note: CORE0 is DSP1 on the scan chain and CORE1 is DSP2 on the scan chain. For multiple DSP16410B devices on a single scan chain, maintain the CORE0-to-CORE1 daisy chain.

Figure 17. Typical Multiprocessor JTAG Connection with Single Scan Chain

4 Hardware Architecture (continued)

4.12 JTAG Test Port (JTAG<0—1>) (continued)

4.12.4 Boundary Scan

JTAG0 contains a full boundary-scan register as described in Table 26 and JTAG1 contains a single-bit boundary-scan register as described in Table 27 on page 62. As described in Section 4.12.3, JTAG0 and JTAG1 of multiple DSP16410B devices can be chained together with full boundary-scan capabilities.

Table 26. JTAG0 Boundary-Scan Register

Cell	Type [†]	Signal Name/ Function	Control Cell	Cell	Type [†]	Signal Name/ Function	Control Cell
0	I	ERTYPE	—	87	DC	IO1BIT[1] direction control	—
1	I	EXM	—	88	I/O	IO1BIT[1]	87
2	I	ESIZE	—	89	DC	IO1BIT[2] direction control	—
3	I	EREQN	—	90	I/O	IO1BIT[2]	89
4	I	ERDY	—	91	DC	IO1BIT[3] direction control	—
20—5	I/O	ED[15:0]	21	92	I/O	IO1BIT[3]	91
21	DC	ED[15:0] direction control	—	93	DC	IO1BIT[4] direction control	—
37—22	I/O	ED[31:16]	38	94	I/O	IO1BIT[4]	93
38	DC	ED[31:16] direction control	—	95	DC	IO1BIT[5] direction control	—
39	O	EACKN	65	96	I/O	IO1BIT[5]	95
41—40	O	ERWN[1:0]	45	97	DC	IO1BIT[6] direction control	—
42	O	EROMN	45	98	I/O	IO1BIT[6]	97
43	O	ERAMN	45	99	DC	IO1BIT[7] direction control‡	—
44	O	EION	45	100	I/O	IO1BIT[7]‡	99
45	OE	EION, ERAMN, EROMN, ERWN[1:0] 3-state control	—	104—101	I	PADD[3:0]	—
64—46	O	EA[18:0]	65	105	I	PCSN	—
65	OE	EA[18:0] 3-state control	—	106	I	PRWN	—
69—66	O	ESEG[3:0]	70	107	I	PIDS	—
70	OE	ESEG[3:0] 3-state control	—	108	I	PODS	—
71	OE	ECKO and EACKN 3-state control	—	109	I	PRDYMD	—
72	O	ECKO	71	110	O	PINT	114
73	OE	SOD1 3-state control	—	111	O	PRDY	114
74	O	SOD1	73	112	O	PIBF	114
75	I	SID1	—	113	O	POBE	114
76	I	SCK1	—	114	OE	PINT, PRDY, PIBF, POBE 3-state control	—
77	DC	SOFS1 direction control	—	130—115	I/O	PD[15:0]	131
78	I/O	SOFS1	77	131	DC	PD[15:0] direction control	—
79	DC	SOCK1 direction control	—	132	I	EYMODE	—
80	I/O	SOCK1	79	133	DC	IO0BIT[0] direction control	—
81	DC	SIFS1 direction control	—	134	I/O	IO0BIT[0]	132
82	I/O	SIFS1	81	135	DC	IO0BIT[1] direction control	—
83	DC	SICK1 direction control	—	136	I/O	IO0BIT[1]	134
84	I/O	SICK1	83	137	DC	IO0BIT[2] direction control	—
85	DC	IO1BIT[0] direction control	—	138	I/O	IO0BIT[2]	136
86	I/O	IO1BIT[0]	85	139	DC	IO0BIT[3] direction control	—

† Key to this column: I = input; OE = 3-state control cell; O = output; DC = bidirectional control cell; I/O = input/output.

‡ There is no pin associated with this signal. This is a pad only and is not connected in the package.

4 Hardware Architecture (continued)

4.12 JTAG Test Port (JTAG(0—1)) (continued)

4.12.4 Boundary Scan (continued)

Table 26. JTAG0 Boundary-Scan Register (continued)

Cell	Type†	Signal Name/ Function	Control Cell	Cell	Type†	Signal Name/ Function	Control Cell
140	I/O	IO0BIT[3]	138	153	DC	SOFS0 direction control	—
141	DC	IO0BIT[4] direction control	—	154	I/O	SOFS0	152
142	I/O	IO0BIT[4]	140	155	DC	SOCK0 direction control	—
143	DC	IO0BIT[5] direction control	—	156	I/O	SOCK0	154
144	I/O	IO0BIT[5]	142	157	DC	SIFS0 direction control	—
145	DC	IO0BIT[6] direction control	—	158	I/O	SIFS0	156
146	I/O	IO0BIT[6]	144	159	DC	SICK0 direction control	—
147	DC	IO0BIT[7] direction control‡	—	160	I/O	SICK0	158
148	I/O	IO0BIT[7]‡	146	164—161	I	INT[3:0]	—
149	OE	SOD0 3-state control	—	165	DC	TRAP direction control	—
150	O	SOD0	148	166	I/O	TRAP	164
151	I	SID0	—	167	I	RSTN	—
152	I	SCK0	—	168	I	CKI	—

† Key to this column: I = input; OE = 3-state control cell; O = output; DC = bidirectional control cell; I/O = input/output.

‡ There is no pin associated with this signal. This is a pad only and is not connected in the package.

Table 27. JTAG1 Boundary-Scan Register

Cell	Function	Control Cell
0	Internal Cell	—

4 Hardware Architecture (continued)

4.13 Direct Memory Access Unit (DMAU)

The DMAU (direct memory access unit) manages movement of data to or from the DSP16410B internal or external memory with minimal core intervention:

- The DMAU can move data between memory and the I/O units:
 - The DMAU provides four single-word transfer (SWT) channels for moving data between memory and SIU(0—1). A core initially defines the data structure and the DMAU provides address generation, compare, and update functions. Two-dimensional array capability facilitates applications such as TDM channel multiplexing/demultiplexing. Each SWT channel allows an SIU to access memory one word (16 bits) at a time.
 - The DMAU provides a single addressing bypass channel for moving data between memory and the PIU. Unlike the SWT channels, the bypass channel does not provide address generation, compare, and update functions. The bypass channel allows a host to address and access memory one word (16 bits) at a time.
- The DMAU can move data between two blocks of memory. It provides two memory-to-memory (MMT) channels for which a core initially defines the data structure. The DMAU provides address generation, compare, and update functions for each channel. The DMAU can perform a block transfer either a single word (16 bits) at a time or a double word (32 bits) at a time.

4.13.1 Overview

The DMAU has six independent channels and an addressing bypass channel as detailed in [Table 28](#). These channels can access any DSP16410B memory

component, including TPRAM0, TPRAM1, and external memory.

[Figure 18 on page 64](#) is a functional overview of the DMAU channels and their interconnections to the peripherals and memory buses. The DMAU arbitrates among the seven channels for access to the memory.

For an SWT channel, a core can define a data structure (array) in DSP16410B memory by programming DMAU memory-mapped registers. The DMAU can then perform source or destination **transfers**. A **source transfer** is defined as a series of read operations from the memory array to an SIU. A **destination transfer** is defined as a series of write operations to the memory array from an SIU. A transfer consists of a series of **transactions** in response to SIU requests. A **source transaction** is defined as reading a word (16 bits) from the array, writing the word to the SIU output data register (**SODR**), and updating the appropriate DMAU registers. A **destination transaction** is defined as reading a word from the SIU input data register (**SIDR**), writing the word to the array, and updating the appropriate DMAU registers. See [Section 4.13.5](#) for details on SWT transactions.

The DMAU also provides two channels for memory-to-memory transfers (MMT). These channels allow a user-defined block of data to be transferred between any two DSP16410B memory blocks, including external memory. Each MMT channel transfers data between a **source block** and a **destination block**. The DMAU can perform a block transfer either a single word (16 bits) at a time or a double word (32 bits) at a time. See [Section 4.13.6](#) for details on memory-to-memory block transfers.

Finally, the DMAU provides an addressing bypass channel that is dedicated to the PIU. This channel bypasses the DMAU address generation, compare, and update processes. The DMAU relies on the PIU to provide the memory address for each PIU transaction

Table 28. DMAU Channel Assignment

DMAU Channel	Description	Associated With
SWT0	Single-word (16-bit) transfers	SIU0
SWT1	Single-word (16-bit) transfers	
SWT2	Single-word (16-bit) transfers	SIU1
SWT3	Single-word (16-bit) transfers	
MMT4	Single-word (16-bit) or double-word (32-bit) transfers	Memory
MMT5	Single-word (16-bit) or double-word (32-bit) transfers	
Bypass	Single-word (16-bit) transfers	PIU

4 Hardware Architecture (continued)

4.13 Direct Memory Access Unit (DMAU) (continued)

4.13.1 Overview (continued)

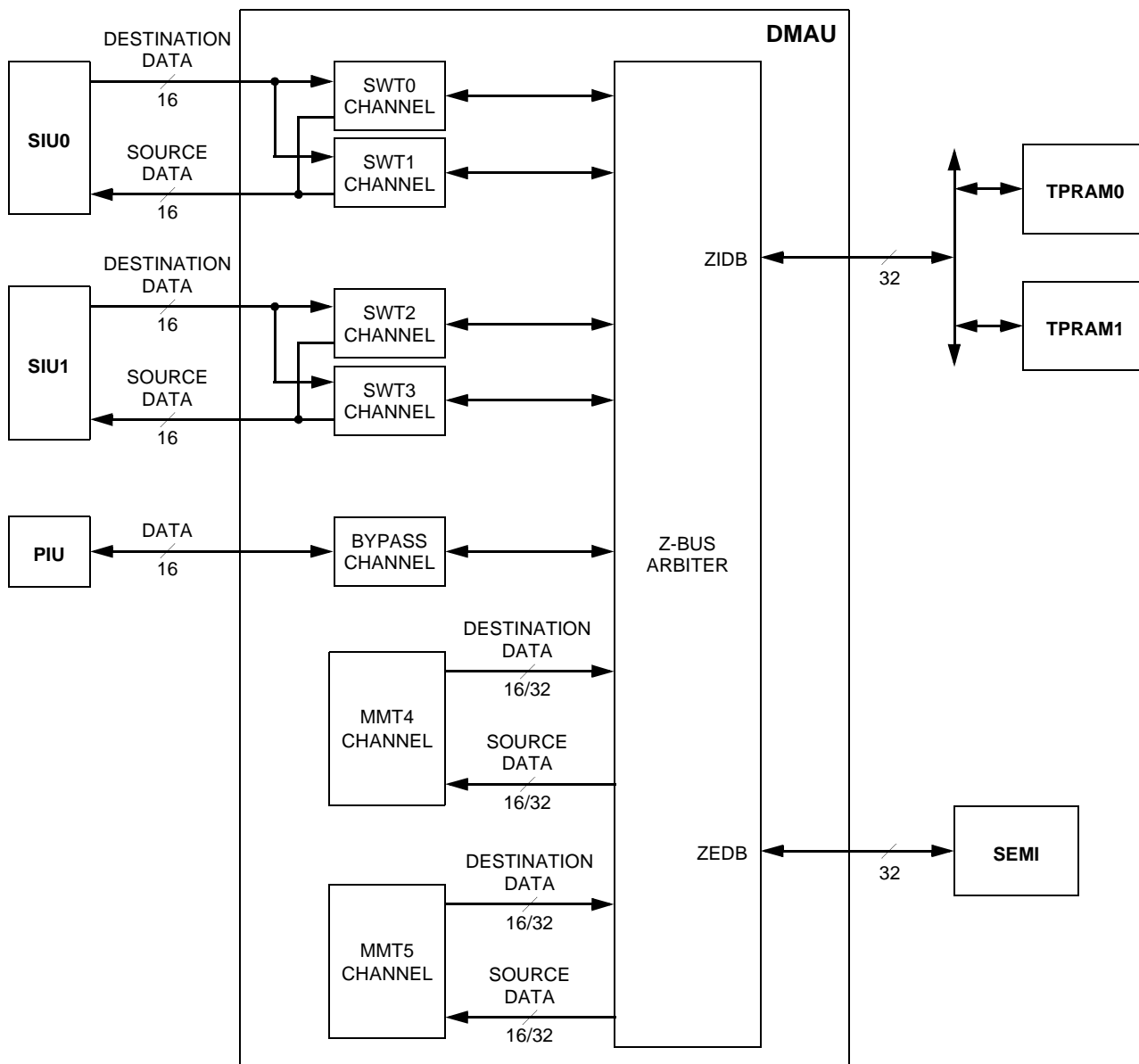


Figure 18. DMAU Interconnections and Channels

Figure 19 is a block diagram of the DMAU. The DMAU includes 55 memory-mapped registers that it uses in processing source transfers, destination transfers, and memory-to-memory block transfers. These registers are configured by programs running in the cores that access the registers. The registers control the DMAU and contain its current status. See Section 4.13.2 for details on these registers. Although the DMAU registers are memory-mapped, they are physically located in the DMAU and are accessible by either core via the SEMI and the SDB (system data bus).

4 Hardware Architecture (continued)

4.13 Direct Memory Access Unit (DMAU) (continued)

4.13.1 Overview (continued)

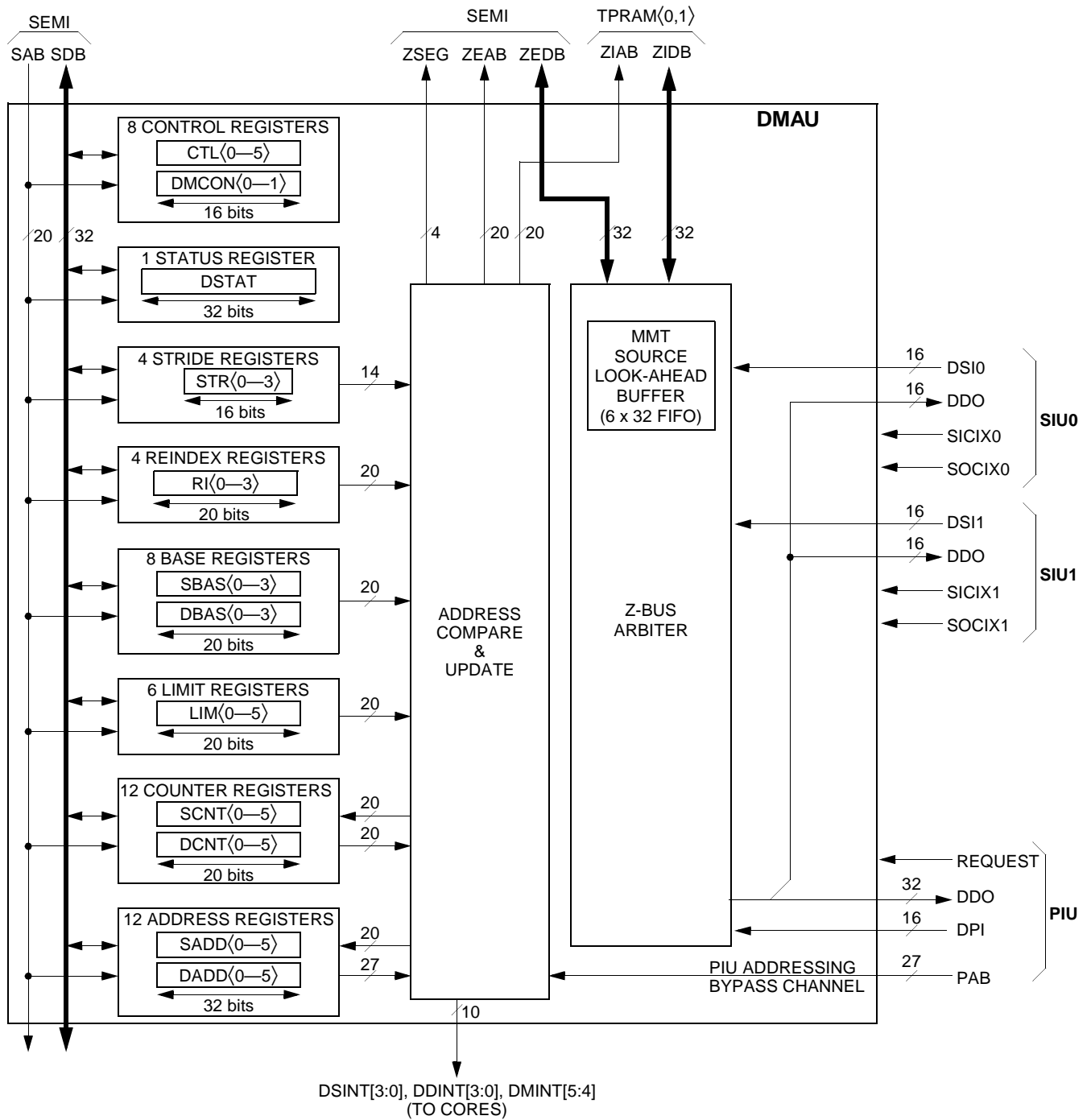


Figure 19. DMAU Block Diagram

4 Hardware Architecture (continued)

4.13 Direct Memory Access Unit (DMAU) (continued)

4.13.2 Registers

Table 29 lists the DMAU memory-mapped registers in functional order, not in address order. Section 6.2.2 on page 228 describes addressing of memory-mapped registers. The DMAU contains a status register and two master control registers for all SWT and MMT channels, **DMCON0**, **DMCON1**, and **DSTAT**. Every DMAU channel has a corresponding control register **CTL<0–5>**, source and destination address register (**SADD<0–5>**) and **DADD<0–5>**, source and destination counter register (**SCNT<0–5>**) and **DCNT<0–5>**, and limit register (**LIM<0–5>**). In addition, each SWT channel has a corresponding source and destination base address register (**SBAS<0–3>** and **DBAS<0–3>**), reindex register (**RI<0–3>**), and stride register (**STR<0–3>**).

Table 29. DMAU Memory-Mapped Registers

Type	Register Name	Channel	Address	Size (Bits)	R/W	Type	Signed/Unsigned	Reset Value†					
DMAU Status	DSTAT	All	0x4206C	32	R	status	unsigned	X					
DMAU Master Control 0	DMCON0	All	0x4205C	16	R/W	control	unsigned	0					
DMAU Master Control 1	DMCON1	All	0x4205E										
Channel Control	CTL0	SWT0	0x42060	16	R/W	control	unsigned	X					
	CTL1	SWT1	0x42062										
	CTL2	SWT2	0x42064										
	CTL3	SWT3	0x42066										
	CTL4	MMT4	0x42068										
	CTL5	MMT5	0x4206A										
Source Address	SADD0	SWT0	0x42000	32	R/W	address	unsigned	X					
Destination Address	DADD0		0x42002										
Source Address	SADD1	SWT1	0x42004										
Destination Address	DADD1		0x42006										
Source Address	SADD2	SWT2	0x42008										
Destination Address	DADD2		0x4200A										
Source Address	SADD3	SWT3	0x4200C										
Destination Address	DADD3		0x4200E										
Source Address	SADD4	MMT4	0x42010										
Destination Address	DADD4		0x42012										
Source Address	SADD5	MMT5	0x42014										
Destination Address	DADD5		0x42016										
Source Count	SCNT0	SWT0	0x42020						20	R/W	data	unsigned	X
Destination Count	DCNT0		0x42022										
Source Count	SCNT1	SWT1	0x42024										
Destination Count	DCNT1		0x42026										
Source Count	SCNT2	SWT2	0x42028										
Destination Count	DCNT2		0x4202A										
Source Count	SCNT3	SWT3	0x4202C										
Destination Count	DCNT3		0x4202E										
Source Count	SCNT4	MMT4	0x42030										
Destination Count	DCNT4		0x42032										
Source Count	SCNT5	MMT5	0x42034										
Destination Count	DCNT5		0x42036										

† For this column, X indicates unknown on powerup reset and unaffected on subsequent reset. Any reserved fields within the register are reset to zero.

‡ The reindex registers are in sign-magnitude format.

4 Hardware Architecture (continued)

4.13 Direct Memory Access Unit (DMAU) (continued)

4.13.2 Registers (continued)

Table 29. DMAU Memory-Mapped Registers (continued)

Type	Register Name	Channel	Address	Size (Bits)	R/W	Type	Signed/Unsigned	Reset Value [†]
Limit	LIM0	SWT0	0x42050	20	R/W	data	unsigned	X
	LIM1	SWT1	0x42052					
	LIM2	SWT2	0x42054					
	LIM3	SWT3	0x42056					
	LIM4	MMT4	0x42058					
	LIM5	MMT5	0x4205A					
Source Base	SBAS0	SWT0	0x42040	20	R/W	address	unsigned	X
Destination Base	DBAS0		0x42042					
Source Base	SBAS1	SWT1	0x42044					
Destination Base	DBAS1		0x42046					
Source Base	SBAS2	SWT2	0x42048					
Destination Base	DBAS2		0x4204A					
Source Base	SBAS3	SWT3	0x4204C					
Destination Base	DBAS3		0x4204E					
Stride	STR0	SWT0	0x42018	16	R/W	data	unsigned	X
	STR1	SWT1	0x4201A					
	STR2	SWT2	0x4201C					
	STR3	SWT3	0x4201E					
Reindex	RI0	SWT0	0x42038	20	R/W	data	signed [‡]	X
	RI1	SWT1	0x4203A					
	RI2	SWT2	0x4203C					
	RI3	SWT3	0x4203E					

[†] For this column, X indicates unknown on powerup reset and unaffected on subsequent reset. Any reserved fields within the register are reset to zero.

[‡] The reindex registers are in sign-magnitude format.

Note: The remainder of this section describes the detailed encoding for each register.

4 Hardware Architecture (continued)

4.13 Direct Memory Access Unit (DMAU) (continued)

4.13.2 Registers (continued)

The DMAU status register (**DSTAT**) reports current DMAU channel activity for both source and destination operations and reports channel errors. This register can be read by the user software executing in either core to determine if a specific DMAU channel is already in use, or if an error has occurred that may result in data corruption. The ERR[5:0] fields of the **DSTAT** register reflect DMAU protocol errors. See [Section 4.13.8 on page 93](#) for information on error reporting and recovery.

Table 30. DSTAT (DMAU Status) Register

The memory address for this register is 0x4206C.

31	30	29	28	27	26	25	24	23	22	21	20	19	18	17	16
RBSY5	RBSY4	SBSY5	DBSY5	SRDY5	DRDY5	ERR5	SBSY4	DBSY4	SRDY4	DRDY4	ERR4	SBSY3	DBSY3	SRDY3	DRDY3
15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
ERR3	SBSY2	DBSY2	SRDY2	DRDY2	ERR2	SBSY1	DBSY1	SRDY1	DRDY1	ERR1	SBSY0	DBSY0	SRDY0	DRDY0	ERR0

Bits	Field	Value	Description	R/W	Reset Value [†]
31	RBSY5	1	MMT5 is busy completing a reset operation [‡] .	R	X
		0	MMT5 is not completing a reset operation.		
30	RBSY4	1	MMT4 is busy completing a reset operation [‡] .	R	X
		0	MMT4 is not completing a reset operation.		
29	SBSY5	1	MMT5 is reading memory.	R	X
		0	MMT5 is not reading memory.		
28	DBSY5	1	MMT5 is writing memory.	R	X
		0	MMT5 is not writing memory.		
27	SRDY5	1	MMT5 has a source transaction pending.	R	X
		0	MMT5 does not have a source transaction pending.		
26	DRDY5	1	MMT5 has a destination transaction pending.	R	X
		0	MMT5 does not have a destination transaction pending.		
25	ERR5	1	MMT5 has detected a protocol error (source or destination). Error report is cleared by writing a 1 to this bit.	R/Clear	X
		0	MMT5—no errors.		
24	SBSY4	1	MMT4 is reading memory.	R	X
		0	MMT4 is not reading memory.		
23	DBSY4	1	MMT4 is writing memory.	R	X
		0	MMT4 is not writing memory.		
22	SRDY4	1	MMT4 has a source transaction pending.	R	X
		0	MMT4 does not have a source transaction pending.		
21	DRDY4	1	MMT4 has a destination transaction pending.	R	X
		0	MMT4 does not have a destination transaction pending.		
20	ERR4	1	MMT4 has detected a protocol error (source or destination). Error report is cleared by writing a 1 to this bit.	R/Clear	X
		0	MMT4—no errors.		
19	SBSY3	1	SWT3 is reading memory.	R	X
		0	SWT3 is not reading memory.		
18	DBSY3	1	SWT3 is writing memory.	R	X
		0	SWT3 is not writing memory.		

[†] For this column, X indicates unknown on powerup reset and unaffected on subsequent reset.

[‡] A core resets MMT5 by setting the RESET5 field (**DMCON1**[5]—[Table 32 on page 71](#)) and resets MMT4 by setting the RESET4 field (**DMCON1**[4]).

4 Hardware Architecture (continued)

4.13 Direct Memory Access Unit (DMAU) (continued)

4.13.2 Registers (continued)

Table 30. DSTAT (DMAU Status) Register (continued)

Bits	Field	Value	Description	R/W	Reset Value [†]
17	SRDY3	1	SWT3 has a source transaction pending.	R	X
		0	SWT3 does not have a source transaction pending.		
16	DRDY3	1	SWT3 has a destination transaction pending.	R	X
		0	SWT3 does not have a destination transaction pending.		
15	ERR3	1	SWT3 has detected a protocol error (source or destination). Error report is cleared by writing a 1 to this bit.	R/Clear	X
		0	SWT3—no errors.		
14	SBSY2	1	SWT2 is reading memory.	R	X
		0	SWT2 is not reading memory.		
13	DBSY2	1	SWT2 is writing memory.	R	X
		0	SWT2 is not writing memory.		
12	SRDY2	1	SWT2 has a source transaction pending.	R	X
		0	SWT2 does not have a source transaction pending.		
11	DRDY2	1	SWT2 has a destination transaction pending.	R	X
		0	SWT2 does not have a destination transaction pending.		
10	ERR2	1	SWT2 has detected a protocol error (source or destination). Error report is cleared by writing a 1 to this bit.	R/Clear	X
		0	SWT2—no errors.		
9	SBSY1	1	SWT1 is reading memory.	R	X
		0	SWT1 is not reading memory.		
8	DBSY1	1	SWT1 is writing memory.	R	X
		0	SWT1 is not writing memory.		
7	SRDY1	1	SWT1 has a source transaction pending.	R	X
		0	SWT1 does not have a source transaction pending.		
6	DRDY1	1	SWT1 has a destination transaction pending.	R	X
		0	SWT1 does not have a destination transaction pending.		
5	ERR1	1	SWT1 has detected a protocol error (source or destination). Error report is cleared by writing a 1 to this bit.	R/Clear	X
		0	SWT1—no errors.		
4	SBSY0	1	SWT0 is reading memory.	R	X
		0	SWT0 is not reading memory.		
3	DBSY0	1	SWT0 is writing memory.	R	X
		0	SWT0 is not writing memory.		
2	SRDY0	1	SWT0 has a source transaction pending.	R	X
		0	SWT0 does not have a source transaction pending.		
1	DRDY0	1	SWT0 has a destination transaction pending.	R	X
		0	SWT0 does not have a destination transaction pending.		
0	ERR0	1	SWT0 has detected a protocol error (source or destination). Error report is cleared by writing a 1 to this bit.	R/Clear	X
		0	SWT0—no errors.		

[†] For this column, X indicates unknown on powerup reset and unaffected on subsequent reset.

[‡] A core resets MMT5 by setting the RESET5 field (**DMCON1**[5]—Table 32 on page 71) and resets MMT4 by setting the RESET4 field (**DMCON1**[4]).

4 Hardware Architecture (continued)

4.13 Direct Memory Access Unit (DMAU) (continued)

4.13.2 Registers (continued)

The DMAU master control registers, **DMCON0** and **DMCON1**, control the reset, enable, or disable of individual DMAU channels. **DMCON0** also controls the enabling of the source look-ahead buffer for pipelined MMT reads of a source block.

Table 31. DMCON0 (DMAU Master Control 0) Register

The memory address for this register is 0x4205C.

15	14	13	12	11	10	9	8	7—4	3—0
HPRIM	MINT	XSIZE5	XSIZE4	TRIGGER5	TRIGGER4	SLKA5	SLKA4	DRUN[3:0]	SRUN[3:0]
Bits	Field	Value	Definition				R/W	Reset Value	
15	HPRIM	0	If MMT channel interruption is enabled (if MINT is set), this bit indicates MMT4 is the higher-priority channel.				R/W	0	
		1	If MMT channel interruption is enabled (if MINT is set), this bit indicates MMT5 is the higher-priority channel.						
14	MINT	0	If the DMAU has begun processing an MMT channel, it transfers all the data for that MMT channel without interruption by the other MMT channel. Any SWT or PIU bypass channel requests interrupt the active MMT channel.				R/W	0	
		1	The higher-priority MMT channel indicated by HPRIM can preempt the lower-priority MMT channel. If the DMAU has begun processing the higher-priority MMT channel, it transfers all the data for that MMT channel without interruption by the lower-priority MMT channel. Any SWT or PIU bypass channel requests interrupt the active MMT channel.						
13	XSIZE5	0	MMT5 transfers single words (16-bit values).				R/W	0	
		1	MMT5 transfers aligned double words (32-bit values)†.						
12	XSIZE4	0	MMT4 transfers single words (16-bit values).				R/W	0	
		1	MMT4 transfers aligned double words (32-bit values)†.						
11	TRIGGER5	0	If the DMAU begins a block transfer using MMT5, it clears this bit.				R/W	0	
		1	Set by core software to request the DMAU to begin a block transfer using MMT5.						
10	TRIGGER4	0	If the DMAU begins a block transfer using MMT4, it clears this bit.				R/W	0	
		1	Set by core software to request the DMAU to begin a block transfer using MMT4.						
9	SLKA5	0	Force source and destination accesses for MMT5 to occur in order (source look-ahead disabled).				R/W	0	
		1	Permit source reads for MMT5 to be launched before older destination writes (source look-ahead enabled). This maximizes block transfer throughput.						
8	SLKA4	0	Force source and destination accesses for MMT4 to occur in order (source look-ahead disabled).				R/W	0	
		1	Permit source reads for MMT4 to be launched before older destination writes (source look-ahead enabled). This maximizes block transfer throughput.						

† The corresponding source and destination addresses must be even.

‡ Each bit of DRUN[3:0] corresponds to one of the SWT<0—3> channels. For example, DRUN3 corresponds to SWT3.

§ Each bit of SRUN[3:0] corresponds to one of the SWT<0—3> channels. For example, SRUN2 corresponds to SWT2.

4 Hardware Architecture (continued)

4.13 Direct Memory Access Unit (DMAU) (continued)

4.13.2 Registers (continued)

Table 31. DMCON0 (DMAU Master Control 0) Register (continued)

Bits	Field	Value	Definition	R/W	Reset Value
7—4	DRUN[3:0]	0	The corresponding SWT channel [‡] does not initiate a new destination transfer. The DMAU clears this field if it has completed a destination transfer and the corresponding AUTOLOAD field (CTL \langle 0—3 \rangle [0]—Table 34 on page 73) is cleared. The cores cannot clear this field. The cores can cause the DMAU to terminate channel activity by setting the corresponding RESET[3:0] field (DMCON1 [3:0]—Table 32 on page 71).	R/ Set	0
		1	The software running in a core sets this field to cause the DMAU to initiate a new destination transfer for the corresponding SWT channel [‡] .		
3—0	SRUN[3:0]	0	The corresponding SWT channel [§] does not initiate a new source transfer. The DMAU clears this field if it has completed a source transfer and the corresponding AUTOLOAD field (CTL \langle 0—3 \rangle [0]—Table 34 on page 73) is cleared. The cores cannot clear this field. The cores can cause the DMAU to terminate channel activity by setting the corresponding RESET[3:0] field (DMCON1 [3:0]—Table 32 on page 71).	R/ Set	0
		1	The software running in a core sets this field to cause the DMAU to initiate a new source transfer for the corresponding SWT channel [§] .		

† The corresponding source and destination addresses must be even.

‡ Each bit of DRUN[3:0] corresponds to one of the SWT \langle 0—3 \rangle channels. For example, DRUN3 corresponds to SWT3.

§ Each bit of SRUN[3:0] corresponds to one of the SWT \langle 0—3 \rangle channels. For example, SRUN2 corresponds to SWT2.

Table 32. DMCON1 (DMAU Master Control 1) Register

The memory address for this register is 0x4205E.

15—7			6	5—4	3—0	
Reserved			PIUDIS	RESET[5:4]	RESET[3:0]	
Bits	Field	Value	Definition		R/W	Reset Value
15—7	Reserved	0	Reserved—write with zero.		R/W	0
6	PIUDIS	0	The DMAU processes PIU requests.		R/W	0
		1	The DMAU ignores PIU requests.			
5—4	RESET[5:4]	0	The corresponding MMT channel [†] is unaffected.		R/W	0
		1	The software running in a core sets this field to cause the DMAU to unconditionally terminate all channel activity for the corresponding MMT channel [†] .			
3—0	RESET[3:0]	0	The corresponding SWT channel [‡] is unaffected.		R/W	0
		1	The software running in a core sets this field to cause the DMAU to unconditionally terminate all channel activity for the corresponding SWT channel [‡] .			

† RESET5 corresponds to MMT5 and RESET4 corresponds to MMT4. Setting RESET[5:4] does not affect the state of any DMAU registers. RESET[5:4] is typically used for error recovery—see Section 4.13.8 on page 93 for details.

‡ Each bit of RESET[3:0] corresponds to one of the SWT \langle 0—3 \rangle channels. For example, RESET3 corresponds to SWT3. Setting a RESET[3:0] field does not affect the state of any DMAU registers, including the state of the SRUN[3:0]/DRUN[3:0] fields (**DMCON0**[7:0]—Table 31). RESET[3:0] is typically used for error recovery—see Section 4.13.8 on page 93 for details.

4 Hardware Architecture (continued)

4.13 Direct Memory Access Unit (DMAU) (continued)

4.13.2 Registers (continued)

Table 34 on page 73 describes the $SWT\langle 0-3 \rangle$ control registers, $CTL\langle 0-3 \rangle$. Each of the $CTL\langle 0-3 \rangle$ registers controls the behavior of the corresponding SWT channel and determines the following:

1. Whether the access takes place in row-major (two-dimensional array) or column-major (one-dimensional array) order.
2. Whether the autoload feature is enabled or disabled. If enabled, this feature causes the DMAU to automatically reload the address registers with the con-

tents of the base register after an entire array has been processed.

3. The point in the operation when a DMAU interrupt request is generated.

The control register for a specific SWT channel determines these attributes for **both** the source and destination transfers for that channel. Therefore, if the SWT channel is used for bidirectional transfers, the source and destination data must have the same array size and structure. As a result, each SWT channel has only one stride ($STR\langle 0-3 \rangle$) and one reindex ($RI\langle 0-3 \rangle$) register. Therefore, references to fields in Table 34 are common to both SWT source and destination transfers and are given as common references. Table 33 maps the common references used in Table 34 to their specific attribute.

Table 33. Collective Designations Used in Table 34

Collective Designation	Description	Register or Register Field	See
RUN	Source Channel Enable for $SWT\langle 3-0 \rangle$	SRUN[3:0] (DMCON0 [3:0])	Table 31 on page 70
	Destination Channel Enable for $SWT\langle 3-0 \rangle$	DRUN[3:0] (DMCON0 [7:4])	
ADD	Source Address	SADD $\langle 0-3 \rangle$	Table 37 on page 76
	Destination Address	DADD $\langle 0-3 \rangle$	
ROW	Source Row Counter	SROW[12:0] (SCNT $\langle 0-3 \rangle$ [19:7])	Table 38 on page 77
	Destination Row Counter	DROW[12:0] (DCNT $\langle 0-3 \rangle$ [19:7])	Table 40 on page 78
COL	Source Column Counter	SCOL[6:0] (SCNT $\langle 0-3 \rangle$ [6:0])	Table 38 on page 77
	Destination Column Counter	DCOL[6:0] (DCNT $\langle 0-3 \rangle$ [6:0])	Table 40 on page 78
LASTROW	Row Limit	LASTROW[12:0] (LIM $\langle 0-3 \rangle$ [19:7])	Table 42 on page 79
LASTCOL	Column Limit	LASTCOL[6:0] (LIM $\langle 0-3 \rangle$ [6:0])	
BAS	Source Base Register	SBAS $\langle 0-3 \rangle$	Table 44 on page 80
	Destination Base Register	DBAS $\langle 0-3 \rangle$	Table 45 on page 80
STR	Stride Register	STR $\langle 0-3 \rangle$	Table 46 on page 81
RI	Reindex Register	RI $\langle 0-3 \rangle$	Table 47 on page 81

4 Hardware Architecture (continued)

4.13 Direct Memory Access Unit (DMAU) (continued)

4.13.2 Registers (continued)

Table 34. CTL<0—3> (SWT<0—3> Control) Registers

See Table 29 starting on page 66 for the memory addresses of these registers.

15—6			5—4	3—1	0
Reserved			POSTMOD[1:0]	SIGCON[2:0]	AUTOLOAD
Bit	Field	Value	Definition	R/W	Reset Value [†]
15—6	Reserved	0	Reserved—write with zero.	R/W	0
5—4	POSTMOD[1:0]	00	The DMAU performs no pointer or counter update operations.	R/W	XX
		01	Select two-dimensional array accesses. After every transaction: <ul style="list-style-type: none"> ■ If the column counter has not expired, the DMAU increments it by one and increments the address by the contents of the stride register. (If COL≠LASTCOL, then COL=COL+1 and ADD=ADD+STR.) ■ If the row counter has not expired and the column counter has expired, the DMAU increments the row counter by one, clears the column counter, and increments the address by the contents of the sign-magnitude reindex register. (If ROW≠LASTROW and COL=LASTCOL, then ROW=ROW+1, COL=0, and ADD=ADD+RI.) ■ If both the row counter and the column counter have expired and the AUTOLOAD field is set, the DMAU clears the row and column counters and reloads the address with the base value. (If ROW=LASTROW and COL=LASTCOL and AUTOLOAD=1, then ROW=0, COL=0, and ADD=BAS.) ■ If both the row counter and the column counter have expired and the AUTOLOAD field is cleared, the DMAU deactivates the channel. (If ROW=LASTROW and COL=LASTCOL and AUTOLOAD=0, then RUN=0.) 		
		10	Select one-dimensional array accesses. After every transaction: <ul style="list-style-type: none"> ■ If the row counter has not expired, the DMAU increments the counter and the address. (If ROW≠LASTROW, then ROW=ROW+1 and ADD=ADD+1.) ■ If the row counter has expired and the column counter has not expired, the DMAU clears the row counter and increments the column counter and the address. (If ROW=LASTROW and COL≠LASTCOL, then ROW=0, COL=COL+1, and ADD=ADD+1.) ■ If both the row counter and the column counter have expired and the AUTOLOAD field is set, the DMAU clears the row and column counters and reloads the address with the base value. (If ROW=LASTROW and COL=LASTCOL and AUTOLOAD=1, then ROW=0, COL=0, and ADD=BAS.) ■ If both the row counter and the column counter have expired and the AUTOLOAD field is cleared, the DMAU clears the row and column counters, reloads the address with the base value, and deactivates the channel. (If ROW=LASTROW and COL=LASTCOL and AUTOLOAD=0, then ROW=0, COL=0, ADD=BAS, and RUN=0.) 		
		11	Reserved.		

[†] For this column, X indicates unknown on powerup reset and unaffected on subsequent reset.

[‡] The DMAU hardware performs the division as a one-bit right shift. Therefore, the least significant bit is truncated for odd values of LASTROW or LASTCOL.

4 Hardware Architecture (continued)

4.13 Direct Memory Access Unit (DMAU) (continued)

4.13.2 Registers (continued)

Table 34. CTL(0—3) (SWT(0—3) Control) Registers (continued)

Bit	Field	Value	Definition	R/W	Reset Value†
3—1	SIGCON[2:0]	000	The DMAU generates an interrupt request after each single word has been transferred.	R/W	XXX
		001	The DMAU generates an interrupt request following completion of a transfer with ROW equal to LASTROW/2‡.		
		010	The DMAU generates an interrupt request following completion of a transfer with COL equal to LASTCOL.		
		011	The DMAU generates an interrupt request following completion of a transfer with COL equal to LASTCOL and ROW equal to LASTROW/2‡.		
		100	The DMAU generates an interrupt request following completion of a transfer with ROW equal to LASTROW.		
		101	The DMAU generates an interrupt request following completion of a transfer with COL equal to LASTCOL and ROW equal to LASTROW.		
		110	The DMAU generates an interrupt request following completion of a transfer with COL equal to LASTCOL/2‡ and ROW equal to LASTROW.		
		111	Reserved.		
0	AUTOLOAD	0	After the DMAU transfers an entire array, it deactivates the channel. (If ROW=LASTROW and COL=LASTCOL, then RUN=0.) The software can reactivate the channel by setting the RUN field.	R/W	X
		1	After the DMAU transfers an entire array, it reloads the channel's counter and address registers with their base values and initiates another array transfer without core intervention. (If ROW=LASTROW and COL=LASTCOL, then ROW=0, COL=0, and ADD=BAS.)		

† For this column, X indicates unknown on powerup reset and unaffected on subsequent reset.

‡ The DMAU hardware performs the division as a one-bit right shift. Therefore, the least significant bit is truncated for odd values of LASTROW or LASTCOL.

MMT block transfers are unidirectional only, but are listed as common references for consistency with the SWT channels. Each of the CTL(4—5) registers described in Table 36 on page 75 controls the behavior of the corresponding MMT channel. The control register of a specific MMT channel determines the point in the block transfer when a DMAU interrupt request is generated. Table 35 on page 75 maps the common references used in Table 36 on page 75 to their specific attribute.

4 Hardware Architecture (continued)

4.13 Direct Memory Access Unit (DMAU) (continued)

4.13.2 Registers (continued)

Table 35. Collective Designations Used in Table 36

Collective Designation	Description	Register or Register Field	See
XSIZE	Transfer Size for MMT4	XSIZE4 (DMCON0 [12]) (0 for 16 bits or 1 for 32 bits)	Table 31 on page 70
	Transfer Size for MMT5	XSIZE5 (DMCON0 [13]) (0 for 16 bits or 1 for 32 bits)	
ADD	Source Address	SADD <4–5>	Table 37 on page 76
	Destination Address	DADD <4–5>	
ROW	Source Row Counter	SROW[12:0] (SCNT <4–5>[19:7])	Table 39 on page 77
	Destination Row Counter	DROW[12:0] (DCNT <4–5>[19:7])	Table 41 on page 78
LASTROW	Row Limit	LASTROW[12:0] (LIM <4–5>[19:7])	Table 43 on page 79

Table 36. CTL<4–5> (MMT<4–5> Control) Registers

See Table 29 starting on page 66 for the memory addresses of these registers.

		15–6	5–4	3–1	0	
		Reserved	POSTMOD[1:0]	SIGCON[2:0]	Reserved	
Bit	Field	Value	Definition		R/W	Reset Value†
15–6	Reserved	0	Reserved—write with zero.		R/W	0
5–4	POSTMOD[1:0]	00	The DMAU performs no pointer or counter update operations.		R/W	XX
		01	Reserved.			
		10	After every transaction: <ul style="list-style-type: none"> ■ If the row counter has not expired, the DMAU increments it and increments the address by the element size‡. (If ROW≠LASTROW, then ROW=ROW+1 and ADD=ADD+1+XSIZE.) ■ If the row counter has expired, the DMAU clears the row counter, increments the address by the element size‡, and deactivates the channel. (If ROW=LASTROW, then ROW=0 and ADD=ADD+1+XSIZE.) 			
		11	Reserved.			
3–1	SIGCON[2:0]	000	The DMAU generates an interrupt request after each element‡ has been transferred.		R/W	XXX
		001	The channel generates an interrupt request following completion of a transfer with ROW equal to LASTROW/2.			
		01X	Reserved.			
		100	The channel generates an interrupt request following completion of a transfer with ROW equal to LASTROW.			
		101	Reserved.			
		11X	Reserved.			
0	Reserved	0	Reserved—write with zero.		R/W	0

† For this column, X indicates unknown on powerup reset and unaffected on subsequent reset.

‡ The element size is 1 for single-word transactions (XSIZE = 0) or 2 for double-word transactions (XSIZE = 1).

4 Hardware Architecture (continued)

4.13 Direct Memory Access Unit (DMAU) (continued)

4.13.2 Registers (continued)

Table 37. SADD<0—5> and DADD<0—5> (Channels 0—5 Source and Destination Address) Registers

See Table 29 starting on page 66 for the memory addresses of these registers.

31—27		26—23		22—20		19—0	
Reserved		ESEG[3:0]		CMP[2:0]		ADD[19:0]	
Bit	Field	Value	Description			R/W	Reset Value [†]
31—27	Reserved	0	Reserved—write with zero.			R/W	0
26—23	ESEG[3:0]	0x0 to 0xF	External memory address extension. If the DMAU accesses external memory (CMP[2:0] = 100), it causes the SEMI to place the value in this field onto the ESEG[3:0] pins.			R/W	X
22—20	CMP[2:0]	000	The selected memory component is TPRAM0.			R/W	XXX
		001	The selected memory component is TPRAM1.			R/W	
		01X	Reserved.			R/W	
		100	The selected memory component is ERAM [‡] , EIO, or internal I/O.			R/W	
		101	Reserved.			R/W	
		11X	Reserved.			R/W	
19—0	ADD[19:0]	0x00000 to 0xFFFFF	The address within the selected memory component. For an MMT<4—5> channel, if the corresponding XSIZE[5:4] field (DMCON0[13:12]—see Table 31 on page 70) is set, this value must be even.			R/W	X

[†] For this column, X indicates unknown on powerup reset and unaffected on subsequent reset.

[‡] If the WEROM field (ECON1[11]—Table 60 on page 110) is set, EROM is selected in place of ERAM.

4 Hardware Architecture (continued)

4.13 Direct Memory Access Unit (DMAU) (continued)

4.13.2 Registers (continued)

Table 38. SCNT<0—3> (SWT<0—3> Source Counter) Registers

See [Table 29 starting on page 66](#) for the memory addresses of these registers.

19—7			6—0	
SROW[12:0]			SCOL[6:0]	
Bit	Field	Description	R/W	Reset Value†
19—7	SROW[12:0]	The row counter of the one-dimensional or two-dimensional source array for the corresponding SWT channel (read data). The DMAU updates this field as the transfer proceeds and automatically clears it upon the completion of the transfer.	R/W	X
6—0	SCOL[6:0]	The column counter of the one-dimensional or two-dimensional source array for the corresponding SWT channel (read data). The DMAU updates this field as the transfer proceeds and automatically clears it upon the completion of the transfer.	R/W	X

† For this column, X indicates unknown on powerup reset and unaffected on subsequent reset. **SCNT<0—3>** are not cleared by a reset of the DMAU channel via the **DMCON1** register ([Table 32 on page 71](#)). Before an SWT channel can be used, the program must clear the corresponding **SCNT<0—3>** register after a DSP16410B device reset. Otherwise, the value of this register is undefined.

Table 39. SCNT<4—5> (MMT<4—5> Source Counter) Registers

See [Table 29 starting on page 66](#) for the memory addresses of these registers.

19—7			6—0	
SROW[12:0]			SCOL[6:0]	
Bit	Field	Description	R/W	Reset Value†
19—7	SROW[12:0]	The row counter of the source block for the corresponding MMT channel (read data). The DMAU increments this field as the transfer proceeds and automatically clears it upon the completion of the transfer.	R/W	X
6—0	SCOL[6:0]	The column counter of the source block for the corresponding MMT channel (read data). Typically, the user has programmed the LASTCOL[6:0] field (LIM<4—5> [6:0]— Table 43 on page 79) with zero, and therefore, the DMAU does not update this field.	R/W	X

† For this column, X indicates unknown on powerup reset and unaffected on subsequent reset. **SCNT<4—5>** are not cleared by a reset of the DMAU channel via the **DMCON1** register ([Table 32 on page 71](#)). Before an MMT channel can be used, the program must clear the corresponding **SCNT<4—5>** register after a DSP16410B device reset. Otherwise, the value of this register is undefined.

4 Hardware Architecture (continued)

4.13 Direct Memory Access Unit (DMAU) (continued)

4.13.2 Registers (continued)

Table 40. DCNT<0—3> (SWT<0—3> Destination Counter) Registers

See Table 29 starting on page 66 for the memory addresses of these registers.

19—7 DROW[12:0]			6—0 DCOL[6:0]	
Bit	Field	Description	R/W	Reset Value†
19—7	DROW[12:0]	The row counter of the one-dimensional or two-dimensional destination array for the corresponding SWT channel (write data). The DMAU updates this field as the transfer proceeds and automatically clears it upon the completion of the transfer.	R/W	X
6—0	DCOL[6:0]	The column counter of the one-dimensional or two-dimensional destination array for the corresponding SWT channel (write data). The DMAU updates this field as the transfer proceeds and automatically clears it upon the completion of the transfer.	R/W	X

† For this column, X indicates unknown on powerup reset and unaffected on subsequent reset. DCNT<0—3> are not cleared by a reset of the DMAU channel via the DMCON1 register (Table 32 on page 71). Before an SWT channel can be used, the program must clear the corresponding DCNT<0—3> register after a DSP16410B device reset. Otherwise, the value of this register is undefined.

Table 41. DCNT<4—5> (MMT<4—5> Destination Counter) Registers

See Table 29 starting on page 66 for the memory addresses of these registers.

19—7 DROW[12:0]			6:0 DCOL[6:0]	
Bit	Field	Description	R/W	Reset Value†
19—7	DROW[12:0]	The row counter of the destination block for the corresponding MMT channel (write data). The DMAU increments this field as the transfer proceeds and automatically clears it upon the completion of the transfer.	R/W	X
6—0	DCOL[6:0]	The column counter of the destination block for the corresponding MMT channel (write data). Typically, the user has programmed the LASTCOL[6:0] field (LIM<4—5>[6:0]—Table 43 on page 79) with zero and therefore the DMAU does not update this field.	R/W	X

† For this column, X indicates unknown on powerup reset and unaffected on subsequent reset. DCNT<4—5> are not cleared by a reset of the DMAU channel via the DMCON1 register (Table 32 on page 71). Before an MMT channel can be used, the program must clear the corresponding DCNT<4—5> register after a DSP16410B device reset. Otherwise, the value of this register is undefined.

4 Hardware Architecture (continued)

4.13 Direct Memory Access Unit (DMAU) (continued)

4.13.2 Registers (continued)

Table 42. LIM<0—3> (SWT<0—3> Limit) Registers

See Table 29 starting on page 66 for the memory addresses of these registers.

19—7		6—0		
LASTROW[12:0]		LASTCOL[6:0]		
Bit	Field	Description	R/W	Reset Value†
19—7	LASTROW[12:0]	The last row count for both the source and destination arrays for the corresponding SWT channel. The source and destination arrays are either one-dimensional or two-dimensional. For a single-buffered array, this field is programmed with the number of rows in each single buffer minus one ($r - 1$). For a double-buffered two-dimensional array, this field is programmed with two times the number of rows in each single buffer minus one ($(2 \times r) - 1$).	R/W	X
6—0	LASTCOL[6:0]	The last column count for both the source and destination arrays for the corresponding SWT channel. The source and destination arrays are either one-dimensional or two-dimensional. This field is programmed with the number of columns minus one ($n - 1$).	R/W	X

† For this column, X indicates unknown on powerup reset and unaffected on subsequent reset.

Table 43. LIM<4—5> (MMT<4—5> Limit) Registers

See Table 29 starting on page 66 for the memory addresses of these registers.

19—7		6—0		
LASTROW[12:0]		LASTCOL[6:0]		
Bit	Field	Description	R/W	Reset Value†
19—7	LASTROW[12:0]	The last row count for both the source and destination blocks for the corresponding MMT channel. This field is typically programmed with the number of rows‡ in the block minus one ($r - 1$).	R/W	X
6—0	LASTCOL[6:0]	The last column count for both the source and destination blocks for the corresponding MMT channel. The user typically programs this field with zero§.	R/W	X

† For this column, X indicates unknown on powerup reset and unaffected on subsequent reset.

‡ Each row contains one element. The element size is either 16 bits or 32 bits based on the programming of the XSIZE4 or XSIZE5 field (DMCON0[13:12]—Table 31 on page 70).

§ This document assumes that the LASTCOL[6:0] field is programmed with zero.

4 Hardware Architecture (continued)

4.13 Direct Memory Access Unit (DMAU) (continued)

4.13.2 Registers (continued)

Table 44. SBAS<0—3> (SWT<0—3> Source Base Address) Registers

See Table 29 starting on page 66 for the memory addresses of these registers.

19—0 Source Base Address				
Bit	Field	Description	R/W	Reset Value†
19—0	Source Base Address	The program must initialize the SBAS<0—3> register with the starting address of the one-dimensional or two-dimensional source array for the corresponding channel (read data). If the corresponding AUTOLOAD field (CTL<0—3> [0]) is set, the DMAU copies the contents of SBAS<0—3> to the corresponding SADD<0—3> register after the transfer of an entire array is complete. The DMAU does not modify SBAS<0—3> .	R/W	X

† For this column, X indicates unknown on powerup reset and unaffected on subsequent reset.

Table 45. DBAS<0—3> (SWT<0—3> Destination Base Address) Registers

See Table 29 starting on page 66 for the memory addresses of these registers.

19—0 Destination Base Address				
Bit	Field	Description	R/W	Reset Value†
19—0	Destination Base Address	The program must initialize the DBAS<0—3> register with the starting address of the one-dimensional or two-dimensional destination array for the corresponding channel (write data). If the corresponding AUTOLOAD field (CTL<0—3> [0]) is set, the DMAU copies the contents of DBAS<0—3> to the corresponding DADD<0—3> register after the transfer of an entire array is complete. The DMAU does not modify DBAS<0—3> .	R/W	X

† For this column, X indicates unknown on powerup reset and unaffected on subsequent reset.

4 Hardware Architecture (continued)

4.13 Direct Memory Access Unit (DMAU) (continued)

4.13.2 Registers (continued)

Table 46. STR<0—3> (SWT<0—3> Stride) Registers

See Table 29 starting on page 66 for the memory addresses of these registers.

15—14		13—0			
Reserved		Stride			
Bit	Field	Value	Description	R/W	Reset Value†
15—14	Reserved	0	Reserved—write with zero.	R/W	0
13—0	Stride	≤16,383	If the corresponding SWT channel is programmed for one-dimensional array accesses (if the POSTMOD[1:0] field (CTL<0—3>[5:4]) is 0x2), this field is ignored. If the corresponding SWT channel is programmed for two-dimensional array accesses (if the POSTMOD[1:0] field (CTL<0—3>[5:4]) is 0x1), the DMAU adds the contents of this register to the corresponding source and destination address registers (SADD<0—3> and DADD<0—3>) until it processes the last column in the array. The program must initialize this register with the number of memory locations between corresponding rows (elements) of consecutive columns (buffers). Typically, the columns (buffers) are back-to-back (contiguous) in memory, and this register is programmed with the number of rows per column.	R/W	X

† For this column, X indicates unknown on powerup reset and unaffected on subsequent reset.

Table 47. RI<0—3> (SWT<0—3> Reindex) Registers

See Table 29 starting on page 66 for the memory addresses of these registers.

19		18—0			
Sign Bit		Magnitude			
Bit	Field	Value	Description	R/W	Reset Value†
19	Sign Bit	1	If the corresponding SWT channel is programmed for one-dimensional array accesses (if the POSTMOD[1:0] field (CTL<0—3>[5:4]) is 0x2), this field is ignored. If the corresponding SWT channel is programmed for two-dimensional array accesses (if the POSTMOD[1:0] field (CTL<0—3>[5:4]) is 0x1), this bit must be set. This causes the reindex value to be negative and the DMAU to subtract the reindex magnitude from SADD<0—3> and DADD<0—3>.	R/W	X
18—0	Magnitude	≤262,143	If the corresponding SWT channel is programmed for one-dimensional array accesses (if the POSTMOD[1:0] field (CTL<0—3>[5:4]) is 0x2), this field is ignored. If the corresponding SWT channel is programmed for two-dimensional array accesses (if the POSTMOD[1:0] field (CTL<0—3>[5:4]) is 0x1), the DMAU subtracts this value from the corresponding address register (SADD<0—3> or DADD<0—3>) after accessing the last column in the array. For a single-buffered array of r rows and n columns ($n > 1$), the magnitude of the reindex value is $(r \times (n - 1)) - 1$. For a double-buffered array of r rows and n columns ($n > 1$), the magnitude of the reindex value is $(2r \times (n - 1)) - 1$.	R/W	X

† For this column, X indicates unknown on powerup reset and unaffected on subsequent reset.

4 Hardware Architecture (continued)

4.13 Direct Memory Access Unit (DMAU) (continued)

4.13.3 Data Structures

The DMAU moves data in one-dimensional array, two-dimensional array, and block transfer patterns. The following sections outline these three types of data structures and the methods for programming the DMAU registers to establish them.

4.13.3.1 One-Dimensional Data Structure (SWT Channels)

Figure 20 illustrates the structure of a one-dimensional array for an SWT channel. The array consists of n columns (buffers), each containing r rows (elements). The columns must be contiguous (back-to-back) in memory. See Section 4.13.5 for more information about SWT channels. See Section 4.13.9.2 for an example of a transfer using a one-dimensional array.

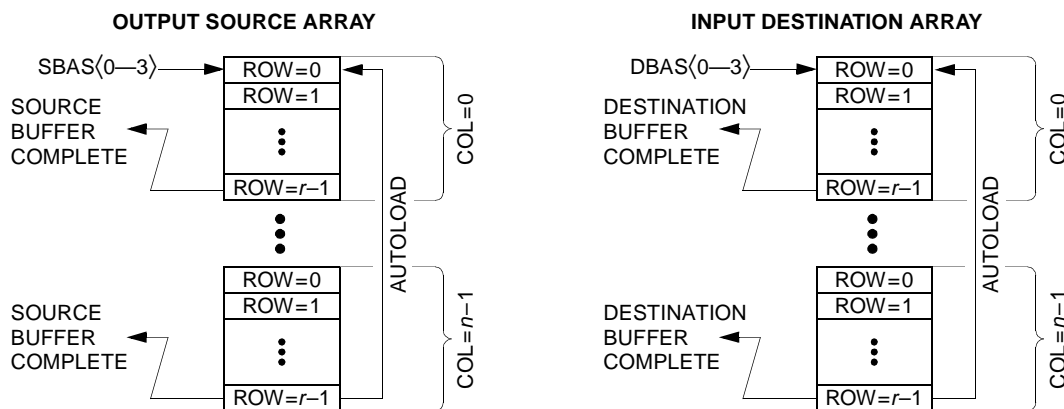


Figure 20. One-Dimensional Data Structure for Buffering n Channels

One-dimensional data structures for data transfers use the address, base, limit, counter, and control registers associated with the SWT channel carrying the data between an SIU and memory.

CTL<0-3> The user software must initialize the corresponding control register with the POSTMOD[1:0] field programmed to 0x2 to enable one-dimensional array accesses, the SIGCON[2:0] field programmed to a value that defines when interrupts are generated, and the AUTOLOAD field set to one so that no further core interaction is needed.

DADD<0-3> and **SADD<0-3>** The user software must initialize the corresponding destination and source address registers to the top of the input (destination) and output (source) arrays located in memory. The DMAU automatically increments these registers as the transfer proceeds.

DBAS<0-3> and **SBAS<0-3>** The user software must also initialize the corresponding destination and source base registers to the top of the input (destination) and output (source) arrays located in

memory. These registers are used with the autoloading feature of the associated SWT channel.

LIM<0-3> The user software must initialize the corresponding limit register with the dimensions of the array. The number of rows (or elements) is r ; therefore, the LASTROW[12:0] field is programmed to $r-1$. The number of columns, n , is the same as the number of buffers; therefore, LASTCOL[6:0] field is programmed to $n-1$.

DCNT<0-3> and **SCNT<0-3>** The corresponding destination and source count registers contain the row and column counters for one-dimensional array accesses. The user software must initially clear these registers. The DMAU automatically clears these registers upon the completion of an SWT transfer, and increments the row and column counter fields of these registers as the transfer proceeds.

DMCON0 The user software must set the corresponding SRUN[3:0] and DRUN[3:0] fields in **DMCON0** to enable source and destination transfers.

4 Hardware Architecture (continued)

4.13 Direct Memory Access Unit (DMAU) (continued)

4.13.3 Data Structures (continued)

4.13.3.2 Two-Dimensional Data Structure (SWT Channels)

Figure 21 illustrates the structure of a two-dimensional double-buffered array for an SWT channel. This structure is useful for TDM channel multiplexing and demultiplexing. The array consists of n columns (double buffers), each containing $2r$ rows (elements). The columns are typically contiguous (back-to-back) in memory, but this is not required. See Section 4.13.5 for more information about SWT channels. See Section 4.13.9.1 for an example of a transfer using a two-dimensional array.

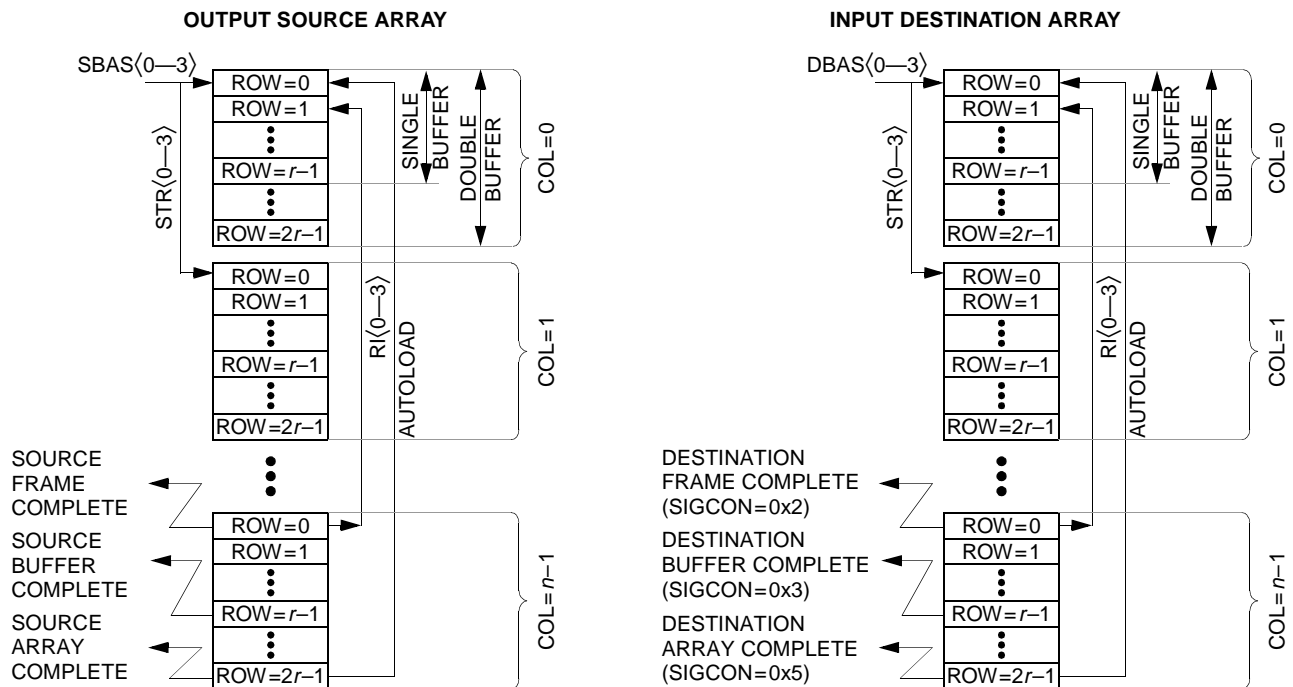


Figure 21. Two-Dimensional Data Structure for Double-Buffering n Channels

Two-dimensional data structures for data transfers use address, base, limit, counter, stride, reindex, and control registers associated with the SWT channel carrying the data between an SIU and memory.

CTL<0-3> The user software must initialize the corresponding control register with the POSTMOD[1:0] field programmed to 0x1 to enable two-dimensional array accesses, the SIGCON[2:0] field programmed to a value that defines when interrupts are generated, and the AUTOLOAD field set to one so that no further core interaction is needed.

DADD<0-3> and **SADD<0-3>** The user software must initialize the corresponding destination and source address registers to the top of the input (destination) and output (source) arrays located in

memory. The DMAU automatically updates these registers in a row-major order as the transfer proceeds.

DBAS<0-3> and **SBAS<0-3>** The user software must also initialize the corresponding destination and source base registers to the top of the input (destination) and output (source) arrays located in memory. These registers are used with the autoload feature of the associated SWT channel.

4 Hardware Architecture (continued)

4.13 Direct Memory Access Unit (DMAU) (continued)

4.13.3 Data Structures (continued)

4.13.3.2 Two-Dimensional Data Structure (SWT Channels) (continued)

LIM<0—3> The user software must initialize the corresponding limit register with the dimensions of the array. The number of rows (or elements) is r . For a single-buffered array, the LASTROW[12:0] field is programmed to $r - 1$. For a double-buffered array (Figure 21), the LASTROW[12:0] field is programmed to $(2 \times r) - 1$. The number of columns (n), is the same as the number of buffers. Therefore, the LASTCOL[6:0] field is programmed to $n - 1$.

DCNT<0—3> and **SCNT<0—3>** The corresponding destination and source count registers contain the row and column counters for two-dimensional array access. The user software must initially clear these registers. The DMAU automatically clears these registers upon the completion of an SWT transfer and increments the row and column counter fields of these registers as the transfer proceeds.

STR<0—3> The user software must initialize the corresponding stride register with the number of memory locations between common rows (elements) of different columns (buffers). Typical data structures have buffers that are contiguous in memory. In this case, the stride is the same as the buffer length (number of rows per column). If the current column is not the last column, the DMAU increments the contents of **DADD<0—3>** and **SADD<0—3>** by the stride value after each transaction, i.e., increments the address registers in row-major order. This causes **DADD<0—3>** and **SADD<0—3>** to address the common row in the next column.

RI<0—3> The user software must initialize the corresponding reindex register to the sign-magnitude pointer postmodification value to be applied to **SADD<0—3>** and **DADD<0—3>** after the DMAU has accessed the last column. For a single-buffered array of r rows and n columns ($n > 1$), the magnitude of the reindex value is $(r \times (n - 1)) - 1$. For a double-buffered array of r rows and n columns ($n > 1$), the magnitude is $(2r \times (n - 1)) - 1$. Because the reindex value is always negative for a two-dimensional array, the user software must set the sign bit of **RI<0—3>**.

DMCON0 The user software must set the corresponding SRUN[3:0] and DRUN[3:0] fields in **DMCON0** to enable source and destination transfers.

4 Hardware Architecture (continued)

4.13 Direct Memory Access Unit (DMAU) (continued)

4.13.3 Data Structures (continued)

4.13.3.3 Memory-to-Memory Block Transfers (MMT Channels)

Figure 22 illustrates a memory-to-memory block transfer using an MMT channel. See Section 4.13.6 for more information about MMT channels. See Section 4.13.9.3 for an example of a memory-to-memory block data transfer using an MMT channel.

Memory-to-memory block data structures for data transfers use address, limit, counter, and control registers associated with the MMT channel transferring the data between two memories.

DADD $\langle 4-5 \rangle$ and **SADD** $\langle 4-5 \rangle$ The user software must initialize the corresponding destination and source address registers to the top of the input (destination) and output (source) blocks located in

memory. The DMAU automatically updates these registers as the transfer proceeds.

LIM $\langle 4-5 \rangle$ The user software must initialize the corresponding limit register with the dimensions of the array. The number of rows (or elements) is r . Therefore, the user software writes $r - 1$ to LASTROW[12:0]. The array is structured as one column (one buffer). Therefore, the user software writes zero to LASTCOL[6:0].

DCNT $\langle 4-5 \rangle$ and **SCNT** $\langle 4-5 \rangle$ The corresponding destination and source count registers contain the row and column counters for memory-to-memory block transfers. The user software must initially clear these registers. The DMAU automatically clears these registers upon the completion of an MMT source transfer, and updates these registers as the source transfer proceeds.

CTL $\langle 4-5 \rangle$ The user software must write the control register with SIGCON[2:0] set to a value that defines when interrupts are generated.

DMCON0 The user software must set the corresponding TRIGGER[5:4] field in **DMCON0** to enable MMT transfers.

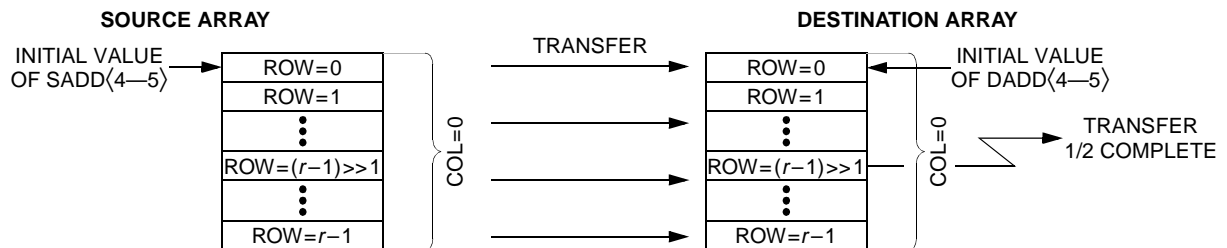


Figure 22. Memory-to-Memory Block Transfer

4.13.4 The PIU Addressing Bypass Channel

If the PIUDIS field (**DMCON1**[6]—Table 32 on page 71) is cleared, a host microprocessor connected to the DSP16410B PIU port can gain access to the entire memory space of the DSP16410B. The access is arbitrated by the DMAU. If PIUDIS is set to one, PIU requests are ignored by the DMAU.

All PIU transactions are handled through the addressing bypass channel. Host requests are independent of both cores and add no overhead to core processing. The host can issue commands, read status information, read and write DSP16410B memory, and send messages via the host parallel port. Specific transactions are accomplished by host commands issued to the PIU. See Section 4.15.5 for more details.

4 Hardware Architecture (continued)

4.13 Direct Memory Access Unit (DMAU) (continued)

4.13.5 Single-Word Transfer Channels (SWT)

The DMAU provides a total of four SWT channels. SWT0 and SWT1 are dedicated to SIU0, and SWT2 and SWT3 are dedicated to SIU1. Each SWT channel is bidirectional and can transfer data to/from either TPRAM0, TPRAM1, or external memory as defined by the associated channel's source and destination address registers (**SADD** $\langle 0-3 \rangle$ and **DADD** $\langle 0-3 \rangle$). Two SWT channels are dedicated to each SIU so that data from a single SIU can be routed to separate memory spaces at any time. Each SIU's **ICIX** $\langle 0-1 \rangle$ and **OCIX** $\langle 0-1 \rangle$ control registers define the mapping of serial port data to one of the two SWT channels dedicated to that SIU. For example, this provides a method for routing logical channel data on a TDM bit stream to/from either TPRAM on a time-slot basis.

If a specific SIU issues a request for service (input buffer full or output buffer empty), an SWT channel performs a **transaction**. SWT channels provide both source and destination transfers. A **source transaction** is defined as a read from DSP16410B memory and write to an SIU output register with the update of the appropriate DMAU registers. A **destination transaction** is defined as the read of an SIU input register and write to DSP16410B memory with the update of the appropriate DMAU registers. For a specific SWT channel, the size and structure of the data to be transferred to/from the SIU must be the same. As an alternative, the source or destination transfer for a specific channel can be disabled, allowing separate DMAU channels to be used for the source and destination transfers. For example, SWT0 can be used to service SIU0 input and SWT1 for SIU0 output.

The DMAU supports address and counter hardware for one- and two-dimensional memory accesses for each SWT channel. The basic data structure is called an **array**, which consists of **columns** (or buffers) and **rows** (or elements). An array can be traversed in either row-major (two-dimensional array) or column-major (one-dimensional array) order, as defined by the DMAU control registers for that channel (**CTL** $\langle 0-3 \rangle$)—Table 34 on page 73). Each SWT channel has two dedicated interrupt signals; one to represent the status of a source transfer and another to represent the status of a destination transfer. These signals can be used to create interrupt sources to either core. (See Section 4.13.7 for details.)

The **SIGCON**[2:0] field (**CTL** $\langle 0-3 \rangle$ [3:1]) registers define the exact meaning associated with **both** the source and destination transfer interrupts. See Table 50 on page 91 for a list of DMAU interrupts and Table 34 on page 73 for the **CTL** $\langle 0-3 \rangle$ bit field definitions.

The following steps are taken during a **source transaction**:

1. One of the cores sets the appropriate **SRUN**[3:0] field (**DMCON0**[3:0])—Table 31 on page 70) to initiate transfers.
2. If the SIU 16-bit output data register (**SODR**) is empty, the SIU requests data from the DMAU. The DMAU reads one data word over the Z-bus from the appropriate DSP16410B memory location using the SWT channel's source address register, **SADD** $\langle 0-3 \rangle$.
3. The DMAU transfers the data word to the corresponding **SODR** register over the peripheral data bus, DDO.
4. The DMAU updates the SWT channel's source address register, **SADD** $\langle 0-3 \rangle$, and the source counter register, **SCNT** $\langle 0-3 \rangle$.
5. The DMAU can generate a core interrupt, based on the value of the **SIGCON**[2:0] field (**CTL** $\langle 0-3 \rangle$ [3:1]).
6. If this is not the last location of the source array (**SCNT** $\langle 0-3 \rangle \neq \text{LIM}\langle 0-3 \rangle$), the DMAU returns to step 2. If this is the last location of the source array:
 - If the **AUTOLOAD** field (**CTL** $\langle 0-3 \rangle$ [0])—Table 34 on page 73) is cleared, the DMAU clears **SCNT** $\langle 0-3 \rangle$, clears the corresponding **SRUN**[3:0] field (**DMCON0**[3:0])—Table 31 on page 70), and terminates the source transfer.
 - If the **AUTOLOAD** field is set:
 - The DMAU reloads **SADD** $\langle 0-3 \rangle$ with the value in the source base address register, **SBAS** $\langle 0-3 \rangle$.
 - The DMAU clears the value in the source counter register (**SCNT** $\langle 0-3 \rangle$ is written with 0).
 - The DMAU initiates a new source transfer without core intervention.

The steps taken for a **destination transaction** are:

1. One of the cores sets the appropriate **DRUN**[3:0] field (**DMCON0**[7:4]) to initiate transfers.
2. If the SIU 16-bit input data register (**SIDR**) is full, the SIU requests that the DMAU read the data. After the DMAU acknowledges the request, the SIU places the contents of **SIDR** onto the data bus (DSI).

4 Hardware Architecture (continued)

4.13 Direct Memory Access Unit (DMAU) (continued)

4.13.5 Single-Word Transfer Channels (SWT) (continued)

3. The DMAU transfers this data word over the Z-bus to the appropriate DSP16410B memory location as defined by the channel's destination address register, **DADD<0—3>**.
4. The DMAU updates the channel's destination address register, **DADD<0—3>**, and the destination counter, **DCNT<0—3>**.
5. The DMAU can generate a core interrupt, based on the value of the **SIGCON[2:0]** field (**CTL<0—3>**[3:1]—[Table 34 on page 73](#)).
6. If this is not the last location of the destination array (**DCNT<0—3>** ≠ **LIM<0—3>**), the DMAU returns to

step 2. If this is the last location of the destination array:

- If the AUTOLOAD field (**CTL<0—3>**[0]—[Table 34 on page 73](#)) is cleared, the DMAU clears **DCNT<0—3>**, clears the corresponding **DRUN[3:0]** field (**DMCON0**[7:4]—[Table 31 on page 70](#)) and terminates the destination transfer.
- If the AUTOLOAD field is set:
 - The DMAU reloads **DADD<0—3>** with the value in the destination base address register, **DBAS<0—3>**.
 - The DMAU clears the value in the destination counter register (**DCNT<0—3>** is written with 0).
 - The DMAU initiates a new destination transfer without core intervention.

The DMAU's control and address registers determine the data structure and access pattern supported by a particular channel and reflect the status of the transfer. These SWT channel registers are described in [Table 48](#), with additional detail provided in [Section 4.13.2](#).

Table 48. SWT-Specific Memory-Mapped Registers

Register	Type	Size	Description
SADD<0—3>	Source Address	32-bit	The program must initialize the SADD<0—3> register with the starting address of the source array [†] for the corresponding channel (read data). The DMAU updates the register with the address of the next memory location to be read by the corresponding SWT channel as the transfer proceeds. Table 37 on page 76 describes the bit fields of the SADD<0—3> registers.
SBAS<0—3>	Source Base Address	20-bit	The program must initialize the SBAS<0—3> register with the starting address of the source array [†] for the corresponding channel (read data). If the corresponding AUTOLOAD field (CTL<0—3> [0]) is set, the DMAU copies the contents of SBAS<0—3> to the corresponding SADD<0—3> register after the transfer of an entire array is complete. The DMAU does not modify SBAS<0—3> .
SCNT<0—3>	Source Counter	20-bit	This register contains the row and column counter of the source array [†] for the corresponding channel (read data). The DMAU updates the register as the transfer proceeds and automatically clears the register upon the completion of the transfer. The source row (SROW) is encoded in SCNT<0—3> [19:7], and the source column (SCOL) is encoded in SCNT<0—3> [6:0]. Note: SCNT<0—3> are not cleared by a reset of the DMAU channel via the DMCON1 register (Table 32 on page 71). Before an SWT channel can be used, the program must clear the corresponding SCNT<0—3> register after a DSP16410B device reset. Otherwise, the value of this register is undefined.
DADD<0—3>	Destination Address	32-bit	The program must initialize the DADD<0—3> register with the starting address of the destination array [†] for the corresponding channel (write data). The DMAU updates the register with the address of the next memory location to be written by the corresponding SWT channel as the transfer proceeds. Table 37 on page 76 describes the bit fields of the DADD<0—3> registers.
DBAS<0—3>	Destination Base Address	20-bit	The program must initialize the DBAS<0—3> register with the starting address of the destination array [†] for the corresponding channel (write data). If the corresponding AUTOLOAD field (CTL<0—3> [0]) is set, the DMAU copies the contents of DBAS<0—3> to the corresponding DADD<0—3> register after the transfer of an entire array is complete. The DMAU does not modify DBAS<0—3> .

[†] The array can be either one-dimensional or two-dimensional.

4 Hardware Architecture (continued)

4.13 Direct Memory Access Unit (DMAU) (continued)

4.13.5 Single-Word Transfer Channels (SWT) (continued)

Table 48. SWT-Specific Memory-Mapped Registers (continued)

Register	Type	Size	Description
DCNT<0—3>	Destination Counter	20-bit	<p>This register contains the row and column counter of the destination array[†] for the corresponding channel (write data). The DMAU updates the register as the transfer proceeds and automatically clears the register upon the completion of the transfer. The destination row (DROW) is encoded in DCNT<0—3>[19:7], and the destination column (DCOL) is encoded in DCNT<0—3>[6:0].</p> <p>Note: DCNT<0—3> are not cleared by a reset of the DMAU channel via the DMCON1 register (Table 32 on page 71). Before an SWT channel can be used, the program must clear the corresponding DCNT<0—3> register after a DSP16410B device reset. Otherwise, the value of this register is undefined.</p>
LIM<0—3>	Limit	20-bit	<p>The user programs LIM<0—3> with the last row count and the last column count for both the source and destination arrays[†] for the corresponding channel. For a single-buffered array, LIM<0—3>[19:7] is programmed with the number of rows in each single buffer minus one ($r - 1$). For a double-buffered two-dimensional array, LIM<0—3>[19:7] is programmed with two times the number of rows in each single buffer minus one ($(2 \times r) - 1$). The number of columns minus one ($n - 1$) is encoded in LIM<0—3>[6:0]. Refer to Section 4.13.9 on page 94 for examples.</p>
STR<0—3>	Stride Register	16-bit	<p>For an SWT channel with one-dimensional array accesses, the program must clear the corresponding STR<0—3> register.</p> <p>For an SWT channel with two-dimensional array accesses, the user software assigns the number of memory locations between common rows (elements) of different columns (buffers). Typically, this value equals the number of rows per column, which places the buffers back-to-back (contiguous) in memory. Refer to Section 4.13.9.1 on page 94 for details.</p>
RI<0—3>	Reindex	20-bit	<p>For an SWT channel with one-dimensional array accesses, the program must clear the corresponding RI<0—3> register.</p> <p>For an SWT channel with two-dimensional array accesses, the DMAU adds the sign-magnitude value in the corresponding RI<0—3> register to the corresponding address register (SADD<0—3> for source transactions and DADD<0—3> for destination transactions) after the last column has been accessed. The magnitude of the reindex value for an array of r rows and n columns ($n > 1$) is $(r \times (n - 1)) - 1$. The magnitude of the reindex value for a two-dimensional array that employs double buffers like that shown in Figure 21 on page 83 is $(2r \times (n - 1)) - 1$. Because the reindex value is always negative, set the sign bit (bit 19) of RI<0—3>.</p>
CTL<0—3>	Control	16-bit	<p>CTL<0—3> controls the following items for the corresponding SWT channel:</p> <ul style="list-style-type: none"> ■ Enabling or disabling of AUTOLOAD for the starting address. ■ Determining the point in the transaction when a DMAU interrupt request is generated. ■ Determining whether the access takes place in row-major (two-dimensional array) or column-major (one-dimensional array) order. <p>CTL<0—3> determines these attributes for both the source and destination arrays for the corresponding SWT channel. See Table 34 on page 73 for the field descriptions of CTL<0—3>.</p>

[†] The array can be either one-dimensional or two-dimensional.

4 Hardware Architecture (continued)

4.13 Direct Memory Access Unit (DMAU) (continued)

4.13.5 Single-Word Transfer Channels (SWT) (continued)

The two 16-bit DMAU master control registers, **DMCON0** and **DMCON1**, also influence the operation of the SWT channels. The 32-bit DMAU status register, **DSTAT**, reflects the status of any SWT transfer. The bit field definition of the DMAU control and status registers is given in [Section 4.13.2](#).

4.13.6 Memory-to-Memory Transfer Channels (MMT)

The DSP16410B DMAU provides two MMT channels for block transfers called MMT4 and MMT5. Each MMT channel moves data between a **source block** and a **destination block**. Both the source and destination blocks must be one-dimensional arrays with the same size and structure, as defined by the MMT channel's control register, **CTL** $\langle 4-5 \rangle$ (see [Table 36 on page 75](#)). The user software initiates an MMT block transfer request by writing a one to the corresponding TRIGGER5 or TRIGGER4 field (**DMCON0**[11,10]—see [Table 31 on page 70](#)). Each transfer can be 16 or 32 bits, as determined by the corresponding XSIZE5 or XSIZE4 field (**DMCON0**[13,12]). If the transfers are 32 bits, the source and destination addresses as specified by **SADD** $\langle 4-5 \rangle$ and **DADD** $\langle 4-5 \rangle$ must both be even.

Once initiated, MMT channel block transfers proceed to completion, and then stop. The DMAU pauses an MMT block transfer to allow an SWT or bypass channel transaction to complete, and then automatically resumes the MMT block transfer. This prevents I/O latencies and possible data overwrites due to long MMT blocks. Each MMT channel has a dedicated interrupt request that can be enabled in either core. The SIGCON[2:0] field (**CTL** $\langle 4-5 \rangle$ [3:1]) determines the exact meaning associated with the interrupt. See [Table 50 on page 91](#) and [Table 34 on page 73](#) for more information.

To optimize throughput, MMT channel read operations can be pipelined. This allows the DMAU to initiate multiple fetches from the source block before an associated write to the destination block is performed. The DMAU stores the data from the multiple fetches into an internal source look-ahead buffer. The user enables multiple fetches into the source look-ahead buffer for

an MMT channel by setting the corresponding SLKA5 or SLKA4 field (**DMCON0**[9,8]).

Assuming that source look-ahead is disabled, the DMAU performs the following steps during an MMT block transfer:

1. The user software executing in one of the cores writes a one to the corresponding TRIGGER5 or TRIGGER4 field (**DMCON0**[11,10]) to initiate the block transfer. The DMAU automatically clears the TRIGGER5 or TRIGGER4 field.
2. The DMAU initiates a read operation from the source block using the address in the channel's source address register, **SADD** $\langle 4-5 \rangle$ (see [Table 37 on page 76](#)). If the corresponding XSIZE5 or XSIZE4 field (**DMCON0**[13,12]) is cleared, the read operation is 16 bits. If the corresponding XSIZE5 or XSIZE4 field is set, the read operation is 32 bits.
3. If the read operation is 16 bits, the DMAU increments **SADD** $\langle 4-5 \rangle$ by one. If the read operation is 32 bits, the DMAU increments **SADD** $\langle 4-5 \rangle$ by two. The DMAU updates the source counter register (**SCNT** $\langle 4-5 \rangle$ —[Table 39 on page 77](#)) by incrementing its SROW[12:0] field by one.
4. When the read data from step 2 becomes available, the DMAU places it into the source look-ahead buffer.
5. The DMAU writes the data in the source look-ahead buffer to the destination block using the address in the channel's destination address register, **DADD** $\langle 4-5 \rangle$. If the corresponding XSIZE5 or XSIZE4 field (**DMCON0**[13,12]) is cleared, the write operation is 16 bits. If the corresponding XSIZE5 or XSIZE4 field is set, the write operation is 32 bits.
6. If the write operation is 16 bits, the DMAU increments **DADD** $\langle 4-5 \rangle$ by one. If the write operation is 32 bits, the DMAU increments **DADD** $\langle 4-5 \rangle$ by two. The DMAU updates the destination counter register (**DCNT** $\langle 4-5 \rangle$) by incrementing its DROW[12:0] field by one.
7. Depending on the SIGCON[2:0] field (**CTL** $\langle 4-5 \rangle$ [3:1]), the DMAU can generate an interrupt.
8. If this is the last location of the block (**DCNT** $\langle 4-5 \rangle$ = **LIM** $\langle 4-5 \rangle$), the DMAU stops processing for the channel. If this is not the last location of the block, the DMAU returns to step 2.

4 Hardware Architecture (continued)

4.13 Direct Memory Access Unit (DMAU) (continued)

4.13.6 Memory-to-Memory Transfer Channels (MMT) (continued)

If source look-ahead is enabled, the DMAU performs the same steps as above except that it initially repeats steps 2–4 multiple times in a pipelined manner. It then performs reads and writes to the source and destination blocks as access cycles become available. It is strongly recommended that the user enable source look-ahead. See [Section 4.14.7.4 on page 130](#) for a performance comparison.

The DMAU's control and address registers determine the data size and location supported by a particular channel and reflect the status of the request. These MMT channel registers are described in [Table 49 on page 90](#) with additional detail provided in [Section 4.13.2](#).

Table 49. MMT-Specific Memory-Mapped Registers

Register	Type	Size	Description
SADD $\langle 4-5 \rangle$	Source Address	32-bit	Prior to each MMT block move, the program must initialize the corresponding SADD $\langle 4-5 \rangle$ register with the starting address in memory for the source block (read data). The DMAU updates the register with the address of the next memory location to be read by the specified MMT channel as the block move proceeds. Table 37 on page 76 describes the bit fields of SADD $\langle 4-5 \rangle$.
SCNT $\langle 4-5 \rangle$	Source Counter	20-bit	This register contains the source row and column counter for the corresponding channel. The DMAU updates the register as the block move proceeds and automatically clears the register upon the completion of the block move. The source row (SROW) is encoded in SCNT $\langle 4-5 \rangle$ [19:7], and the source column (SCOL) is encoded in SCNT $\langle 4-5 \rangle$ [6:0]. Note: SCNT $\langle 4-5 \rangle$ are not cleared by a reset of the DMAU channel via the DMCON1 register (Table 32 on page 71). Before an MMT channel can be used, the program must clear the corresponding SCNT $\langle 4-5 \rangle$ register after a DSP16410B device reset. Otherwise, the value of this register is undefined.
DADD $\langle 4-5 \rangle$	Destination Address	32-bit	Prior to each MMT block move, the program must initialize the corresponding DADD $\langle 4-5 \rangle$ register with the starting address in memory for the destination block (write data). The DMAU updates the register with the address of the next memory location to be written by the specified MMT channel as the block move proceeds. Table 37 on page 76 describes the bit fields of DADD $\langle 4-5 \rangle$.
DCNT $\langle 4-5 \rangle$	Destination Counter	20-bit	This register contains the destination row and column counter for the corresponding channel. The DMAU updates the register as the block move proceeds and automatically clears the register upon the completion of the block move. The destination row (DROW) is encoded in DCNT $\langle 4-5 \rangle$ [19:7] and the destination column (DCOL) is encoded in DCNT $\langle 4-5 \rangle$ [6:0]. Note: DCNT $\langle 4-5 \rangle$ are not cleared by a reset of the DMAU channel via the DMCON1 register (Table 32 on page 71). Before an MMT channel can be used, the user program must clear the corresponding DCNT $\langle 4-5 \rangle$ register after a DSP16410B device reset. Otherwise, the value of this register is undefined.
LIM $\langle 4-5 \rangle$	Limit	20-bit	The user programs LIM $\langle 4-5 \rangle$ with the last row count and the last column count for both the source and destination blocks for the corresponding channel. The last row count is the number of rows minus one and is encoded in the LASTROW field (LIM $\langle 4-5 \rangle$ [19:7]). The last column count is the number of columns minus one and is encoded in the LASTCOL field (LIM $\langle 4-5 \rangle$ [6:0]). Typically, LASTCOL is zero for a block move.
CTL $\langle 4-5 \rangle$	Control	16-bit	CTL $\langle 4-5 \rangle$ controls interrupt generation for both the source and destination block moves.

The two 16-bit DMAU master control registers, **DMCON0** and **DMCON1**, influence the operation of the MMT channels. The 32-bit DMAU status register, **DSTAT**, reflects the status of any MMT transfer. The bit field definition of the DMAU control and status registers is given in [Section 4.13.2](#).

4 Hardware Architecture (continued)

4.13 Direct Memory Access Unit (DMAU) (continued)

4.13.7 Interrupts and Priority Resolution

The DMAU provides information to both cores of the DSP16410B in the form of status and interrupts. A core can determine status by reading the DMAU's memory-mapped **DSTAT** register, which reflects the current state of any DMAU channel. The field definitions for **DSTAT** are defined in [Table 30 on page 68](#).

A core can configure the DMAU interrupts by programming the corresponding SIGCON[2:0] field (**CTL** \langle **0—3** \rangle [3:1]—[Table 34 on page 73](#) and **CTL** \langle **4—5** \rangle [3:1]—see [Table 36 on page 75](#)). Several DMAU interrupt signals are multiplexed to each core, so not all DMAU interrupt requests can be monitored by a core simultaneously. Refer to [Section 4.4.2](#) regarding the interrupt multiplexer, IMUX. [Table 50](#) provides a list of the DMAU interrupt signals and their description.

Table 50. DMAU Interrupts

DMAU Channel	Description [†]	DSP Core Interrupt Name
SWT0	SIU0 source (output) transaction complete	DSINT0
	SIU0 destination (input) transaction complete	DDINT0
SWT1	SIU0 source (output) transaction complete	DSINT1
	SIU0 destination (input) transaction complete	DDINT1
SWT2	SIU1 source (output) transaction complete	DSINT2
	SIU1 destination (input) transaction complete	DDINT2
SWT3	SIU1 source (output) transaction complete	DSINT3
	SIU1 destination (input) transaction complete	DDINT3
MMT4	Memory-to-memory transfer complete	DMINT4
MMT5	Memory-to-memory transfer complete	DMINT5

[†] The SIGCON[2:0] field of the channel's **CTL** \langle **0—5** \rangle register determines the condition under which the DMAU asserts the interrupt. See [Table 34 on page 73](#) for a description of **CTL** \langle **0—3** \rangle or [Table 36 on page 75](#) for a description of **CTL** \langle **4—5** \rangle .

4 Hardware Architecture (continued)

4.13 Direct Memory Access Unit (DMAU) (continued)

4.13.7 Interrupts and Priority Resolution (continued)

The DMAU provides arbitration for requests from many sources. If multiple requests are pending simultaneously, the DMAU completes its current transaction¹ and then provides access to the source that has the highest priority. The order of priority, from highest to lowest, is as follows:

1. SWT0 source transaction (SIU0 output) (highest)
2. SWT0 destination transaction (SIU0 input)
3. SWT1 source transaction (SIU0 output)
4. SWT1 destination transaction (SIU0 input)
5. SWT2 source transaction (SIU1 output)
6. SWT2 destination transaction (SIU1 input)
7. SWT3 source transaction (SIU1 output)
8. SWT3 destination transaction (SIU1 input)
9. PIU
10. MMT4 destination write
11. MMT5 destination write
12. MMT4 source fetch
13. MMT5 source fetch (lowest)

MMT channel block transfers that are in progress are paused if any SWT or PIU bypass channel request occurs. The single SWT or bypass channel transaction completes, and then the paused MMT channel block transfer resumes.

MMT channel priority can be changed by the user software. The default priority of the MMT channels is listed above. If both MMT4 and MMT5 require service at the same time, an MMT4 request has higher priority than the corresponding MMT5 request. The default operation does not allow a new MMT request to interrupt an MMT block transfer already in progress, i.e., the DMAU's default condition is to start and complete an MMT block transfer before a new MMT block transfer can begin. Any MMT block transfer can be interrupted by any SWT or PIU bypass channel transaction.

The default operation of the MMT channels can be changed. The HPRIM field (**DMCON0**[15]—[Table 31 on page 70](#)) is used to select the relative priority of MMT4 and MMT5. If HPRIM is cleared (the default), MMT4 has higher priority than MMT5. If HPRIM is set, MMT5 has the higher priority.

A higher-priority MMT channel can be made to interrupt a lower-priority MMT channel block transfer already in progress. The MINT field (**DMCON0**[14]) controls this feature. If MINT is cleared, MMT channels do not interrupt each other, as stated above, and an MMT block transfer already in progress completes before another MMT channel request is taken. If MINT is set, the higher-priority MMT channel can interrupt the lower-priority channel as determined by the HPRIM field setting. In a typical application, the higher-priority channel is assigned to moving small, time-critical data blocks, and the lower-priority channel is assigned to large, less time-critical blocks. This feature alleviates latency that can be incurred due to the transfer of large data blocks.

1. A request to the DMAU can result in more than one transaction, a transaction being the transfer of one single (16-bit) or double (32-bit) word.

4 Hardware Architecture (continued)

4.13 Direct Memory Access Unit (DMAU) (continued)

4.13.8 Error Reporting and Recovery

Each of the ERR[5:0] fields of the **DSTAT** register (Table 30 on page 68) reflects a DMAU protocol failure that indicates a loss of data for the corresponding channel. For the SWT<0—3> channels, the DMAU sets the corresponding ERR[3:0] field if:

- An SIU<0—1> requests DMAU service for a channel before the DMAU has accepted the previous request from that SIU<0—1> for that channel.
- An SIU<0—1> requests DMAU service for a channel and that channel's RESET[3:0] field (**DMCON1**[3:0]—Table 32 on page 71) is set.
- An SIU<0—1> requests DMAU destination/source service for a channel and that channel's DRUN[3:0]/SRUN[3:0] field (**DMCON0**[7:0]—Table 31 on page 70) is cleared.
- An SIU<0—1> requests DMAU service for a channel and that channel's source/destination transfer is complete (**SCNT**<0—3>/**DCNT**<0—3> = **LIM**<0—3>) and that channel's AUTOLOAD field (**CTL**<0—3>[0]—Table 34 on page 73) is cleared.

For the MMT<4—5> channels, the DMAU sets the corresponding ERR[5:4] field if:

- The user software attempts to set the TRIGGER[5:4] field by writing 1 to **DMCON0**[11:10] and the TRIGGER[5:4] field is already set.
- The user software attempts to set the TRIGGER[5:4] field by writing 1 to **DMCON0**[11:10] and the RESET[5:4] field (**DMCON1**[5:4]) is set.

If servicing a DMAU channel interrupt, the user software should poll **DSTAT** to determine whether an error has occurred. If so, the user software must perform the following steps:

1. Set the corresponding RESET[5:0] field (**DMCON1**[5:0]) to terminate all channel activity.
2. Write a 1 to the corresponding ERR[5:0] field to clear the field and the error condition.
3. Reinitialize the corresponding channel address and count registers.
4. Clear the corresponding RESET[5:0] field to re-allow channel activity.
5. For an MMT channel, re-enable a channel transfer by setting the appropriate TRIGGER[5:4] field (**DMCON0**[11:10]).

4 Hardware Architecture (continued)

4.13 Direct Memory Access Unit (DMAU) (continued)

4.13.9 Programming Examples

This section illustrates three typical DMAU applications.

4.13.9.1 SWT Example 1: A Two-Dimensional Array

This example describes the input and output of four channels of full-duplex TDM speech data from SIU0 with the following assumptions:

- The data is double-buffered to avoid latencies and the potential of missing samples.
- Input and output data have the same array size and structure and are processed by the SWT0 channel.
- There are four logical channels (time slots) grouped in four contiguous double buffers, corresponding to the number of columns (*n*) in a two-dimensional array.
- Each single buffer has 160 elements, or rows (*r*), and each double buffer has a length of 320 (0x140).
- CORE0 begins processing data after 160 samples have been input for all four logical channels.
- SIU0 input (destination) data begins at address 0x01000 in TPRAM0.
- SIU0 output (source) data begins at address 0x02000 in TPRAM0.
- The autoloading feature is used to minimize core intervention.

Figure 23 illustrates this data structure. This example does not discuss the setup and control of SIU0.

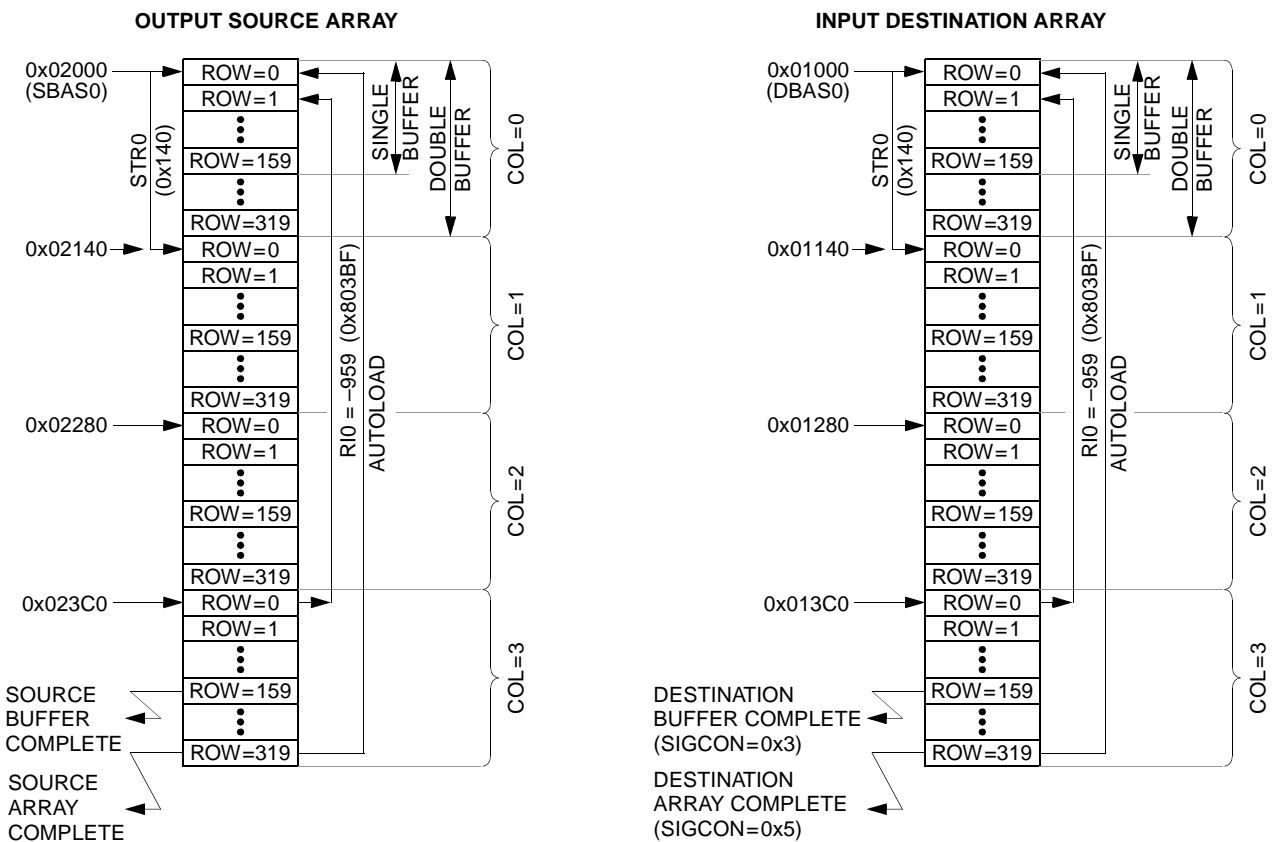


Figure 23. Example of a Two-Dimensional Double-Buffered Data Structure

4 Hardware Architecture (continued)

4.13 Direct Memory Access Unit (DMAU) (continued)

4.13.9 Programming Examples (continued)

4.13.9.1 SWT Example 1: A Two-Dimensional Array (continued)

The user software running in CORE0 must perform the following steps to properly initialize SWT0:

1. The user software sets the source address (**SADD0**—Table 37 on page 76) and the source base address (**SBAS0**—Table 44 on page 80) to the top of the output (source) array located in TPRAM0. The user software writes 0x00002000 to **SADD0** and 0x02000 to **SBAS0**.
2. The user software sets the destination address (**DADD0**—Table 37 on page 76) and the destination base address (**DBAS0**—Table 45 on page 80) to the top of the input (destination) array located in TPRAM0. The user software writes 0x00001000 to **DADD0** and 0x01000 to **DBAS0**.
3. The user software clears the source and destination counter registers **SCNT0** and **DCNT0** (Table 38 on page 77 and Table 40 on page 78).
4. The user software initializes the limit register (**LIM0**—Table 42 on page 79) with the dimensions of the array. The number of rows (or elements) is $2r$ (320), so the user software writes 319 ($2r - 1$) into the LASTROW[12:0] field (**LIM0**[19:7]). The number of columns is 4, so the user software writes 3 ($n - 1$) into the LASTCOL[6:0] field (**LIM0**[6:0]). The user software writes 0x09F83 into **LIM0**.
5. The user software initializes the stride register (**STR0**—Table 46 on page 81) with the distance between corresponding rows of consecutive columns. Because the buffers are contiguous in this example, the stride is the same as the buffer length and the user software writes 0x0140 into **STR0**.
6. The user software initializes the reindex register (**RI0**—Table 47 on page 81) with the sign-magnitude postmodification value to be applied to **SADD0** and **DADD0** after each time that the last column has been accessed. The magnitude of the reindex value is $((2r \times (n - 1)) - 1)$ or $(320 \times 3) - 1 = 959 = 0x3BF$. The sign must be negative, so the user software writes 0x803BF into **RI0**.
7. The user software writes the control registers to enable SWT0 and begin I/O processing. First, the user software writes one into the POSTMOD[1:0] field (**CTL0**[5:4]—Table 34 on page 73) to enable

two-dimensional array accesses, writes 0x3 to the SIGCON[2:0] field (**CTL0**[3:1]), and writes 1 to the AUTOLOAD field (**CTL0**[0]) so that no further core interaction is needed. The user software writes 0x0017 to **CTL0**.

8. Finally, the user software sets both the SRUN0 and DRUN0 fields (**DMCON0**[0] and **DMCON0**[4]—Table 31 on page 70) to enable SWT0 source and destination transfers. The user software writes 0x0011 to **DMCON0**.

The DMAU begins processing the SWT0 input and output channels. For the output channel, the DMAU performs the following steps:

1. It reads the single word at the TPRAM0 location pointed to by **SADD0** (0x00002000) and transfers the data to SIU0. This data is the first output sample for the first logical channel (ROW = 0 and COL = 0).
2. It increments **SADD0** by the contents of **STR0**, so **SADD0** contains 0x00002140 and points to the first output sample for the second logical channel (ROW = 0 and COL = 1). It updates **SCNT0** by incrementing the column counter, so **SCNT0** contains 0x00001.
3. It reads the data at 0x02140 and transfers it to SIU0.
4. It increments **SADD0** by the contents of **STR0**, so **SADD0** contains 0x00002280 and points to the first output sample for the third logical channel (ROW = 0 and COL = 2). It updates **SCNT0** by incrementing the column counter, so **SCNT0** contains 0x00002.
5. As in steps 3 and 4, the DMAU continues to read data, transfer the data to SIU0, and update **SADD0** and **SCNT0** until the column counter equals the last column (**SCNT0**[6:0] = **LIM0**[6:0] = 3). **SADD0** contains 0x000023C0 and points to the first row of the last column.
6. The DMAU subtracts the magnitude of the contents of **RI0** from **SADD0** (0x000023C0 - 0x3BF) and places the result into **SADD0** (0x00002001). **SADD0** points to the second output sample for the first logical channel (ROW = 1 and COL = 0).

The DMAU continues processing in this manner until it processes row 159 of column 3. At this point, ROW = LASTROW/2 and COL = LASTCOL. Because this condition is met and SIGCON[2:0] = 0x3, the DMAU asserts the DSINT0 interrupt to CORE0. CORE0's ISR changes SIGCON[2:0] to 0x5 so that the DMAU asserts DSINT0 again after it has processed the remaining samples in the buffers. CORE0 can overwrite the already-processed samples while the DMAU continues to process the remaining samples.

The steps performed by the DMAU for the input channel are similar to those for the output channel.

4 Hardware Architecture (continued)

4.13 Direct Memory Access Unit (DMAU) (continued)

4.13.9 Programming Examples (continued)

4.13.9.2 SWT Example 2: A One-Dimensional Array

This example describes the input of four blocks of speech data from SIU1 with the following assumptions:

- The data is single-buffered.
- Data is processed by the SWT3 channel.
- There are four blocks of data grouped in four contiguous buffers, corresponding to the number of columns (n) in a one-dimensional array.
- Each single buffer has 160 elements, or rows ($r = 0xA0$).
- The DMAU fills four buffers in sequential order, i.e., it receives all 160 samples of one buffer and then all 160 samples of the next buffer, etc.
- The DMAU places the data in ascending linear order in memory beginning at TPRAM1 address 0x01000.
- CORE1 begins processing data after 160 samples have been input.
- The autoloading feature is used to minimize core intervention.

Figure 24 illustrates the data structure for this example.

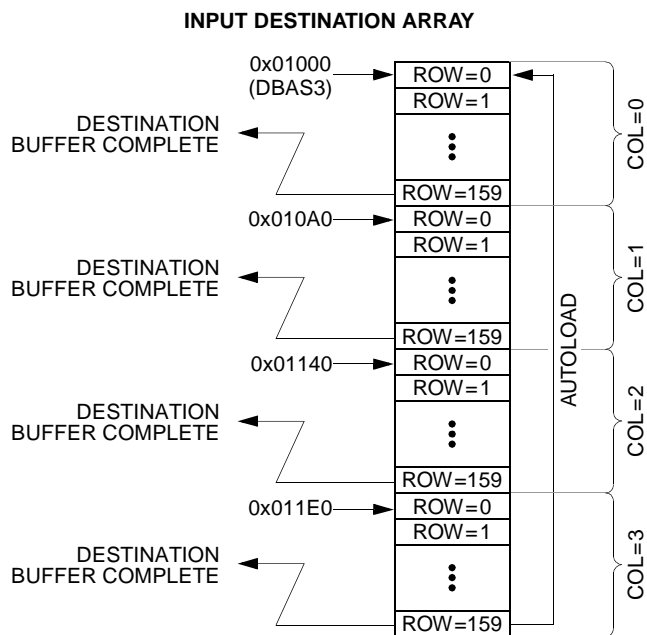


Figure 24. Example of One-Dimensional Data Structure

4 Hardware Architecture (continued)

4.13 Direct Memory Access Unit (DMAU) (continued)

4.13.9 Programming Examples (continued)

4.13.9.2 SWT Example 2: A One-Dimensional Array (continued)

The user software running in CORE1 must perform the following steps to properly initialize SWT3:

1. The user software sets the destination address (**DADD3**—Table 37 on page 76) and the destination base address (**DBAS3**—Table 45 on page 80) to the top of the input (destination) array located in TPRAM1. The user software writes 0x00101000 to **DADD3** and 0x01000 to **DBAS3**.
2. The user software clears the destination counter (**DCNT3**—Table 40 on page 78).
3. The user software initializes the limit register (**LIM3**—Table 42 on page 79) with the dimensions of the array. The number of rows (or elements) is 160, so the user software writes 159 ($r - 1$) into the LASTROW[12:0] field (**LIM3**[19:7]). The number of columns is 4, so the user software writes 3 ($n - 1$) into the LASTCOL[6:0] field (**LIM3**[6:0]). The user software writes 0x04F83 to **LIM3**.
4. The user software writes the control registers to enable SWT3 and begin I/O processing. First, the user software writes two into the POSTMOD[1:0] field (**CTL3**[5:4]—Table 34 on page 73) to enable one-dimensional array accesses, writes 0x4 to the SIGCON[2:0] field (**CTL3**[3:1]), and writes 1 to the AUTOLOAD field (**CTL3**[0]) so that no further core interaction is needed. The user software writes 0x0029 to **CTL3**.
5. Finally, the user software sets the DRUN3 field (**DMCON0**[7]—Table 31 on page 70) to enable SWT3 destination transfers. The user software writes 0x0080 to **DMCON0**.

The DMAU begins processing the SWT3 input channel and performs the following steps:

1. It receives data from SIU1 and writes it to the single-word TPRAM1 location pointed to by **DADD3** (0x00101000). This data is the first input sample for the first buffer (ROW = 0 and COL = 0).
2. It increments **DADD3** by one, so **DADD3** contains 0x00101001 and points to the second input sample for the first buffer (ROW = 1 and COL = 0). It updates **SCNT3** by incrementing the row counter, so **SCNT3** contains 0x00080.
3. It receives data from SIU1 and writes it to the single-word TPRAM1 location pointed to by **DADD3** (0x00101001).

The DMAU continues processing in this manner until it fills row 159 of column 0. At this point, ROW = LASTROW and COL = 0. Because this condition is met and SIGCON[2:0] = 0x4, the DMAU asserts the DDINT3 interrupt to CORE1. CORE1 can begin processing the first buffer while the DMAU continues to fill the second buffer.

4 Hardware Architecture (continued)

4.13 Direct Memory Access Unit (DMAU) (continued)

4.13.9 Programming Examples (continued)

4.13.9.3 MMT Example

This example illustrates the use of MMT4 to move a source block of 100 rows or elements ($r = 100$) in TPRAM0 to a destination block in TPRAM1, as Figure 25 illustrates. For this example, the source address in TPRAM0 is 0x01000 and the destination address in TPRAM1 is 0x02000.

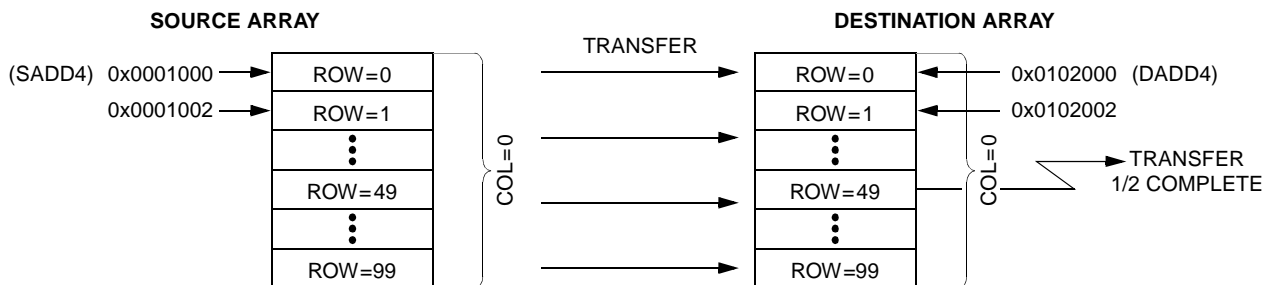


Figure 25. Memory-to-Memory Block Transfer

The user software running in one of the cores must perform the following steps to properly initialize MMT4:

1. The user software writes the source address (**SADD4**—Table 37 on page 76) with the top of the output (source) block located in TPRAM0. The user software writes 0x00001000 to **SADD4**.
2. The user software writes the destination address (**DADD4**—Table 37 on page 76) with the top of the input (destination) block located in TPRAM1. The user software writes 0x00102000 to **DADD4**.
3. The user software clears the source and destination counter registers **SCNT4** and **DCNT4** (Table 39 on page 77 and Table 41 on page 78).
4. The user software initializes the limit register (**LIM4**—Table 43 on page 79) with the dimensions of the array. The number of rows (or elements) is 100, so the user software writes 99 ($r - 1$) into the LASTROW[12:0] field (**LIM4**[19:7] = 0x63). The number of columns is one, so the user software writes zero into the LASTCOL[6:0] field (**LIM4**[6:0]). The user software writes 0x03180 to **LIM4**.
5. The user software writes the control registers to enable MMT4 and begin block processing. First, the user software writes two into the POSTMOD[1:0] field (**CTL4**[5:4]—Table 36 on page 75) to enable pointer and counter update operations, and writes 0x1 to the SIGCON[2:0] field (**CTL4**[3:1]). The user software writes 0x0022 to **CTL4**.
6. Finally, the user software sets the SLKA4 field (**DMCON0**[8]—Table 31 on page 70) to enable source look-ahead, sets the XSIZE4 field (**DMCON0**[12]) to transfer 32-bit words, and sets the TRIGGER4 field (**DMCON0**[10]) to initiate MMT4 block transfers. The user software writes 0x1500 to **DMCON0**.

The DMAU begins processing the MMT4 channel. For each read operation from TPRAM0 starting at address 0x01000, the DMAU increments **SADD4** by two and increments the SROW[12:0] field of **SCNT4** by one. The DMAU performs multiple fetches from TPRAM0 and places the data into the source look-ahead buffer. For each write operation to TPRAM1 starting at address 0x02000, the DMAU increments **DADD4** by two and increments the SROW[12:0] field of **DCNT4** by one. Because SIGCON[2:0] = 0x1, the DMAU interrupts the cores when the transfer is half complete ($DROW[12:0] = LASTROW/2 = LASTROW[12:0] \gg 1 = 0x31$ or **DCNT4** = 0x1880). The ISR then changes SIGCON[2:0] to 0x4 to cause the DMAU to interrupt the cores again when the transfer is complete ($DROW[12:0] = LASTROW[12:0]$ or **DCNT4** = **LIM4** = 0x3180).

4 Hardware Architecture (continued)

4.14 System and External Memory Interface (SEMI)

The system and external memory interface (SEMI) is the DSP16410B interface to external memory and memory-mapped off-chip peripherals:

- The SEMI supports a maximum total external memory size of 18 Mwords (16-bit words) through a combination of an address bus, an address bus extension, and decoded enables.
- The SEMI can configure the external data bus as either 16 bits or 32 bits.
- The SEMI can support a mix of asynchronous memory and synchronous, pipelined *ZBT* (zero bus turnaround) SRAMs.
- The SEMI provides support for bus arbitration logic for shared-memory systems.
- The SEMI provides programmable enable assertion, setup, and hold times for external asynchronous memory.

These features are controlled via a combination of SEMI pins and control registers. Some additional features of the SEMI are the following:

- The SEMI arbitrates and prioritizes accesses from both cores and from the DMAU.
- The SEMI allows the cores to boot from internal or external memory controlled by the state of an input pin.
- The SEMI controls the internal system bus, which allows the cores, the DMAU, and the PIU to access the shared internal I/O memory component. This component includes the SLM and the internal memory-mapped registers within the DMAU, SIU0, SIU1, PIU, and SEMI.

Figure 26 depicts the internal and external interfaces to the SEMI. The SEMI interfaces directly to the X-memory space buses and Y-memory space buses for both cores and to the DMAU's external Z-memory space buses. This allows:

- Either core to perform external program or data accesses.
- Either core or the DMAU to access the SLM or internal memory-mapped registers.

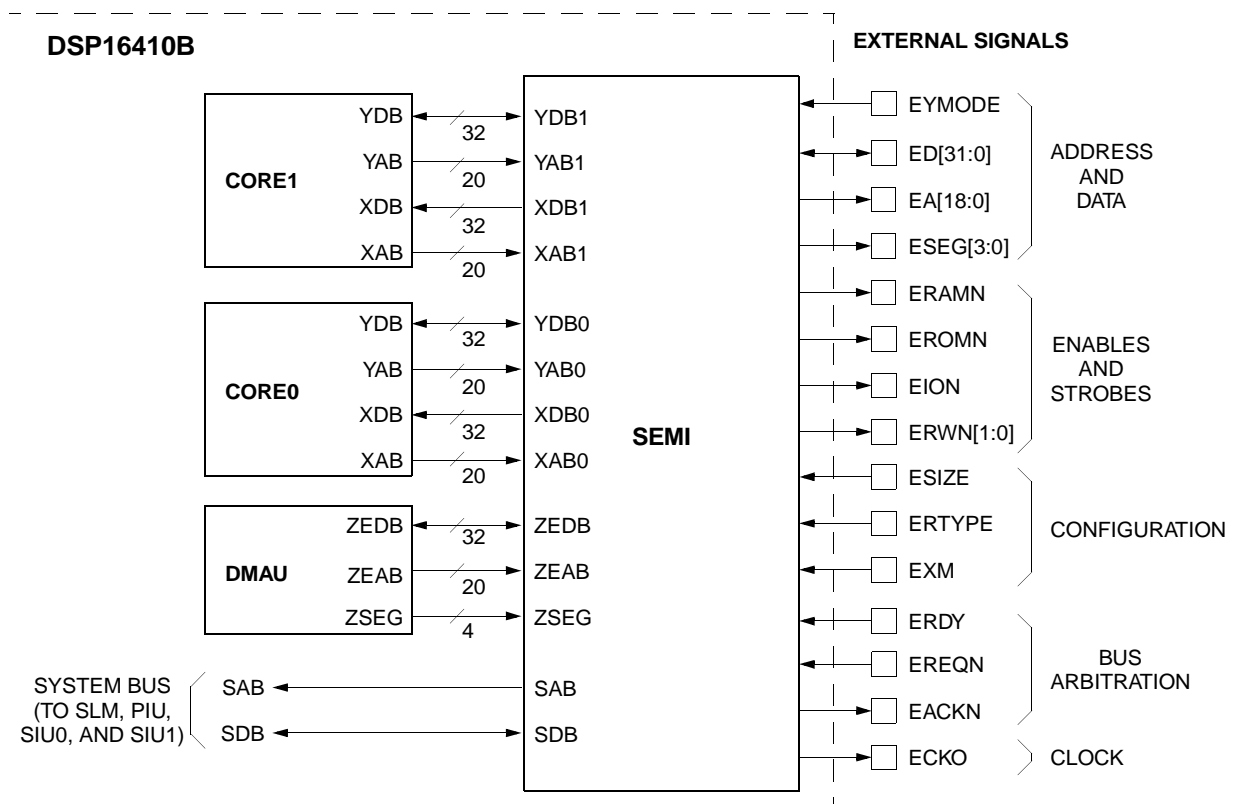


Figure 26. SEMI Interface Block Diagram

4 Hardware Architecture (continued)

4.14 System and External Memory Interface (SEMI) (continued)

4.14.1 External Interface

Table 51 provides an overview of the SEMI pins. These pins are described in detail in the remainder of this section.

Table 51. Overview of SEMI Pins

Function	Pin	Type	Description
Clock	ECKO	O	External clock.
Configuration	ESIZE	I	Size of external SEMI data bus: ESIZE = 0 selects 16-bit data bus. ESIZE = 1 selects 32-bit data bus.
	ERTYPE	I	EROM type: ERTYPE = 0 selects asynchronous memory for the EROM component. ERTYPE = 1 selects synchronous pipelined ZBT SRAM for the EROM component.
	EXM	I	Boot source: EXM = 0 selects IROM. EXM = 1 selects EROM.
Bus Arbitration for Asynchronous Memory	EREQN	I	External request for SEMI bus (negative assertion).
	EACKN	O	SEMI acknowledge for external request (negative assertion).
	ERDY	I	External device ready for asynchronous access.
Enables and Strobes	ERAMN	O/Z	ERAM component enable (negative assertion).
	EROMN	O/Z	EROM component enable (negative assertion).
	EION	O/Z	EIO component enable (negative assertion).
	ERWN[1:0]	O/Z	External read/write not: If ESIZE = 0 (16-bit external bus): ERWN1: Inactive (logic high). ERWN0: Write enable (negative assertion). If ESIZE = 1 (32-bit external bus): ERWN1: Odd word (least significant 16 bits) write enable (negative assertion). ERWN0: Even word (most significant 16 bits) write enable (negative assertion).
Address and Data	ED[31:0]	I/O/Z	Bidirectional 32-bit external data bus.
	EA[18:1]	O/Z	External address bus bits 18—1.
	EA0	O/Z	If ESIZE = 0: External address bus bit 0. If ESIZE = 1 and the external component is synchronous [†] : Write strobe (negative assertion).
	ESEG[3:0]	O/Z	External segment address.
	EYMODE	I	This pin determines the mode of the external data bus. It must be static and tied to V _{ss} (if the SEMI is used) or V _{DD2} (if the SEMI is not used). If EYMODE = 0, the external data bus ED[31:0] operates normally as described above. If EYMODE = 1, ED[31:0] are statically configured as outputs (regardless of the state of RSTN) and must not be connected externally. If EYMODE = 1, external pull-up resistors are not needed on ED[31:0]. See Section 10.1 on page 269 for details.

[†] The EROM component is synchronous if the ERTYPE pin is logic 1. The ERAM component is synchronous if YTYPE field (ECON1[9]) is set and the EIO component is synchronous if the ITYPE field (ECON1[10]) is set. ECON1 is described in Table 60 on page 110.

4 Hardware Architecture (continued)

4.14 System and External Memory Interface (SEMI) (continued)

4.14.1 External Interface (continued)

4.14.1.1 Configuration

The SEMI configuration pins are inputs that are individually tied high or low based on system requirements. The ESIZE and ERTYPE pins reflect the configuration of the external memory system. The EXM pin specifies the memory boot area for the DSP16000 cores. [Table 52](#) details the SEMI configuration pins.

Table 52. Configuration Pins for the SEMI External Interface

Pin	Value	Description
ESIZE (input)	0	Configures external data bus as 16 bits: <ul style="list-style-type: none"> ■ ED[31:16] is active, and ED[15:0] is 3-state. ■ EA[18:0] provides the address. ■ For a single-word (16-bit) access, the SEMI places the address onto EA[18:0]: <ul style="list-style-type: none"> — For a read, the SEMI transfers the word from ED[31:16]. — For a write, the SEMI drives the word onto ED[31:16] and asserts ERWN0. ■ For a double-word (32-bit) access, the SEMI performs two single-word (16-bit) accesses: <ul style="list-style-type: none"> — First, the SEMI accesses the most significant half of the double word at the original address (see single-word (16-bit) access described above). — Second, the SEMI increments the address and accesses the least significant half of the double word (see single-word (16-bit) access described above).
	1	Configures external data bus as 32 bits: <ul style="list-style-type: none"> ■ EA[18:1] provides the even address. ■ For a single-word (16-bit) access to an even location: <ul style="list-style-type: none"> — For a read, the SEMI transfers the word from ED[31:16] and ignores ED[15:0]. — For a write, the SEMI drives the word onto ED[31:16] and asserts ERWN0†. ■ For a single-word (16-bit) access to an odd location: <ul style="list-style-type: none"> — For a read, the SEMI transfers the word from ED[15:0] and ignores ED[31:16]. — For a write, the SEMI drives the word onto ED[15:0] asserts ERWN1†. ■ For a double-word (32-bit) aligned access, i.e., an access to an even address: <ul style="list-style-type: none"> — For a read, the SEMI transfers the double word from ED[31:0]. — For a write, the SEMI drives the double word onto ED[31:0] and asserts ERWN0 and ERWN1†. ■ For a double-word (32-bit) misaligned access, the SEMI performs two single-word (16-bit) accesses: <ul style="list-style-type: none"> — First, the SEMI accesses the most significant half of the double word at the original address (see single-word (16-bit) access to an odd location described above). — Second, the SEMI increments the address and accesses the least significant half of the double word (see single-word (16-bit) access to an even location described above).
ERTYPE (input)	0	The EROM component is populated with ROM or asynchronous SRAM, and the SEMI performs asynchronous accesses to the EROM component.
	1	The EROM component is populated with synchronous ZBT SRAM, and the SEMI performs synchronous accesses to the EROM component.
EXM (input)	0	If EXM is logic low when the RSTN pin makes a low-to-high transition, both cores begin program execution from their internal ROM (IROM) memory at location 0x20000.
	1	If EXM is logic high when the RSTN pin makes a low-to-high transition, both cores begin program execution from external ROM (EROM) memory at location 0x80000. The SEMI arbitrates the accesses from the two cores.

† For a synchronous write, the SEMI also asserts EA0 as a write strobe. The EROM component is synchronous if the ERTYPE pin is logic high. The ERAM component is synchronous if the YTYPE field (**ECON1**[9]) is set. The EIO component is synchronous if the ITYPE field (**ECON1**[10]) is set. **ECON1** is described in [Table 60 on page 110](#).

4 Hardware Architecture (continued)

4.14 System and External Memory Interface (SEMI) (continued)

4.14.1 External Interface (continued)

4.14.1.2 Asynchronous Memory Bus Arbitration

The SEMI allows an external device to request direct access to an asynchronous external memory by asserting the EREQN pin. The SEMI acknowledges the external request by asserting its EACKN pin. The SEMI allows an external device to extend the duration of an external asynchronous access by deasserting the ERDY pin.

Table 53. Asynchronous Memory Bus Arbitration Pins

Pin	Description
EREQN (negative-assertion input)	<p>An external device asserts EREQN (low) to request direct access to an asynchronous external memory. If the NOSHARE field (ECON1[8]—see Table 60 on page 110) is set, the DSP16410B ignores the request. If NOSHARE is cleared, a minimum of four cycles later the SEMI grants the request by performing the following:</p> <ul style="list-style-type: none"> ■ First, the SEMI completes any external access that is already in progress. ■ The SEMI 3-states the address bus and segment address (EA[18:0] and ESEG[3:0]), the data bus (ED[31:0]), and all the external enables and strobes (ERAMN, EROMN, EION, and ERWN[1:0]) until the external device deasserts EREQN. The SEMI continues to drive ECKO. ■ The SEMI acknowledges the request by asserting EACKN. <p>The cores and the DMAU continue processing. If a core or the DMAU attempts to perform an external memory access, it stalls until the external device relinquishes the bus. If the external device deasserts EREQN (changes EREQN from 0 to 1), four cycles later the SEMI deasserts EACKN (changes EACKN from 0 to 1). To avoid external bus contention, the external device must wait for at least $ATIME_{MAX}$ cycles[†] after it deasserts EREQN (changes EREQN from 0 to 1) before reasserting EREQN (changing EREQN from 1 to 0). The software can read the state of the EREQN pin in the EREQN field (ECON1[4]—see Table 60 on page 110).</p> <p>Note: If EREQN is not in use by the application, it must be tied high.</p>
EACKN (negative-assertion output)	<p>The SEMI acknowledges the request of an external device for direct access to an asynchronous external memory by asserting EACKN. See the description of the EREQN pin above for details. The software can read the state of the EACKN pin in the EACKN field (ECON1[5]—see Table 60 on page 110).</p>
ERDY (positive-assertion input)	<p>An external device instructs the SEMI to extend the duration of the current asynchronous external memory access by driving ERDY low. See Section 4.14.5.2 for details. The software can read the state of the ERDY pin in the EREADY field (ECON1[6]—see Table 60 on page 110).</p> <p>Note: If this pin is not in use by the application or if all external memory is synchronous, ERDY must be tied high.</p>

[†] $ATIME_{MAX}$ is the greatest of IATIME(**ECON0**[11:8]), YATIME (**ECON0**[7:4]), and XATIME (**ECON0**[3:0]).

4 Hardware Architecture (continued)

4.14 System and External Memory Interface (SEMI) (continued)

4.14.1 External Interface (continued)

4.14.1.3 Enables and Strobes

The SEMI provides a negative-assertion external memory enable output pin for each of the three external memory components, ERAM, EIO, and EROM. These pins are the active-low enables for the external memory components ERAM (external RAM), EROM (external ROM), and EIO (external I/O). Refer to the memory maps described in [Section 4.5 on page 37](#) and shown in [Figures 6, 7, 8, and 9](#) for details about these memory components. The SEMI provides two negative-assertion write strobe output pins, ERWN[1:0]. [Table 54](#) details the SEMI enables and strobe pins. The SEMI 3-states the enables and strobes if it grants a request by an external device to access the external memory (see description of the EREQN pin in [Table 53 on page 102](#)).

Table 54. Enable and Strobe Pins for the SEMI External Interface

Pin	Value	Description
ERAMN (negative-assertion output)	0	The SEMI is selecting the ERAM memory component for an access. The SEMI asserts this enable for a duration based on whether the ERAM memory component is configured as asynchronous or synchronous: <ul style="list-style-type: none"> ■ If the ERAM memory component is configured as asynchronous (the YTYPE field (ECON1[9]—see Table 60 on page 110) is cleared), the SEMI asserts ERAMN for the number of instruction cycles specified by the YATIME[3:0] field (ECON0[7:4]—see Table 59 on page 109). ■ If the ERAM memory component is configured as synchronous (the YTYPE field is set), the SEMI asserts ERAMN for two instruction cycles (one ECKO cycle[†]) for a read or write operation.
	1	The SEMI is not selecting the ERAM memory component for an access.
	Z	The SEMI 3-states ERAMN if it grants a request by an external device to access the external memory (see description of the EREQN pin in Table 53 on page 102).
EION (negative-assertion output)	0	The SEMI is selecting the EIO memory component for an access. The SEMI asserts this enable for a duration based on whether the EIO memory component is configured as asynchronous or synchronous: <ul style="list-style-type: none"> ■ If the EIO memory component is configured as asynchronous (the ITYPE field (ECON1[10]—see Table 60 on page 110) is cleared), the SEMI asserts EION for the number of instruction cycles specified by the IATIME[3:0] field (ECON0[11:8]—see Table 59 on page 109). ■ If the EIO memory component is configured as synchronous (the ITYPE field is set), the SEMI asserts EION for two instruction cycles (one ECKO cycle[†]) for a read or write operation.
	1	The SEMI is not selecting the EIO memory component for an access.
	Z	The SEMI 3-states EION if it grants a request by an external device to access the external memory (see description of the EREQN pin in Table 53 on page 102).
EROMN (negative-assertion output)	0	The SEMI is selecting the EROM memory component for an access [‡] . The SEMI asserts this enable for a duration based on whether the EROM memory component is configured as asynchronous or synchronous: <ul style="list-style-type: none"> ■ If the EROM memory component is configured as asynchronous (the ERTYPE pin is low), the SEMI asserts EROMN for the number of instruction cycles specified by the XATIME[3:0] field (ECON0[3:0]—see Table 59 on page 109). ■ If the EROM memory component is configured as synchronous (the ERTYPE pin is high), the SEMI asserts EROMN for two instruction cycles (one ECKO cycle[†]) for a read or write operation[‡].
	1	The SEMI is not selecting the EROM memory component for a read access.
	Z	The SEMI 3-states EROMN if it grants a request by an external device to access the external memory (see description of the EREQN pin in Table 53 on page 102).

[†] If any memory component is configured as synchronous, ECKO must be programmed as CLK/2, i.e., the ECKO[1:0] field (**ECON1**[1:0]—[Table 60 on page 110](#)) must be programmed to 0x0.

[‡] The SEMI can write the EROM component only if the WEROM field (**ECON1**[11]—see [Table 60 on page 110](#)) is set.

4 Hardware Architecture (continued)

4.14 System and External Memory Interface (SEMI) (continued)

4.14.1 External Interface (continued)

4.14.1.3 Enables and Strobes (continued)

Table 54. Enable and Strobe Pins for the SEMI External Interface (continued)

Pin	Value	Description
ERWN1 (negative-assertion output)	0	The external memory is configured for 32-bit data (the ESIZE pin is high), and the SEMI is performing an external write access over the least significant half of the external data bus (ED[15:0]).
	1	The external memory is configured for 16-bit data (the ESIZE pin is low) or the external memory is configured for 32-bit data (the ESIZE pin is high), and the SEMI is not performing an external write access over the least significant half of the external data bus (ED[15:0]).
	Z	The SEMI 3-states ERWN1 if it grants a request by an external device to access the external memory (see description of the EREQN pin in Table 53 on page 102).
ERWN0 (negative-assertion output)	0	The SEMI is performing an external write access over the most significant half of the external data bus (ED[31:16]).
	1	The SEMI is not performing an external write access over the most significant half of the external data bus (ED[31:16]).
	Z	The SEMI 3-states ERWN0 if it grants a request by an external device to access the external memory (see description of the EREQN pin in Table 53 on page 102).

† If any memory component is configured as synchronous, ECKO must be programmed as CLK/2, i.e., the ECKO[1:0] field (**ECON1**[1:0]—[Table 60 on page 110](#)) must be programmed to 0x0.

‡ The SEMI can write the EROM component only if the WEROM field (**ECON1**[11]—see [Table 60 on page 110](#)) is set.

4 Hardware Architecture (continued)

4.14 System and External Memory Interface (SEMI) (continued)

4.14.1 External Interface (continued)

4.14.1.4 Address and Data

The SEMI provides a 32-bit external data bus, ED[31:0]. If the external memory is configured for 16-bit data (the ESIZE input pin is low), the SEMI uses only the upper half of the data bus (ED[31:16]). The SEMI provides a 19-bit external address bus, EA[18:0], to select a location within the selected external memory component (ERAM, EIO, or EROM). If the external memory is configured for 16-bit data, the SEMI uses EA[18:0] to address single (16-bit) words within the selected memory component. If the external memory is configured for 32-bit data (the ESIZE input pin is high), the SEMI uses EA[18:1] to address double (32-bit) words within the selected memory component and does not use EA0 as an address bit. For more detail, see [Table 55](#) or [Section 4.14.2](#).

The SEMI provides the ESEG[3:0] pins to expand the size of each of the external memory components using one of the following methods:

1. ESEG[3:0] can be interpreted by the external memory system as four separate decoded address enable signals. Each ESEG[3:0] pin individually selects one of four segments for each memory component. This results in four glueless 512 Kword (1 Mbyte) ERAM segments, four glueless 512 Kword (1 Mbyte) EROM segments, and four glueless 128 Kword (256 Kbytes) EIO segments.
2. ESEG[3:0] can be interpreted by the external memory system as an extension of the address bus, i.e., the ESEG[3:0] pins can be concatenated with the EAB[18:0] pins to form a 23-bit address. This results in one glueless 8 Mword (16 Mbytes) ERAM segment, one glueless 8 Mword (16 Mbytes) EROM segment, and one glueless 2 Mword (4 Mbytes) EIO segment.

For external accesses by either core, the SEMI places the contents of a field in one of four segment address extension registers onto the ESEG[3:0] pins. The four segment address extension registers are described in [Section 4.14.4](#). For external accesses by the DMAU or PIU, the contents of address registers within those units determine the state of the ESEG[3:0] pins. See [Table 55](#) for more detail.

Table 55. Address and Data Bus Pins for the SEMI External Interface

Pins	Description
ED[31:16] (input/output)	<ul style="list-style-type: none"> ■ If the external memory is configured for 16-bit data (the ESIZE pin is low), the SEMI uses ED[31:16] for all external accesses. ■ If the external memory is configured for 32-bit data (the ESIZE pin is high), the SEMI uses ED[31:16] if: <ul style="list-style-type: none"> — The SEMI is accessing a single word (16 bits) at an even address. — The SEMI is accessing a double word at an even (aligned) address. — The SEMI is accessing the least significant half of a double word at an odd (misaligned) double-word address. ■ If the SEMI is not currently performing one of the above types of accesses, it 3-states ED[31:16].
ED[15:0] (input/output)	<ul style="list-style-type: none"> ■ If the external memory is configured for 32-bit data (the ESIZE pin is high), the SEMI uses ED[15:0] if: <ul style="list-style-type: none"> — The SEMI is accessing a single word (16 bits) at an odd address. — The SEMI is accessing a double word at an even (aligned) address. — The SEMI is accessing the most significant half of a double word at an odd (misaligned) double-word address. ■ If the SEMI is not currently performing one of the above types of accesses, it 3-states ED[15:0].

† The EROM component is synchronous if the ERTYPE pin is logic 1. The ERAM component is synchronous if YTYPE field (ECON1[9]) is set. The EIO component is synchronous if the ITYPE field (ECON1[10]) is set. ECON1 is described in [Table 60 on page 110](#).

4 Hardware Architecture (continued)

4.14 System and External Memory Interface (SEMI) (continued)

4.14.1 External Interface (continued)

4.14.1.4 Address and Data (continued)

Table 55. Address and Data Bus Pins for the SEMI External Interface (continued)

Pins	Description
EA[18:1] (output)	<ul style="list-style-type: none"> ■ If the external memory is configured for 16-bit data (the ESIZE pin is low), the SEMI places the 18 most significant bits of the 19-bit external address onto EA[18:1]. ■ If the external memory is configured for 32-bit data (the ESIZE pin is high), the SEMI places the 18-bit external address onto EA[18:1]. ■ After an access is complete and before the start of a new access, the SEMI continues to drive EA[18:1] with its current state. ■ The SEMI 3-states EA[18:1] if it grants a request by an external device to access the external memory (see description of the EREQN pin in Table 53 on page 102).
EA0 (output)	<ul style="list-style-type: none"> ■ If the external memory is configured for 16-bit data (the ESIZE pin is low), the SEMI places the least significant bit of the 19-bit external address onto EA0. ■ If the external memory is configured for 32-bit data (the ESIZE pin is high), the SEMI does not use EA0 as an address bit: <ul style="list-style-type: none"> — If the selected memory component is configured as asynchronous[†], the SEMI drives EA0 with its previous value. — If the selected memory component is configured as synchronous[†], the SEMI drives a negative-assertion write strobe onto EA0 (the SEMI drives EA0 with the logical AND of ERWN1 and ERWN0). ■ The SEMI 3-states EA0 if it grants a request by an external device to access the external memory (see description of the EREQN pin in Table 53 on page 102).
ESEG[3:0] (output)	<ul style="list-style-type: none"> ■ If CORE0 accesses EROM, the SEMI drives ESEG[3:0] with the contents of the XSEG0[3:0] field (EXSEG0[3:0])—see Table 61 on page 111). ■ If CORE1 accesses EROM, the SEMI drives ESEG[3:0] with the contents of the XSEG1[3:0] field (EXSEG1[3:0])—see Table 62 on page 111). ■ If CORE0 accesses ERAM, the SEMI drives ESEG[3:0] with the contents of the YSEG0[3:0] field (EYSEG0[3:0])—see Table 63 on page 112). ■ If CORE1 accesses ERAM, the SEMI drives ESEG[3:0] with the contents of the YSEG1[3:0] field (EYSEG1[3:0])—see Table 64 on page 112). ■ If CORE0 accesses EIO, the SEMI drives ESEG[3:0] with the contents of the ISEG0[3:0] field (EYSEG0[7:4])—see Table 63 on page 112). ■ If CORE1 accesses EIO, the SEMI drives ESEG[3:0] with the contents of the ISEG1[3:0] field (EYSEG1[7:4])—see Table 64 on page 112). ■ If one of the DMAU SWT<0–3> or MMT<4–5> channels accesses EROM, ERAM, or EIO, the SEMI places the contents of the ESEG[3:0] field (SADD<0–5>[26:23] for read operations and DADD<0–5>[26:23] for write operations—see Table 37 on page 76) onto its ESEG[3:0] pins. ■ If the PIU accesses EROM, ERAM, or EIO via the DMAU bypass channel, the SEMI places the contents of the ESEG[3:0] field (PA[26:23])—see Table 78 on page 135) onto its ESEG[3:0] pins. ■ After an access is complete and before the start of a new access, the SEMI continues to drive ESEG[3:0] with its current state. ■ The SEMI 3-states ESEG[3:0] if it grants a request by an external device to access the external memory (see description of the EREQN pin in Table 53 on page 102).

[†] The EROM component is synchronous if the ERTYPE pin is logic 1. The ERAM component is synchronous if YTYPE field (**ECON1**[9]) is set. The EIO component is synchronous if the ITYPE field (**ECON1**[10]) is set. **ECON1** is described in [Table 60 on page 110](#).

4 Hardware Architecture (continued)

4.14 System and External Memory Interface (SEMI) (continued)

4.14.2 16-Bit External Bus Accesses

Regardless of the configuration of the external data bus via the ESIZE pin, each access by a core or the DMAU can be a 16-bit (single-word) or 32-bit (double-word) access. Table 56 summarizes each type of access for a 16-bit external bus configuration (ESIZE = 0).

Table 56. 16-Bit External Bus Configuration

Internal Address	Type of Access	External Address		External Data	ERWN1	ERWN0
Even or Odd	Single-Word Read	Even or Odd	EA[18:0]	ED[31:16]	1	1
	Single-Word Write		EA[18:0]	ED[31:16]	1	0
Even (aligned [†])	Double-Word Read	Even	EA[18:0]	ED[31:16]	1	1
		Odd	EA[18:0]	ED[31:16]	1	1
	Double-Word Write	Even	EA[18:0]	ED[31:16]	1	0
		Odd	EA[18:0]	ED[31:16]	1	0
Odd (misaligned [‡])	Double-Word Read	Odd	EA[18:0]	ED[31:16]	1	1
		Even	EA[18:0]	ED[31:16]	1	1
	Double-Word Write	Odd	EA[18:0]	ED[31:16]	1	0
		Even	EA[18:0]	ED[31:16]	1	0

[†] The SEMI performs two separate back-to-back 16-bit accesses, even address (most significant data) first and odd address (least significant data) second.

[‡] The SEMI performs two separate 16-bit accesses, odd address (most significant data) first and even address (least significant data) second. The two accesses are not necessarily back-to-back, i.e., they can be separated by other accesses.

4.14.3 32-Bit External Bus Accesses

Regardless of the configuration of the external data bus via the ESIZE pin, each access by a core or the DMAU can be a 16-bit (single-word) or 32-bit (double-word) access. Table 57 summarizes each type of access for a 32-bit external bus configuration (ESIZE = 1).

Table 57. 32-Bit External Bus Configuration

Internal Address	Type of Access	External Address	External Data	ERWN1	ERWN0
Even	Single-Word Read	EA[18:1]	ED[31:16]	1	1
	Single-Word Write	EA[18:1]	ED[31:16]	1	0 [†]
Odd	Single-Word Read	EA[18:1]	ED[15:0]	1	1
	Single-Word Write	EA[18:1]	ED[15:0]	0 [†]	1
Even (aligned)	Double-Word Read	EA[18:1]	ED[31:0]	1	1
	Double-Word Write	EA[18:1]	ED[31:0]	0 [†]	0 [†]
Odd (misaligned [‡])	Double-Word Read	EA[18:1]	ED[15:0]	1	1
		EA[18:1]	ED[31:16]	1	1
	Double-Word Write	EA[18:1]	ED[15:0]	0 [†]	1
		EA[18:1]	ED[31:16]	1	0 [†]

[†] For a write operation to a synchronous memory component, the SEMI also drives the EA0 pin low for use as a write enable. The EROM component is synchronous if the ERTYPE pin is logic 1. The ERAM component is synchronous if the YTYPE field (**ECON1**[9]) is set. The EIO component is synchronous if the ITYPE field (**ECON1**[10]) is set. **ECON1** is described in Table 60 on page 110.

[‡] The SEMI performs two separate 16-bit accesses. It accesses the most significant data in the odd address first, and then the least significant data in the even address second. The two accesses are not necessarily back-to-back, i.e., they can be separated by other accesses.

4 Hardware Architecture (continued)

4.14 System and External Memory Interface (SEMI) (continued)

4.14.4 Registers

There are six 16-bit memory-mapped control registers that configure the operation of the SEMI, as shown in Table 58.

Table 58. SEMI Memory-Mapped Registers

Register Name	Address	Description	Size (Bits)	R/W	Type	Reset Value
ECON0	0x40000	SEMI Control	16	R/W	Control	0x0FFF
ECON1	0x40002	SEMI Status and Control	16	R/W†	Control	0‡
EXSEG0	0x40004	External X Segment Register for CORE0	16	R/W	Address	0
EYSEG0	0x40006	External Y Segment Register for CORE0				
EXSEG1	0x40008	External X Segment Register for CORE1				
EYSEG1	0x4000A	External Y Segment Register for CORE1				

† Some bits in this register are read-only or write-only.

‡ With the following exceptions: **ECON1**[6,4] are a reflection of the state of external pins and are unaffected by reset, and **ECON1**[5] is set.

4 Hardware Architecture (continued)

4.14 System and External Memory Interface (SEMI) (continued)

4.14.4 Registers (continued)

4.14.4.1 ECON0 Register

ECON0 determines the setup, hold, and assertion times for the three external memory component enables. The programmer needs to use the **ECON0** register only if one or more of the external memory components (ERAM, EROM, or EIO) is configured as asynchronous (see [Section 4.14.4.2 on page 110](#) and [Section 4.14.1.1 on page 101](#)).

Table 59. ECON0 (External Control 0) Register

The memory address for this register is 0x40000.

15		14		13		12		11—8		7—4		3—0	
WHOLD		RHOLD		WSETUP		RSETUP		IATIME[3:0]		YATIME[3:0]		XATIME[3:0]	
Bit	Field	Value	Description									R/W	Reset Value
15	WHOLD	0	The SEMI does not extend the write cycle.									R/W	0
		1	The SEMI extends the write cycle for one CLK cycle, applies the target address, deasserts all enables, deasserts all write strobes, and 3-states ED[31:0].										
14	RHOLD	0	The SEMI does not extend the read cycle.									R/W	0
		1	The SEMI extends the read cycle for one CLK cycle, applies the target address, and deasserts all enables.										
13	WSETUP	0	The SEMI does not delay the assertion of the write strobe, the memory enable, and the assertion of ED[31:0] for write operations.									R/W	0
		1	The SEMI delays the assertion of the write strobe, the memory enable, and ED[31:0] during a write cycle for one CLK cycle. During the setup time, the SEMI applies the target address to EA[18:0], deasserts all enables and ERWN signals, and 3-states ED[31:0].										
12	RSETUP	0	The SEMI does not delay the assertion of the memory enable for read operations.									R/W	0
		1	The SEMI delays the assertion of the memory enable during a read cycle for one CLK cycle. During the setup time, the SEMI applies the target address to EA[18:0], deasserts all enables and ERWN signals, and 3-states ED[31:0].										
11—8	IATIME[3:0]	0—15	The duration in CLK cycles (1—15) that the SEMI asserts EION for an asynchronous access to the EIO component. A value of 0 or 1 corresponds to a 1 CLK cycle assertion time.									R/W	0xF
7—4	YATIME[3:0]	0—15	The duration in CLK cycles (1—15) that the SEMI asserts ERAMN for an asynchronous access to the ERAM component. A value of 0 or 1 corresponds to a 1 CLK cycle assertion time.									R/W	0xF
3—0	XATIME[3:0]	0—15	The duration in CLK cycles (1—15) that the SEMI asserts EROMN for an asynchronous access to the EROM component. A value of 0 or 1 corresponds to a 1 CLK cycle assertion time.									R/W	0xF

4 Hardware Architecture (continued)

4.14 System and External Memory Interface (SEMI) (continued)

4.14.4 Registers (continued)

4.14.4.2 ECON1 Register

The **ECON1** register (Table 60) reports status information and controls additional features of the SEMI. If any of the external memory components (ERAM, EROM, or EIO) are configured as synchronous¹, the ECKO[1:0] field of this register must be set to zero to select f_{CLK}/2 for the ECKO pin.

Table 60. ECON1 (External Control 1) Register

The memory address for this register is 0x40002.

15—12	11	10	9	8	7	6	5	4	3—2	1—0
Reserved	WEROM	ITYPE	YTYPE	NOSHARE	Reserved	EREDY	EACKN	EREQN	Reserved	ECKO[1:0]
Bit	Field	Value	Description				R/W	Reset Value		
15—12	Reserved	0	Reserved—write with zero.				R/W	0		
11	WEROM	0	The external portion of Y-memory and Z-memory space is ERAM (see Section 4.5.3 on page 38).				R/W	0		
		1	The external portion of Y-memory and Z-memory space is EROM (see Section 4.5.3 on page 38).							
10	ITYPE	0	EION is asynchronous SRAM.				R/W	0		
		1	EION is pipelined, synchronous SRAM.							
9	YTYPE	0	ERAMN is asynchronous SRAM.				R/W	0		
		1	ERAMN is pipelined, synchronous SRAM.							
8	NOSHARE	0	SEMI works as a bus-shared interface and asserts EACKN in response to EREQN.				R/W	0		
		1	SEMI ignores requests for the external bus and does not assert EACKN.							
7	Reserved	0	Reserved—write with zero.				R/W	0		
6	EREDY	0	The ERDY pin indicates an external device is requesting the SEMI to extend the current asynchronous external memory access (see Table 53 on page 102).				R	P†		
		1	The ERDY pin indicates an external device is not requesting the SEMI to extend the current asynchronous external memory access (see Table 53 on page 102).							
5	EACKN	0	The EACKN pin indicates the SEMI acknowledges a request by an external device for access to external memory (see Table 53 on page 102).				R	1		
		1	The EACKN pin indicates the SEMI does not acknowledge a request by an external device for access to external memory (see Table 53 on page 102).							
4	EREQN	0	The EREQN pin indicates an external device is requesting access to external memory (see Table 53 on page 102).				R	P†		
		1	The EREQN pin indicates an external device is not requesting access to external memory (see Table 53 on page 102).							
3—2	Reserved	0	Reserved—write with zero.				R/W	0		
1—0	ECKO[1:0]	00	The SEMI external clock (ECKO pin) is CLK/2 for synchronous operation of the SEMI.				R/W	00		
		01	The SEMI external clock (ECKO pin) is the internal clock CLK.							
		10	The SEMI external clock (ECKO pin) is the buffered input clock pin CKI.							
		11	The SEMI external clock (ECKO pin) is held low.							

† The state is a reflection of the state of the external pins and is unaffected by reset.

1. The EROM component is synchronous if the ERTYPE pin is logic 1. The ERAM component is synchronous if the YTYPE field (ECON1[9]) is set. The EIO component is synchronous if the ITYPE field (ECON1[10]) is set. ECON1 is described in Table 60.

4 Hardware Architecture (continued)

4.14 System and External Memory Interface (SEMI) (continued)

4.14.4 Registers (continued)

4.14.4.3 Segment Registers

The external program and data memory components (EROM, ERAM, and EIO) can each be expanded for each core through a combination of registers and pins. The ESEG[3:0] pins (see Section 4.14.1) reflect the value of the **EXSEG0**, **EXSEG1**, **EYSEG0**, or **EYSEG1** external segment registers for a given external access. A user's program executing in either core can write to these registers to expand the external ERAM and EROM data components. The value written to any one of these registers is driven onto the ESEG[3:0] pins for a corresponding memory component as described below and can be interpreted by the system as an

address extension (EA[22:19], for example) or as decoded enables.

The SEMI drives bits 3:0 of the 16-bit **EXSEG0** register onto the ESEG[3:0] pins at the same time as it drives the address onto EA[18:0] for an external ROM (EROM) access from CORE0.

The SEMI drives bits 3:0 (for ERAM) or bits 7:4 (for EIO) of the 16-bit **EYSEG0** register onto the ESEG[3:0] pins at the same time as it drives the address onto EA[18:0] for an external RAM (ERAM or EIO) access from CORE0.

The SEMI drives bits 3:0 of the 16-bit **EXSEG1** register onto the ESEG[3:0] pins at the same time as it drives the address onto EA[18:0] for an external ROM (EROM) access from CORE1.

The SEMI drives bits 3:0 (for ERAM) or bits 7:4 (for EIO) of the 16-bit **EYSEG1** register onto the ESEG[3:0] pins at the same time as it drives the address onto EA[18:0] for an external RAM (ERAM or EIO) access from CORE1.

Table 61. EXSEG0 (CORE0 External X Segment Address Extension) Register

The memory address for this register is 0x40004.

15—4			3—0	
Reserved			XSEG0[3:0]	
Bit	Field	Description	R/W	Reset Value
15—4	Reserved	Reserved—write with zero.	R/W	0
3—0	XSEG0[3:0]	External segment address extension for X-memory accesses to EROM by CORE0.	R/W	0

Table 62. EXSEG1 (CORE1 External X Segment Address Extension) Register

The memory address for this register is 0x40008.

15—4			3—0	
Reserved			XSEG1[3:0]	
Bit	Field	Description	R/W	Reset Value
15—4	Reserved	Reserved—write with zero.	R/W	0
3—0	XSEG1[3:0]	External segment address extension for X-memory accesses to EROM by CORE1.	R/W	0

4 Hardware Architecture (continued)

4.14 System and External Memory Interface (SEMI) (continued)

4.14.4 Registers (continued)

4.14.4.3 Segment Registers (continued)

Table 63. EYSEG0 (CORE0 External Y Segment Address Extension) Register

The memory address for this register is 0x40006.

15—8			7—4	3—0
Reserved			ISEG0[3:0]	YSEG0[3:0]
Bit	Field	Description	R/W	Reset Value
15—8	Reserved	Reserved—write with zero.	R/W	0
7—4	ISEG0[3:0]	External segment address extension for Y-memory accesses to EIO by CORE0.	R/W	0
3—0	YSEG0[3:0]	External segment address extension for Y-memory accesses to ERAM by CORE0.	R/W	0

Table 64. EYSEG1 (CORE1 External Y Segment Address Extension) Register

The memory address for this register is 0x4000A.

15—8			7—4	3—0
Reserved			ISEG1[3:0]	YSEG1[3:0]
Bit	Field	Description	R/W	Reset Value
15—8	Reserved	Reserved—write with zero.	R/W	0
7—4	ISEG1[3:0]	External segment address extension for Y-memory accesses to EIO by CORE1.	R/W	0
3—0	YSEG1[3:0]	External segment address extension for Y-memory accesses to ERAM by CORE1.	R/W	0

4 Hardware Architecture (continued)

4.14 System and External Memory Interface (SEMI) (continued)

4.14.5 Asynchronous Memory

This section describes the functional timing and interfacing for external memory components that are configured as asynchronous. The EROM component is asynchronous if the ERTYPE pin is logic 0. The ERAM component is asynchronous if the YTYPE field (**ECON1**[9]) is cleared, and the EIO component is asynchronous if the ITYPE field (**ECON1**[10]) is cleared. **ECON1** is described in [Table 60 on page 110](#).

In this section:

- The designation *ENABLE* refers to the EROMN, ERAMN, or EION pin.
- The designation *ERWN* refers to:
 - The ERWN0 pin if the external data bus is configured as 16 bits, i.e., if the ESIZE pin is logic low.
 - The ERWN1 and ERWN0 pins if the external data bus is configured as 32 bits, i.e., if the ESIZE pin is logic high.
- The designation *EA* refers to:
 - The external address pins EA[18:0] and the external segment address pins ESEG[3:0] if the external data bus is configured as 16 bits, i.e., if the ESIZE pin is logic low.
 - The external address pins EA[18:1] and the external segment address pins ESEG[3:0] if the external data bus is configured as 32 bits, i.e., if the ESIZE pin is logic high.
- The designation *ED* refers to:
 - The external data pins ED[31:16] if the external data bus is configured as 16 bits, i.e., if the ESIZE pin is logic low.
 - The external data pins ED[31:0] if the external data bus is configured as 32 bits, i.e., if the ESIZE pin is logic high.
- The designation *ATIME* refers to IATIME (**ECON0**[11:8]) for accesses to the EIO space, YATIME (**ECON0**[7:4]) for accesses to the ERAM space, or XATIME (**ECON0**[3:0]) for accesses to the EROM space.
- RSETUP refers to the RSETUP field (**ECON0**[12])—see [Table 59 on page 109](#).
- RHOLD refers to the RHOLD field (**ECON0**[14]).
- WSETUP refers to the WSETUP field (**ECON0**[13]).
- WHOLD refers to the WHOLD field (**ECON0**[15]).

4.14.5.1 Functional Timing

The following describes the functional timing for an asynchronous read operation:

1. On a rising edge of the internal clock (CLK), the SEMI asserts *ENABLE* and drives the read address onto *EA*. If RSETUP is set, the SEMI asserts *ENABLE* one CLK cycle later.
2. The SEMI asserts *ENABLE* for *ATIME* CLK cycles.
3. The SEMI deasserts *ENABLE* on a rising edge of CLK and latches the data from *ED*.
4. The SEMI continues to drive the read address onto *EA* for a minimum of one CLK cycle to guarantee an address hold time of at least one cycle. If RHOLD is set, the SEMI continues to drive the read address for an additional CLK cycle.

The SEMI continues to drive the address until another external memory access is initiated. Another read or a write to the same memory component can immediately follow the read cycle described above.

The following describes the functional timing for an asynchronous write operation:

1. On a rising edge of the internal clock (CLK), the SEMI asserts *ERWN* and drives the write address onto *EA*. If WSETUP is set, the SEMI asserts *ERWN* one CLK cycle later.
2. One CLK cycle after the SEMI asserts *ERWN*, the SEMI asserts *ENABLE* and drives valid data onto *ED* to guarantee one CLK cycle of setup time.
3. The SEMI asserts *ENABLE* for *ATIME* CLK cycles.
4. The SEMI deasserts *ENABLE* on a rising edge of CLK.
5. The SEMI continues to drive *ED* with the write data, drive *EA* with the write address, and assert *ERWN* for one additional CLK cycle to guarantee one cycle of hold time. If WHOLD is set, the SEMI continues to drive the write address for an additional CLK cycle.

The SEMI continues to drive the address until another external memory access is initiated. Another write to the same memory component can immediately follow the write cycle described above. If a read to the same memory component follows the write cycle described above, the SEMI inserts an idle bus cycle (one CLK cycle).

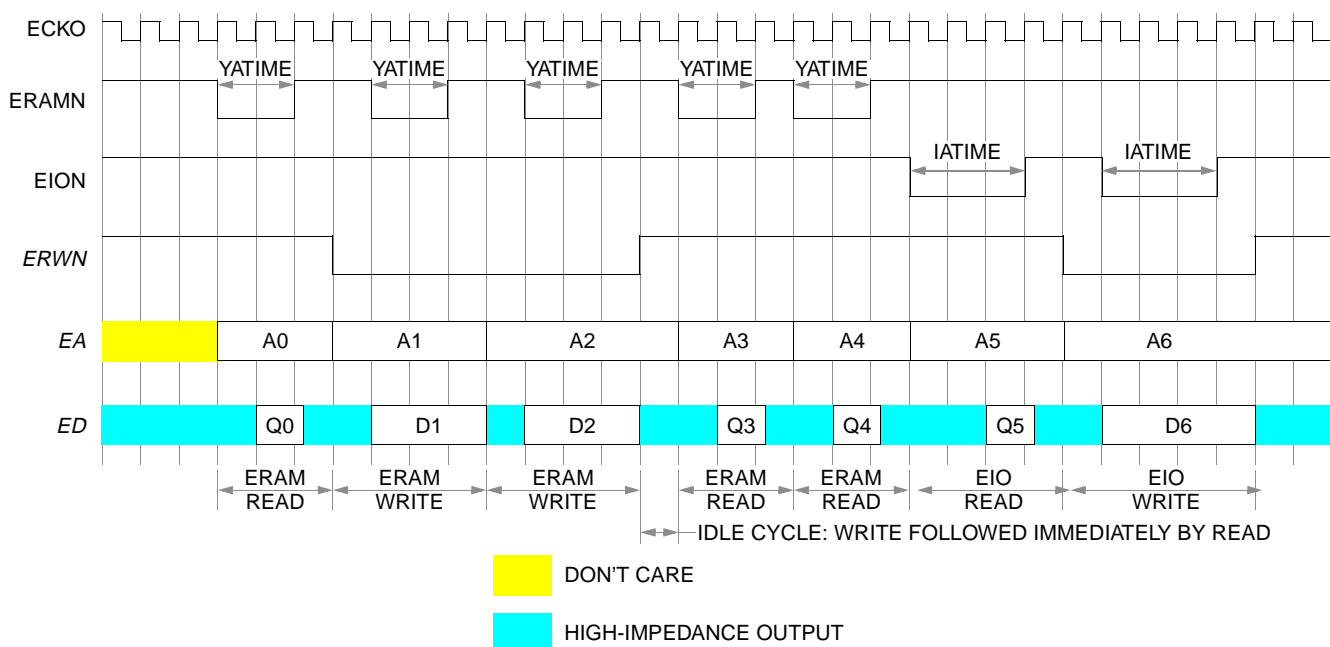
4 Hardware Architecture (continued)

4.14 System and External Memory Interface (SEMI) (continued)

4.14.5 Asynchronous Memory (continued)

4.14.5.1 Functional Timing (continued)

Figures 27 through 30 provide examples of asynchronous memory accesses for various SEMI configurations. These examples assume that the DMAU is performing the external memory accesses. The access rate shown is not achievable if the accesses are performed by one or both cores. For details on SEMI performance for an asynchronous interface, see Section 4.14.7.2 on page 126. For a summary of SEMI performance, see Section 4.14.7.4 on page 130.



Notes:

It is assumed that ECKO is programmed as CLK, i.e., the ECKO[1:0] field (**ECON1**[1:0]—Table 60 on page 110) is programmed to 0x1.

It is assumed that the YATIME[3:0] field (**ECON0**[7:4]—Table 59 on page 109) is programmed to 0x2 and the IATIME[3:0] field (**ECON0**[11:8]) is programmed to 0x3.

It is assumed that the DMAU is performing the external memory accesses. The access rate shown is not achievable if the accesses are performed by one or both cores.

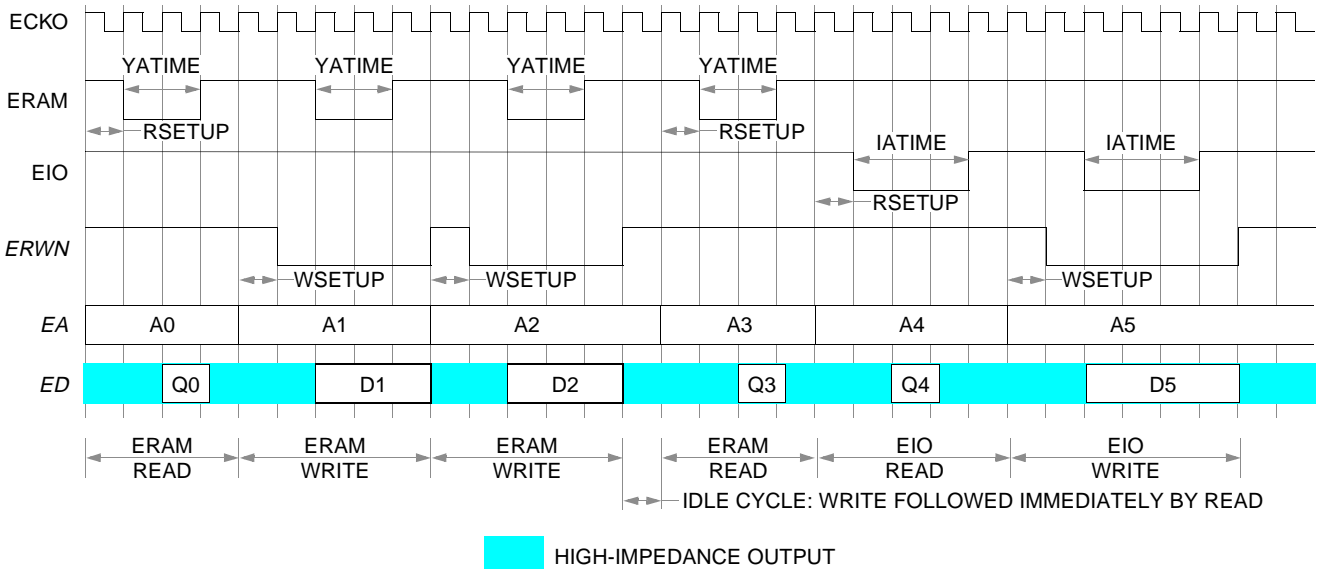
Figure 27. Asynchronous Memory Cycles

4 Hardware Architecture (continued)

4.14 System and External Memory Interface (SEMI) (continued)

4.14.5 Asynchronous Memory (continued)

4.14.5.1 Functional Timing (continued)



Notes:

It is assumed that ECKO is programmed as CLK, i.e., the ECKO[1:0] field (**ECON1**[1:0]—Table 60 on page 110) is programmed to 0x1.

It is assumed that the YATIME[3:0] field (**ECON0**[7:4]—Table 59 on page 109) is programmed to 0x2 and the IATIME[3:0] field (**ECON0**[11:8]) is programmed to 0x3.

It is assumed that the DMAU is performing the external memory accesses. The access rate shown is not achievable if the accesses are performed by one or both cores.

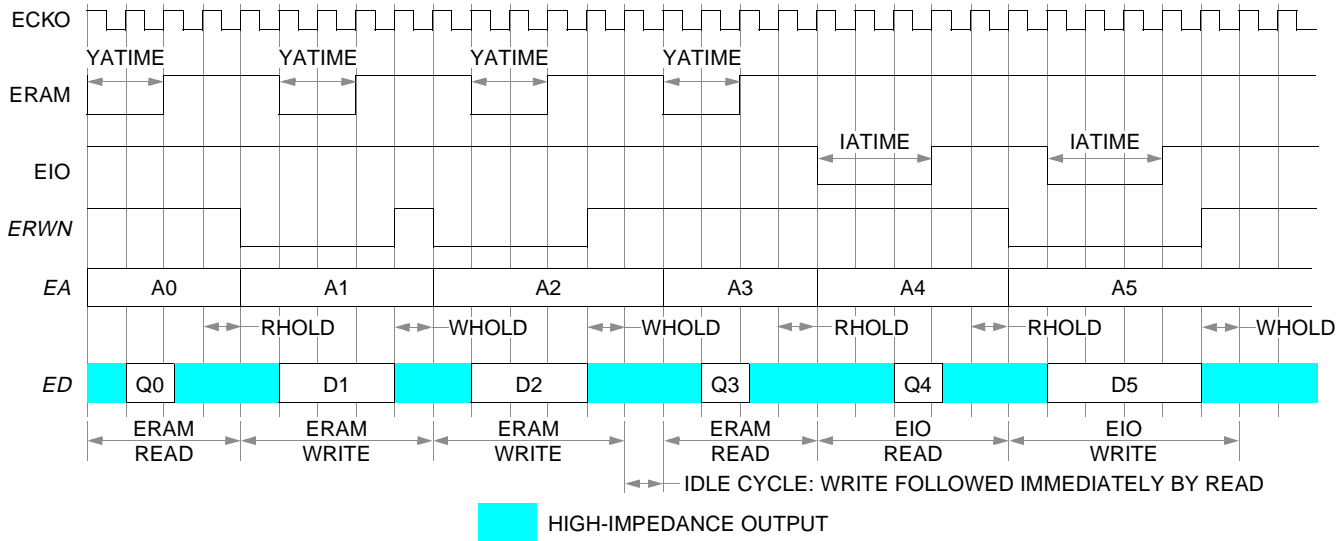
Figure 28. Asynchronous Memory Cycles (RSETUP = 1, WSETUP = 1)

4 Hardware Architecture (continued)

4.14 System and External Memory Interface (SEMI) (continued)

4.14.5 Asynchronous Memory (continued)

4.14.5.1 Functional Timing (continued)



Notes:

It is assumed that ECKO is programmed as CLK, i.e., the ECKO[1:0] field (**ECON1**[1:0]—Table 60 on page 110) is programmed to 0x1.

It is assumed that the YATIME[3:0] field (**ECON0**[7:4]—Table 59 on page 109) is programmed to 0x2 and the IATIME[3:0] field (**ECON0**[11:8]) is programmed to 0x3.

It is assumed that the DMAU is performing the external memory accesses. The access rate shown is not achievable if the accesses are performed by one or both cores.

Figure 29. Asynchronous Memory Cycles (RHOLD = 1, WHOLD = 1)

4 Hardware Architecture (continued)

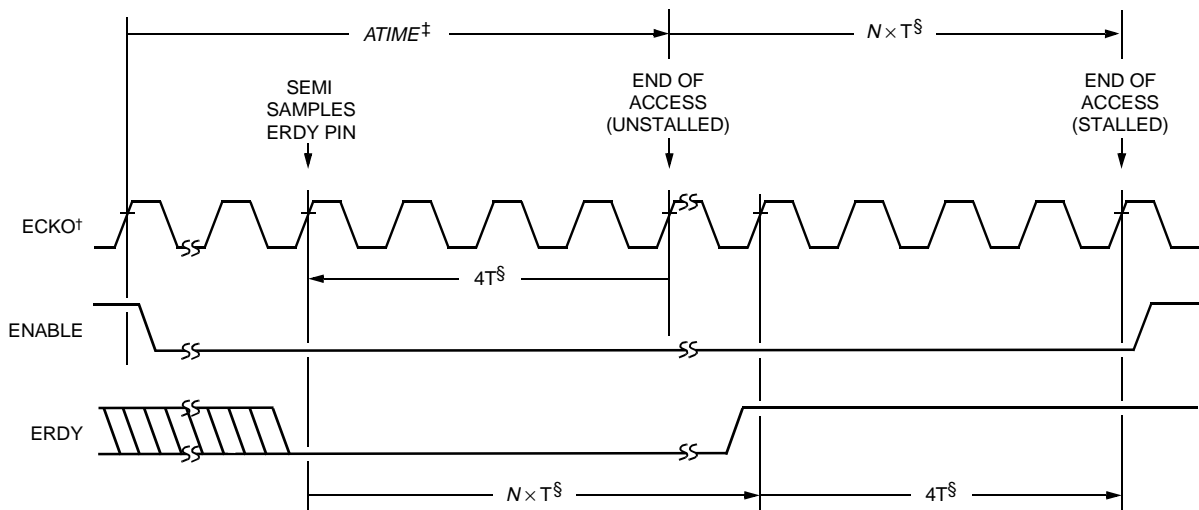
4.14 System and External Memory Interface (SEMI) (continued)

4.14.5 Asynchronous Memory (continued)

4.14.5.2 Extending Access Time Via the ERDY Pin

An external device can delay the completion of an external memory access to an asynchronous memory component by control of the ERDY pin (see Figure 30). If driven low by the external device, the SEMI extends the current external memory access that is already in progress. To guarantee proper operation, ERDY must be driven low at least 4 CLK cycles before the end of the access and the enable must be programmed for at least 5 CLK cycles of assertion (via the YATIME, XATIME, or IATIME field of **ECON0**—see Table 59 on page 109). The SEMI ignores the state of ERDY prior to 4 CLK cycles before the end of the access. The access is extended by 4 CLK cycles after ERDY is driven high. The state of ERDY is readable in the EREADY field (**ECON1**[6]—see Table 60 on page 110).

This feature of the SEMI provides a convenient interface to peripherals that have a variable access time or require an access time greater than 15 CLK cycles in duration.



† ECKO reflects CLK, i.e., **ECON1**[1:0] = 1.

‡ *ATIME* must be programmed as greater than or equal to five CLK cycles. Otherwise, the SEMI ignores the state of ERDY.

§ T = internal clock period (CLK). N must be greater than or equal to one, i.e., ERDY must be held low for at least one CLK cycle after the SEMI samples ERDY.

Figure 30. Use of ERDY Pin to Extend Asynchronous Accesses

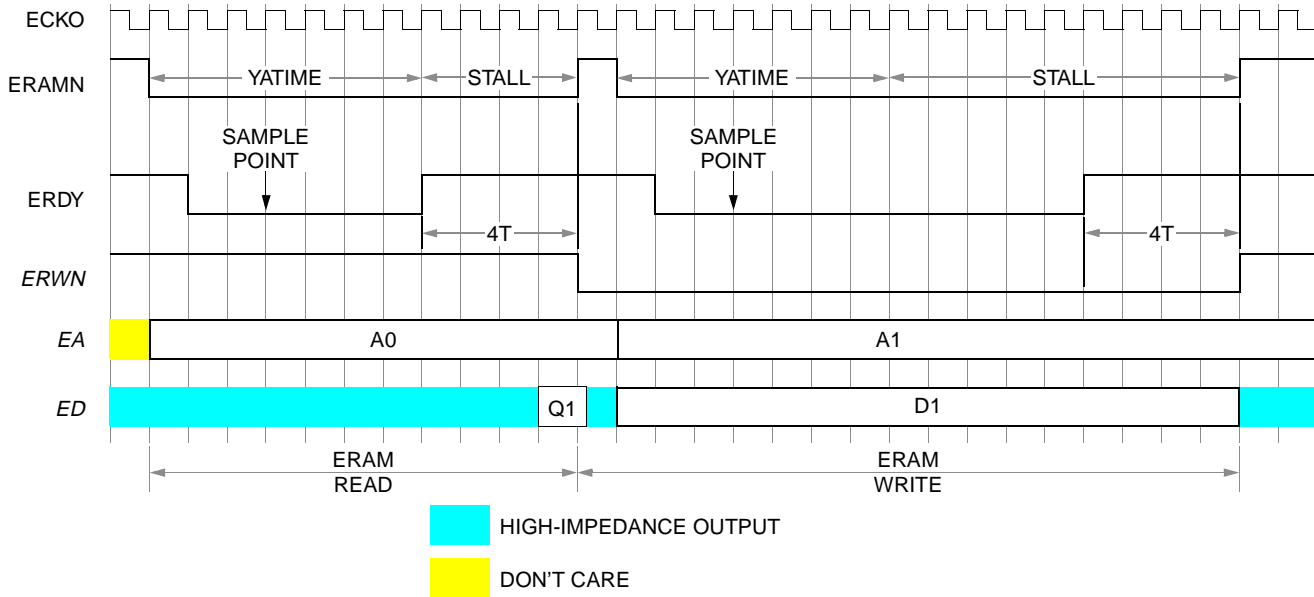
4 Hardware Architecture (continued)

4.14 System and External Memory Interface (SEMI) (continued)

4.14.5 Asynchronous Memory (continued)

4.14.5.2 Extending Access Time Via the ERDY Pin (continued)

Figure 31 illustrates an example read and write operation using the ERDY pin to extend the accesses.



Notes:
It is assumed that ECKO is programmed as CLK, i.e., the ECKO[1:0] field (**ECON1**[1:0]—Table 60 on page 110) is programmed to 0x1.
It is assumed that the YATIME[3:0] field (**ECON0**[7:4]—Table 59 on page 109) is programmed to 0x7.

Figure 31. Example of Using the ERDY Pin

4 Hardware Architecture (continued)

4.14 System and External Memory Interface (SEMI) (continued)

4.14.5 Asynchronous Memory (continued)

4.14.5.3 Interfacing Examples

Figures 32 and 33 illustrate two examples of interfacing 16-bit asynchronous SRAMs to the SEMI. The user can individually configure the EROMN, ERAMN, and EION enables to support asynchronous devices. The ERTYPE pin must be at logic low for the EROM component to be configured for asynchronous accesses. Clearing the YTYPE field (**ECON1**[9]) and ITYPE field (**ECON1**[10]) configures the ERAM and EIO components for asynchronous accesses.

The programmer can individually configure the access time (defined as the number of CLK cycles that the enable is asserted) for each enable. The YATIME field (**ECON0**[7:4]) specifies the number of CLK cycles that the ERAMN enable is asserted. The XATIME field (**ECON0**[3:0]) specifies the number of CLK cycles that the EROMN enable is asserted. The IATIME field (**ECON0**[11:8]) specifies the number of CLK cycles that the EION enable is asserted. The range of values for these fields is from 0 to 15 (corresponding to a range of 1 to 15 CLK cycles). A value of 0 or 1 programs a 1 CLK assertion time for the corresponding enable.

4 Hardware Architecture (continued)

4.14 System and External Memory Interface (SEMI) (continued)

4.14.5 Asynchronous Memory (continued)

4.14.5.3 Interfacing Examples (continued)

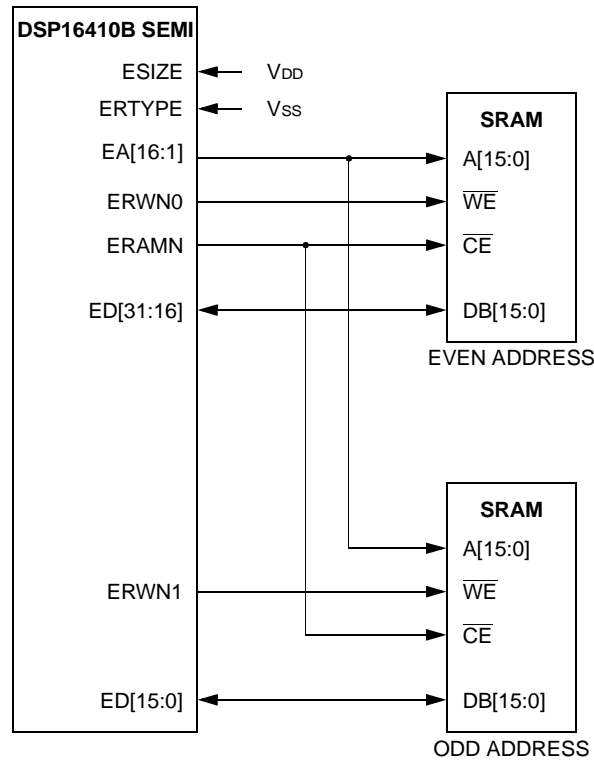


Figure 32. 32-Bit External Interface with 16-Bit Asynchronous SRAMs

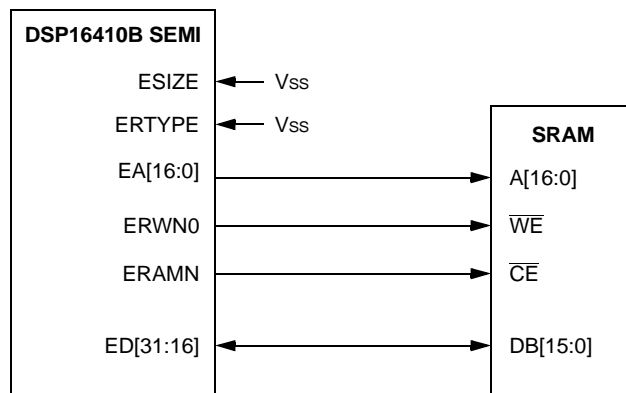


Figure 33. 16-Bit External Interface with 16-Bit Asynchronous SRAMs

4 Hardware Architecture (continued)

4.14 System and External Memory Interface (SEMI) (continued)

4.14.6 Synchronous Memory

This section describes the functional timing and interfacing for external memory components that are configured as synchronous. The EROM component is synchronous if the ERTYPE pin is logic 1. The ERAM component is synchronous if the YTYPE field (**ECON1**[9]) is set, and the EIO component is synchronous if the ITYPE field (**ECON1**[10]) is set. **ECON1** is described in [Table 60 on page 110](#).

If any of the external memory components (EROM, ERAM, or EIO) are configured as synchronous, the SEMI external output clock (ECKO) **must** be programmed for a frequency of $f_{CLK}/2$ by clearing the ECKO[1:0] field (**ECON1**[1:0]). The DSP16410B clears the ECKO[1:0] field by default after reset.

In this section:

- The designation *ENABLE* refers to the EROMN, ERAMN, or EION pin.
- The designation *ERWN* refers to:
 - The ERWN0 pin if the external data bus is configured as 16 bits, i.e., if the ESIZE pin is logic low.
 - The ERWN1, ERWN0, and EA0¹ pins if the external data bus is configured as 32 bits, i.e., if the ESIZE pin is logic high.
- The designation *EA* refers to:
 - The external address pins EA[18:0] and the external segment address pins ESEG[3:0] if the external data bus is configured as 16 bits, i.e., if the ESIZE pin is logic low.
 - The external address pins EA[18:1] and the external segment address pins ESEG[3:0] if the external data bus is configured as 32 bits, i.e., if the ESIZE pin is logic high.
- The designation *ED* refers to:
 - The external data pins ED[31:16] if the external data bus is configured as 16 bits, i.e., if the ESIZE pin is logic low.
 - The external data pins ED[31:0] if the external data bus is configured as 32 bits, i.e., if the ESIZE pin is logic high.

4.14.6.1 Functional Timing

The following describes the functional timing for a synchronous read operation (see [Figure 34 on page 122](#)):

1. On a rising edge of the external output clock (ECKO), the SEMI drives the read address onto *EA* and asserts *ENABLE* for one ECKO cycle.
2. On the rising edge of the second ECKO cycle, the SEMI deasserts *ENABLE*.
3. On the rising edge of the third ECKO cycle, a new access can begin because synchronous accesses are pipelined.
4. On the rising edge of the fourth ECKO cycle, the SEMI latches the data from *ED*.

The following describes the functional timing for a synchronous write operation (see [Figure 34 on page 122](#)):

1. On a rising edge of the external output clock (ECKO), the SEMI drives the write address onto *EA* and asserts *ERWN* and *ENABLE* for one ECKO cycle.
2. On the rising edge of the second ECKO cycle, the SEMI deasserts *ENABLE* and *ERWN*.
3. On the rising edge of the third ECKO cycle, a new access can begin because synchronous accesses are pipelined. On this edge, the SEMI drives *ED* with the write data for one ECKO cycle.
4. On the rising edge of the fourth cycle, the external memory latches the data from *ED*.

1. The EA0 pin is a strobe only if the bus is configured for 32 bits and the memory is configured as synchronous.

4 Hardware Architecture (continued)

4.14 System and External Memory Interface (SEMI) (continued)

4.14.6 Synchronous Memory (continued)

4.14.6.1 Functional Timing (continued)

Figure 34 illustrates an example of synchronous memory accesses. This example assumes that the DMAU is performing the external memory accesses. The access rate shown is not achievable if the accesses are performed by one or both cores. For details on SEMI performance for a synchronous interface, see Section 4.14.7.3 on page 128. For a summary of SEMI performance, see Section 4.14.7.4 on page 130.

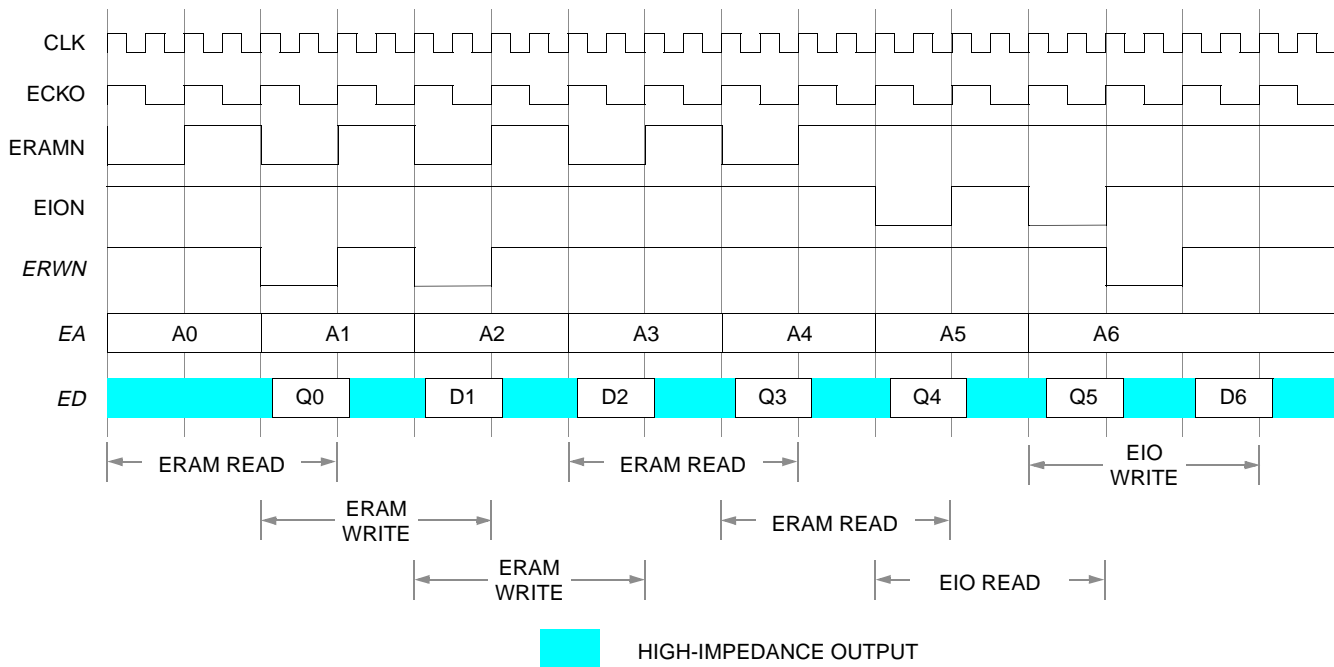


Figure 34. Synchronous Memory Cycles

4 Hardware Architecture (continued)

4.14 System and External Memory Interface (SEMI) (continued)

4.14.6 Synchronous Memory (continued)

4.14.6.2 Interfacing Examples

For synchronous operation, the programmer **must** configure the SEMI external output clock (ECKO) to CLK/2 by clearing the ECKO field (**ECON1**[1:0]—Table 60 on page 110). The DSP16410B clears the ECKO[1:0] field by default after reset.

Figures 35 and 36 illustrate examples of interfacing 16-bit and 32-bit pipelined synchronous ZBT SRAMs to the SEMI. The programmer can individually configure EROMN, ERAMN, and EION enables to support this type of synchronous device. The ERTYPE pin must be at logic high for the EROM component to be configured for synchronous accesses. Setting the YTYPE field (**ECON1**[9]) and ITYPE field (**ECON1**[10]) configures the ERAM and EIO components for synchronous accesses.

Figure 35 illustrates interfacing the SEMI to a 16-bit synchronous, pipelined ZBT SRAM. In this example:

1. The SEMI address bus (EA[17:0]) is connected to the SRAM's address bus (A[17:0]). One of the SEMI ESEG[3:0] pins can be optionally connected to the SRAM's active-high chip select input (CE2).
2. The upper 16 bits of the SEMI data bus (ED[31:16]) are connected to the SRAM's bidirectional data bus (DQ[15:0]).
3. The SEMI external clock (ECKO) is programmed for operation at $f_{CLK}/2$ and is connected to the SRAM's CLK input.
4. The SEMI external data component enable (ERAMN) and external read/write strobe (ERWN0) are connected to the SRAM's active-low chip enable and write enable inputs, respectively.
5. The SRAM's active-low $\overline{ADV/LD}$ must be tied low.
6. The SEMI's ESIZE pin is tied low to configure the data bus for 16-bit accesses.

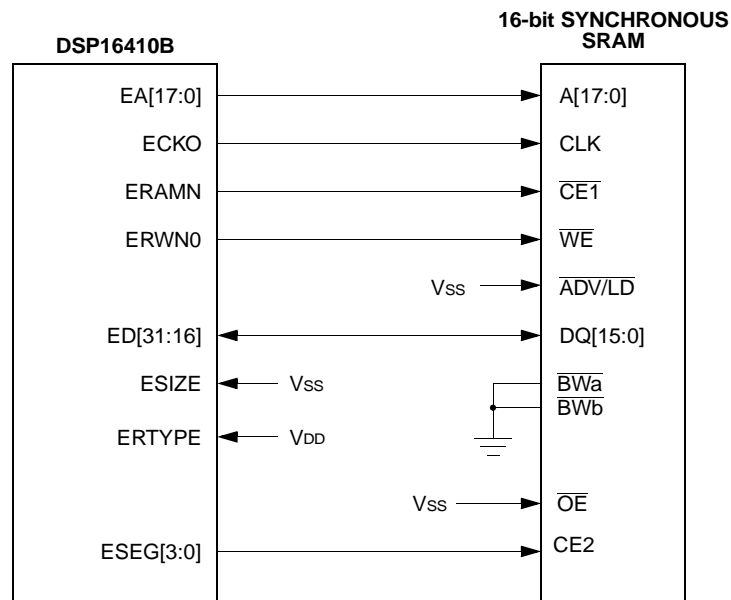


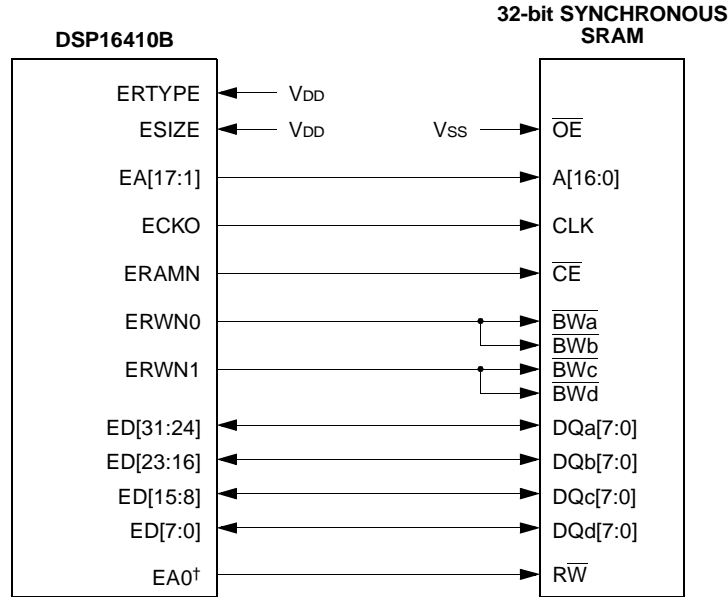
Figure 35. 16-Bit External Interface with 16-Bit Pipelined, Synchronous ZBT SRAMs

4 Hardware Architecture (continued)

4.14 System and External Memory Interface (SEMI) (continued)

4.14.6 Synchronous Memory (continued)

4.14.6.2 Interfacing Examples (continued)



† SEMI is configured for a 32-bit data bus. In this configuration, EA0 is RWN for 32-bit accesses (logical AND of ERWN0 and ERWN1).

Figure 36. 32-Bit External Interface with 32-Bit Pipelined, Synchronous ZBT SRAMs

4 Hardware Architecture (continued)

4.14 System and External Memory Interface (SEMI) (continued)

4.14.7 Performance

The following terms are used in this section:

- A requester, a core or the DMAU, requests the SEMI to access external memory or the system bus.
- Contention refers to multiple requests for the same resource at the same time.
- The designation *ATIME* refers to *IATIME* (**ECON0**[11:8]—see [Table 59 on page 109](#)) for accesses to the EIO space, *YATIME* (**ECON0**[7:4]) for accesses to the ERAM space, or *XATIME* (**ECON0**[3:0]) for accesses to the EROM space.
- **RSETUP** refers to the **RSETUP** field (**ECON0**[12]).
- **RHOLD** refers to the **RHOLD** field (**ECON0**[14]).
- **WSETUP** refers to the **WSETUP** field (**ECON0**[13]).
- **WHOLD** refers to the **WHOLD** field (**ECON0**[15]).
- Misaligned refers to 32-bit accesses to odd addresses.
- *SLKA* refers to the *SLKA*_(5—4) fields (**DMCON0**[9:8]—see [Table 31 on page 70](#)).
- **TCLK** refers to one period of the internal clock **CLK**.

The SEMI controls and arbitrates two types of memory accesses. The first is to external memory. The second is to the internal I/O segment accessed via the system bus. [Section 4.14.7.1](#) describes the SEMI performance for system bus accesses. [Section 4.14.7.2 on page 126](#) describes the SEMI performance for asynchronous external memory accesses and [Section 4.14.7.3 on page 128](#) describes the SEMI performance for synchronous external memory accesses. The performance for all of these types of accesses are summarized in [Section 4.14.7.4 on page 130](#).

For the remainder of this section, unless otherwise otherwise stated, the following assumptions apply:

- There is only a single requester, i.e., no contention.
- SEMI requests by the DMAU are from a memory-to-memory (MMT) channel and the user program has enabled the source look-ahead feature by setting the appropriate *SLKA* field ([Section 4.13.6](#)).

The source of the request (core vs. DMAU), the configuration of the SEMI data bus size (16-bit vs. 32-bit), and the type of access (read vs. write) determine the throughput of any external memory access.

[Section 4.14.7.2](#) and [Section 4.14.7.3](#) describe the performance for all combinations.

The DMAU source look-ahead feature takes advantage of the DMAU pipeline and allows the DMAU to read source data before completing the previous write to the destination. [Section 4.14.7.4 on page 130](#) shows performance figures with this feature both enabled and disabled.

For an MMT channel, each DMAU access consists of a read of the source location and write to the destination location. Therefore, the DMAU performance values stated in this section assume two operations per transfer.

4.14.7.1 System Bus

The SEMI controls and arbitrates accesses to internal I/O segment accessed via the system bus. Only 16-bit and aligned 32-bit transfers are permitted via the system bus. The system bus is used to access all the memory-mapped registers in the DMAU, SIU0, SIU1, PIU, and SEMI. See [Section 6.2.2 on page 228](#) for details on the memory-mapped registers. Misaligned 32-bit accesses to internal I/O space cause undefined results.

[Table 65](#) specifies the minimum system bus access time for either a single-word (16-bit) or double-word (32-bit) access by a single requester. The SEMI processes system bus accesses by multiple requesters at a maximum rate of one access per CLK cycle.

Table 65. System Bus Minimum Access Times

Access	Minimum Access Time
Read	$5 \times T_{CLK}$
Write	$2 \times T_{CLK}$

For example, if a program executing in CORE0 performs a read of the 16-bit **DMCON0** register, the read requires a minimum of five CLK cycles. The access could take longer if the SEMI is busy processing a prior request, i.e., if there is contention. As a second example of an S-bus transfer, assume the DMAU is moving data between TPRAM0 and the SLM. The SLM is a memory block accessed via the S-bus. Assuming no contention, the DMAU can read a word from TPRAM0 and write a word to the SLM at an effective rate of two 16-bit words per two CLK cycles.

4 Hardware Architecture (continued)

4.14 System and External Memory Interface (SEMI) (continued)

4.14.7 Performance (continued)

4.14.7.2 External Memory, Asynchronous Interface

External Accesses by Either Core, 32-bit SEMI Data Bus

The following describes the SEMI performance for read and write operations by either core to asynchronous memory with the external data bus configured as 32-bit (the ESIZE pin is logic high):

READS—For the cores, 16-bit and 32-bit aligned external asynchronous memory reads occur with a minimum period of the enable assertion time (as programmed in *ATIME*), plus a one CLK cycle enforced hold time, plus three CLK cycles for the SEMI pipeline to complete the core access. This assumes that RSETUP and RHOLD are cleared. The core treats misaligned 32-bit reads as two separate 16-bit reads requiring two complete SEMI accesses.

The core read access time for a 32-bit data bus is the following:

$$[ATIME + 4 + RSETUP + RHOLD] \times misaligned \times T_{CLK}$$

where:

- *misaligned* = 1 for 16-bit and aligned 32-bit accesses.
- *misaligned* = 2 for misaligned 32-bit accesses.

WRITES—For the cores, 16-bit and 32-bit aligned asynchronous memory writes can occur with a minimum period of the enable assertion time (as programmed in *ATIME*), plus a one CLK cycle enforced setup time, plus a one CLK cycle enforced hold time. This assumes that WSETUP and WHOLD are cleared. Unlike read cycles, the core does not wait for the SEMI pipeline to complete the access, so the three CLK cycle pipeline delay is not incurred on core writes. The core treats misaligned 32-bit writes as two separate 16-bit writes requiring two complete SEMI accesses.

The core write access time for a 32-bit data bus is the following:

$$[ATIME + 2 + WSETUP + WHOLD] \times misaligned \times T_{CLK}$$

where *misaligned* has the same definition as for reads.

External Accesses by the DMAU, 32-bit SEMI Data Bus

The following describes the SEMI performance for read and write operations by a DMAU MMT channel to asynchronous memory with the external data bus configured as 32-bit (the ESIZE pin is logic high):

READS—For the DMAU MMT channels with *SLKA* = 1, 16-bit and 32-bit aligned external asynchronous memory reads (with corresponding writes to internal TPRAM) occur with a minimum period of the enable assertion time (as programmed in *ATIME*) plus a one CLK cycle enforced hold time. This assumes that RSETUP and RHOLD are cleared. Misaligned 32-bit reads are **not** permitted.

The DMAU read access time for a 32-bit data bus with *SLKA* = 1 is the following:

$$[ATIME + 1 + RSETUP + RHOLD] \times T_{CLK}$$

WRITES—For the DMAU MMT channels with *SLKA* = 1, 16-bit and 32-bit aligned asynchronous memory writes (with corresponding reads from internal TPRAM) can occur with a minimum period of the enable assertion time (as programmed in *ATIME*), plus a one CLK cycle enforced setup time, plus a one CLK cycle enforced hold time. This assumes that WSETUP and WHOLD are cleared. Misaligned 32-bit writes are **not** permitted.

The DMAU write access time for a 32-bit data bus with *SLKA* = 1 is the following:

$$[ATIME + 2 + WSETUP + WHOLD] \times T_{CLK}$$

4 Hardware Architecture (continued)

4.14 System and External Memory Interface (SEMI) (continued)

4.14.7 Performance (continued)

4.14.7.2 External Memory, Asynchronous Interface (continued)

External Accesses by Either Core, 16-bit SEMI Data Bus

The following describes the SEMI performance for read and write operations by either core to asynchronous memory with the external data bus configured as 16-bit (the ESIZE pin is logic low):

READS—For the cores, 16-bit external asynchronous memory reads occur with a minimum period of the enable assertion time (as programmed in *ATIME*), plus a one CLK cycle enforced hold time, plus three CLK cycles for the SEMI pipeline to complete the core access. This assumes that RSETUP and RHOLD are cleared. The SEMI coordinates two separate accesses for aligned 32-bit reads, adding two CLK cycles to the above description. The core treats misaligned 32-bit reads as two separate 16-bit reads requiring two complete SEMI accesses.

The core read access time for a 16-bit data bus is the following:

$$[ATIME + aligned + RSETUP + RHOLD] \times misaligned \times T_{CLK}$$

where:

- *aligned* = 4 and *misaligned* = 1 for 16-bit accesses.
- *aligned* = 6 and *misaligned* = 1 for 32-bit aligned accesses.
- *aligned* = 4 and *misaligned* = 2 for 32-bit misaligned accesses.

WRITES—For the cores, 16-bit asynchronous memory writes can occur with a minimum period of the enable assertion time (as programmed in *ATIME*), plus a one CLK cycle enforced setup time, plus a one CLK cycle enforced hold time. This assumes that WSETUP and WHOLD are cleared. Unlike read cycles, the core does not wait for the SEMI pipeline to complete the access, so the three CLK cycle pipeline delay is not incurred on core writes. The SEMI coordinates and treats aligned 32-bit writes as two separate accesses. The core treats misaligned 32-bit writes as two separate 16-bit writes requiring two complete SEMI accesses.

The core write access time for a 16-bit data bus is the following:

$$[ATIME + 2 + WSETUP + WHOLD] \times longword \times T_{CLK}$$

where:

- *longword* = 1 for 16-bit accesses.
- *longword* = 2 for 32-bit accesses.

External Accesses by the DMAU, 16-bit SEMI Data Bus

The following describes the SEMI performance for read and write operations by a DMAU MMT channel to asynchronous memory with the external data bus configured as 16-bit (the ESIZE pin is logic low):

READS—For the DMAU MMT channels with *SLKA* = 1, 16-bit external asynchronous memory reads (with corresponding writes to internal TPRAM) occur with a minimum period of the enable assertion time (as programmed into *ATIME*) plus a one CLK cycle enforced hold time. This assumes that RSETUP and RHOLD are cleared. The SEMI coordinates and treats aligned 32-bit reads as two separate accesses. Misaligned 32-bit reads are **not** permitted.

The DMAU read access time for a 16-bit data bus with *SLKA* = 1 is the following:

$$[ATIME + 1 + RSETUP + RHOLD] \times longword \times T_{CLK}$$

where:

- *longword* = 1 for 16-bit accesses.
- *longword* = 2 for 32-bit aligned accesses.

WRITES—For the DMAU MMT channels with *SLKA* = 1, 16-bit asynchronous memory writes (with corresponding reads from internal TPRAM) can occur with a minimum period of the enable assertion time (as programmed in *ATIME*), plus a one CLK cycle enforced setup time, plus a one CLK cycle enforced hold time. This assumes that WSETUP and WHOLD are cleared. The SEMI coordinates and treats aligned 32-bit writes as two separate accesses. Misaligned 32-bit writes are **not** permitted.

The DMAU write access time for a 16-bit data bus with *SLKA* = 1 is the following:

$$[ATIME + 2 + WSETUP + WHOLD] \times longword \times T_{CLK}$$

where *longword* has the same meaning as for DMAU reads.

4 Hardware Architecture (continued)

4.14 System and External Memory Interface (SEMI) (continued)

4.14.7 Performance (continued)

4.14.7.3 External Memory, Synchronous Interface

The primary advantage of synchronous memory is bandwidth, not latency. For synchronous operation, the SEMI external output clock (ECKO) must be programmed for a frequency of $f_{CLK}/2$ by writing zero to the ECKO field (**ECON1** [1:0]).

External Accesses by Either Core, 32-bit SEMI Data Bus

The following describes the SEMI performance for read and write operations by either core to synchronous memory with the external data bus configured as 32-bit (the ESIZE pin is logic high):

READS—For the cores, 16-bit and 32-bit aligned external synchronous memory reads occur with a minimum period of eight CLK cycles (four ECKO cycles), plus three CLK cycles for SEMI to arbitrate the core access, plus one CLK cycle to synchronize ECKO with a rising edge of CLK. The core treats misaligned 32-bit reads as two separate 16-bit reads requiring two complete SEMI accesses.

The core read access time for a 32-bit data bus is the following:

$$12 \times \text{misaligned} \times T_{CLK}$$

where:

- *misaligned* = 1 for 16-bit and aligned 32-bit accesses.
- *misaligned* = 2 for misaligned 32-bit accesses.

WRITES—For the cores, 16-bit and 32-bit aligned synchronous memory writes can occur with a minimum period of four CLK cycles (two ECKO cycles) per transfer. The core treats misaligned 32-bit writes as two separate 16-bit writes requiring two complete SEMI accesses.

The core write access time for a 32-bit data bus is the following:

$$4 \times \text{misaligned} \times T_{CLK}$$

where *misaligned* has the same definition as for reads.

External Accesses by the DMAU, 32-bit SEMI Data Bus

The following describes the SEMI performance for read and write operations by a DMAU MMT channel to synchronous memory with the external data bus configured as 32-bit (the ESIZE pin is logic high):

READS—For the DMAU MMT channels with $SLKA = 1$, 16-bit and 32-bit aligned external synchronous memory reads (with corresponding writes to internal TPRAM) occur with a minimum period of four CLK cycles (two ECKO cycles). Misaligned 32-bit reads are **not** permitted.

The DMAU read access time for a 32-bit data bus with $SLKA = 1$ is four CLK cycles.

$$4 \times T_{CLK}$$

WRITES—For the DMAU MMT channels with $SLKA = 1$, 16-bit and 32-bit aligned synchronous memory writes (with corresponding reads from internal TPRAM) can occur with a minimum period of four CLK cycles (two ECKO cycles). Misaligned 32-bit writes are **not** permitted.

The DMAU write access time for a 32-bit data bus and $SLKA = 1$ is four CLK cycles.

$$4 \times T_{CLK}$$

4 Hardware Architecture (continued)

4.14 System and External Memory Interface (SEMI) (continued)

4.14.7 Performance (continued)

4.14.7.3 External Memory, Synchronous Interface (continued)

External Accesses by Either Core, 16-bit SEMI Data Bus

The following describes the SEMI performance for read and write operations by either core to synchronous memory with the external data bus configured as 16-bit (the ESIZE pin is logic low):

READS—For the cores, 16-bit external synchronous memory reads occur with a minimum period of eight CLK cycles (four ECKO cycles), plus three CLK cycles for SEMI to arbitrate the core access, plus one CLK cycle to synchronize ECKO with a rising edge of CLK. The SEMI coordinates and treats aligned 32-bit reads as two separate accesses. The core treats misaligned 32-bit reads as two separate 16-bit reads requiring two complete SEMI accesses.

The core read access time for a 16-bit data bus is the following:

$$(12 + \textit{aligned}) \times \textit{misaligned} \times T_{\text{CLK}}$$

where:

- *aligned* = 0 and *misaligned* = 1 for 16-bit accesses.
- *aligned* = 4 and *misaligned* = 1 for 32-bit aligned accesses.
- *aligned* = 0 and *misaligned* = 2 for 32-bit misaligned accesses.

WRITES—For the cores, 16-bit synchronous memory writes can occur with a minimum period of four CLK cycles (two ECKO cycles) per transfer. The SEMI coordinates and treats aligned 32-bit writes as two separate accesses. The core treats misaligned 32-bit writes as two separate 16-bit writes requiring two complete SEMI accesses.

The core write access time for a 16-bit data bus is the following:

$$4 \times \textit{longword} \times T_{\text{CLK}}$$

where:

- *longword* = 1 for 16-bit accesses.
- *longword* = 2 for any 32-bit accesses.

External Accesses by the DMAU, 16-bit SEMI Data Bus

The following describes the SEMI performance for read and write operations by a DMAU MMT channel to synchronous memory with the external data bus configured as 16-bit (the ESIZE pin is logic low):

READS—For the DMAU MMT channels with *SLKA* = 1, 16-bit external synchronous memory reads (with corresponding writes to internal TPRAM) occur with a minimum period of four CLK cycles (two ECKO cycles). The SEMI coordinates and treats aligned 32-bit reads as two separate accesses. Misaligned 32-bit reads are **not** permitted.

The DMAU read access time for a 16-bit data bus with *SLKA* = 1 is the following:

$$4 \times \textit{longword} \times T_{\text{CLK}}$$

where:

- *longword* = 1 for 16-bit accesses.
- *longword* = 2 for any 32-bit aligned accesses.

WRITES—For the DMAU MMT channels with *SLKA* = 1, 16-bit synchronous memory writes (with corresponding reads from internal TPRAM) can occur with a minimum period of four CLK cycles (two ECKO cycles). The SEMI coordinates and treats aligned 32-bit writes as two separate accesses. Misaligned 32-bit writes are **not** permitted.

The DMAU write access time for a 16-bit data bus with *SLKA* = 1 is the following:

$$4 \times \textit{longword} \times T_{\text{CLK}}$$

where *longword* has the same meaning as for DMAU reads.

4 Hardware Architecture (continued)

4.14 System and External Memory Interface (SEMI) (continued)

4.14.7 Performance (continued)

4.14.7.4 Summary of Access Times

Tables 66 through 69 summarize the information in Section 4.14.7.2 and Section 4.14.7.3.

Table 66. Access Time Per SEMI Transaction, Asynchronous Interface, 32-Bit Data Bus

Requester	Access Type	Reads	Writes
Core	16-bit	$[ATIME + 4 + RSETUP + RHOLD] \times T_{CLK}$	$[ATIME + 2 + WSETUP + WHOLD] \times T_{CLK}$
	32-bit aligned		
	32-bit misaligned	$[ATIME + 4 + RSETUP + RHOLD] \times 2 \times T_{CLK}$	$[ATIME + 2 + WSETUP + WHOLD] \times 2 \times T_{CLK}$
DMAU, <i>SLKA</i> = 1	16-bit	$[ATIME + 1 + RSETUP + RHOLD] \times T_{CLK}$	$[ATIME + 2 + WSETUP + WHOLD] \times T_{CLK}$
	32-bit aligned		

Table 67. Access Time Per SEMI Transaction, Asynchronous Interface, 16-Bit Data Bus

Requester	Access Type	Reads	Writes
Core	16-bit	$[ATIME + 4 + RSETUP + RHOLD] \times T_{CLK}$	$[ATIME + 2 + WSETUP + WHOLD] \times T_{CLK}$
	32-bit aligned	$[ATIME + 6 + RSETUP + RHOLD] \times T_{CLK}$	$[ATIME + 2 + WSETUP + WHOLD] \times 2 \times T_{CLK}$
	32-bit misaligned	$[ATIME + 4 + RSETUP + RHOLD] \times 2 \times T_{CLK}$	$[ATIME + 2 + WSETUP + WHOLD] \times 2 \times T_{CLK}$
DMAU, <i>SLKA</i> = 1	16-bit	$[ATIME + 1 + RSETUP + RHOLD] \times T_{CLK}$	$[ATIME + 2 + WSETUP + WHOLD] \times T_{CLK}$
	32-bit aligned	$[ATIME + 1 + RSETUP + RHOLD] \times 2 \times T_{CLK}$	$[ATIME + 2 + WSETUP + WHOLD] \times 2 \times T_{CLK}$

Table 68. Access Time Per SEMI Transaction, Synchronous Interface, 32-Bit Data Bus

Requester	Access Type	Reads	Writes
Core	16-bit	$12 \times T_{CLK}$	$4 \times T_{CLK}$
	32-bit aligned		
	32-bit misaligned	$24 \times T_{CLK}$	$8 \times T_{CLK}$
DMAU, <i>SLKA</i> = 1	16-bit	$4 \times T_{CLK}$	$4 \times T_{CLK}$
	32-bit aligned		

Table 69. Access Time Per SEMI Transaction, Synchronous Interface, 16-Bit Data Bus

Requester	Access Type	Reads	Writes
Core	16-bit	$12 \times T_{CLK}$	$4 \times T_{CLK}$
	32-bit aligned	$16 \times T_{CLK}$	$8 \times T_{CLK}$
	32-bit misaligned	$24 \times T_{CLK}$	$8 \times T_{CLK}$
DMAU, <i>SLKA</i> = 1	16-bit	$4 \times T_{CLK}$	$4 \times T_{CLK}$
	32-bit aligned	$8 \times T_{CLK}$	$8 \times T_{CLK}$

4 Hardware Architecture (continued)

4.14 System and External Memory Interface (SEMI) (continued)

4.14.7 Performance (continued)

4.14.7.4 Summary of Access Times (continued)

Tables 70 and 71 show example access times under various conditions, including DMAU accesses with $SLKA = 0$. These access times are derived from actual measurements. For the asynchronous access times, it is assumed that the programmed enable assertion time is one ($ATIME = 1$) and that $RSETUP = RHOLD = WSETUP = WHOLD = 0$. The actual value of these fields is application-dependent.

Table 70. Example Average Access Time Per SEMI Transaction, 32-Bit Data Bus

Requester	Access Type	Asynchronous		Synchronous	
		Reads	Writes	Reads	Writes
Core	16-bit	$5 \times T_{CLK}$	$3 \times T_{CLK}$	$12 \times T_{CLK}$	$4 \times T_{CLK}$
	32-bit aligned				
	32-bit misaligned	$10 \times T_{CLK}$	$6 \times T_{CLK}$	$24 \times T_{CLK}$	$8 \times T_{CLK}$
DMAU, $SLKA = 1$	16-bit	$2 \times T_{CLK}$	$3 \times T_{CLK}$	$4 \times T_{CLK}$	$4 \times T_{CLK}$
	32-bit aligned				
DMAU, $SLKA = 0$	16-bit	$9 \times T_{CLK}$	$5 \times T_{CLK}$	$14 \times T_{CLK}$	$5 \times T_{CLK}$
	32-bit aligned				

Table 71. Example Average Access Time Per SEMI Transaction, 16-Bit Data Bus

Requester	Access Type	Asynchronous		Synchronous	
		Reads	Writes	Reads	Writes
Core	16-bit	$5 \times T_{CLK}$	$3 \times T_{CLK}$	$12 \times T_{CLK}$	$4 \times T_{CLK}$
	32-bit aligned	$7 \times T_{CLK}$	$6 \times T_{CLK}$	$16 \times T_{CLK}$	$8 \times T_{CLK}$
	32-bit misaligned	$10 \times T_{CLK}$	$6 \times T_{CLK}$	$24 \times T_{CLK}$	$8 \times T_{CLK}$
DMAU, $SLKA = 1$	16-bit	$2 \times T_{CLK}$	$3 \times T_{CLK}$	$4 \times T_{CLK}$	$4 \times T_{CLK}$
	32-bit aligned	$4 \times T_{CLK}$	$6 \times T_{CLK}$	$8 \times T_{CLK}$	$8 \times T_{CLK}$
DMAU, $SLKA = 0$	16-bit	$9 \times T_{CLK}$	$5 \times T_{CLK}$	$14 \times T_{CLK}$	$5 \times T_{CLK}$
	32-bit aligned	$11 \times T_{CLK}$	$6 \times T_{CLK}$	$18 \times T_{CLK}$	$8 \times T_{CLK}$

4.14.8 Priority

SEMI prioritizes the requests from both cores and the DMAU in the following order:

1. CORE0 program (X) and data (Y) requests have the highest priority. If CORE0 requires a simultaneous X and Y access, X is performed first, then Y.
2. CORE1 program (X) and data (Y) requests have the second highest priority. If CORE1 requires a simultaneous X and Y access, X is performed first, then Y.
3. DMAU data requests have the lowest priority.

4 Hardware Architecture (continued)

4.15 Parallel Interface Unit (PIU)

The parallel interface unit (PIU) is the DSP16410B interface to a host microprocessor or microcontroller. This interface is a 16-bit parallel port that is passive only, i.e., the DSP16410B is the slave to the host for all transactions. The PIU is both *Intel*¹ and *Motorola*² memory bus compatible and provides select logic for a shared-bus interface. As an additional feature, the host can access the entire DSP16410B memory (internal and external) through the PIU.

The PIU control and data registers are memory-mapped into the DSP16410B shared internal I/O memory component (Section 4.5.7 on page 42). The host can access all of the PIU data and control registers via external pins. Both cores and the DMAU can access these registers directly via the system bus. The DMAU can directly access the PIU data registers **PDI** and **PDO**.

The DMAU supports the PIU via a dedicated bypass channel. Unlike the DMAU SWT and MMT channels, the PIU bypass channel must be configured by the host via commands over the PIU address pins, PADD[3:0].

The PIU provides three interrupt signals to the cores. These interrupts indicate a host-generated request or the completion of an input or output transaction.

1. *Intel* is a registered trademark of Intel Corporation.
2. *Motorola* is a registered trademark of Motorola, Inc.

The PIU provides the following features:

- A high-speed, 16-bit parallel host interface
- Compatibility with industry-standard microprocessor buses
- Chip select logic for shared bus system architectures
- Interrupt output pin for DSP16410B-to-host interrupt generation
- Dedicated host and core scratch registers for convenient messaging
- Supported by DMAU to access all memory

4.15.1 Registers

As summarized in Table 72, the PIU contains seven memory-mapped registers that are accessible by the host and the cores. The host accesses these registers by issuing commands through the PIU. Please refer to Section 4.15.5 on page 144. All PIU registers are accessed by the host as 16-bit quantities. The cores access the PIU registers as 32-bit memory-mapped locations residing in the shared internal I/O memory component (Section 4.5.7 on page 42). The PIU registers are aligned to even addresses and occupy addresses 0x41000 to 0x4100A, as noted in Table 72. Section 6.2.2 on page 228 provides an overview of memory-mapped registers.

Table 72. PIU Registers

Register Name	Address	Size (Host)	Size (Cores)	R/W (Host)	R/W (Cores)	Type†	Description
PCON	0x41000	16	32	R/W‡	R/W‡	c & s	PIU control and status. The application must choose one of the cores to write PCON .
PDI §	0x41008	16	32	W	R	data	PIU data in from host.
PDO	0x4100A	16	32	R	R/W	data	PIU data out to host. For a typical application, the DMAU writes PDO , but either core can also write PDO . The application must choose one of these entities to write PDO .
PAH	0x41004 (PA)	16	32	R/W	R/W	data	PIU address for host access to DSP16410B memory. The application must choose either the host or one of the cores to write this register.
PAL		16		R/W			
DSCRATCH	0x41002	16	32	R	R/W	data	DSP scratch. The application must choose one of the cores to write DSCRATCH .
HSCRATCH	0x41006	16	32	W	R	data	Host scratch.

† c & s means control and status.

‡ All bits of **PCON** are readable by both the host and the cores. Not all bits are writable—see Table 73 on page 133 for details.

§ **PDI** is double-buffered (unlike the DSP16XX PHIF **PDX** register). Therefore, a host write to **PDI** can be issued (but not completed) before a previous host write to **PDI** is completed.

4 Hardware Architecture (continued)

4.15 Parallel Interface Unit (PIU) (continued)

4.15.1 Registers (continued)

The **PCON** register is the PIU status and control register. This register reflects the state of the PIU flags (PIBF and POBE) and provides a mechanism for the host and a core to interrupt each other or reset the PIU. The bit fields of **PCON** are detailed in [Table 73](#). For each bit field, the table defines what actions can be performed by the host or a core: read, write, clear to zero, or set to one. All the bit fields of **PCON** can be read by the host and by the cores. If the **PCON** register is read, only the lower 7 bits contain valid information. The upper bits are undefined. If the host or a core writes **PCON**, it must write the upper 25 bits with zero.

Table 73. PCON (PIU Control) Register

The memory address for this register is 0x41000. The application must ensure that both cores do not write **PCON** at the same time.

			31—7	6	5	4	3	2	1	0
			Reserved	DRESET	HRESET	HINT	PINT	PREADY	PIBF	POBE
Bit	Field	Name	Value	Description			R/W (Cores)	R/W (Host)	Reset Value†	
31—7	Reserved	—	—	Reserved—write with zero; undefined on read.			—	—	—	
6	DRESET	DSP Reset	0	Always read as zero. Write with zero—no effect.			Set/Read	—	0	
			1	The program running in a core resets‡ the PIU by writing a 1 to this field. The PIU reset clears this field automatically.						
5	HRESET	Host Reset	0	Always read as zero. Write with zero—no effect.			—	Set/Read	0	
			1	The host resets‡ the PIU by writing a one to this field. The PIU reset clears this field automatically.						
4	HINT§	Interrupt from Host	0	Read as zero—no outstanding interrupt from host. Write with zero—no effect.			Clear/Read	Set/Read	0	
			1	If this field is initially cleared and the host sets it, the PIU asserts the PHINT interrupt. The interrupted core's service routine must clear this field after servicing the PHINT request to allow the host to request a subsequent interrupt. The service routine clears the field by writing one to it.						
3	PINT§	PIU Interrupt to Host	0	Read as zero—no outstanding interrupt to host. Write with zero—no effect.			Set/Read	Clear/Read	0	
			1	If this field is initially cleared and a program running in either core sets it, the PIU asserts the PINT pin to interrupt the host. The host must clear this field after servicing the PINT request to allow a core to request a subsequent interrupt. It clears the field by writing 1 to it.						
2	PREADY	PIU Ready	—	This bit is the logical OR of the PIBF and POBE flags. (It is not the same as the PRDY pin.) If set, the PIU is not ready.			Read	Read	1	
1	PIBF	PIU Input Buffer Full	0	PDI contains data that has already been read by one of the cores. The host may write PDI with new data.			Read	Read	0	
			1	PDI contains data from a prior host write request. To avoid loss of data, the host must not write PDI .						
0	POBE	PIU Output Buffer Empty	0	PDO contains new data. To avoid loss of data, the cores must not write PDO .			Read	Read	1	
			1	PDO contains data that has already been read by the host. The cores may write PDO with new data.						

† Device reset or PIU reset.

‡ The purpose of the PIU reset is to reinitialize all PIU sequencers and flags to their reset state.

§ If the host and a core attempt to set/clear this bit simultaneously, the PIU clears the bit.

4 Hardware Architecture (continued)

4.15 Parallel Interface Unit (PIU) (continued)

4.15.1 Registers (continued)

The **PDI** and **PDO** registers (Table 74 and Table 75) are the 16-bit PIU input and output data registers. **PDI** contains data written by the host at the conclusion of a valid host write cycle. **PDO** contains data written by a core or the DMAU that is driven onto the PIU data bus during a valid host read cycle.

Table 74. PDI (PIU Data In) Register

The memory address for this register is 0x41008.

31—16			15—0		
Reserved			PIU Input Data		
Bit	Field	Description	R/W (Cores)	R/W (Host)	Reset Value
31—16	Reserved	Reserved—read as zero.	R	W	0
15—0	PIU Input Data	PIU data in from host.	R	W	0

Table 75. PDO (PIU Data Out) Register

The memory address for this register is 0x4100A. For a typical application, the DMAU writes **PDO**, but the cores can also write **PDO**. The application must ensure that these entities do not write **PDO** at the same time.

31—16			15—0		
Reserved			PIU Output Data		
Bit	Field	Description	R/W (Cores)	R/W (Host)	Reset Value
31—16	Reserved	Reserved—write with zero.	R/W	R	0
15—0	PIU Output Data	PIU data out to host.	R/W	R	0

The **DSCRATCH** and **HSCRATCH** registers (Table 77 and Table 76) are the DSP and host scratch registers that can be used to pass messaging data between a core and the host. After a core writes 16-bit data to **DSCRATCH**, the host can read this data by issuing a **read_dscratch** command. Conversely, the host can write 16-bit data to **HSCRATCH** by issuing a **write_hscratch** command. See Section 4.15.5 on page 144 for details on host commands.

Table 76. HSCRATCH (Host Scratch) Register

The memory address for this register is 0x41006.

31—16			15—0		
Reserved			Host Scratch		
Bit	Field	Description	R/W (Cores)	R/W (Host)	Reset Value
31—16	Reserved	Reserved—read as zero.	R	W	0
15—0	Host Scratch	Host scratch data to DSP16410B.	R	W	0

Table 77. DSCRATCH (DSP Scratch) Register

The memory address for this register is 0x41002. The application must choose one of the cores to write **DSCRATCH**.

31—16			15—0		
Reserved			DSP Scratch		
Bit	Field	Description	R/W (Cores)	R/W (Host)	Reset Value
31—16	Reserved	Reserved—write with zero.	R/W	R	0
15—0	DSP Scratch	DSP scratch data to host.	R/W	R	0

4 Hardware Architecture (continued)

4.15 Parallel Interface Unit (PIU) (continued)

4.15.1 Registers (continued)

The **PA** register (Table 78) provides the DSP16410B memory address for any host accesses to DSP16410B memory. The host must access this register as two 16-bit quantities—the high half (**PAH**) and the low half (**PAL**). A core accesses **PA** as a double-word (32-bit) location at address 0x41004. See Figure 37 for details. As shown in Table 78, the ADD[19:0] field (**PA**[19:0]) contains the memory address to be accessed within the selected memory component determined by the CMP[2:0] field (**PA**[22:20]). The ESEG[3:0] field (**PA**[26:23]) determines the external segment extension for external memory accesses through the SEMI. The SEMI drives the value in the ESEG[3:0] field onto the ESEG[3:0] pins at the same time that it asserts the appropriate enable pin (ERAMN, EION, or EROMN) and drives the external memory address onto EA[18:0].

Table 78. PA (Parallel Address) Register

The memory address for this register is 0x41004. The application must choose either the host or one of the cores to write this register.

31—27		26—23		22—20		19—0		
Reserved		ESEG[3:0]		CMP[2:0]		ADD[19:0]		
Bit	DSP Access	Host Access	Field	Value	Definition	R/W	Reset Value	
31—27	PA†	PAH[15:0]‡	Reserved	0	Reserved—write with zero.	R/W	0	
26—23			ESEG[3:0]	0x0 to 0xF	External memory address extension. The value of this field is placed directly on the ESEG[3:0] pins for PIU accesses to external memory§.	R/W	0x0	
22—20			CMP[2:0]	000	000	The selected memory component is TPRAM0.	R/W	000
					001	The selected memory component is TPRAM1.		
					01X	Reserved.		
					100	The selected memory component is ERAM††, EIO, or internal I/O.		
	101	Reserved.						
19—16	ADD[19:0]	PAL[15:0]‡‡	ADD[19:0]	0x00000 to 0xFFFFF	The address within the selected memory space.	R/W	0x00000	
15—0								

† Memory-mapped to double word at address 0x41004.

‡ Write with **write_pah** command; read with **read_pah** command.

§ This field is valid only for external memory accesses (CMP[2:0] = 100) and is ignored for internal memory accesses.

†† If the WEROM field (ECON1[11]—Table 60 on page 110) is set, EROM is selected in place of ERAM.

‡‡ Write with **write_pal** command; read with **read_pal** command.

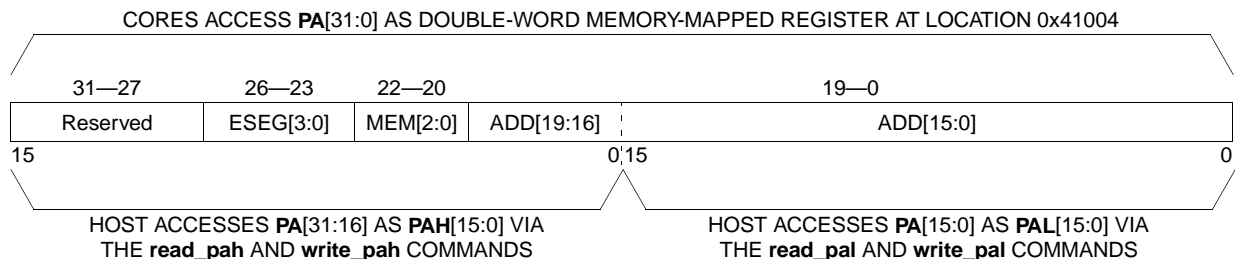


Figure 37. 32-Bit PA Register Host and Core Access

4 Hardware Architecture (continued)

4.15 Parallel Interface Unit (PIU) (continued)

4.15.1 Registers (continued)

The host accesses **PAH** and **PAL** by executing the **read_pah**, **read_pal**, **write_pah**, and **write_pal** commands. After certain host commands, the PIU autoincrements the value in **PA**. See [Section 4.15.5 on page 144](#) for details on host commands. Unlike the DSP1620 and DSP16210 MIOU, the PIU increments the value in the **PA** register linearly and does not wrap it.

4.15.2 Hardware Interface

The host interface to the PIU consists of 29 pins, as summarized in [Table 79](#). The remainder of this section describes these pins in detail.

Table 79. PIU External Interface

Function	Pin	Type	Description
Address and Data	PD[15:0]	I/O/Z	16-bit bidirectional, parallel data bus. 3-stated if PCSN = 1.
	PADD[3:0]†	I	PIU 4-bit address and control input.
Enables and Stobes	PODS‡	I	PIU output data strobe. <i>Intel</i> host: Connect to the host active-low read data strobe. <i>Motorola</i> host: Connect to the host data strobe.
	PIDS‡	I	PIU input data strobe. <i>Intel</i> host: Connect to the host active-low write data strobe. <i>Motorola</i> host: Connect to logic 0 to program an active-high data strobe. Connect to logic 1 to program an active-low data strobe.
	PRWN‡	I	PIU read/write not. <i>Intel</i> host: Connect to the host active-low host write strobe. <i>Motorola</i> host: Connect to host RWN strobe.
	PCSN‡	I	PIU chip select—active-low.
Flags, Interrupt, and Ready	POBE	O	PIU output buffer empty flag.
	PIBF	O	PIU input buffer full flag.
	PINT	O	PIU interrupt (interrupt signal to host).
	PRDY	O	PIU ready. Indicates the status of the current host read operation or previous host write operation. The PRDYMD pin determines the logic level of this pin.
	PRDYMD†	I	PIU ready pin mode. 0: PRDY pin is active-low (PRDY = 0 indicates the PIU is ready). 1: PRDY pin is active-high (PRDY = 1 indicates the PIU is ready).

† If the system application does not use these pins, they must be tied low.

‡ If the system application does not use these pins, they must be tied high.

4 Hardware Architecture (continued)

4.15 Parallel Interface Unit (PIU) (continued)

4.15.2 Hardware Interface (continued)

4.15.2.1 Enables and Strobes

The PIU provides a chip select input pin (PCSN) that allows the host to connect to multiple DSP16410B or other devices. The function of the enable and strobe pins (PODS, PIDS, and PRWN) is based on whether the host type is *Intel* or *Motorola*. In order to support both types of hosts, the PIU generates a negative-assertion internal strobe PSTRN that is a logical combination of PCSN, PODS, and PIDS as follows:

$$PSTRN = PCSN | (\overline{PIDS} \wedge \overline{PODS})$$

The PIU initiates all transactions on the falling edge of PSTRN and completes all transactions on the rising edge of PSTRN.

Table 80. Enable and Strobe Pins

Pin	Name	Value	Description
PCSN (input)	PIU Chip Select	0	The host is selecting this device for PIU transfers.
		1	The host is not selecting this device for PIU transfers and the PIU 3-states PD[15:0] and ignores any activity on PIDS, PODS, and PRWN.
PODS (input)	PIU Output Data Strobe	—	<ul style="list-style-type: none"> ■ For an <i>Intel</i> host, PODS functions as an output data strobe and must be connected to the host active-low read data strobe. The host initiates a read transaction by asserting (low) both PCSN and PODS. The host concludes a read transaction by deasserting (high) either PCSN or PODS. ■ For a <i>Motorola</i> host, PODS functions as a data strobe and must be connected to the host data strobe. The state of the PIDS pin determines the active level of PODS. If PIDS = 0, PODS is an active-high data strobe. If PIDS = 1, PODS is an active-low data strobe. The host initiates a read transaction by asserting both PCSN and PODS. The host concludes a read transaction by deasserting either PCSN or PODS.
PIDS (input)	PIU Input Data Strobe	—	<ul style="list-style-type: none"> ■ For an <i>Intel</i> host, PIDS functions as an input data strobe and must be connected to the host active-low write data strobe. The host initiates a write transaction by asserting (low) both PCSN and PIDS. The host concludes a write transaction by deasserting (high) either PCSN or PIDS. ■ For a <i>Motorola</i> host, the state of PIDS determines the active level of the host data strobe, PODS.
PRWN (input)	PIU Read/Write Not Strobe	—	<p>The host drives PRWN high during host reads, and low during host writes. PRWN must be stable for the entire access (while PCSN and the appropriate data strobes are asserted).</p> <ul style="list-style-type: none"> ■ For an <i>Intel</i> host, PRWN and PIDS are connected to the host active-low write data strobe. ■ For a <i>Motorola</i> host, PRWN functions as an active read/write strobe and must be connected to the host RWN output.

4 Hardware Architecture (continued)

4.15 Parallel Interface Unit (PIU) (continued)

4.15.2 Hardware Interface (continued)

4.15.2.2 Address and Data Pins

The PIU provides a 16-bit external data bus (PD[15:0]). It provides a 4-bit input address bus (PADD[3:0]) that the host uses to select between PIU registers and to issue PIU commands.

Table 81. Address and Data Pins

Pin	Name	Description
PD[15:0] (input/ output)	Data Bus	<ul style="list-style-type: none"> ■ If the host issues a read command, the PIU drives the data contained in PDO onto PD[15:0]. ■ If the host issues a write command, it drives the data onto PD[15:0] and the PIU latches the data into PDI. ■ If the PIU is not selected by the host (PCSN is high), the PIU 3-states PD[15:0].
PADD[3:0] (input)	Address Bus	A 4-bit address input driven by the host to select between various PIU registers and to issue PIU commands. See Section 4.15.5 on page 144 for details.

4 Hardware Architecture (continued)

4.15 Parallel Interface Unit (PIU) (continued)

4.15.2 Hardware Interface (continued)

4.15.2.3 Flags, Interrupt, and Ready Pins

The PIU provides buffer status flag pins, an interrupt to the host, and a host ready and mode pin pair.

Table 82. Flags, Interrupt, and Ready Pins

Pin	Name	Value	Description	
POBE [†] (output)	PIU Output Buffer Empty	0	PDO contains data ready for the host to read.	
		1	PDO is empty, i.e., there is no data for the host to read.	
PIBF [‡] (output)	PIU Input Buffer Full	0	PDI is empty, so the host can safely write another word into PDI .	
		1	PDI is full with the previous word that was written by the host. If the host writes PDI , the previous data is overwritten.	
PINT (output)	PIU Interrupt Host	0	A core has not requested an interrupt to the host.	
		1	A core has requested an interrupt to the host by setting the PINT field (PCON [3]— Table 73 on page 133). The host acknowledges the interrupt by writing a 1 to the PINT field, clearing it.	
PRDYMD (input)	PIU Ready Mode	0	PRDY is active-low.	
		1	PRDY is active-high.	
PRDY [§] (output)	PIU Ready	If PRDYMD = 0	0	<ul style="list-style-type: none"> For a host data read operation, the read data in PDO and on PD[15:0] is valid and the host can latch the data and conclude the read cycle^{††}. For a host write operation, the previous write operation has been processed by the DSP16410B (PDI is empty) and the host can conclude the current write cycle^{††}, i.e., can write PDI with new data.
			1	<ul style="list-style-type: none"> For a host data read operation, the DSP16410B is processing the current read operation (PDO is still empty) and the host must extend the current access until the PIU drives PRDY low before concluding the read cycle^{††}. For a host write operation, the DSP16410B is processing the previous write operation (PDI is still full) and the host must extend the current access until the PIU drives PRDY low before concluding the write cycle^{††}.
			0	<ul style="list-style-type: none"> For a host data read operation, the DSP16410B is processing the current read operation (PDO is still empty) and the host must extend the current access until the PIU drives PRDY high before concluding the read cycle^{††}. For a host write operation, the DSP16410B is processing the previous write operation (PDI is still full) and the host must extend the current access until the PIU drives PRDY high before concluding the write cycle^{††}.
		If PRDYMD = 1	0	<ul style="list-style-type: none"> For a host data read operation, the DSP16410B is processing the current read operation (PDO is still empty) and the host must extend the current access until the PIU drives PRDY high before concluding the read cycle^{††}. For a host write operation, the DSP16410B is processing the previous write operation (PDI is still full) and the host must extend the current access until the PIU drives PRDY high before concluding the write cycle^{††}.
			1	<ul style="list-style-type: none"> For a host data read operation, the read data in PDO and on PD[15:0] is valid and the host can latch the data and conclude the read cycle^{††}. For a host write operation, the previous write operation has been processed by the DSP16410B (PDI is empty) and the host can conclude the current write cycle^{††}, i.e., can write PDI with new data.
			0	<ul style="list-style-type: none"> For a host data read operation, the read data in PDO and on PD[15:0] is valid and the host can latch the data and conclude the read cycle^{††}. For a host write operation, the previous write operation has been processed by the DSP16410B (PDI is empty) and the host can conclude the current write cycle^{††}, i.e., can write PDI with new data.

[†] The state of this pin is also readable by the cores in the POBE field (**PCON**[0]—see [Table 73 on page 133](#)).

[‡] The state of this pin is also readable by the cores in the PIBF field (**PCON**[1]—see [Table 73 on page 133](#)).

[§] For the descriptions in this table to be valid, the PIU must be activated, i.e., PSTRN must be asserted. See [Section 4.15.2.1 on page 137](#) for a definition of PSTRN.

^{††} See description of PIDS and PODS in [Table 80 on page 137](#).

4 Hardware Architecture (continued)

4.15 Parallel Interface Unit (PIU) (continued)

4.15.3 Host Data Read and Write Cycles

This section describes typical host read and write cycles of data for both *Intel* and *Motorola* hosts.

Figure 38 on page 141 is a functional timing diagram of a data read and a data write cycle for both an *Intel* and a *Motorola* host. The address that the host applies to PADD[3:0] during the cycle determines the transaction type, i.e., determines the host command. See Section 4.15.5 on page 144 for details on host commands.

The following sequence corresponds to the *Intel* data read cycle shown in Figure 38:

1. The host drives a valid address onto PADD[3:0].
The host must hold PIDS high for the entire duration of the access.
2. The host initiates the cycle by asserting (low) PCSN and PODS.
3. When data becomes available in **PDO**, the PIU drives the data onto PD[15:0].
4. To notify the host that the data in **PDO** and on PD[15:0] is valid, the PIU asserts PRDY and deasserts POBE. If the data in **PDO** is not yet valid, the PIU continues deasserting PRDY and the host must wait until the PIU asserts PRDY.
5. The host concludes the cycle by deasserting PCSN or PODS and latching the data from PD[15:0].
6. The PIU 3-states PD[15:0].

The following sequence corresponds to the *Intel* data write cycle shown in Figure 38:

1. The host drives a valid address onto PADD[3:0].
The host must hold PODS high for the entire duration of the access.
2. The host initiates the cycle by asserting (low) PCSN, PIDS, and PRWN.
3. The host drives data onto PD[15:0].
4. If **PDI** is empty, the PIU notifies the host by asserting PRDY and deasserting PIBF. If **PDI** is still full from a previous host write, the host must wait until the PIU asserts PRDY.
5. The host concludes the cycle by deasserting PCSN or PIDS, causing the PIU to latch the data from PD[15:0] into **PDI**.
6. The host 3-states PD[15:0].

The following sequence corresponds to the *Motorola* data read cycle shown in Figure 38. In the figure and in the timing sequences described below, it is assumed that PIDS is tied high, selecting an active-low data strobe (PODS).

1. The host drives a valid address onto PADD[3:0].
The host must hold PRWN high for the duration of the access.
2. The host initiates the cycle by asserting PCSN and PODS (low).
3. When data becomes available in **PDO**, the PIU drives the data onto PD[15:0].
4. To notify the host that the data in **PDO** and on PD[15:0] is valid, the PIU asserts PRDY and deasserts POBE. If the data in **PDO** is not yet valid, the PIU continues deasserting PRDY and the host must wait until the PIU asserts PRDY.
5. The host concludes the cycle by deasserting PCSN or PODS and latching the data from PD[15:0].
6. The PIU 3-states PD[15:0].

The following sequence corresponds to the *Motorola* data write cycle shown in Figure 38. In the figure and in the timing sequences described below, it is assumed that PIDS is tied high, selecting an active-low data strobe (PODS).

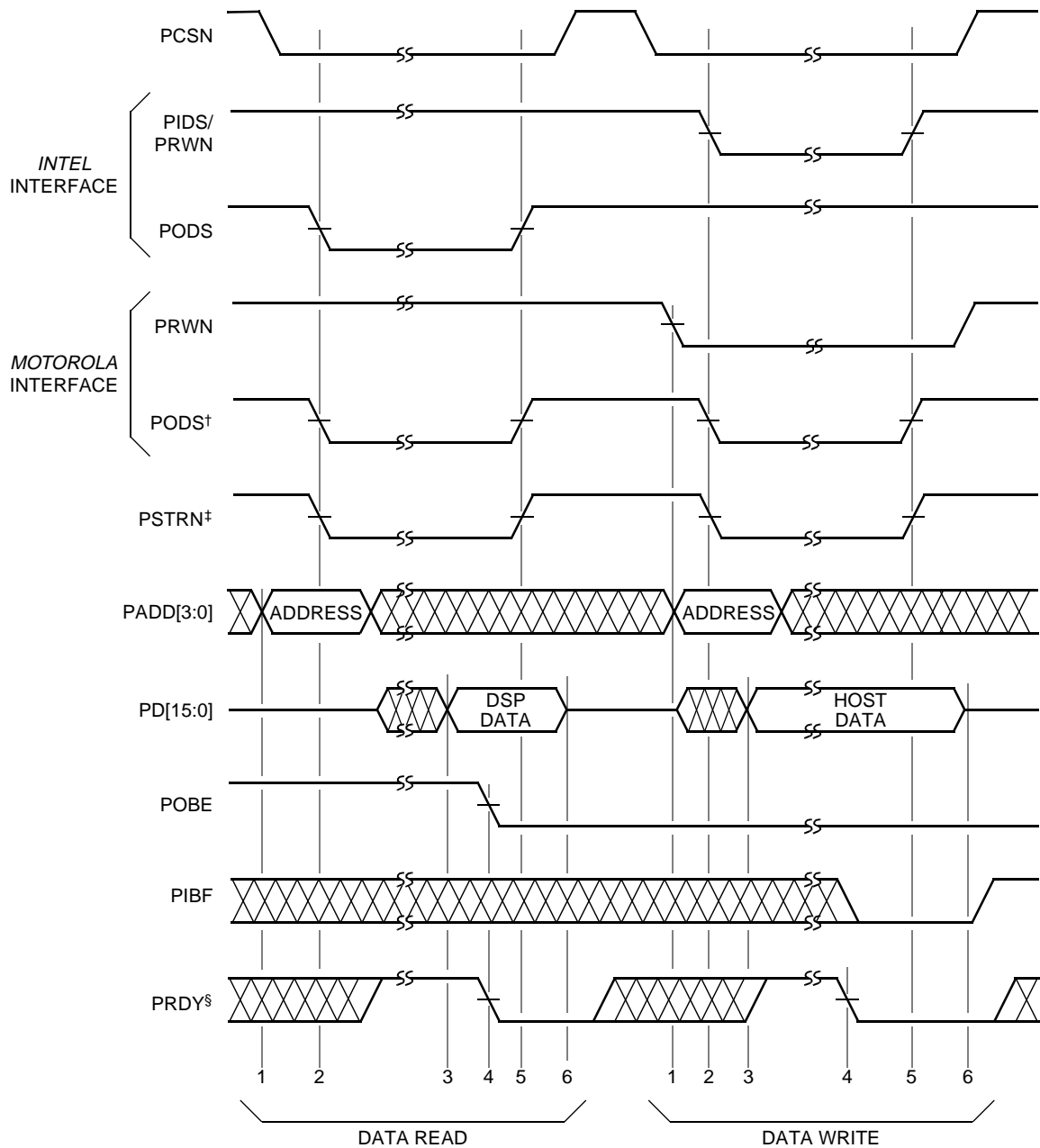
1. The host drives a valid address onto PADD[3:0] and drives PRWN low.
2. The host initiates the cycle by asserting PCSN and PODS (low).
3. The host drives data onto PD[15:0].
4. If **PDI** is empty, the PIU notifies the host by asserting PRDY and deasserting PIBF. If **PDI** is still full from a previous host write, the host must wait until the PIU asserts PRDY.
5. The host concludes the cycle by deasserting PCSN or PODS, causing the PIU to latch the data from PD[15:0] into **PDI**.
6. The host 3-states PD[15:0].

Note: Once the host initiates a data read or data write transaction, it must complete it properly as described above. If the host concludes the transaction before the PIU asserts PRDY, the results are undefined and the PIU must be reset. In this case, the host can reset the PIU by setting the HRESET field (**PCON**[5]—Table 73 on page 133) or a core can reset the PIU by setting the DRESET field (**PCON**[6]).

4 Hardware Architecture (continued)

4.15 Parallel Interface Unit (PIU) (continued)

4.15.3 Host Data Read and Write Cycles (continued)



† For the *Motorola* interface, it is assumed that PIDS is tied high, selecting an active-low data strobe (PODS).

‡ PSTRN is an internal signal that is a logical combination of PCSN, PIDS, and PODS as follows: $PSTRN = PCSN | (PIDS \wedge PODS)$.

§ It is assumed that the PRDYMD input pin is logic low, causing PRDY to be active-low.

Figure 38. PIU Functional Timing for a Data Read and Write Operation

4 Hardware Architecture (continued)

4.15 Parallel Interface Unit (PIU) (continued)

4.15.4 Host Register Read and Write Cycles

This section describes typical host read and write cycles of PIU registers for both *Intel* and *Motorola* hosts. Figure 39 on page 143 is a functional timing diagram of a register read and a register write cycle for both an *Intel* and a *Motorola* host. The address that the host applies to PADD[3:0] during the cycle determines how the host accesses the register, i.e., determines the host command. See Section 4.15.5 on page 144 for details on host commands.

The following sequence corresponds to the *Intel* host read of the **PAH**, **PAL**, **PCON**, or **DSCRATCH** register shown in Figure 39:

1. The host drives a valid address onto PADD[3:0].
The host must hold PIDS high for the entire duration of the access.
2. The host initiates the cycle by asserting (low) PCSN and PODS.
3. The PIU drives the contents of the register onto PD[15:0].
4. The host concludes the cycle by deasserting PCSN or PODS and latching the data from PD[15:0].
5. The PIU 3-states PD[15:0].

The following sequence corresponds to the *Intel* host write of the **PAH**, **PAL**, **PCON**, or **HSCRATCH** register shown in Figure 39. The PIU uses the **PDI** register to temporarily hold the write data.

1. The host drives a valid address onto PADD[3:0].
The host must hold PODS high for the entire duration of the access.
2. The host initiates the cycle by asserting (low) PCSN, PIDS, and PRWN.
3. The host drives data onto PD[15:0].
4. If **PDI** is empty, the PIU notifies the host by asserting PRDY and deasserting PIBF. If **PDI** is still full from a previous host write, the host must wait until the PIU asserts PRDY.
5. The host concludes the cycle by deasserting PCSN or PIDS, causing the PIU to latch the data from PD[15:0] into **PDI**. The PIU transfers the data in **PDI** into **PAH**, **PAL**, **PCON**, or **HSCRATCH**.
6. The host 3-states PD[15:0].

The following sequence corresponds to the *Motorola* read of the **PAH**, **PAL**, **PCON**, or **DSCRATCH** register shown in Figure 39. In the figure and in the timing sequences described below, it is assumed that PIDS is tied high, selecting an active-low data strobe (PODS).

1. The host drives a valid address onto PADD[3:0].
The host must hold PRWN high for the duration of the access.
2. The host initiates the cycle by asserting (low) PCSN and PODS
3. The PIU drives the data in the register onto PD[15:0].
4. The host concludes the cycle by deasserting PCSN or PODS and latching the data from PD[15:0].
5. The PIU 3-states PD[15:0].

The following sequence corresponds to the *Motorola* write of the **PAH**, **PAL**, **PCON**, or **DSCRATCH** register shown in Figure 39. In the figure and in the timing sequences described below, it is assumed that PIDS is tied high, selecting an active-low data strobe (PODS).

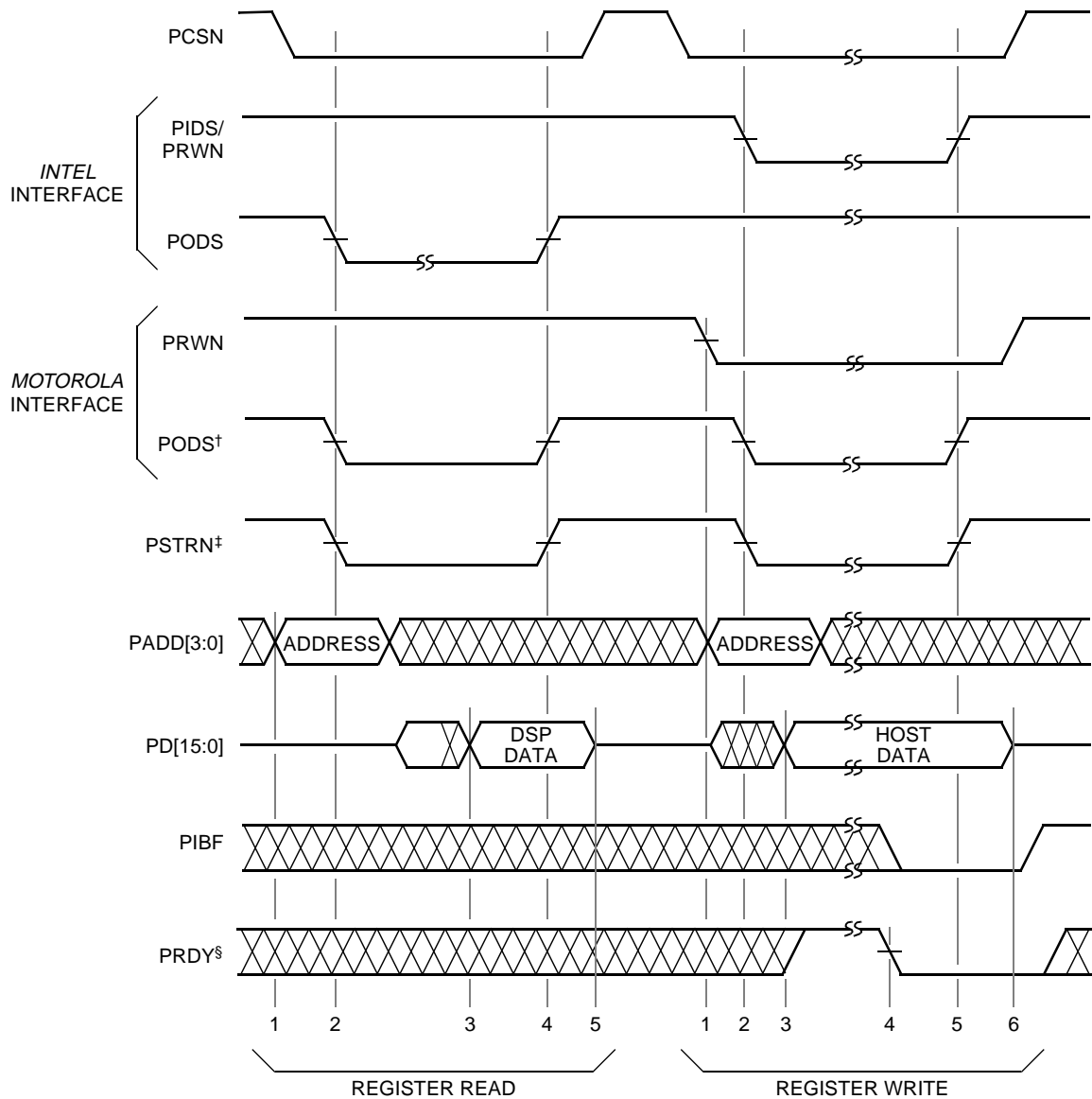
1. The host drives a valid address onto PADD[3:0] and drives PRWN low.
2. The host initiates the cycle by asserting (low) PCSN and PODS.
3. The host drives data onto PD[15:0].
4. If **PDI** is empty, the PIU notifies the host by asserting PRDY and deasserting PIBF. If **PDI** is still full from a previous host write, the host must wait until the PIU asserts PRDY.
5. The host concludes the cycle by deasserting PCSN or PODS, causing the PIU to latch the data from PD[15:0] into **PDI**. The PIU transfers the data in **PDI** into **PAH**, **PAL**, **PCON**, or **HSCRATCH**.
6. The host 3-states PD[15:0].

Note: Once the host initiates a register write transaction, it must complete it properly as described above. If the host concludes the transaction before the PIU asserts PRDY, the results are undefined and the PIU must be reset. In this case, the host can reset the PIU by setting the HRESET field (**PCON**[5]—Table 73 on page 133) or a core can reset the PIU by setting the DRESET field (**PCON**[6]).

4 Hardware Architecture (continued)

4.15 Parallel Interface Unit (PIU) (continued)

4.15.4 Host Register Read and Write Cycles (continued)



[†] For the *Motorola* interface, it is assumed that PIDS is tied high, selecting an active-low data strobe (PODS).

[‡] PSTRN is an internal signal that is a logical combination of PCSN, PIDS, and PODS as follows: $PSTRN = PCSN \mid (\overline{PIDS} \wedge \overline{PODS})$.

[§] It is assumed that the PRDYMD input pin is logic low, causing PRDY to be active-low.

Figure 39. PIU Functional Timing for a Register Read and Write Operation

4 Hardware Architecture (continued)

4.15 Parallel Interface Unit (PIU) (continued)

4.15.5 Host Commands

The host commands are summarized in Table 83. A host command is a host read or write cycle with the PADD[3:0] pins configured to select one of several commands. Each command has a corresponding mnemonic as defined in the table. These mnemonics are defined to simplify the explanations that follow and are also used by the DSP16410B model in the *LUxWORKS™* debugger. These commands are detailed in the remainder of this section.

Table 83. Summary of Host Commands

Command Type	Pins		Command Mnemonic	Description (PIU/DMAU Response)	Flow Control
	PRWN	PADD[3:0]			
Memory Write	0	0000	write_pdi	Write DSP16410B memory location pointed to by PA with data on PD[15:0].	Yes
	0	0001	write_pdi++	1. Write DSP16410B memory location pointed to by PA with data on PD[15:0]. 2. Increment PA by one.	
PIU Register Write	0	100X	write_pah	Write high half of PA via PDI with data from PD[15:0].	Yes
	0	101X	write_pal	Write low half of PA via PDI with data from PD[15:0].	
	0	110X	write_pcon	Write PCON via PDI with data from PD[15:0].	
	0	111X	write_hscratch	Write HSCRATCH via PDI with data from PD[15:0].	
Memory Read	1	0000	read_pdo	Read DSP16410B memory location pointed to by PA , and place the contents onto PD[15:0].	Yes
	1	0001	read_pdo++	1. Read DSP16410B memory location pointed to by PA , and place the contents onto PD[15:0]. 2. Increment PA by one.	
	1	0010	—	Reserved.	—
	1	0011	rdpf_pdo++	Perform a memory read operation with prefetch. This is the highest-performance command for host reads of contiguous blocks of memory. See Section 4.15.5.3 on page 146 for details.	Yes
	1	0100	load_pdo	1. Read DSP16410B memory location pointed to by PA , and place the contents in PDO . 2. Follow with unld_pdo .	No
	1	0101	load_pdo++	1. Read DSP16410B memory location pointed to by PA , and place the contents in PDO . 2. Increment PA by one. 3. Follow with unld_pdo .	No
	1	0110	unld_pdo	Place the contents of PDO onto PD[15:0].	Yes
PIU Register Read	1	100X	read_pah	Place the contents of the high half of PA onto PD[15:0].	No
	1	101X	read_pal	Place the contents of the low half of PA onto PD[15:0].	
	1	110X	read_pcon	Place the contents of PCON onto PD[15:0].	
	1	111X	read_dscratch	Place the contents of DSCRATCH onto PD[15:0].	

4 Hardware Architecture (continued)

4.15 Parallel Interface Unit (PIU) (continued)

4.15.5 Host Commands (continued)

The host issues commands to the PIU through the PIU's external interface. Host commands allow the host to access all DSP16410B internal and external memory locations. Host commands can also read or write PIU scratch and control/status registers. All commands are executed by a combination of actions performed by the PIU and by the DMAU bypass channel.

A host command consists of four parts:

1. Read versus write operation is determined by the state of the PRWN pin.
2. The selection of a PIU internal register (**PDI**, **PDO**, **PA**, **PCON**, **HSCRATCH**, or **DSCRATCH**) is made by PADD[3:1].
3. The command can be qualified by the state of the PADD[0] pin. This pin determines if a read or write command requires a postincrement of the **PA** register.
4. Data is read or driven onto PD[15:0] by the host.

4.15.5.1 Status/Control/Address Register Read Commands

The host can read the **PA**, **PCON**, and **DSCRATCH** registers by issuing the appropriate command as part of a host read cycle. These commands do **not** affect the state of the **PA**, **PCON**, or **PDO** registers or the state of the PIBF, POBE, or PRDY pins. No flow control is required for these commands.

Table 84. Status/Control/Address Register Read Commands

Command Mnemonic	Description
read_pah	This command causes the PIU to place the upper 16-bit contents of the PA register (PAH) onto PD[15:0].
read_pal	This command causes the PIU to place the lower 16-bit contents of the PA register (PAL) onto PD[15:0].
read_pcon	This command causes the PIU to place the 16-bit contents of the PCON register onto PD[15:0].
read_dscratch	This command causes the PIU to place the 16-bit contents of the DSCRATCH register onto PD[15:0].

4.15.5.2 Status/Control/Address Register Write Commands

The host can write the **PA**, **PCON**, and **HSCRATCH** registers by executing the appropriate command as part of a host write cycle. Flow control **is** required for these commands, i.e., the host must check the status of the PRDY pin to ensure that any previous data write has completed before writing to **PA**, **PCON**, or **HSCRATCH**. For a description of flow control, see the flow control description in [Section 4.15.5.5 on page 148](#).

Table 85. Status/Control/Address Register Write Commands

Command Mnemonic	Description
write_pah	This command causes the PIU to move the contents of the PDI register into the upper 16 bits of the PA register (PAH). The data move begins at the termination of a PIU host write cycle.
write_pal	This command causes the PIU to move the contents of the PDI register into the lower 16 bits of the PA register (PAL). The data move begins at the termination of a PIU host write cycle.
write_pcon	This command causes the PIU to move the contents of the PDI register into the PCON register. The data move begins at the termination of a PIU host write cycle.
write_hscratch	This command causes the PIU to move the contents of the PDI register into the HSCRATCH register. The data move begins at the termination of a PIU host write cycle.

4 Hardware Architecture (continued)

4.15 Parallel Interface Unit (PIU) (continued)

4.15.5 Host Commands (continued)

4.15.5.3 Memory Read Commands

The DMAU¹ coordinates and executes host data read commands via its PIU bypass channel (Section 4.13.4 on page 85). Prior to issuing a data read command, the host must initialize the **PA** register with the starting address in memory by executing the **write_pah** and **write_pal** commands. Table 86 describes each host read command in detail:

Table 86. Memory Read Commands

Command Mnemonic	Description
load_pdo	This command causes the PIU to: <ul style="list-style-type: none"> ■ Request the DMAU to fetch the single word (16 bits) pointed to by the contents of PA. ■ Place the word into PDO. The host does not wait for the data after issuing this command (flow control can be ignored), but must issue a subsequent unld_pdo command.
load_pdo++	This command causes the PIU to: <ul style="list-style-type: none"> ■ Request the DMAU to fetch the single word (16 bits) pointed to by the contents of PA. ■ Place the word into PDO. ■ Postincrement the address in PA by one to point to the next single-word location. The host does not wait for the data after issuing this command (flow control can be ignored), but must issue a subsequent unld_pdo command.
unld_pdo	This command causes the PIU to drive the current contents of PDO onto PD[15:0]. The host must use proper flow control with this command (see Section 4.15.5.4 on page 147).
read_pdo	This command causes the PIU to: <ul style="list-style-type: none"> ■ Request the DMAU to fetch the single word (16 bits) pointed to by the contents of PA. ■ Place the word into PDO. ■ Drive the contents of PDO onto PD[15:0]. The host must use proper flow control with this command (see Section 4.15.5.4 on page 147).
read_pdo++	This command causes the PIU to: <ul style="list-style-type: none"> ■ Request the DMAU to fetch the single word (16 bits) from the address in PA. ■ Place the word into PDO. ■ Drive the contents of PDO onto PD[15:0]. ■ Postincrement the address in PA by one to point to the next single-word location. The host must use proper flow control with this command (see Section 4.15.5.4 on page 147).

1. A core can coordinate host data read commands by program control, but this is very inefficient compared to using the DMAU for this purpose.

4 Hardware Architecture (continued)

4.15 Parallel Interface Unit (PIU) (continued)

4.15.5 Host Commands (continued)

4.15.5.3 Memory Read Commands (continued)

Table 86. Memory Read Commands (continued)

Command Mnemonic	Description
rdpf_pdo++	<p>This command is a host read with prefetch. It is the highest-performance command for host reads of contiguous blocks of memory because it causes the DMAU to fetch the block of data as double words (32 bits). Because the host reads the data as single words (16 bits), the PIU stores the other half of the double word in a prefetch buffer. As a result, the host must adhere to the following rules to use this command:</p> <ul style="list-style-type: none"> ■ Before the host issues its first rdpf_pdo++ command with a new memory address, it must first issue a read_pdo++ command. This flushes the prefetch buffer from any previously issued rdpf_pdo++ command. ■ The host must not issue a command that reads or writes PA, PCON, HSCRATCH, or DSCRATCH within a series of rdpf_pdo++ commands. ■ The host must use proper flow control with this command (see Section 4.15.5.4). <p>For every two rdpf_pdo++ commands issued by the host, the DMAU and PIU perform the following:</p> <ul style="list-style-type: none"> ■ The PIU requests the DMAU to fetch the double word[†] pointed to by the contents of PA. ■ The PIU postincrements PA by two to point to the next double-word location. ■ The PIU places the first word (the single word at the address in PA) into PDO, places the second word (the single word at the address in PA + 1) into the prefetch buffer, and drives the word in PDO onto PD[15:0]. ■ In response to the second rdpf_pdo++ command issued by the host, the PIU places the second word (the contents of the prefetch buffer) into PDO and drives the word in PDO onto PD[15:0]. <p>This command achieves an average throughput of one word per seven CLK cycles.</p>

[†] If **PA** contains an odd address, the PIU requests a single-word access for the first **rdpf_pdo++** command in the sequence because the DMAU requires all double-word accesses to have even addresses. All subsequent **rdpf_pdo++** commands in the sequence have even addresses and the PIU requests double-word accesses.

4.15.5.4 Flow Control for Memory Read Commands

The host performs flow control for memory read commands by one of two methods:

1. The host can monitor the PRDY pin to extend an access that has been initiated and wait for PRDY to be asserted. This method must be used for the **read_pdo**, **read_pdo++**, and **rdpf_pdo++** commands and can be used for the **unld_pdo** command.
2. If the host is unable to use the PRDY pin for flow control, it cannot use the **read_pdo**, **read_pdo++**, or **rdpf_pdo++** command to read memory and must instead use the combination of the **load_pdo** and **unld_pdo** commands. The host monitors the POBE field (**PCON**[0]—see [Table 73 on page 133](#)) to determine if **PDO** is full and can be read with the **unld_pdo** command, as shown in the following pseudocode:

```

Issue the load_pdo command to the core // Fetch a word from DSP16410B memory
Do: // and place into PDO register.
Issue a read_pcon command to the core // Host read of PCON.
Repeat until POBE is 0 // Wait for POBE = 0.
Issue the unld_pdo command // Data in PDO now on PD[15:0].

```

4 Hardware Architecture (continued)

4.15 Parallel Interface Unit (PIU) (continued)

4.15.5 Host Commands (continued)

4.15.5.5 Memory Write Commands

The DMAU¹ coordinates and executes host data write commands via its PIU bypass channel (Section 4.13.4 on page 85). Prior to issuing a data write command, the host must initialize the **PA** register with the starting address in memory by executing the **write_pah** and **write_pal** commands. Table 87 describes each host write command in detail.

Table 87. Memory Write Commands

Command Mnemonic	Description
write_pdi	This command causes the PIU to: <ul style="list-style-type: none"> ■ Latch the data from PD[15:0] into PDI. ■ Request the DMAU to write the contents of PDI to the single word pointed to by the contents of PA. The host must use proper flow control with this command (see Section 4.15.5.6).
write_pdi++	This command causes the PIU to: <ul style="list-style-type: none"> ■ Latch the data from PD[15:0] into PDI. ■ Request the DMAU to write the contents of PDI to the single word pointed to by the contents of PA. ■ Postincrement the address in PA to point the next single-word location. The host must use proper flow control with this command (see Section 4.15.5.6).

4.15.5.6 Flow Control for Control/Status/Address Register and Memory Write Commands

The host must use proper flow control for write commands (**write_pdi**, **write_pdi++**, **write_pah**, **write_pal**, **write_pcon**, or **write_hscratch**) using one of two methods:

1. After the host initiates a write cycle, it can monitor the PRDY pin to determine if **PDI** is already full. If so, the host can extend the access and wait for the PIU to assert PRDY.
2. If the host is unable to use the PRDY pin for flow control, it can monitor the PIBF field (**PCON**[1]—see Table 73 on page 133) before initiating the transaction. For example, the host can execute the following pseudocode:

```

Do:
    Issue a read_pcon command to the core    // Host read of PCON.
    Repeat until PIBF == 0                  // Wait for PIBF = 0.
    Issue the write_pdi command             // Write word into PDI.
    
```

1. A core can coordinate host data read commands by program control, but this is very inefficient compared to using the DMAU for this purpose.

4 Hardware Architecture (continued)

4.15 Parallel Interface Unit (PIU) (continued)

4.15.6 Host Command Examples

4.15.6.1 Download of Program or Data

This example illustrates a host download to DSP16410B TPRAM1 (CORE1) memory. Download will begin at address 0x0 in TPRAM1 and proceed for 1000 16-bit words. For all the following steps, the host must observe proper flow control.

1. First, the host must write the starting address into the **PA** register. The starting address is location 0x0 in TPRAM1, so the host issues the following two host write commands:

```
write_pah 0x0010      // Host sets PADD[3:0] to 0x8 and writes 0x0010 to PD[15:0]
write_pal 0x0         // Host sets PADD[3:0] to 0xA and writes 0x0 to PD[15:0]
```

2. Next, the host begins to write the data to TPRAM1. This is done by repeatedly issuing the following command 999 times. Each iteration writes the appropriate data to be loaded to each sequential 16-bit location in TPRAM1.

```
write_pdi++ data      // Host sets PADD[3:0] to 0x1 and writes data to PD[15:0]
```

3. For the write of the last data word (in this example, the 1000th word), the host issues the following command:

```
write_pdi data_      // Host sets PADD[3:0] to 0x0 and writes data_ to PD[15:0]
```

4.15.6.2 Upload of Data

This example illustrates a host upload from DSP16410B TPRAM0 (CORE0) memory. The upload begins at address 0x0200 in TPRAM0 and proceeds for 160 16-bit words. For all the following steps, the host must observe proper flow control.

1. First, the host must write the starting address into the **PA** register. The starting address is location 0x0200 in TPRAM0, so the host issues the following two host write commands:

```
write_pah 0x0         // Host sets PADD[3:0] to 0x8 and writes 0x0 to PD[15:0].
write_pal 0x0200      // Host sets PADD[3:0] to 0xA and writes 0x0200 to PD[15:0].
```

2. Next, the host begins to read the data from TPRAM0, as transferred to the PIU's **PDO** register via the DMAU. This is done by first issuing the following command which drives PD[15:0] with the data from TPRAM0 address 0x00200:

```
read_pdo++ // Host sets PADD[3:0]=0x1 and reads data (address 0x00200) on PD[15:0].
           // (PIU requests DMAU to fetch single word from address 0x00200.)
```

3. The host then issues the following commands. Because the address is initially misaligned, the first command causes the PIU to request the DMAU to fetch a single word. For the remaining commands, the PIU requests the DMAU to fetch a double word for every other command.

```
rdpf_pdo++ // Host sets PADD[3:0]=0x3 and reads data (address 0x00201) on PD[15:0].
           // (PIU requests DMAU to fetch single word from address 0x00201.)
rdpf_pdo++ // Host sets PADD[3:0]=0x3 and reads data (address 0x00202) on PD[15:0].
           // (PIU requests DMAU to fetch double word from address 0x00202.)
rdpf_pdo++ // Host sets PADD[3:0]=0x3 and reads data(address 0x00203)on PD[15:0].
           ⋮
           // Repeat rdpf_pdo++ command 156 more times for a total of 159 times.
```

Note: The host **must not** issue a command that reads or writes **PA**, **PCON**, **HSCRATCH**, or **DSCRATCH** within a series of **rdpf_pdo++** commands.

4 Hardware Architecture (continued)

4.15 Parallel Interface Unit (PIU) (continued)

4.15.7 PIU Interrupts

A core can request an interrupt to the host by setting the PINT field (**PCON**[3]—see [Table 73 on page 133](#)). If this field is initially cleared and the core sets it, the PIU asserts (high) the PINT pin. The host must clear this field after servicing the PINT request to allow a core to request a subsequent interrupt. It clears the field by writing 1 to it.

The host can request an interrupt to the cores by setting the HINT field (**PCON**[4]—see [Table 73 on page 133](#)). If this field is initially cleared and the host sets it, the PIU asserts the PHINT interrupt to the cores. The interrupted core's service routine must clear this field after servicing the PHINT request to allow the host to request a subsequent interrupt. It clears the field by writing 1 to it. See [Section 4.4](#) for more information on interrupts.

4 Hardware Architecture (continued)

4.16 Serial Interface Unit (SIU)

The DSP16410B provides two identical serial interface units (SIU) to interface to codecs and various time division multiplex (TDM) bit streams. Each SIU is a full-duplex, double-buffered serial port with independent input and output frame and bit clock control. The SIU can generate clocks and frame syncs internally (active) or can use clocks and frame syncs generated externally (passive). The programmable modes of the SIU provide for T1/E1 and ST-bus compatibility.

The SIU control registers **SCON** $\langle 0-12 \rangle$, the SIU status registers (**STAT** and **FSTAT**), and the SIU input and output channel index registers (**ICIX** $\langle 0-1 \rangle$ and **OCIX** $\langle 0-1 \rangle$) are memory-mapped into the DSP16410B shared I/O memory component (see [Section 4.5.7 on page 42](#)). [Section 4.16.15 on page 181](#) provides a detailed description of the encoding of these registers.

The DMAU supports each SIU with two bidirectional SWT (single-word transfer) channels. SIU0 is directly connected to DMAU channels SWT0 and SWT1. SIU1 is directly connected to DMAU channels SWT2 and SWT3. The SWT channels provide transfers between the SIU input and output data registers and any DSP16410B memory space with minimal core overhead. Each of the SWT channels can perform two-dimensional memory accesses to support the buffering of TDM data to or from the SIU. Refer to [Section 4.13 on page 63](#) for more information on the DMAU.

Each SIU provides two interrupt signals directly to each DSP core, indicating the completion of an input or output transaction. Each core can individually enable or mask these interrupts by programming the core's **inc0** register.

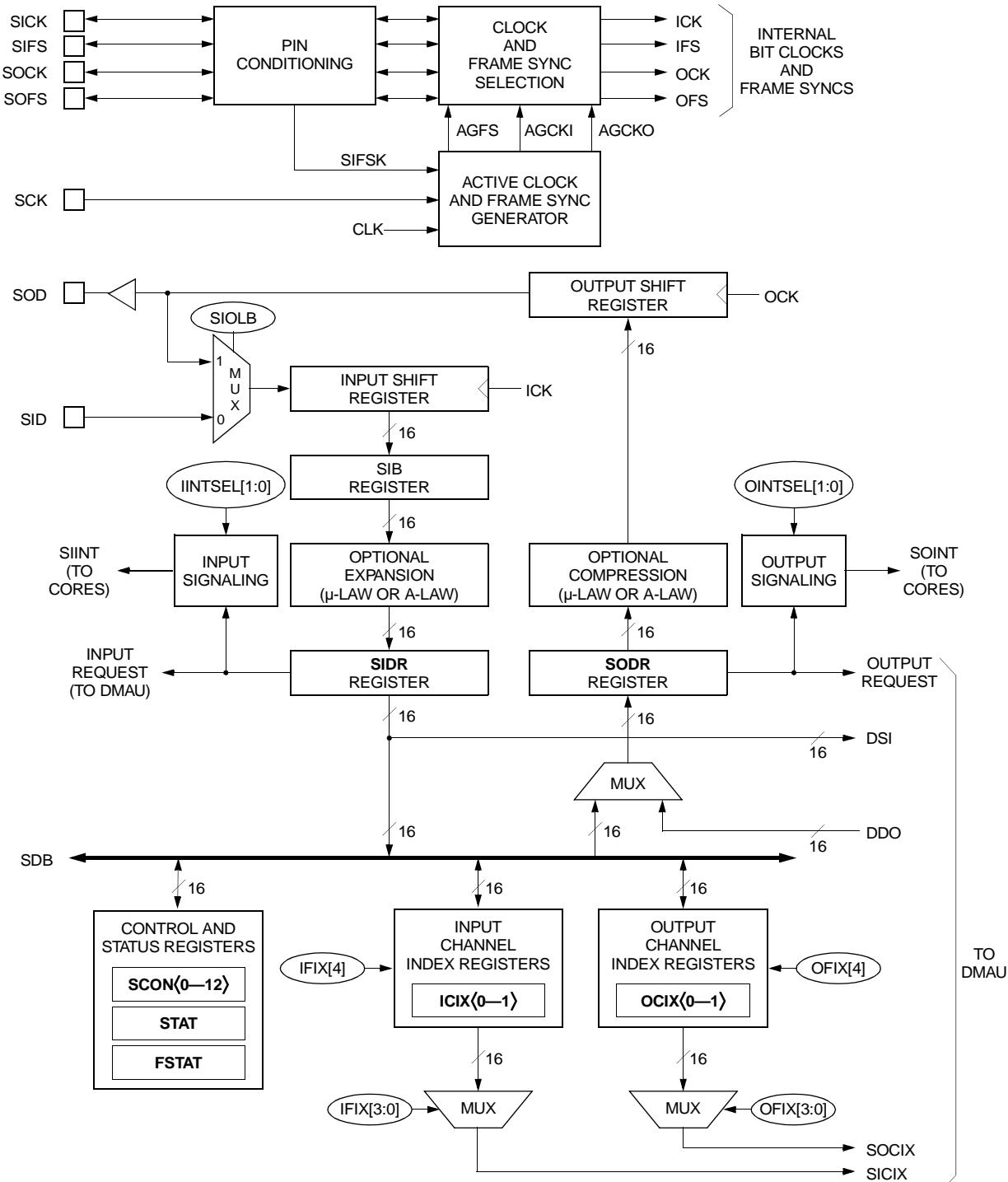
The DSP16410B SIU provides the following features:

- Two modes of operation—channel mode and frame mode:
 - Both modes support a maximum frame size of 128 logical channels.
 - Frame mode selects all channels within a given frame.
 - Channel mode with a maximum of 32 channels in two subframes allows minimum core intervention (a core configures the input and output sections independently only once or on frame boundaries).
 - Channel mode with a maximum of 128 channels in eight subframes is achievable if a core configures the input and output sections independently on subframe boundaries.
- Independent input and output sections:
 - Programmable data length (4, 8, 12, or 16 bits).
 - LSB or MSB first.
 - Programmable frame sync active level, frequency, and position relative to the first data bit in the frame.
 - Programmable bit clock active level and frequency.
 - Programmable active or passive frame syncs and bit clocks.
- Compatible with T1/E1 and ST-bus framer devices.
- Hardware for μ -law and A-law companding.

4 Hardware Architecture (continued)

4.16 Serial Interface Unit (SIU) (continued)

Figure 40 is a block diagram of an SIU.



Note: The signals within ovals are control/status register bits. SIOLB is **SCON10**[8]. IFIX[6:0] is **FSTAT**[6:0]. OFIX[6:0] is **FSTAT**[14:8].

Figure 40. SIU Block Diagram

4 Hardware Architecture (continued)

4.16 Serial Interface Unit (SIU) (continued)

4.16.1 Hardware Interface

The system interface to the SIU consists of seven pins, described in [Table 88](#).

Table 88. SIU External Interface

Pin†	Type	Name	Description
SID	I	SIU Input Data	The SIU latches data from SID into its input shift register. By default, the SIU latches data from SID on each falling edge of the input bit clock.
SICK	I/O/Z	SIU Input Bit Clock	By default, SICK is configured as an input (passive) that provides the serial input bit clock. Alternatively, the SIU can generate the input bit clock internally and can drive this clock onto the SICK output (active).
SIFS	I/O/Z	SIU Input Frame Sync	SIFS specifies the beginning of a new input frame. By default, SIFS is active-high and is configured as an input (passive). Alternatively, the SIU can generate the input frame sync internally and can drive this sync onto the SIFS output (active). To support a 2x ST-Bus interface, SIFS can be configured as an input that synchronizes the internally generated (active) input and output bit clocks.
SOD	O/Z	SIU Output Data	The SIU drives data onto SOD from its output shift register. By default, the SIU drives data onto SOD on each rising edge of the output bit clock. The SIU 3-states SOD during inactive or masked channel periods.
SOCK	I/O/Z	SIU Output Bit Clock	By default, SOCK is configured as an input (passive) that provides the serial output bit clock. Alternatively, the SIU can generate the output bit clock internally and can drive this clock onto the SOCK output (active).
SOFS	I/O/Z	SIU Output Frame Sync	SOFS specifies the beginning of a new output frame. By default, SOFS is active-high and is configured as an input (passive). Alternatively, the SIU can generate the output frame sync internally and can drive this sync onto the SOFS output (active).
SCK	I	SIU External Clock Source	SCK is an input that provides an external clock source for generating the active mode input and output bit clocks and frame syncs.

† The name of the pins has a 0 suffix for SIU0 and a 1 suffix for SIU1.

4 Hardware Architecture (continued)

4.16 Serial Interface Unit (SIU) (continued)

4.16.2 Pin Conditioning Logic, Bit Clock Selection Logic, and Frame Sync Selection Logic

Figure 41 on page 155 diagrams the pin conditioning logic, bit clock selection logic, and frame sync selection logic. This logic is controlled by fields in the **SCON10**, **SCON3**, **SCON2**, and **SCON1** registers as detailed in Table 89. Input functional timing is described in detail in Section 4.16.3 on page 156. Output functional timing is described in detail in Section 4.16.4 on page 157. Active clock and frame sync generation is described in detail in Section 4.16.5 on page 158. SIU loopback is described in detail in Section 4.16.7 on page 165.

Table 89. Control Register Fields for Pin Conditioning, Bit Clock Selection, and Frame Sync Selection

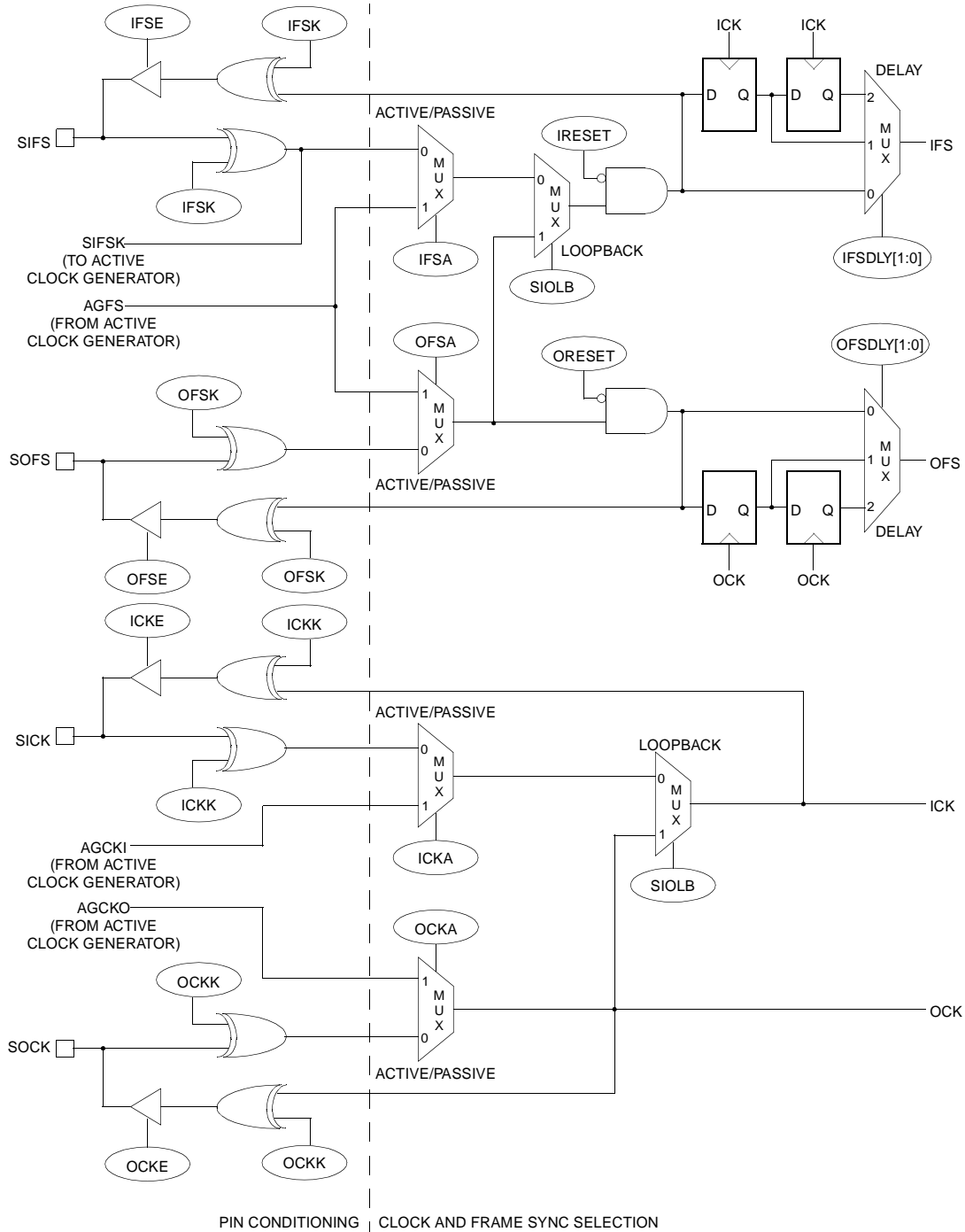
Field		Value	Description
SIOLB	SCON10 [8]	0	Disable SIU loopback mode.
		1	Enable SIU loopback mode.
OCKK	SCON10 [7]	0	The SIU drives output data onto SOD on the rising edge of the output bit clock.
		1	The SIU drives output data onto SOD on the falling edge of the output bit clock.
OCKA	SCON10 [6]	0	The output bit clock is provided externally on the SOCK pin (passive).
		1	The output bit clock is internally generated (active).
OFSK	SCON10 [5]	0	The output frame sync is active-high.
		1	The output frame sync is active-low.
OFSA	SCON10 [4]	0	The output frame sync is provided externally on the SOFS pin (passive).
		1	The output frame sync is internally generated (active).
ICKK	SCON10 [3]	0	The SIU latches input data from SID on the falling edge of the output bit clock.
		1	The SIU latches input data from SID on the rising edge of the output bit clock.
ICKA	SCON10 [2]	0	The input bit clock is provided externally on the SICK pin (passive).
		1	The input bit clock is internally generated (active).
IFSK	SCON10 [1]	0	The input frame sync is active-high.
		1	The input frame sync is active-low.
IFSA	SCON10 [0]	0	The input frame sync is provided externally on the SIFS pin (passive).
		1	The input frame sync is internally generated (active).
OFSE†	SCON3 [15]	0	Do not drive internally generated output frame sync onto SOFS.
		1	Drive internally generated output frame sync onto SOFS.
OCKE†	SCON3 [14]	0	Do not drive internally generated output bit clock onto SOCK.
		1	Drive internally generated output bit clock onto SOCK.
IFSE†	SCON3 [7]	0	Do not drive internally generated input frame sync onto SIFS.
		1	Drive internally generated input frame sync onto SIFS.
ICKE†	SCON3 [6]	0	Do not drive internally generated input bit clock onto SICK.
		1	Drive internally generated input bit clock onto SICK.
ORESET	SCON2 [10]	0	Activate output section and begin output processing after next output frame sync.
		1	Deactivate output section and initialize bit and frame counters.
OFSDLY[1:0]	SCON2 [9:8]	00	Do not delay output frame sync.
		01	Delay output frame sync by one cycle of the output bit clock.
		10	Delay output frame sync by two cycles of the output bit clock.
IRESET	SCON1 [10]	0	Activate input section and begin input processing after next input frame sync.
		1	Deactivate input section and initialize bit and frame counters.
IFSDLY[1:0]	SCON1 [9:8]	00	Do not delay input frame sync.
		01	Delay input frame sync by one cycle of the input bit clock.
		10	Delay input frame sync by two cycles of the input bit clock.

† Set this field in active mode only, i.e., if the corresponding OCKA/OFSA/ICKA/IFSA field is set.

4 Hardware Architecture (continued)

4.16 Serial Interface Unit (SIU) (continued)

4.16.2 Pin Conditioning Logic, Bit Clock Selection Logic, and Frame Sync Selection Logic (continued)



Note: The signals within ovals are control register fields. SIOLB is **SCON10**[8], IFSE is **SCON3**[7], IFSK is **SCON10**[1], IFSA is **SCON10**[0], IRESET is **SCON1**[10], IFSDLY[1:0] is **SCON1**[9:8], OFSE is **SCON3**[15], OFSK is **SCON10**[5], OFSA is **SCON10**[4], ORESET is **SCON2**[10], OFSDLY[1:0] is **SCON2**[9:8], ICKE is **SCON3**[6], ICKK is **SCON10**[3], ICKA is **SCON10**[2], OCKE is **SCON3**[14], OCKK is **SCON10**[7], and OCKA is **SCON10**[6].

Figure 41. Pin Conditioning Logic, Bit Clock Selection Logic, and Frame Sync Selection Logic

4 Hardware Architecture (continued)

4.16 Serial Interface Unit (SIU) (continued)

4.16.3 Basic Input Processing

The SIU begins input processing when the user software clears the IRESET field (**SCON1**[10]). The system application must ensure that the input bit clock is applied before IRESET is cleared. If an input bit clock is active (internally generated), the user program must wait at least two bit clock cycles between changing AGRESET (**SCON12**[15]) and clearing IRESET. If the DMAU is used to service the SIU, the user software must activate the DMAU channel before clearing IRESET.

Figure 42 illustrates the default functional input timing. SICK (SIU input bit clock) synchronizes all SIU input transactions. The SIU samples SIFS (SIU input frame sync) on the rising edge of SICK. If the SIU detects a rising edge of SIFS, it initiates input processing for a new frame. The SIU latches data bits from SID (SIU input data) on the falling edge of SICK for active channels (i.e., channels selected via software).

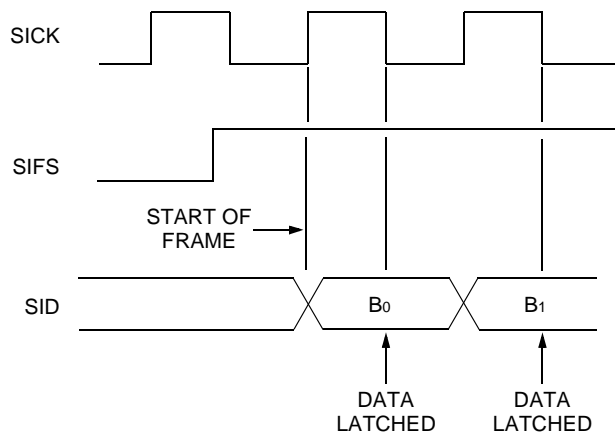


Figure 42. Default Serial Input Functional Timing

To vary the functional input timing from the default operation described above, either core can program control register fields as follows:

- If either core sets the ICKK field (**SCON10**[3])—see Table 111 on page 188), the SIU inverts SICK and:
 - Detects the assertion of SIFS on the falling edge of SICK.
 - Latches data from SID on each rising edge of SICK.
- If the software sets the IFSK field (**SCON10**[1]), SIFS is active-low and the start of a new frame is specified by a high-to-low transition (falling edge) on SIFS detected by an activating edge¹ of the input bit clock.
- By default, the SIU latches the first data bit of an input frame from SID one phase of SICK after the detection of the input frame sync. Either core can increase this delay by one or two input bit clock cycles by programming the IFSDLY[1:0] field (**SCON1**[9:8])—see Table 102 on page 183).

An externally generated input bit clock can drive SICK (passive mode) or the SIU can generate an internal input bit clock that can be applied to SICK (active mode). An externally generated input frame sync can drive SIFS (passive mode) or the SIU can generate an internal input frame sync that can be applied to SIFS (active mode). See Section 4.16.5 on page 158 for details on clock and frame sync generation.

Note: The combination of passive input bit clock and active input frame sync is not supported.

The SIU clocks in the data for the selected channel into a 16-bit input shift register (see Figure 40 on page 152). After the SIU clocks in a complete 4, 8, 12, or 16 bits according to the ISIZE[1:0] field (**SCON0**[4:3])—see Table 101 on page 182), it transfers the data to **SIB** (serial input buffer register) and sets the SIBV (serial input buffer valid) flag (**STAT**[1])—see Table 116 on page 194). **SIB** is not a user-accessible register. Either core can program the IMSB field (**SCON0**[2]) to select MSB- or LSB-first data transfer from the input shift register to **SIB**. For data lengths that are less than 16 bits, the SIU right justifies the data (places the data in the lower bit positions) in **SIB** and fills the upper bits with zeros.

1. The activating edge of the input bit clock is the rising edge of the clock if the ICKK field (**SCON10**[3]) is cleared and the falling edge of the clock if the ICKK field is set.

4 Hardware Architecture (continued)

4.16 Serial Interface Unit (SIU) (continued)

4.16.3 Basic Input Processing (continued)

If **SIDR** (serial input data register) is empty (the **SIDV** flag (**STAT**[0]) is cleared), the following actions occur:

1. The SIU formats the data (μ -law, A-law, or no modification) in **SIB** according to the **IFORMAT**[1:0] field (**SCON0**[1:0]—see [Table 101 on page 182](#)).
2. The SIU transfers the formatted data to **SIDR**.
3. The SIU clears the **SIBV** (serial input buffer valid) flag (**STAT**[1]).
4. The SIU sets the **SIDV** flag to indicate that **SIDR** is full.
5. The SIU signals the DMAU that serial input data is ready for transfer to memory.
6. If the **IINTSEL**[1:0] field (**SCON10**[12:11]—see [Table 111 on page 188](#)) equals two, the SIU asserts the **SIINT** interrupt to the cores to request service.

Data remains in **SIDR** and **SIDV** remains set until the data is read by the DMAU or by one of the cores. After **SIDR** has been read, the DSP16410B clears the **SIDV** flag.

If new data is completely shifted in before the old data in **SIB** is transferred to **SIDR** (i.e., while **SIBV** and **SIDV** are both set), an input buffer overflow occurs and the new data overwrites the old data. The SIU sets the **IOFLOW** field (**STAT**[6]) to reflect this error condition. If the **IINTSEL**[1:0] field (**SCON10**[12:11]) equals three, the SIU asserts the **SIINT** interrupt to the cores to reflect this condition.

4.16.4 Basic Output Processing

The SIU begins output processing when the user software clears the **ORESET** field (**SCON2**[10]). The system application must ensure that the output bit clock is applied before **ORESET** is cleared. If an output bit clock is active (internally generated), the user program must wait at least four bit clock cycles between changing **AGRESET** (**SCON12**[15]) and clearing **ORESET**. If the DMAU is used to service the SIU, the user software must activate the DMAU channel before clearing **ORESET**.

[Figure 43](#) illustrates the default serial functional output timing. **SOCK** (SIU output bit clock) synchronizes all SIU output transactions. The SIU samples **SOFS** (SIU

output frame sync) on the rising edge of **SOCK**. If the SIU detects a rising edge of **SOFS**, it initiates output processing for a new frame. The SIU drives data bits onto **SOD** (SIU output data) on the rising edge of **SOCK** for active channels (i.e., channels selected via software). The SIU 3-states **SOD** for inactive channels and during idle periods. (See [Section 4.16.8 on page 165](#) for details.)

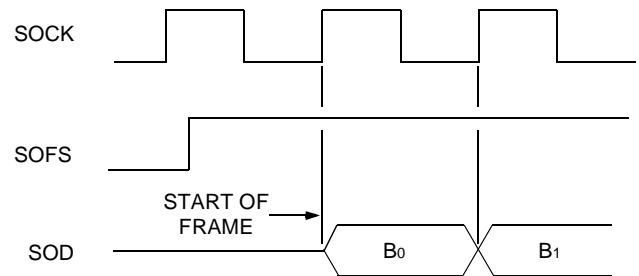


Figure 43. Default Serial Output Functional Timing

To vary the serial function output timing from the default operation described above, either core can program control register fields as follows:

- If either core sets the **OCKK** field (**SCON10**[7]—see [Table 111 on page 188](#)), the SIU inverts **SOCK** and:
 - Detects the assertion of **SOFS** on the falling edge of **SOCK**.
 - Drives data onto **SOD** on each falling edge of **SOCK**.
- If either core sets the **OFSK** field (**SCON10**[5]), **SOFS** is active-low and the start of a new frame is specified by a high-to-low transition (falling edge) on **SOFS** detected by an activating edge¹ of the output bit clock.
- By default, the SIU drives output data onto **SOD** immediately after the detection of the output frame sync. Either core can program the **OFSDLY**[1:0] field (**SCON2**[9:8]—see [Table 103 on page 184](#)) to cause the SIU to delay driving data onto **SOD** by one or two output bit clock cycles.

SOCK can provide an externally generated output bit clock (passive mode) or the SIU can generate an internal output bit clock (active mode) that can be applied to **SOCK**. **SOFS** can provide an externally generated output frame sync (passive mode) or the SIU can generate an internal output frame sync (active mode) that can be applied to **SOFS**. See [Section 4.16.5 on page 158](#) for details on clock and frame sync generation.

Note: The combination of passive output bit clock and active output frame sync is not supported.

1. The activating edge of the output bit clock is the rising edge if the **OCKK** field (**SCON10**[7]) is cleared and falling edge if the **OCKK** field is set.

4 Hardware Architecture (continued)

4.16 Serial Interface Unit (SIU) (continued)

4.16.4 Basic Output Processing (continued)

The DMAU or either of the cores writes output data into **SODR** (serial output data register). See [Figure 40 on page 152](#). If **SODR** is empty, the SIU clears the SODV flag (serial output data valid, **STAT**[3]—[Table 116 on page 194](#)). This indicates that a core or the DMAU can write new data to **SODR**. The following describes the sequence of events that follow this condition:

1. The SIU signals the DMAU that it is ready to accept new data. If the OINTSEL[1:0] field (**SCON10**[14:13]) equals two, the SIU generates the SOINT interrupt signal to both cores.
2. The DMAU or one of the cores writes **SODR** with new data.
3. The SIU sets SODV to indicate that **SODR** is full.
4. At the beginning of the time slot for the next active channel (on an activating edge of the output bit clock), the SIU transfers the contents of **SODR** to the 16-bit output shift register, clears SODV, and drives the first data bit onto SOD. While transferring the data from **SODR** to the output shift register, the SIU formats the data (μ -law, A-law, or no modification) according to the value of the OFORMAT[1:0] field (**SCON0**[9:8]—see [Table 101 on page 182](#)). Based on the value of the OMSB field (**SCON0**[10]), the SIU shifts the data out LSB-first or MSB-first. Based on the value of the OSIZE[1:0] field (**SCON0**[12:11]), the SIU drives 4, 8, 12, or 16 bits of the data in the output shift register onto SOD. If OSIZE[1:0] is programmed to select a data size of 4, 8, or 12 bits, the data must be right-justified (placed in the least significant bits) of the 16-bit **SODR** register.

Output buffer underflow can occur if the DMAU or core does not write new data into **SODR** before the contents of **SODR** is to be transferred to the output shift register. Specifically, an output buffer underflow occurs if all three of the following conditions exist:

- **SODR** is empty (SODV = 0).
- The output shift register is empty.
- The time slot for an active channel is pending.

If output buffer underflow occurs, the SIU sets the OUFLOW field (**STAT**[7]) and continues to output the old data in **SODR** (repeats step 4) for any active channels until the DMAU or core writes new data to **SODR**. If the OINTSEL[1:0] field (**SCON10**[14:13]) equals three, the SIU asserts the SOINT interrupt to notify the cores of the underflow condition.

4.16.5 Clock and Frame Sync Generation

Generation of the SIU bit clocks (SICK and SOCK) and frame syncs (SIFS and SOFS) can be active or passive. In active mode, these signals can be derived from the DSP clock, CLK, or from an external clock source applied to the SCK pin. In either case, the active clock source is divided down by a programmable clock divider to generate the desired bit clock and frame sync frequencies. In passive mode, the external clock source applied to the SICK pin is used directly as the input bit clock, the signal applied to SIFS is used directly as the input frame sync, the clock source applied to the SOCK pin is used directly as the output bit clock, and the signal applied to SOFS is used as the output frame sync. All of the bit fields that control bit clock and frame sync generation are summarized in [Table 90 on page 161](#).

The input section and the output section of each SIU operate independently and require individual clock sources to be specified.

Note: The combination of passive input bit clock and active input frame sync is not supported, and the combination of passive output bit clock and active output frame sync is not supported. If the combination of an active bit clock and a passive frame sync is selected, the frame sync must be derived from the bit clock and must meet the timing requirements specified in [Section 11.11](#).

The default operation specifies that the SIU clocks input data bits from SID on the falling edge of SICK and drive output data bits onto SOD on the rising edge of SOCK. The DSP16410B can invert the polarity (active level) of the SICK pin by setting the ICKK field (**SCON10**[3]—see [Table 111 on page 188](#)) and the polarity (active level) of the SOCK pin by setting the OCKK field (**SCON10**[7]). The SIU can generate one or both bit clocks internally (active) or externally (passive). Setting the ICKA field (**SCON10**[2]) puts SICK into active mode, and setting the OCKA field (**SCON10**[6]) puts SOCK into active mode.

4 Hardware Architecture (continued)

4.16 Serial Interface Unit (SIU) (continued)

4.16.5 Clock and Frame Sync Generation (continued)

Active bit clocks are generated by dividing down either the internal clock (CLK) or a clock source applied to the SCK pin, depending on the AGEXT field (**SCON12**[12]—see [Table 113 on page 192](#)). The active clock generator must also be enabled by clearing the AGRESET field (**SCON12**[15]) and programming a divide ratio into the AGCKLIM[7:0] field (**SCON11**[7:0]—see [Table 112 on page 191](#)). If either bit clock is internally generated, the corresponding clock pin (SICK or SOCK) is an output that can be turned off by clearing the ICKE field (**SCON3**[6]—see [Table 104 on page 185](#)) or the OCKE field (**SCON3**[14]—see [Table 104 on page 185](#)), placing the corresponding pin into 3-state.

Passive bit clocks are externally generated and applied directly to the corresponding SICK or SOCK pins. In this case, the ICKA or OCKA field (**SCON10**[2] or **SCON10**[6]) is cleared. The program should disable the active clock generator by setting the AGRESET field (**SCON12**[15]) only if both clocks and both frame syncs are externally generated.

The default operation of the SIU specifies the active level of the input and output frame sync pins to be active-high, so the rising edge of SIFS or SOFS indicates the beginning of an input or output frame, respectively. The program can invert the active level (active-low) by setting the IFSK and OFSK fields (**SCON10**[1] and **SCON10**[5]). The program can configure one or both frame syncs as internally generated (active) or externally generated (passive), based on the states of the IFSA and OFSA fields (**SCON10**[0] and **SCON10**[4]).

The active frame syncs are generated by dividing down the internally generated active mode bit clock. The active clock generator must also be enabled by clearing the AGRESET field (**SCON12**[15]) and by programming a divide ratio into the AGFSLIM[10:0] field (**SCON12**[10:0]). If either frame sync is internally generated, the corresponding frame sync pin (SIFS or SOFS) is an output that can be turned off by clearing the IFSE field (**SCON3**[7]—see [Table 104 on page 185](#)) or the OFSE field (**SCON3**[15]—see [Table 104 on page 185](#)), placing the corresponding pin into 3-state.

Passive frame syncs are externally generated and applied directly to the SIFS or SOFS pins. In this case, the IFSA field (**SCON10**[0]—see [Table 111 on page 188](#)) or the OFSA field (**SCON10**[4]) is cleared. The program should disable the active clock generator by setting the AGRESET field (**SCON12**[15]—see [Table 113 on page 192](#)) only if both frame syncs and both bit clocks are externally generated.

The active clock generator has the ability to synchronize to an external source (SIFS). If the AGSYNC field of (**SCON12**[14]) is set, the internal clock generator is synchronized by SIFS. This feature is used **only** if an external clock source is applied to the SCK pin and drives the internal clock generator, i.e., if the program set the AGEXT field (**SCON12**[12]). A typical application for using external synchronization is an ST-bus interface that employs a 2X external clock source. This feature is discussed in more detail in the next section.

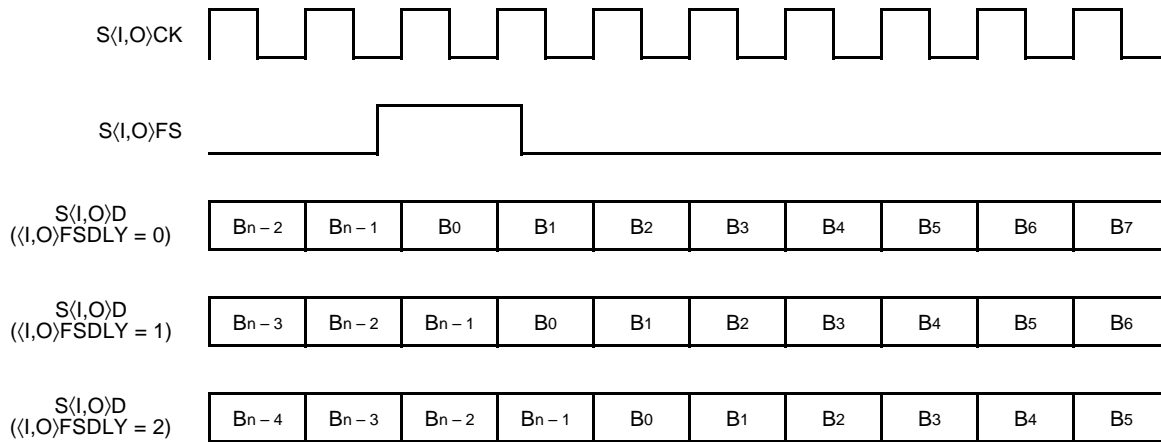
The active clock generator also has the ability to provide additional input data setup time if an external source (the SCK pin, selected by AGEXT = 1) is selected to generate the input and output bit clocks. If the I2XDLY field (**SCON1**[11]—see [Table 102 on page 183](#)) is set, the high phase of the internally generated input bit clock, ICK, is stretched by one SCK phase, providing extra data capture time. This feature is illustrated in [Figure 53 on page 180](#).

The relative location of data bit 0 of a new frame can be delayed by a maximum of two bit clock periods with respect to the location of the frame sync. This feature is controlled by the IFSDLY[1:0] field (**SCON1**[9:8]—see [Table 102 on page 183](#)) for input and the OFSDLY[1:0] field (**SCON2**[9:8]—see [Table 103 on page 184](#)) for output. The location of the leading edge of frame sync is approximately coincident with bit 0 by default. However, bit 0 can be delayed by one or two bit clocks after frame sync as shown in [Figure 44](#).

4 Hardware Architecture (continued)

4.16 Serial Interface Unit (SIU) (continued)

4.16.5 Clock and Frame Sync Generation (continued)



5-7849 (F)

Figure 44. Frame Sync to Data Delay Timing

4 Hardware Architecture (continued)

4.16 Serial Interface Unit (SIU) (continued)

4.16.5 Clock and Frame Sync Generation (continued)

Table 90. A Summary of Bit Clock and Frame Sync Control Register Fields

Bit Field	Register	Description
AGRESET	SCON12[15]	Enables the internal active clock divider/generator.
AGSYNC	SCON12[14]	Enables synchronization of the internal active clock generator to SIFS. If set, AGEXT must also be set. This feature is enabled for 2x ST-bus operation.
SCKK	SCON12[13]	Defines the active level of the external clock source, SCK.
AGEXT	SCON12[12]	Defines the clock source to the internal clock divider/generator (either the DSP CLK or external SCK pin).
AGFSLIM[10:0]	SCON12[10:0]	Defines the clock divider ratio for the internal generation of frame syncs (active mode).
AGCKLIM[7:0]	SCON11[7:0]	Defines the clock divider ratio for the internal generation of bit clocks (active mode).
SIOLB	SCON10[8]	Enables SIU loopback mode. See Section 4.16.7 on page 165 .
OCKK	SCON10[7]	Defines the active level of the SOCK pin.
OCKA†	SCON10[6]	Defines SOCK as internally (active mode, SOCK is an output) or externally (passive mode, SOCK is an input) generated.
OFSK	SCON10[5]	Defines the active level of the SOFS pin.
OFSA†	SCON10[4]	Defines SOFS as internally (active mode, SOFS is an output) or externally (passive mode, SOFS is an input) generated.
ICKK	SCON10[3]	Defines the active level of the SICK pin.
ICKA†	SCON10[2]	Defines SICK as internally (SICK is an output) or externally (SICK is an input) generated.
IFSK	SCON10[1]	Defines the active level of the SIFS pin.
IFSA†	SCON10[0]	Defines SIFS as internally (active mode, SIFS is an output) or externally (passive mode, SIFS is an input) generated.
IFSE	SCON3[7]	For active mode SIFS, this bit determines if the SIFS pin is driven as an output.
ICKE	SCON3[6]	For active mode SICK, this bit determines if the SICK pin is driven as an output.
OFSE	SCON3[15]	For active mode SOFS, this bit determines if the SOFS pin is driven as an output.
OCKE	SCON3[14]	For active mode SOCK, this bit determines if the SOCK pin is driven as an output.
I2XDLY	SCON1[11]	If set, the SIU stretches the high phase of the internally generated input bit clock, ICK, by one SCK phase to provide additional serial input data setup (capture) time. This feature is valid only if AGEXT = 1 and ICKA = 1.

† The combination of passive output bit clock (OCKA = 0) and active output frame sync (OFSA = 1) is not supported. The combination of passive input bit clock (ICKA = 0) and active input frame sync (IFSA = 1) is not supported.

4 Hardware Architecture (continued)

4.16 Serial Interface Unit (SIU) (continued)

4.16.5 Clock and Frame Sync Generation (continued)

Table 91 offers three typical settings for the SIU control register fields that determine bit clock and frame sync generation. The term **as required** used in this table refers to the user's system requirements.

- Example 1 shows the bit field values if both bit clocks and frame syncs are supplied directly from an external serial device (e.g., a codec).

- Example 2 shows the bit field values if both bit clocks and frame syncs are active and generated directly from the internal clock, CLK. This example assumes that the SICK, SOCK, SIFS, and SOFS pins are outputs driven by the SIU.
- Example 3 shows the bit field values if both bit clocks and the output frame sync are active and generated directly from the external clock source applied to the SCK pin. The SIFS pin is driven by an external source and is used to synchronize the internal frame bit counter. The SICK, SOCK, and SOFS pins are not driven by the SIU, and the high phase of the internal input bit clock is stretched. These settings are valid for a double-rate clock ST-bus interface. The effect of these SIU control register settings is illustrated by Figure 53 on page 180.

Table 91. Examples of Bit Clock and Frame Sync Control Register Fields

Bit Field	Register	Example 1 All Passive	Example 2 All Active (CLK)	Example 3 All Active (SCK) Double-Rate ST-Bus
AGRESET	SCON12[15]	1	0	0
AGSYNC	SCON12[14]	0	0	1
SCKK	SCON12[13]	0	0	1
AGEXT	SCON12[12]	0	0	1
AGFSLIM[10:0]	SCON12[10:0]	0	as required	as required
AGCKLIM[7:0]	SCON11[7:0]	0	as required	1
SIOLB	SCON10[8]	0	0	0
OCKK	SCON10[7]	as required	as required	as required
OCKA†	SCON10[6]	0	1	1
OFSK	SCON10[5]	as required	as required	as required
OFSA†	SCON10[4]	0	1	1
ICKK	SCON10[3]	as required	as required	as required
ICKA†	SCON10[2]	0	1	1
IFSK	SCON10[1]	as required	as required	1
IFSA†	SCON10[0]	0	1	1
IFSE	SCON3[7]	0	1	0
ICKE	SCON3[6]	0	1	0
OFSE	SCON3[15]	0	1	0
OCKE	SCON3[14]	0	1	0
I2XDLY	SCON1[11]	0	0	1

† The combination of passive output bit clock (OCKA = 0) and active output frame sync (OFSA = 1) is not supported. The combination of passive input bit clock (ICKA = 0) and active input frame sync (IFSA = 1) is not supported.

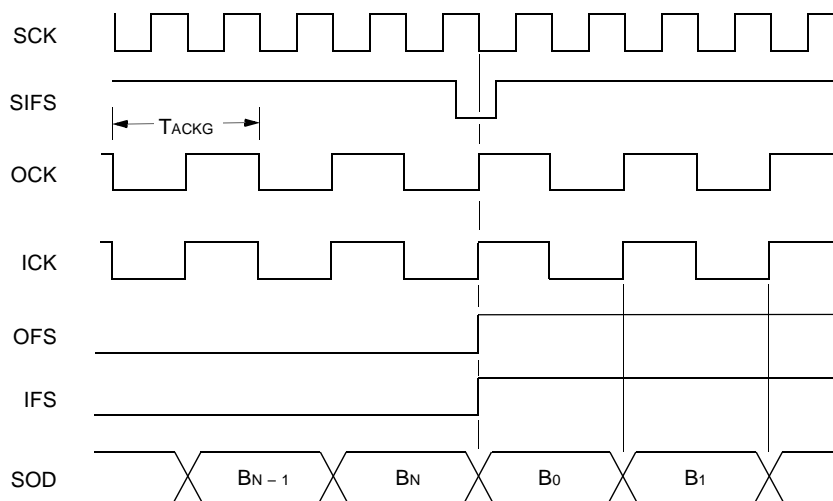
4 Hardware Architecture (continued)

4.16 Serial Interface Unit (SIU) (continued)

4.16.6 ST-Bus Timing Examples

Figures 45 and 46 illustrate SIU timing examples for 2x ST-bus compatibility, which requires active clock generation with SCK as the clock source and SIFS synchronization enabled (AGEXT = 1, IFSA = 1, and AGSYNC = 1). The input frame sync, SIFS, is externally generated.

Figure 45 illustrates the functional timing of the internally generated bit clocks, ICK and OCK, assuming the bit clock divide ratio is two (AGCKLIM = 1). This results in bit clocks that have a period that is twice the period of SCK. Since the divide ratio is even, the duty cycle of the generated bit clock is 50%. Also shown are the internally generated frame syncs, IFS and OFS. Refer to Figure 40 on page 152 for a block diagram of the internal clock generator.



Note: The timing reference TACKG is the active clock period determined by the AGCKLIM[7:0] field (SCON11[7:0]).

Figure 45. Clock and Frame Sync Generation with External Clock and Synchronization (AGEXT = AGSYNC = IFSA = IFSK = 1 and Timing Requires No Resynchronization)

4 Hardware Architecture (continued)

4.16 Serial Interface Unit (SIU) (continued)

4.16.6 ST-Bus Timing Examples (continued)

Figure 46 illustrates the functional timing of the internally generated bit clocks and frame syncs, ICK, OCK, IFS, and OFS, assuming the bit clock divide ratio is two ($AGCKLIM = 1$, same as Figure 45 on page 163) and SIFS is asserted while the internally generated bit clocks are high. In this case, the internal bit clocks are forced to remain high at the falling edge of SIFS. This effectively stretches the internal bit clocks by one SCK cycle, synchronizing the internal bit clocks to the external frame sync, SIFS. As a result, the first frame following synchronization is lost. The SIU 3-states the SOD pin during the lost frame. Subsequent frames are synchronized and function correctly. The dotted lines in this figure show the location of SIFS and the active bit clocks and syncs if SIFS had occurred one SCK cycle later (i.e., if the internal frame bit counter had expired prior to the assertion of SIFS, the same as Figure 45).

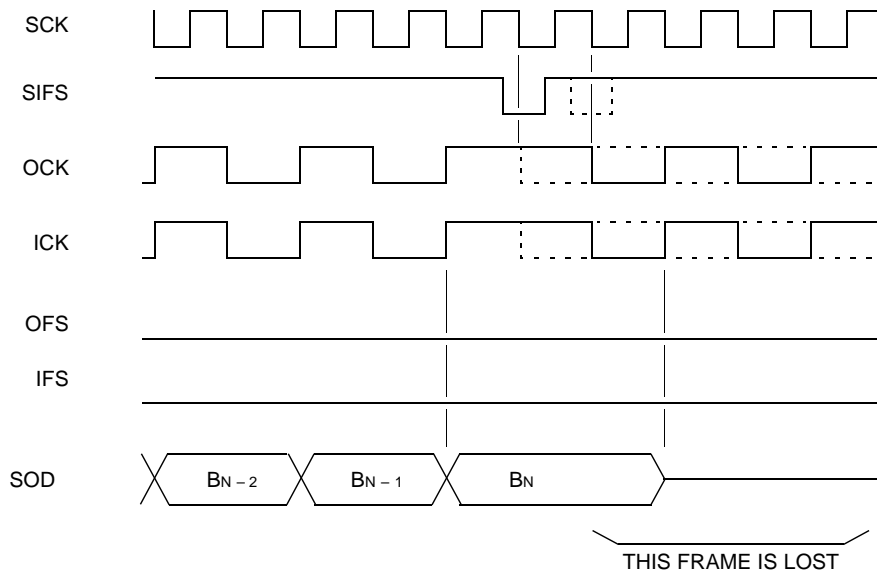


Figure 46. Clock and Frame Sync Generation with External Clock and Synchronization (AGEXT = AGSYNC = IFSA = IFSK = 1 and Timing Requires Resynchronization)

4 Hardware Architecture (continued)

4.16 Serial Interface Unit (SIU) (continued)

4.16.7 SIU Loopback

Each SIU of the DSP16410B includes an internal diagnostic mode to verify functionality of the SIU without requiring system intervention. If the SIOLB field (**SCON10**[8]—see [Table 111 on page 188](#)) is set, the SIU output data pin (SOD) is internally looped back to the SIU input data pin (SID), the output bit clock is internally connected to the input bit clock, and the output frame sync is internally connected to the input frame sync. Any input at the SID pin is ignored while loopback is enabled.

There are two ways that SIU loopback can be used:

1. The user's code can define the output bit clock and output frame sync to be active and the input bit clock and input frame sync to be passive. See [Section 4.16.5](#) for information on configuring the bit clocks and frame syncs as active or passive. If SIU loopback is enabled, the active signals generate the necessary clocks and frame syncs for the SIU to send and receive data to itself. Unless enabled by the user, the SICK, SOCK, SIFS, and SOFS pins are 3-state. To enable these outputs, set the ICKE, OCKE, IFSE, and OFSE fields (see **SCON3** in [Table 104 on page 185](#)).

2. The user's code can define all the SIU clocks and syncs to be passive. See [Section 4.16.5](#) for information on configuring the bit clocks and frame syncs as active or passive. The system must supply a bit clock to the SOCK pin and a frame sync to the SOFS pin.

4.16.8 Basic Frame Structure

The primary data structure processed by the SIU is a frame, a sequence of bits that is initiated by a frame sync. Each input and output frame is composed of a number of channels, as determined by the IFLIM[6:0] field (**SCON1**[6:0]—[Table 102 on page 183](#)) for input and the OFLIM[6:0] field (**SCON2**[6:0]—[Table 103 on page 184](#)) for output. Each channel consists of 4, 8, 12, or 16 bits, as determined by the ISIZE[1:0] and OSIZE[1:0] fields (**SCON0**[4:3] and **SCON0**[12:11]—see [Table 101 on page 182](#)), and has a programmable data format (μ -law, A-law, or linear) as determined by the IFORMAT[1:0] and OFORMAT[1:0] fields (**SCON0**[1:0] and **SCON0**[9:8]). All channels in a frame must have the same data length and data format. [Figure 47](#) illustrates the basic frame structure assuming five channels per frame ($\langle I, O \rangle$ IFLIM[6:0] = 4) and a channel size of 8 bits ($\langle I, O \rangle$ SIZE[1:0] = 0). [Figure 48 on page 166](#) illustrates the same frame structure with idle time. The SIU 3-states the SOD pin during idle time.

Note: If the output section is configured for a one-channel frame (OFLIM[6:0] = 0x0) and a passive frame sync (OFSA(**SCON10**[4]) = 0), the SOFS frame sync interval must be constant and a multiple of the OCK output bit clock.

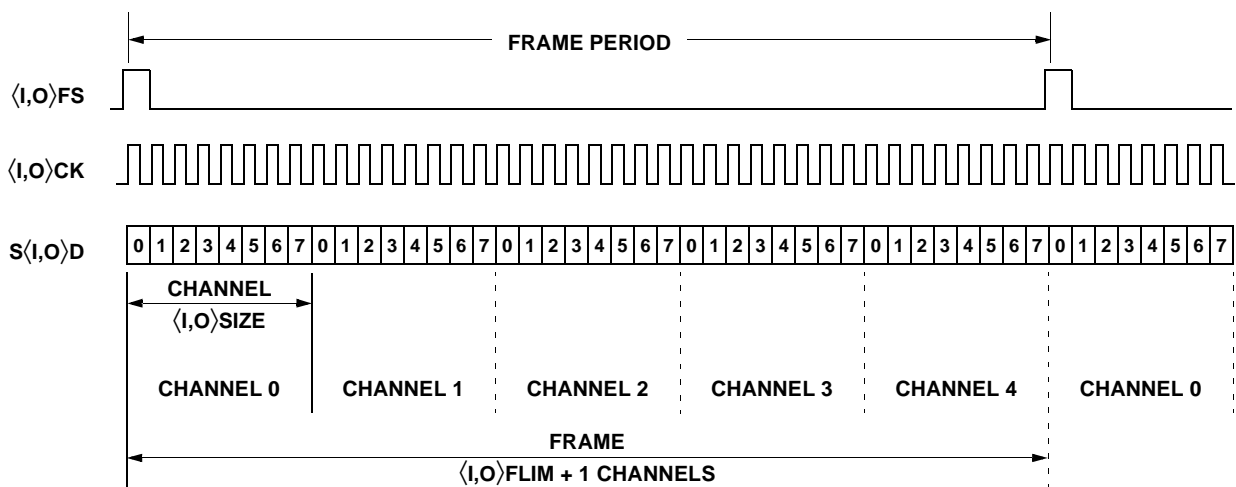
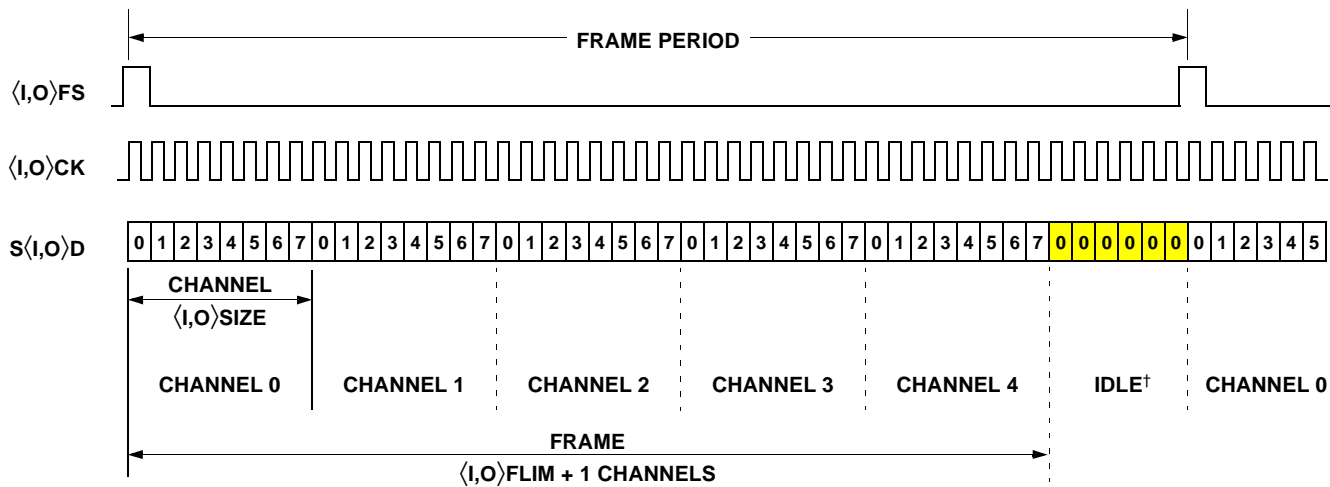


Figure 47. Basic Frame Structure

4 Hardware Architecture (continued)

4.16 Serial Interface Unit (SIU) (continued)

4.16.8 Basic Frame Structure (continued)



† The SIU 3-states SOD during idle time.

Figure 48. Basic Frame Structure with Idle Time

To assist channel selection within a frame, a frame is partitioned into a maximum of eight subframes. Each subframe has 16 logical channels, for a total channel capacity of 128 channels per frame.

4.16.9 Assigning SIU Logical Channels to DMAU Channels

Regardless of the operating mode, the channel index registers for the SIU must be initialized via software if the DMAU is used to transfer data to and from memory. There are a total of four 16-bit channel index registers: two for input (**ICIX** $\langle 0-1 \rangle$) and two for output (**OCIX** $\langle 0-1 \rangle$). Each bit corresponds to one logical channel within the currently selected even or odd subframe. These bit fields determine the assignment of logical channels within a subframe to a specific DMAU SWT channel dedicated to that SIU. Recall that two bidirectional SWT channels of the DMAU support each SIU so that logical channels can be routed to two separate memory spaces.

In channel mode, **ICIX0** corresponds to the currently selected even input subframe, as determined by the ISFID_E[1:0] field (**SCON3**[1:0])—see Table 104 on

page 185). **ICIX1** corresponds to the currently selected odd input subframe, as determined by the ISFID_O[1:0] field (**SCON3**[4:3]). **OCIX0** corresponds to the currently selected even output subframe, as determined by the OSFID_E[1:0] field (**SCON3**[9:8])—see Table 104 on page 185). **OCIX1** corresponds to the currently selected odd output subframe, as determined by the OSFID_O[1:0] field (**SCON3**[12:11]). In frame mode, **ICIX** $\langle 0-1 \rangle$ and **OCIX** $\langle 0-1 \rangle$ are circularly mapped to multiple channels in the frame as illustrated by Table 120 on page 196 and Table 119 on page 195.

If a bit field of SIU0's **ICIX** $\langle 0-1 \rangle$ or **OCIX** $\langle 0-1 \rangle$ register is cleared, the corresponding logical channel of SIU0 is assigned to SWT0. If a bit field of these registers is set to one, the corresponding logical channel of SIU0 is assigned to SWT1. If a bit field of SIU1's **ICIX** $\langle 0-1 \rangle$ or **OCIX** $\langle 0-1 \rangle$ register is cleared, the corresponding logical channel of SIU1 is assigned to SWT2. If a bit field of these same registers is set to one, the corresponding logical channel of SIU1 is assigned to SWT3. For example, to assign SIU0 input channels 0 to 7 to SWT0 and 8 to 15 to SWT1, the value written to **ICIX0** is 0xFF00.

4 Hardware Architecture (continued)

4.16 Serial Interface Unit (SIU) (continued)

4.16.10 Frame Error Detection and Reporting

The SIU supports back-to-back frame processing. However, when a frame has completed, the SIU stops processing until the beginning of another frame is detected by sampling a new frame sync. If the new frame sync is detected before a frame has completed, the following actions are taken by the SIU:

1. An interrupt request is generated, if enabled. Specifically, if the occurrence of SIFS is detected before the end of the input frame, an input error has occurred. If enabled via the IINTSEL[1:0] field (**SCON10**[12:11]—see [Table 111 on page 188](#)), the SIINT interrupt is asserted to the DSP cores. If the occurrence of SOFS is detected before the end of the output frame, an output error has occurred. If enabled via the OINTSEL[1:0] field (**SCON10**[14:13]), the SOINT interrupt is asserted to the cores.
2. The IFERR flag (input frame error) or OFERR flag (output frame error) is set in the **STAT** register ([Table 116 on page 194](#)), as appropriate. All sub-frame, channel, and bit counters are reinitialized and a new input or output frame transaction is initiated. The data from the incomplete frame can be erroneous and the core software should perform error recovery in response to the setting of IFERR or OFERR.
3. If the SIU is in passive mode (clocks and frame sync are externally generated) or in active mode with the AGSYNC field (**SCON12**[14]) cleared, the new frame transaction begins immediately after the new frame sync is detected. If the SIU is in active mode with AGSYNC set and an externally generated clock is applied to SCK, the new frame transaction begins after the detection of the first frame sync that does not cause resynchronization of the bit clocks. See [Section 4.16.6 on page 163](#) for details on resynchronizing bit clocks in active mode.

4.16.11 Frame Mode

Frame mode allows for a high channel capacity, but sacrifices channel selectivity. A program selects frame mode by setting the IFRAME field (**SCON1**[7]—[Table 102 on page 183](#)) for input and the OFRAME field (**SCON2**[7]—see [Table 103 on page 184](#)) for output. In this mode, the SIU processes all channels in the frame. A maximum of 128 consecutive channels in the frame can be accessed. The IFLIM[6:0] field

(**SCON1**[6:0]) and OFLIM[6:0] field (**SCON2**[6:0]) define the number of channels in each input and output frame.

If using frame mode, the user performs the following steps in software:

1. Configure the number of channels in the frame structure (1 to 128) by programming the IFLIM[6:0] field with the input frame size, and the OFLIM[6:0] field with the output frame size. The input and output frame size is the number of channels minus one. For simple serial communications (one channel per frame), these fields should be programmed to zero.
2. Configure the channel size (4, 8, 12, or 16 bits) by writing the ISIZE[1:0] and OSIZE[1:0] fields (**SCON0**[4:3] and **SCON0**[12:11]—see [Table 101 on page 182](#)). Select LSB-first or MSB-first by programming the IMSB and OMSB fields (**SCON0**[2] and **SCON0**[10]). Configure the data format by programming the IFORMAT[1:0] and OFORMAT[1:0] fields (**SCON0**[1:0] and **SCON0**[9:8]).
3. Program **ICIX** $\langle 0-1 \rangle$ and **OCIX** $\langle 0-1 \rangle$ (the 16-bit channel index registers, see [Table 118 on page 195](#)) to assign specific SIU input and output channels to be routed to one of two DMAU SWT channels (SWT0 or SWT1 for SIU0; SWT2 or SWT3 for SIU1). The maximum number of channels that **ICIX** $\langle 0-1 \rangle$ or **OCIX** $\langle 0-1 \rangle$ can specify is 32 (two 16-bit registers). If the number of channels is greater than 32, the DMAU routing specified for channels 0—31 is applied to channels 32—63, channels 64—95, etc., as shown in [Table 120 on page 196](#) and [Table 119 on page 195](#). For the special case of simple serial communications (one channel per frame), program channels 0 and 1 to the same value, i.e., program **ICIX** $\langle 0-1 \rangle$ [1:0] to the same value for input and **OCIX** $\langle 0-1 \rangle$ [1:0] to the same value for output.
4. Enable frame mode by setting IFRAME (**SCON1**[7]) and OFRAME (**SCON2**[7]).
5. Disable channel mode by clearing the ISFIDV_E field (**SCON3**[2]—see [Table 104 on page 185](#)), ISFIDV_O field (**SCON3**[5]), OSFIDV_E field (**SCON3**[10]), and OSFIDV_O field (**SCON3**[13]).
6. Select passive vs. active bit clocks and frame syncs (see [Section 4.16.5 on page 158](#) for details).
7. Program the IINTSEL[1:0] field (**SCON10**[12:11]) OINTSEL[1:0] field (**SCON10**[14:13]) as required by the application.
8. Begin input and output processing by clearing the IRESET field (**SCON1**[10]) and the ORESET field (**SCON2**[10]).

4 Hardware Architecture (continued)

4.16 Serial Interface Unit (SIU) (continued)

4.16.12 Channel Mode—32 Channels or Less in Two Subframes or Less

Compared to frame mode, channel mode provides for channel selectivity with minimal core overhead at the expense of channel density. For input, this mode is selected if the following conditions are met:

- The IFRAME field (**SCON1**[7])—see Table 102 on page 183) is cleared.
- The ISFIDV_E field (**SCON3**[2])—see Table 104 on page 185), the ISFIDV_O field (**SCON3**[5]), or both are set.

For output, channel mode is selected if the following conditions are met:

- The OFRAME field (**SCON2**[7])—see Table 102 on page 183) is cleared.

- The OSFIDV_E field (**SCON3**[10]), the OSFIDV_O field (**SCON3**[13]), or both are set.

In this mode, the SIU processes a maximum of 32 channels within a given frame. The maximum frame size is 128 channels. The IFLIM[6:0] field (**SCON1**[6:0])—Table 102 on page 183) for input and the OFLIM[6:0] field (**SCON2**[6:0])—Table 103 on page 184) for output define the number of channels in the frame structure.

To assist with channel selection, both input and output frames are divided into eight subframes: four even (0, 2, 4, 6) and four odd (1, 3, 5, 7). The SIU can enable only one even and one odd subframe at any one time. Each subframe contains 16 channels¹ that can be individually enabled. Figure 49 shows a 128-channel frame and the relationship between frames, subframes, and logical channels. Table 92 on page 169 specifies the association of channel numbers to even and odd subframes.

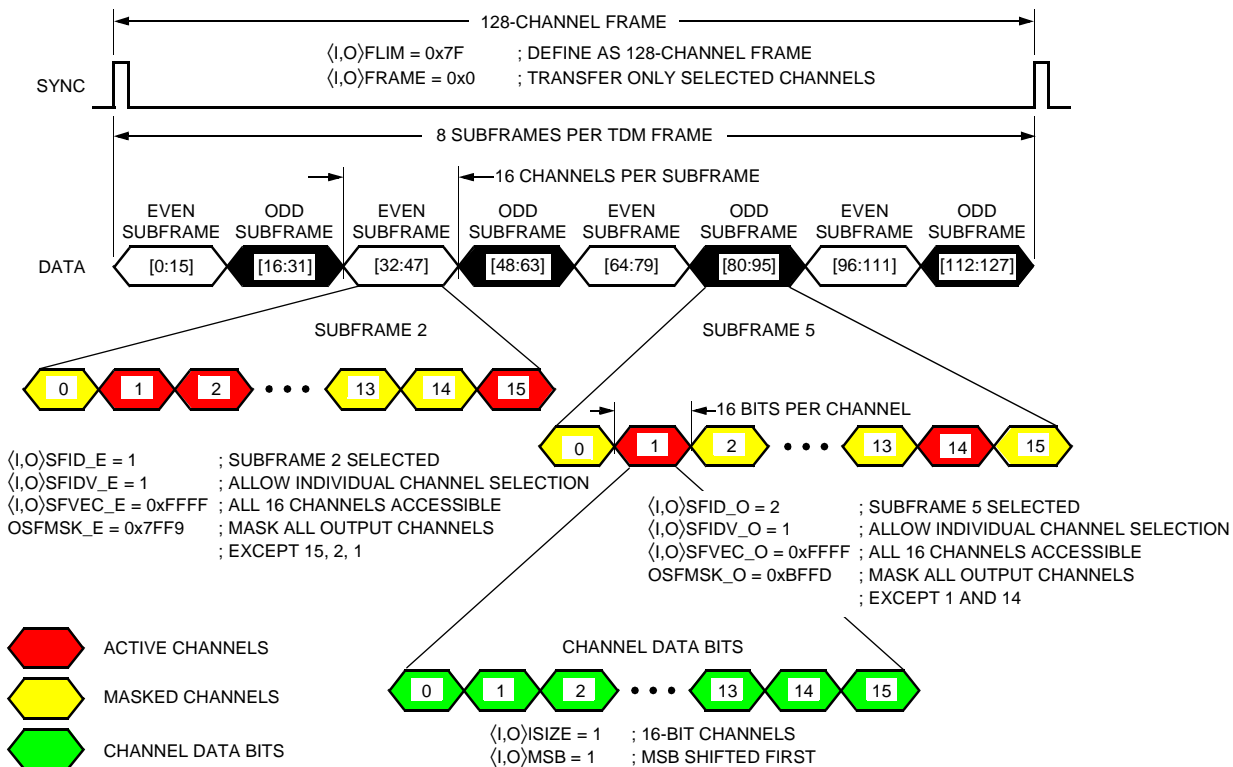


Figure 49. Channel Mode on a 128-Channel Frame

1. It is assumed that for channel mode, the number of channels per frame as determined by the IFLIM[6:0] and OFLIM[6:0] fields is evenly divisible by 16. This results in exactly 16 channels per subframe. If the number of channels per frame is not evenly divisible by 16, the last subframe is a partial subframe of less than 16 channels. If this is the case and if interrupts are programmed to occur on subframe boundaries (see Figure 51 on page 175), then an interrupt is not generated for the partial subframe.

4 Hardware Architecture (continued)

4.16 Serial Interface Unit (SIU) (continued)

4.16.12 Channel Mode—32 Channels or Less in Two Subframes or Less (continued)

Table 92. Subframe Definition

Even Subframes		Odd Subframes	
Subframe	Channels	Subframe	Channels
0	0—15	1	16—31
2	32—47	3	48—63
4	64—79	5	80—95
6	96—111	7	112—127

For SIU processing of specific logical channels, the user enables at least one active even or odd subframe within the input and output frames and defines the even (0, 2, 4, or 6) or odd (1, 3, 5, or 7) input and output subframe ID. Within each active subframe, active input channels and active output channels are individually selected via the channel activation vectors. These features are controlled by the SIU control memory-mapped registers, **SCON**(3—9).

In channel mode, the SIU drives data onto the SOD pin only during the time slots for active output channels. Otherwise, the SIU 3-states SOD. Similarly, in channel mode, the SIU latches input data bits only during the time slots for active input channels.

If the DMAU is used to transfer SIU input data to memory, each active input channel (time slot) can be individually routed to a specific SWT channel. See [Section 4.16.9 on page 166](#) for details.

4 Hardware Architecture (continued)

4.16 Serial Interface Unit (SIU) (continued)

4.16.12 Channel Mode—32 Channels or Less in Two Subframes or Less (continued)

If using channel mode, the user performs the following steps in software:

1. Configure the number of channels in the frame structure (1 to 128) by programming the IFLIM[6:0] field (**SCON1**[6:0]—see [Table 102 on page 183](#)) with the frame size for input and the OFLIM[6:0] field (**SCON2**[6:0]—see [Table 103 on page 184](#)) with the frame size for output.
2. Configure the channel size (4, 8, 12, or 16 bits) by writing the ISIZE[1:0] and OSIZE[1:0] fields (**SCON0**[4:3] and **SCON0**[12:11]—see [Table 101 on page 182](#)). Select LSB-first or MSB-first by programming the IMSB and OMSB fields (**SCON0**[2] and **SCON0**[10]). Configure the data format by programming the IFORMAT[1:0] and OFORMAT[1:0] fields (**SCON0**[1:0] and **SCON0**[9:8]).
3. Disable frame mode by clearing the IFRAME field (**SCON1**[7]—see [Table 102 on page 183](#)) and the OFRAME field (**SCON2**[7]—see [Table 103 on page 184](#)).
4. Select the number of subframes (one or two) to be enabled. If two subframes are enabled, one must be even and one must be odd. See step 5.
5. Select the active subframe(s) and channels within each subframe. [Tables 93 to 97](#) further detail the bit fields described below.
 - To activate an even input subframe, set the ISFIDV_E field (**SCON3**[2]—see [Table 104 on page 185](#)). Also program the ISFID_E[1:0] field (**SCON3**[1:0]) with the address of the active even subframe (active subframe number is $2 \times \text{ISFID_E}$). Within the active subframe, up to 16 logical channels can be individually enabled via the ISFVEC_E[15:0] field (**SCON4**—see [Table 105 on page 186](#)). For each enabled channel, assign one of two DMAU SWT channels by setting or clearing the corresponding bit in **ICIX0** ([Table 120 on page 196](#)).
 - To activate an odd input subframe, set the ISFIDV_O field (**SCON3**[5]—see [Table 104 on page 185](#)). Also program the ISFID_O[1:0] field (**SCON3**[4:3]) with the address of the active odd subframe (active subframe number is $(2 \times \text{ISFID_O}) + 1$). Within the active subframe, up to 16 logical channels can be individually

enabled via the ISFVEC_O[15:0] field (**SCON5**—see [Table 106 on page 186](#)). For each enabled channel, assign one of two DMAU SWT channels by setting or clearing the corresponding bit in **ICIX1** ([Table 120 on page 196](#)).

- To activate an even output subframe, set the OSFIDV_E field (**SCON3**[10]). Also program the OSFID_E[1:0] field (**SCON3**[9:8]) with the address of the active even subframe (active subframe number is $2 \times \text{OSFID_E}$). Within the active subframe, up to 16 logical channels can be individually enabled via the OSFVEC_E[15:0] field (**SCON6**—see [Table 107 on page 187](#)). Any enabled channel can be individually masked via the OSFMSK_E[15:0] field (**SCON8**—see [Table 109 on page 187](#)). Masking an output channel retains the data structure (the DMAU counters are updated) but does not drive data onto SOD for that channel period. For each enabled channel, assign one of two DMAU SWT channels by setting or clearing the corresponding bit in **OCIX0** ([Table 119 on page 195](#)).
 - To activate an odd output subframe, set the OSFIDV_O field (**SCON3**[13]). Also program the OSFID_O[1:0] field (**SCON3**[12:11]) with the address of the active odd subframe (active subframe number is $(2 \times \text{OSFID_O}) + 1$). Within the active subframe, up to 16 logical channels can be individually enabled via the OSFVEC_O[15:0] field (**SCON7**—see [Table 108 on page 187](#)). Any enabled channel can be individually masked via the OSFMSK_O[15:0] field (**SCON9**—see [Table 110 on page 187](#)). Masking an output channel retains the data structure (the DMAU counters are updated) but does not drive data onto SOD for that channel period. For each enabled channel, assign one of two DMAU SWT channels by setting or clearing the corresponding bit in **OCIX1** ([Table 119 on page 195](#)).
6. Select passive vs. active bit clocks and frame syncs (see [Table 4.16.5 on page 158](#) for details).
 7. Program the IINTSEL[1:0] field (**SCON10**[12:11]) OINTSEL[1:0] field (**SCON10**[14:13]) as required by the application.
 8. Begin processing the active channels by clearing the IRESET field (**SCON1**[10]—see [Table 102 on page 183](#)) and the ORESET field (**SCON2**[10]—see [Table 103 on page 184](#)). Further user software intervention for SIU configuration is only required to redefine the subframe enable, the subframe ID, or the active channels within a subframe and their associated channel index values.

4 Hardware Architecture (continued)

4.16 Serial Interface Unit (SIU) (continued)

4.16.12 Channel Mode—32 Channels or Less in Two Subframes or Less (continued)

Table 93. Location of Control Fields Used in Channel Mode

Input/ Output	Even Subframe Control		Odd Subframe Control		Description
	Field	Register	Field	Register	
Input	ISFIDV_E	SCON3[2]	ISFIDV_O	SCON3[5]	Subframe ID valid (enable).
	ISFID_E[1:0]	SCON3[1:0]	ISFID_O[1:0]	SCON3[4:3]	Subframe ID.
	ISFVEC_E[15:0]	SCON4[15:0]	ISFVEC_O[15:0]	SCON5[15:0]	Channel activation vector.
Output	OSFIDV_E	SCON3[10]	OSFIDV_O	SCON3[13]	Subframe ID valid (enable).
	OSFID_E[1:0]	SCON3[9:8]	OSFID_O[1:0]	SCON3[12:11]	Subframe ID.
	OSFVEC_E[15:0]	SCON6[15:0]	OSFVEC_O[15:0]	SCON7[15:0]	Channel activation vector.
	OSFMSK_E[15:0]	SCON8[15:0]	OSFMSK_O[15:0]	SCON9[15:0]	Channel masking vector.

Table 94. Description of Control Fields Used in Channel Mode

Input/ Output	Even Subframe Control		Odd Subframe Control	
	Field	Description	Field	Description
Input	ISFIDV_E	Enable even input subframes.	ISFIDV_O	Enable odd input subframes.
	ISFID_E[1:0]	Select one of four even input subframes 0, 2, 4, or 6 (active subframe = $2 \times \text{ISFID_E}$).	ISFID_O[1:0]	Select one of four odd input subframes 1, 3, 5, or 7 (active subframe = $(2 \times \text{ISFID_O}) + 1$).
	ISFVEC_E[15:0]	Bit vector activates up to 16 logical channels independently within selected even input subframe.	ISFVEC_O[15:0]	Bit vector activates up to 16 logical channels independently within selected odd input subframe.
Output	OSFIDV_E	Enable even output subframes.	OSFIDV_O	Enable odd output subframes.
	OSFID_E[1:0]	Select one of four even output subframes 0, 2, 4, or 6 (active subframe = $2 \times \text{OSFID_E}$).	OSFID_O[1:0]	Select one of four odd output subframes 1, 3, 5, or 7 (active subframe = $(2 \times \text{OSFID_O}) + 1$).
	OSFVEC_E[15:0]	Bit vector activates up to 16 logical channels independently within selected even output subframe.	OSFVEC_O[15:0]	Bit vector activates up to 16 logical channels independently within selected odd output subframe.
	OSFMSK_E[15:0]	Bit vector selects up to 16 logical channels independently within selected even output subframe to be masked [†] .	OSFMSK_O[15:0]	Bit vector selects up to 16 logical channels independently within selected odd output subframe to be masked [†] .

[†] If an output channel is masked, then the SOD pin is forced to the high-impedance state during that channel's time slot.

4 Hardware Architecture (continued)

4.16 Serial Interface Unit (SIU) (continued)

4.16.12 Channel Mode—32 Channels or Less in Two Subframes or Less (continued)

Table 95. Subframe Selection

Input/ Output	Even/Odd Subframes	To Select Subframe	Set Control Bit		Configure Control Field		
			Name	Location	Name	Location	Value
Input	Even	0	ISFIDV_E	SCON3[2]	ISFID_E[1:0]	SCON3[1:0]	0
		2					1
		4					2
		6					3
	Odd	1	ISFIDV_O	SCON3[5]	ISFID_O[1:0]	SCON3[4:3]	0
		3					1
		5					2
		7					3
Output	Even	0	OSFIDV_E	SCON3[10]	OSFID_E[1:0]	SCON3[9:8]	0
		2					1
		4					2
		6					3
	Odd	1	OSFIDV_O	SCON3[13]	OSFID_O[1:0]	SCON3[12:11]	0
		3					1
		5					2
		7					3

Table 96. Channel Activation Within a Selected Subframe

Input/ Output	Selected Even/Odd Subframe	Control Field		
		Name	Location	Description
Input	Even	ISFVEC_E[15:0]	SCON4[15:0]	See Figure 50 on page 173.
	Odd	ISFVEC_O[15:0]	SCON5[15:0]	See Figure 50 on page 173.
Output	Even	OSFVEC_E[15:0]	SCON6[15:0]	See Figure 50 on page 173.
	Odd	OSFVEC_O[15:0]	SCON7[15:0]	See Figure 50 on page 173.

Table 97. Channel Masking Within a Selected Subframe

Input/ Output	Selected Even/Odd Subframe	Control Field		Description
		Name	Location	
Output	Even	OSFMSK_E[15:0]	SCON8[15:0]	See Figure 50 on page 173.
	Odd	OSFMSK_O[15:0]	SCON9[15:0]	See Figure 50 on page 173.

4 Hardware Architecture (continued)

4.16 Serial Interface Unit (SIU) (continued)

4.16.12 Channel Mode—32 Channels or Less in Two Subframes or Less (continued)

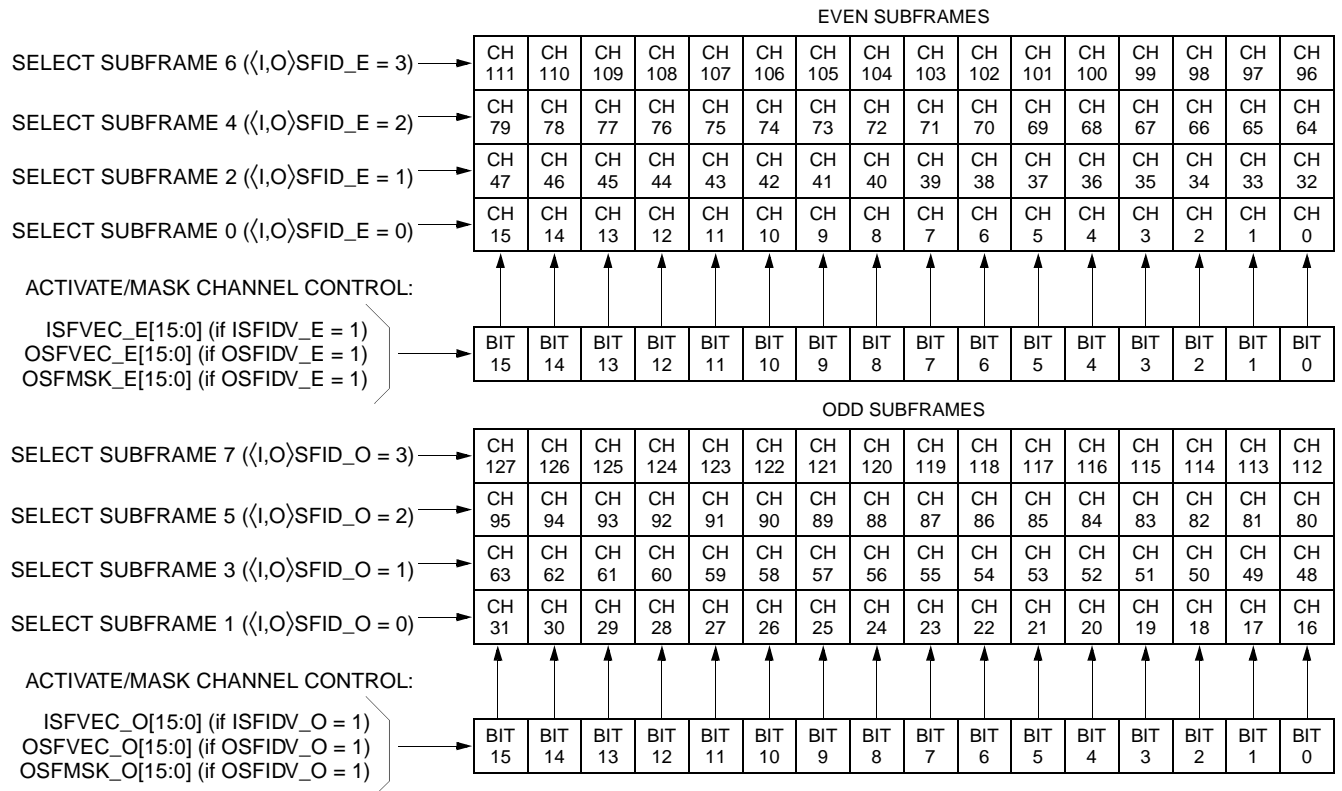


Figure 50. Subframe and Channel Selection in Channel Mode

4 Hardware Architecture (continued)

4.16 Serial Interface Unit (SIU) (continued)

4.16.13 Channel Mode—Up to 128 Channels in a Maximum of Eight Subframes

The SIU has the ability to process a maximum of 128 channels in channel mode if the SIU control is properly synchronized with core intervention. The steps required for the additional channel processing are the same as for the channel mode discussed in [Section 4.16.12](#). However, the SIU control registers must be reconfigured with greater frequency, costing additional core overhead. In this case, subframe activation and channel definition within a subframe can occur as often as every subframe boundary.

The SIU has the ability to interrupt either core at frame boundaries, subframe boundaries, channel boundaries, or if an error is detected (overflow or underflow). The interrupt signal trigger is determined by the IINT-SEL[1:0] field (**SCON10**[12:11]—see [Table 111 on page 188](#)) for input processing and by the OINT-SEL[1:0] field (**SCON10**[14:13]) for output processing. When servicing subframe boundary interrupts generated by SIU0 or SIU1, either CORE0 or CORE1 can modify the input and output subframe and channel control fields without affecting the current subframe being processed. Specifically, the cores can modify the OSFID_E[1:0] and OSFID_O[1:0] fields (**SCON3**—see [Table 104 on page 185](#)), the ISFID_E[1:0] and ISFID_O[1:0] fields (**SCON3**—see [Table 104 on page 185](#)), the ISFVEC_E[15:0] field (**SCON4**—see [Table 105 on page 186](#)), the ISFVEC_O[15:0] field (**SCON5**—see [Table 106 on page 186](#)), the OSFVEC_E[15:0] field (**SCON6**—see [Table 107 on page 187](#)), the OSFVEC_O[15:0] field (**SCON7**—see [Table 108 on page 187](#)), the OSFMSK_E[15:0] field (**SCON8**—see [Table 109 on page 187](#)), and the OSFMSK_O[15:0] field (**SCON9**—see [Table 110 on page 187](#)). This is also true for the **ICIX0**, **ICIX1**, **OCIX0**, and **OCIX1** registers (see [Table 120 on page 196](#) and [Table 119 on page 195](#)). The SIU latches the values in these control bit fields at the beginning of every subframe.

If one of the cores uses this feature in an SIINT or SOINT interrupt service routine (ISR), the SIU can be programmed to individually select channels for input or output anywhere within the frame. The user can take advantage of this feature by updating the input and output subframe and channel control fields after each subframe is processed, allowing channels in more than two subframes to be processed during each frame. This requires the ISR to count the subframe interrupts and program the necessary SIU control registers with the appropriate values to process the next desired subframe. The user also has the option of programming the input and output subframe and channel control fields two subframes in advance, as these bit fields are double-buffered. For example, if the active subframe is even, the user's ISR can reprogram the control bit fields with the appropriate values for the next even subframe without disturbing the processing of the currently active subframe.

In channel mode, the SIU drives data onto the SOD pin only during the time slots for active output channels. Otherwise, the SIU 3-states SOD. Similarly, in channel mode, the SIU latches input data bits only during the time slots for active input channels.

4 Hardware Architecture (continued)

4.16 Serial Interface Unit (SIU) (continued)

4.16.13 Channel Mode—Up to 128 Channels in a Maximum of Eight Subframes (continued)

Figure 51 illustrates the conditions under which the SIINT or SOINT input or output interrupt is asserted if the IINTSEL[1:0] or OINTSEL[1:0] field (**SCON10**[12:11] or **SCON10**[14:13]—see Table 111 on page 188) is programmed to cause the SIU to generate interrupts on subframe boundaries. The SIU computes the current channel number modulo 16. It compares this value to 15 and generates SIINT or SOINT if there is a match. This notifies the cores of the completion of the subframe.

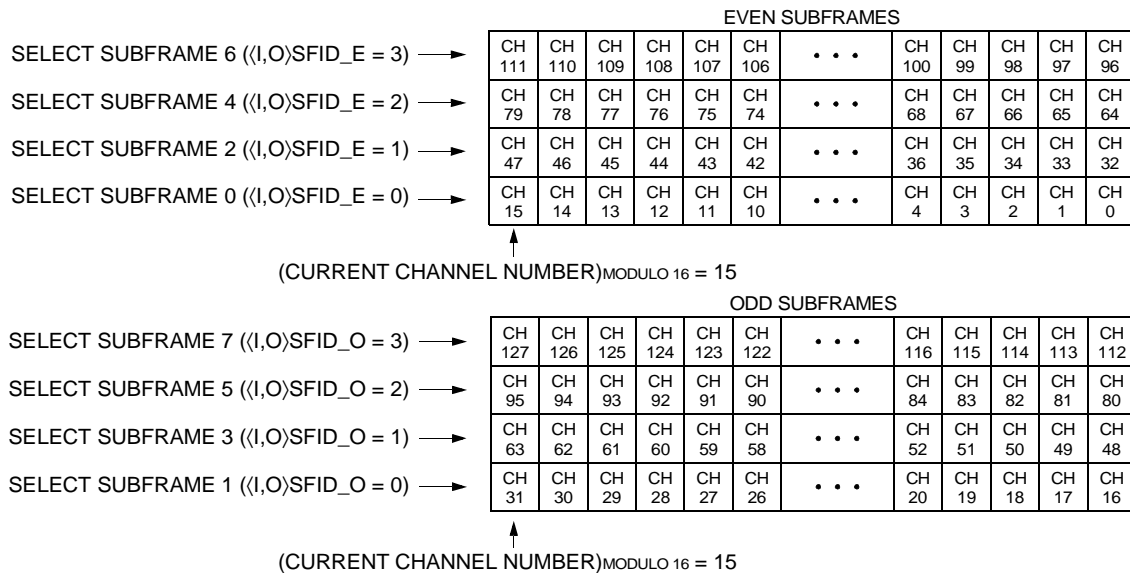


Figure 51. Generating Interrupts on Subframe Boundaries

4 Hardware Architecture (continued)

4.16 Serial Interface Unit (SIU) (continued)

4.16.13 Channel Mode—Up to 128 Channels in a Maximum of Eight Subframes (continued)

For example, the following steps are performed by software running in CORE0 to use SIU0 to process input channels 2, 3, 18, 20, 36, 55, 78, 100, and 111 as part of a 128-channel input frame. It is assumed that the DMAU SWT0 and SWT1 channels are used to transfer the input data to memory.

1. Initialize the SWT0 and SWT1 channels (see [Section 4.13.5 on page 86](#)).
2. Configure the channel size (4, 8, 12 or 16 bits) by writing the ISIZE[1:0] field (**SCON0**[4:3]—[Table 101 on page 182](#)). Select LSB-first or MSB-first by programming the IMSB field (**SCON0**[2]). Configure the data format by programming the IFORMAT[1:0] field (**SCON0**[1:0]).
3. Configure SIU0 for a 128-channel input frame structure by programming the IFLIM[6:0] field (**SCON1**[6:0]—[Table 102 on page 183](#)) to 127. Enable channel mode with two active subframes by clearing the IFRAME field (**SCON1**[7]) and setting the ISFIDV_E and ISFIDV_O fields (**SCON3**[2,5]—[Table 104 on page 185](#)). Program input interrupts to occur at every subframe boundary by programming the IINTSEL[1:0] field (**SCON10**[12:11]—[Table 111 on page 188](#)) to 0x1.
4. Program SIU0 with the active channels for the first even (channels 2 and 3) and odd (18 and 20) subframes. This is accomplished by writing the first subframe IDs (0 and 1) to the ISFID_E[1:0] and ISFID_O[1:0] fields (**SCON3**—see [Table 104 on page 185](#)) and enabling the channels within these subframes via the ISFVEC_E[15:0] field (**SCON4**—see [Table 105 on page 186](#)) and ISFVEC_O[15:0] field (**SCON5**—see [Table 106 on page 186](#)). In summary, ISFID_E[1:0] = 0, ISFID_O[1:0] = 0, ISVEC_E[15:0] = 0xC, and ISVEC_O[15:0] = 0x14.
5. Program the input channel index registers to assign each channel to either SWT0 or SWT1. The SWT channel chosen determines the destination of the data. In this example, channels 2 and 18 are assigned to SWT0, and channels 3 and 20 are assigned to SWT1. Therefore, **ICIX0** = 0x8 and **ICIX1** = 0x10.
6. Enable the SIINT interrupt (see [Section 4.4.6 on page 31](#)) and the SWT0 and SWT1 channels of the DMAU by setting the DRUN[1:0] fields (**DMCON0**[5:4]—[Table 31 on page 70](#)). Create a software-managed subframe counter and initialize the counter to zero. Clear the IRESET field (**SCON1**[10]—see [Table 102 on page 183](#)) to begin input data processing by SIU0. CORE0 can continue to process the user's application.
7. When the SIINT interrupt occurs, CORE0's ISR immediately reads the software-managed subframe counter to determine the current subframe in progress and increments the counter by one. The ISR then reprograms the SIU to process the next even subframe. In this example, the next even subframe is 2, so ISFID_E[1:0] is programmed to 0x1. The active channel for this subframe is 36, so ISVEC_E[15:0] is written with 0x10. **ICIX0** also must be reprogrammed to assign channel 36 to either SWT0 or SWT1. If SWT1 is selected, then **ICIX0** = 0x10. This active channel setting takes place at the next subframe boundary. This ISR is now complete and CORE0 returns to the previous activity.
8. When the next SIINT interrupt occurs, CORE0's ISR again reads the subframe counter to determine the current subframe in progress. If the counter value is 7, it is reset to zero; otherwise, the value is incremented by one. The ISR then reprograms SIU0 to process the next odd subframe. In this example, the next odd subframe is 3, so ISFID_O[1:0] is programmed to 0x1. The desired active channel for this subframe is 55, so ISVEC_O[15:0] is written with 0x80. **ICIX1** must also be reprogrammed to assign channel 55 to either SWT0 or SWT1. If SWT1 is selected, then **ICIX1** = 0x80. This active channel setting takes place at the next subframe boundary. This ISR is now complete, and CORE0 returns to the previous activity.
9. Steps 7 and 8 are repeated indefinitely, processing all eight subframes and then beginning again with subframe 0 of the next frame.

4 Hardware Architecture (continued)

4.16 Serial Interface Unit (SIU) (continued)

4.16.14 SIU Examples

The following sections illustrate examples of single-channel I/O and the ST-Bus interface.

4.16.14.1 Single-Channel I/O

If the SIU is interfaced directly to a single codec, the program typically configures the SIU as follows:

1. Enable frame mode operation, one channel per frame.
2. Configure the data length as required by the external device (4, 8, 12, or 16 bits).
3. Enable passive bit clocks and frame syncs, configured as required by the external device. See [Table 91 on page 162](#).

This configuration assumes that the codec device generates the bit clock and frame sync.

4 Hardware Architecture (continued)

4.16 Serial Interface Unit (SIU) (continued)

4.16.14 SIU Examples (continued)

4.16.14.2 ST-Bus Interface

The SIU is compatible with the *MITEL*¹ ST-bus. Both single and double-rate clock protocols are supported. Table 98 describes the SIU control field settings and resulting signals for both protocols.

Table 98. Control Register and Field Configuration for ST-Bus Interface

Control Field	Description		Value (Single-Rate Clock)	Value (Double-Rate Clock)
OSIZE[1:0]	SCON0[12:11]	Clear for 8-bit output data.	00	00
ISIZE[1:0]	SCON0[4:3]	Clear for 8-bit input data.	00	00
I2XDLY	SCON1[11]	Set to extend high phase of ICK.	0	1
IFSDLY[1:0]	SCON1[9:8]	Clear for no IFS delay.	00	00
OFSDLY[1:0]	SCON2[9:8]	Clear for no OFS delay.	00	00
OFSE	SCON3[15]	For active OFS, selects whether OFS is driven onto SOFS pin.	0	0
OCKE	SCON3[14]	Clear to not drive active OCK onto SOCK pin.	0	0
IFSE	SCON3[7]	For active IFS, selects whether IFS is driven onto SIFS pin.	0	0
ICKE	SCON3[6]	Clear to not drive active ICK onto SICK pin.	0	0
SIOLB	SCON10[8]	Clear to disable loopback.	0	0
OCKK	SCON10[7]	Clear to drive output data on rising edge of output bit clock.	0	X
OCKA	SCON10[6]	Clear to select passive OCK. Set to select active OCK.	0	1
OFSK	SCON10[5]	Set to invert OFS (active-low frame sync).	1	X
OFSA	SCON10[4]	Clear to select passive OFS. Set to select active OFS.	0	1
ICKK	SCON10[3]	Clear to capture input data on falling edge of input bit clock.	0	X
ICKA	SCON10[2]	Clear to select passive ICK. Set to select active ICK.	0	1
IFSK	SCON10[1]	Set to invert IFS.	1	1
IFSA	SCON10[0]	Clear to select passive IFS. Set to select active IFS.	0	1
AGCKLIM[7:0]	SCON11[7:0]	Active bit clock divide ratio.	X	1 (ICK and OCK are SCK/2)
AGRESET	SCON12[15]	Clear to activate active clock and frame sync generator.	0	0
AGSYNC	SCON12[14]	Set to synchronize active generated bit clocks to SIFS pin.	0	1
SCKK	SCON12[13]	Set to invert SCK. Clear if AGEXT is cleared.	0	1
AGEXT	SCON12[12]	Clear to select CLK as source for active clock and frame sync generator. Set to select SCK as source for active clock and frame sync generator.	0	1
AGFSLIM[10:0]	SCON12[10:0]	Active frame sync divide ratio.	X	0x3FF

1. *MITEL* is a registered trademark of Mitel Corporation.

4 Hardware Architecture (continued)

4.16 Serial Interface Unit (SIU) (continued)

4.16.14 SIU Examples (continued)

4.16.14.2 ST-Bus Interface (continued)

Table 99 describes the SIU control registers and control register fields that must be configured as required by the particular system application using an ST-Bus interface.

Table 99. Control Register and Fields That Are Configured as Required for ST-Bus Interface

Control Register or Field	Description	
OMSB	SCON0 [10]	Selects LSB- or MSB-first output data.
OFORMAT[1:0]	SCON0 [9:8]	Selects linear, μ -law, or A-law output format.
IMSB	SCON0 [2]	Selects LSB- or MSB-first input data.
IFORMAT[1:0]	SCON0 [1:0]	Selects linear, μ -law, or A-law input format.
IFRAME	SCON1 [7]	Clear to select input channel mode. Set to select input frame mode.
IFLIM[6:0]	SCON1 [6:0]	Program to 127 for 128 channels per input frame.
OFRAME	SCON2 [7]	Clear to select output channel mode. Set to select output frame mode.
OFLIM[6:0]	SCON2 [6:0]	Program to 127 for 128 channels per output frame.
OSFIDV_O	SCON3 [13]	Set to enable odd output subframes.
OSFID_O[1:0]	SCON3 [12:11]	Selects odd output subframe 1, 3, 5, or 7.
OSFIDV_E	SCON3 [10]	Set to enable even output subframes.
OSFID_E[1:0]	SCON3 [9:8]	Selects even output subframe 0, 2, 4, or 6.
ISFIDV_O	SCON3 [5]	Set to enable odd input subframes.
ISFID_O[1:0]	SCON3 [4:3]	Selects odd input subframe 1, 3, 5, or 7.
ISFIDV_E	SCON3 [2]	Set to enable even input subframes.
ISFID_E[1:0]	SCON3 [1:0]	Selects even input subframe 0, 2, 4, or 6.
ISFVEC_E[15:0]	SCON4 [15:0]	Set to enable corresponding channel of the selected even input subframe.
ISFVEC_O[15:0]	SCON5 [15:0]	Set to enable corresponding channel of the selected odd input subframe.
OSFVEC_E[15:0]	SCON6 [15:0]	Set to enable corresponding channel of the selected even output subframe.
OSFVEC_O[15:0]	SCON7 [15:0]	Set to enable corresponding channel of the selected odd output subframe.
OSFMSK_E[15:0]	SCON8 [15:0]	Set to mask corresponding channel of the selected even output subframe.
OSFMSK_O[15:0]	SCON9 [15:0]	Set to mask corresponding channel of the selected odd output subframe.
OINTSEL[1:0]	SCON10 [14:13]	Selects one of four conditions for which the SIU output interrupt (SOINT) is asserted.
IINTSEL[1:0]	SCON10 [12:11]	Selects one of four conditions for which the SIU input interrupt (SIINT) is asserted.
ICIX0 [15:0]	Input channel index for the active even input subframe—selects one of two DMAU SWT channels (SWT0 or SWT1 for SIU0; SWT2 or SWT3 for SIU1) for each logical channel in the active even input subframe.	
ICIX1 [15:0]	Input channel index for the active odd input subframe—selects one of two DMAU SWT channels (SWT0 or SWT1 for SIU0; SWT2 or SWT3 for SIU1) for each logical channel in the active odd input subframe.	
OCIX0 [15:0]	Input channel index for the active even output subframe—selects one of two DMAU SWT channels (SWT0 or SWT1 for SIU0; SWT2 or SWT3 for SIU1) for each logical channel in the active even output subframe.	
OCIX1 [15:0]	Input channel index for the active odd output subframe—selects one of two DMAU SWT channels (SWT0 or SWT1 for SIU0; SWT2 or SWT3 for SIU1) for each logical channel in the active odd output subframe.	

4 Hardware Architecture (continued)

4.16 Serial Interface Unit (SIU) (continued)

4.16.14 SIU Examples (continued)

4.16.14.2 ST-Bus Interface (continued)

Figure 52 illustrates ST-bus operation with a single rate clock.

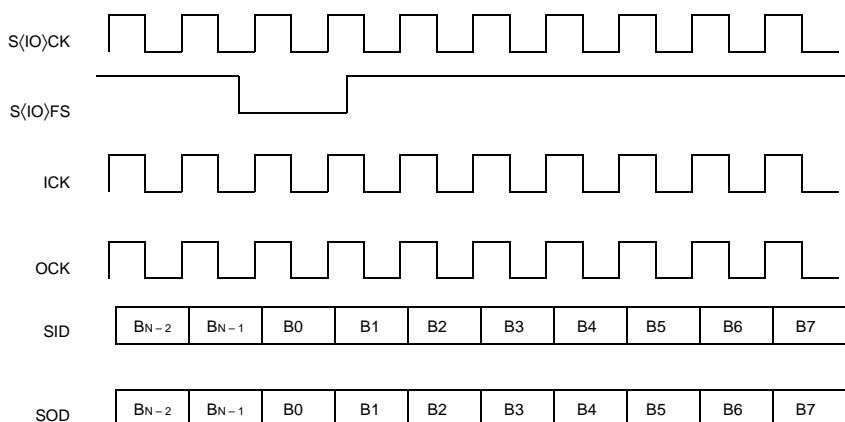


Figure 52. ST-Bus Single-Rate Clock

Figure 53 illustrates ST-bus operation with a double-rate clock applied to SCK, with an active mode bit clock and output frame sync generation for internal use only. In addition, this figure assumes the use of SIFS for external clock synchronization (AGSYNC = 1) of both the input and output bit clocks. ICK, OCK, IFS, and OFS are the internally generated bit clocks and frame syncs. Refer to Figure 40 on page 152 to review the block diagram of the internal clock generator.

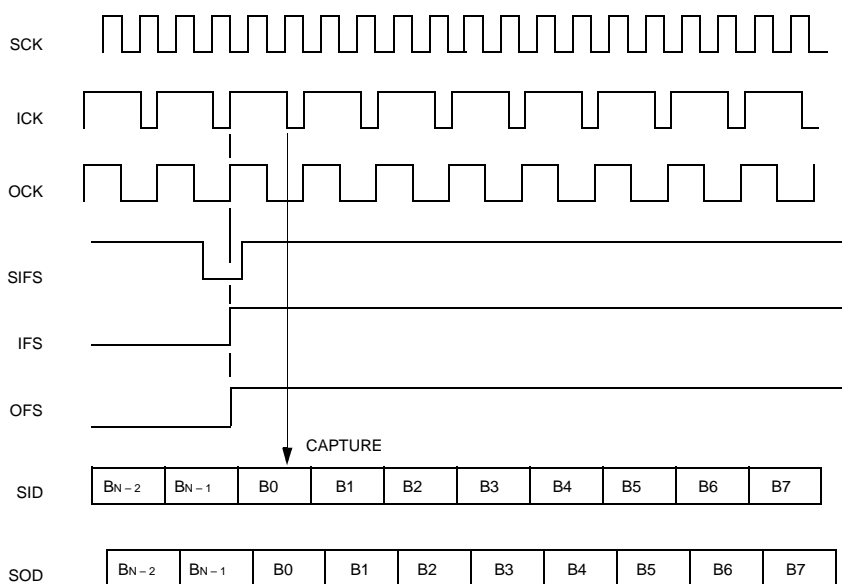


Figure 53. ST-Bus Double-Rate Clock

4 Hardware Architecture (continued)

4.16 Serial Interface Unit (SIU) (continued)

4.16.15 Registers

Each SIU contains 21 control, status, and data registers as summarized in Table 100. These can be functionally grouped as:

- Thirteen control registers (**SCON** $\langle 0-12 \rangle$)
- Two status registers (**STAT** and **FSTAT**)

- One read-only input data register (**SIDR**)
- One write-only output register (**SODR**)
- Two input channel index registers (**ICIX** $\langle 0-1 \rangle$)
- Two output channel index registers (**OCIX** $\langle 0-1 \rangle$)

All of these 16-bit registers are aligned on even addresses in DSP16410B shared I/O memory space. The remainder of this section provides detail on each of these registers.

Table 100 summarizes all the SIU memory-mapped registers. Tables 101 through 119 describe each register individually.

Table 100. SIU Registers

Register Name	Address		Description	Size (Bits) [†]	R/W	Type [‡]	Reset Value
	SIU0	SIU1					
SCON0	0x43000	0x44000	SIU Input/Output General Control	16	R/W	control	0x0000
SCON1	0x43002	0x44002	SIU Input Frame Control				0x0400
SCON2	0x43004	0x44004	SIU Output Frame Control				0x0400
SCON3	0x43006	0x44006	SIU Input/Output Subframe Control				0x0000
SCON4	0x43008	0x44008	SIU Input Even Subframe Valid Vector Control				0x0000
SCON5	0x4300A	0x4400A	SIU Input Odd Subframe Valid Vector Control				0x0000
SCON6	0x4300C	0x4400C	SIU Output Even Subframe Valid Vector Control				0x0000
SCON7	0x4300E	0x4400E	SIU Output Odd Subframe Valid Vector Control				0x0000
SCON8	0x43010	0x44010	SIU Output Even Subframe Mask Vector Control				0x0000
SCON9	0x43012	0x44012	SIU Output Odd Subframe Mask Vector Control				0x0000
SCON10	0x43014	0x44014	SIU Input/Output General Control				0x0000
SCON11	0x43016	0x44016	SIU Input/Output Active Clock Control				0x0000
SCON12	0x43018	0x44018	SIU Input/Output Active Frame Sync Control				0x8000
SIDR	0x4301A	0x4401A	SIU Input Data	16	R	data	0x0000
SODR	0x4301C	0x4401C	SIU Output Data		W		
STAT	0x4301E	0x4401E	SIU Input/Output General Status	16	R/W [§]	c & s	0x0000
FSTAT	0x43020	0x44020	SIU Input/Output Frame Status	16	R	status	0x0000
OCIX0	0x43030	0x44030	SIU Output Channel Index for Even Subframes	16	R/W	control	0x0000
OCIX1	0x43032	0x44032	SIU Output Channel Index for Odd Subframes				
ICIX0	0x43040	0x44040	SIU Input Channel Index for Even Subframes	16	R/W	control	0x0000
ICIX1	0x43042	0x44042	SIU Input Channel Index for Odd Subframes				

[†] The SIU memory-mapped register sizes represent bits used. The registers are right-justified and padded to 32 bits (the unused upper bits are zero-filled).

[‡] c & s means control and status.

[§] All bits of **STAT** are readable, and some can be written with one to clear them.

4 Hardware Architecture (continued)

4.16 Serial Interface Unit (SIU) (continued)

4.16.15 Registers (continued)

Table 101. SCON0 (SIU Input/Output General Control) Register

The memory address for this register is 0x43000 for SIU0 and 0x44000 for SIU1.

15—13		12—11		10		9—8		7—5		4—3		2		1—0	
Reserved		OSIZE[1:0]		OMSB		OFORMAT[1:0]		Reserved		ISIZE[1:0]		IMSB		IFORMAT[1:0]	
Bit	Field	Value	Description										R/W	Reset Value	
15—13	Reserved	0	Reserved—write with zero.										R/W	0	
12—11	OSIZE[1:0] [†]	0	The channel size for serial output data is 8 bits [‡] .										R/W	0	
		1	The channel size for serial output data is 16 bits.												
		2	The channel size for serial output data is 4 bits [‡] .												
		3	The channel size for serial output data is 12 bits [‡] .												
10	OMSB [†]	0	Shift data out onto SOD pin least significant bit (LSB) first.										R/W	0	
		1	Shift data out onto SOD pin most significant bit (MSB) first.												
9—8	OFORMAT[1:0] [†]	00	When transferring data from the SODR register to the output shift register, do not format (modify) the data.										R/W	00	
		01	Reserved.												
		10	When transferring 16-bit data from the SODR register to the output shift register, convert the most significant 14 bits of SODR (SODR [15:2]) from linear PCM format to 8-bit μ -law PCM format, place the result into the lower half of the output shift register, and clear the upper half. Ignore the least significant 2 bits of SODR .												
		11	When transferring 16-bit data from the SODR register to the output shift register, convert the most significant 13 bits of SODR (SODR [15:3]) from linear PCM format to 8-bit A-law PCM format, place the result into the lower half of the output shift register, and clear the upper half. Ignore the least significant 3 bits of SODR .												
7—5	Reserved	0	Reserved—write with zero.										R/W	0	
4—3	ISIZE[1:0] [§]	0	The channel size for serial input data is 8 bits ^{††} .										R/W	0	
		1	The channel size for serial input data is 16 bits.												
		2	The channel size for serial input data is 4 bits ^{††} .												
		3	The channel size for serial input data is 12 bits ^{††} .												
2	IMSB [§]	0	Capture input data from SID pin least significant bit (LSB) first.										R/W	0	
		1	Capture input data from SID pin most significant bit (MSB) first.												
1—0	IFORMAT[1:0] [§]	00	When transferring 16-bit data from the SIB ^{‡‡} register to the SIDR register, do not format (modify) the data.										R/W	00	
		01	Reserved.												
		10	When transferring data from the SIB ^{‡‡} register to the SIDR register, convert the lower 8 bits of SIB (SIB [7:0]) from μ -law PCM format to 14-bit linear PCM format, place the result into the 14 most significant bits of SIDR (SIDR [15:2]), and clear the least significant 2 bits of SIDR (SIDR [1:0]).												
		11	When transferring data from the SIB ^{‡‡} register to the SIDR register, convert the lower 8 bits of SIB (SIB [7:0]) from A-law PCM format to 13-bit linear PCM format, place the result into the 13 most significant bits of SIDR (SIDR [15:3]), and clear the least significant 3 bits of SIDR (SIDR [2:0]).												

[†] If the ORESET field (**SCON2**[10]) is cleared, do not change the value in this field.

[‡] The SIU shifts data from the low portion of the output shift register onto the SOD pin and ignores the high portion of the register.

[§] If the IRESET field (**SCON1**[10]) is cleared, do not change the value in this field.

^{††} The SIU right justifies the received serial input data, i.e., it places the data in the least significant bit positions of the 16-bit serial input buffer register and fills the upper bits with zeros.

^{‡‡} The **SIB** register is an intermediate register that holds the contents of the input shift register and is not user accessible.

4 Hardware Architecture (continued)

4.16 Serial Interface Unit (SIU) (continued)

4.16.15 Registers (continued)

Table 102. SCON1 (SIU Input Frame Control) Register

The memory address for this register is 0x43002 for SIU0 and 0x44002 for SIU1.

15—12		11	10	9—8	7	6—0	
Reserved		I2XDLY	IRESET	IFSDLY[1:0]	IFRAME	IFLIM[6:0]	
Bit	Field	Value	Description			R/W	Reset Value
15—12	Reserved	0	Reserved—write with zero.			R/W	0
11	I2XDLY [†]	0	Do not stretch the active generated input bit clock (ICK) relative to the active-mode generated output bit clock (OCK), i.e., ICK and OCK are identical and in-phase.			R/W	0
		1	Stretch the high phase of the active generated input clock (ICK) by one SCK phase relative to the active generated output bit clock (OCK) to provide additional input serial data capture time.				
10	IRESET	0	Activate input section and begin input processing at the start of the first active input channel.			R/W	1
		1	Deactivate input section and initialize bit and frame counters.				
9—8	IFSDLY[1:0] [†]	00	No input frame sync delay—capture input data from SID pin starting with the same internal bit clock (ICK) that latches the input frame sync (SIFS pin for passive sync or IFS signal for active generated sync).			R/W	00
		01	One-cycle input frame sync delay—capture input data from SID pin starting one bit clock (ICK) after the bit clock that latches the input frame sync (SIFS pin for passive sync or IFS signal for active generated sync).				
		10	Two-cycle input frame sync delay—capture input data from SID pin starting two bit clocks (ICK) after the bit clock that latches the input frame sync (SIFS pin for passive sync or IFS signal for active generated sync).				
		11	Reserved.				
7	IFRAME [†]	0	Channel mode—base the input transfer decision on the ISFIDV_E field (SCON3[2]), the ISFVEC_E[15:0] field (SCON4[15:0]), the ISFIDV_O field (SCON3[5]), and the ISFVEC_O[15:0] field (SCON5[15:0]).			R/W	0
		1	Frame mode—capture all IFLIM + 1 channels in the frame.				
6—0	IFLIM[6:0] [†]	0—127	Input frame channel count limit—the number of channels in the input frame is IFLIM + 1.			R/W	0

[†] If the IRESET field (SCON1[10]) is cleared, do not change the value in this field.

4 Hardware Architecture (continued)

4.16 Serial Interface Unit (SIU) (continued)

4.16.15 Registers (continued)

Table 103. SCON2 (SIU Output Frame Control) Register

The memory address for this register is 0x43004 for SIU0 and 0x44004 for SIU1.

15—11		10	9—8	7	6—0	
Reserved		ORESET	OFSPLY[1:0]	OFRAME	OFLIM[6:0]	
Bit	Field	Value	Description		R/W	Reset Value
15—11	Reserved	0	Reserved—write with zero.		R/W	0
10	ORESET	0	Activate output section, request output service from the DMAU, and drive SOD pin at the start of the first active output channel.		R/W	1
		1	Deactivate output section and initialize bit and frame counters.			
9—8	OFSPLY[1:0]†	00	No output frame sync delay—drive output data onto SOD pin starting with the same internal bit clock (OCK) that latches the output frame sync (SOFS pin for passive sync or OFS signal for active generated sync).		R/W	00
		01	One-cycle output frame sync delay—drive output data onto SOD pin starting one bit clock (OCK) after the bit clock that latches the output frame sync (SOFS pin for passive sync or OFS signal for active generated sync).			
		10	Two-cycle output frame sync delay—drive output data onto SOD pin starting two bit clocks (OCK) after the bit clock that latches output frame sync (SOFS pin for passive sync or OFS signal for active generated sync).			
		11	Reserved.			
7	OFRAME†	0	Channel mode—base the output transfer decision on the OSFIDV_E field (SCON3[10]), the OSFVEC_E[15:0] field (SCON6[15:0]), the OSFIDV_O field (SCON3[13]), and the OSFVEC_O[15:0] field (SCON7[15:0]).		R/W	0
		1	Frame mode—transmit all OFLIM + 1 channels in the frame.			
6—0	OFLIM[6:0]†	0—127	Output frame channel count limit—the number of channels in the output frame is OFLIM + 1.		R/W	0

† If the ORESET field (SCON2[10]) is cleared, do not change the value in this field.

4 Hardware Architecture (continued)

4.16 Serial Interface Unit (SIU) (continued)

4.16.15 Registers (continued)

Table 104. SCON3 (SIU Input/Output Subframe Control) Register

The memory address for this register is 0x43006 for SIU0 and 0x44006 for SIU1.

15		14		13		12—11		10		9—8	
OFSE		OCKE		OSFIDV_O		OSFID_O[1:0]		OSFIDV_E		OSFID_E[1:0]	
7		6		5		4—3		2		1—0	
IFSE		ICKE		ISFIDV_O		ISFID_O[1:0]		ISFIDV_E		ISFID_E[1:0]	
Bit	Field	Value	Description				R/W	Reset Value			
15	OFSE (active mode only)	0	Do not drive internally generated frame sync onto SOFS pin.				R/W	0			
		1	Drive internally generated frame sync onto SOFS pin.								
14	OCKE (active mode only)	0	Do not drive internally generated clock onto SOCK pin.				R/W	0			
		1	Drive internally generated clock onto SOCK pin.								
13	OSFIDV_O (channel mode only)	0	Odd output subframe vector valid. Disable odd output subframes. In frame mode (OFRAME(SCON2[7]) = 1), this field must be cleared.				R/W	0			
		1	Odd output subframe vector valid. Enable odd output subframes.								
12—11	OSFID_O[1:0] (channel mode only)	00	For odd subframes, the output subframe ID of the subframe under control of the OSFVEC_O[15:0] field (SCON7[15:0]) and the OSFMSK_O[15:0] field (SCON9[15:0]) is: $2 \times \text{OSFID}_O + 1$ as shown at right.				1	R/W	00		
		01					3				
		10					5				
		11					7				
10	OSFIDV_E (channel mode only)	0	Even output subframe vector valid. Disable even output subframes. In frame mode (OFRAME(SCON2[7]) = 1), this field must be cleared.				R/W	0			
		1	Even output subframe vector valid. Enable even output subframes.								
9—8	OSFID_E[1:0] (channel mode only)	00	For even subframes, the output subframe ID of the subframe under control of the OSFVEC_E[15:0] field (SCON6[15:0]) and the OSFMSK_E[15:0] field (SCON8[15:0]) is: $2 \times \text{OSFID}_E$ as shown at right.				0	R/W	00		
		01					2				
		10					4				
		11					6				
7	IFSE (active mode only)	0	Do not drive internally generated frame sync onto SIFS pin.				R/W	0			
		1	Active mode only. Drive internally generated frame sync onto SIFS pin.								
6	ICKE (active mode only)	0	Do not drive internally generated clock onto SICK pin.				R/W	0			
		1	Active mode only. Drive internally generated clock onto SICK pin.								
5	ISFIDV_O (channel mode only)	0	Odd input subframe vector valid. Disable odd input subframes. In frame mode (OFRAME(SCON2[7]) = 1), this field must be cleared.				R/W	0			
		1	Odd input subframe vector valid. Enable odd input subframes.								
4—3	ISFID_O[1:0] (channel mode only)	00	For odd subframes, the input subframe ID of the subframe under control of the ISFVEC_O[15:0] field (SCON5[15:0]) is: $2 \times \text{ISFID}_O + 1$ as shown at right.				1	R/W	00		
		01					3				
		10					5				
		11					7				
2	ISFIDV_E (channel mode only)	0	Even input subframe vector valid. Disable even input subframes. In frame mode (OFRAME(SCON2[7]) = 1), this field must be cleared.				R/W	0			
		1	Even input subframe vector valid. Enable even input subframes.								
1—0	ISFID_E[1:0] (channel mode only)	00	For even subframes, the input subframe ID of the subframe under control of the ISFVEC_E[15:0] field (SCON4[15:0]) is: $2 \times \text{ISFID}_E$ as shown at right.				0	R/W	00		
		01					2				
		10					4				
		11					6				

4 Hardware Architecture (continued)

4.16 Serial Interface Unit (SIU) (continued)

4.16.15 Registers (continued)

Table 105. SCON4 (SIU Input Even Subframe Valid Vector Control) Register

The memory address for this register is 0x43008 for SIU0 and 0x44008 for SIU1.

15—0					
ISFVEC_E[15:0]					
Bit	Field	Value	Description	R/W	Reset Value
15—0	ISFVEC_E[15:0]	0	The corresponding channel of the selected even input subframe is disabled.	R/W	0
		1	The corresponding channel of the selected even input subframe is enabled.		

Table 106. SCON5 (SIU Input Odd Subframe Valid Vector Control) Register

The memory address for this register is 0x4300A for SIU0 and 0x4400A for SIU1.

15—0					
ISFVEC_O[15:0]					
Bit	Field	Value	Description	R/W	Reset Value
15—0	ISFVEC_O[15:0]	0	The corresponding channel of the selected odd input subframe is disabled.	R/W	0
		1	The corresponding channel of the selected odd input subframe is enabled.		

4 Hardware Architecture (continued)

4.16 Serial Interface Unit (SIU) (continued)

4.16.15 Registers (continued)

Table 107. SCON6 (SIU Output Even Subframe Valid Vector Control) Register

The memory address for this register is 0x4300C for SIU0 and 0x4400C for SIU1.

15—0					
OSFVEC_E[15:0]					
Bit	Field	Value	Description	R/W	Reset Value
15—0	OSFVEC_E[15:0]	0	The corresponding channel of the selected even output subframe is disabled.	R/W	0
		1	The corresponding channel of the selected even output subframe is enabled.		

Table 108. SCON7 (SIU Output Odd Subframe Valid Vector Control) Register

The memory address for this register is 0x4300E for SIU0 and 0x4400E for SIU1.

15—0					
OSFVEC_O[15:0]					
Bit	Field	Value	Description	R/W	Reset Value
15—0	OSFVEC_O[15:0]	0	The corresponding channel of the selected odd output subframe is disabled.	R/W	0
		1	The corresponding channel of the selected odd output subframe is enabled.		

Table 109. SCON8 (SIU Output Even Subframe Mask Vector Control) Register

The memory address for this register is 0x43010 for SIU0 and 0x44010 for SIU1.

15—0					
OSFMSK_E[15:0]					
Bit	Field	Value	Description	R/W	Reset Value
15—0	OSFMSK_E[15:0]	0	Do not mask the corresponding output channel.	R/W	0
		1	For an active even subframe, mask the corresponding output channel (do not drive SOD during the output time slot).		

Table 110. SCON9 (SIU Output Odd Subframe Mask Vector Control) Register

The memory address for this register is 0x43012 for SIU0 and 0x44012 for SIU1.

15—0					
OSFMSK_O[15:0]					
Bit	Field	Value	Description	R/W	Reset Value
15—0	OSFMSK_O[15:0]	0	Do not mask the corresponding output channel.	R/W	0
		1	For an active odd subframe, mask the corresponding output channel (do not drive SOD during the output time slot).		

4 Hardware Architecture (continued)

4.16 Serial Interface Unit (SIU) (continued)

4.16.15 Registers (continued)

Table 111. SCON10 (SIU Input/Output General Control) Register

The memory address for this register is 0x43014 for SIU0 and 0x44014 for SIU1.

15	14—13	12—11	10—9	8	7	6	5	4	3	2	1	0
Reserved	OINTSEL[1:0]	IINTSEL[1:0]	Reserved	SIOLB	OCKK	OCKA	OFSK	OFSA	ICKK	ICKA	IFSK	IFSA
Bit	Field	Value	Description								R/W	Reset Value
15	Reserved	0	Reserved—write with zero.								R/W	0
14—13	OINTSEL[1:0]	00	Assert output interrupt (SOINT) after output frame sync detected.								R/W	00
		01	Assert output interrupt (SOINT) after output subframe transfer complete.									
		10	Assert output interrupt (SOINT) after output channel transfer complete.									
		11	Assert output interrupt (SOINT) after output frame error or output underflow error occurs†.									
12—11	IINTSEL[1:0]	00	Assert input interrupt (SIINT) after input frame sync detected.								R/W	00
		01	Assert input interrupt (SIINT) after input subframe transfer complete.									
		10	Assert input interrupt (SIINT) after input channel transfer complete.									
		11	Assert input interrupt (SIINT) after input frame error or input overflow error occurs†.									
10—9	Reserved	0	Reserved—write with zero.								R/W	0
8	SIOLB‡	0	Normal operation.								R/W	0
		1	Place SIU in loopback mode (SOD internally connected to SID, OCK internally connected to ICK, OFS internally connected to IFS).									
7	OCKK§	0	Drive output data onto the SOD pin on the rising edge of the output bit clock pin (SOCK). <ul style="list-style-type: none"> ■ If OCKA is 0 (passive clock), do not invert SOCK to generate the internal output bit clock (OCK). ■ If OCKA is 1 (active clock), do not invert the active generated output bit clock (OCK) before applying to the SOCK pin. 								R/W	0
		1	Drive output data onto the SOD pin on the falling edge of the output bit clock pin (SOCK). <ul style="list-style-type: none"> ■ If OCKA is 0 (passive clock), invert SOCK to generate the internal output bit clock (OCK). ■ If OCKA is 1 (active clock), invert the active generated output bit clock (OCK) before applying to the SOCK pin. 									
6	OCKA§	0	Passive mode output clock††—drive the internal output bit clock (OCK) from the external output bit clock pin (SOCK pin modified according to OCKK). The SIU configures SOCK as an input.								R/W	0
		1	Active mode output clock—drive the internal output bit clock (OCK) from the active generated output bit clock derived from CLK or SCK. The SIU configures SOCK as an output.									

† To determine the type of error, the program can read the contents of the **STAT** register (see [Table 116 on page 194](#)).

‡ If the IRESET field (**SCON1**[10]) or ORESET field (**SCON2**[10]) is cleared, do not change the value in this field.

§ If the ORESET field (**SCON2**[10]) is cleared, do not change the value in this field.

††The combination of passive output bit clock (OCKA = 0) and active output frame sync (OFSA = 1) is not supported. The combination of passive input bit clock (ICKA = 0) and active input frame sync (IFSA = 1) is not supported.

§§ If the IRESET field (**SCON1**[10]) is cleared, do not change the value in this field.

4 Hardware Architecture (continued)

4.16 Serial Interface Unit (SIU) (continued)

4.16.15 Registers (continued)

Table 111. **SCON10 (SIU Input/Output General Control) Register** (continued)

Bit	Field	Value	Description	R/W	Reset Value
5	OFSK [§]	0	The external output frame sync pin (SOFS) is active-high. <ul style="list-style-type: none"> ■ If OFSA is 0 (passive sync), do not invert SOFS to generate the internal output frame sync (OFS). ■ If OFSA is 1 (active sync), do not invert the active generated output frame sync (OFS) before applying to the SOFS pin. 	R/W	0
		1	The external output frame sync pin (SOFS) is active-low. <ul style="list-style-type: none"> ■ If OFSA is 0 (passive sync), invert SOFS to generate the internal output frame sync (OFS). ■ If OFSA is 1 (active sync), invert the active generated output frame sync (OFS) before applying to the SOFS pin. 		
4	OFSA [§]	0	Passive mode output frame sync—drive the internal output frame sync (OFS) from the external output frame sync pin (SOFS modified according to OFSK and SCON2 [OFSDLY]). The SIU configures SOFS as an input.	R/W	0
		1	Active mode output frame sync ^{††} —drive the internal output frame sync (OFS) from the active generated frame sync (AGFS) modified according to SCON2 [OFSDLY]. The SIU configures SOFS as an output.		
3	ICKK ^{§§}	0	Capture input data from the SID pin on the falling edge of the input bit clock pin (SICK). <ul style="list-style-type: none"> ■ If ICKA is 0 (passive clock), do not invert the input bit clock pin (SICK) to generate ICK. ■ If ICKA is 1 (active clock), do not invert the active generated input bit clock (ICK) before applying to the SICK pin. 	R/W	0
		1	Capture input data from the SID pin on the rising edge of the input bit clock pin (SICK). <ul style="list-style-type: none"> ■ If ICKA is 0 (passive clock), invert SICK to generate the internal input bit clock (ICK). ■ If ICKA is 1 (active clock), invert the active generated input bit clock (ICK) before applying to the SICK pin. 		
2	ICKA ^{§§}	0	Passive mode input bit clock ^{††} —drive the internal input bit clock (ICK) from the external input bit clock pin (SICK pin modified according to ICKK). The SIU configures SICK as an input.	R/W	0
		1	Active mode input bit clock—drive the internal input bit clock (ICK) from the active generated input bit clock derived from CLK or SCK. The SIU configures SICK as an output.		

† To determine the type of error, the program can read the contents of the **STAT** register (see Table 116 on page 194).

‡ If the IRESET field (**SCON1**[10]) or ORESET field (**SCON2**[10]) is cleared, do not change the value in this field.

§ If the ORESET field (**SCON2**[10]) is cleared, do not change the value in this field.

††The combination of passive output bit clock (OCKA = 0) and active output frame sync (OFSA = 1) is not supported. The combination of passive input bit clock (ICKA = 0) and active input frame sync (IFSA = 1) is not supported.

§§ If the IRESET field (**SCON1**[10]) is cleared, do not change the value in this field.

4 Hardware Architecture (continued)

4.16 Serial Interface Unit (SIU) (continued)

4.16.15 Registers (continued)

Table 111. **SCON10 (SIU Input/Output General Control) Register** (continued)

Bit	Field	Value	Description	R/W	Reset Value
1	IFSK ^{§§}	0	The external input frame sync pin (SIFS) is active-high. <ul style="list-style-type: none"> ■ If IFSA is 0 (passive sync), do not invert SIFS to generate the internal input frame sync (IFS). ■ If IFSA is 1 (active sync), do not invert the active generated input frame sync (IFS) before applying to the SIFS pin. 	R/W	0
		1	The external input frame sync pin (SIFS) is active-low. <ul style="list-style-type: none"> ■ If IFSA is 0 (passive sync), invert the input frame sync pin (SIFS) to generate the internal input frame sync (IFS). ■ If IFSA is 1 (active sync), invert the active generated input frame sync (IFS) before applying to the SIFS pin. 		
0	IFSA ^{§§}	0	Passive mode input frame sync—drive the internal input frame sync (IFS) from the external input frame sync pin (SIFS) modified according to IFSK and SCON1 [IFSDLY]. The SIU configures SIFS as an input.	R/W	0
		1	Active mode input frame sync ^{††} —drive the internal input frame sync (IFS) from the active generated frame sync (AGFS) modified according to SCON1 [IFSDLY]. If SCON12 [AGSYNC] is cleared, the SIU configures SIFS as an output. If SCON12 [AGSYNC] is set, the SIU configures SIFS as an input for the purpose of synchronizing the active generated bit clocks.		

† To determine the type of error, the program can read the contents of the **STAT** register (see Table 116 on page 194).

‡ If the IRESET field (**SCON1**[10]) or ORESET field (**SCON2**[10]) is cleared, do not change the value in this field.

§ If the ORESET field (**SCON2**[10]) is cleared, do not change the value in this field.

††The combination of passive output bit clock (OCCA = 0) and active output frame sync (OFSA = 1) is not supported. The combination of passive input bit clock (ICKA = 0) and active input frame sync (IFSA = 1) is not supported.

§§ If the IRESET field (**SCON1**[10]) is cleared, do not change the value in this field.

4 Hardware Architecture (continued)

4.16 Serial Interface Unit (SIU) (continued)

4.16.15 Registers (continued)

Table 112. SCON11 (SIU Input/Output Active Clock Control) Register

The memory address for this register is 0x43016 for SIU0 and 0x44016 for SIU1.

15—8			7—0																																										
Reserved			AGCKLIM[7:0]																																										
Bit	Field	Value	Description	R/W	Reset Value																																								
15—8	Reserved	0	Reserved—write with zero.	R/W	0																																								
7—0	AGCKLIM[7:0] [†]	0—255	<p>Active clock divide ratio—controls the period and duty cycle of the active generated input and output bit clocks (ICK and OCK).</p> <p>The period of ICK and OCK (T_{AGCK}) is the following: $T_{AGCK} = T_{CKAG} \times (\max(1, AGCKLIM[7:0]) + 1)$ where T_{CKAG} is the period of the clock source[‡] for ICK and OCK.</p> <p>The high and low times of ICK and OCK (T_{AGCKH} and T_{AGCKL}) are as follows: $T_{AGCKH} = T_{CKAG} \times \text{int}((\max(1, AGCKLIM[7:0]) + 2) \div 2)$ $T_{AGCKL} = T_{CKAG} \times \text{int}((\max(1, AGCKLIM[7:0]) + 1) \div 2)$ where T_{CKAG} is the period of the clock source[§] for ICK and OCK and $\text{int}()$ is the integer function (truncation).</p> <p>The following table illustrates examples:</p> <table border="1" style="margin-left: auto; margin-right: auto;"> <thead> <tr> <th></th> <th>Bit Clock Period</th> <th>High Time</th> <th>Low Time</th> </tr> <tr> <th>AGCKLIM[7:0]</th> <th>T_{AGCK}</th> <th>T_{AGCKH}</th> <th>T_{AGCKL}</th> </tr> </thead> <tbody> <tr> <td>0 or 1</td> <td>$2 \times T_{CKAG}$</td> <td>$1 \times T_{CKAG}$</td> <td>$1 \times T_{CKAG}$</td> </tr> <tr> <td>2</td> <td>$3 \times T_{CKAG}$</td> <td>$2 \times T_{CKAG}$</td> <td>$1 \times T_{CKAG}$</td> </tr> <tr> <td>3</td> <td>$4 \times T_{CKAG}$</td> <td>$2 \times T_{CKAG}$</td> <td>$2 \times T_{CKAG}$</td> </tr> <tr> <td>4</td> <td>$5 \times T_{CKAG}$</td> <td>$3 \times T_{CKAG}$</td> <td>$2 \times T_{CKAG}$</td> </tr> <tr> <td>5</td> <td>$6 \times T_{CKAG}$</td> <td>$3 \times T_{CKAG}$</td> <td>$3 \times T_{CKAG}$</td> </tr> <tr> <td>6</td> <td>$7 \times T_{CKAG}$</td> <td>$4 \times T_{CKAG}$</td> <td>$3 \times T_{CKAG}$</td> </tr> <tr> <td>254</td> <td>$255 \times T_{CKAG}$</td> <td>$128 \times T_{CKAG}$</td> <td>$127 \times T_{CKAG}$</td> </tr> <tr> <td>255</td> <td>$256 \times T_{CKAG}$</td> <td>$128 \times T_{CKAG}$</td> <td>$128 \times T_{CKAG}$</td> </tr> </tbody> </table>		Bit Clock Period	High Time	Low Time	AGCKLIM[7:0]	T_{AGCK}	T_{AGCKH}	T_{AGCKL}	0 or 1	$2 \times T_{CKAG}$	$1 \times T_{CKAG}$	$1 \times T_{CKAG}$	2	$3 \times T_{CKAG}$	$2 \times T_{CKAG}$	$1 \times T_{CKAG}$	3	$4 \times T_{CKAG}$	$2 \times T_{CKAG}$	$2 \times T_{CKAG}$	4	$5 \times T_{CKAG}$	$3 \times T_{CKAG}$	$2 \times T_{CKAG}$	5	$6 \times T_{CKAG}$	$3 \times T_{CKAG}$	$3 \times T_{CKAG}$	6	$7 \times T_{CKAG}$	$4 \times T_{CKAG}$	$3 \times T_{CKAG}$	254	$255 \times T_{CKAG}$	$128 \times T_{CKAG}$	$127 \times T_{CKAG}$	255	$256 \times T_{CKAG}$	$128 \times T_{CKAG}$	$128 \times T_{CKAG}$	R/W	0
	Bit Clock Period	High Time	Low Time																																										
AGCKLIM[7:0]	T_{AGCK}	T_{AGCKH}	T_{AGCKL}																																										
0 or 1	$2 \times T_{CKAG}$	$1 \times T_{CKAG}$	$1 \times T_{CKAG}$																																										
2	$3 \times T_{CKAG}$	$2 \times T_{CKAG}$	$1 \times T_{CKAG}$																																										
3	$4 \times T_{CKAG}$	$2 \times T_{CKAG}$	$2 \times T_{CKAG}$																																										
4	$5 \times T_{CKAG}$	$3 \times T_{CKAG}$	$2 \times T_{CKAG}$																																										
5	$6 \times T_{CKAG}$	$3 \times T_{CKAG}$	$3 \times T_{CKAG}$																																										
6	$7 \times T_{CKAG}$	$4 \times T_{CKAG}$	$3 \times T_{CKAG}$																																										
254	$255 \times T_{CKAG}$	$128 \times T_{CKAG}$	$127 \times T_{CKAG}$																																										
255	$256 \times T_{CKAG}$	$128 \times T_{CKAG}$	$128 \times T_{CKAG}$																																										

[†] If the IRESET field (SCON1[10]) or ORESET field (SCON2[10]) is cleared, do not change the value in this field.

[‡] The clock source is selected by SCON12[AGEXT] as either the SCK pin (modified by SCON12[SCKK]) or the processor clock, CLK.

4 Hardware Architecture (continued)

4.16 Serial Interface Unit (SIU) (continued)

4.16.15 Registers (continued)

Table 113. SCON12 (SIU Input/Output Active Frame Sync Control) Register

The memory address for this register is 0x43018 for SIU0 and 0x44018 for SIU1.

15		14		13		12		11		10—0																	
AGRESET		AGSYNC		SCKK		AGEXT		Reserved		AGFSLIM[10:0]																	
Bit	Field	Value	Description						R/W	Reset Value																	
15	AGRESET [†]	0	Activate the active clock and frame sync generator.						R/W	1																	
		1	Deactivate the active clock and frame sync generator.																								
14	AGSYNC [†]	0	Do not synchronize the active generated input and output bit clocks to an external source.						R/W	0																	
		1	Configure the external input frame sync (SIFS) pin as an input and synchronize the active generated input and output bit clocks to SIFS.																								
13	SCKK [†]	0	Do not invert the SCK pin before applying it to the active clock generator, i.e., if SCK is selected as the active clock source [‡] , the rising edge of the active generated input and output bit clocks is generated by the rising edge of SCK.						R/W	0																	
		1	Invert the SCK pin before applying it to the active clock generator, i.e., if SCK is selected as the active clock source [‡] , the rising edge of the active generated input and output bit clocks is generated by the falling edge of SCK. Set this bit only if AGEXT is also set.																								
12	AGEXT [†]	0	The processor clock (CLK) is the clock source for the active clock and frame sync generator.						R/W	0																	
		1	The SCK pin (modified according to SCKK) is the clock source for the active clock and frame sync generator.																								
11	Reserved	0	Reserved—write with zero.						R/W	0																	
10—0	AGFSLIM[10:0] [†]	0—2047	Active frame sync divide ratio—controls the period and duty cycle of the active generated frame syncs (IFS and OFS). The period of IFS and OFS (TAGFS) is the following: $TAGFS = TAGCK \times (\max(1, AGFSLIM[10:0]) + 1)$ where TAGCK is the period of the clock source [§] for IFS and OFS. The high and low times of IFS and OFS (TAGFSH and TAGFSL) are as follows: $TAGFSH = TAGCK \times \text{int}((\max(1, AGFSLIM[10:0]) + 1) \div 2)$ $TAGFSL = TAGCK \times \text{int}((\max(1, AGFSLIM[10:0]) + 2) \div 2)$ where TAGCK is the period of the clock source [§] for IFS and OFS and int() is the integer function (truncation). The following table illustrates examples:						R/W	0																	
			<table border="1"> <thead> <tr> <th></th> <th>Frame Sync Period</th> <th>High Time</th> <th>Low Time</th> </tr> </thead> <tbody> <tr> <th>AGFSLIM[7:0]</th> <th>TAGFS</th> <th>TAGFSH</th> <th>TAGFSL</th> </tr> <tr> <td>15</td> <td>16 × TAGCK</td> <td>8 × TAGCK</td> <td>8 × TAGCK</td> </tr> <tr> <td>16</td> <td>17 × TAGCK</td> <td>8 × TAGCK</td> <td>9 × TAGCK</td> </tr> <tr> <td>2047</td> <td>2048 × TAGCK</td> <td>1024 × TAGCK</td> <td>1024 × TAGCK</td> </tr> </tbody> </table>				Frame Sync Period	High Time			Low Time	AGFSLIM[7:0]	TAGFS	TAGFSH	TAGFSL	15	16 × TAGCK	8 × TAGCK	8 × TAGCK	16	17 × TAGCK	8 × TAGCK	9 × TAGCK	2047	2048 × TAGCK	1024 × TAGCK	1024 × TAGCK
	Frame Sync Period	High Time	Low Time																								
AGFSLIM[7:0]	TAGFS	TAGFSH	TAGFSL																								
15	16 × TAGCK	8 × TAGCK	8 × TAGCK																								
16	17 × TAGCK	8 × TAGCK	9 × TAGCK																								
2047	2048 × TAGCK	1024 × TAGCK	1024 × TAGCK																								

[†] If the IRESET field (SCON1[10]) or ORESET field (SCON2[10]) is cleared, do not change the value in this field.

[‡] SCK is selected as the clock source for the active clock generator if AGEXT is 1.

[§] The clock source is the active generated bit clock with period TAGCK.

4 Hardware Architecture (continued)

4.16 Serial Interface Unit (SIU) (continued)

4.16.15 Registers (continued)

Table 114. SIDR (SIU Input Data) Register

The memory address for this register is 0x4301A for SIU0 and 0x4401A for SIU1.

15—0 Serial Input Data				
Bit	Field	Description	R/W	Reset Value
15—0	Serial Input Data	Read-only 16-bit serial input data. The SIU can optionally expand the data in the input shift register before latching it into SIDR . The user program controls this optional expansion by configuring the IFORMAT[1:0] field (SCON0 [1:0]—Table 101 on page 182).	R	0

Table 115. SODR (SIU Output Data) Register

The memory address for this register is 0x4301C for SIU0 and 0x4401C for SIU1.

15—0 Serial Output Data				
Bit	Field	Description	R/W	Reset Value
15—0	Serial Output Data	Write-only 16-bit serial output data. The SIU optionally compresses the data in SODR before latching it into the output shift register. The user program controls this optional compression by configuring the OFORMAT[1:0] field (SCON0 [9:8]—Table 101 on page 182).	W	0

4 Hardware Architecture (continued)

4.16 Serial Interface Unit (SIU) (continued)

4.16.15 Registers (continued)

Table 116. STAT (SIU Input/Output General Status) Register

The memory address for this register is 0x4301E for SIU0 and 0x4401E for SIU1.

15—8		7	6	5	4	3	2	1	0
Reserved		OUFLOW	IOFLOW	OFERR	IFERR	SODV	Reserved	SIBV	SIDV
Bit	Field	Value	Description			R/W	Reset Value		
15—8	Reserved	0	Reserved—write with zero.			R/W	0		
7	OUFLOW [†]	0	Output underflow error has not occurred.			R/Clear	0		
		1	Output underflow error has occurred.						
6	IOFLOW [†]	0	Input overflow error has not occurred.			R/Clear	0		
		1	Input overflow error has occurred.						
5	OFERR [†]	0	Output frame error has not occurred.			R/Clear	0		
		1	Output frame error has occurred.						
4	IFERR [†]	0	Input frame error has not occurred.			R/Clear	0		
		1	Input frame error has occurred.						
3	SODV	0	SODR does not contain valid data.			R	0		
		1	SODR contains valid data.						
2	Reserved	0	Reserved—write with zero.			R/W	0		
1	SIBV	0	SIB [‡] does not contain valid data.			R	0		
		1	SIB [‡] contains valid data.						
0	SIDV	0	SIDR does not contain valid data.			R	0		
		1	SIDR contains valid data.						

[†] The programmer clears this bit by writing it with 1. Writing 0 to this bit leaves it unchanged.

[‡] The **SIB** register is an intermediate register that holds the contents of the input shift register and is not user accessible.

Table 117. FSTAT (SIU Input/Output Frame Status) Register

The memory address for this register is 0x43020 for SIU0 and 0x44020 for SIU1.

15		14—8		7	6—0		
OACTIVE		OFIX[6:0]		IACTIVE	IFIX[6:0]		
Bit	Field	Value	Description			R/W	Reset Value
15	OACTIVE	0	No output channels have been processed.			R	0
		1	At least one output channel has been processed following output section reset (ORESET(SCON2[10]) = 0). (Distinguishes the 0th and $n \times 8$ th output subframes.)				
14—8	OFIX[6:0]	0—127	Channel index of the next enabled output channel.			R	0
7	IACTIVE	0	No input channels have been processed.			R	0
		1	At least one input channel has been processed following input section reset (IRESET(SCON1[10]) = 0). (Distinguishes the 0th and $n \times 8$ th input subframes.)				
6—0	IFIX[6:0]	0—127	Current input channel index.			R	0

4 Hardware Architecture (continued)

4.16 Serial Interface Unit (SIU) (continued)

4.16.15 Registers (continued)

Table 118. OCIX<0—1> and ICIX<0—1> (SIU Output and Input Channel Index) Registers

Register	Address		Description	See
	SIU0	SIU1		
OCIX0	0x43030	0x44030	Output channel index for the active even subframe.	Table 119
OCIX1	0x43032	0x44032	Output channel index for the active odd subframe.	Table 119
ICIX0	0x43040	0x44040	Input channel index for the active even subframe.	Table 120 on page 196
ICIX1	0x43042	0x44042	Input channel index for the active odd subframe.	Table 120 on page 196

Table 119. OCIX<0—1> (SIU Output Channel Index) Registers

See Table 118 on page 195 for the memory addresses of these registers.

			15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Channel Mode (Each bit is mapped to a logical channel in the active sub-frame.)	OCIX0	Subframe 0	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
		Subframe 2	47	46	45	44	43	42	41	40	39	38	37	36	35	34	33	32
		Subframe 4	79	78	77	76	75	74	73	72	71	70	69	68	67	66	65	64
		Subframe 6	111	110	109	108	107	106	105	104	103	102	101	100	99	98	97	96
	OCIX1	Subframe 1	31	30	29	28	27	26	25	24	23	22	21	20	19	18	17	16
		Subframe 3	63	62	61	60	59	58	57	56	55	54	53	52	51	50	49	48
		Subframe 5	95	94	93	92	91	90	89	88	87	86	85	84	83	82	81	80
		Subframe 7	127	126	125	124	123	122	121	120	119	118	117	116	115	114	113	112

			15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Frame Mode† (Each bit is circularly mapped to four logical channels.)	OCIX0		15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
			47	46	45	44	43	42	41	40	39	38	37	36	35	34	33	32
			79	78	77	76	75	74	73	72	71	70	69	68	67	66	65	64
			111	110	109	108	107	106	105	104	103	102	101	100	99	98	97	96
	OCIX1		31	30	29	28	27	26	25	24	23	22	21	20	19	18	17	16
			63	62	61	60	59	58	57	56	55	54	53	52	51	50	49	48
			95	94	93	92	91	90	89	88	87	86	85	84	83	82	81	80
			127	126	125	124	123	122	121	120	119	118	117	116	115	114	113	112

Bit	Value	Description (SIU0)	Description (SIU1)	R/W	Reset Value
15—0	0	Use DMAU channel SWT0 for output to the logical channel shown above.	Use DMAU channel SWT2 for output to the logical channel shown above.	R/W	0
	1	Use DMAU channel SWT1 for output to the logical channel shown above.	Use DMAU channel SWT3 for output to the logical channel shown above.		

† If the number of logical channels per frame is one (OFLIM[6:0] (SCON2[6:0]) = 0) in frame mode, bits 1 and 0 of OCIX0 (OCIX0[1:0]) must be programmed with the same value.

4 Hardware Architecture (continued)

4.16 Serial Interface Unit (SIU) (continued)

4.16.15 Registers (continued)

Table 120. ICIX<0—1> (SIU Input Channel Index) Registers

See Table 118 for the memory addresses of these registers.

			15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Channel Mode (Each bit is mapped to a logical channel in the active sub-frame.)	ICIX0	Subframe 0	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
		Subframe 2	47	46	45	44	43	42	41	40	39	38	37	36	35	34	33	32
		Subframe 4	79	78	77	76	75	74	73	72	71	70	69	68	67	66	65	64
		Subframe 6	111	110	109	108	107	106	105	104	103	102	101	100	99	98	97	96
	ICIX1	Subframe 1	31	30	29	28	27	26	25	24	23	22	21	20	19	18	17	16
		Subframe 3	63	62	61	60	59	58	57	56	55	54	53	52	51	50	49	48
		Subframe 5	95	94	93	92	91	90	89	88	87	86	85	84	83	82	81	80
		Subframe 7	127	126	125	124	123	122	121	120	119	118	117	116	115	114	113	112

			15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Frame Mode† (Each bit is circularly mapped to four logical channels.)	ICIX0	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0	
		47	46	45	44	43	42	41	40	39	38	37	36	35	34	33	32	
		79	78	77	76	75	74	73	72	71	70	69	68	67	66	65	64	
		111	110	109	108	107	106	105	104	103	102	101	100	99	98	97	96	
	ICIX1	31	30	29	28	27	26	25	24	23	22	21	20	19	18	17	16	
		63	62	61	60	59	58	57	56	55	54	53	52	51	50	49	48	
		95	94	93	92	91	90	89	88	87	86	85	84	83	82	81	80	
		127	126	125	124	123	122	121	120	119	118	117	116	115	114	113	112	

Bit	Value	Description (SIU0)	Description (SIU1)	R/W	Reset Value
15—0	0	Use DMAU channel SWT0 for input from the logical channel shown above.	Use DMAU channel SWT2 for input from the logical channel shown above.	R/W	0
	1	Use DMAU channel SWT1 for input from the logical channel shown above.	Use DMAU channel SWT3 for input from the logical channel shown above.		

† If the number of logical channels per frame is one (IFLIM[6:0](SCON1[6:0]) = 0) in frame mode, bits 1 and 0 of ICIX0 (ICIX0[1:0]) must be programmed with the same value.

4 Hardware Architecture (continued)

4.17 Internal Clock Selection

The DSP16410B internal clock can be driven from one of two sources. The primary source clock is an on-chip programmable clock synthesizer that can be driven by an external clock input pin (CKI) at a fraction of the required instruction rate. The clock synthesizer is based on a phase-lock loop (PLL). The terms clock synthesizer and PLL are used interchangeably. Section 4.18 describes the PLL and its associated **pllcon**, **pllfrq**, and **plldly** registers in detail.

Note: Internal clock functions for the DSP16410B are controlled by CORE0 because the registers **pllcon**, **pllfrq**, and **plldly** are only available to programs executing in CORE0.

Figure 54 illustrates the internal clock selection logic that selects the internal clock (fCLK) from one of the following two source clocks:

- CKI: This pin is driven by an external oscillator or the pin's associated boundary-scan logic under JTAG control. If CKI is selected as the source clock, fCLK has the frequency and duty cycle of fCKI. The

DSP16410B consumes less power if clocked with CKI.

- PLL: The PLL generates a source clock with a programmable frequency. If the PLL is selected as the source clock, fCLK has the frequency and duty cycle of the PLL output fSYN.

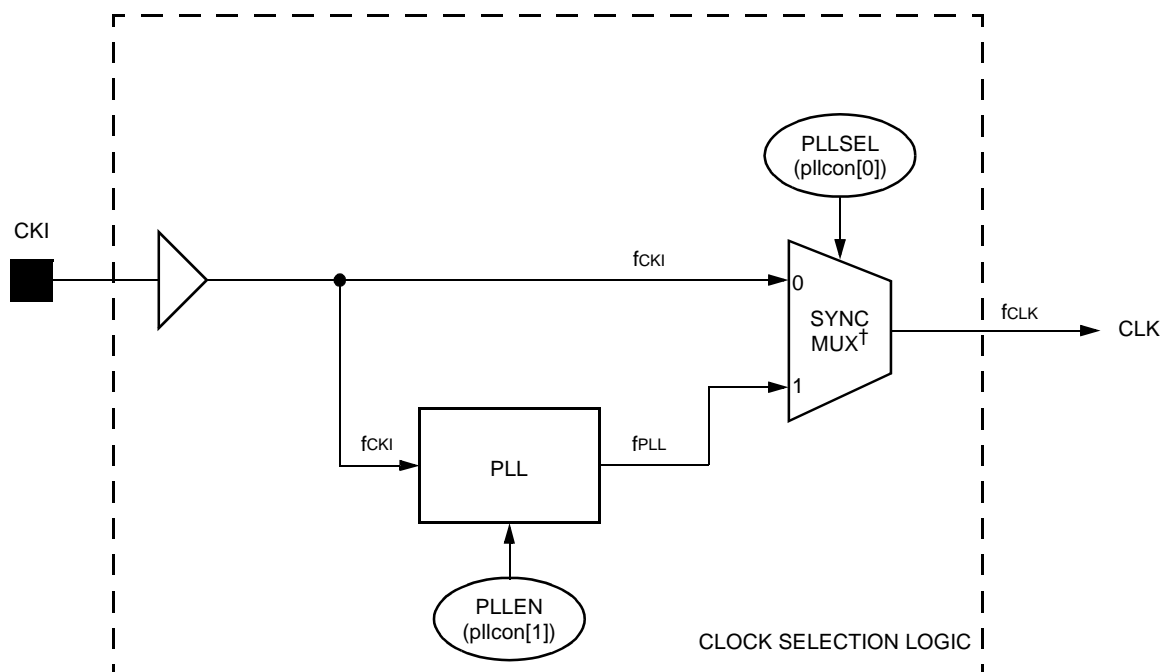
After device reset, the default source clock signal is CKI.

The programmer can select the PLL as the source clock by setting the PLLSEL field (**pllcon**[0])—see Table 122 on page 199). Before selecting the PLL as the clock source, the user program must first enable (power up) the PLL by setting the PLEN field (**pllcon**[1]) and then wait for the PLL to lock. See Section 4.18 for details.

Table 121 summarizes the selection of the two source clocks as a function of the PLLSEL field.

Table 121. Source Clock Selection

PLLSEL (pllcon [0])	fCLK	Description
0	fCKI	CKI pin
1	fSYN	PLL



† The multiplexer is designed so that no partial clocks or glitching occurs.

Figure 54. Internal Clock Selection Logic

4 Hardware Architecture (continued)

4.18 Clock Synthesis

Figure 55 is a block diagram of the clock synthesizer, or phase-lock loop (PLL). CORE0 enables, selects, and configures the PLL by writing to three registers, **pllcon**, **pllfrq**, and **plldly** (see Section 4.18.3 on page 199). **pllcon** is used to enable and select the PLL clock synthesizer (see Section 4.17). **pllfrq** determines the frequency multiplier of the PLL (see Section 4.18.1). Before selecting the PLL as the clock source, the user program must first enable (power up) the PLL by setting the PLEN field (**pllcon**[1]) and then wait for the PLL to lock. **plldly** is used for PLL LOCK flag generation (see Section 4.18.2).

4.18.1 PLL Operating Frequency

The PLL-synthesized clock frequency is determined by the fields of the **pllfrq** register. The synthesized clock frequency is calculated as:

$$f_{\text{SYN}} = f_{\text{CKI}} \cdot \frac{(M + 2)}{(D + 2) \cdot f(\text{OD})}$$

In the formula above, f_{SYN} is the frequency of the clock generated by the PLL, $(M + 2)$ is the frequency multiplier, $(D + 2)$ is the feedback divisor, and $f(\text{OD})$ is the output frequency divisor. The values of M, D, and $f(\text{OD})$ are determined by the M[8:0], D[4:0], and OD[1:0] fields of **pllfrq** as defined in Table 123 on page 199.

Table 183 on page 277 specifies the minimum and maximum values for the input clock frequency (f_{CKI}),

the divided input clock frequency ($f_{\text{CKI}}/(D + 2)$), and the VCO output frequency (f_{VCO}). The values of M, D, and $f(\text{OD})$ must be chosen to meet these requirements.

4.18.2 PLL LOCK Flag Generation

The DSP16410B does not provide a PLL-generated status flag that indicates when the PLL has locked. Instead, a user-programmable register, **plldly** (Table 124 on page 199), and an associated delay counter is used for this purpose. If the **pllcon** register is written to enable the PLL, the delay counter is loaded with the value in **plldly**. The PLL decrements this counter for each subsequent cycle of the DSP input clock (CKI). When the counter reaches zero, the LOCK status flag is asserted. The state of the LOCK flag can be tested by conditional instructions (Section 6.1.1) and is also visible in the **alf** register (Table 140 on page 232). The LOCK flag is cleared by a device reset or a write to the **pllcon** register.

The PLL requires 0.5 ms to achieve lock. The application software should set the **plldly** register to a value that produces a minimum delay of 0.5 ms. The register setting needed to achieve this delay is dependent on the frequency of the input clock (CKI). The programmed value for **plldly** that results in a countdown delay of 0.5 ms is the following:

$$\text{plldly} = 500 \times f_{\text{CKI}}$$

where f_{CKI} is the input clock frequency in MHz.

See Section 4.18.4 for PLL programming examples that include the use of **plldly**.

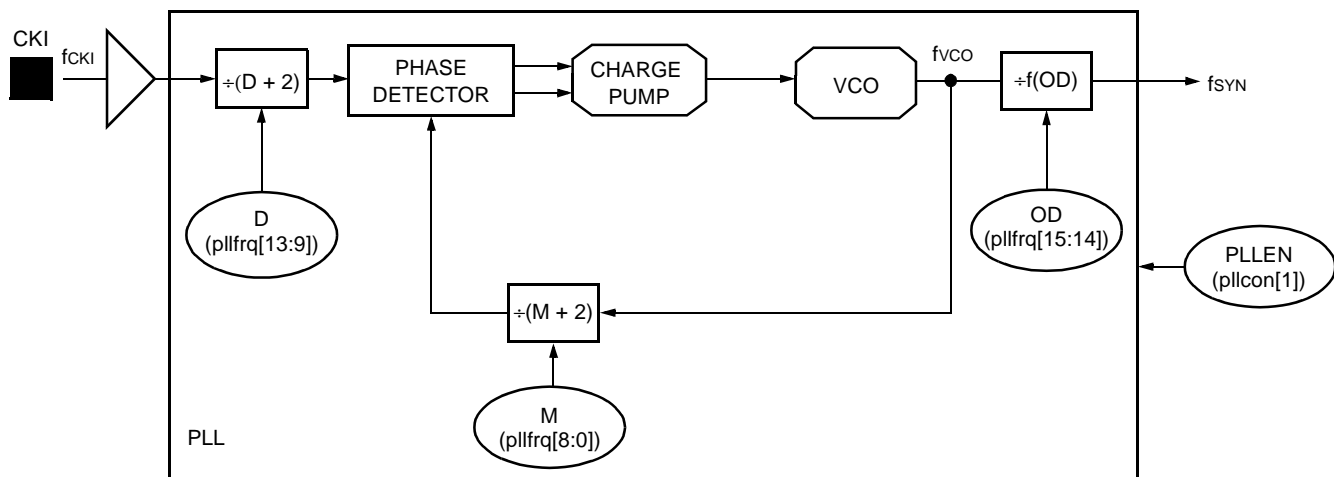


Figure 55. Clock Synthesizer (PLL) Block Diagram

4 Hardware Architecture (continued)

4.18 Clock Synthesis (continued)

4.18.3 PLL Registers

Table 122. pllcon (Phase-Lock Loop Control) Register

Note: pllcon is accessible in CORE0 only.

15—2			1	0	
Reserved			PLLEN	PLLSEL	
Bit	Field	Value	Description	R/W	Reset Value
15—2	Reserved	—	Reserved—write with zero.	R/W	0
1	PLLEN	0	Disable (power down) the PLL.	R/W	0
		1	Enable (power up) the PLL.		
0	PLLSEL	0	Select the CKI input as the internal clock (CLK) source.	R/W	0
		1	Select the PLL as the internal clock (CLK) source.		

Table 123. pllfrq (Phase-Lock Loop Frequency Control) Register

Note: pllfrq is accessible in CORE0 only.

15—14			13—9	8—0	
OD[1:0]			D[4:0]	M[8:0]	
Bit	Field	Value	Description	R/W	Reset Value
15—14	OD[1:0]	00	$f(OD) = 2$. Divide VCO output by 2.	R/W	00
		01	$f(OD) = 4$. Divide VCO output by 4.		
		10	$f(OD) = 4$. Divide VCO output by 4.		
		11	$f(OD) = 8$. Divide VCO output by 8.		
13—9	D[4:0]	0—31	Divide f_{CKI} by this value plus two ($D + 2$).	R/W	00000
8—0	M[8:0]	0—511	Multiply f_{CKI} by this value plus two ($M + 2$).	R/W	000000000

Table 124. plldly (Phase-Lock Loop Delay Control) Register

Note: plldly is accessible in CORE0 only.

15—0					
DLY[15:0]					
Bit	15—0	Value	Description	R/W	Reset Value
15—0	DLY[15:0]	—	The contents of DLY[15:0] is loaded into the PLL delay counter after a pllcon register write. If PLLEN (pllcon [1]) is 1, the counter decrements each CKI cycle. When the counter reaches zero, the LOCK flag† for both CORE0 and CORE1 is asserted.	R/W	0x1388

† The state of the LOCK flag can be tested by conditional instructions (Table 134 on page 223) and is also visible in the **alf** register (Table 140 on page 232). The LOCK flag is cleared by a device reset or a write to the **pllcon** register.

4 Hardware Architecture (continued)

4.18 Clock Synthesis (continued)

4.18.4 PLL Programming Examples

The following examples illustrate the recommended PLL programming sequence.

PLL programming example 1: CKI 10 MHz, CLK target 150 MHz.

```

pllcon=0x0000      // Turn off the PLL
plldly=0x1388      // Set countdown delay = 0.5 ms (500 x 10 = 5000 = 0x1388)
pllfrq=0x003A      // OD=0, D=0, M=58. fsyn=10*(58+2)/((0+2)*(2)). VCO=300 MHz
pllcon=0x0002      // Turn on PLL
4*nop              // Wait for pllcon write to complete

pllwait:
if lock goto pllcon // Wait for countdown to complete
goto pllwait

pllcon:
pllcon=0x0003      // Select PLL as CLK source

```

PLL programming example 2: CKI = 13.5 MHz, CLK target 162 MHz.

```

pllcon=0x0000      // Turn off the PLL
plldly=0x1A5E      // Set countdown delay = 0.5 ms (500 x 13.5 = 6750 = 0x1A5E)
pllfrq=0x002E      // OD=0, D=0, M=46. fsyn=13.5*(46+2)/((0+2)*(2)). VCO=324 MHz
pllcon=0x0002      // Turn on PLL
4*nop              // Wait for pllcon write to complete

pllwait:
if lock goto pllcon // Wait for countdown to complete
goto pllwait

pllcon:
pllcon=0x0003      // Select PLL as CLK source

```

4.18.5 Powering Down the PLL

Clearing the PLEN field (**pllcon**[1]) powers down the PLL. Do not power down the PLL (do not clear PLEN) if the PLL is selected as the clock source (PLLSEL (**pllcon**[0]) = 1). The PLL must be deselected as the clock source prior to or concurrent with powering down the PLL. See [Section 4.20](#) for general information on power management.

Caution: Do not power down the PLL (PLEN = 0) while it is selected as the clock source (PLLSEL = 1). If this occurs, the device freezes because it has no clock source and cannot operate. To recover from this condition, the RSTN, TRST0N, and TRST1N pins must be asserted to reset the device.

4.18.6 Phase-Lock Loop (PLL) Frequency Accuracy and Jitter

Although the average frequency of the PLL output has almost the same relative accuracy as the input clock, noise sources within the DSP16410B produce jitter on the PLL clock. The PLL is guaranteed to have sufficiently low jitter to operate the DSP16410B. However, if the PLL clock is used as the clock source for external devices via the ECKO pin, do not apply this clock to jitter-sensitive devices. See [Table 183 on page 277](#) for the input jitter requirements for the PLL.

Note: Jitter on the ECKO output clock pin does not need to be taken into account with respect to the timing requirements and characteristics specified in [Section 11](#).

4 Hardware Architecture (continued)

4.19 External Clock Selection

The ECKO pin can be programmed using the ECKO[1:0] field (**ECON1**[1:0]—[Table 60 on page 110](#)) to select one of the following outputs:

1. CLK/2: The internal clock CLK divided by 2.
2. CLK: The internal clock CLK.
3. CKI: The buffered CKI pin.
4. ZERO: Logic low.

After reset, the ECKO output pin is configured as CLK/2 and CLK is configured as CKI. Therefore, after reset, ECKO is configured as CKI/2.

The logic that controls the ECKO pin is illustrated in [Figure 56 on page 203](#). If the application does not require a clock on the ECKO pin, the user can program ECKO as logic low during initialization to reduce power consumption.

Note: Although **ECON1** can be accessed by either core, the programmer should select only one core (such as CORE0) to control the ECKO pin. The programmer is responsible for developing a protocol between CORE0 and CORE1. Intercore coordination is not part of the DSP16410B hardware.

4 Hardware Architecture (continued)

4.20 Power Management

A program running in a core can place that core into low-power standby mode by setting the AWAIT field (**alf**[15]—see [Table 140 on page 232](#)). In this mode, the clock to that core and its associated TPRAM are disabled except for the minimum core circuitry required to process an incoming interrupt or trap. The clock to the peripherals is unaffected.

[Figure 56 on page 203](#) illustrates the following:

- Distribution of CLK to the cores and peripherals.
- Function of the AWAIT field.
- Interrupts to the core used to exit low-power standby mode.
- ECKO pin selection logic (see [Section 4.19 on page 201](#) for details).

If a core is in low-power standby mode, program execution in that core is suspended without loss of state. If an interrupt that was enabled by that core occurs or if a trap occurs, the core clears its AWAIT field, exits low-power standby mode, resumes program execution, and services the interrupt or trap. See [Section 4.4.5 on page 30](#) and [Section 4.4.6 on page 31](#) for information on enabling interrupts.

If the DMAU accesses the TPRAM while the associated core is in standby mode, the clock to the TPRAM is re-enabled for that access. However, if the core goes into standby mode while an access to a memory component is in progress, it locks out the DMAU from accessing that component. To prevent locking out the DMAU, the user program must use the macro **SLEEP_ALF ()** in the **16410.h** file. The **16410.h** file is included with the Agere software generation system

(SGS) tools. Using **SLEEP_ALF ()** guarantees that the core completes all pending memory accesses before entering standby mode.

SLEEP_ALF () expands to the following:

```
.align
    goto .+1
    alf=0x8000
    3*nop
```

If CORE0 is entering low-power standby mode, it can further save power by doing one or more of the following prior to entering standby mode:

1. Select the CKI pin as the source clock to the cores and peripherals by clearing the PLLSEL field (**pllcon**[0]—see [Table 122 on page 199](#)).
2. Disable (power down) the PLL by clearing the PLEN field (**pllcon**[1]).
3. Drive the ECKO¹ pin low by programming the ECKO[1:0] field (**ECON1**[1:0]—see [Table 60 on page 110](#)) to 3.

Options 1 and 2 result in increased wake-up latency, which is the delay from the time that the core exits standby mode (due to an interrupt) to the time that the core resumes full-speed execution. Before selecting these options, the programmer must ensure that the increased wake-up latency is acceptable in the application. [Table 125](#) compares the wake-up latency for various selections of clocks during standby mode. It also illustrates the trade-off of wake-up latency vs. power consumption. Disabling the PLL during low-power standby mode results in the minimum power consumption and highest wake-up latency. See [Section 10.3 on page 271](#) and [Section 11.2 on page 278](#) for details on power dissipation and wake-up latency for various operating modes.

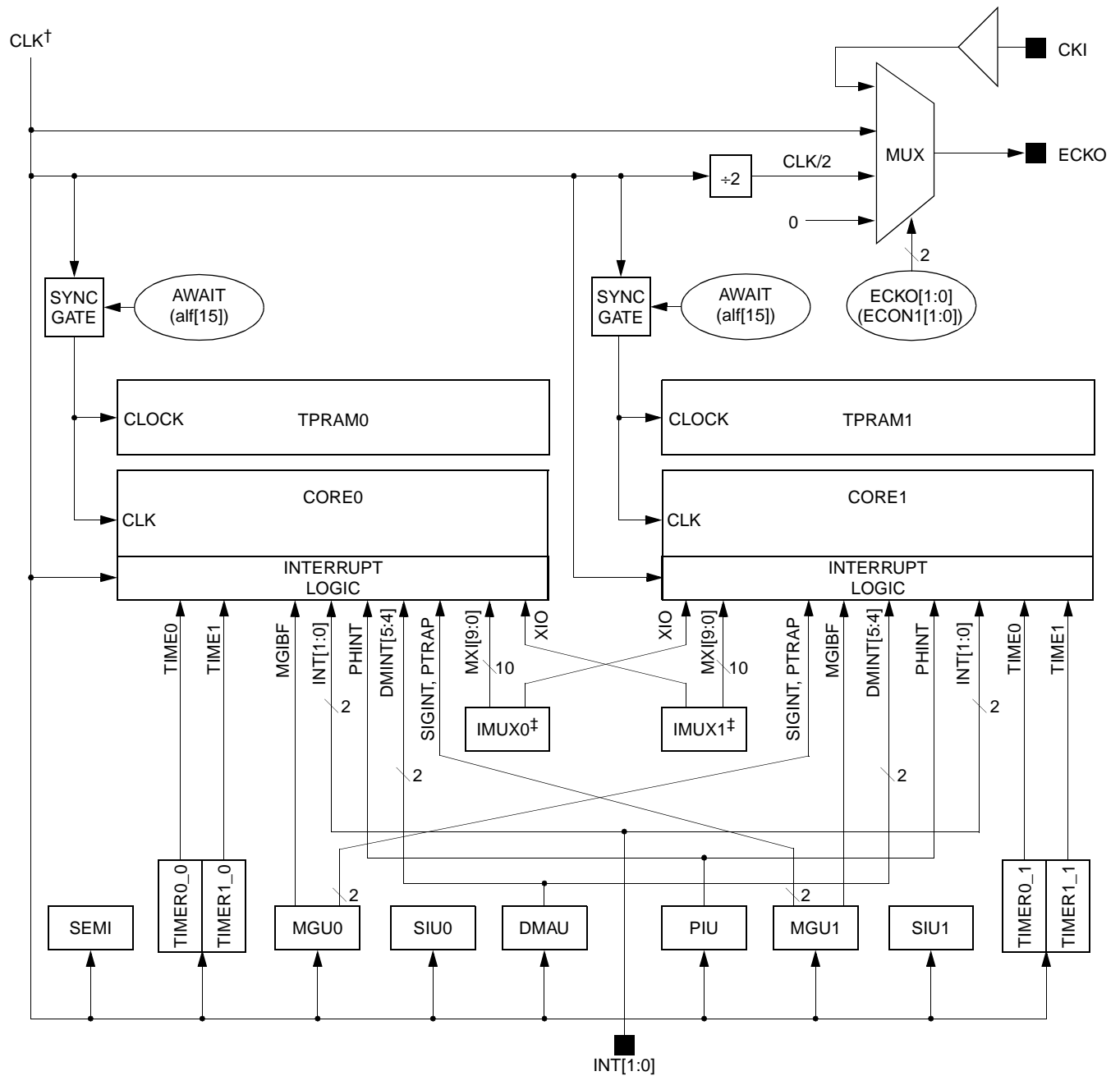
Table 125. Wake-Up Latency and Power Consumption for Low-Power Standby Mode

Source Clock Selected In Standby Mode	Status of PLL In Standby Mode	Wake-Up Latency	Latency vs. Power Consumption Trade-off
PLL	Enabled	3 PLL cycles	Minimum wake-up latency (highest power)
CKI Pin	Enabled	3 CKI cycles	—
	Disabled	3 CKI cycles + PLL lock-in time	Minimum power (highest wake-up latency)

1. Although **ECON1** can be accessed by either core, the programmer should select only one core (such as CORE0) to control the ECKO pin. The programmer is responsible for developing a protocol between CORE0 and CORE1. Intercore coordination is not part of the DSP16410B hardware.

4 Hardware Architecture (continued)

4.20 Power Management (continued)



† CLK is described in Section 4.17.

‡ The IMUX is described in Section 4.4.2.

Figure 56. Power Management and Clock Distribution

4 Hardware Architecture (continued)

4.20 Power Management (continued)

If the program running in CORE0 selects the CKI pin as the source clock before entering standby mode, that clock is selected as the source clock immediately after the core exits standby mode. Likewise, if the program running in CORE0 disables the PLL before entering standby mode, the PLL is disabled immediately after the core exits standby mode. Assuming the PLL is the source clock for normal operation, the CORE0 program must re-enable and then re-select the PLL after exiting standby mode in order to resume full-speed processing.

An interrupt causes the associated core to exit standby mode and immediately service the interrupt. If the interrupt is to CORE0 and the interrupt service routine (ISR) performs time-critical processing, it must re-enable and then reselect the PLL before performing any processing to service the interrupt. If the interrupt is to CORE1 and the ISR performs time-critical processing, CORE1 must interrupt CORE0 to re-enable and then reselect the PLL before CORE1 performs any processing to service the interrupt. The programmer is responsible for developing a protocol between CORE0 and CORE1 to coordinate changing clocks. Intercore coordination is not part of the DSP16410B hardware.

If the program selects the CKI pin as the source clock before entering standby mode, the peripherals also operate at the slower rate. This can result in an increased delay for a peripheral to interrupt the core to exit standby mode.

If CORE0 or CORE1 is entering low-power standby mode, it can save additional power by powering down one or both of its timers (set `timer{0,1}c[6]`) prior to entering low-power standby mode. [Section 4.10 on page 52](#) describes the procedures for powering down the timers.

5 Processor Boot-Up and Memory Download

The state of the EXM pin at the time of reset determines whether CORE0 and CORE1 boot from their internal boot ROMs or from external memory, as specified in [Table 126](#).

Table 126. Core Boot-Up After Reset

State of EXM Pin on Rising Edge of RSTN	CORE0 Begins Executing Code From:	CORE1 Begins Executing Code From:
EXM = 0	IROM0 (address 0x20000)	IROM1 (address 0x20000)
EXM = 1	EROM (address 0x80000)	EROM (address 0x80000)

[Table 127](#) summarizes the contents of the internal boot ROMs, IROM0 and IROM1. The contents of IROM0 and IROM1 are identical.

Table 127. Contents of IROM0 and IROM1 Boot ROMs

Address		Code
0x20000	—	Instruction: goto 0x20800 (boot routine).
0x20004	0x203FF	Reserved for HDS code.
0x20800	0x208FF	Boot routine.
0x20FFE	0x20FFF	Processor type: 0x00000003.

If the cores boot from their internal boot ROMs, then they execute a boot routine that is described in [Section 5.1](#). This routine simply waits for an external host to download code and data into the TPRAMs via the PIU. When the download is complete, the boot routine causes each core to branch to the first location in its TPRAM.

If the cores boot from EROM, then the user must place a boot routine for both cores into EROM prior to reset. [Section 5.2 on page 206](#) outlines a boot routine that downloads code and data into the TPRAMs via the DMAU and then causes each core to branch to the first location in its own TPRAM.

Note: After the deassertion of RSTN and during the execution of the boot routine, the clock synthesizer (PLL) is disabled and the frequency of the internal clock (CLK) is the same as the input clock pin (CKI).

5.1 IROM Boot Routine and Host Download Via PIU

CORE0 and CORE1 boot from IROM0 and IROM1 if the EXM pin is low when RSTN is deasserted. The boot routine in IROM0 is identical to that in IROM1. The routine polls for the PHINT interrupt condition¹ in the **ins** register ([Table 150 on page 239](#)) to determine when the external host has completed downloading to TPRAM via the PIU. While the cores wait for PHINT to be set, the host can download code and data to any of the memory spaces in the Z-memory space, summarized below:

- Internal memory and I/O:
 - TPRAM0
 - TPRAM1
 - Internal I/O (includes SLM and memory-mapped peripheral registers)
- External memory and I/O:
 - EIO space
 - ERAM space
 - EROM space

1. Interrupts remain globally disabled during execution of the boot routine, and the PHINT interrupt condition is detected by polling.

5 Processor Boot-Up and Memory Download (continued)

5.1 IROM Boot Routine and Host Download Via PIU (continued)

The host accesses DSP16410B memory by executing commands that cause the PIU to use the DMAU bypass channel for downloading. See [Section 4.15.5 on page 144](#) for details. When the host has completed the download, it asserts the PHINT interrupt and sets the PHINT interrupt pending status field (**ins**[13]—see [Table 150 on page 239](#)) by writing the HINT field (**PCON**[4]—see [Table 73 on page 133](#)). After each boot routine detects the assertion of PHINT, it branches to the first location of TPRAM (TPRAM0 for CORE0 and TPRAM1 for CORE1).

The boot routine is shown below:

```
.rsect ".rom"                // Address 0x20000

goto PUPBOOT                // Branch to boot routine.

// Other Vectors, HDS code, and Production test code go here.

.rsect ".PowerUpBoot"      // Address 20800

PUPBOOT:    pt0=0
pollboot:   a0=ins
            a0 & 0x0000002000           // Check ins[PHINT].
            if eq goto pollboot        // Wait for ins[PHINT] to be set.
            r0=0x41000                // Point to the PCON register.
            a0=0x0010
            ins=0xffff                // Clear pending interrupts in ins.
            *r0=a0                    // Write PCON to clear HINT bit.
            a0=0; r0=0                // Cleanup.
            goto pt0                  // Jump to user code.
```

5.2 EROM Boot Routine and DMAU Download

CORE0 and CORE1 both boot from EROM at address 0x80000 if the EXM pin is high when RSTN is deasserted. The cores access EROM via the SEMI, and the SEMI interleaves the accesses so that CORE0 executes the instruction at address 0x80000 first, then CORE1 executes the instruction at address 0x80000 next, etc. The user must place a boot routine for both cores into EROM prior to reset. This boot routine can contain instructions to download code and data from ERAM to internal memory (TPRAM0 and TPRAM1) via the DMAU. The download can be performed either by both cores or by one core while the other core waits. In either case, the boot routine must distinguish whether CORE0 or CORE1 is executing it. It does this by reading the processor ID (**pid**) register ([Table 153 on page 239](#)). The contents of CORE0's **pid** register is 0x0 and the contents of CORE1's **pid** register is 0x1. After determining the processor ID, the boot routine can branch to the correct boot procedure for that core. Once the download is complete, both cores can terminate their boot procedures by executing the following instructions:

```
pt0=0x0
nop
goto pt0
```

This causes CORE0 to begin executing instructions at address 0x0 of TPRAM0 and CORE1 to begin executing instructions at address 0x0 of TPRAM1.

6 Software Architecture

6.1 Instruction Set Quick Reference

The DSP16410B instruction set consists of both 16-bit and 32-bit wide instructions and resembles C-code. Table 128 defines the seven types of instructions. The assembler translates a line of assembly code into the most efficient DSP16410B instruction(s). See Table 130 on page 215 for instruction set notation conventions.

Table 128. DSP16410B Instruction Groups

Instruction Group	F Title (If Applicable)	Description
MAC	{F1} {TRANSFER} {F1E} {TRANSFER} {if CON} F1E	The powerful MAC instruction group is the primary group of instructions used for signal processing. Up to two data transfers can be combined with up to four parallel DAU operations in a single MAC instruction to execute simultaneously [†] . The DAU operation combinations include (but are not limited to) either a dual-MAC [‡] operation, an ALU operation and a BMU operation, or an ALU/ACS operation and an ADDER/ACS operation. The F1E instructions that do not include a transfer statement can execute conditionally based on the state of flags [§] .
Special Function	{if CON} F2 ifc CON F2 {if CON} F2E ifc CON F2E	Special functions include rounding, negation, absolute value, and fixed arithmetic left and right shift operations. The operands are an accumulator, another DAU register, or an accumulator and another DAU register. Some special function instructions increment counters. Special functions execute conditionally based on the state of flags [§] .
ALU	F3 {if CON} F3E	ALU instructions operate on two accumulators or on an accumulator and another DAU register. Many instructions can also operate on an accumulator and an immediate data word. The ALU operations are add, subtract, logical AND, logical OR, exclusive OR, maximum, minimum, and divide-step. Some F3E instructions include a parallel ADDER operation. The F3E instructions can execute conditionally based on the state of flags [§] .
BMU	F4 {if CON} F4E	Full barrel shifting, exponent computation, normalization computation, bit-field extraction or insertion, and data shuffling between two accumulators are BMU operations that act on the accumulators. BMU operations are controlled by an accumulator, an auxiliary register, or a 16-bit immediate value. The F4E instructions can execute conditionally based on the state of flags [§] .
Data Move and Pointer Arithmetic	—	Data move instructions transfer data between two registers or between a register and memory. This instruction group also supports immediate loads of registers, conditional register-to-register moves, pipeline block moves, and specialized stack operations. Pointer arithmetic instructions perform arithmetic on data pointers and do not perform a memory access.
Control	—	The control instruction group contains branch and call subroutine instructions with either a 20-bit absolute address or a 12-bit or 16-bit PC-relative address. This group also includes instructions to enable and disable interrupts. Some control instructions can execute conditionally based on the state of processor flags [§] .
Cache	—	Cache instructions implement low-overhead loops by loading a set of up to 31 instructions into cache memory and repetitively executing them as many as $2^{16} - 1$ times.

[†] Executes in one instruction cycle in most cases.

[‡] A dual-MAC operation consists of two multiplies and an add or subtract operation by the ALU, an add or subtract operation by the ADDER, or both.

[§] See Section 6.1.1 for a description of processor flags.

6 Software Architecture (continued)

6.1 Instruction Set Quick Reference (continued)

See the *DSP16000 Digital Signal Processor Core Information Manual* for a detailed description of:

- The instruction set
- Pipeline hazards¹
- Instruction encoding formats and field descriptions
- Instruction set reference

Table 129 on page 209 lists the entire instruction set with its cycle performance and the number of memory locations required for each. Figure 57 is an illustration of a single row of the table and a description of how to interpret its contents.

Instruction	Flags		Cycles		Words
	sz	lme	Out	In	
ALU Group					
aD = aS OP <aTE, pE>	(F3)	szlm-	1	1	1

† szlme corresponds to the LMI (s), LEQ (z), LLV (l), LMV (m), and EPAR (e) flags. If a letter appears in this column, the corresponding flag is affected by this instruction. If a dash appears in this column, the corresponding flag is unaffected by this instruction. In the example shown, the instruction affects all flags except for EPAR. For MAC group instructions with both an ALU/ACS operation and an ADDER or BMU operation, the ALU/ACS result affects the LMI, LEQ, LLV, and LMV flags and the EPAR flag is unaffected.

Figure 57. Interpretation of the Instruction Set Summary Table

Table 130 on page 215 summarizes the instruction set notation conventions for interpreting the instruction syntax descriptions. Table 131 on page 216 is an overall replacement table that summarizes the replacement for every upper-case character string in the instruction set summary table (Table 129 on page 209) except for F1 and F1E in the MAC instruction group. Table 132 on page 219 describes the replacement for the F1 field, and Table 133 on page 221 describes the replacement for the F1E field.

1. A pipeline hazard occurs when a write to a register precedes an access that uses the same register and that register is not updated because of pipeline timing. The DSP16000 assembler automatically inserts a **nop** in this case to avoid the hazard.

6 Software Architecture (continued)

6.1 Instruction Set Quick Reference (continued)

Table 129. Instruction Set Summary

Instruction		Flags	Cycles		Words	
			szlme	Out		In
Multiply/Accumulate (MAC) Group						
{F1}	Y	szlme-	1	1	1	
{F1}	$x\langle h,l \rangle = Y$	szlme-	1+Xc [†]	1	1	
{F1}	$y\langle h,l \rangle = Y$	szlme-				
{F1}	$a\bar{D}\langle h,l \rangle = Y$	szlme-				
{F1}	$Y = y\langle h,l \rangle$	szlme-				
{F1}	$Y = a\bar{T}\langle h,l \rangle$	szlme-				
{F1}	yh = aTh	xh = X				szlme-
{F1}	yh = Y	xh = X				szlme-
{if CON}	F1E	szlme	1	1	2	
{F1E}	$y\langle h,l \rangle = aTE\langle h,l \rangle$	szlme	1+Xc [†]	1	2	
{F1E}	$aTE\langle h,l \rangle = y\langle h,l \rangle$	szlme				
{F1E}	y = aE_Ph	szlme				
{F1E}	aE_Ph = y	szlme				
{F1E}	$x\langle h,l \rangle = YE$	szlme				
{F1E}	$y\langle h,l \rangle = YE$	szlme				
{F1E}	$aTE\langle h,l \rangle = YE$	szlme				
{F1E}	aE_Ph = YE	szlme				
{F1E}	YE = x $\langle h,l \rangle$	szlme				
{F1E}	YE = y $\langle h,l \rangle$	szlme				
{F1E}	YE = aTE $\langle h,l \rangle$	szlme				
{F1E}	YE = aE_Ph	szlme				
{F1E}	$y\langle h \rangle = *r0$ r0 = rNE + jhb	szlme				
{F1E}	YE	szlme				
{F1E}		x $\langle h,l \rangle = XE$				szlme
{F1E}		aTE $\langle h,l \rangle = XE$				szlme
{F1E}		aE_Ph = XE				szlme
{F1E}	y = aE_Ph	x $\langle h \rangle = XE$				szlme
{F1E}	$y\langle h \rangle = aTE\langle h \rangle$	x $\langle h \rangle = XE$				szlme
{F1E}	aTE $\langle h \rangle = y\langle h \rangle$	x $\langle h \rangle = XE$				szlme
{F1E}	$y\langle h,l \rangle = YE\ddagger$	a4 $\langle h \rangle = XE$				szlme
{F1E}	$y\langle h,l \rangle = YE$	x $\langle h \rangle = XE$				szlme
{F1E}	YE = y $\langle h,l \rangle$	x $\langle h \rangle = XE$				szlme
{F1E}	$y\langle h \rangle = YE\ddagger$	a4_5h = XE				szlme
{F1E}	YE = a6_7h	x $\langle h \rangle = XE$				szlme
{F1E}	YE = a6 $\langle h \rangle\ddagger$	x $\langle h \rangle = XE$				szlme
{F1E}	YE = a6 $\langle h \rangle\ddagger$	a4 $\langle h \rangle = XE$				szlme

† Xc is one cycle if XAAU contention occurs and zero cycles otherwise. XAAU contention occurs frequently for these instruction types and can only be avoided by use of the cache.

‡ For this transfer, the postincrement options *rME and *rME-- are not available for double-word loads.

§ The - (40-bit subtraction) operation is encoded as aDE=aSE+IM16 with the IM16 value negated.

†† For conditional branch instructions, the execution time is two cycles if the branch is not taken.

‡‡ The instruction performs the same function whether or not {near} (optional) is included.

§§ Not including the N instructions.

6 Software Architecture (continued)

6.1 Instruction Set Quick Reference (continued)

Table 129. Instruction Set Summary (continued)

Instruction	Flags	Cycles		Words
		szlme	Out In	
Multiply/Accumulate (MAC) Group (continued)				
{F1E} y{h} = *r0 r0 = rNE+j{lb} j = k k = XE	szlme	1+Xc†	1	2
{F1E} XE	szlme			
Special Function Group				
{if CON} aD = aS>><1,4,8,16>	(F2) szlme	1	1	1
ifc CON aD = aS>><1,4,8,16>	(F2) szlme			
{if CON} aD = aS	(F2) szlm-			
ifc CON aD = aS	(F2) szlm-			
{if CON} aD = -aS	(F2) szlm-			
ifc CON aD = -aS	(F2) szlm-			
{if CON} aD = ~aS	(F2) szlm-			
ifc CON aD = ~aS	(F2) szlm-			
{if CON} aD = rnd(aS)	(F2) szlm-			
ifc CON aD = rnd(aS)	(F2) szlm-			
{if CON} aDh = aSh+1	(F2) szlm-			
ifc CON aDh = aSh+1	(F2) szlm-			
{if CON} aD = aS+1	(F2) szlm-			
ifc CON aD = aS+1	(F2) szlm-			
{if CON} aD = <y,p0>	(F2) szlm-			
ifc CON aD = <y,p0>	(F2) szlm-			
{if CON} aD = aS<<<1,4,8,16>	(F2) szlme			
ifc CON aD = aS<<<1,4,8,16>	(F2) szlme			
{if CON} aDE = aSE>><1,2,4,8,16>	(F2E) szlme	1	1	2
ifc CON aDE = aSE>><1,2,4,8,16>	(F2E) szlme			
{if CON} aDE = aSE	(F2E) szlm-			
ifc CON aDE = aSE	(F2E) szlm-			
{if CON} aDE = -aSE	(F2E) szlm-			
ifc CON aDE = -aSE	(F2E) szlm-			
{if CON} aDE = ~aSE	(F2E) szlm-			
ifc CON aDE = ~aSE	(F2E) szlm-			
{if CON} aDE = rnd(<aSE,pE>)	(F2E) szlm-			
ifc CON aDE = rnd(<aSE,pE>)	(F2E) szlm-			
{if CON} aDE = rnd(-pE)	(F2E) szlm-			
ifc CON aDE = rnd(-pE)	(F2E) szlm-			
{if CON} aDE = rnd(aSE+pE)	(F2E) szlm-			
ifc CON aDE = rnd(aSE+pE)	(F2E) szlm-			
{if CON} aDE = rnd(aSE-pE)	(F2E) szlm-			
ifc CON aDE = rnd(aSE-pE)	(F2E) szlm-			

† Xc is one cycle if XAAU contention occurs and zero cycles otherwise. XAAU contention occurs frequently for these instruction types and can only be avoided by use of the cache.

‡ For this transfer, the postincrement options *rME and *rME-- are not available for double-word loads.

§ The - (40-bit subtraction) operation is encoded as aDE=aSE+IM16 with the IM16 value negated.

†† For conditional branch instructions, the execution time is two cycles if the branch is not taken.

‡‡ The instruction performs the same function whether or not {near} (optional) is included.

§§ Not including the N instructions.

6 Software Architecture (continued)

6.1 Instruction Set Quick Reference (continued)

Table 129. Instruction Set Summary (continued)

Instruction	Flags	Cycles		Words	
		szlme	Out		In
Special Function Group (continued)					
{if CON} aDE = abs(aSE)	(F2E)	szlme	1	1	2
ifc CON aDE = abs(aSE)	(F2E)	szlme			
{if CON} aDE = aSEh+1	(F2E)	szlme			
ifc CON aDEh = aSEh+1	(F2E)	szlme			
{if CON} aDE = aSE+1	(F2E)	szlme			
ifc CON aDE = aSE+1	(F2E)	szlme			
{if CON} aDE = <y,pE>	(F2E)	szlme			
ifc CON aDE = <y,pE>	(F2E)	szlme			
{if CON} aDE = <-y,-pE>	(F2E)	szlme			
ifc CON aDE = <-y,-pE>	(F2E)	szlme			
{if CON} aDE = aSE<<(1,2,4,8,16)	(F2E)	szlme			
ifc CON aDE = aSE<<(1,2,4,8,16)	(F2E)	szlme			
ALU Group					
aD = aS OP <aTE,pE>	(F3)	szlme	1	1	1
aD = <aTE,pE> - aS	(F3)	szlme			
aD = FUNC(aS,<aTE,pE>)	(F3)	szlme			
aS - <aTE,pE>	(F3)	szlme			
aS&<aTE,pE>	(F3)	szlme			
{if CON} aDE = aSE OP <pE,y>	(F3E)	szlme	1	1	2
{if CON} aDE = aSE OP aTE	(F3E)	szlme			
{if CON} aDE = <pE,y>-aSE	(F3E)	szlme			
{if CON} aDE = FUNC(aSE,<pE,y>)	(F3E)	szlme			
{if CON} aDE = FUNC(aSE,aTE)	(F3E)	szlme			
{if CON} aSE - <pE,y>	(F3E)	szlme			
{if CON} aSE&<pE,y>	(F3E)	szlme			
{if CON} aSE - aTE	(F3E)	szlme			
{if CON} aSE&aTE	(F3E)	szlme			
{if CON} aDEE = aSEE±aTEE aDPE = aSPE±aTPE	(F3E)	szlme			
if CON aDE = aSE+aTE else aDE = aSE-aTE	(F3E)	szlme			
aDE = aSE(h,l) OP IM16§	(F3 with immediate)	szlme	1	1	2
aDE = IM16-aSE(h,l)	(F3 with immediate)	szlme			
aSE(h,l) - IM16	(F3 with immediate)	szlme			
aSE(h,l) & IM16	(F3 with immediate)	szlme			

† Xc is one cycle if XAAU contention occurs and zero cycles otherwise. XAAU contention occurs frequently for these instruction types and can only be avoided by use of the cache.

‡ For this transfer, the postincrement options *rME and *rME-- are not available for double-word loads.

§ The - (40-bit subtraction) operation is encoded as aDE=aSE+IM16 with the IM16 value negated.

†† For conditional branch instructions, the execution time is two cycles if the branch is not taken.

‡‡ The instruction performs the same function whether or not {near} (optional) is included.

§§ Not including the N instructions.

6 Software Architecture (continued)

6.1 Instruction Set Quick Reference (continued)

Table 129. Instruction Set Summary (continued)

Instruction	Flags	Cycles		Words
		szlme	Out In	
BMU Group				
aD = aS SHIFT (aTEh, arM) (F4)	szlme	1	1	1
aDh = exp(aTE) (F4)	szlme			
aD = norm(aS, (aTEh, arM)) (F4)	szlme			
aD = extracts(aS, aTEh) aD = extractz(aS, aTEh)	(F4) szlme			
aD = inserts(aS, aTEh) aD = insertz(aS, aTEh)	(F4) szlme			
aD = extract(aS, arM) aD = extracts(aS, arM) aD = extractz(aS, arM)	(F4) szlme			
aD = insert(aS, arM) aD = inserts(aS, arM) aD = insertz(aS, arM)	(F4) szlme			
aD = aS:aTE (F4)	szlm-			
aDE = extract(aSE, IM8W, IM8O) (F4 with immediate) aDE = extracts(aSE, IM8W, IM8O) aDE = extractz(aSE, IM8W, IM8O)	szlme	1	1	2
aDE = insert(aSE, IM8W, IM8O) (F4 with immediate) aDE = inserts(aSE, IM8W, IM8O) aDE = insertz(aSE, IM8W, IM8O)	szlme			
aDE=aSE SHIFT IM16 (F4 with immediate)	szlme			
{if CON} aDE = aSE SHIFT(aTEh, arM) (F4E)	szlme	1	1	2
{if CON} aDEh = exp(aTE) (F4E)	szlme			
{if CON} aDE = norm(aSE, (aTEh, arM)) (F4E)	szlme			
{if CON} aDE = extracts(aSE, aTEh) {if CON} aDE = extractz(aSE, aTEh)	(F4E) szlme			
{if CON} aDE = inserts(aSE, aTEh) {if CON} aDE = insertz(aSE, aTEh)	(F4E) szlme			
{if CON} aDE = extract(aSE, arM) {if CON} aDE = extracts(aSE, arM) {if CON} aDE = extractz(aSE, arM)	(F4E) szlme			
{if CON} aDE = insert(aSE, arM) {if CON} aDE = inserts(aSE, arM) {if CON} aDE = insertz(aSE, arM)	(F4E) szlme			
{if CON} aDE = aSE:aTE (F4E)	szlm-			

† Xc is one cycle if XAAU contention occurs and zero cycles otherwise. XAAU contention occurs frequently for these instruction types and can only be avoided by use of the cache.

‡ For this transfer, the postincrement options *rME and *rME-- are not available for double-word loads.

§ The - (40-bit subtraction) operation is encoded as aDE=aSE+IM16 with the IM16 value negated.

†† For conditional branch instructions, the execution time is two cycles if the branch is not taken.

‡‡ The instruction performs the same function whether or not {near} (optional) is included.

§§ Not including the N instructions.

6 Software Architecture (continued)

6.1 Instruction Set Quick Reference (continued)

Table 129. Instruction Set Summary (continued)

Instruction	Flags	Cycles		Words	
	szlme	Out	In		
Data Move and Pointer Arithmetic Group					
RAB = IM20	—	1	1	2	
RA = IM4	—	1	1	1	
RA _D = RA _S	—	1	1	1	
{if CON} RAB _D = RAB _S	—			2	
RB = aTE(h,l)	—	1	1	1	
aTE(h,l) = RB	—				
RA = Y	—	1	1	1	
Y = RA	—				
RAB = YE	—	1	1	2	
YE = RC	—				
RAB = *sp++2	—	1	1	1	
*sp--2 = RC	—				
sp--2	—				
*sp = RC	—				
push RC	—				
pop RAB	—				
r3--sizeof(RAB)	—				
RA = *(sp+IM5)	—	2	2	1	
*(sp+IM5) = RA	—				
RAB = *(RP+IM12)	—	2	2	2	
*(RP+IM12) = RC	—				
RAB = *(RP+(j,k))	—				
*(RP+(j,k)) = RC	—				
RY = RP+IM12	—	1	1	2	
RY = RP+(j,k)	—				
RAB = *r7	r7 = sp+IM11	1	1	2	
*r7 = RC	r7 = sp+IM11				
YE† = x{h}	x{h} = XE	—	1+Xc†	1	2

† Xc is one cycle if XAAU contention occurs and zero cycles otherwise. XAAU contention occurs frequently for these instruction types and can only be avoided by use of the cache.

‡ For this transfer, the postincrement options *rME and *rME-- are not available for double-word loads.

§ The - (40-bit subtraction) operation is encoded as aDE=aSE+IM16 with the IM16 value negated.

†† For conditional branch instructions, the execution time is two cycles if the branch is not taken.

‡‡ The instruction performs the same function whether or not {near} (optional) is included.

§§ Not including the N instructions.

6 Software Architecture (continued)

6.1 Instruction Set Quick Reference (continued)

Table 129. Instruction Set Summary (continued)

Instruction	Flags	Cycles		Words
	szlme	Out	In	
Control Group				
{near} goto IM12 ^{‡‡}	—	3	—	1
{near} call IM12 ^{‡‡}	—			
if CON goto IM16	—	3 ^{††}	—	2
if CON call IM16	—			
far goto IM20	—	3	—	
far call IM20	—			
{if CON} goto ptE	—	3 ^{††}	—	1
{if CON} call ptE	—			
{if CON} call pr	—			
tcall	—	3	—	
icall IM6	—			
{if CON} return	—	3 ^{††}	—	
ireturn	—	3	—	
treturn	—			
ei	—	1	1	
di	—			
Cache Group				
do K {N_INSTR}	—	1 ^{§§}	—	1 ^{§§}
redo K	—	2	—	1
do cloop {N_INSTR}	—	1 ^{§§}	—	1 ^{§§}
redo cloop	—	2	—	1

† Xc is one cycle if XAAU contention occurs and zero cycles otherwise. XAAU contention occurs frequently for these instruction types and can only be avoided by use of the cache.

‡ For this transfer, the postincrement options *rME and *rME-- are not available for double-word loads.

§ The - (40-bit subtraction) operation is encoded as aDE=aSE+IM16 with the IM16 value negated.

†† For conditional branch instructions, the execution time is two cycles if the branch is not taken.

‡‡ The instruction performs the same function whether or not {near} (optional) is included.

§§ Not including the N instructions.

6 Software Architecture (continued)

6.1 Instruction Set Quick Reference (continued)

Table 130 defines the symbols used in instruction descriptions. Some symbols and characters are part of the instruction syntax, and must appear as shown within the instruction. Other symbols are representational and are replaced by other characters. The table groups these two types of symbols separately.

Table 130. Notation Conventions for Instruction Set Descriptions

Symbol	Meaning	
Part of Syntax	*	16-bit x 16-bit multiplication resulting in a 32-bit product. Exception: When used as a prefix to an address register, denotes register-indirect addressing, e.g., *r3.
	**2	Squaring is a 16-bit x 16-bit multiplication of the operand with itself resulting in a 32-bit product.
	+	40-bit addition†.
	-	40-bit subtraction†.
	++	Register postincrement.
	--	Register postdecrement.
	>>	Arithmetic right shift (with sign-extension from bit 39).
	<<	Arithmetic left shift (padded with zeros).
	>>>	Logical right shift (zero guard bits before shift).
	<<<	Logical left shift (padded with zeros; sign-extended from bit 31).
	&	40-bit bitwise logical AND†.
		40-bit bitwise logical OR†.
	^	40-bit bitwise logical exclusive-OR†.
	:	Register shuffle‡.
	~	Ones complement (bitwise inverse).
	()	Parentheses enclose multiple operands delimited by commas that are also part of the syntax.
	{ }	Braces enclose multiple instructions within a cache loop.
	_ (underscore)	The underscore character indicates an accumulator vector (concatenation of the high halves of a pair of sequential accumulators, e.g., a0_1h).
	lower-case	Lower-case characters appear as shown in the instruction.
	Not Part of Syntax (Replaced)	< >
{ }		Mid braces enclose one or more optional items delimited by commas.
±		Replaced by either + or -.
UPPER-CASE		Upper-case characters, character strings, and characters plus numerals (e.g., M, CON, and IM16) are replaced. Replacement tables accompany each instruction group description.
F Titles		Represents a statement of a DAU function:
F1		MAC.
F1E		Extended MAC.
F2		Special function.
F2E		Extended special function.
F3		ALU.
F3E	Extended ALU.	
F4	BMU.	
F4E	Extended BMU.	

† The ALU/ACS and ADDER perform 40-bit operations, but the operands can be 16 bits, 32 bits, or 40 bits. In the special case of the split-mode F1E instruction ($xh=aSPEh\pm yh$, $xl=aSPEl\pm yl$, $aDE=aSEE+p0+p1$, $p0=xh**2$, $p1=xl**2$), the ALU performs two 16-bit addition/subtraction operations in parallel.

‡ Note that this symbol does not denote compound addressing as it does for the DSP16XX family.

6 Software Architecture (continued)

6.1 Instruction Set Quick Reference (continued)

Table 131. Overall Replacement Table

Symbol	Used in Instruction Type(s)	Replaced By	Description
aD	F1, F2, F3, F4	a0 or a1 (DSP16XX-compatible)	D indicates destination of an operation.
aS			S indicates source of an operation.
aT	F1		T indicates an accumulator that is the source of a data transfer.
aD̄			D̄ indicates an accumulator other than the destination accumulator.
aDE	F1E, F2E, F3/E, F4/E	a0, a1, a2, a3, a4, a5, a6, or a7	D indicates destination of an operation. S indicates source of an operation. T indicates an accumulator that is either an additional source for an operation or the source or destination of a data transfer. E indicates the extended set of accumulators.
aSE			
aTE	F1E, F3/E, F4/E, data move		
aDEE	F1E, F3E	a(DPE – 1) → a0, a2, a4, or a6	D indicates destination of an operation. S indicates source of an operation. T indicates an accumulator that is either an additional source for an operation or the source or destination of a data transfer. The first E indicates an even accumulator that is paired with its corresponding paired extended (odd) accumulator, i.e., the matching aDPE, aSPE, or aTPE accumulator. The second E indicates the extended set of accumulators.
aSEE		a(SPE – 1) → a0, a2, a4, or a6	
aTEE	F3E	a(TPE – 1) → a0, a2, a4, or a6	
aDPE	F1E, F3E	a(DEE + 1) → a1, a3, a5, or a7	P indicates an odd accumulator that is paired with an even extended accumulator, i.e., the matching aDEE, aSEE, or aTEE accumulator. E indicates the extended set of accumulators.
aSPE		a(SEE + 1) → a1, a3, a5, or a7	
aTPE	F3E	a(TEE + 1) → a1, a3, a5, or a7	
aE_Ph	F1E	a0_1h, a2_3h, a4_5h, or a6_7h	An accumulator vector, i.e., the concatenated 16-bit high halves of two adjacent accumulators to form a 32-bit vector.
arM	F4, F4E	ar0, ar1, ar2, or ar3	One of the four auxiliary accumulators.
CON	F1E, F2, F2E, F3E, F4E, control, data move	mi, pl, eq, ne, lvs, lvc, mvs, mvc, heads, tails, c0ge, c0lt, c1ge, c1lt, true, false, gt, le, oddp, evenp, smvs, smvc, jobf, jibe, jcont, lock, mgibe, mgobf, somef, somet, allf, or allt	Conditional mnemonics. Certain instructions are conditionally executed, e.g., if CON F2E . See Table 134 on page 223 .
FUNC	F3, F3E	max, min, or divs	One of three ALU functions: maximum, minimum, or divide-step.
IM4	data move	4-bit unsigned immediate value (0 to 15)	Signed/unsigned status of the IM4 value matches that of the destination register of the data move assignment instruction.
		4-bit signed immediate value (–8 to +7)	
IM5	data move	5-bit unsigned immediate value (0 to 31)	Added to stack pointer sp to form stack address.
IM6	control	6-bit unsigned immediate value (0 to 63)	Vector for icall instruction.
IM8O IM8W	F4	8-bit unsigned immediate value (0 to 255)	Offset and width for bit-field insert and extract instructions. The BMU truncates these values to 6 bits.
IM11	data move	11-bit unsigned immediate value (0 to 2047)	Added to stack pointer sp to form stack address.

† The size of the transfer (single- or double-word) depends on the size of the register on the other side of the equal sign.

‡ These postmodification options are not available for a double-word load except for a load of an accumulator vector.

6 Software Architecture (continued)

6.1 Instruction Set Quick Reference (continued)

Table 131. Overall Replacement Table (continued)

Symbol	Used in Instruction Type(s)	Replaced By	Description	
IM12	control	12-bit signed immediate value (-2048 to +2047)	PC-relative near address for goto and call instructions.	
	data move and pointer arithmetic		Postmodification to a general YAAU pointer register to form address for data move. Added to the value of a general YAAU pointer register, and the result is stored into any YAAU register.	
IM16	control	16-bit signed immediate value (-32,768 to +32,767)	Offset for conditional PC-relative goto/call instructions.	
	F3, F4		Operand for ALU or BMU operation.	
IM20	control, data move	20-bit unsigned immediate value (0 to 1,048,576)	Absolute (unsigned) far address for goto and call instructions. For data move instructions, the signed/unsigned status of the IM20 value matches that of the destination register of the assignment instruction.	
		20-bit signed immediate value (-524,288 to 524,287)		
K	cache	1 to 127 or the value in cloop	For the do K {N_INSTR} and redo K cache instructions.	
N		1 to 31		
OP	F1, F1E, F3, F3E	+, -, &, , or ^	40-bit ALU operation.	
pE	F2E, F3, F3E	p0 or p1	One of the product registers as source for a special function or ALU operation.	
ptE	F1E, control, data move	pt0 or pt1	One of the two XAAU pointer registers as address for an XE memory access (see XE entry in this table).	
RA	data move	a0, a1, a2, a3, a4, a5, a6, a7, a0h, a1h, a2h, a3h, a4h, a5h, a6h, a7h, a0l, a1l, a2l, a3l, a4l, a5l, a6l, a7l, alf, auc0, c0, c1, c2, h, i, j, k, p0, p0h, p0l, p1, p1h, p1l, pr, psw0, pt0, pt1, r0, r1, r2, r3, r4, r5, r6, r7, rb0, rb1, re0, re1, sp, x, xh, xl, y, yh, or yl	One of the main set of core registers that is specified as the source or destination of a data move operation. The subscripts are used to indicate that two different registers can be specified, e.g., RA_D = RA_S describes a register-to-register move instruction where RA _D and RA _S are, in general, two different registers.	
RA _D				
RA _S				
RB		core	a0g, a1g, a2g, a3g, a4g, a5g, a6g, a7g, a0_1h, a2_3h, a4_5h, a6_7h, ar0, ar1, ar2, ar3, auc1, cloop, cstate, csave, inc0, inc1, ins, pi, psw1, ptrap, vbase, or vsw	One of the secondary set of registers that is specified as the source or destination of a data move operation. This set includes core and off-core registers.
		off-core	cbit, imux, jjob, mgi, mgo, pid, pllcon, pllfrq, plldly, sbit, signal, timer0, timer1, timer0c, timer1c	
RAB		Any of the RA or RB registers (see rows above)	Any one of the registers in the main (RA) or secondary (RB) sets of registers that is specified as the source or destination of a data move operation. The subscripts are used to indicate that two different registers can be specified.	
RAB _b				
RAB _s				
RC		Any of the RA registers or any of the core RB registers (see rows above)	Any core register that is specified as the source of a data move operation.	
rM	F1, data move	r0, r1, r2, or r3	One of four general YAAU pointer registers used for a Y memory access (see Y entry in this table).	

† The size of the transfer (single- or double-word) depends on the size of the register on the other side of the equal sign.

‡ These postmodification options are not available for a double-word load except for a load of an accumulator vector.

6 Software Architecture (continued)

6.1 Instruction Set Quick Reference (continued)

Table 131. Overall Replacement Table (continued)

Symbol	Used in Instruction Type(s)	Replaced By	Description
rME	F1E, data move	r0, r1, r2, r3, r4, r5, r6, or r7	One of eight general YAAU pointer registers used for a YE memory access (see YE entry in this table). E indicates the extended set of pointer registers.
rNE	F1E	r1, r2, r3, r4, r5, r6, or r7	One of seven general YAAU pointer registers used for a table look-up pointer update.
RP	data move and pointer arithmetic	r0, r1, r2, r3, r4, r5, r6, or sp	One of seven general YAAU pointer registers or the YAAU stack pointer.
RY	pointer arithmetic	r0, r1, r2, r3, r4, r5, r6, r7, sp, rb0, rb1, re0, re1, j, or k	Any one of the YAAU registers, including the stack pointer, circular buffer pointers, and increment registers.
X	F1	*pt0++ or *pt0++i	A single-word location pointed to by pt0 .
Y	F1	*rM, *rM++, *rM--, or *rM++j	A single-word location pointed to by rM .
	{F1} Y	rM++, rM--, or rM++j	Modification of rM pointer register (no memory access).
	data move	*rM, *rM++, *rM--, or *rM++j	A single- or double-word [†] location pointed to by rM .
XE	F1E, data move	*ptE [‡] , *ptE++, *ptE-- [‡] , *ptE++h, or *ptE++i	A single-word or double-word [†] memory location pointed to by ptE .
	{F1E} XE	ptE++, ptE--, ptE++h, ptE++i, or ptE++2	Modification of ptE pointer register (no memory access).
YE	F1E, data move	*rME, *rME++, *rME--, *rME++j, or *rME++k	A single-word or double-word [†] memory location pointed to by rME .
	{F1E} YE	rME++, rME--, rME++j, rME++k, rME++2, or rME--2	Modification of rME pointer register (no memory access).

[†] The size of the transfer (single- or double-word) depends on the size of the register on the other side of the equal sign.

[‡] These postmodification options are not available for a double-word load except for a load of an accumulator vector.

Table 132 on page 219 defines the F1 instruction syntax as any function statement combined with any transfer statement. Two types of F1 function statements are shown: the MAC (multiply/accumulate) type and the arithmetic/logic type. The MAC type is formed by combining any two items from the designated ALU and Multiplier columns. The arithmetic/logic type is chosen from the items in the designated Arithmetic/Logic Function Statement column.

6 Software Architecture (continued)

6.1 Instruction Set Quick Reference (continued)

Table 132. F1 Instruction Syntax

Combine Any F1 Function Statement with Any Transfer Statement				
F1 MAC Function Statement— Combine Any Items in Following Two Columns:		Transfer Statement	Cycles (Out/In Cache) [†]	16-Bit Words
ALU	Multiplier			
aD = {aS ±} p0	p0 = xh * yh	Y‡	1/1	1
(no ALU operation) [§]	(no multiply operation) [§]	$\langle x, y, a\bar{D}^{\dagger\dagger} \rangle \langle h, l \rangle = Y$	1/1	
F1 Arithmetic/Logic Function Statement (ALU)		$Y = \langle y, aT \rangle \langle h, l \rangle$	1/1	
aD = {aS OP} y		$yh = \langle Y, a\bar{T}h \rangle \quad xh = X$	1 + Xc ^{‡‡} /1	
aS – y		(no transfer) ^{§§}	1/1	
aS & y				
nop ^{†††}				
(no F1 function statement) [§]				

† Not including conflict, misalignment, or external wait-states (see the *DSP16000 Digital Signal Processor Core Information Manual*).

‡ This Y transfer statement must increment or decrement the contents of an **rM** register. It is not necessary to include the * before the **rM** register because no access is made to a memory location.

§ Leave the ALU column blank to specify no ALU operation, the multiplier column blank to specify no multiply operation, or both columns blank to specify no F1 function statement. If both columns are left blank and a transfer statement is used (a transfer-only F1 instruction, i.e., **yh = *r2 xh = *pt0++**), the assembler interprets the F1 function statement as a **nop**.

†† For this instruction, **aD** must be the opposite of **aD**, e.g., if **aD** is **a0**, **aD** must be **a1** and vice versa.

‡‡ Xc is one cycle if XAAU contention occurs and zero cycles otherwise. XAAU contention occurs frequently for these instruction types and can only be avoided by use of the cache. See the *DSP16000 Digital Signal Processor Core Information Manual*.

§§ The assembler encodes an instruction that consists of a function statement **F1** with no transfer statement as **F1 *r0**.

††† **nop** is no-operation. A programmer can write **nop** with or without an accompanying transfer statement. The assembler encodes **nop** without a transfer statement as **nop *r0**.

6 Software Architecture (continued)

6.1 Instruction Set Quick Reference (continued)

Table 133 on page 221 summarizes the syntax for F1E function statements and the following paragraphs describe each class of instruction.

Note: Each function statement can be combined with a parallel transfer statement to form a single DSP16410B instruction.

General-Purpose MAC Combine any ALU, ADDER, or ALU and ADDER operation from the left column with any single- or dual-multiply operation from the right column. Either column can be left blank.¹

Additional General-Purpose MAC These statements are general-purpose. The combinations of operations must be as shown. The first statement clears two accumulators and both product registers. The second statement is the equivalent of the F1 statement **aD = p0 p0 = xh * yh** except that any accumulator aDE can be specified. The third statement is the equivalent of the F1 statement **aD = p0** except that any accumulator aDE can be specified. The fourth statement is a no-operation and, as with all F1E function statements, can be combined with a transfer statement.

Special-Purpose MAC for Mixed Precision Combine any ADDER operation or any ALU and ADDER operation from the left column with any dual-multiply operation from the right column. Either column can be left blank.¹ These statements are intended for, but are not limited to, mixed-precision MAC applications. Mixed-precision multiplication is 16 bits x 31 bits.

Special-Purpose MAC for Double Precision These statements are intended for, but are not limited to, double-precision MAC applications. The combinations of operations must be as shown. Double-precision multiplication is 31 bits x 31 bits.

Special-Purpose MAC for Viterbi These statements are intended for, but are not limited to, Viterbi decoding applications. The combinations of operations must be as shown. This group includes ALU split-mode operations.

Special-Purpose MAC for FFT This statement is intended for, but is not limited to, FFT applications.

ALU These statements are ALU operations. The first three statements in this group are the equivalent of the F1 arithmetic/logic function statements.

Special-Purpose ALU/ACS, ADDER/ACS for Viterbi These statements are intended for, but are not limited to, Viterbi decoding applications. They provide either an ALU/ACS operation with or without a parallel ADDER/ACS operation or split-mode ALU and ADDER operations. The combinations of operations must be as shown. This group includes the Viterbi compare functions.

Special-Purpose ALU, BMU These statements are intended for, but are not limited to, special-purpose applications. They provide a BMU operation with or without a parallel ALU operation. The combinations of operations must be as shown.

1. If both columns are left blank and a transfer statement is used, the DSP16000 assembler interprets the F1E function statement as a no-operation (**nop**).

6 Software Architecture (continued)

6.1 Instruction Set Quick Reference (continued)

Table 133. F1E Function Statement Syntax

General-Purpose MAC Function Statements—Combine Any Items in Two Columns:

ALU [†]	ADDER [†]	Multipliers	
aDE=aSE±p0		p0=xh*yh	
	aDE=aSE±p0±p1 [‡]	p0=xh*yh	p1=xl*yl
aDEE=aSEE±p0	aDPE=aSPE±p1	p0=xh*yl	p1=xl*yh
	(no ALU/ACS or ADDER operation)	p0=xh*yh	p1=xh*yl
		p0=xl*yh	p1=xl*yl
		(no multiply operation)	

Additional General-Purpose MAC Function Statements

ALU [†]	ADDER [†]	Multipliers	
aDE=0	aSE=0	p0=0	p1=0
aDE=p0		p0=xh*yh	
aDE=p0			
nop			

Special-Purpose MAC Function Statements for Mixed Precision—Combine Any Items in Two Columns:

ALU [†]	ADDER [†]	Multipliers	
	aDE=p0+(p1>>15) [§]	p0=xh*yh	p1=xh*(yl>>>1)
aDEE=aSE+aDPE	aDPE=p0+(p1>>15) [§]	p0=xl*yh	p1=xl*(yl>>>1)
	(no ALU/ACS or ADDER operation)	(no multiply operation)	

Special-Purpose MAC Function Statements for Double Precision

ALU [†]	ADDER [†]	Multipliers	
	aDE=aSE+p0+(p1>>15) ^{‡§}	p0=xh*yh	p1=xh*(yl>>>1)
	aDE=aSE+p0+(p1>>15) ^{‡§}		
	aDE=p0+(p1>>15) [§]	p0=0	p1=(xl>>>1)*yh
aDEE=aSE+aDPE	aDPE=p0+(p1>>15) [§]	p0=0	p1=(xl>>>1)*yh
	aDE=(p0>>1)+(p1>>16)	p0=(xl>>>1)*yh	p1=xh*yh
aDEE=aSE+aDPE	aDPE=(p0>>1)+(p1>>16)	p0=(xl>>>1)*yh	p1=xh*yh
aDE=aSE+(p0>>1)			
		p0=xh*(yl>>>1)	p1=(xl>>>1)*(yl>>>1)
aDE=(aSE>>14)+p1		p0=xh*(yl>>>1)	p1=(xl>>>1)*(yl>>>1)
aDE=(aSE>>14)+p1			

[†] DAU flags are affected by the ALU or ALU/ACS operation (except for the split-mode function which does not affect the flags). If there is no ALU or ALU/ACS operation, the DAU flags are affected by the ADDER or BMU operation.

[‡] If **auc0**[10] (FSAT field) is set, the result of the add/subtract of the first two operands is saturated to 32 bits prior to adding/subtracting the third operand and the final result is saturated to 32 bits.

[§] If **auc0**[9] = 1, the least significant bit of **p1>>15** is cleared.

^{††} This is a 16-bit operation. The DAU stores the result in the high half of the destination accumulator and clears the low half.

^{‡‡} This split-mode instruction does not affect the DAU flags. Do not set FSAT for this instruction because if FSAT is set, the entire 32 bits are saturated.

6 Software Architecture (continued)

6.1 Instruction Set Quick Reference (continued)

Table 133. F1E Function Statement Syntax (continued)

Special-Purpose MAC Function Statements for Viterbi

ALU†	ADDER†	Multipliers
$xh=aSPEh+yh$ $xl=aSPEl+y ^{††}$	$aDE=aSEE+p0+p1$	$p0=xh^{**2}$ $p1=xl^{**2}$
$xh=aSPEh-yh$ $xl=aSPEl-y ^{††}$	$aDE=aSEE+p0+p1$	$p0=xh^{**2}$ $p1=xl^{**2}$
	$aDE=aSE+p0+p1^{\ddagger}$	$p0=xh^{**2}$ $p1=xl^{**2}$

Special-Purpose MAC Function Statement for FFT

ALU†	ADDER†	Multipliers
$aDEE=-aSEE+p0$	$aDPE=-aSPE+p1$	$p0=xh*yh$ $p1=xl*y $

ALU Function Statements

$aDE=\{aSE\ OP\}y$
$aSE-y$
$aSE\&y$
$aDE=aDE\pm aSE$

Special-Purpose ALU/ACS, ADDER/ACS Function Statements for Viterbi

ALU/ACS†	ADDER†
$aDEE=cmp0(aSEE,aDEE)$	$aDPE=aDPE+aSPE$
$aDEE=cmp0(aSEE,aDEE)$	$aDPE=cmp0(aSPE,aDPE)$
$aDE=cmp0(aSE,aDE)$	
$aDEE=cmp1(aSE,aDEE)$	$aDPE=aDPE-aSE$
$aDEEh=cmp1(aSEeh,aSEEl)^{††}$	$aDPEh=cmp1(aSPEh,aSPEl)^{††}$
$aDE=cmp1(aSE,aDE)$	
$aDEE=cmp2(aSE,aDEE)$	$aDPE=aDPE-aSE$
$aDE=cmp2(aSE,aDE)$	
$aDEE=aSEE+y$	$aDPE=aSPE-y$
$aDEE=aSEE-y$	$aDPE=aSPE+y$
$aDEEh=aSEh+yh$ $aDEEl=aSEl+y ^{††}$	$aDPEh=aSEh-yh$ $aDPEl=aSEl-y ^{††}$
$aDEEh=aSEh-yh$ $aDEEl=aSEl-y ^{††}$	$aDPEh=aSEh+yh$ $aDPEl=aSEl+y ^{††}$

Special-Purpose ALU, BMU Function Statements

ALU†	BMU†
$aDEE=rnd(aDPE)$	$aDPE=aSEE>>aSPEh$
	$aDE=aSEE>>aSPEh$
$aDE=abs(aDE)$	$aSE=aSE<<ar3$
	$aDE=aSE<<ar3$
	$aDE=aSE<<<ar3$
$aDEE=min(aDPE,aDEE)$	$aDPEh=exp(aSE)$

† DAU flags are affected by the ALU or ALU/ACS operation (except for the split-mode function which does not affect the flags). If there is no ALU or ALU/ACS operation, the DAU flags are affected by the ADDER or BMU operation.

‡ If **auc0[10]** (FSAT field) is set, the result of the add/subtract of the first two operands is saturated to 32 bits prior to adding/subtracting the third operand and the final result is saturated to 32 bits.

§ If **auc0[9]** = 1, the least significant bit of **p1>>15** is cleared.

†† This is a 16-bit operation. The DAU stores the result in the high half of the destination accumulator and clears the low half.

‡‡ This split-mode instruction does not affect the DAU flags. Do not set FSAT for this instruction because if FSAT is set, the entire 32 bits are saturated.

6 Software Architecture (continued)

6.1 Instruction Set Quick Reference (continued)

6.1.1 Conditions Based on the State of Flags

A conditional instruction begins with either **if CON** or **ifc CON** where a condition to test replaces **CON**. Table 134 describes the complete set of condition codes available for use in conditional instructions. It also includes the state of the internal flag or flags that cause the condition to be true.

Table 134. DSP16410B Conditional Mnemonics

CON Encoding	CON Mnemonic	Flag(s) If CON Is True	Type [†]	Description
00000	mi	LMI = 1	Core	Most recent DAU result is negative.
00001	pl	LMI ≠ 1	Core	Most recent DAU result is positive or zero.
00010	eq	LEQ = 1	Core	Most recent DAU result is equal to zero.
00011	ne	LEQ ≠ 1	Core	Most recent DAU result is not equal to zero.
00100	lvs	LLV = 1	Core	Most recent DAU result has overflowed 40 bits.
00101	lvc	LLV ≠ 1	Core	Most recent DAU result has not overflowed 40 bits.
00110	mvs	LMV = 1	Core	Most recent DAU result has overflowed 32 bits.
00111	mvc	LMV ≠ 1	Core	Most recent DAU result has not overflowed 32 bits.
01000	heads	—	Core	Pseudorandom sequence generator output is set.
01001	tails	—	Core	Pseudorandom bit is cleared.
01010	c0ge [‡]	—	Core	Current value in counter c0 is greater than or equal to zero.
01011	c0lt [‡]	—	Core	Current value in counter c0 is less than zero.
01100	c1ge [‡]	—	Core	Current value in counter c1 is greater than or equal to zero.
01101	c1lt [‡]	—	Core	Current value in counter c1 is less than zero.
01110	true	1	Core	Always.
01111	false	0	Core	Never.
10000	gt	(LMI ≠ 1) and (LEQ ≠ 1)	Core	Most recent DAU result is greater than zero.
10001	le	(LMI = 1) or (LEQ = 1)	Core	Most recent DAU result is less than or equal to zero.
10010	smvs	SLMV = 1	Core	A previous result has overflowed 32 bits (sticky flag).
10011	smvc	SLMV ≠ 1	Core	A previous result has not overflowed 32 bits since SLMV last cleared.
10100	oddp	EPAR ≠ 1	Core	Most recent 40-bit BMU result has odd parity.
10101	evenp	EPAR = 1	Core	Most recent 40-bit BMU result has even parity.
10110	jobf	JOBF = 1	JTAG	jjob output buffer full.
10111	jibe	JIBE = 1	JTAG	jjob input buffer empty.
11000	jcont	JCONT = 1	JTAG	JTAG continue.
11001	lock	LOCK = 1	CLOCK	PLL delay counter has reached zero.
11010	mgibe	MGIBE = 1	MGU	Input message buffer register mg i is empty.
11011	mgobf	MGOBF = 1	MGU	Input message buffer register mg o is full.
11100	somef	SOMEF = 1	BIO	Some false, some input bits tested did not compare successfully.
11101	somet	SOMET = 1	BIO	Some true, some input bits tested compared successfully.
11110	allf	ALLF = 1	BIO	All false, no BIO input bits tested compared successfully.
11111	allt	ALLT = 1	BIO	All true, all BIO input bits tested compared successfully.

[†] All peripheral (off-core) flags are accessible in the **alf** register.

[‡] Each test of **c0ge** or **c0lt** causes counter **c0** to postincrement. Each test of **c1ge** or **c1lt** causes counter **c1** to postincrement.

6 Software Architecture (continued)

6.2 Registers

DSP16410B registers fall into one of the following three categories:

- Directly program-accessible (or register-mapped) registers are directly accessible in instructions and are designated with lower-case bold, e.g., **timer0**. These registers are described in [Section 6.2.1](#).
- Memory-mapped registers are accessible at a memory address and are designated with upper-case bold, e.g., **DSTAT**. These registers are described in [Section 6.2.2 on page 228](#).
- Pin-accessible registers are accessible only through the external device pins and are designated with upper-case bold, i.e., **ID**. Each JTAG port contains the pin-accessible identification register, **ID**, described in [Table 148 on page 238](#). This register is accessible via its associated JTAG port.

Note: The program counter (**PC**) is an addressing register not accessible to the programmer or through external pins. The core automatically controls this register to properly sequence the instructions.

6.2.1 Directly Program-Accessible (Register-Mapped) Registers

[Figure 58 on page 225](#) depicts the directly program-accessible (register-mapped) registers. The figure differentiates core and off-core registers. As the figure indicates, the **pllcon**, **pllfrq**, and **plldly** registers are available in CORE0 only.

Note: There is write-to-read latency associated with the pipelined IDB. The assembler compensates for this. See the *DSP16000 Digital Signal Processor Core Information Manual* for further details.

As shown in [Figure 58 on page 225](#), the register-mapped registers consist of three types:

Data registers store data either from the result of instruction execution or from memory. Data registers become source operands for instructions. This class of registers also includes postincrement registers whose contents are added to address registers to form new addresses.

Control and Status registers are used to determine the state of the machine or to set different configurations to control the machine.

Address registers are used to hold memory location pointers. In some cases, the user can treat address registers as general-purpose data registers accessible by data move instructions.

[Table 135 on page 226](#) summarizes the register-mapped registers. It lists all valid register designators as they appear in an instruction syntax. For each register, the table specifies its size, whether it is readable or writable, its type, whether it is signed or unsigned, and the hardware function block in which it is located. It also indicates whether the register is in the core or is off-core. Off-core register-mapped registers cannot be stored to memory in a single instruction. For example, the following instruction is not allowed and will generate an error by the assembler:

```
*r0 = mgi // NOT ALLOWED
```

To store the contents of an off-core register to memory, first store the register to an intermediate register and then store the intermediate register to memory. See the example below:

```
a0h = mgi // a0h is intermediate reg.
*r0 = a0h // store mgi to memory
```


6 Software Architecture (continued)

6.2 Registers (continued)

6.2.1 Directly Program-Accessible (Register-Mapped) Registers (continued)

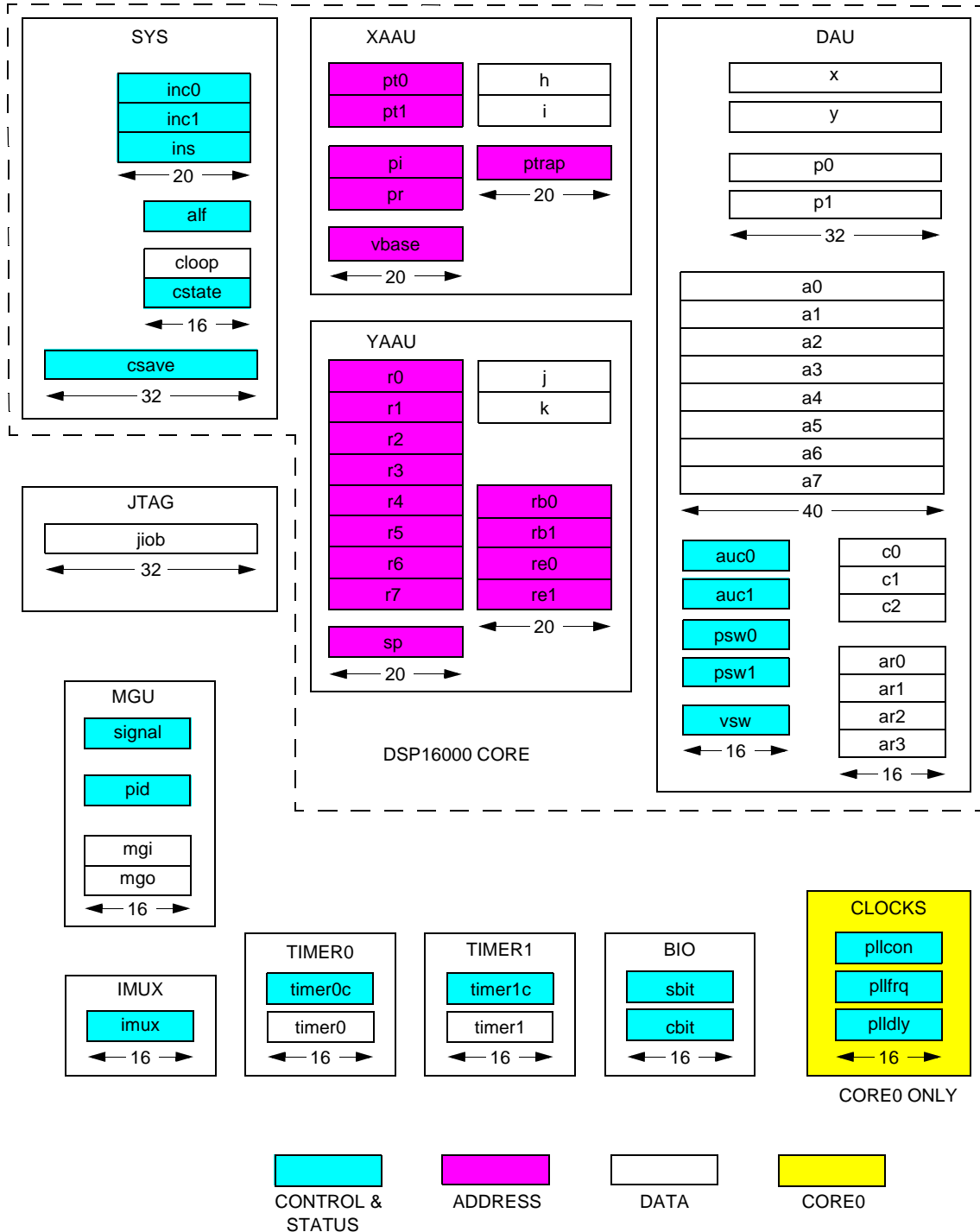


Figure 58. DSP16410B Program-Accessible Registers for Each Core

6 Software Architecture (continued)

6.2 Registers (continued)

6.2.1 Directly Program-Accessible (Register-Mapped) Registers (continued)

Table 135. Program-Accessible (Register-Mapped) Registers by Type, Listed Alphabetically

Register Name	Description	Size (Bits)	R/W†	Type‡	Signed§/Unsigned	Core/Off-Core	Function Block
a0, a1, a2, a3, a4, a5, a6, a7	Accumulators 0—7	40	R/W	data	signed	core	DAU
a0h, a1h, a2h, a3h, a4h, a5h, a6h, a7h	Accumulators 0—7, high halves (bits 31—16)	16	R/W	data	signed	core	DAU
a0l, a1l, a2l, a3l, a4l, a5l, a6l, a7l	Accumulators 0—7, low halves (bits 15—0)	16	R/W	data	signed	core	DAU
a0g, a1g, a2g, a3g, a4g, a5g, a6g, a7g	Accumulators 0—7, guard bits (bits 39—32)	8	R/W	data	signed	core	DAU
a0_1h, a2_3h, a4_5h, a6_7h	Accumulator vectors (concatenated high halves of two adjacent accumulators)	32	R/W	data	signed	core	DAU
alf	AWAIT and flags	16	R/W	c & s	unsigned	core	SYS
ar0, ar1, ar2, ar3	Auxiliary registers 0—3	16	R/W	data	signed	core	DAU
auc0, auc1	Arithmetic unit control	16	R/W	c & s	unsigned	core	DAU
c0, c1	Counters 0 and 1	16	R/W	data	signed	core	DAU
c2	Counter holding register	16	R/W	data	signed	core	DAU
cbit	BIO control	16	R/W	control	unsigned	off-core	BIO
cloop	Cache loop count	16	R/W	data	unsigned	core	SYS
csave	Cache save	32	R/W	control	unsigned	core	SYS
cstate	Cache state	16	R/W	control	unsigned	core	SYS
h	Pointer postincrement	20	R/W	data	signed	core	XAAU
i	Pointer postincrement	20	R/W	data	signed	core	XAAU
imux	Interrupt multiplex control	16	R/W	control	unsigned	off-core	IMUX
inc0, inc1	Interrupt control 0 and 1	20	R/W	control	unsigned	core	SYS
ins	Interrupt status	20	R/C††	status	unsigned	core	SYS
j	Pointer postincrement/offset	20	R/W	data	signed	core	YAAU
jhb	High byte of j (bits 15—8)	8	R	data	unsigned	core	YAAU
jlb	Low byte of j (bits 7—0)	8	R	data	unsigned	core	YAAU
jjob	JTAG test	32	R/W	data	unsigned	off-core	JTAG
k	Pointer postincrement/offset	20	R/W	data	signed	core	YAAU
mgi	Core-to-core message input	16	R	data	unsigned	off-core	MGU
mgo	Core-to-core message output	16	W	data	unsigned	off-core	MGU
p0	Product 0	32	R/W	data	signed	core	DAU
p0h	High half of p0 (bits 31—16)	16	R/W	data	signed	core	DAU
p0l	Low half of p0 (bits 15—0)	16	R/W	data	signed	core	DAU
p1	Product 1	32	R/W	data	signed	core	DAU
p1h	High half of p1 (bits 31—16)	16	R/W	data	signed	core	DAU
p1l	Low half of p1 (bits 15—0)	16	R/W	data	signed	core	DAU
pi	Program interrupt return	20	R/W	address	unsigned	core	XAAU
pid	Processor identification	16	R	c & s	unsigned	off-core	MGU

† R indicates that the register is readable by instructions; W indicates the register is writable by instructions.

‡ c & s means control and status.

§ Signed registers are in two's complement format.

†† C indicates that the register is cleared and not set.

‡‡ The IEN field (bit 14) of the **psw1** register is read only (writes to this bit are ignored).

§§ The VALUE[6:0] field (bits 6—0) are read only (writes to these bits are ignored).

6 Software Architecture (continued)

6.2 Registers (continued)

6.2.1 Directly Program-Accessible (Register-Mapped) Registers (continued)

Table 135. Program-Accessible (Register-Mapped) Registers by Type, Listed Alphabetically (continued)

Register Name	Description	Size (Bits)	R/W†	Type‡	Signed§/ Unsigned	Core/ Off-Core	Function Block
pllcon	Phase-lock loop control (CORE0 only)	16	R/W	control	unsigned	off-core	Clocks
plldly	Phase-lock loop delay control (CORE0 only)	16	R/W	control	unsigned	off-core	Clocks
pllfrq	Phase-lock loop frequency control (CORE0 only)	16	R/W	control	unsigned	off-core	Clocks
pr	Subroutine return	20	R/W	address	unsigned	core	XAAU
psw0, psw1	Program status words 0 and 1	16	R/W‡‡	c & s	unsigned	core	DAU
pt0, pt1	Pointers 0 and 1 to X-memory space	20	R/W	address	unsigned	core	XAAU
ptrap	Program trap return	20	R/W	address	unsigned	core	XAAU
r0, r1, r2, r3, r4, r5, r6, r7	Pointers 0—7 to Y-memory space	20	R/W	address	unsigned	core	YAAU
rb0, rb1	Circular buffer pointers 0 and 1 (begin address)	20	R/W	address	unsigned	core	YAAU
re0, re1	Circular buffer pointers 0 and 1 (end address)	20	R/W	address	unsigned	core	YAAU
sbit	BIO status/control	16	R/W§§	c & s	unsigned	off-core	BIO
signal	Core-to-core signal	16	W	control	unsigned	off-core	MGU
sp	Stack pointer	20	R/W	address	unsigned	core	YAAU
timer0, timer1	Timer running count 0 and 1 for Timer0 and Timer1	16	R/W	data	unsigned	off-core	Timer
timer0c, timer1c	Timer control 0 and 1 for Timer0 and Timer1	16	R/W	control	unsigned	off-core	Timer
vbase	Vector base offset	20	R/W	address	unsigned	core	XAAU
vsw	Viterbi support word	16	R/W	control	unsigned	core	DAU
x	Multiplier input	32	R/W	data	signed	core	DAU
xh	High half of x (bits 31—16)	16	R/W	data	signed	core	DAU
xl	Low half of x (bits 15—0)	16	R/W	data	signed	core	DAU
y	Multiplier input	32	R/W	data	signed	core	DAU
yh	High half of y (bits 31—16)	16	R/W	data	signed	core	DAU
yl	Low half of y (bits 15—0)	16	R/W	data	signed	core	DAU

† R indicates that the register is readable by instructions; W indicates the register is writable by instructions.

‡ c & s means control and status.

§ Signed registers are in two's complement format.

‡‡ C indicates that the register is cleared and not set.

‡‡‡ The IEN field (bit 14) of the **psw1** register is read only (writes to this bit are ignored).

§§ The VALUE[6:0] field (bits 6—0) are read only (writes to these bits are ignored).

6 Software Architecture (continued)

6.2 Registers (continued)

6.2.2 Memory-Mapped Registers

The memory-mapped registers located in their associated peripherals are each mapped to an even address. The sizes of these registers are 16 bits, 20 bits, or 32 bits. A register that is 20 bits or 32 bits must be accessed as an aligned double word. A register that is 16 bits can be accessed as a single word with an even address or as an aligned double word with the same even address. If a register that is 16 bits or 20 bits is accessed as a double word, the contents of the register are right-justified. Memory-mapped registers have the same internal format as other registers and are different from memory. Figure 59 illustrates three memory-mapped registers.

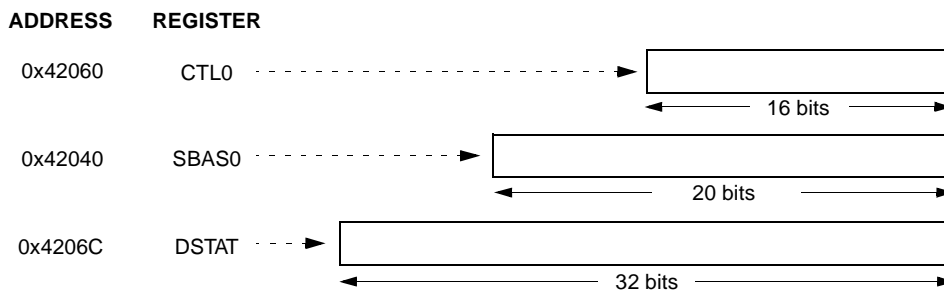


Figure 59. Example Memory-Mapped Registers

Note: Accessing memory-mapped registers with an odd address yields undefined results. The memory-mapped registers are defined by name and equated to their even memory addresses in the include file that is provided with the *LUxWORKS* tools, **16410_mmregs.h**. To differentiate the memory-mapped registers for SIU0 and SIU1, **16410_mmregs.h** appends the suffix **_U0** or **_U1** to the register name. For example, **16410_mmregs.h** defines **SCON0_U0** as the address for the SIU0 **SCON0** register and **FSTAT_U1** as the address for the SIU1 **FSTAT** register.

Memory-mapped registers are designated with upper-case bold. For example, the 32-bit DMAU status register **DSTAT** is mapped to address 0x4206C. The code segment example below accesses **DSTAT**:

```
r0 = 0x4206C      // Address of DSTAT.
nop
a0 = *r0          // Copy the contents of DSTAT to a0.
```

Alternatively:

```
#include "16410_mmregs.h"
r0 = DSTAT        // Address of DSTAT (DSTAT defined as 0x4206C in 16410_mmregs.h).
nop
a0 = *r0          // Copy the contents of DSTAT to a0.
```

After the above code segment executes, the register **a0** contains the value stored in **DSTAT**. The peripherals that contain memory-mapped registers are listed below:

- DMAU (See Table 136 on page 229).
- SEMI (See Table 137 on page 230).
- PIU (See Table 138 on page 231).
- SIU0 and SIU1 (See Table 139 on page 231.)

6 Software Architecture (continued)

6.2 Registers (continued)

6.2.2 Memory-Mapped Registers (continued)

Table 136 summarizes the DMAU memory-mapped registers. These registers are described in detail in Section 4.13.2 on page 66.

Table 136. DMAU Memory-Mapped Registers

Type	Register Name	Channel	Address	Size (Bits)	R/W	Type	Signed/Unsigned	Reset Value [†]					
DMAU Status	DSTAT	All	0x4206C	32	R	status	unsigned	X					
DMAU Master Control 0	DMCON0	All	0x4205C	16	R/W	control	unsigned	0					
DMAU Master Control 1	DMCON1	All	0x4205E										
Channel Control	CTL0	SWT0	0x42060	16	R/W	control	unsigned	X					
	CTL1	SWT1	0x42062										
	CTL2	SWT2	0x42064										
	CTL3	SWT3	0x42066										
	CTL4	MMT4	0x42068										
	CTL5	MMT5	0x4206A										
Source Address	SADD0	SWT0	0x42000	32	R/W	address	unsigned	X					
Destination Address	DADD0		0x42002										
Source Address	SADD1	SWT1	0x42004										
Destination Address	DADD1		0x42006										
Source Address	SADD2	SWT2	0x42008										
Destination Address	DADD2		0x4200A										
Source Address	SADD3	SWT3	0x4200C										
Destination Address	DADD3		0x4200E										
Source Address	SADD4	MMT4	0x42010										
Destination Address	DADD4		0x42012										
Source Address	SADD5	MMT5	0x42014										
Destination Address	DADD5		0x42016										
Source Count	SCNT0	SWT0	0x42020						20	R/W	data	unsigned	X
Destination Count	DCNT0		0x42022										
Source Count	SCNT1	SWT1	0x42024										
Destination Count	DCNT1		0x42026										
Source Count	SCNT2	SWT2	0x42028										
Destination Count	DCNT2		0x4202A										
Source Count	SCNT3	SWT3	0x4202C										
Destination Count	DCNT3		0x4202E										
Source Count	SCNT4	MMT4	0x42030										
Destination Count	DCNT4		0x42032										
Source Count	SCNT5	MMT5	0x42034										
Destination Count	DCNT5		0x42036										

[†] For this column, X indicates unknown on powerup reset and unaffected on subsequent reset. Any reserved fields within the register are reset to zero.

[‡] The reindex registers are in sign-magnitude format.

6 Software Architecture (continued)

6.2 Registers (continued)

6.2.2 Memory-Mapped Registers (continued)

Table 136. DMAU Memory-Mapped Registers (continued)

Type	Register Name	Channel	Address	Size (Bits)	R/W	Type	Signed/Unsigned	Reset Value [†]
Limit	LIM0	SWT0	0x42050	20	R/W	data	unsigned	X
	LIM1	SWT1	0x42052					
	LIM2	SWT2	0x42054					
	LIM3	SWT3	0x42056					
	LIM4	MMT4	0x42058					
	LIM5	MMT5	0x4205A					
Source Base	SBAS0	SWT0	0x42040	20	R/W	address	unsigned	X
Destination Base	DBAS0		0x42042					
Source Base	SBAS1	SWT1	0x42044	20	R/W	address	unsigned	X
Destination Base	DBAS1		0x42046					
Source Base	SBAS2	SWT2	0x42048	20	R/W	address	unsigned	X
Destination Base	DBAS2		0x4204A					
Source Base	SBAS3	SWT3	0x4204C	20	R/W	address	unsigned	X
Destination Base	DBAS3		0x4204E					
Stride	STR0	SWT0	0x42018	16	R/W	data	unsigned	X
	STR1	SWT1	0x4201A					
	STR2	SWT2	0x4201C					
	STR3	SWT3	0x4201E					
Reindex	RI0	SWT0	0x42038	20	R/W	data	signed [‡]	X
	RI1	SWT1	0x4203A					
	RI2	SWT2	0x4203C					
	RI3	SWT3	0x4203E					

[†] For this column, X indicates unknown on powerup reset and unaffected on subsequent reset. Any reserved fields within the register are reset to zero.

[‡] The reindex registers are in sign-magnitude format.

Table 137 summarizes the SEMI memory-mapped registers. These registers are described in detail in Section 4.14.4 on page 108.

Table 137. SEMI Memory-Mapped Registers

Register Name	Address	Description	Size (Bits)	R/W	Type	Reset Value
ECON0	0x40000	SEMI Control	16	R/W	Control	0x0FFF
ECON1	0x40002	SEMI Status and Control	16	R/W [†]	Control	0 [‡]
EXSEG0	0x40004	External X Segment Register for CORE0	16	R/W	Address	0
EYSEG0	0x40006	External Y Segment Register for CORE0				
EXSEG1	0x40008	External X Segment Register for CORE1				
EYSEG1	0x4000A	External Y Segment Register for CORE1				

[†] Some bits in this register are read-only or write-only.

[‡] With the following exceptions: ECON1[6,4] are a reflection of the state of external pins and are unaffected by reset, and ECON1[5] is set.

6 Software Architecture (continued)

6.2 Registers (continued)

6.2.2 Memory-Mapped Registers (continued)

Table 138 summarizes the PIU memory-mapped registers. These registers are described in detail in Section 4.15.1 on page 132.

Table 138. PIU Registers

Register Name	Address	Description	Size (Bits)	R/W	Type [†]	Reset Value [‡]
PCON	0x41000	PIU Control and Status	32	R/W [§]	c & s	0x5
PDI	0x41008	PIU Data In from Host	32	R	data	X
PDO	0x4100A	PIU Data Out to Host		R/W		
PA	0x41004	PIU Address for Host Access to DSP Memory	32	R/W	address	0x0
DSCRATCH	0x41002	DSP Scratch	32	R/W	data	0x0
HSCRATCH	0x41006	Host Scratch		R		

[†] c & s means control and status.

[‡] For this column, X indicates unknown on powerup reset and unaffected on subsequent reset.

[§] Some bits of **PCON** are read-only and some bits are writable by either the host or the DSP, but not both.

Table 139 summarizes the SIU memory-mapped registers. These registers are described in detail in Section 4.16.15 on page 181.

Table 139. SIU Memory-Mapped Registers

Register Name	Address		Description	Size (Bits) [†]	R/W	Type [‡]	Reset Value
	SIU0	SIU1					
SCON0	0x43000	0x44000	SIU Input/Output General Control	16	R/W	control	0x0000
SCON1	0x43002	0x44002	SIU Input Frame Control				0x0400
SCON2	0x43004	0x44004	SIU Output Frame Control				0x0400
SCON3	0x43006	0x44006	SIU Input/Output Subframe Control				0x0000
SCON4	0x43008	0x44008	SIU Input Even Subframe Valid Vector Control				0x0000
SCON5	0x4300A	0x4400A	SIU Input Odd Subframe Valid Vector Control				0x0000
SCON6	0x4300C	0x4400C	SIU Output Even Subframe Valid Vector Control				0x0000
SCON7	0x4300E	0x4400E	SIU Output Odd Subframe Valid Vector Control				0x0000
SCON8	0x43010	0x44010	SIU Output Even Subframe Mask Vector Control				0x0000
SCON9	0x43012	0x44012	SIU Output Odd Subframe Mask Vector Control				0x0000
SCON10	0x43014	0x44014	SIU Input/Output General Control				0x0000
SCON11	0x43016	0x44016	SIU Input/Output Active Clock Control				0x0000
SCON12	0x43018	0x44018	SIU Input/Output Active Frame Sync Control				0x8000
SIDR	0x4301A	0x4401A	SIU Input Data	16	R	data	0x0000
SODR	0x4301C	0x4401C	SIU Output Data		W		
STAT	0x4301E	0x4401E	SIU Input/Output General Status	16	R/W [§]	c & s	0x0000
FSTAT	0x43020	0x44020	SIU Input/Output Frame Status	16	R	status	0x0000
OCIX0	0x43030	0x44030	SIU Output Channel Index for Even Subframes	16	R/W	control	0x0000
OCIX1	0x43032	0x44032	SIU Output Channel Index for Odd Subframes				
ICIX0	0x43040	0x44040	SIU Input Channel Index for Even Subframes	16	R/W	control	0x0000
ICIX1	0x43042	0x44042	SIU Input Channel Index for Odd Subframes				

[†] The SIU memory-mapped register sizes represent bits used. The registers are right-justified and padded to 32 bits (the unused upper bits are zero-filled).

[‡] c & s means control and status.

[§] All bits of **STAT** are readable, and some can be written with one to clear them.

6 Software Architecture (continued)

6.2 Registers (continued)

6.2.3 Register Encodings

Tables 140—163 describe the encodings of the directly program-accessible registers.

Table 140. alf (AWAIT Low-Power and Flag) Register

15	14—10	9	8	7	6	5	4	3	2	1	0
AWAIT	Reserved	JOBF	JIBE	JCONT	LOCK†	MGIBE	MGOBF	SOMEF	SOMET	ALLF	ALLT
Bit	Field	Value	Description							R/W	Reset Value‡
15	AWAIT	0	Core operates normally.							R/W	0
		1	Core enters power-saving standby mode.								
14—10	Reserved	0	Reserved—write with zero.							R/W	0
9	JOBF	0	JTAG jjob output buffer is empty.							R/W	X
		1	JTAG jjob output buffer is full.								
8	JIBE	0	JTAG jjob input buffer is full.							R/W	X
		1	JTAG jjob input buffer is empty.								
7	JCONT	—	JTAG continue flag.							R/W	X
6	LOCK†	0	The PLL delay counter has not reached zero.							R/W	0
		1	The PLL delay counter has reached zero.								
5	MGIBE	0	Core's input message buffer register mgi is full.							R/W	X
		1	Core's input message buffer register mgi is empty (waiting to be written by other core).								
4	MGOBF	0	Core's output message buffer register mgo is empty.							R/W	X
		1	Core's output message buffer register mgo is full (waiting to be read by other core).								
3	SOMEF	0	Either all the tested BIO input pins match the test pattern, none of the BIO input pins are tested, or all the BIO pins are configured as outputs.							R/W	X
		1	SOME false—some or all tested BIO inputs pins do not match the test pattern.								
2	SOMET	0	Either none of the tested BIO input pins match the test pattern, none of the BIO input pins were tested, or all the BIO pins are configured as outputs.							R/W	X
		1	SOME true—some or all tested BIO input pins match the test pattern.								
1	ALLF	0	Some or all of the tested BIO input pins match the test pattern.							R/W	X
		1	ALL false—either no tested BIO input bits match the test pattern, none of the BIO input pins are tested, or all the BIO pins are configured as outputs.								
0	ALLT	0	Not all (some or none) of the tested BIO input bits match the test pattern.							R/W	X
		1	ALL true—either all tested BIO input bits match the test pattern, none of the BIO input pins inputs are tested, or all the BIO pins are configured as outputs.								

† LOCK is cleared on device reset or if the **pllcon** register is written.

‡ For this column, X indicates unknown on powerup reset and unaffected on subsequent reset.

6 Software Architecture (continued)

6.2 Registers (continued)

6.2.3 Register Encodings (continued)

Table 141. auc0 (Arithmetic Unit Control 0) Register

15—14	13—11	10	9	8	7	6	5—4	3—2	1—0
P1SHFT[1:0]	Reserved	FSAT	SHFT15	RAND	X=Y=	YCLR	ACLR[1:0]	ASAT[1:0]	P0SHFT[1:0]
Bit	Field	Value	Description				R/W	Reset Value	
15—14	P1SHFT[1:0]	00	p1 not shifted.				R/W	00	
		01	p1 >>2.						
		10	p1 <<2.						
		11	p1 <<1.						
13—11	Reserved	0	Reserved—write with zero.				R/W	0	
10	FSAT	0	Disabled when zero.				R/W	0	
		1	Enable 32-bit saturation for the following results: the scaled outputs of the p0 and p1 registers, the intermediate result of the 3-input ADDER [†] , and the results of the ALU/ACS, ADDER/ACS, and BMU.				R/W	0	
9	SHFT15	0	p1 >>15 in F1E operations performs normally.				R/W	0	
		1	To support GSM-EFR, p1 >>15 in F1E operations actually performs (p1 >>16)<<1 clearing the least significant bit.						
8	RAND	0	Enable pseudorandom sequence generator (PSG). [‡]				R/W	0	
		1	Reset and disable pseudorandom sequence generator (PSG).						
7	X=Y=	0	Normal operation.				R/W	0	
		1	Data transfer statements that load the y register also load the x register with the same value. [§]						
6	YCLR	0	The DAU clears yl if it loads yh .				R/W	0	
		1	The DAU leaves yl unchanged if it loads yh .						
5	ACLR[1]	0	The DAU clears a1l if it loads a1h .				R/W	0	
		1	The DAU leaves a1l unchanged if it loads a1h .						
4	ACLR[0]	0	The DAU clears a0l if it loads a0h .				R/W	0	
		1	The DAU leaves a0l unchanged if it loads a0h .						
3	ASAT[1]	0	Enable a1 saturation ^{††} on 32-bit overflow.				R/W	0	
		1	Disable a1 saturation on 32-bit overflow.						
2	ASAT[0]	0	Enable a0 saturation ^{††} on 32-bit overflow.				R/W	0	
		1	Disable a0 saturation on 32-bit overflow.						
1—0	P0SHFT[1:0]	00	p0 not shifted.				R/W	00	
		01	p0 >>2.						
		10	p0 <<2.						
		11	p0 <<1.						

† Saturation takes effect only if the ADDER has three input operands and there is no ALU/ACS operation in the same instruction.

‡ After re-enabling the PSG by clearing RAND, the program must wait one instruction cycle before testing the heads or tails condition.

§ The following apply:

- Instructions that explicitly load any part of the **x** register (i.e., **x**, **xh**, or **xl**) take precedence over the X=Y= mode.
- Instructions that load **yh** (but not **x** or **xh**) load **xh** with the same data. If YCLR is zero, the DAU clears **yl** and **xl**.
- Instructions that load **yl** load **xl** with the same data and leave **yh** and **xh** unchanged.

†† If enabled, 32-bit saturation of the accumulator value occurs if the DAU stores the value to memory or to a register. Saturation also applies if the DAU stores the low half, high half, or guard bits of the accumulator. There is no change to the contents stored in the accumulator; only the value stored to memory or a register is saturated.

6 Software Architecture (continued)

6.2 Registers (continued)

6.2.3 Register Encodings (continued)

Table 142. auc1 (Arithmetic Unit Control 1) Register

15		14—12		11—6		5—0	
Reserved		XYFBK[2:0]		ACLR[7:2]		ASAT[7:2]	
Bit	Field	Value	Description			R/W	Reset Value
15	Reserved	0	Reserved—write with zero.			R/W	0
14—12	XYFBK[2:0]†	000	Normal operation.			R/W	000
		001	Any DAU function result stored into a6 [31:0] is also stored into x .‡				
		010	Any DAU function result stored into a6 [31:16] is also stored into xh .‡				
		011	Any DAU function result stored into a6 [31:16] is also stored into xh , and any DAU function result stored into a7 [31:16] is also stored into xl .‡				
		100	Reserved.				
		101	Any DAU function result stored into a6 [31:0] is also stored into y .§				
		110	Any DAU function result stored into a6 [31:16] is also stored into yh .§††				
		111	Any DAU function result stored into a6 [31:16] is also stored into yh , and any DAU function result stored into a7 [31:16] is also stored into yl .§††				
11	ACLR[7]	0	The DAU clears a7l if it loads a7h .			R/W	0
		1	The DAU leaves a7l unchanged if it loads a7h .				
10	ACLR[6]	0	The DAU clears a6l if it loads a6h .			R/W	0
		1	The DAU leaves a6l unchanged if it loads a6h .				
9	ACLR[5]	0	The DAU clears a5l if it loads a5h .			R/W	0
		1	The DAU leaves a5l unchanged if it loads a5h .				
8	ACLR[4]	0	The DAU clears a4l if it loads a4h .			R/W	0
		1	The DAU leaves a4l unchanged if it loads a4h .				
7	ACLR[3]	0	The DAU clears a3l if it loads a3h .			R/W	0
		1	The DAU leaves a3l unchanged if it loads a3h .				
6	ACLR[2]	0	The DAU clears a2l if it loads a2h .			R/W	0
		1	The DAU leaves a2l unchanged if it loads a2h .				
5	ASAT[7]	0	Enable a7 saturation§§ on 32-bit overflow.			R/W	0
		1	Disable a7 saturation on 32-bit overflow.				
4	ASAT[6]	0	Enable a6 saturation§§ on 32-bit overflow.			R/W	0
		1	Disable a6 saturation on 32-bit overflow.				
3	ASAT[5]	0	Enable a5 saturation§§ on 32-bit overflow.			R/W	0
		1	Disable a5 saturation on 32-bit overflow.				
2	ASAT[4]	0	Enable a4 saturation§§ on 32-bit overflow.			R/W	0
		1	Disable a4 saturation on 32-bit overflow.				
1	ASAT[3]	0	Enable a3 saturation§§ on 32-bit overflow.			R/W	0
		1	Disable a3 saturation on 32-bit overflow.				
0	ASAT[2]	0	Enable a2 saturation§§ on 32-bit overflow.			R/W	0
		1	Disable a2 saturation on 32-bit overflow.				

† If the application enables any of the XYFBK modes, i.e., XYFBK[2:0] ≠ 000, the following apply:
 ■ Only if the DAU writes its result to **a6** or **a7** (e.g., **a6**=**a3**+**p0**) will the result be written to **x** or **y**. Data transfers or data move operations (e.g., **a6**=***r2**) leave the **x** or **y** register unchanged regardless of the state of the XYFBK[2:0] field setting.
 ■ If the instruction itself loads the same portion of the **x** or **y** register that the XYFBK[2:0] field specifies, the instruction load takes precedence.

‡ If the application enables the X=Y= mode (**auc0**[7] = 1), the XYFBK mode takes precedence.

§ If the application enables the X=Y= mode (**auc0**[7] = 1), the DAU also writes the **y** register value into the **x**, **xh**, or **xl** register as appropriate.

†† If the application enables the YCLR mode (**auc0**[6] = 0), the DAU clears **yl**.

‡‡ If the application enables the YCLR mode (**auc0**[6] = 0) and the instruction contains a result written to **a6** and the operation writes no result to **a7**, the DAU clears **yl**. If the application enables the YCLR mode and the instruction writes a result to **a7**, the XYFBK mode takes precedence and the DAU does not clear **yl**.

§§ If saturation is enabled and any portion of an accumulator is stored to memory or a register, the DAU saturates the entire accumulator value and stores the appropriate portion. The DAU does not change the contents of the accumulator.

6 Software Architecture (continued)

6.2 Registers (continued)

6.2.3 Register Encodings (continued)

Table 143. cbit (BIO Control) Register

15		14—8		7		6—0	
Reserved		MODE[6:0]/MASK[6:0]		Reserved		DATA[6:0]/PAT[6:0]	
Bit	Field	Value	Description			R/W	Reset Value
15	Reserved	0	Reserved—write with zero.			R/W	0
14—8	MODE[6:0] (outputs [†])	0	The BIO drives the corresponding IO<0,1>BIT[6:0] output pin to the corresponding value in DATA[6:0].			R/W	0
		1	<ul style="list-style-type: none"> ■ If the corresponding DATA[6:0] field is 0, the BIO does not change the state of the corresponding IO<0,1>BIT[6:0] output pin. ■ If the corresponding DATA[6:0] field is 1, the BIO toggles (inverts) the state of the corresponding IO<0,1>BIT[6:0] output pin. 				
	MASK[6:0] (inputs [†])	0	The BIO does not test the state of the corresponding IO<0,1>BIT[6:0] input pin to determine the state of the BIO flags [‡] .				
		1	The BIO compares the state of the corresponding IO<0,1>BIT[6:0] input pin to the corresponding value in the PAT[6:0] field to determine the state of the BIO flags [‡] —true if pin matches or false if pin doesn't match.				
7	Reserved	0	Reserved—write with zero.			R/W	0
6—0	DATA[6:0] (outputs [†])	0	<ul style="list-style-type: none"> ■ If the corresponding MODE[6:0] field is 0, the BIO drives the corresponding IO<0,1>BIT[6:0] output pin to logic 0. ■ If the corresponding MODE[6:0] field is 1, the BIO does not change the state of the corresponding IO<0,1>BIT[6:0] output pin. 			R/W	0
		1	<ul style="list-style-type: none"> ■ If the corresponding MODE[6:0] field is 0, the BIO drives the corresponding IO<0,1>BIT[6:0] output pin to logic 1. ■ If the corresponding MODE[6:0] field is 1, the BIO toggles (inverts) the state of the corresponding IO<0,1>BIT[6:0] output pin. 				
	PAT[6:0] (inputs [†])	0	If the corresponding MASK[6:0] field is 1, the BIO tests the state of the corresponding IO<0,1>BIT[6:0] input pin to determine the state of the BIO flags [‡] —true if pin is logic 0 or false if pin is logic 1.				
		1	If the corresponding MASK[6:0] field is 1, the BIO tests the state of the corresponding IO<0,1>BIT[6:0] input pin to determine the state of the BIO flags [‡] —true if pin is logic 1 or false if pin is logic 0.				

[†] An IO<0,1>BIT[6:0] pin is configured as an output if the corresponding DIREC[6:0] field (**sbit**[14:8]) has been set by the user software. An IO<0,1>BIT[6:0] pin is configured as an input if the corresponding DIREC[6:0] field has been cleared by the user software or by device reset.

[‡] The BIO flags are ALLT, ALLF, SOMET, and SOMEF. See [Table 19 on page 51](#) for details on BIO flags.

6 Software Architecture (continued)

6.2 Registers (continued)

6.2.3 Register Encodings (continued)

Table 144. **cloop** (Cache Loop) Register

15—0				
Cache Loop Count				
Bit	Field	Description	R/W	Reset Value
15—0	Cache Loop Count	Contains the count for the number of loop iterations for a do K , redo K , do cloop , or redo cloop instruction. The core decrements cloop after every loop iteration and cloop contains zero after the loop has completed.	R/W	0

Table 145. **csave** (Cache Save) Register

31—0				
Cache Save				
Bit	Field	Description	R/W	Reset Value†
31—0	Cache Save	Contains the opcode of the instruction following a do K , redo K , do cloop , or redo cloop instruction.	R/W	X

† For this column, X indicates unknown on powerup reset and unaffected on subsequent reset.

Table 146. **cstate** (Cache State) Register

15		14		13		12—10		9—5		4—0			
SU		EX		LD		Reserved		PTR[4:0]		N[4:0]			
Bit	Field	Value	Description									R/W	Reset Value
15	SU	0	The cache is not suspended—the core is not executing an interrupt or trap service routine that has interrupted or trapped a cache loop.									R/W	0
		1	The cache is suspended—the core is executing an interrupt or trap service routine that has interrupted or trapped a cache loop.										
14	EX	0	The core is not executing from cache—it is either loading the cache (executing iteration 1 of a cache loop) or it is not executing a cache loop.									R/W	0
		1	The core is executing from cache—it is executing iteration 2 or higher of a cache loop.										
13	LD	0	The core is not loading the cache—it is either not executing a cache loop or it is executing iteration 2 or higher of a cache loop.									R/W	0
		1	The core is loading the cache—it is executing iteration 1 of a cache loop.										
12—10	Reserved	0	Reserved—write with zero.									R/W	0
9—5	PTR[4:0]	0—30	Pointer to current instruction in cache to load or execute.									R/W	0
4—0	N[4:0]†	0—31	Number of instructions in the cache loop to load/save/restore.									R/W	0

† After execution of the first **do K** or **do cloop** instruction, N[4:0] contains a nonzero value.

6 Software Architecture (continued)

6.2 Registers (continued)

6.2.3 Register Encodings (continued)

Table 147. imux (Interrupt Multiplex Control) Register

15—14		13—12		11—10		9—8		7	6	5	4	3	2	1	0
XIOC[1:0]		Reserved		IMUX9[1:0]		IMUX8[1:0]		IMUX7	IMUX6	IMUX5	IMUX4	IMUX3	IMUX2	IMUX1	IMUX0
Bit	Field	Controls Multiplexed Interrupt	Value	Interrupt Selected	Description	R/W	Reset Value								
15—14	XIOC[1:0]	XIO	00	0 (logic low)	—	R/W	00								
			01	DMINT4	DMAU interrupt for MMT4.										
			10	DMINT5	DMAU interrupt for MMT5.										
			11	Reserved	Reserved.										
13—12	Reserved	—	0	—	Reserved—write with zero.	R/W	0								
11—10	IMUX9[1:0]	MXI9	00	INT3	Pin.	R/W	00								
			01	POBE	PIU output buffer empty.										
			10	PIBF	PIU input buffer full.										
			11	Reserved	Reserved.										
9—8	IMUX8[1:0]	MXI8	00	INT2	Pin.	R/W	00								
			01	POBE	PIU output buffer empty.										
			10	PIBF	PIU input buffer full.										
			11	Reserved	Reserved.										
7	IMUX7	MXI7	0	SIINT1	SIU1 input interrupt.	R/W	0								
			1	DDINT2	DMAU destination interrupt for SWT2 (SIU1).										
6	IMUX6	MXI6	0	SOINT1	SIU1 output interrupt.	R/W	0								
			1	DSINT2	DMAU source interrupt for SWT2 (SIU1).										
5	IMUX5	MXI5	0	SIINT0	SIU0 input interrupt.	R/W	0								
			1	DDINT0	DMAU destination interrupt for SWT0 (SIU0).										
4	IMUX4	MXI4	0	SOINT0	SIU0 output interrupt.	R/W	0								
			1	DSINT0	DMAU source interrupt for SWT0 (SIU0).										
3	IMUX3	MXI3	0	DDINT2	DMAU destination interrupt for SWT2 (SIU1).	R/W	0								
			1	DDINT3	DMAU destination interrupt for SWT3 (SIU1).										
2	IMUX2	MXI2	0	DSINT2	DMAU source interrupt for SWT2 (SIU1).	R/W	0								
			1	DSINT3	DMAU source interrupt for SWT3 (SIU1).										
1	IMUX1	MXI1	0	DDINT0	DMAU destination interrupt for SWT0 (SIU0).	R/W	0								
			1	DDINT1	DMAU destination interrupt for SWT1 (SIU0).										
0	IMUX0	MXI0	0	DSINT0	DMAU source interrupt for SWT0 (SIU0).	R/W	0								
			1	DSINT1	DMAU source interrupt for SWT1 (SIU0).										

6 Software Architecture (continued)

6.2 Registers (continued)

6.2.3 Register Encodings (continued)

Table 148. ID (JTAG Identification) Register

31—28		27—19		18—12		11—0	
DEVICE OPTIONS		ROMCODE		PART ID		AGERE ID	
Bit	Field	Value	Description	R/W	Reset Value		
31—28	DEVICE OPTIONS	0x2	JTAG0—device options.	R	0x2		
		0x3	JTAG1—device options.		0x3		
27—19	ROMCODE	0x190	ROMCODE of device.		0x190		
18—12	PART ID	0x14	Part ID—DSP16410B.		0x14		
11—0	AGERE ID	0x03B	Agere identification.	0x03B			

Table 149. inc0 and inc1 (Interrupt Control) Registers 0 and 1

	19—18	17—16	15—14	13—12	11—10	9—8	7—6	5—4	3—2	1—0
inc0	INT1[1:0]	INT0[1:0]	DMINT5[1:0]	DMINT4[1:0]	MXI3[1:0]	MXI2[1:0]	MXI1[1:0]	MXI0[1:0]	TIME1[1:0]	TIME0[1:0]
inc1	MXI9[1:0]	MXI8[1:0]	MXI7[1:0]	MXI6[1:0]	MXI5[1:0]	MXI4[1:0]	PHINT[1:0]	XIO[1:0]	SIGINT[1:0]	MGIBF[1:0]
Field	Value	Description	R/W	Reset Value						
INT<0—1>[1:0] DMINT<4—5>[1:0] MXI<0—9>[1:0] [†] TIME<0—1>[1:0]	00	Disable the selected interrupt (no priority).	R/W	00						
PHINT[1:0] XIO[1:0] SIGINT[1:0] MGIBF[1:0]	01	Enable the selected interrupt at priority 1 (lowest).								
	10	Enable the selected interrupt at priority 2.								
	11	Enable the selected interrupt at priority 3 (highest).								

† See Table 5 on page 28 for definition of MXI<0—9> (IMUX<0—9>).

6 Software Architecture (continued)

6.2 Registers (continued)

6.2.3 Register Encodings (continued)

Table 150. ins (Interrupt Status) Register

19	18	17	16	15	14	13	12	11	10
MXI9	MXI8	MXI7	MXI6	MXI5	MXI4	PHINT	XIO	SIGINT	MGIBF
9	8	7	6	5	4	3	2	1	0
INT1	INT0	DMINT5	DMINT4	MXI3	MXI2	MXI1	MXI0	TIME1	TIME0

Field	Value	Description	R/W	Reset Value
MXI<0—9>† PHINT XIO SIGINT MGIBF	0	Read—corresponding interrupt not pending. Write—no effect.	R/Clear	0
INT<0—1> DMINT<4—5> TIME<0—1>	1	Read—corresponding interrupt is pending. Write—clears bit and changes corresponding interrupt status to not pending.		

† See Table 5 on page 28 for definition of MXI<0—9> (IMUX<0—9>).

Table 151. mgi (Core-to-Core Message Input) Register

15—0				
Message Input				
Bit	Field	Description	R/W	Reset Value
15—0	Message Input	Full-duplex message buffer that holds the input data word.	R	0

Table 152. mgo (Core-to-Core Message Output) Register

15—0				
Message Output				
Bit	Field	Description	R/W	Reset Value
15—0	Message Output	Full-duplex message buffer that holds the output data word.	W	0

Table 153. pid (Processor Identification) Register

15—0							
PID							
Bit	Field	Value		Description	R/W	Reset Value	
15—0	PID	0x0000	CORE0	Processor identification to allow the software to distinguish whether it is running on CORE0 or CORE1.	R	0x0000	CORE0
		0x0001	CORE1			0x0001	CORE1

6 Software Architecture (continued)

6.2 Registers (continued)

6.2.3 Register Encodings (continued)

Table 154. pllcon (Phase-Lock Loop Control) Register

Note: pllcon is accessible in CORE0 only.

15—2			1	0	
Reserved			PLLEN	PLLSEL	
Bit	Field	Value	Description	R/W	Reset Value
15—2	Reserved	—	Reserved—write with zero.	R/W	0
1	PLLEN	0	Disable (power down) the PLL.	R/W	0
		1	Enable (power up) the PLL.		
0	PLLSEL	0	Select the CKI input as the internal clock (CLK) source.	R/W	0
		1	Select the PLL as the internal clock (CLK) source.		

Table 155. pllfrq (Phase-Lock Loop Frequency Control) Register

Note: pllfrq is accessible in CORE0 only.

15—14			13—9	8—0	
OD[1:0]			D[4:0]	M[8:0]	
Bit	Field	Value	Description	R/W	Reset Value
15—14	OD[1:0]	00	$f(OD) = 2$. Divide VCO output by 2.	R/W	00
		01	$f(OD) = 4$. Divide VCO output by 4.		
		10	$f(OD) = 4$. Divide VCO output by 4.		
		11	$f(OD) = 8$. Divide VCO output by 8.		
13—9	D[4:0]	0—31	Divide f_{CKI} by this value plus two ($D + 2$).	R/W	00000
8—0	M[8:0]	0—511	Multiply f_{CKI} by this value plus two ($M + 2$).	R/W	00000000

Table 156. plldly (Phase-Lock Loop Delay Control) Register

Note: plldly is accessible in CORE0 only.

15—0					
DLY[15:0]					
Bit	15—0	Value	Description	R/W	Reset Value
15—0	DLY[15:0]	—	The contents of DLY[15:0] is loaded into the PLL delay counter after a pllcon register write. If PLLEN (pllcon [1]) is 1, the counter decrements each CKI cycle. When the counter reaches zero, the LOCK flag† for both CORE0 and CORE1 is asserted.	R/W	0x1388

† The state of the LOCK flag can be tested by conditional instructions (Table 134 on page 223) and is also visible in the **alf** register (Table 140 on page 232). The LOCK flag is cleared by a device reset or a write to the **pllcon** register.

6 Software Architecture (continued)

6.2 Registers (continued)

6.2.3 Register Encodings (continued)

Table 157. psw0 (Processor Status Word 0) Register

15	14	13	12	11	10	9	8—5	4	3—0
LMI	LEQ	LLV	LMV	SLLV	SLMV	a1V	a1[35:32]	a0V	a0[35:32]
Bit	Field	Value	Description				R/W	Reset Value [†]	
15	LMI	0	Most recent DAU result [‡] is not negative.				R/W	X	
		1	Most recent DAU result [§] is negative (minus).						
14	LEQ	0	Most recent DAU result [§] is not zero.				R/W	X	
		1	Most recent DAU result [§] is zero (equal).						
13	LLV	0	Most recent DAU operation [§] did not result in logical overflow.				R/W	X	
		1	Most recent DAU operation [§] resulted in logical overflow. ^{††}						
12	LMV	0	Most recent DAU operation did not result in mathematical overflow.				R/W	X	
		1	Most recent DAU operation [§] resulted in mathematical overflow. ^{‡‡}						
11	SLLV	0	Previous DAU operation did not result in logical overflow.				R/W	0	
		1	Sticky version of LLV that remains active once set by a DAU operation until explicitly cleared by a write to psw0 .						
10	SLMV	0	Previous DAU operation did not result in mathematical overflow.				R/W	0	
		1	Sticky version of LMV that remains active once set by a DAU operation until explicitly cleared by a write to psw0 .						
9	a1V	0	The current contents of a1 is not mathematically overflowed.				R/W	X	
		1	The current contents of a1 is mathematically overflowed. ^{§§}						
8—5	a1[35:32]	—	Reflects the four lower guard bits of a1 . ^{†††}				R/W	XXXX	
4	a0V	0	The current contents of a0 is not mathematically overflowed.				R/W	X	
		1	The current contents of a0 is mathematically overflowed. ^{§§}						
3—0	a0[35:32]	—	Reflects the four lower guard bits of a0 . ^{†††}				R/W	XXXX	

[†] In this column, X indicates unknown on powerup reset and unaffected on subsequent reset.

[‡] ALU/ACS result or operation if the instruction uses the ALU/ACS; otherwise, ADDER or BMU result, whichever applies.

[§] ALU/ACS result if the DAU operation uses the ALU/ACS; otherwise, ADDER or BMU result, whichever applies.

^{††} The ALU or ADDER cannot represent the result in 40 bits or the BMU control operand is out of range.

^{‡‡} The ALU/ACS, ADDER, or BMU cannot represent the result in 32 bits. For the BMU, other conditions can also cause mathematical overflow.

^{§§} The most recent DAU result that was written to that accumulator resulted in mathematical overflow (LMV) with FSAT = 0.

^{†††} Required for compatibility with DSP16XX family.

6 Software Architecture (continued)

6.2 Registers (continued)

6.2.3 Register Encodings (continued)

Table 158. psw1 (Processor Status Word 1) Register

15	14	13—12	11—10	9—7	6	5—0
Reserved	IEN	IPLc[1:0]	IPLp[1:0]	Reserved	EPAR	a[7:2]V
Bit	Field	Value	Description	R/W	Reset Value†	
15	Reserved	0	Reserved—write with zero.	R/W	0	
14	IEN‡	0	Hardware interrupts are globally disabled.	R	0	
		1	Hardware interrupts are globally enabled.			
13—12	IPLc[1:0]	00	Current hardware interrupt priority level is 0; core handles pending interrupts of priority 1, 2, or 3.	R/W	00	
		01	Current hardware interrupt priority level is 1; core handles pending interrupts of priority 2 or 3.			
		10	Current hardware interrupt priority level is 2; core handles pending interrupts of priority 3 only.			
		11	Current hardware interrupt priority level is 3; core does not handle any pending interrupts.			
11—10	IPLp[1:0]	00	Previous hardware interrupt priority level§ was 0.	R/W	XX	
		01	Previous hardware interrupt priority level§ was 1.			
		10	Previous hardware interrupt priority level§ was 2.			
		11	Previous hardware interrupt priority level§ was 3.			
9—7	Reserved	0	Reserved—write with zero.	R/W	X	
6	EPAR	0	Most recent BMU or special function shift result has odd parity.	R/W	X	
		1	Most recent BMU or special function shift result has even parity.			
5	a7V	0	The current contents of a7 are not mathematically overflowed.	R/W	X	
		1	The current contents of a7 are mathematically overflowed.††			
4	a6V	0	The current contents of a6 are not mathematically overflowed.	R/W	X	
		1	The current contents of a6 are mathematically overflowed.††			
3	a5V	0	The current contents of a5 are not mathematically overflowed.	R/W	X	
		1	The current contents of a5 are mathematically overflowed.††			
2	a4V	0	The current contents of a4 are not mathematically overflowed.	R/W	X	
		1	The current contents of a4 are mathematically overflowed.††			
1	a3V	0	The current contents of a3 are not mathematically overflowed.	R/W	X	
		1	The current contents of a3 are mathematically overflowed.††			
0	a2V	0	The current contents of a2 are not mathematically overflowed.	R/W	X	
		1	The current contents of a2 are mathematically overflowed.††			

† In this column, X indicates unknown on powerup reset and unaffected on subsequent reset.
 ‡ The user clears this bit by executing a **di** instruction and sets it by executing an **ei** or **ireturn** instruction. The core clears this bit whenever it begins to service an interrupt.
 § Previous interrupt priority level is the priority level of the interrupt most recently serviced prior to the current interrupt. This field is used for interrupt nesting.
 †† The most recent DAU result that was written to that accumulator resulted in mathematical overflow (LMV) with FSAT = 0.

6 Software Architecture (continued)

6.2 Registers (continued)

6.2.3 Register Encodings (continued)

Table 159. sbit (BIO Status/Control) Register

15		14—8		7		6—0	
Reserved		DIREC[6:0]		Reserved		VALUE[6:0]	
Bit	Field	Value	Description	R/W	Reset Value [†]		
15	Reserved	0	Reserved—write with zero.	R/W	0		
14—8	DIREC[6:0] (Controls direction of pins)	0	Configure the corresponding IO<0,1>BIT[6:0] pin as an input.	R/W	0		
		1	Configure the corresponding IO<0,1>BIT[6:0] pin as an output.				
7	Reserved	—	Reserved.	R	X		
6—0	VALUE[6:0] [‡] (Current value of pins)	0	The current state of the corresponding IO<0,1>BIT[6:0] pin is logic 0.	R	P [§]		
		1	The current state of the corresponding IO<0,1>BIT[6:0] pin is logic 1.				

[†] For this column, X indicates unknown on powerup reset and unaffected on subsequent reset.

[‡] This field is read-only—writing the VALUE[6:0] field of **sbit** has no effect. If the user software toggles a bit in the DIREC[6:0] field, there is a latency of one cycle until the VALUE[6:0] field reflects the current state of the corresponding IO<0,1>BIT[6:0] pin. If an IO<0,1>BIT[6:0] pin is configured as an output (DIREC[6:0] = 1) and the user software writes **cbit** to change the state of the pin, there is a latency of two cycles until the VALUE[6:0] field reflects the current state of the corresponding IO<0,1>BIT[6:0] output pin.

[§] The IO<0,1>BIT[6:0] pins are configured as inputs after reset. If external circuitry does not drive an IO<0,1>BIT[n] pin, the VALUE[n] field is undefined after reset.

Table 160. signal (Core-to-Core Signal) Register

15—11			1		0	
Reserved			SIGTRAP		SIGINT	
Bit	Field	Value	Description	R/W	Reset Value	
15—11	Reserved	0	Reserved—write with zero.	W	0	
1	SIGTRAP	0	No effect.	W	0	
		1	Trap the other core by asserting its PTRAP signal.			
0	SIGINT	0	No effect.	W	0	
		1	Interrupt the other core by asserting its SIGINT interrupt.			

Note: If the program sets the SIGTRAP or SIGINT field, the MGU automatically clears the field after asserting the trap or interrupt. Therefore, the program must not explicitly clear the field.

6 Software Architecture (continued)

6.2 Registers (continued)

6.2.3 Register Encodings (continued)

Table 161. timer0c and timer1c (TIMER<0,1> Control) Registers

15—7		6	5	4	3—0	
Reserved		PWR_DWN	RELOAD	COUNT	PRESCALE[3:0]	
Bit	Field	Value	Description		R/W	Reset Value
15—7	Reserved	0	Reserved—write with zero.		R/W	0
6	PWR_DWN	0	Power up the timer.		R/W	0
		1	Power down the timer†.			
5	RELOAD	0	Stop decrementing the down counter after it reaches zero.		R/W	0
		1	Automatically reload the down counter from the period register after the counter reaches zero and continue decrementing the counter indefinitely.			
4	COUNT	0	Hold the down counter at its current value, i.e., stop the timer.		R/W	0
		1	Decrement the down counter, i.e., run the timer.			
3—0	PRESCALE[3:0]	0000	Controls the counter prescaler to determine the frequency of the timer, i.e., the frequency of the clock applied to the timer down counter. This frequency is a ratio of the internal clock frequency f _{CLK} .	f _{CLK} /2	R/W	0000
		0001		f _{CLK} /4		
		0010		f _{CLK} /8		
		0011		f _{CLK} /16		
		0100		f _{CLK} /32		
		0101		f _{CLK} /64		
		0110		f _{CLK} /128		
		0111		f _{CLK} /256		
		1000		f _{CLK} /512		
		1001		f _{CLK} /1024		
		1010		f _{CLK} /2048		
		1011		f _{CLK} /4096		
		1100		f _{CLK} /8192		
		1101		f _{CLK} /16384		
		1110		f _{CLK} /32768		
		1111		f _{CLK} /65536		

† If TIMER<0,1> is powered down, timer<0,1> cannot be read or written. While the timer is powered down, the state of the down counter and period register remain unchanged.

6 Software Architecture (continued)

6.2 Registers (continued)

6.2.3 Register Encodings (continued)

Table 162. timer0 and timer1 (TIMER<0,1> Running Count) Registers

15—0				
TIMER<0,1> Down Counter				
TIMER<0,1> Period Register				
Bit	Field [†]	Description	R/W [‡]	Reset Value [§]
15—0	Down Counter	If the COUNT field (timer<0,1>c[4]) is set, TIMER<0,1> decrements this portion of the timer<0,1> register every prescale period. When the down counter reaches zero, TIMER<0,1> generates an interrupt.	R/W	0
15—0	Period Register	If the COUNT field (timer<0,1>c[4]) and the RELOAD field (timer<0,1>c[5]) are both set and the down counter contains zero, TIMER<0,1> reloads the down counter with the contents of this portion of the timer<0,1> register.	W	X

[†] If the user program writes to the **timer<0,1>** register, TIMER<0,1> loads the 16-bit write value into the down counter and into the period register simultaneously. If the user program reads the **timer<0,1>** register, TIMER<0,1> returns the current 16-bit value from the down counter.

[‡] To read or write the **timer<0,1>** register, TIMER<0,1> must be powered up, i.e., the PWR_DWN field (**timer<0,1>c[6]**) must be cleared.

[§] For this column, X indicates unknown on powerup reset and unaffected on subsequent reset.

Table 163. vsw (Viterbi Support Word) Register

15—6			5	4	3	2	1	0
Reserved			VEN	MAX	TB2	Reserved	CFLAG1	CFLAG0
Bit	Field	Value	Description				R/W	Reset Value
15—6	Reserved	0	Reserved—write with zero.				R/W	0
5	VEN	0	Disables Viterbi side effects.				R/W	0
		1	Enables Viterbi side effects.					
4	MAX	0	The cmp0() , cmp1() , and cmp2() functions select the minimum value from the input operands.				R/W	0
		1	The cmp0() , cmp1() , and cmp2() functions select the maximum value from the input operands.					
3	TB2	0 (GSM/IS95-compatible mode)	For the single-ACS (40-bit) cmp1() function, the traceback encoder stuffs one traceback bit into ar0 . For the single-ACS (40-bit) cmp0() function, the traceback encoder stuffs one old traceback bit from ar0 into ar1 . For the dual-ACS (16-bit) cmp1() function, the traceback encoder stuffs CFLAG into ar0 and ar2 .				R/W	0
		1 (IS54/IS136-compatible mode)	For the single-ACS (40-bit) cmp1() function, the traceback encoder stuffs two traceback bits into ar0 . For the single-ACS (40-bit) cmp0() function, the traceback encoder stuffs two old traceback bits from ar0 into ar1 .					
2	Reserved	0	Reserved—write with zero.				R/W	0
1	CFLAG1	—	Previous value of CFLAG0. The traceback encoder copies the value of CFLAG0 to CFLAG1 if the DAU executes a cmp2() function and VEN=1.				R/W	0
0	CFLAG0	—	Previous value of CFLAG [†] . The traceback encoder copies the value of CFLAG to CFLAG0 if the DAU executes a cmp2() function and VEN=1.				R/W	0

[†] For the **cmp2(aSE, aDE)** function, CFLAG=0 if MAX=0 and aSE≥aDE or if MAX=1 and aSE<aDE, and CFLAG=1 if MAX=0 and aSE<aDE or if MAX=1 and aSE≥aDE.

6 Software Architecture (continued)

6.2 Registers (continued)

6.2.4 Reset States

Pin reset occurs if a high-to-low transition is applied to the RSTN pin. Tables 164 through 168 show how reset affects the core and off-core registers. The following bit codes apply:

- Bit code • indicates that this bit is unknown on powerup reset and unaffected on a subsequent pin reset.
- Bit code P indicates the value on the corresponding input pin.

Table 164. Core Register States After Reset—40-Bit Registers

Register	Bits 39—0
a0	•••• •••• •••• •••• •••• •••• •••• •••• •••• ••••
a1	•••• •••• ••~• ••~• ••~• ••~• ••~• ••~• ••~• ••~• ••~•
a2	•••• ••~• ••~• ••~• ••~• ••~• ••~• ••~• ••~• ••~•
a3	•••• ••~• ••~• ••~• ••~• ••~• ••~• ••~• ••~• ••~•
a4	••~• ••~• ••~• ••~• ••~• ••~• ••~• ••~• ••~• ••~•
a5	••~• ••~• ••~• ••~• ••~• ••~• ••~• ••~• ••~• ••~•
a6	••~• ••~• ••~• ••~• ••~• ••~• ••~• ••~• ••~• ••~•
a7	••~• ••~• ••~• ••~• ••~• ••~• ••~• ••~• ••~• ••~•

Table 165. Core Register States After Reset—32-Bit Registers

Register	Bits 31—0
csave	••~• ••~• ••~• ••~• ••~• ••~• ••~• ••~• ••~• ••~•
p0	••~• ••~• ••~• ••~• ••~• ••~• ••~• ••~• ••~• ••~•
p1	••~• ••~• ••~• ••~• ••~• ••~• ••~• ••~• ••~• ••~•
x	••~• ••~• ••~• ••~• ••~• ••~• ••~• ••~• ••~• ••~•
y	••~• ••~• ••~• ••~• ••~• ••~• ••~• ••~• ••~• ••~•

6 Software Architecture (continued)

6.2 Registers (continued)

6.2.4 Reset States (continued)

Table 166. Core Register States After Reset—20-Bit Registers

Register	Bits 19—0	Register	Bits 19—0
h	r1
i	r2
inc0	0000 0000 0000 0000 0000	r3
inc1	0000 0000 0000 0000 0000	r4
ins	0000 0000 0000 0000 0000	r5
j	r6
k	r7
PC†	XXXX 0000 0000 0000 0000	rb0	0000 0000 0000 0000 0000
pi	rb1	0000 0000 0000 0000 0000
pr	re0	0000 0000 0000 0000 0000
pt0	re1	0000 0000 0000 0000 0000
pt1	sp
ptrap	vbase	0010 0000 0000 0001 0100
r0		

† **PC** resets to 0x20000 (first address of IROM) if the EXM pin is 0 at the time of reset. It resets to 0x80000 (first address of EROM) if the EXM pin is 1 at the time of reset.

Table 167. Core Register States After Reset—16-Bit Registers

Register	Bits 15—0	Register	Bits 15—0
alf	0000 00..	c1
ar0	c2
ar1	cloop	0000 0000 0000 0000
ar2	cstate	0000 0000 0000 0000
ar3	psw0 00..
auc0	0000 0000 0000 0000	psw1	0000
auc1	0000 0000 0000 0000	vsw	0000 0000 0000 0000
c0		

Table 168. Off-Core (Peripheral) Register Reset Values

Register	Bits 15—0	Register	Bits 15—0
cbit	pllfrq	0000 0000 0000 0000
imux	0000 0000 0000 0000	plldly	0001 0011 1000 1000
mgi	0000 0000 0000 0000	sbit	0000 0000 •PPP PPPP
mgo	0000 0000 0000 0000	signal	0000 0000 0000 0000
pid (CORE0)	0000 0000 0000 0000	timer<0—1>	0000 0000 0000 0000
pid (CORE1)	0000 0000 0000 0001	timer<0—1>c	0000 0000 0000 0000
pllcon	0000 0000 0000 0000		
jjob†		

† The **jjob** register is the only peripheral register that is 32 bits; therefore, the bit pattern shown is for bits 31—0.

6 Software Architecture (continued)

6.2 Registers (continued)

6.2.4 Reset States (continued)

Table 169. Memory-Mapped Register Reset Values—32-Bit Registers

Register	Bits 31—0
DADD<0—5>	0000 0...
DSCRATCH	0000 0000 0000 0000 0000 0000 0000 0000
DSTAT
HSCRATCH	0000 0000 0000 0000 0000 0000 0000 0000
PA	0000 0000 0000 0000 0000 0000 0000 0000
PCON	0000 0000 0000 0000 0000 0000 0000 0101
PDI	0000 0000 0000 0000 0000 0000 0000 0000
PDO	0000 0000 0000 0000 0000 0000 0000 0000
SADD<0—5>	0000 0...

Table 170. Memory-Mapped Register Reset Values—20-Bit Registers

Register	Bits 19—0
DBAS<0—3>
DCNT<0—5>
LIM<0—5>
RI<0—3>
SBAS<0—3>
SCNT<0—5>

Table 171. Memory-Mapped Register Reset Values—16-Bit Registers

Register	Bits 15—0
CTL<0—3>	0000 0000 00..
CTL<4—5>	0000 0000 00..
DMCON<0—1>	0000 0000 0000 0000
ECON0	0000 1111 1111 1111
ECON1	0000 0000 0P1P 0000
EXSEG<0—1>	0000 0000 0000 0000
EYSEG<0—1>	0000 0000 0000 0000
FSTAT	0000 0000 0000 0000
ICIX<0—1>	0000 0000 0000 0000
OCIX<0—1>	0000 0000 0000 0000
SCON0	0000 0000 0000 0000
SCON<1—2>	0000 0100 0000 0000
SCON<3—11>	0000 0000 0000 0000
SCON12	1000 0000 0000 0000
SIDR	0000 0000 0000 0000
SODR	0000 0000 0000 0000
STAT	0000 0000 0000 0000
STR<0—3>	00..

6 Software Architecture (continued)

6.2 Registers (continued)

6.2.5 RB Field Encoding

Table 172 describes the encoding of the RB field. This information supplements the instruction set encoding information in the *DSP16000 Digital Signal Processor Core Instruction Set Reference Manual*.

Table 172. RB Field

RB [†]	Register	RB [†]	Register	RB [†]	Register	RB [†]	Register
000000	a0g	010000	Reserved	100000	Reserved	110000	Reserved
000001	a1g	010001	cloop	100001	Reserved	110001	Reserved
000010	a2g	010010	cstate	100010	plldly	110010	Reserved
000011	a3g	010011	csave	100011	pllfrq	110011	Reserved
000100	a4g	010100	auc1	100100	signal	110100	Reserved
000101	a5g	010101	ptrap	100101	cbit	110101	Reserved
000110	a6g	010110	vsw	100110	sbit	110110	Reserved
000111	a7g	010111	Reserved	100111	timer0c	110111	Reserved
001000	a0_1h	011000	ar0	101000	timer0	111000	Reserved
001001	inc1	011001	ar1	101001	timer1c	111001	Reserved
001010	a2_3h	011010	ar2	101010	timer1	111010	Reserved
001011	inc0	011011	ar3	101011	mgo	111011	Reserved
001100	a4_5h	011100	vbase	101100	mgi	111100	Reserved
001101	pi	011101	ins	101101	imux	111101	Reserved
001110	a6_7h	011110	Reserved	101110	pid	111110	Reserved
001111	psw1	011111	Reserved	101111	pllcon	111111	jjob

[†] RB field specifies one of a secondary set of registers as the destination of a data move. Codes 000000 through 011111 correspond to core registers and codes 100000 through 111111 correspond to off-core (peripheral) registers.

7 Ball Grid Array Information

7.1 208-Ball PBGA Package

Figure 60 illustrates the ball assignment for the 208-ball PBGA package. This view is from the top of the package.

	1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16	
A	VDD2	ED5	ED7	ED9	ED11	ED15	ED17	VSS	VDD1	ED26	ED30	ERWN1	VSS	EION	EA1	VDD2	A
B	ED3	VDD1	ED6	ED8	VSS	ED14	ED16	ED20	ED25	ED27	ED31	EROMN	ERAMN	EA0	VDD1	EA3	B
C	ED2	ED1	ED4	ED10	ED12	VDD1	ED18	ED21	ED24	VDD2	ED29	ERWN0	VDD2	EA2	EA4	EA5	C
D	VSS	ED0	VDD2	VDD1	ED13	VDD2	ED19	ED22	ED23	VSS	ED28	EACKN	VDD1	EA8	EA7	EA6	D
E	EREQN	ERDY	ESIZE	EXM									EA11	EA10	VSS	EA9	E
F	TDO0	ERTYPE	TRST0N	TCK0									VDD2	VDD1	EA12	EA13	F
G	TDI0	TMS0	VDD2	VSS			VSS	VSS	VSS	VSS			EA17	EA16	EA14	EA15	G
H	VDD1A	CKI	VSS1A	RSTN			VSS	VSS	VSS	VSS			ESEG1	ESEG0	EA18	VSS	H
J	VSS	INT2	INT3	TRAP			VSS	VSS	VSS	VSS			ESEG2	ESEG3	VDD1	ECKO	J
K	SICK0	SIFS0	INT0	INT1			VSS	VSS	VSS	VSS			VSS	VDD2	TMS1	TDI1	K
L	SOCK0	SOFS0	VDD1	VDD2									TCK1	TRST1N	SOD1	TDO1	L
M	SOD0	VSS	SID0	SCK0									SID1	SCK1	SOCK1	SOFS1	M
N	IO0BIT5	IO0BIT4	IO0BIT6	VDD1	PD10	PD6	VSS	PD1	PD0	PRDY	VDD2	PCSN	VDD1	VDD2	SIFS1	VSS	N
P	IO0BIT3	IO0BIT2	IO0BIT0	VDD2	PD11	PD7	VDD2	PD2	POBE	PINT	VDD1	PADD3	PADD1	IO1BIT2	IO1BIT0	SICK1	P
R	IO0BIT1	VDD1	EYMODE	PD14	PD13	PD9	PD5	VDD1	PIBF	PODS	PRWN	VSS	PADD0	IO1BIT4	VDD1	IO1BIT1	R
T	VDD2	VSS	PD15	VSS	PD12	PD8	PD4	PD3	VSS	PRDYMD	PIDS	PADD2	IO1BIT6	IO1BIT5	IO1BIT3	VDD2	T

Figure 60. 208-Ball PBGA Package Ball Grid Array Assignments (See-Through Top View)

7 Ball Grid Array Information (continued)

7.1 208-Ball PBGA Package (continued)

Table 173 describes the PBGA ball assignments sorted by symbol for the 208-ball package. For each signal or power/ground connection, this table lists the PBGA coordinate, the symbol name, the type (I = input, O = output, I/O = input/output, O/Z = 3-state output, P = power, G = ground), and description. Inputs and bidirectional pins do not maintain full CMOS levels when not driven. They must be pulled to V_{DD2} or V_{SS} through the appropriate pull up/down resistor (refer to [Section 10.1 on page 269](#)). An unused external SEMI data bus (ED[31:0]) can be statically configured as outputs by asserting the EYMODE pin. At full CMOS levels, no significant dc current is drawn.

Table 173. 208-Ball PBGA Ball Assignments Sorted Alphabetically by Symbol

Symbol	208 Ball PBGA Coordinate	Type	Description
CKI	H2	I	External Clock Input.
EA[18:0]	H15, G13, G14, G16, G15, F16, F15, E13, E14, E16, D14, D15, D16, C16, C15, B16, C14, A15, B14	O	External Address Bus, Bits 18—0.
EACKN	D12	O	External Device Acknowledge for External Memory Interface (negative assertion).
ECKO	J16	O	Programmable Clock Output.
ED[31:0]	B11, A11, C11, D11, B10, A10, B9, C9, D9, D8, C8, B8, D7, C7, A7, B7, A6, B6, D5, C5, A5, C4, A4, B4, A3, B3, A2, C3, B1, C1, C2, D2	I/O	External Memory Data Bus, Bits 31—0.
EION	A14	O	Enable for External I/O (negative assertion).
ERAMN	B13	O	External RAM Enable (negative assertion).
ERDY	E2	I	External Memory Device Ready.
EREQN	E1	I	External Device Request for EMI Interface (negative assertion).
EROMN	B12	O	Enable for External ROM (negative assertion).
ERTYPE	F2	I	EROM Type Control: If 0, asynchronous SRAM mode. If 1, synchronous SRAM mode.
ERWN0	C12	O	Read/Write, Bit 0 (negative assertion).
ERWN1	A12	O	Read/Write, Bit 1 (negative assertion).
ESEG[3:0]	J14, J13, H13, H14	O	External Segment Address, Bits 3—0.
ESIZE	E3	I	External Memory Bus Size Control: If 0, 16-bit external interface. If 1, 32-bit external interface.
EXM	E4	I	External Boot-up Control for CORE0.
EYMODE	R3	I	External Data Bus Mode Configuration Pin.
INT[3:0]	J3, J2, K4, K3	I	External Interrupt Requests 3—0.
IO0BIT[6:0]	N3, N1, N2, P1, P2, R1, P3	I/O	BIO0 Status/Control, Bits 6—0.
IO1BIT[6:0]	T13, T14, R14, T15, P14, R16, P15	I/O	BIO1 Status/Control, Bits 6—0.
PADD[3:0]	P12, T12, P13, R13	I	PIU Address, Bits 3—0.
PCSN	N12	I	PIU Chip Select (negative assertion).
PD[15:0]	T3, R4, R5, T5, P5, N5, R6, T6, P6, N6, R7, T7, T8, P8, N8, N9	I/O	PIU Data Bus, Bits 15—0.
PIBF	R9	O	PIU Input Buffer Full Flag.
PIDS	T11	I	PIU Input Data Strobe.
PINT	P10	O	PIU Interrupt Request to Host.
POBE	P9	O	PIU Output Buffer Empty Flag.
PODS	R10	I	PIU Output Data Strobe.

7 Ball Grid Array Information (continued)

7.1 208-Ball PBGA Package (continued)

Table 173. 208-Ball PBGA Ball Assignments Sorted Alphabetically by Symbol (continued)

Symbol	208-Ball PBGA Coordinate	Type	Description
PRDY	N10	O	PIU Host Ready.
PRDYMD	T10	I	PRDY Mode.
PRWN	R11	I	PIU Read/Write (negative assertion).
RSTN	H4	I	Device Reset (negative assertion).
SCK0	M4	I	External Clock for SIU0 Active Generator.
SCK1	M14	I	External Clock for SIU1 Active Generator.
SICK0	K1	I/O	SIU0 Input Clock.
SICK1	P16	I/O	SIU1 Input Clock.
SID0	M3	I	SIU0 Input Data.
SID1	M13	I	SIU1 Input Data.
SIFS0	K2	I/O	SIU0 Input Frame Sync.
SIFS1	N15	I/O	SIU1 Input Frame Sync.
SOCK0	L1	I/O	SIU0 Output Clock.
SOCK1	M15	I/O	SIU1 Output Clock.
SOD0	M1	O/Z	SIU0 Output Data.
SOD1	L15	O/Z	SIU1 Output Data.
SOFS0	L2	I/O	SIU0 Output Frame Sync.
SOFS1	M16	I/O	SIU1 Output Frame Sync.
TCK0	F4	I	JTAG Test Clock for CORE0.
TCK1	L13	I	JTAG Test Clock for CORE1.
TDI0	G1	I	JTAG Test Data Input for CORE0.
TDI1	K16	I	JTAG Test Data Input for CORE1.
TDO0	F1	O	JTAG Test Data Output for CORE0.
TDO1	L16	O	JTAG Test Data Output for CORE1.
TMS0	G2	I	JTAG Test Mode Select for CORE0.
TMS1	K15	I	JTAG Test Mode Select for CORE1.
TRAP	J4	I/O	TRAP/Breakpoint Indication.
TRST0N	F3	I	JTAG TAP Controller Reset for CORE0 (negative assertion).
TRST1N	L14	I	JTAG TAP Controller Reset for CORE1 (negative assertion).
VDD1	A9, B2, B15, C6, D4, D13, F14, J15, L3, N4, N13, P11, R2, R8, R15	P	Power Supply for Internal Circuitry.
VDD1A	H1	P	Power Supply for PLL Circuitry.
VDD2	A1, A16, C13, D3, D6, F13, G3, K14, L4, N11, N14, P4, P7, T1, T16, C10	P	Power Supply for External Circuitry (I/O).
VSS	A13, A8, B5, D1, D10, E15, G7, G8, G9, G10, G4, H7, H8, H9, H10, H16, J1, J7, J8, J9, J10, K7, K8, K9, K10, K13, M2, N7, N16, R12, T2, T4, T9	G	Ground.
VSS1A	H3	G	Ground for PLL Circuitry.

7 Ball Grid Array Information (continued)

7.2 256-Ball EBGA Package

Figure 61 illustrates the ball assignment for the 256-ball EBGA package. This view is from the top of the package.

	1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16	17	18	19	20	
A	VSS	VDD2	EION	ERWN1	VSS	VSS	VDD2	ED27	ED25	ED23	VDD2	VSS	VSS	ED15	VDD2	VSS	ED9	ED5	VDD2	VSS	A
B	VDD2	VSS	EA2	ERAMN	ERWN0	ED30	NC	ED28	ED26	ED22	ED20	ED18	ED17	ED14	NC	ED11	ED7	VDD1	VSS	VDD2	B
C	EA4	EA3	VSS	EA1	VDD1	EACKN	VDD1	ED29	VDD1	VDD1	ED21	ED19	ED16	ED13	ED12	ED8	NC	VSS	ED4	ED1	C
D	EA8	EA6	VDD1	NC	EA0	EROMN	ED31	VDD2	VDD1	ED24	VDD2	VDD1	VDD1	VDD2	ED10	ED6	NC	ED3	ED0	EREQN	D
E	VSS	EA10	EA7	EA5													ED2	VDD1	ESIZE	VSS	E
F	VDD2	NC	EA11	EA9													ERDY	EXM	TDO0	VSS	F
G	VDD1	EA13	EA12	VDD2													ERTYPE	VDD1	NC	VDD2	G
H	VSS	EA16	EA15	EA14													VDD2	TRST0N	TCK0	TMS0	H
J	VSS	VDD1	EA18	EA17													TDI0	VDD1A	CKI	VSS1A	J
K	VDD2	ESEG0	NC	VDD2													RSTN	INT3	VDD1	TRAP	K
L	ESEG2	ESEG1	VDD1	ESEG3													VDD2	INT2	INT1	VDD2	L
M	ECKO	TDI1	VDD1	VDD1													SICK0	INT0	SIFS0	VSS	M
N	TMS1	TCK1	TRST1N	VDD2													SOFS0	SOCK0	VDD1	VSS	N
P	VDD2	NC	VDD1	SOD1													VDD2	SOD0	SID0	SCK0	P
R	VSS	TDO1	SID1	SOCK1													IO0BIT4	IO0BIT6	NC	VDD2	R
T	VSS	SCK1	VDD1	IO1BIT0													VDD1	IO0BIT2	IO0BIT5	VSS	T
U	SOFS1	SIFS1	IO1BIT1	NC	IO1BIT4	PADD1	VDD2	VDD1	VDD1	VDD2	PD2	VDD1	VDD2	PD9	PD13	EYMODE	NC	NC	IO0BIT1	IO0BIT3	U
V	SICK1	IO1BIT2	VSS	NC	IO1BIT6	PADD3	PCSN	PODS	PRDY	POBE	VDD1	VDD1	PD7	VDD1	PD10	VDD1	VSS	VSS	NC	NC	V
W	VDD2	VSS	VDD1	IO1BIT5	PADD2	NC	PRWN	PRDYMD	PINT	PIBF	PD0	PD4	PD6	NC	PD8	PD11	PD14	IO0BIT0	VSS	VDD2	W
Y	VSS	VDD2	IO1BIT3	PADD0	VSS	VDD2	PIDS	VSS	VSS	VDD2	PD1	PD3	PD5	VDD2	VSS	VSS	PD12	PD15	VDD2	VSS	Y

Figure 61. 256-Ball EBGA Package Ball Grid Array Assignments (See-Through Top View)

7 Ball Grid Array Information (continued)

7.2 256-Ball EPGA Package (continued)

Table 174 describes the EPGA ball assignments sorted by symbol for the 256-ball package. For each signal or power/ground connection, this table lists the EPGA coordinate, the symbol name, the type (I = input, O = output, I/O = input/output, O/Z = 3-state output, P = power, G = ground), and description. Inputs and bidirectional pins do not maintain full CMOS levels when not driven. They must be pulled to V_{DD2} or V_{SS} through the appropriate pull up/down resistor (refer to Section 10.1 on page 269). An unused external SEMI data bus (ED[31:0]) can be statically configured as outputs by asserting the EYMODE pin. At full CMOS levels, no significant dc current is drawn.

Table 174. 256-Ball EPGA Ball Assignments Sorted Alphabetically by Symbol

Symbol	PBGA Coordinate	Type	Description
CKI	J19	I	External Clock Input.
EA[18:0]	B3, C1, C2, C4, D1, D2, D5, E2, E3, E4, F3, F4, G2, G3, H2, H3, H4, J3, J4	O	External Address Bus, Bits 18—0.
EACKN	C6	O	External Device Acknowledge for External Memory Interface (negative assertion).
ECKO	M1	O	Programmable Clock Output.
ED[31:0]	A8, A9, A10, A14, A17, A18, B6, B8, B9, B10, B11, B12, B13, B14, B16, B17, C8, C11, C12, C13, C14, C15, C16, C19, C20, D7, D10, D15, D16, D18, D19, E17	I/O	External Memory Data Bus, Bits 31—0.
EION	A3	O	Enable for External I/O (negative assertion).
ERAMN	B4	O	External RAM Enable (negative assertion).
ERDY	F17	I	External Memory Device Ready.
EREQN	D20	I	External Device Request for EMI Interface (negative assertion).
EROMN	D6	O	Enable for External ROM (negative assertion).
ERTYPE	G17	I	EROM Type Control: If 0, asynchronous SRAM mode. If 1, synchronous SRAM mode.
ERWN0	B5	O	Read/Write, Bit 0 (negative assertion).
ERWN1	A4	O	Read/Write, Bit 1 (negative assertion).
ESEG[3:0]	K2, L1, L2, L4	O	External Segment Address, Bits 3—0.
ESIZE	E19	I	External Memory Bus Size Control: If 0, 16-bit external interface. If 1, 32-bit external interface.
EXM	F18	I	External Boot-up Control for CORE0.
EYMODE	U16	I	External Data Bus Mode Configuration Pin.
INT[3:0]	K18, L18, L19, M18	I	External Interrupt Requests 3—0.
IO0BIT[6:0]	R17, R18, T18, T19, U19, U20, W18	I/O	BIO0 Status/Control, Bits 6—0.
IO1BIT[6:0]	T4, U3, U5, V2, V5, W4, Y3	I/O	BIO1 Status/Control, Bits 6—0.
PADD[3:0]	U6, V6, W5, Y4	I	PIU Address, Bits 3—0.
PCSN	V7	I	PIU Chip Select (negative assertion).
PD[15:0]	U11, U14, U15, V13, V15, W11, W12, W13, W15, W16, W17, Y11, Y12, Y13, Y17, Y18	I/O	PIU Data Bus, Bits 15—0.
PIBF	W10	O	PIU Input Buffer Full Flag.
PIDS	Y7	I	PIU Input Data Strobe.
PINT	W9	O	PIU Interrupt Request to Host.
POBE	V10	O	PIU Output Buffer Empty Flag.
PODS	V8	I	PIU Output Data Strobe.

7 Ball Grid Array Information (continued)

7.2 256-Ball EBGA Package (continued)

Table 174. 256-Ball EBGA Ball Assignments Sorted Alphabetically by Symbol (continued)

Symbol	PBGA Coordinate	Type	Description
PRDY	V9	O	PIU Host Ready.
PRDYMD	W8	I	PRDY Mode.
PRWN	W7	I	PIU Read/Write (negative assertion).
RSTN	K17	I	Device Reset (negative assertion).
SCK0	P20	I	External Clock for SIU0 Active Generator.
SCK1	T2	I	External Clock for SIU1 Active Generator.
SICK0	M17	I/O	SIU0 Input Clock.
SICK1	V1	I/O	SIU1 Input Clock.
SID0	P19	I	SIU0 Input Data.
SID1	R3	I	SIU1 Input Data.
SIFS0	M19	I/O	SIU0 Input Frame Sync.
SIFS1	U2	I/O	SIU1 Input Frame Sync.
SOCK0	N18	I/O	SIU0 Output Clock.
SOCK1	R4	I/O	SIU1 Output Clock.
SOD0	P18	O/Z	SIU0 Output Data.
SOD1	P4	O/Z	SIU1 Output Data.
SOFS0	N17	I/O	SIU0 Output Frame Sync.
SOFS1	U1	I/O	SIU1 Output Frame Sync.
TCK0	H19	I	JTAG Test Clock for CORE0.
TCK1	N2	I	JTAG Test Clock for CORE1.
TDI0	J17	I	JTAG Test Data Input for CORE0.
TDI1	M2	I	JTAG Test Data Input for CORE1.
TDO0	F19	O	JTAG Test Data Output for CORE0.
TDO1	R2	O	JTAG Test Data Output for CORE1.
TMS0	H20	I	JTAG Test Mode Select for CORE0.
TMS1	N1	I	JTAG Test Mode Select for CORE1.
TRAP	K20	I/O	TRAP/Breakpoint Indication.
TRST0N	H18	I	JTAG TAP Controller Reset for CORE0 (negative assertion).
TRST1N	N3	I	JTAG TAP Controller Reset for CORE1 (negative assertion).
VDD1	B18, C5, C7, C9, C10, D3, D9, D12, D13, E18, G1, G18, J2, K19, L3, M3, M4, N19, P3, T3, T17, U8, U9, U12, V11, V12, V14, V16, W3	P	Power Supply for Internal Circuitry.
VDD1A	J18	P	Power Supply for PLL Circuitry.
VDD2	A2, A7, A11, A15, A19, B1, B20, D8, D11, D14, F1, G4, G20, H17, K1, K4, L17, L20, N4, P1, P17, R20, U7, U10, U13, W1, W20, Y2, Y6, Y10, Y14, Y19	P	Power Supply for External Circuitry (I/O).
VSS	A1, A5, A6, A12, A13, A16, A20, B2, B19, C3, C18, E1, E20, F20, H1, J1, M20, N20, R1, T1, T20, V3, V17, V18, W2, W19, Y1, Y5, Y8, Y9, Y15, Y16, Y20	G	Ground.
VSS1A	J20	G	Ground for PLL Circuitry.
NC	B7, B15, C17, D4, D17, F2, G19, K3, P2, R19, U4, U17, U18, V4, V19, V20, W6, W14	—	Not Connected. Tie externally to ground.

8 Signal Descriptions

Figure 62 shows the interface pinout for the DSP16410B. The signals can be separated into nine interfaces as shown. Following is a description of these interfaces and the signals that comprise them.

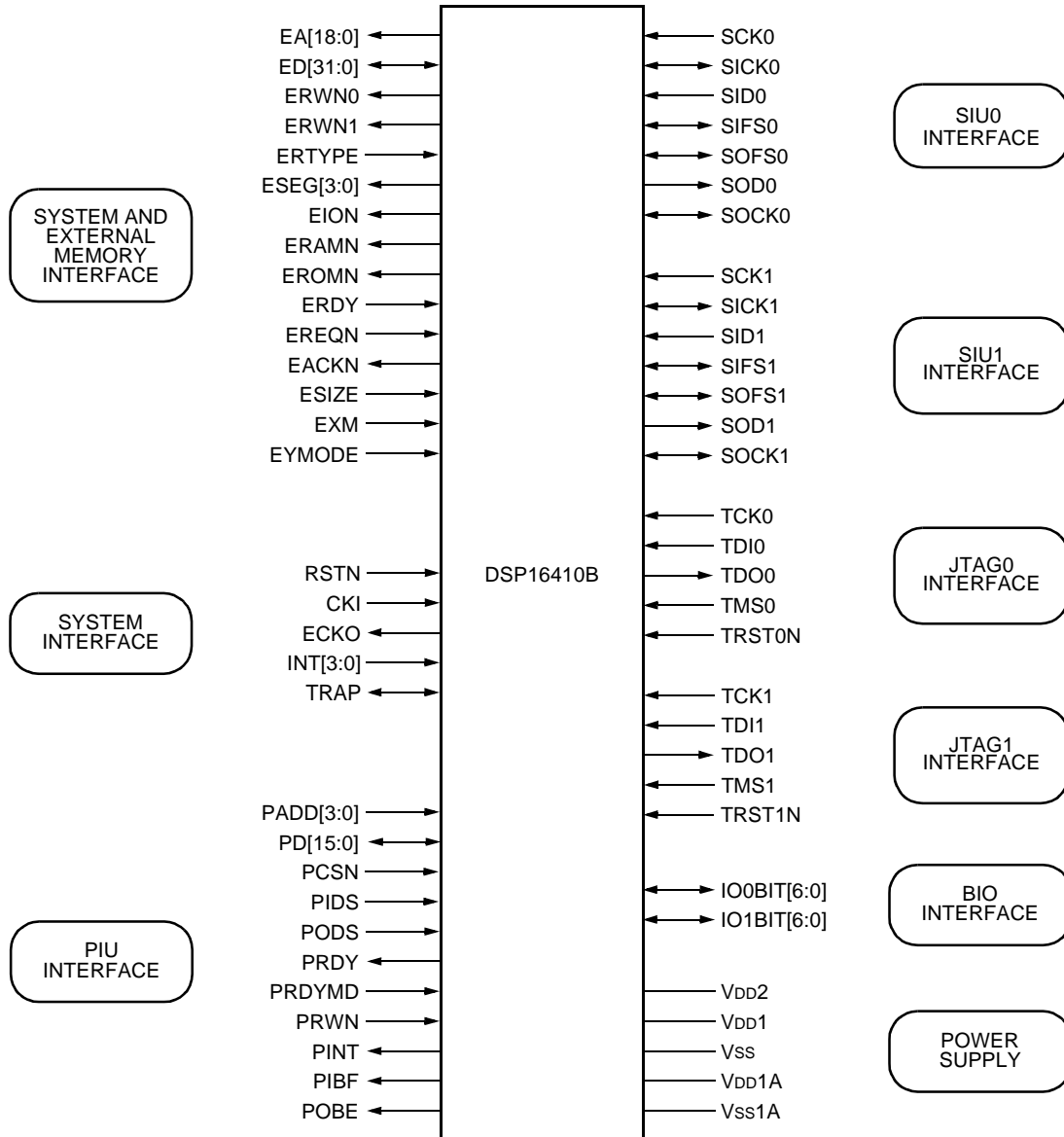


Figure 62. DSP16410B Pinout by Interface

8 Signal Descriptions (continued)

8.1 System Interface

The system interface consists of the clock, interrupt, and reset signals for the processor.

RSTN—Device Reset: Negative assertion input. A high-to-low transition causes the processor to enter the reset state. See [Section 4.3 on page 23](#) for details.

CKI—Input Clock: The CKI input buffer drives the internal clock (CLK) directly or drives the on-chip PLL (see [Section 4.17 on page 197](#)). The PLL allows the CKI input clock to be at a lower frequency than the internal clock.

ECKO—Programmable Clock Output: Buffered output clock with options programmable via the **ECON1** register (see [Table 60 on page 110](#)). The selectable ECKO options are as follows:

- CLK/2: A free-running output clock at half the frequency of the internal clock. This setting is required for a synchronous memory interface on SEMI. (This is the default selection after reset.)
- CLK: A free-running output clock at the frequency of the internal clock.
- CKI: Clock input pin.
- ZERO: A constant logic 0 output.

INT[3:0]—External Interrupt Requests: Positive assertion inputs. Hardware interrupts to the DSP16410B are edge-sensitive, enabled via the **inc0** register (see [Table 149 on page 238](#)). If enabled and asserted properly with no equal- or higher-priority interrupts being serviced, each hardware interrupt causes the core to vector to the memory location described in [Table 9 on page 33](#). If an INT[3:0] pin is asserted for at least the minimum required assertion time (see [Section 11.7 on page 283](#)), the corresponding external interrupt request is recorded in the **ins** register (see [Table 150 on page 239](#)). If both INT0 and RSTN are asserted, all output and bidirectional pins are put in a 3-state condition except TDO, which 3-states by JTAG control.

TRAP—TRAP/Breakpoint Indication: Positive pulse assertion input/output. If asserted, the processor is put into the trap condition, which normally causes a branch to the location **vbase + 4**. Although normally an input, this pin can be configured as an output by the HDS block. As an output, the pin can be used to signal an HDS breakpoint in a multiple processor environment.

8.2 BIO Interface

IO0BIT[6:0]—BIO Signals: Input/Output. Each of these pins can be independently configured via software as either an input or an output by CORE0. As outputs, they can be independently set, toggled, or cleared. As inputs, they can be tested independently or in combinations for various data patterns.

IO1BIT[6:0]—BIO Signals: Input/Output. Each of these pins can be independently configured via software as either an input or an output by CORE1. As outputs, they can be independently set, toggled, or cleared. As inputs, they can be tested independently or in combinations for various data patterns.

8.3 System and External Memory Interface

ED[31:0]—Bidirectional 32-bit External Data Bus: Input/output. The external data bus operates as a 16-bit or 32-bit data bus, as determined by the state of the ESIZE pin:

- If defined as a 16-bit bus (ESIZE = 0), the SEMI uses ED[31:16] and 3-states ED[15:0]. If the cores or the DMAU attempt to initiate a 32-bit transfer to or from external memory, the SEMI performs two 16-bit transfers.
- If defined as a 32-bit bus (ESIZE = 1), the SEMI uses ED[31:0]. If the cores or the DMAU attempt to initiate a 16-bit transfer, the SEMI drives ED[31:16] for accesses to an even address or ED[15:0] for accesses to an odd address.

If the SEMI is not performing an external access, it 3-states ED[31:0]. If the EYMODE pin is tied high, ED[31:0] are statically configured as outputs (see description of EYMODE below).

EYMODE—External Data Bus Mode: Input. This pin determines the mode of the external data bus. It must be static and tied to Vss (if the SEMI is used) or VDD2 (if the SEMI is not used). If EYMODE = 0, the external data bus pins ED[31:0] are statically configured as outputs (regardless of the state of RSTN) and must not be connected externally. If EYMODE = 1, external pull-up resistors are not needed on ED[31:0]. See [Section 10.1 on page 269](#) for details.

8 Signal Descriptions (continued)

8.3 System and External Memory Interface (continued)

EA[18:1]—External Address Bus Bits 18—1:

Output. The function of this bus depends on the state of the ESIZE pin:

- If the external data bus is configured as a 16-bit bus (ESIZE = 0), the SEMI places the 18 most significant bits of the 19-bit external address onto EA[18:1].
- If the external data bus is configured as a 32-bit bus (ESIZE = 1), the SEMI places the 18-bit external address onto EA[18:1].

After an access is complete and before the start of a new access, the SEMI continues to drive EA[18:1] with its current state. The SEMI 3-states EA[18:1] if it grants a request by an external device to access the external memory (see description of the EREQN pin).

EA0—External Address Bus Bit 0: Output. The function of this bit depends on the state of the ESIZE pin:

- If the external data bus is configured as a 16-bit bus (ESIZE = 0), the SEMI places the least significant bit of the 19-bit external address onto EA0.
- If the external data bus is configured as a 32-bit bus (ESIZE = 1), the SEMI does not use EA0 as an address bit:
 - If the selected memory component is configured as asynchronous¹, the SEMI drives EA0 with its previous value.
 - If the selected memory component is configured as synchronous¹, the SEMI drives a negative-assertion write strobe onto EA0 (the SEMI drives EA0 with the logical AND of ERWN1 and ERWN0).

After an access is complete and before the start of a new access, the SEMI continues to drive EA0 with its current state. The SEMI 3-states EA0 if it grants a request by an external device to access the external memory (see description of the EREQN pin).

ESEG[3:0]—External Segment Address:

Output. The external segment address outputs provide an additional 4 bits of address or decoded enables for extending the external address range of the DSP16410B. The state of ESEG[3:0] is determined by the **EXSEG0**, **EYSEG0**, **EXSEG1**, and **EYSEG1** registers for a CORE0 or CORE1 external memory access.

Refer to [Section 4.14.1.4 on page 105](#) for more details. If the DMAU accesses external memory, the SEMI places the contents of the ESEG[3:0] field of the **SADD<0—5>** or **DADD<0—5>** register onto the ESEG[3:0] pins (see [Table 37 on page 76](#) for details). If the PIU accesses external memory, the SEMI places the contents of the ESEG[3:0] field of the **PA** register onto the ESEG[3:0] pins (see [Table 78 on page 135](#) for details). ESEG[3:0] retain their previous state while the SEMI is not performing external accesses. The SEMI 3-states ESEG[3:0] if it grants a request by an external device to access the external memory (see description of the EREQN pin).

ERWN[1:0]—External Read/Write Not: Output. The external read/write strobes are two separate write strobes. In general, if driven high by the SEMI, these signals indicate an external read access. If driven low, these signals indicate an external write access. However, the exact function of these pins is qualified by the value of the ESIZE pin:

- If ESIZE = 0 (16-bit data bus), ERWN1 is always inactive (high) and ERWN0 is an active write strobe.
- If ESIZE = 1 (32-bit data bus), ERWN0 is the write enable for the upper (most significant) 16 bits of the data (ED[31:16]) and ERWN1 is the write enable for the lower (least significant) 16 bits of the data (ED[15:0]).

The SEMI 3-states ERWN[1:0] if it grants a request by an external device to access the external memory (see description of the EREQN pin).

ERAMN—ERAM Space Enable: Negative-assertion output. The external RAM enable selects the ERAM memory component (external data memory). For asynchronous accesses, the SEMI asserts ERAMN for the number of cycles specified by the YATIME[3:0] field (**ECON0**[7:4]—see [Table 59 on page 109](#)). For synchronous accesses, the SEMI asserts ERAMN for two instruction cycles (one ECKO cycle²). ERAM is configured as synchronous if the YTYPE field is set (**ECON1**[9]—see [Table 60 on page 110](#)) is set. The SEMI 3-states ERAMN if it grants a request by an external device to access the external memory (see description of the EREQN pin).

1. The EROM component is synchronous if the ERTYPE pin is logic 1. The ERAM component is synchronous if YTYPE field (**ECON1**[9]) is set. The EIO component is synchronous if the ITYPE field (**ECON1**[10]) is set. **ECON1** is described in [Table 60 on page 110](#).
2. If any memory component is configured as synchronous, ECKO must be programmed as CLK/2, i.e., the ECKO[1:0] field (**ECON1**[1:0]—[Table 60 on page 110](#)) must be programmed to 0x0.

8 Signal Descriptions (continued)

8.3 System and External Memory Interface (continued)

EROMN—EROM Space Enable: Negative-assertion output. The external ROM enable selects the EROM memory component (external program memory). For asynchronous accesses, the SEMI asserts EROMN for the number of cycles specified by the XATIME[3:0] field (**ECON0**[3:0]—see [Table 59 on page 109](#)). For synchronous accesses, the SEMI asserts EROMN for two instruction cycles (one ECKO cycle²). EROM is configured as synchronous if the ERTYPE pin is high. The SEMI 3-states EROMN if it grants a request by an external device to access the external memory (see description of the EREQN pin).

EION—EIO Space Enable: Negative-assertion output. The external I/O enable selects the EIO memory component (external memory-mapped peripherals or data memory). For asynchronous accesses, the SEMI asserts EION for the number of cycles specified by the IATIME[3:0] field (**ECON0**[11:8]—see [Table 59 on page 109](#)). For synchronous accesses, the SEMI asserts EION for two instruction cycles (one ECKO cycle¹). EION is configured as synchronous if the ITYPE field is set (**ECON1**[10]—see [Table 60 on page 110](#)) is set. The SEMI 3-states EION if it grants a request by an external device to access the external memory (see description of the EREQN pin).

ERDY—External Device Ready for SEMI Data: Positive-assertion input. The external READY input is a control pin that allows an external device to extend an external asynchronous memory access. If driven low by the external device, the SEMI extends the current external memory access that is already in progress. To guarantee proper operation, ERDY must be driven low at least 4 CLK cycles before the end of the access and the enable must be programmed for at least 5 CLK cycles of assertion (via the YATIME, XATIME, or IATIME field of **ECON0**—see [Table 59 on page 109](#)). The SEMI ignores the state of ERDY prior to 4 CLK cycles before the end of the access. The access is extended by 4 CLK cycles after ERDY is driven high. The state of ERDY is readable in the EREADY field (**ECON1**[6]—see [Table 60 on page 110](#)).

Note: If ERDY is not in use by the application or if all external memory is synchronous, ERDY must be tied high.

EREQN—External Device Requests Access to SEMI Bus: Negative-assertion input. An external device asserts EREQN low to request the external memory bus for access to external asynchronous memory. If the NOSHARE field (**ECON1**[8]—see [Table 60 on page 110](#)) is set, the DSP16410B ignores the request. If NOSHARE is cleared, a minimum of four cycles later the SEMI grants the request by performing the following:

- First, the SEMI completes any external access that is already in progress.
- The SEMI 3-states the address bus and segment address (EA[18:0] and ESEG[3:0]), the data bus (ED[31:0]), and all the external enables and strobes (ERAMN, EROMN, EION, and ERWN[1:0]) until the external device deasserts EREQN. The SEMI continues to drive ECKO.
- The SEMI acknowledges the request by asserting EACKN.

The cores and the DMAU continue processing. If a core or the DMAU attempts to perform an external memory access, it stalls until the external device relinquishes the bus. If the external device deasserts EREQN (changes EREQN from 0 to 1), four cycles later the SEMI deasserts EACKN (changes EACKN from 0 to 1). To avoid external bus contention, the external device must wait for at least $ATIME_{MAX}$ cycles² after the it deasserts EREQN (changes EREQN from 0 to 1) before reasserting EREQN (changing EREQN from 1 to 0). The software can read the state of the EREQN pin in the EREQN field (**ECON1**[4]—see [Table 60 on page 110](#)).

Note: If EREQN is not in use by the application, it must be tied high.

1. If any memory component is configured as synchronous, ECKO must be programmed as CLK/2, i.e., the ECKO[1:0] field (**ECON1**[1:0]—[Table 60 on page 110](#)) must be programmed to 0x0.

2. $ATIME_{MAX}$ is the greatest of IATIME(**ECON0**[11:8]), YATIME (**ECON0**[7:4]), and XATIME (**ECON0**[3:0]).

8 Signal Descriptions (continued)

8.3 System and External Memory Interface (continued)

EACKN—DSP16410B Acknowledges External Bus Request: Negative-assertion output. The SEMI acknowledges the request of an external device for direct access to an asynchronous external memory by asserting EACKN. See the description of the EREQN pin above for details. The software can read the state of the EACKN pin in the EACKN field (**ECON1**[5]—see [Table 60 on page 110](#)).

ESIZE—Size of External SEMI Bus: Input. The external data bus size input determines the size of the active data bus. If **ESIZE** = 0, the external data bus is configured as 16 bits and the SEMI uses **ED**[31:16] and 3-states **ED**[15:0]. If **ESIZE** = 1, the external data bus is configured as 32 bits and the SEMI uses **ED**[31:0].

ERTYPE—EROM Type: Input. The external ROM type input determines the type of memory device in the EROM component (selected by the EROMN enable). If **ERTYPE** = 0, the EROM component is populated with ROM or asynchronous SRAM, and the SEMI performs asynchronous accesses to the EROM component. If **ERTYPE** = 1, the EROM component is populated with synchronous *ZBT* SRAM and the SEMI performs synchronous accesses to the EROM component.

EXM—Boot Source: Input. The external execution memory input determines the active memory for program execution after DSP16410B reset. If **EXM** = 0 when the **RSTN** pin makes a low-to-high transition, both cores begin execution from their internal ROM (IROM) memory at location 0x20000. If **EXM** = 1 when the **RSTN** pin makes a low-to-high transition, both cores begin execution from external ROM (EROM) memory at location 0x80000. If the cores begin execution from external ROM, the SEMI arbitrates the accesses from the two cores.

8.4 SIU0 Interface

SID0—External Serial Input Data: Input. By default, data is latched on the **SID0** pin on a falling edge of the input bit clock (**SICK0**) during a selected channel.

SOD0—External Serial Output Data: Output. By default, data is driven onto the **SOD0** pin on a rising edge of the output bit clock (**SOCK0**) during a selected and unmasked channel. During inactive or masked channel periods, **SOD0** is 3-state.

SICK0—Input Bit Clock: Input/output. **SICK0** can be an input (passive input clock) or an output (active input clock). The **SICK0** pin is the input data bit clock. By default, data on **SID0** is latched on a falling edge of this clock, but the active level of this clock can be changed by the **ICKK** field (**SCON10**[3]—[Table 111 on page 188](#)). **SICK0** can be configured via software as an input (passive, externally generated) or an output (active, internally generated) via the **ICKA** field (**SCON10**[2]) and the **ICKE** field (**SCON3**[6]—[Table 104 on page 185](#)).

SOCK0—Output Bit Clock: Input/output. **SOCK0** can be an input (passive output clock) or an output (active output clock). The **SOCK0** pin is the output data bit clock. By default, data on **SOD0** is driven on a rising edge of **SOCK0** during active channel periods, but the active level of this clock can be changed by the **OCKK** field (**SCON10**[7]). **SOCK0** can be configured via software as an input (passive, externally generated) or an output (active, internally generated) via the **OCKA** of **SCON10**[6] and the **OCKE** field (**SCON3**[14]).

SIFS0—Input Frame Synchronization: Input/output. The **SIFS0** signal indicates the beginning of a new input frame. By default, **SIFS0** is active-high, and a low-to-high transition (rising edge) indicates the start of a new frame. The active level and position of the input frame sync relative to the first input data bit can be changed via the **IFSK** field (**SCON10**[1]) and the **IFSDLY**[1:0] field (**SCON1**[9:8]—[Table 102 on page 183](#)), respectively. **SIFS0** can be configured via software as an input (passive, externally generated) or an output (active, internally generated) via the **IFSA** field (**SCON10**[0]) and the **IFSE** field (**SCON3**[7]).

SOFS0—Output Frame Synchronization: Input/output. The **SOFS0** signal indicates the beginning of a new output frame. By default, **SOFS0** is active-high, and a low-to-high transition (rising edge) indicates the start of a new frame. The active level and position of the output frame sync relative to the first output data bit can be changed via the **OFSK** field (**SCON10**[5]) and the **OFSDLY**[1:0] field (**SCON2**[9:8]—[Table 103 on page 184](#)), respectively. **SOFS0** can be configured via software as an input (passive, externally generated) or an output (active, internally generated) via the **OFSA** field (**SCON10**[4]) and the **OFSE** field (**SCON3**[15]).

8 Signal Descriptions (continued)

8.4 SIU0 Interface (continued)

SCK0—External Clock Source: Input. The SCK0 pin is an input that provides an external clock source for generating the input and output bit clocks and frame syncs. If enabled via the AGEXT field (**SCON12**[12]—[Table 113 on page 192](#)), the clock source applied to SCK0 replaces the internal clock (CLK) for active mode timing generation of the bit clocks and frame syncs. The active level of the clock applied to this pin can be inverted by setting the SCKK field (**SCON12**[13]).

8.5 SIU1 Interface

SID1—External Serial Input Data: Input. By default, data is latched on the SID1 pin on a falling edge of the input bit clock, SICK1, during a selected channel.

SOD1—External Serial Output Data: Output. By default, data is driven onto the SOD1 pin on a rising edge of the output bit clock, SOCK1, during a selected and unmasked channel. During inactive or masked channel periods, SOD1 is 3-state.

SICK1—Input Bit Clock: Input/output. SICK1 can be an input (passive input clock) or an output (active input clock). The SICK1 pin is the input data bit clock. By default, data on SID1 is latched on a falling edge of this clock, but the active level of this clock can be changed by the ICKK field (**SCON10**[3]—[Table 111 on page 188](#)). SICK1 can be configured via software as an input (passive, externally generated) or an output (active, internally generated) via the ICKA field (**SCON10**[2]) and the ICKE field (**SCON3**[6]—[Table 104 on page 185](#)).

SOCK1—Output Bit Clock: Input/output. SOCK1 can be an input (passive output clock) or an output (active output clock). The SOCK1 pin is the output data bit clock. By default, data on SOD1 is driven on a rising edge of SOCK1 during active channel periods, but the active level of this clock can be changed by the OCKK field (**SCON10**[7]). SOCK1 can be configured via software as an input (passive, externally generated) or an output (active, internally generated) via the OCKA field (**SCON10**[6]) and the OCKE field (**SCON3**[14]).

SIFS1—Input Frame Synchronization: Input/output. The SIFS1 signal indicates the beginning of a new input frame. By default, SIFS1 is active-high, and a low-to-high transition (rising edge) indicates the start of a new frame. The active level and position of the input frame sync relative to the first input data bit can be changed via the IFSK field (**SCON10**[1]) and the IFS-DLY[1:0] field (**SCON1**[9:8]), respectively. SIFS1 can be configured via software as an input (passive, externally generated) or an output (active, internally generated) via the IFSA field (**SCON10**[0]) and the IFSE (**SCON3**[7]).

SOFS1—Output Frame Synchronization: Input/output. The SOFS1 signal indicates the beginning of a new output frame. By default, SOFS1 is active-high, and a low-to-high transition (rising edge) indicates the start of a new frame. The active level and position of the output frame sync relative to the first output data bit can be changed via the OFSK field (**SCON10**[5]) and the OFSDLY[1:0] field (**SCON2**[9:8]—[Table 103 on page 184](#)), respectively. SOFS1 can be configured via software as an input (passive, externally generated) or an output (active, internally generated) via the OFSA field (**SCON10**[4]) and the OFSE field (**SCON3**[15]).

SCK1—External Clock Source: Input. The SCK1 pin is an input that provides an external clock source for generating the input and output bit clocks and frame syncs. If enabled via the AGEXT field of **SCON12**[12]—[Table 113 on page 192](#)), the clock source applied to SCK1 replaces the internal clock (CLK) for active mode timing generation of the bit clocks and frame syncs. The active level of the clock applied to this pin can be inverted by setting the SCKK field (**SCON12**[13]).

8 Signal Descriptions (continued)

8.6 PIU Interface

The host interface to the PIU consists of 29 pins.

PD[15:0]—16-Bit Bidirectional, Parallel Data Bus:

Input/output. During host data reads, the DSP16410B drives the data contained in the PIU output data register (**PDO**) onto this bus. During host data writes, data driven by the host onto this bus is latched into the PIU input data register (**PDI**). If the PIU is not selected by the host (**PCSN** is high), PD[15:0] is 3-state.

PADD[3:0]—PIU 4-Bit Address and Control:

Input. The 4-bit address input that is driven by the host to select between various PIU registers and to issue PIU commands. Refer to [Section 4.15.5 on page 144](#) for details. If unused, these input pins should be tied low.

POBE—PIU Output Buffer Empty Flag: Output. This status pin directly reflects the state of the PIU output data register (**PDO**). If POBE = 0, the **PDO** register contains data ready for the host to read. If POBE = 1, the **PDO** register is empty and there is no data for the host to read. The host can read the state of this pin anytime **PCSN** is asserted low. The state of this pin is also reflected in the POBE field of the **PCON** register.

PIBF—PIU Input Buffer Full Flag: Output. This status pin directly reflects the state of the PIU input data register (**PDI**). If PIBF = 0, **PDI** is empty and the host can safely write another word to the PIU. If PIBF = 1, **PDI** is full with the previous word that was written by the host. If the host issues another write to the PIU while PIBF = 1, the previous data in **PDI** is overwritten. The host can read this pin anytime **PCSN** is asserted low. The state of this pin is also reflected in the PIBF field (**PCON**[1]—[Table 73 on page 133](#)).

PRDY—PIU Host Ready: Output. This status pin directly reflects the state of the previous PIU host transaction. It is used by the host to extend the current access until the previous access is complete. The active state of this pin is determined by the state of the PRDYMD pin. The state of PRDY is valid only if the PIU is activated, i.e., if **PSTRN** is asserted. (See [Section 4.15.2.1 on page 137](#) for a definition of **PSTRN**.)

- If PRDYMD = 0, PRDY is active-low. If PRDY = 0, the previous host read or host write is complete, and the host can continue with the current read or write transaction. If PRDY = 1, the previous PIU read or write is still in progress (**PDI** is still full or **PDO** is still empty) and the host must extend the current access until PRDY = 0.

- If PRDYMD = 1, PRDY is active-high. If PRDY = 1, the previous host read or host write is complete, and the host can continue with the current read or write transaction. If PRDY = 0, the previous PIU read or write is still in progress (**PDI** is still full or **PDO** is still empty) and the host must extend the current access until PRDY = 1.

PINT—PIU Interrupt: Output. Can be set by the DSP16410B to generate a host interrupt. If a core sets the PINT field (**PCON**[3]—[Table 73 on page 133](#)), the PIU drives the PINT pin high to create a host interrupt. After the host acknowledges the interrupt, it must clear the PINT field (**PCON**[3]).

PRDYMD—PIU Ready Pin Mode: Input. Determines the active state of the PRDY pin. Refer to the PRDY pin description above. If unused, PRDYMD should be tied low.

PODS—PIU Output Data Strobe: Input. Function is dependent upon the host type (*Intel* or *Motorola*). If unused, PODS must be tied high:

- *Intel* mode: In this mode, PODS functions as an output data strobe and must be connected to the host active-low read data strobe. The host read transaction is initiated by the assertion (low) of **PCSN** and PODS. It is terminated by the deassertion (high) of **PCSN** or PODS.
- *Motorola* mode: In this mode, PODS functions as a data strobe and must be connected to the host data strobe. The active level of PODS (active-high or active-low) is determined by the state of the PIDS pin. A host read or write transaction is initiated by the assertion of **PCSN** and PODS. It is terminated by the deassertion of **PCSN** or PODS.

PIDS—PIU Input Data Strobe: Input. Function is dependent upon the host type (*Intel* or *Motorola*). If unused, PIDS must be tied high:

- *Intel* mode: In this mode, PIDS functions as an input data strobe and must be connected to the host active-low write data strobe. The host write transaction is initiated by the assertion (low) of **PCSN** and PIDS. It is terminated by the deassertion (high) of **PCSN** or PIDS.
- *Motorola* mode: In this mode, the state of PIDS determines the active level of the host data strobe, PODS. If PIDS = 0, PODS is an active-high data strobe. If PIDS = 1, PODS is an active-low data strobe.

8 Signal Descriptions (continued)

8.6 PIU Interface (continued)

PRWN—PIU Read/Write Not: Input. Function is dependent upon the host type (*Intel* or *Motorola*). In either case, PRWN is driven high by the host during host reads and driven low by the host during host writes. PRWN must be stable for the entire access (while PCSN and the appropriate data strobe are asserted). If unused, PRWN must be tied high.

- *Intel* mode: In this mode, PRWN is connected to the active-low write data strobe of the host processor, the same as the PIDS input.
- *Motorola* mode: In this mode, PRWN functions as an active read/write strobe and must be connected to the RWN output of the *Motorola* host processor.

PCSN—PIU Chip Select: Negative-assertion input. PCSN is the chip select from the host for shared-bus systems. If PCSN = 0, the PIU of the selected DSP16410B is active for transfers with the host. If PCSN = 1, the PIU ignores any activity on PIDS, PODS, and PRWN and 3-states PD[15:0]. If unused, PCSN must be tied high.

8.7 JTAG0 Test Interface

The JTAG0 test interface has features that allow programs and data to be downloaded into CORE0 via five pins. This provides extensive test and diagnostic capability. In addition, internal circuitry allows the device to be controlled through the JTAG port to provide on-chip, in-circuit emulation. Agere Systems provides hardware and software tools to interface to the on-chip HDS via the JTAG port.

Note: JTAG0 provides all JTAG/*IEEE* 1149.1 standard test capabilities including boundary scan.

TDI0—JTAG Test Data Input: Serial input signal. All serial-scanned data and instructions are input on this pin. This pin has an internal pull-up resistor.

TDO0—JTAG Test Data Output: Serial output signal. Serial-scanned data and status bits are output on this pin.

TMS0—JTAG Test Mode Select: Mode control signal that, combined with TCK0, controls the scan operations. This pin has an internal pull-up resistor.

TCK0—JTAG Test Clock: Serial shift clock. This signal clocks all data into the port through TDI0 and out of the port through TDO0. It also controls the port by latching the TMS0 signal inside the state-machine controller.

TRST0N—JTAG TAP Controller Reset: Negative assertion. Test reset. If asserted low, resets the JTAG0 TAP controller. In an application environment, this pin must be asserted prior to or concurrent with RSTN. This pin has an internal pull-up resistor.

8.8 JTAG1 Test Interface

The JTAG1 test interface has features that allow programs and data to be downloaded into CORE1 via five pins. This provides extensive test and diagnostic capability. In addition, internal circuitry allows the device to be controlled through the JTAG port to provide on-chip, in-circuit emulation. Agere Systems provides hardware and software tools to interface to the on-chip HDS via the JTAG port.

Note: JTAG1 provides all JTAG/*IEEE* 1149.1 standard test capabilities including boundary scan.

TDI1—JTAG Test Data Input: Serial input signal. All serial-scanned data and instructions are input on this pin. This pin has an internal pull-up resistor.

TDO1—JTAG Test Data Output: Serial output signal. Serial-scanned data and status bits are output on this pin.

TMS1—JTAG Test Mode Select: Mode control signal that, combined with TCK1, controls the scan operations. This pin has an internal pull-up resistor.

TCK1—JTAG Test Clock: Serial shift clock. This signal clocks all data into the port through TDI1 and out of the port through TDO1. It also controls the port by latching the TMS1 signal inside the state-machine controller.

TRST1N—JTAG TAP Controller Reset: Negative assertion. Test reset. If asserted low, TRST1N resets the JTAG1 TAP controller. In an application environment, this pin must be asserted prior to or concurrent with RSTN. This pin has an internal pull-up resistor.

8 Signal Descriptions (continued)

8.9 Power and Ground

VDD1—Core Supply Voltage: Supply voltage for the DSP16000 cores and all internal DSP16410B circuitry. Required voltage level is 1.8 V nominal.

VDD2—I/O Supply Voltage: Supply voltage for the I/O pins. Required voltage level is 3.3 V nominal.

VSS—Ground: Ground for core and I/O supplies.

VDD1A—Analog Supply Voltage: Supply voltage for the PLL circuitry. Required voltage level is 1.8 V nominal.

VSS1A—Analog Ground: Ground for analog supply.

9 Device Characteristics

9.1 Absolute Maximum Ratings

Stresses in excess of the absolute maximum ratings can cause permanent damage to the device. These are absolute stress ratings only. Functional operation of the device is not implied at these or any other conditions in excess of those given in the operational sections of the data sheet. Exposure to absolute maximum ratings for extended periods can adversely affect device reliability.

External leads can be bonded and soldered safely at temperatures of up to 220 °C.

Table 175. Absolute Maximum Ratings for Supply Pins

Parameter	Min	Max	Unit
Voltage on VDD1 with Respect to Ground	-0.5	2.0	V
Voltage on VDD1A with Respect to Ground	-0.5	2.0	V
Voltage on VDD2 with Respect to Ground	-0.5	4.0	V
Voltage Range on Any Signal Pin	V _{SS} - 0.3	V _{DD2} + 0.3	V
		4.0	
Junction Temperature (T _J)	-40	125	°C
Storage Temperature Range	-40	150	°C

9.2 Handling Precautions

All MOS devices must be handled with certain precautions to avoid damage due to the accumulation of static charge. Although input protection circuitry has been incorporated into the devices to minimize the effect of this static buildup, proper precautions should be taken to avoid exposure to electrostatic discharge during handling and mounting. Agere Systems employs a human-body model for ESD-susceptibility testing. Since the failure voltage of electronic devices is dependent on the current, voltage, and hence, the resistance and capacitance, it is important that standard values be employed to establish a reference by which to compare test data. Values of 100 pF and 1500 Ω are the most common and are the values used in the Agere Systems human-body model test circuit. The breakdown voltage for the DSP16410B is greater than 1000 V.

9.3 Recommended Operating Conditions

Table 176. Recommended Operating Conditions

Maximum Internal Clock (CLK) Frequency	Minimum Internal Clock (CLK) Period T	Junction Temperature T _J (°C)		Supply Voltage VDD1, VDD1A (V)		Supply Voltage VDD2 (V)	
		Min	Max	Min	Max	Min	Max
185 MHz	5.4 ns	-40	120	1.71	1.95	3.0	3.6

The ratio of the instruction cycle rate to the input clock frequency is 1:1 without the PLL and ((M + 2)/((D + 2) * f(OD))):1 with the PLL selected. **The maximum input clock (CKI pin) frequency when the PLL is not selected as the device clock source is 50 MHz. The maximum input clock frequency is 40 MHz when the PLL is selected.**

9 Device Characteristics (continued)

9.3 Recommended Operating Conditions (continued)

9.3.1 Package Thermal Considerations

The maximum allowable ambient temperature, T_{AMAX} , is dependent upon the device power dissipation and is determined by the following equation:

$$T_{AMAX} = T_{JMAX} - P_{MAX} \times \Theta_{JA}$$

Where P_{MAX} is the maximum device power dissipation for the application, T_{JMAX} is the maximum device junction temperature specified in [Table 177](#), and Θ_{JA} is the maximum thermal resistance in still-air-ambient specified in [Table 177](#). See [Section 10.3](#) for information on determining the maximum device power dissipation.

Table 177. Package Thermal Considerations

Device Package	Parameter	Value	Unit
208 PBGA	Maximum Junction Temperature (T_{JMAX})	120	°C
208 PBGA	Maximum Thermal Resistance in Still-Air-Ambient (Θ_{JA})	27	°C/W
256 EBGA	Maximum Junction Temperature (T_{JMAX})	120	°C
256 EBGA	Maximum Thermal Resistance in Still-Air-Ambient (Θ_{JA})	15	°C/W

WARNING: Due to package thermal constraints, proper precautions in the user’s application should be taken to avoid exceeding the maximum junction temperature of 120 °C. Otherwise, the device performance and reliability is adversely affected.

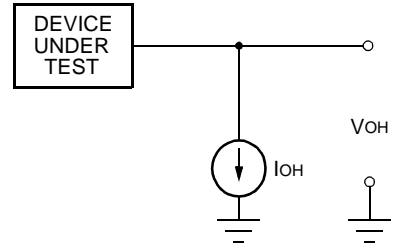
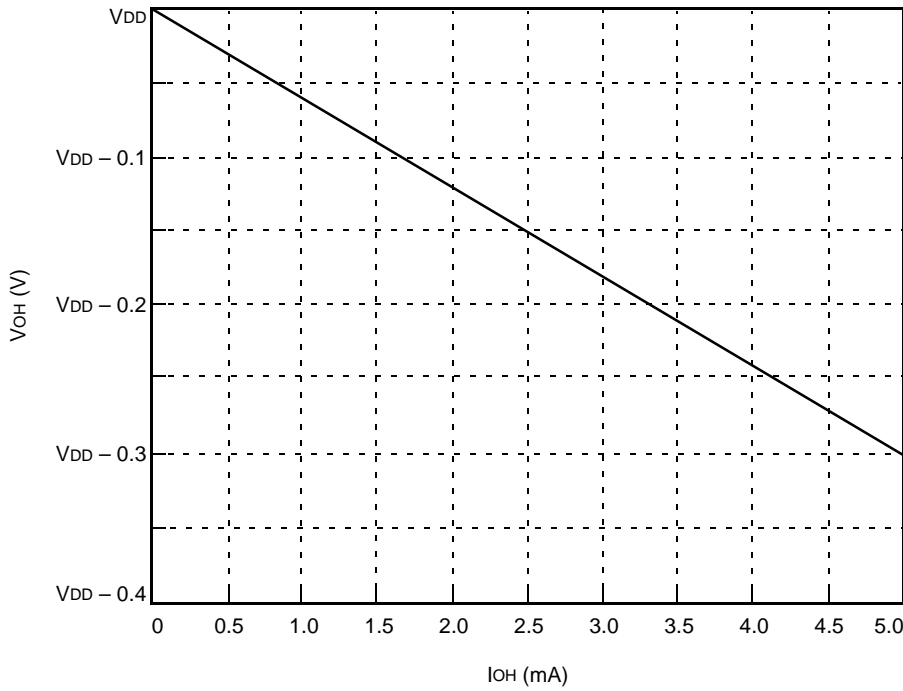
10 Electrical Characteristics and Requirements

Electrical characteristics refer to the behavior of the device under specified conditions. Electrical requirements refer to conditions imposed on the user for proper operation of the device. The parameters below are valid for the conditions described in the previous section, [Section 9.3 on page 265](#).

Table 178. Electrical Characteristics and Requirements

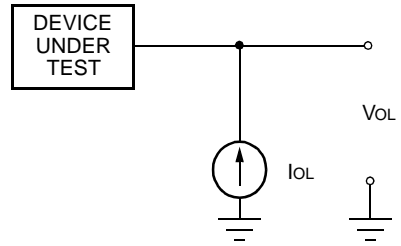
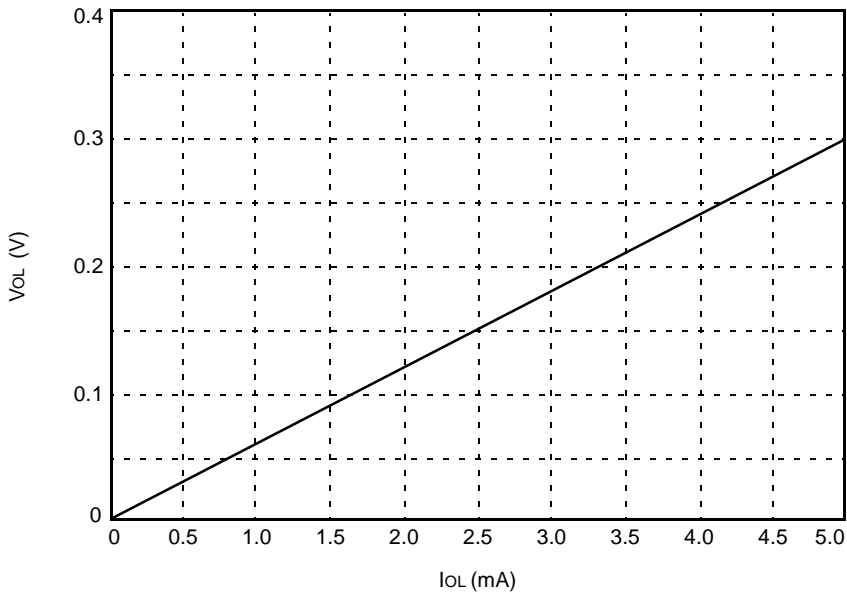
Parameter	Symbol	Min	Max	Unit
Input Voltage: Low High	V_{IL} V_{IH}	-0.3 $0.7 \times V_{DD2}$	$0.3 \times V_{DD2}$ $V_{DD2} + 0.3$	V V
Input Current (except TMS0, TMS1, TDI0, TDI1, TRST0N, TRST1N): Low ($V_{IL} = 0$ V, $V_{DD2} = 3.6$ V) High ($V_{IH} = 3.6$ V, $V_{DD2} = 3.6$ V)	I_{IL} I_{IH}	-5 —	— 5	μ A μ A
Input Current (TMS0, TMS1, TDI0, TDI1, TRST0N, TRST1N): Low ($V_{IL} = 0$ V, $V_{DD2} = 3.6$ V) High ($V_{IH} = 3.6$ V, $V_{DD2} = 3.6$ V)	I_{IL} I_{IH}	-100 —	— 5	μ A μ A
Output Low Voltage: Low ($I_{OL} = 2.0$ mA) Low ($I_{OL} = 50$ μ A)	V_{OL} V_{OL}	— —	0.4 0.2	V V
Output High Voltage: High ($I_{OH} = -2.0$ mA) High ($I_{OH} = -50$ μ A)	V_{OH} V_{OH}	$V_{DD2} - 0.7$ $V_{DD2} - 0.2$	— —	V V
Output 3-State Current: Low ($V_{DD2} = 3.6$ V, $V_{IL} = 0$ V) High ($V_{DD2} = 3.6$ V, $V_{IH} = 3.6$ V)	I_{OZL} I_{OZH}	-10 —	— 10	μ A μ A
Input Capacitance	C_I	—	5	pF

10 Electrical Characteristics and Requirements (continued)



5-4007(C).a

Figure 63. Plot of V_{OH} vs. I_{OH} Under Typical Operating Conditions



5-4008(C).b

Figure 64. Plot of V_{OL} vs. I_{OL} Under Typical Operating Conditions

10 Electrical Characteristics and Requirements (continued)

10.1 Maintenance of Valid Logic Levels for Bidirectional Signals and Unused Inputs

The DSP16410B does not include any internal circuitry to maintain valid logic levels on input pins or on bidirectional pins that are not driven. For correct device operation and low static power dissipation, valid CMOS levels must be applied to all input and bidirectional pins. Failure to ensure full CMOS levels (V_{IL} or V_{IH}) on pins that are not driven (including floating data buses) may result in high static power consumption and possible device failure.

Any unused input pin must be pulled up to the I/O pin supply (V_{DD2}) or pulled down to V_{SS} according to the functional requirements of the pin. The pin can be pulled up or down directly or through a 10 k Ω resistor.

Any unused bidirectional pin, statically configured as an input, should be pulled to V_{DD2} or V_{SS} through a 10 k Ω resistor. Any bidirectional pin that is dynamically configured, such as the SEMI or PIU data buses, should be tied to V_{DD2} or V_{SS} through a pull-up/down resistor that supports the performance of the circuit. The value of the resistor should be selected to avoid exceeding the dc voltage and current characteristics of any device attached to the pin.

If the SEMI interface is unused in the system, the EYMODE pin should be connected to V_{DD2} to force the internal data bus transceivers to always be in the output mode. This avoids the need to add 32 pull-up resistors to ED[31:0]. If the SEMI interface is used in the system, the EYMODE pin must be connected to V_{SS} and pull-up or pull-down resistors must be added to ED[31:0] as described below.

The value of the pull-up resistors used on the SEMI data bus depends on the programmed bus width, 32-bit or 16-bit, as determined by the ESIZE pin. It is recommended that any 16-bit peripheral that is connected to the external memory interface of the DSP16410B use the upper 16 bits of the data bus (ED[31:16]). This is required if the external memory interface is configured as a 16-bit interface. For the following configurations, 10 k Ω pull-up or pull-down resistors can be used on the external data bus:

- 32-bit SEMI with no 16-bit peripherals
- 32-bit SEMI with 16-bit peripherals connected to ED[31:16]
- 16-bit interface (ED[31:16] only)

If the DSP16410B's external memory interface is configured for 32-bit operation with 16-bit peripherals on the lower half of the external data bus (ED[15:0]), the external data bus (ED[31:0]) should have 2 k Ω pull-up or pull-down resistors to meet the rise or fall time requirements of the DSP16410B¹.

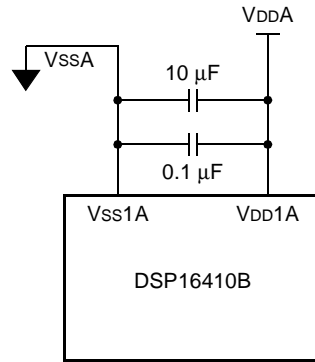
The different requirements for the size of the pull-up/pull-down resistors arise from the manner in which SEMI treats 16-bit accesses if the interface is configured for 32-bit operation. If configured as a 32-bit interface and a 16-bit read is performed to a device on the upper half of the data bus, the SEMI latches the value on the upper 16 bits internally onto the lower 16 bits. This ensures that the lower half of the data bus sees valid logic levels both in this case and also if the bus is operated as a 16-bit bus. However, if a 16-bit read operation is performed (on a 32-bit bus) to a 16-bit peripheral on the lower 16 bits, no data is latched onto the upper 16 bits, resulting in the upper half of the bus floating. In this case, the smaller pull-up resistors ensure the floating data bits transition to a valid logic level fast enough to avoid metastability problems when the inputs are latched by the SEMI.

1. The 2 k Ω resistor value assumes a bus loading of 30 pF and also ensures IOL is not violated.

10 Electrical Characteristics and Requirements (continued)

10.2 Analog Power Supply Decoupling

Bypass and decoupling capacitors (0.01 μF , 10 μF) should be placed between the analog supply pin (VDD1A) and analog ground (VSS1A). These capacitors should be placed as close to the VDD1A pin as possible. This minimizes ground bounce and supply noise to ensure reliable operation. Refer to Figure 65.



5-8896.b (F)

Figure 65. Analog Supply Bypass and Decoupling Capacitors

10 Electrical Characteristics and Requirements (continued)

10.3 Power Dissipation

The total device power dissipation is comprised of two components:

- The contribution from the VDD1 and VDD1A supplies, referred to as internal power dissipation.
- The contribution from the VDD2 supply, referred to as I/O power dissipation.

The next two sections specify power dissipation for each component.

10.3.1 Internal Power Dissipation

Internal power dissipation is highly dependent on operating voltage, core program activity, internal peripheral activity, and CLK frequency. Table 179 lists the DSP16410B typical internal power dissipation contribution for various conditions. The following conditions are assumed for all cases:

- VDD1 and VDD1A are both 1.8 V.
- All memory accesses by the cores and the DMAU are to internal memory.
- SIU0 and SIU1 are operating at 30 MHz in loopback mode. An external device drives the SICK<0—1> and SOCK<0—1> input pins at 30 MHz, and SIU<0—1> are programmed to select passive input clocks and internal loopback (the ICKA field (**SCON10**[2]—Table 111 on page 188) and OCKA field (**SCON10**[6]) are cleared and the SIOLB field (**SCON10**[8]) is set).
- The PLL is enabled and selected as the source of the internal clock, CLK. Table 179 specifies the internal power dissipation for the following values of CLK: 170 MHz and 185 MHz.

Table 179. Typical Internal Power Dissipation at 1.8 V

Condition			Internal Power Dissipation (W)	
Type	Core Operation	DMAU Activity	170 MHz	185 MHz
Low-power Standby	The AWAIT field (alf [15]) is set in both cores.	The DMAU is operating the MMT4 channel to continuously transfer data.	0.25	0.27
Typical	Both cores repetitively execute a 20-tap FIR filter†.		0.80	0.87
Worst-case‡	Both cores execute worst-case instructions with worst-case data patterns.	The DMAU is operating all six channels (SWT<0—3> and MMT<4—5>) to continuously transfer data.	1.44	1.56

† To optimize execution speed, the cores each execute the inner loop of the filter from cache and perform a double-word data access every cycle from separate modules of TPRAM.

‡ This is an artificial condition that is unlikely to occur for an extended period of time in an actual application because the cores are not performing any I/O servicing. In an actual application, the cores perform I/O servicing that changes program flow and lowers the power dissipation.

The internal power dissipation for the low-power standby and typical operating modes described in Table 179 is representative of actual applications. The worst-case internal power dissipation occurs under an artificial condition that is unlikely to occur for an extended period of time in an actual application. This worst-case power should be used for the calculation of maximum ambient operating temperature (T_{AMAX}) defined in Section 9.3.1. This value should also be used for worst-case system power supply design for VDD1 and VDD1A.

10 Electrical Characteristics and Requirements (continued)

10.3 Power Dissipation (continued)

10.3.2 I/O Power Dissipation

I/O power dissipation is highly dependent on operating voltage, I/O loading, and I/O signal frequency. It can be estimated as:

$$C_L \cdot V_{DD2}^2 \cdot f$$

where C_L is the load capacitance, V_{DD2} is the I/O supply voltage, and f is the frequency of output signal.

Table 180 lists the estimated typical I/O power dissipation contribution for each output and I/O pin for a typical application under specific conditions. The following conditions are assumed for all cases:

- V_{DD2} is 3.3 V.
- The load capacitance for each output and I/O pin is 30 pF.

For applications with values of C_L , V_{DD2} , or f that differ from those assumed for Table 180, the above formula can be used to adjust the I/O power dissipation values in the table.

Table 180. Typical I/O Power Dissipation at 3.3 V

Internal Peripheral	Pin(s)	Type	No. of Pins	Signal Frequency (MHz)	I/O Power Dissipation (mW)	
					170 MHz	185 MHz
SEMI†	ED[31:0]	I/O‡	32	CLK/4	222	242
	ERWN[1:0]	O	2	CLK/4	13.8	15
	EA0	O	1	CLK/8	6.9	7.6
	EA[18:1]	O	18	CLK/4	250	273
	ESEG[3:0]	O	4	CLK/4	56	60
	EROMN	O	1	CLK/12	4.6	5.1
	ERAMN	O	1	CLK/12	4.6	5.1
	EION	O	1	CLK/12	4.6	5.1
	ECKO	O	1	CLK/2	27.2	30.2
BIO<0—1>	IO<0—1>BIT[6:0]	O§	14	1	4.6	4.6
PIU	PD[15:0]	I/O‡	16	30	78.5	78.5
	PINT	O	1	1	0.33	0.33
	PIBF	O	1	30	9.8	9.8
	POBE	O	1	30	9.8	9.8
	PRDY	O	1	30	9.8	9.8
SIU<0—1>	SICK<0—1>	O	2	8	5.2	5.2
	SOCK<0—1>	O	2	8	5.2	5.2
	SOD<0—1>	O	2	8	5.2	5.2
	SIFS<0—1>	O	2	0.03	0.019	0.019
	SOFS<0—1>	O	2	0.03	0.019	0.019

† Assumptions: The SEMI is configured for a 32-bit external data bus (the ESIZE pin is high). The contribution from the EACKN pin is negligible.

‡ Assumption: the pins switch from input to output at a 50% duty cycle.

§ Assumption: the corresponding core has configured these pins as outputs.

10 Electrical Characteristics and Requirements (continued)

10.3 Power Dissipation (continued)

10.3.2 I/O Power Dissipation (continued)

Power dissipation due to the input buffers is highly dependent upon the input voltage level. At full CMOS levels, essentially no dc current is drawn. However, for levels between the power supply rails, especially at or near the threshold of $V_{DD2}/2$, high current can flow. See [Section 10.1](#) for more information.

WARNING: The device needs to be clocked for at least six CKI cycles during reset after powerup. Otherwise, high currents might flow.

10.4 Power Supply Sequencing Issues

The DSP16410B requires two supply voltages. The use of dual voltages reduces internal device power consumption while supporting standard 3.3 V external interfaces. The external (I/O) power supply voltage is V_{DD2} , the internal supply voltage is V_{DD1} , and the internal analog supply voltage is V_{DD1A} . V_{DD1} and V_{DD1A} are typically generated by the same power supply, with V_{DD1A} receiving enhanced filtering near the device. In the discussion that follows, V_{DD1} and V_{DD1A} are assumed to rise and fall together, and are collectively referred to as V_{DD1} throughout the remainder of this section.

Power supply design is a system issue. [Section 10.4.1](#) describes the recommended power supply sequencing specifications to avoid inducing latch-up or large currents that may reduce the long term life of the device. [Section 10.4.2](#) discusses external power sequence protection circuits that may be used to meet the recommendations discussed in [Section 10.4.1](#).

10.4.1 Supply Sequencing Recommendations

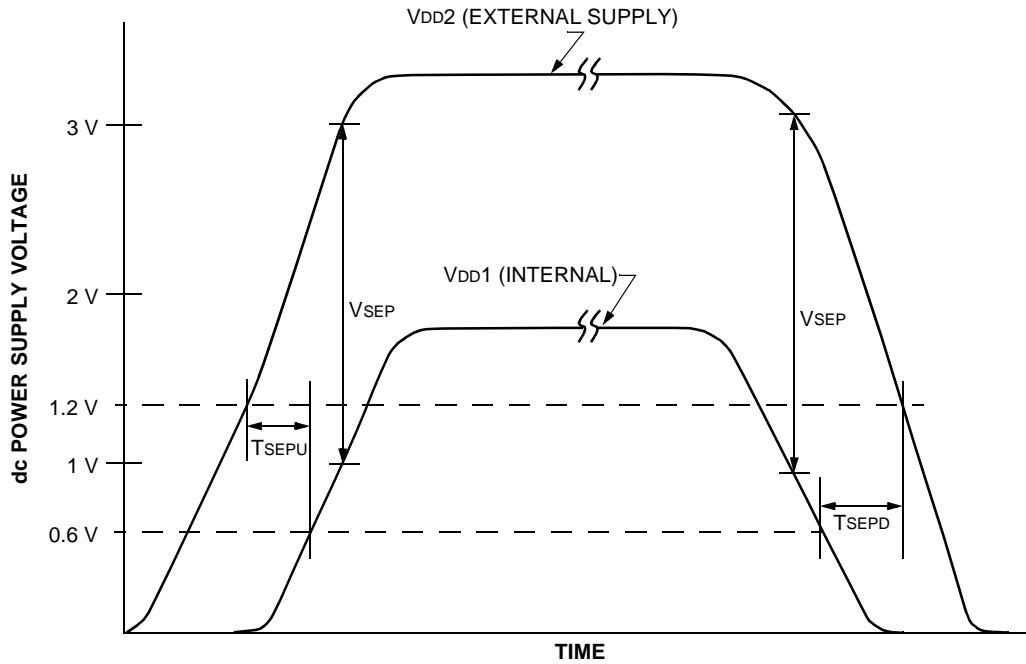
Control of powerup and powerdown sequences is recommended to address the following key issues. See [Figure 66](#) and [Table 181 on page 274](#) for definitions of the terms V_{SEP} , T_{SEPU} , and T_{SEPD} .

1. If the internal supply voltage (V_{DD1}) exceeds the external supply voltage (V_{DD2}) by a specified amount, large currents may flow through on-chip ESD structures that may reduce the long-term life of the device or induce latch-up. The difference between the internal and external supply voltages is defined as V_{SEP} . It is recommended that the value of V_{SEP} specified in [Table 181](#) be met during device powerup and device powerdown. External components may be required to ensure this specification is met (see [Section 10.4.2](#)).
2. During powerup, if the external supply voltage (V_{DD2}) exceeds a specified voltage (1.2 V) and the internal supply voltage (V_{DD1}) does not reach a specified voltage (0.6 V) within a specified time interval (T_{SEPU}), large currents may flow through the I/O buffer transistors. This is because the I/O buffer transistors are powered by V_{DD2} but their control transistors powered by V_{DD1} are not at valid logic levels. If the requirement for T_{SEPU} cannot be met, external components are recommended (see [Section 10.4.2](#)).
3. During powerdown, if the internal supply voltage (V_{DD1}) falls below a specified voltage (0.6 V) and the external supply voltage (V_{DD2}) does not fall below a specified voltage (1.2 V) within a specified time interval (T_{SEPD}), large currents may flow through the I/O buffer transistors. This is because the control transistors (powered by V_{DD1}) for the I/O buffer transistors are no longer at valid logic levels while the I/O buffer transistors remain powered by V_{DD2} . If the requirement for T_{SEPD} cannot be met, external components are recommended (see [Section 10.4.2](#)).

10 Electrical Characteristics and Requirements (continued)

10.4 Power Supply Sequencing Issues (continued)

10.4.1 Supply Sequencing Recommendations (continued)



0930 (F)

Figure 66. Power Supply Sequencing Recommendations

Table 181. Power Sequencing Recommendations

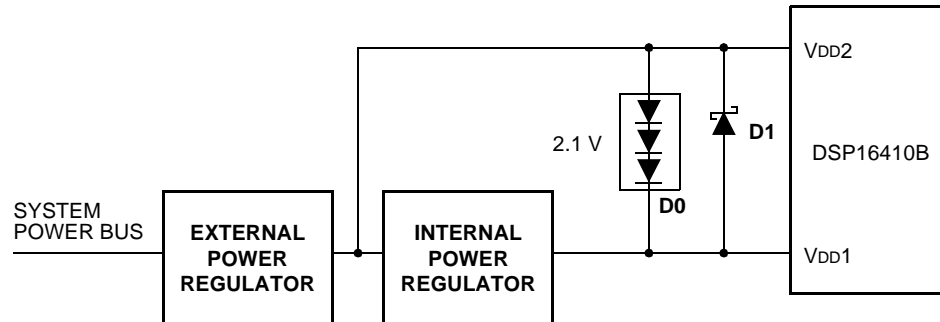
Parameter	Value	Description
VSEP	$-0.6\text{ V} < V_{SEP}$	$V_{SEP} = V_{DD2} - V_{DD1}$. VSEP constraint must be satisfied for the entire duration of power-on and power-off supply ramp.
TSEPU	$0 \leq T_{SEPU} < 50\text{ ms}$	Time after VDD2 reaches 1.2 V and before VDD1 reaches 0.6 V.
TSEPD	$0 \leq T_{SEPD} < 100\text{ ms}$	Time after VDD1 reaches 0.6 V and before VDD2 reaches 1.2 V.

10 Electrical Characteristics and Requirements (continued)

10.4 Power Supply Sequencing Issues (continued)

10.4.2 External Power Sequence Protection Circuits

This section discusses external power sequence protection circuits which may be used to meet the recommendations discussed in Section 10.4.1. For the purpose of this discussion, the dual supply configuration of Figure 67 will be used. The recommendations for this series supply system apply to parallel supply configurations where a common power bus simultaneously controls both the internal and external supplies.



1563(F)

Figure 67. Power Supply Example

Figure 67 illustrates a typical supply configuration. The external power regulator provides power to the internal power regulator.

Use of schottky diode D1 to bootstrap the VDD2 supply from the VDD1 supply is recommended. D1 ensures that the VSEP recommendation is met during device powerdown and powerup. In addition, D1 protects the DSP16410B from damage in the event of an external power regulator failure.

Diode network D0, which may be a series of diodes or a single zener diode, bootstraps the VDD1 supply. After VDD2 is a fixed voltage above VDD1 (2.1 V as determined by D0), the VDD2 supply will power VDD1 until D0 is cut off as VDD1 achieves its operating voltage. If TSEPU/TSEPD recommendations are met, D0 is not required. Since D0 protects the DSP16410B from damage in the event of an internal supply failure and reduces TSEPU, use of D0 is recommended. To ensure D0 cutoff during normal system operation, D0's forward voltage (VF) should be 2.1 V. D0 should be selected to ensure a minimum VDD1 of 0.8 V under DSP load.

11 Timing Characteristics and Requirements

Timing characteristics refer to the behavior of the device under specified conditions. Timing requirements refer to conditions imposed on the user for proper operation of the device. All timing data is valid for the following conditions:

$T_J = -40\text{ }^\circ\text{C}$ to $+120\text{ }^\circ\text{C}$ (See [Section 9.3 on page 265.](#))

$V_{DD2} = 3.3\text{ V} \pm 0.3\text{ V}$, $V_{SS} = 0\text{ V}$ (See [Section 9.3 on page 265.](#))

Capacitance load on outputs (C_L) = 30 pF

Output characteristics can be derated as a function of load capacitance (C_L).

All outputs: $0.025\text{ ns/pF} \leq dt/dC_L \leq 0.07\text{ ns/pF}$ for $10 \leq C_L \leq 100\text{ pF}$.

For example, if the actual load capacitance on an output pin is 20 pF instead of 30 pF, the maximum derating for a rising edge is $(20 - 30)\text{ pF} \times 0.07\text{ ns/pF} = 0.7\text{ ns}$ **less** than the specified rise time or delay that includes a rise time. The minimum derating for the same 20 pF load would be $(20 - 30)\text{ pF} \times 0.025\text{ ns/pF} = 0.25\text{ ns}$.

Test conditions for inputs:

- Rise and fall times of 4 ns or less.
- Timing reference levels for CKI, RSTN, TRST0N, TRST1N, TCK0, and TCK1 are V_{IH} and V_{IL} .
- Timing reference level for all other inputs is V_M (see [Table 182](#)).

Test conditions for outputs (unless noted otherwise):

- $C_{LOAD} = 30\text{ pF}$.
- Timing reference levels for ECKO are V_{OH} and V_{OL} .
- Timing reference level for all other outputs is V_M (see [Table 182](#)).
- 3-state delays measured to the high-impedance state of the output driver.

Unless otherwise noted, ECKO in the timing diagrams is the free-running CLK (**ECON1**[1:0] ([Table 60 on page 110](#)) = 1).



5-8215 (F)

Figure 68. Reference Voltage Level for Timing Characteristics and Requirements for Inputs and Outputs

Table 182. Reference Voltage Level for Timing Characteristics and Requirements for Inputs and Outputs

Abbreviated Reference	Parameter	Value	Unit
V_M	Reference Voltage Level for Timing Characteristics and Requirements for Inputs and Outputs	1.5	V

11 Timing Characteristics and Requirements (continued)

11.1 Phase-Lock Loop

Table 183. PLL Requirements

Parameter	Symbol	Min	Max	Unit
VCO Frequency Range [†] (V _{DD1A} = 1.8 V)	f _{vco}	200	500	MHz
Input Jitter at CKI	—	—	200	ps-rms
PLL Lock Time	t _L	—	0.5	ms
CKI Frequency with PLL Enabled [‡]	f _{CKI}	6	40	MHz
CKI Frequency with PLL Disabled [‡]	f _{CKI}	0	50	MHz
f _{CKI} /(D [§] + 2)	—	3	20	MHz

[†] The VCO output frequency (f_{vco}) is f_{CKI} × (M + 2)/(D + 2), where M and D are determined by fields in the **pllfrq** register (Table 123 on page 199).

[‡] The PLL is disabled (powered down) if the PLEN field (**pllcon**[1]) is cleared, which is the default after reset. The PLL is enabled (powered up) if the PLEN field (**pllcon**[1]) is set.

[§] D is the PLL input divider and is defined by **pllfrq**[13:9](Table 123 on page 199).

11 Timing Characteristics and Requirements (continued)

11.2 Wake-Up Latency

Table 184 specifies the wake-up latency for the low-power standby mode. The wake-up latency is the delay between exiting low-power standby mode and resumption of normal execution. See Section 4.20 on page 202 for an explanation of low-power standby mode and wake-up latency.

Table 184. Wake-Up Latency

Condition		Wake-Up Latency	
		(PLL Deselected [†] During Normal Execution)	(PLL Enabled [‡] and Selected [†] During Normal Execution)
Low-power Standby Mode (AWAIT (aif[15]) = 1)	PLL Disabled [‡] During Standby	3T [§]	3T [§] + t _L ^{††}
	PLL Enabled [‡] During Standby	3T [§]	3T [§]

[†] The PLL is deselected if the PLLSEL field (**pllcon**[0]) is cleared, which is the default after reset. The PLL is selected if the PLLSEL field (**pllcon**[0]) is set.

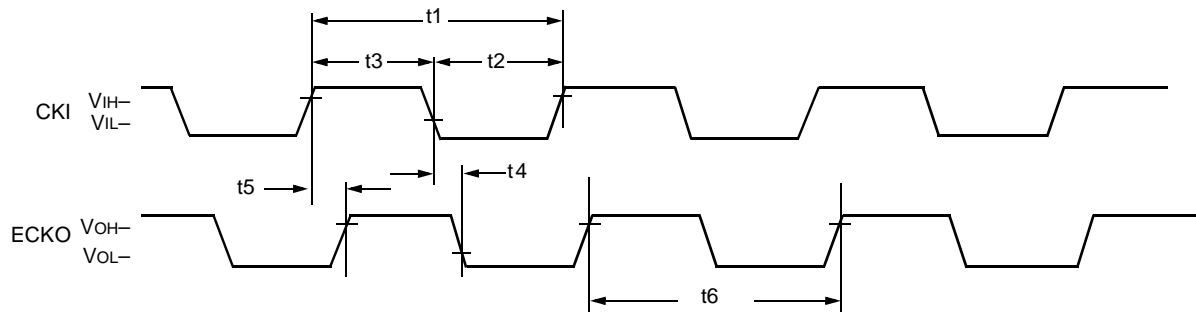
[‡] The PLL is disabled (powered down) if the PLEN field (**pllcon**[1]) is cleared, which is the default after reset. The PLL is enabled (powered up) if the PLEN field (**pllcon**[1]) is set.

[§] T = CLK clock cycle (f_{CLK} = f_{CKI} if PLL deselected; f_{CLK} = f_{CKI} x ((M + 2)/((D + 2) x f(OD))) if PLL enabled and selected).

^{††} t_L = PLL lock-in time (see Table 183 on page 277).

11 Timing Characteristics and Requirements (continued)

11.3 DSP Clock Generation



5-4009(F).i

Figure 69. I/O Clock Timing Diagram

Table 185. Timing Requirements for Input Clock

Abbreviated Reference	Parameter	Min	Max	Unit
t1†	Clock In Period (high to high)	20	—‡	ns
t2	Clock In Low Time (low to high)	10	—	ns
t3	Clock In High Time (high to low)	10	—	ns

† For the timing requirements shown, it is assumed that CKI (not the PLL output) is selected as the internal clock source. If the PLL is selected as the internal clock source, the minimum required CKI period is 25 ns and the maximum required CKI period is 167 ns.

‡ Device is fully static, t1 is tested at 100 ns input clock option, and memory hold time is tested at 0.1 s.

Table 186. Timing Characteristics for Output Clock

Abbreviated Reference	Parameter	Min	Max	Unit
t4	Clock Out High Delay (low to high)	—	10	ns
t5	Clock Out Low Delay (high to high)	—	10	ns
t6	Clock Out Period (high to high)	T†	—	ns

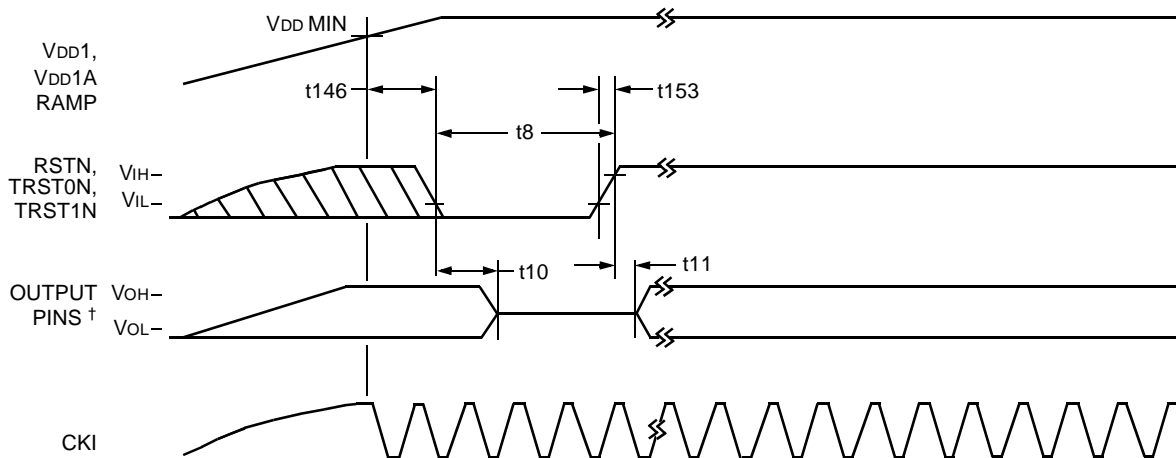
† T = internal clock period (CLK).

11 Timing Characteristics and Requirements (continued)

11.4 Reset Circuit

The DSP16410B has three external reset pins: RSTN, TRST0N, TRST1N. At initial powerup or if any supply voltage (VDD1, VDD1A, or VDD2) falls below VDD MIN¹, a device reset is required and RSTN, TRST0N, TRST1N must be asserted simultaneously to initialize the device.

Note: The TRST0N and TRST1N pins must be asserted even if the JTAG controller is not used by the application.



5-4010(F).r

† When both INT0 and RSTN are asserted, all output and bidirectional pins (except TDO, which 3-states by JTAG control) are put in a 3-state condition. With RSTN asserted and INT0 not asserted, EION, ERAMN, EROMN, EACKN, ERWN0, and ERWN1 outputs are driven high. EA[18:0], ESEG[3:0], and ECKO are driven low.

Figure 70. Powerup and Device Reset Timing Diagram

Table 187. Timing Requirements for Powerup and Device Reset

Abbreviated Reference	Parameter	Min	Max	Unit
t8	RSTN, TRST0N, and TRST1N Reset Pulse (low to high)	7T [†]	—	ns
t146	VDD1, VDD1A MIN to RSTN, TRST0N, and TRST1N Low	2T [†]	—	ns
t153	RSTN, TRST0N, and TRST1N Rise (low to high)	—	60	ns

† T = internal clock period (CKI).

Table 188. Timing Characteristics for Device Reset

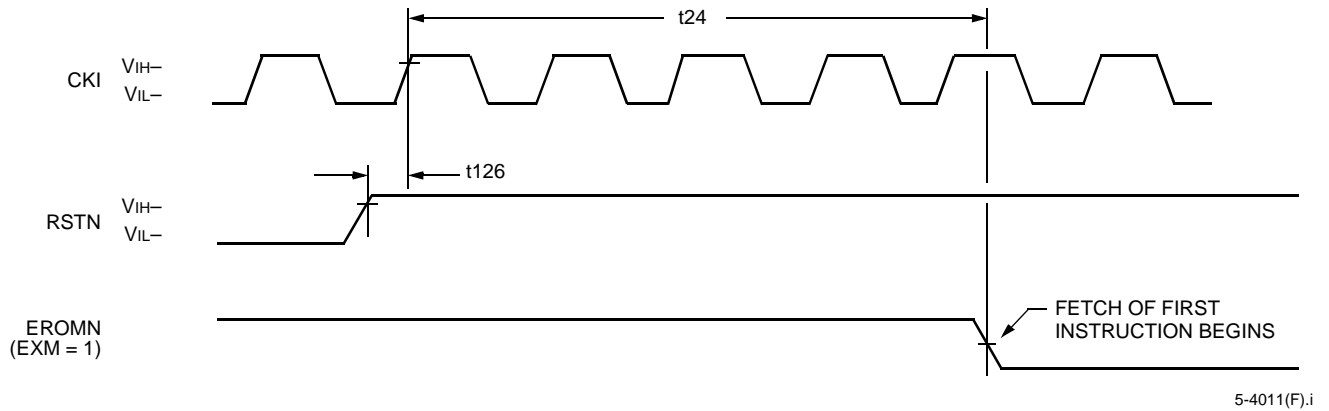
Abbreviated Reference	Parameter	Min	Max	Unit
t10	RSTN Disable Time (low to 3-state)	—	50	ns
t11	RSTN Enable Time (high to valid)	—	50	ns

Note: The device needs to be clocked for at least six CKI cycles during reset after powerup. Otherwise, high currents may flow.

1. See Table 176 on page 265.

11 Timing Characteristics and Requirements (continued)

11.5 Reset Synchronization



Note: See Section 11.9 for timing characteristics of the EROMN pin.

Figure 71. Reset Synchronization Timing

Table 189. Timing Requirements for Reset Synchronization Timing

Abbreviated Reference	Parameter	Min	Max	Unit
t126	Reset Setup (high to high)	3	$T/2 - 1^\dagger$	ns
t24	CKI to Enable Valid	$4T + 0.5$	$4T + 4$	ns

$\dagger T$ = internal clock period (CKI).

11 Timing Characteristics and Requirements (continued)

11.6 JTAG

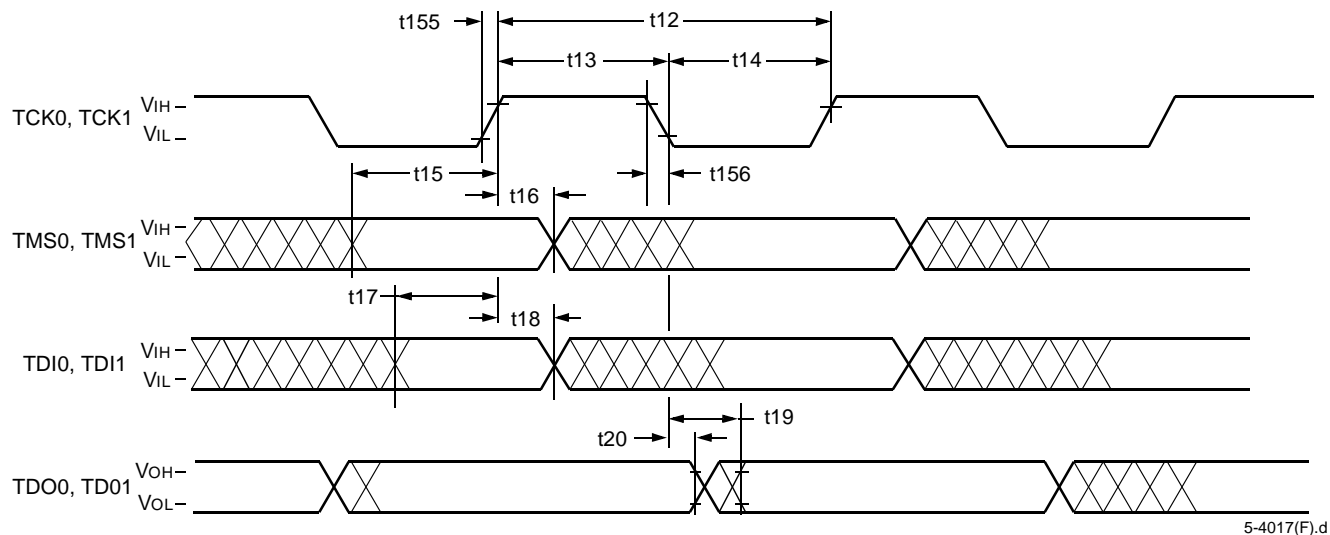


Figure 72. JTAG I/O Timing Diagram

Table 190. Timing Requirements for JTAG I/O

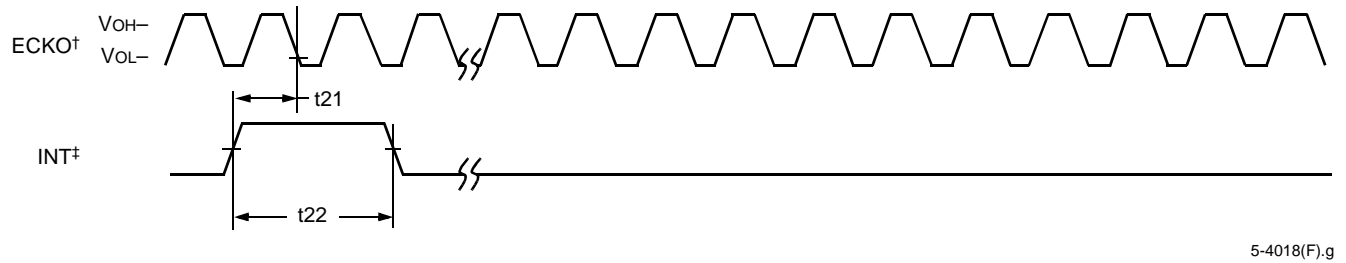
Abbreviated Reference	Parameter	Min	Max	Unit
t12	TCK Period (high to high)	50	—	ns
t13	TCK High Time (high to low)	22.5	—	ns
t14	TCK Low Time (low to high)	22.5	—	ns
t155	TCK Rise Transition Time (low to high)	0.6	—	V/ns
t156	TCK Fall Transition Time (high to low)	0.6	—	V/ns
t15	TMS Setup Time (valid to high)	7.5	—	ns
t16	TMS Hold Time (high to invalid)	5	—	ns
t17	TDI Setup Time (valid to high)	7.5	—	ns
t18	TDI Hold Time (high to invalid)	5	—	ns

Table 191. Timing Characteristics for JTAG I/O

Abbreviated Reference	Parameter	Min	Max	Unit
t19	TDO Delay (low to valid)	—	15	ns
t20	TDO Hold (low to invalid)	0	—	ns

11 Timing Characteristics and Requirements (continued)

11.7 Interrupt and Trap



† ECKO is free-running.

‡ INT is one of INT[3:0] or TRAP.

Figure 73. Interrupt and Trap Timing Diagram

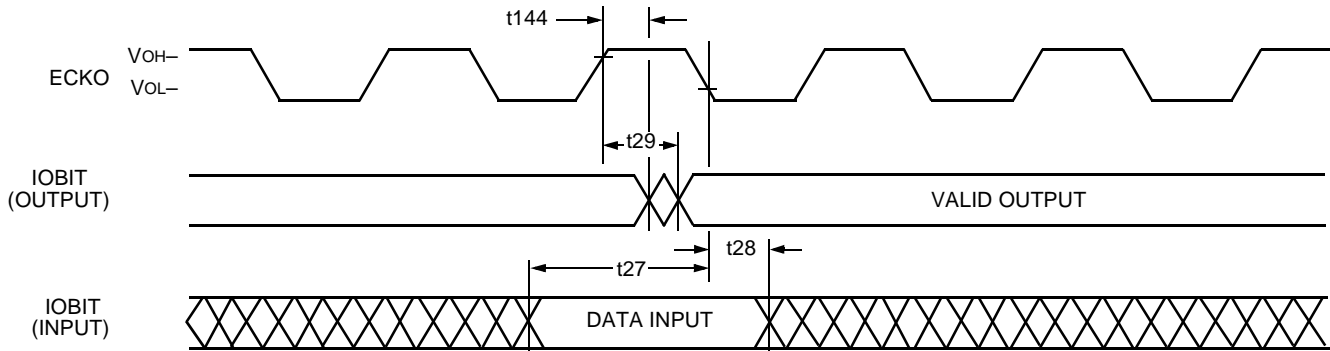
Table 192. Timing Requirements for Interrupt and Trap

Abbreviated Reference	Parameter	Min	Max	Unit
t21	Interrupt Setup (high to low)	8	—	ns
t22	INT/TRAP Assertion Time (high to low)	2T†	—	ns

† T = internal clock period (CLK).

11 Timing Characteristics and Requirements (continued)

11.8 Bit I/O



5-4019(F).c

Figure 74. Write Outputs Followed by Read Inputs (cbit = IMMEDIATE; a1 = sbit) Timing Characteristics

Table 193. Timing Requirements for BIO Input Read

Abbreviated Reference	Parameter	Min	Max	Unit
t27	IOBIT Input Setup Time (valid to low)	10	—	ns
t28	IOBIT Input Hold Time (low to invalid)	0	—	ns

Table 194. Timing Characteristics for BIO Output

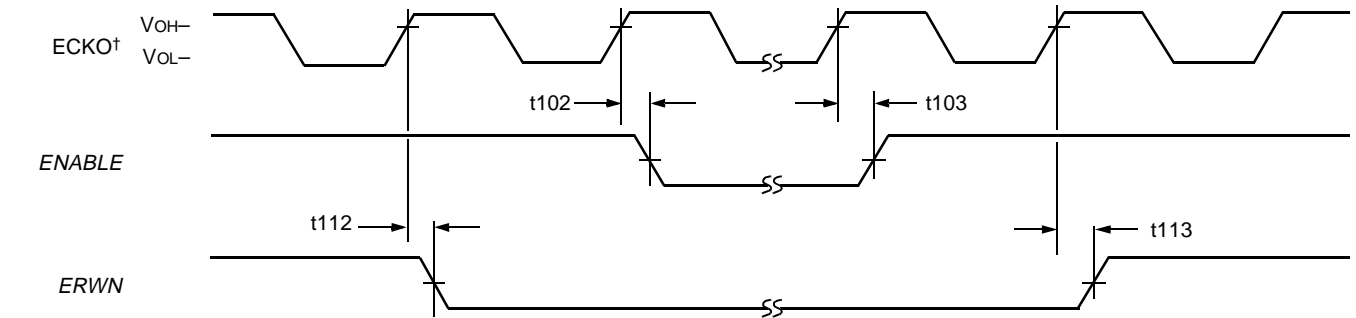
Abbreviated Reference	Parameter	Min	Max	Unit
t29	IOBIT Output Valid Time (high to valid)	—	9	ns
t144	IOBIT Output Hold Time (high to invalid)	1	—	ns

11 Timing Characteristics and Requirements (continued)

11.9 System and External Memory Interface

In the following timing diagrams and associated tables:

- The designation *ENABLE* refers to one of the following pins: EROMN, ERAMN, or EION. The designation *ENABLES* refers to all of the following pins: EROMN, ERAMN, and EION.
- The designation *ERWN* refers to:
 - The ERWN0 pin if the external data bus is configured as 16 bits, i.e., if the ESIZE pin is logic low.
 - The ERWN1 and ERWN0 pins if the external data bus is configured as 32 bits, i.e., if the ESIZE pin is logic high.
 - The ERWN1, ERWN0, and EA0 pins if the external data bus is configured as 32 bits, i.e., if the ESIZE pin is logic high, and if the memory access is synchronous.
- The designation *EA* refers to:
 - The external address pins EA[18:0] and the external segment address pins ESEG[3:0] if the external data bus is configured as 16 bits, i.e., if the ESIZE pin is logic low.
 - The external address pins EA[18:1] and the external segment address pins ESEG[3:0] if the external data bus is configured as 32 bits, i.e., if the ESIZE pin is logic high.
- The designation *ED* refers to:
 - The external data pins ED[31:16] if the external data bus is configured as 16 bits, i.e., if the ESIZE pin is logic low.
 - The external data pins ED[31:0] if the external data bus is configured as 32 bits, i.e., if the ESIZE pin is logic high.
- The designation *ATIME* refers to IATIME (**ECON0**[11:8]) for accesses to the EIO space, YATIME (**ECON0**[7:4]) for accesses to the ERAM space, or XATIME (**ECON0**[3:0]) for accesses to the EROM space.



† ECKO reflects CLK, i.e., **ECON1**[1:0] = 1.

Figure 75. Enable and Write Strobe Transition Timing

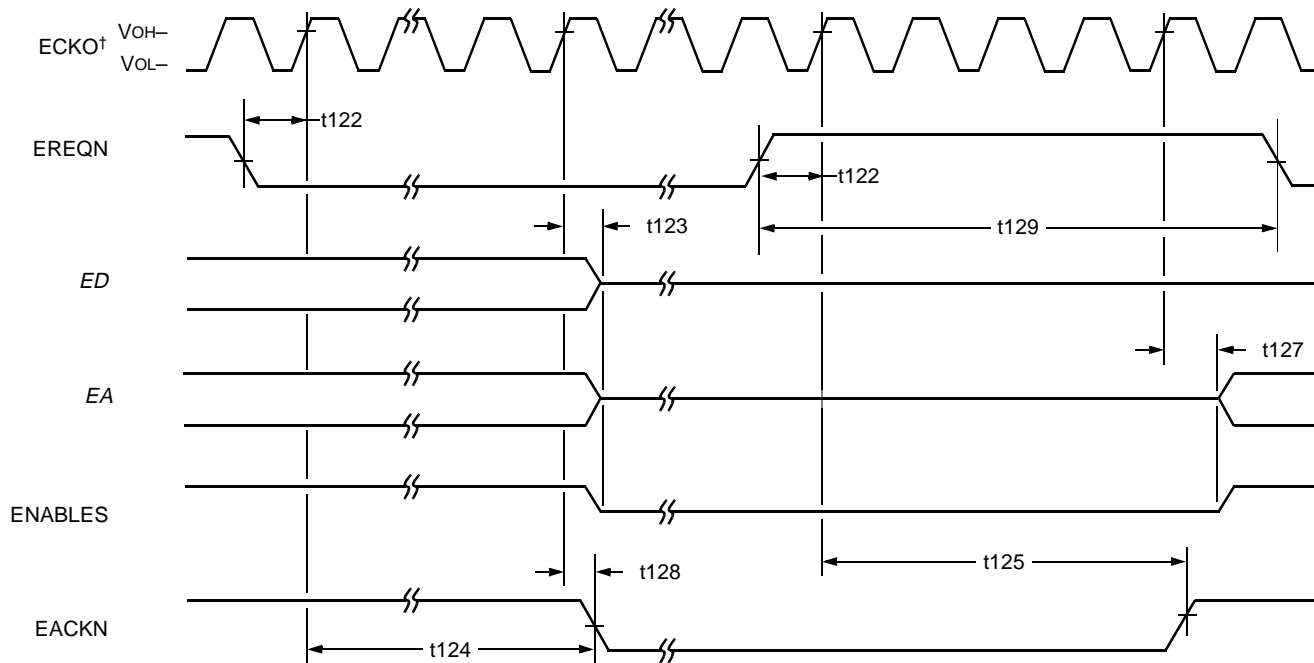
Table 195. Timing Characteristics for *ERWN* and Memory Enables

Abbreviated Reference	Parameter	Min	Max	Unit
t102	ECKO to <i>ENABLE</i> Active (high to low)	0.5	4	ns
t103	ECKO to <i>ENABLE</i> Inactive (high to high)	0.5	4	ns
t112	ECKO to <i>ERWN</i> Active (high to low)	0.5	4	ns
t113	ECKO to <i>ERWN</i> Inactive (high to high)	0.5	4	ns

11 Timing Characteristics and Requirements (continued)

11.9 System and External Memory Interface (continued)

11.9.1 Asynchronous Interface



† ECKO reflects CLK, i.e., $ECON1[1:0] = 1$.

Figure 76. Timing Diagram for EREQN and EACKN

Table 196. Timing Requirements for EREQN

Abbreviated Reference	Parameter	Min	Max	Unit
t122	EREQN Setup (low to high or high to high)	5	—	ns
t129	EREQN Deassertion (high to low)	$ATIME_{MAX}^\dagger$	—	ns

† $ATIME_{MAX}$ = the greatest of $IATIME(ECON0[11:8])$, $YATIME(ECON0[7:4])$, and $XATIME(ECON0[3:0])$.

Table 197. Timing Characteristics for EACKN and SEMI Bus Disable

Abbreviated Reference	Parameter	Min	Max	Unit
t123	Memory Bus Disable Delay (high to 3-state)	—	6	ns
t124	EACKN Assertion Delay† (high to low)	$4T^\ddagger$	—	ns
t125	EACKN Deassertion Delay (high to high)	$4T^\ddagger$	$4T^\ddagger + 3$	ns
t127	Memory Bus Enable Delay (high to active)	5	—	ns
t128	EACKN Delay (high to low)	—	3	ns

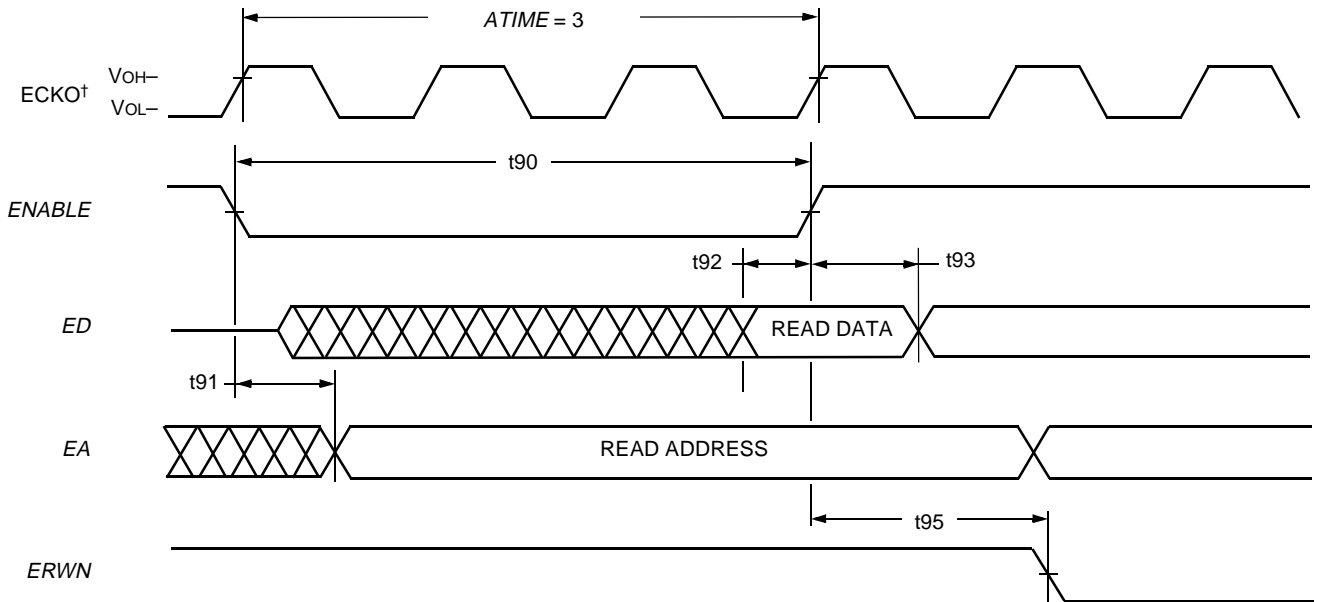
† If any *ENABLE* is asserted (low) when *EREQN* is asserted (low), then the delay occurs from the time that *ENABLE* is deasserted (high). (The SEMI does not acknowledge the request by asserting *EACKN* until it has completed any pending memory accesses.)

‡ T = internal clock period (CLK).

11 Timing Characteristics and Requirements (continued)

11.9 System and External Memory Interface (continued)

11.9.1 Asynchronous Interface (continued)



† ECKO reflects CLK, i.e., **ECON1**[1:0] = 1.

Figure 77. Asynchronous Read Timing Diagram (RHOLD = 0 and RSETUP = 0)

Table 198. Timing Requirements for Asynchronous Memory Read Operations

Abbreviated Reference	Parameter	Min	Max	Unit
t92	Read Data Setup (valid to <i>ENABLE</i> high)	5	—	ns
t93	Read Data Hold (<i>ENABLE</i> high to invalid)	0	—	ns

Table 199. Timing Characteristics for Asynchronous Memory Read Operations

Abbreviated Reference	Parameter	Min	Max	Unit
t90	<i>ENABLE</i> Width (low to high)	$(T^\dagger \times ATIME) - 3$	—	ns
t91	Address Delay (<i>ENABLE</i> low to valid)	—	$2 - (T^\dagger \times RSETUP^\ddagger)$	ns
t95	<i>ERWN</i> Activation (<i>ENABLE</i> high to <i>ERWN</i> low)	$T^\dagger \times (1 + RHOLD^\S + WSETUP^{\dagger\dagger}) - 3$	—	—

† T = internal clock period (CLK).

‡ RSETUP = **ECON0**[12].

§ RHOLD = **ECON0**[14].

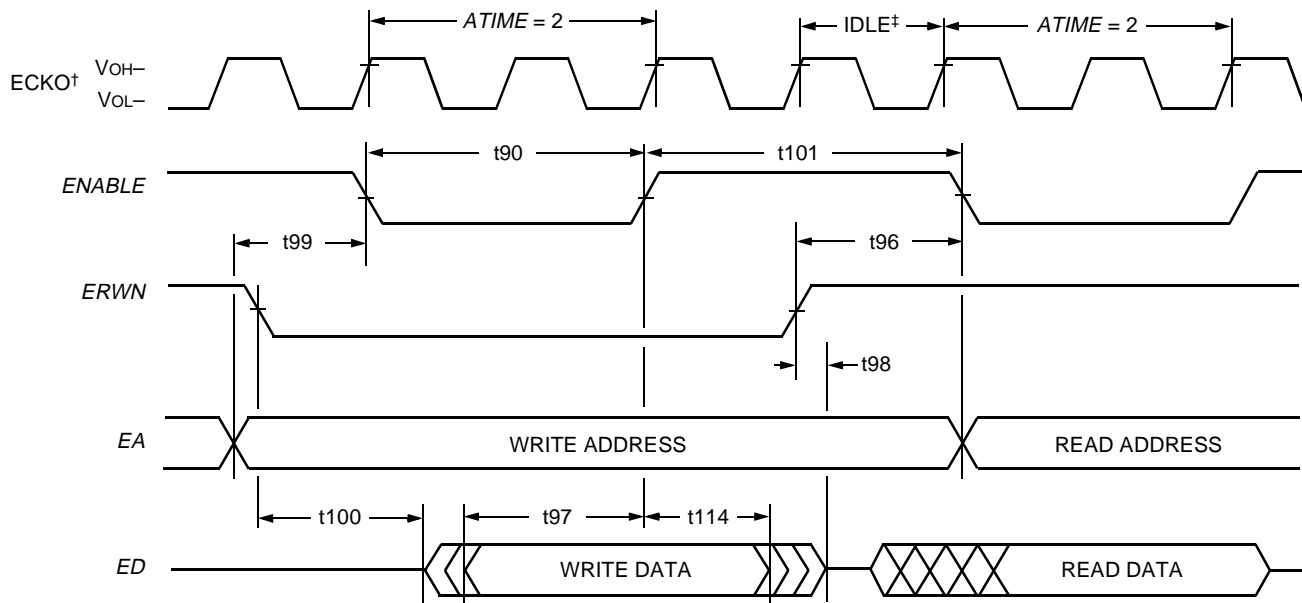
†† WSETUP = **ECON0**[13].

Note: The external memory access time from the asserting of *ENABLE* can be calculated as $t90 - (t91 + t92)$.

11 Timing Characteristics and Requirements (continued)

11.9 System and External Memory Interface (continued)

11.9.1 Asynchronous Interface (continued)



† ECKO reflects CLK, i.e., **ECON1**[1:0] = 1.

‡ The idle cycle is caused by the read following the write.

Figure 78. Asynchronous Write Timing Diagram (WHOLD = 0, WSETUP = 0)

Table 200. Timing Characteristics for Asynchronous Memory Write Operations

Abbreviated Reference	Parameter	Min	Max	Unit
t90	ENABLE Width (low to high)	$(T^\dagger \times ATIME) - 3$	—	ns
t96	Enable Delay (ERWN high to ENABLE low)	$T^\dagger \times (1 + WHOLD^\ddagger + RSETUP^\S) - 3$	—	ns
t97	Write Data Setup (valid to ENABLE high)	$(T^\dagger \times ATIME) - 3$	—	ns
t98	Write Data Deactivation (ERWN high to 3-state)	—	3	ns
t99	Write Address Setup (valid to ENABLE low)	$T^\dagger \times (1 + WSETUP^{\dagger\dagger}) - 3$	—	ns
t100	Write Data Activation (ERWN low to low-Z)	$T^\dagger - 2$	—	ns
t101	Address Hold Time (ENABLE high to invalid)	$T^\dagger \times (1 + WHOLD^\ddagger) - 3$	—	ns
t114	Write Data Hold Time (ENABLE high to invalid)	$T - 3$	—	ns

† T = internal clock period (CLK).

‡ WHOLD = **ECON0**[15].

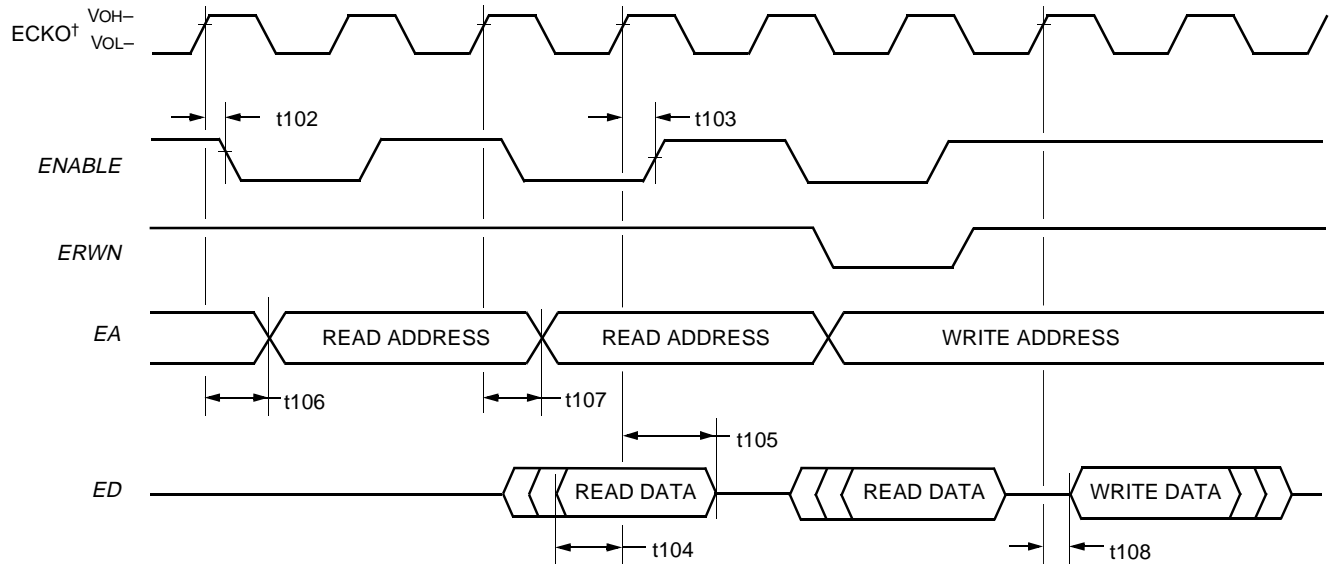
§ RSETUP = **ECON0**[12].

†† WSETUP = **ECON0**[13].

11 Timing Characteristics and Requirements (continued)

11.9 System and External Memory Interface (continued)

11.9.2 Synchronous Interface



† ECKO reflects CLK/2, i.e., ECON1[1:0] = 0.

Figure 79. Synchronous Read Timing Diagram (Read-Read-Write Sequence)

Table 201. Timing Requirements for Synchronous Read Operations

Abbreviated Reference	Parameter	Min	Max	Unit
t104	Read Data Setup (valid to high)	4	—	ns
t105	Read Data Hold (high to invalid)	1	—	ns

Table 202. Timing Characteristics for Synchronous Read Operations

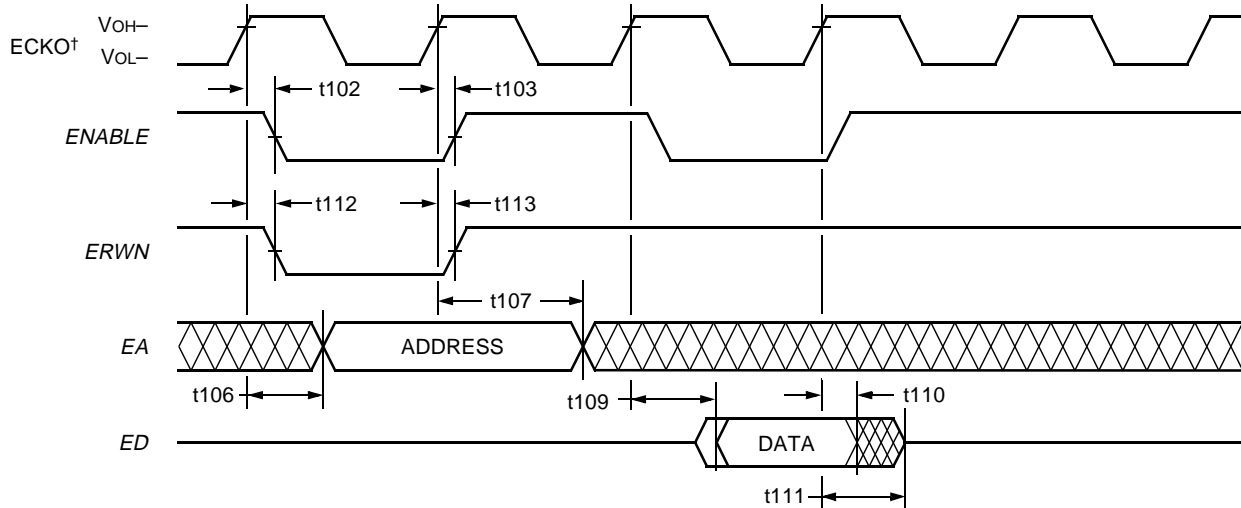
Abbreviated Reference	Parameter	Min	Max	Unit
t102	ECKO to ENABLE Active (high to low)	0.5	4	ns
t103	ECKO to ENABLE Inactive (high to high)	0.5	4	ns
t106	Address Delay (high to valid)	—	2.5	ns
t107	Address Hold (high to invalid)	0.5	—	ns
t108	Write Data Active (high to low-Z)	T† - 3	—	ns

† T = internal clock period (CLK).

11 Timing Characteristics and Requirements (continued)

11.9 System and External Memory Interface (continued)

11.9.2 Synchronous Interface (continued)



† ECKO reflects CLK/2, i.e., ECON1[1:0] = 0.

Figure 80. Synchronous Write Timing Diagram

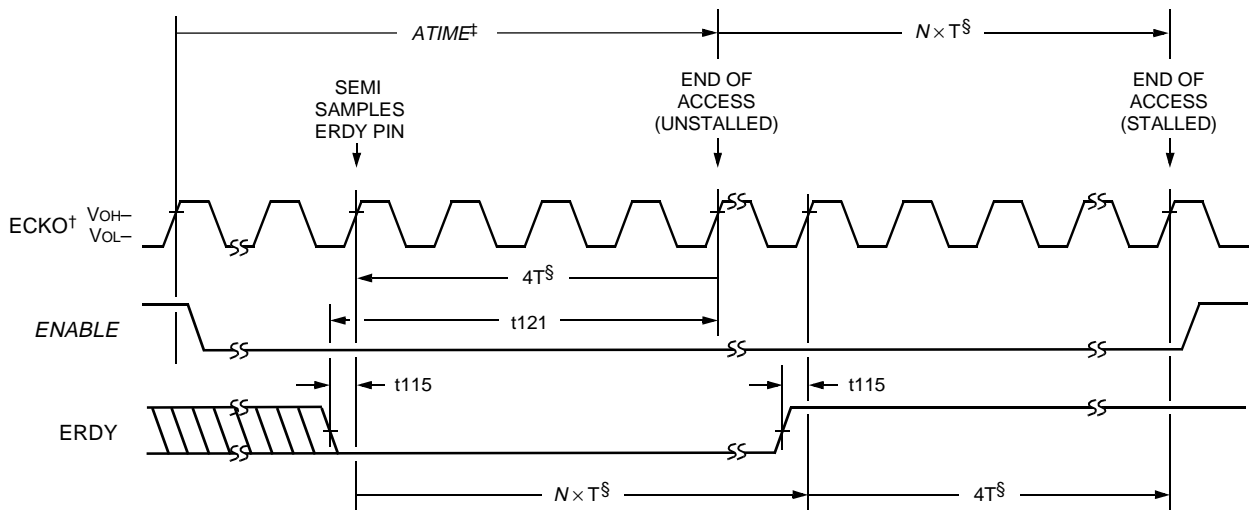
Table 203. Timing Characteristics for Synchronous Write Operations

Abbreviated Reference	Parameter	Min	Max	Unit
t102	ECKO to <i>ENABLE</i> Active (high to low)	0.5	4	ns
t103	ECKO to <i>ENABLE</i> Inactive (high to high)	0.5	4	ns
t106	Address Delay (high to valid)	—	2.5	ns
t107	Address Hold (high to invalid)	0.5	—	ns
t109	Write Data Delay (high to valid)	—	2.5	ns
t110	Write Data Hold (high to invalid)	0.5	—	ns
t111	Write Data Deactivation Delay (high to 3-state)	—	2.5	ns
t112	ECKO to <i>ERWN</i> Active (high to low)	0.5	4	ns
t113	ECKO to <i>ERWN</i> Inactive (high to high)	0.5	4	ns

11 Timing Characteristics and Requirements (continued)

11.9 System and External Memory Interface (continued)

11.9.3 ERDY Interface



† ECKO reflects CLK, i.e., **ECON1**[1:0] = 1.

‡ *ATIME* must be programmed as greater than or equal to five CLK cycles. Otherwise, the SEMI ignores the state of ERDY.

§ T = internal clock period (CLK). *N* must be greater than or equal to one, i.e., ERDY must be held low for at least one CLK cycle after the SEMI samples ERDY.

Figure 81. ERDY Pin Timing Diagram

As indicated in the drawing, the SEMI:

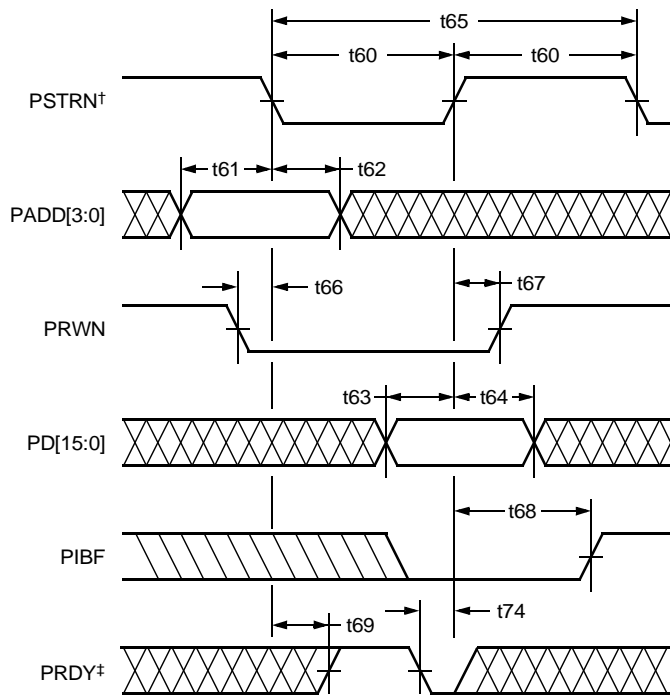
- Samples the state of ERDY at $4T$ prior to the end of the access (unstalled). (The end of the access (unstalled) occurs at *ATIME* cycles after *ENABLE* goes low.)
- Ignores the state of ERDY before the ERDY sample point.
- Stalls the external memory access by $N \times T$ cycles, i.e., by the number of cycles that ERDY is held low following the ERDY sample point.

Table 204. Timing Requirements for ERDY Pin

Abbreviated Reference	Parameter	Min	Max	Unit
t115	ERDY Setup to any ECKO (low to high or high to high)	5	—	ns
t121	ERDY Setup to ECKO at End of Unstalled Access (low to high)	$4T + 5$	—	ns

11 Timing Characteristics and Requirements (continued)

11.10 PIU



† PSTRN is the logical OR of the PCSN input pin with the exclusive NOR of the PIDS and PODS input pins, i.e., $PSTRN = PCSN \vee (PIDS \wedge PODS)$.

‡ It is assumed that the PRDYMD pin is logic low, configuring the PRDY pin as active-low.

Figure 82. Host Data Write to PDI Timing Diagram

Table 205. Timing Requirements for PIU Data Write Operations

Abbreviated Reference	Parameter	Min	Max	Unit
t60	PSTRN Pulse Width (high to low or low to high)	max (2T [†] , 15)	—	ns
t61	PADD Setup Time [‡] (valid to low)	5	—	ns
t62	PADD Hold Time [‡] (low to invalid)	5	—	ns
t63	PD Setup Time [§] (valid to high)	6	—	ns
t64	PD Hold Time [§] (high to invalid)	5	—	ns
t65	PSTRN Request Period (low to low)	max (5T [†] , 30)	—	ns
t66	PRWN Setup Time [‡] (low to low)	0	—	ns
t67	PRWN Hold Time [§] (high to high)	0	—	ns
t74	PSTRN Hold (low to high)	1	—	ns

† T is the period of the internal clock (CLK).

‡ Time to the falling edge of PIDS, PODS, or PCSN, whichever occurs last.

§ Time to the rising edge of PIDS, PODS, or PCSN, whichever occurs first.

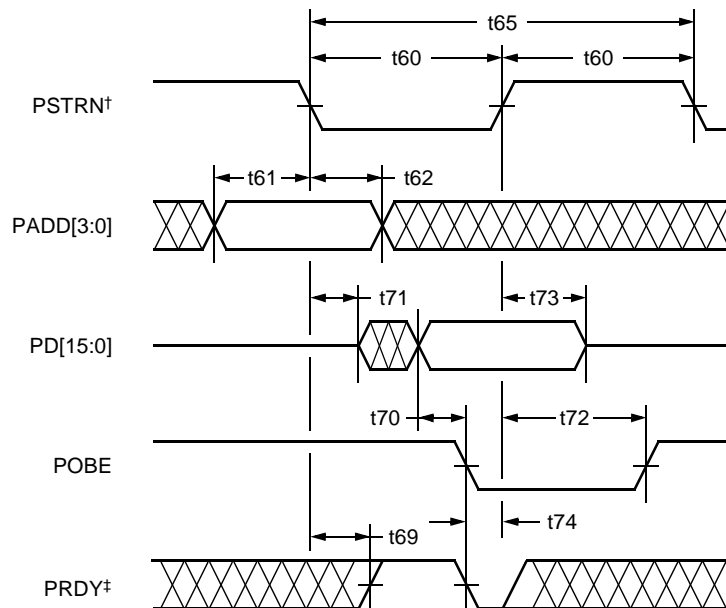
Table 206. Timing Characteristics for PIU Data Write Operations

Abbreviated Reference	Parameter	Min	Max	Unit
t68	PIBF Delay [†] (high to high)	1	12	ns
t69	PRDY Delay (low to valid)	1	12	ns

† Delay from the rising edge of PIDS, PODS, or PCSN, whichever occurs first.

11 Timing Characteristics and Requirements (continued)

11.10 PIU (continued)



† PSTRN is the logical OR of the PCSN input pin with the exclusive NOR of the PIDS and PODS input pins, i.e.,
 $PSTRN = PCSN \vee (PIDS \wedge PODS)$.

‡ It is assumed that the PRDYMD pin is logic low, configuring the PRDY pin as active-low.

Figure 83. Host Data Read from PDO Timing Diagram

Table 207. Timing Requirements for PIU Data Read Operations

Abbreviated Reference	Parameter	Min	Max	Unit
t60	PSTRN Pulse Width (high to low or low to high)	max (2T [†] , 15)	—	ns
t61	PADD Setup Time [‡] (valid to low)	5	—	ns
t62	PADD Hold Time [‡] (low to invalid)	5	—	ns
t65	PSTRN Request Period (low to low)	max (5T [†] , 30)	—	ns
t74	PSTRN Hold (low to high)	1	—	ns

† T is the period of the internal clock (CLK).

‡ Time to the falling edge of PIDS, PODS, or PCSN, whichever occurs last.

Table 208. Timing Characteristics for PIU Data Read Operations

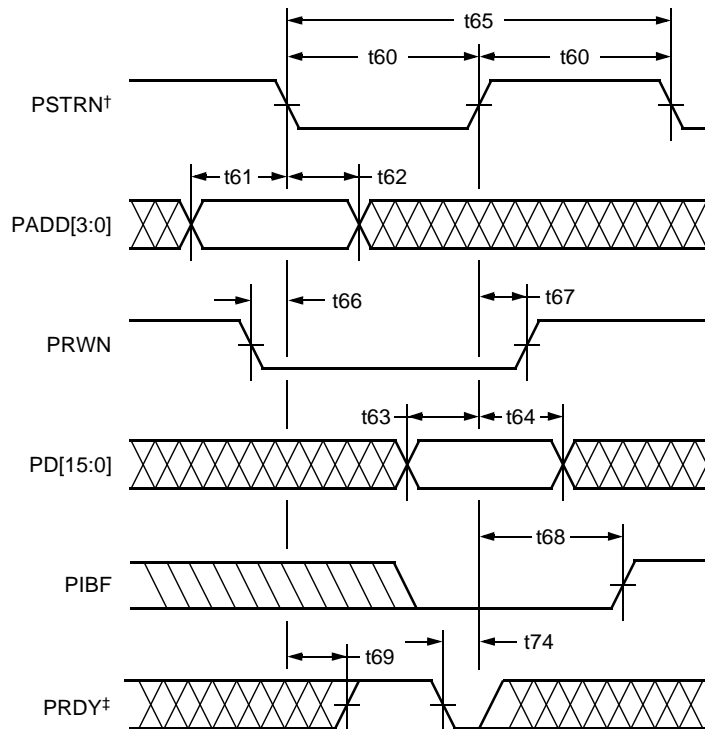
Abbreviated Reference	Parameter	Min	Max	Unit
t69	PRDY Delay (low to valid)	1	12	ns
t70	POBE, PRDY Delays (valid to low)	T - 3	T	ns
t71	PD Activation Delay [†] (low to low-Z)	1	6	ns
t72	POBE Delay [‡] (high to high)	1	12	ns
t73	PD Deactivation Delay [‡] (high to 3-state)	1	12	ns

† Delay from the falling edge of PIDS, PODS, or PCSN, whichever occurs last.

‡ Delay from the rising edge of PIDS, PODS, or PCSN, whichever occurs first.

11 Timing Characteristics and Requirements (continued)

11.10 PIU (continued)



† PSTRN is the logical OR of the PCSN input pin with the exclusive NOR of the PIDS and PODS input pins, i.e.,
 $PSTRN = PCSN \mid (PIDS \wedge PODS)$.

‡ It is assumed that the PRDYMD pin is logic low, configuring the PRDY pin as active-low.

Figure 84. Host Register Write (PAH, PAL, PCON, or HSCRATCH) Timing Diagram

Table 209. Timing Requirements for PIU Register Write Operations

Abbreviated Reference	Parameter	Min	Max	Unit
t60	PSTRN Pulse Width (high to low or low to high)	max (2T [†] , 15)	—	ns
t61	PADD Setup Time [‡] (valid to low)	5	—	ns
t62	PADD Hold Time [‡] (low to invalid)	5	—	ns
t63	PD Setup Time [§] (valid to high)	6	—	ns
t64	PD Hold Time [§] (high to invalid)	5	—	ns
t65	PSTRN Request Period (low to low)	max (5T [†] , 30)	—	ns
t66	PRWN Setup Time [‡] (low to low)	0	—	ns
t67	PRWN Hold Time [§] (high to high)	0	—	ns
t74	PSTRN Hold (low to high)	1	12	ns

† T is the period of the internal clock (CLK).

‡ Time to the falling edge of PIDS, PODS, or PCSN, whichever occurs last.

§ Time to the rising edge of PIDS, PODS, or PCSN, whichever occurs first.

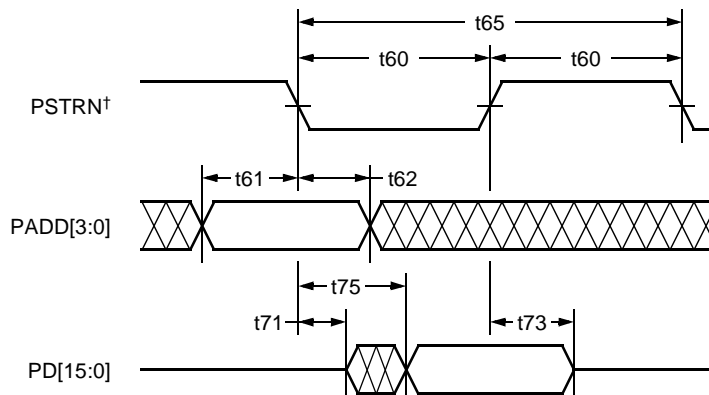
Table 210. Timing Characteristics for PIU Register Write Operations

Abbreviated Reference	Parameter	Min	Max	Unit
t68	PIBF Delay [†] (high to high)	1	12	ns
t69	PRDY Delay (low to valid)	1	12	ns

† Delay from the rising edge of PIDS, PODS, or PCSN, whichever occurs first.

11 Timing Characteristics and Requirements (continued)

11.10 PIU (continued)



5-7853 (F)

† PSTRN is the logical OR of the PCSN input pin with the exclusive NOR of the PIDS and PODS input pins, i.e.,
 $PSTRN = PCSN \mid (\overline{PIDS \wedge PODS})$.

Figure 85. Host Register Read (PAH, PAL, PCON, or DSCRATCH) Timing Diagram

Table 211. Timing Requirements for PIU Register Read Operations

Abbreviated Reference	Parameter	Min	Max	Unit
t60	PSTRN Pulse Width (high to low or low to high)	max (2T†, 15)	—	ns
t61	PADD Setup Time‡ (valid to low)	5	—	ns
t62	PADD Hold Time‡ (low to invalid)	5	—	ns
t65	PSTRN Request Period (low to low)	max (5T†, 30)	—	ns

† T is the period of the internal clock (CLK).

‡ Time to the falling edge of PIDS, PODS, or PCSN, whichever occurs last.

Table 212. Timing Characteristics for PIU Register Read Operations

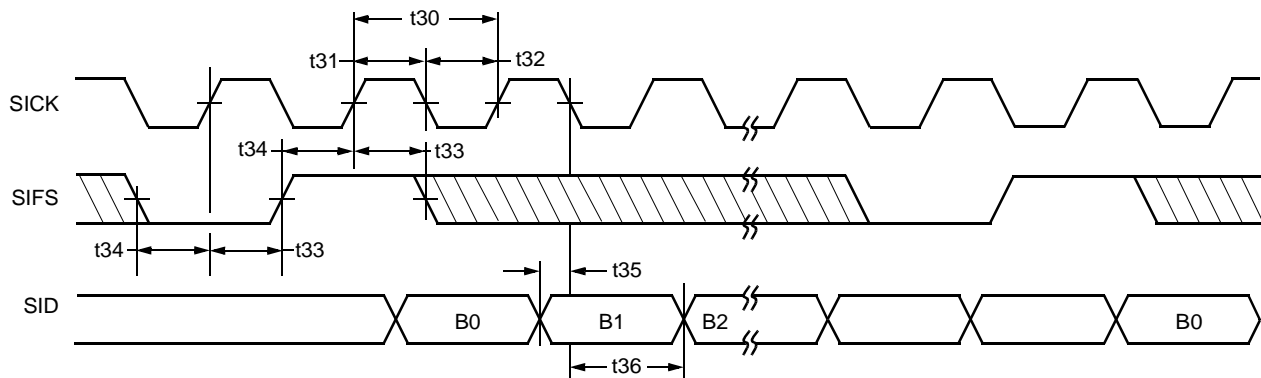
Abbreviated Reference	Parameter	Min	Max	Unit
t71	PD Activation Delay† (low to low-Z)	1	6	ns
t73	PD Deactivation Delay‡ (high to 3-state)	1	12	ns
t75	PD Delay† (low to valid)	—	16	ns

† Delay from the falling edge of PIDS, PODS, or PCSN, whichever occurs last.

‡ Delay from the rising edge of PIDS, PODS, or PCSN, whichever occurs first.

11 Timing Characteristics and Requirements (continued)

11.11 SIU



5-8033 (F)

Note: It is assumed that the SIU is configured with ICKA(SCON10[2]) = 0 for passive mode input clock, ICKK(SCON10[3]) = 0 for no inversion of SICK, IFSA(SCON10[0]) = 0 for passive mode input frame sync, IFSK(SCON10[1]) = 0 for no inversion of SIFS, IMSB(SCON0[2]) = 0 for LSB-first input, and IFSDLY[1:0](SCON1[9:8]) = 00 for no input frame sync delay.

Figure 86. SIU Passive Frame and Channel Mode Input Timing Diagram

Table 213. Timing Requirements for SIU Passive Frame Mode Input

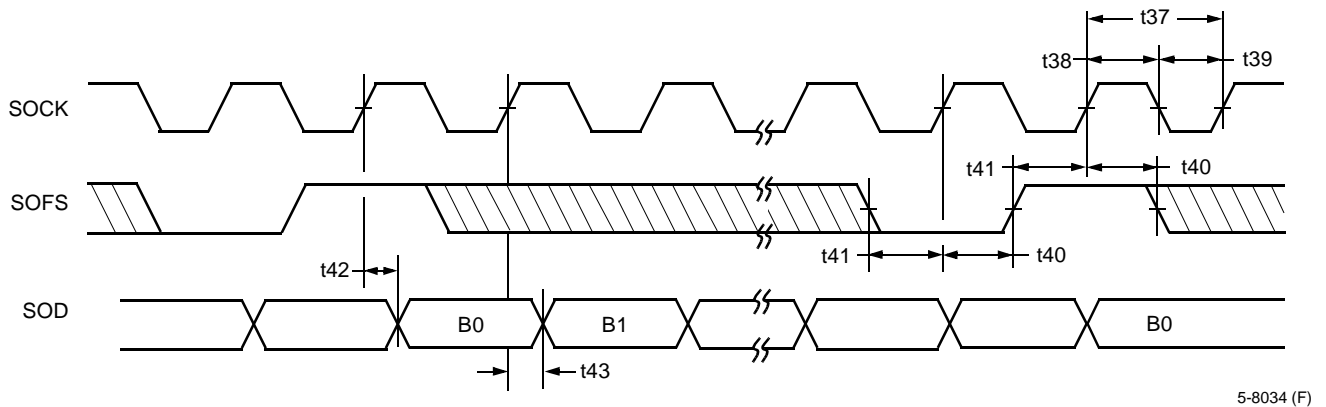
Abbreviated Reference	Parameter	Min	Max	Unit
t30	SICK Bit Clock Period (high to high)	25	—	ns
t31	SICK Bit Clock High Time (high to low)	10	—	ns
t32	SICK Bit Clock Low Time (low to high)	10	—	ns
t33	SIFS Hold Time (high to low or high to high)	10	—	ns
t34	SIFS Setup Time (low to high or high to high)	10	—	ns
t35	SID Setup Time (valid to low)	5	—	ns
t36	SID Hold Time (low to invalid)	8	—	ns

Table 214. Timing Requirements for SIU Passive Channel Mode Input

Abbreviated Reference	Parameter	Min	Max	Unit
t30	SICK Bit Clock Period (high to high)	61.035	—	ns
t31	SICK Bit Clock High Time (high to low)	28	—	ns
t32	SICK Bit Clock Low Time (low to high)	28	—	ns
t33	SIFS Hold Time (high to low or high to high)	10	—	ns
t34	SIFS Setup Time (low to high or high to high)	10	—	ns
t35	SID Setup Time (valid to low)	5	—	ns
t36	SID Hold Time (low to invalid)	8	—	ns

11 Timing Characteristics and Requirements (continued)

11.11 SIU (continued)



Note: It is assumed that the SIU is configured with OCKA(SCON10[6]) = 0 for passive mode output clock, OCKK(SCON10[7]) = 0 for no inversion of SOCK, OFSA(SCON10[4]) = 0 for passive mode output frame sync, OFSK(SCON10[5]) = 0 for no inversion of SOFS, OMSB(SCON0[10]) = 0 for LSB-first output, OFRAME(SCON2[7]) = 1 for frame mode output, and OFSDLY[1:0](SCON2[9:8]) = 00 for no output frame sync delay.

Figure 87. SIU Passive Frame Mode Output Timing Diagram

Table 215. Timing Requirements for SIU Passive Frame Mode Output

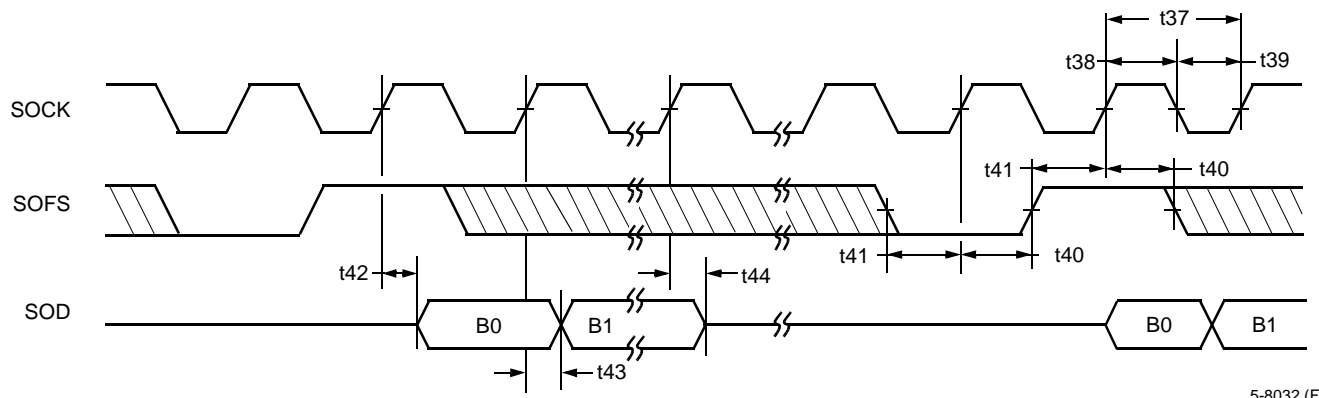
Abbreviated Reference	Parameter	Min	Max	Unit
t37	SOCK Bit Clock Period (high to high)	25	—	ns
t38	SOCK Bit Clock High Time (high to low)	10	—	ns
t39	SOCK Bit Clock Low Time (low to high)	10	—	ns
t40	SOFS Hold Time (high to low or high to high)	10	—	ns
t41	SOFS Setup Time (low to high or high to high)	10	—	ns

Table 216. Timing Characteristics for SIU Passive Frame Mode Output

Abbreviated Reference	Parameter	Min	Max	Unit
t42	SOD Delay (high to valid)	1	16	ns
t43	SOD Hold (high to invalid)	0	4	ns

11 Timing Characteristics and Requirements (continued)

11.11 SIU (continued)



5-8032 (F)

Note: It is assumed that the SIU is configured with $OCCA(\mathbf{SCON10}[6]) = 0$ for passive mode output clock, $OCKK(\mathbf{SCON10}[7]) = 0$ for no inversion of SOCK, $OFSA(\mathbf{SCON10}[4]) = 0$ for passive mode output frame sync, $OFK(\mathbf{SCON10}[5]) = 0$ for no inversion of SOFS, $OMSB(\mathbf{SCON0}[10]) = 0$ for LSB-first output, $OFAME(\mathbf{SCON2}[7]) = 0$ for channel mode output, and $OFSDLY[1:0](\mathbf{SCON2}[9:8]) = 00$ for no output frame sync delay.

Figure 88. SIU Passive Channel Mode Output Timing Diagram

Table 217. Timing Requirements for SIU Passive Channel Mode Output

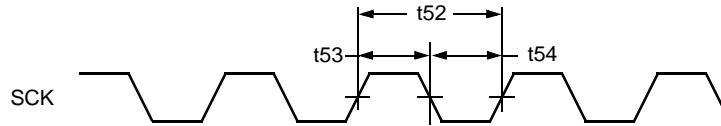
Abbreviated Reference	Parameter	Min	Max	Unit
t37	SOCK Bit Clock Period (high to high)	61.035	—	ns
t38	SOCK Bit Clock High Time (high to low)	28	—	ns
t39	SOCK Bit Clock Low Time (low to high)	28	—	ns
t40	SOFS Hold Time (high to low or high to high)	10	—	ns
t41	SOFS Setup Time (low to high or high to high)	10	—	ns

Table 218. Timing Characteristics for SIU Passive Channel Mode Output

Abbreviated Reference	Parameter	Min	Max	Unit
t42	SOD Delay (high to valid)	1	16	ns
t43	SOD Hold (high to invalid)	0	4	ns
t44	SOD Deactivation Delay (high to 3-state)	—	12	ns

11 Timing Characteristics and Requirements (continued)

11.11 SIU (continued)



5-8037 (F)

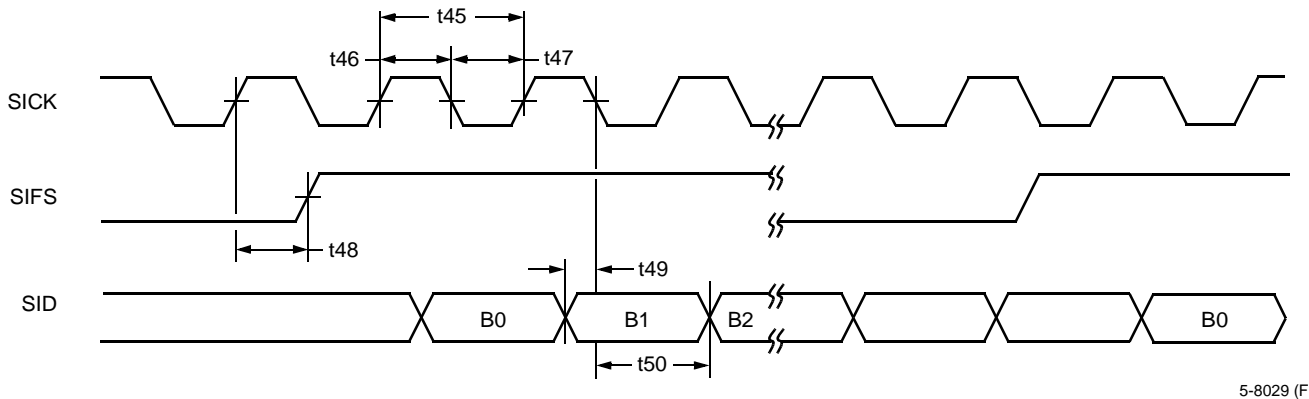
Figure 89. SCK External Clock Source Input Timing Diagram

Table 219. Timing Requirements for SCK External Clock Source

Abbreviated Reference	Parameter	Min	Max	Unit
t52	SCK Bit Clock Period (high to high)	25	—	ns
t53	SCK Bit Clock High Time (high to low)	10	—	ns
t54	SCK Bit Clock Low Time (low to high)	10	—	ns

11 Timing Characteristics and Requirements (continued)

11.11 SIU (continued)



5-8029 (F)

Note: It is assumed that the SIU is configured with ICKA(**SCON10**[2]) = 1 for active mode input clock, ICKK(**SCON10**[3]) = 0 for no inversion of SICK, IFSA(**SCON10**[0]) = 1 for active mode input frame sync, IFSK(**SCON10**[1]) = 0 for no inversion of SIFS, IMSB(**SCON0**[2]) = 0 for LSB-first input, and IFSDLY[1:0](**SCON1**[9:8]) = 00 for no input frame sync delay.

Figure 90. SIU Active Frame and Channel Mode Input Timing Diagram

Table 220. Timing Requirements for SIU Active Frame Mode Input

Abbreviated Reference	Parameter	Min	Max	Unit
t45	SICK Bit Clock Period (high to high)	25 [†]	—	ns
t49	SID Setup Time (valid to low)	9	—	ns
t50	SID Hold Time (low to invalid)	8	—	ns

[†] The active clock source is programmed as either the internal clock CLK or the SCK pin, depending on the AGEXT field (**SCON12**[12]). The period of SICK is dependent on the period of the active clock source and the programming of the AGCKLIM[7:0] field (**SCON11**[7:0]). The application must ensure that the period of SICK is at least 25 ns.

Table 221. Timing Characteristics for SIU Active Frame Mode Input

Abbreviated Reference	Parameter	Min	Max	Unit
t46	SICK Bit Clock High Time (high to low)	TAGCKH [†] - 3	TAGCKH [†] + 3	ns
t47	SICK Bit Clock Low Time (low to high)	TAGCKL [†] - 3	TAGCKL [†] + 3	ns
t48	SIFS Delay (high to high)	TCKAG [†] - 5	TCKAG [†] + 5	ns

[†] TAGCKH and TAGCKL are dependent on the programming of the AGCKLIM[7:0] field (**SCON11**[7:0]) and the period of the active clock source. TCKAG is the period of the active clock source. The active clock source is programmed as either the internal clock CLK or the SCK pin, depending on the AGEXT field (**SCON12**[12]).

11 Timing Characteristics and Requirements (continued)

11.11 SIU (continued)

Table 222. Timing Requirements for SIU Active Channel Mode Input

Abbreviated Reference	Parameter	Min	Max	Unit
t45	SICK Bit Clock Period (high to high)	61.035 [†]	—	ns
t49	SID Setup Time (valid to low)	9	—	ns
t50	SID Hold Time (low to invalid)	8	—	ns

[†] The active clock source is programmed as either the internal clock CLK or the SCK pin, depending on the AGEXT field (**SCON12**[12]). The period of SICK is dependent on the period of the active clock source and the programming of the AGCKLIM[7:0] field (**SCON11**[7:0]). The application must ensure that the period of SICK is at least 61.035 ns.

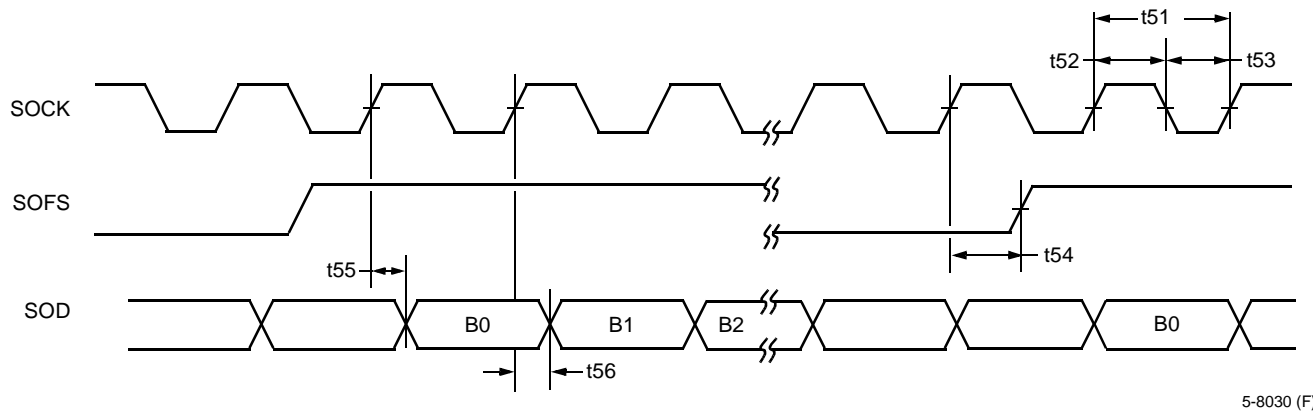
Table 223. Timing Characteristics for SIU Active Channel Mode Input

Abbreviated Reference	Parameter	Min	Max	Unit
t46	SICK Bit Clock High Time (high to low)	TAGCKH [†] – 3	TAGCKH [†] + 3	ns
t47	SICK Bit Clock Low Time (low to high)	TAGCKL [†] – 3	TAGCKL [†] + 3	ns
t48	SIFS Delay (high to high)	TCKAG [†] – 5	TCKAG [†] + 5	ns

[†] TAGCKH and TAGCKL are dependent on the programming of the AGCKLIM[7:0] field (**SCON11**[7:0]) and the period of the active clock source. TCKAG is the period of the active clock source. The active clock source is programmed as either the internal clock CLK or the SCK pin, depending on the AGEXT field (**SCON12**[12]).

11 Timing Characteristics and Requirements (continued)

11.11 SIU (continued)



5-8030 (F)

Note: It is assumed that the SIU is configured with OCKA(**SCON10**[6]) = 1 for active mode output clock, OCKK(**SCON10**[7]) = 0 for no inversion of SOCK, OFSA(**SCON10**[4]) = 1 for active mode output frame sync, OFSK(**SCON10**[5]) = 0 for no inversion of SOFS, OMSB(**SCON0**[10]) = 0 for LSB-first output, OFRAME(**SCON2**[7]) = 1 for frame mode output, and OFSDLY[1:0](**SCON2**[9:8]) = 00 for no output frame sync delay.

Figure 91. SIU Active Frame Mode Output Timing Diagram

Table 224. Timing Requirements for SIU Active Frame Mode Output

Abbreviated Reference	Parameter	Min	Max	Unit
t51	SOCK Bit Clock Period (high to high)	25 [†]	—	ns

[†] The active clock source is programmed as either the internal clock CLK or the SCK pin, depending on the AGEXT field (**SCON12**[12]). The period of SOCK is dependent on the period of the active clock source and the programming of the AGCKLIM[7:0] field (**SCON11**[7:0]). The application must ensure that the period of SOCK is at least 25 ns.

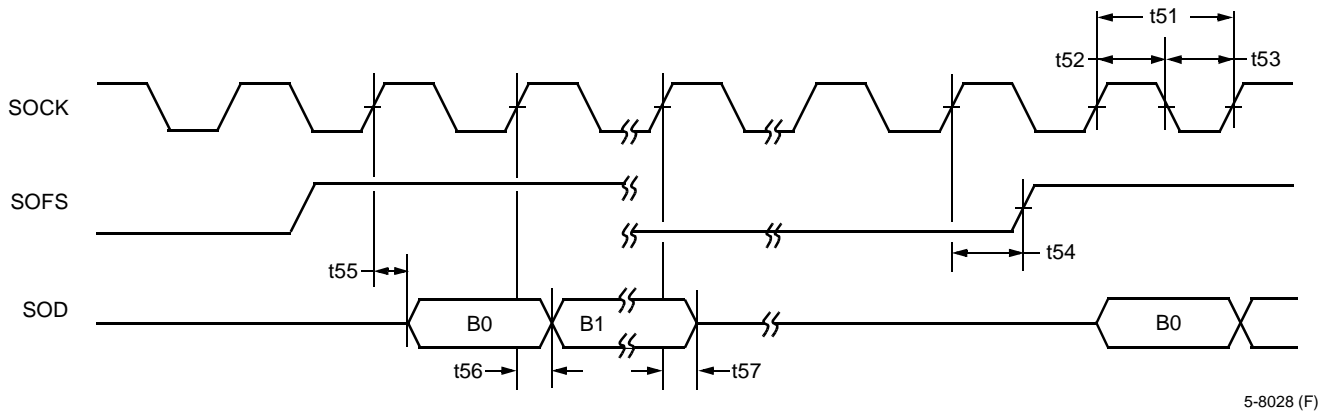
Table 225. Timing Characteristics for SIU Active Frame Mode Output

Abbreviated Reference	Parameter	Min	Max	Unit
t52	SOCK Bit Clock High Time (high to low)	TAGCKH [†] - 3	TAGCKH [†] + 3	ns
t53	SOCK Bit Clock Low Time (low to high)	TAGCKL [†] - 3	TAGCKL [†] + 3	ns
t54	SOFS Delay (high to high)	TCKAG [†] - 5	TCKAG [†] + 5	ns
t55	SOD Data Delay (high to valid)	0	16	ns
t56	SOD Data Hold (high to invalid)	-3	5	ns

[†] TAGCKH and TAGCKL are dependent on the programming of the AGCKLIM[7:0] field (**SCON11**[7:0]) and the period of the active clock source. TCKAG is the period of the active clock source. The active clock source is programmed as either the internal clock CLK or the SCK pin, depending on the AGEXT field (**SCON12**[12]).

11 Timing Characteristics and Requirements (continued)

11.11 SIU (continued)



5-8028 (F)

Note: It is assumed that the SIU is configured with $OCKA(\mathbf{SCON10}[6]) = 1$ for active mode output clock, $OCKK(\mathbf{SCON10}[7]) = 0$ for no inversion of SOCK, $OFSA(\mathbf{SCON10}[4]) = 1$ for active mode output frame sync, $OFK(\mathbf{SCON10}[5]) = 0$ for no inversion of SOFS, $OMSB(\mathbf{SCON0}[10]) = 0$ for LSB-first output, $OFRAME(\mathbf{SCON2}[7]) = 1$ for frame mode output, and $OFSDLY[1:0](\mathbf{SCON2}[9:8]) = 00$ for no output frame sync delay.

Figure 92. SIU Active Channel Mode Output Timing Diagram

Table 226. Timing Requirements for SIU Active Channel Mode Output

Abbreviated Reference	Parameter	Min	Max	Unit
t51	SOCK Bit Clock Period (high to high)	61.035 [†]	—	ns

[†] The active clock source is programmed as either the internal clock CLK or the SCK pin, depending on the AGEXT field ($\mathbf{SCON12}[12]$). The period of SOCK is dependent on the period of the active clock source and the programming of the AGCKLIM[7:0] field ($\mathbf{SCON11}[7:0]$). The application must ensure that the period of SOCK is at least 61.035 ns.

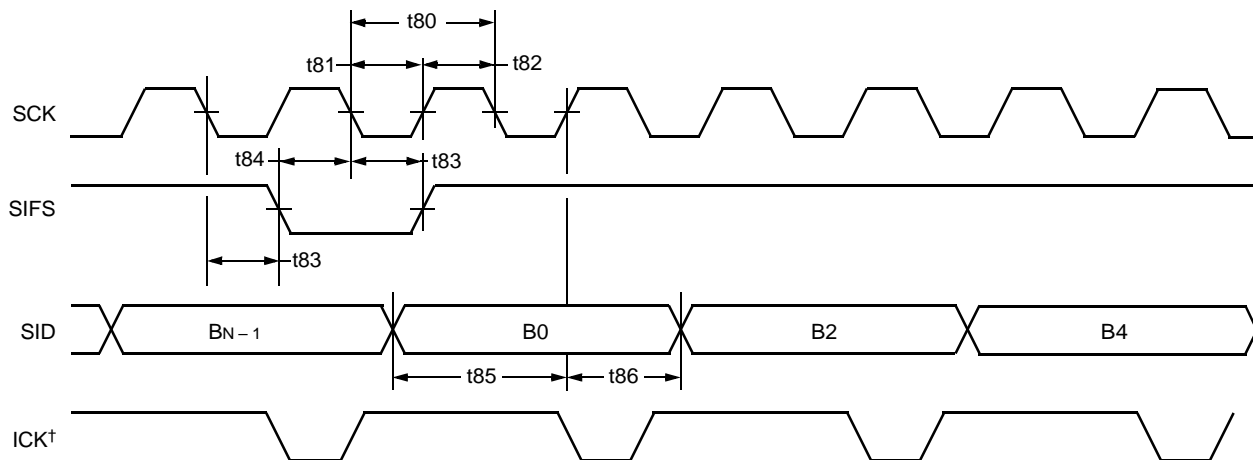
Table 227. Timing Characteristics for SIU Active Channel Mode Output

Abbreviated Reference	Parameter	Min	Max	Unit
t52	SOCK Bit Clock High Time (high to low)	$T_{AGCKH}^{\dagger} - 3$	$T_{AGCKH}^{\dagger} + 3$	ns
t53	SOCK Bit Clock Low Time (low to high)	$T_{AGCKL}^{\dagger} - 3$	$T_{AGCKL}^{\dagger} + 3$	ns
t54	SOFS Delay (high to high)	$T_{CKAG}^{\dagger} - 5$	$T_{CKAG}^{\dagger} + 5$	ns
t55	SOD Data Delay (high to valid)	0	16	ns
t56	SOD Data Hold (high to invalid)	-3	5	ns
t57	SOD Deactivation Delay (high to 3-state)	—	15	

[†] T_{AGCKH} and T_{AGCKL} are dependent on the programming of the AGCKLIM[7:0] field ($\mathbf{SCON11}[7:0]$) and the period of the active clock source. T_{CKAG} is the period of the active clock source. The active clock source is programmed as either the internal clock CLK or the SCK pin, depending on the AGEXT field ($\mathbf{SCON12}[12]$).

11 Timing Characteristics and Requirements (continued)

11.11 SIU (continued)



† ICK is the internal active generated bit clock shown for reference purposes only.

Note: It is assumed that the SIU is configured with ICKA (**SCON10**[2]) = 1 for active mode input clock, I2XDLY (**SCON1**[11]) = 1 for extension of active input bit clock, IFSA (**SCON10**[0]) = 1 and AGSYNC (**SCON12**[14]) = 1 to configure SIFS as an input and to synchronize the active bit clocks and active frame syncs to SIFS, IFSK (**SCON10**[1]) = 1 for inversion of SIFS, IMSB (**SCON0**[2]) = 0 for LSB-first input, IFSDLY[1:0] (**SCON1**[9:8]) = 00 for no input frame sync delay, AGEXT (**SCON12**[12]) = 1 for SCK pin as active clock source, SCKK (**SCON12**[13]) = 1 for inversion of SCK, and AGCKLIM[7:0] (**SCON11**[7:0]) = 1 for an active clock divide ratio of 2.

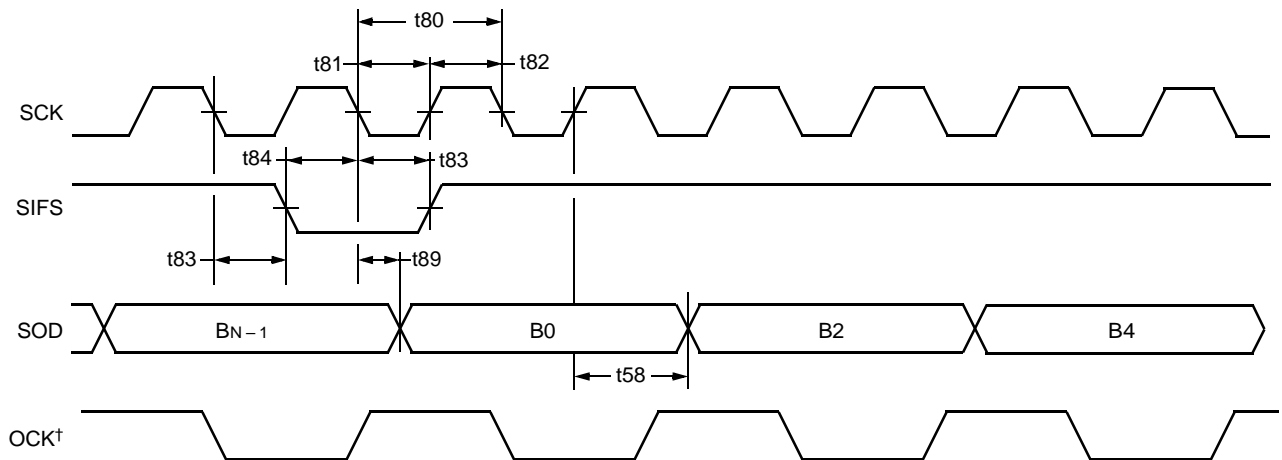
Figure 93. ST-Bus 2x Input Timing Diagram

Table 228. ST-Bus 2x Input Timing Requirements

Abbreviated Reference	Parameter	Min	Max	Unit
t80	SCK Clock Period	60	—	ns
t81	SCK Clock Low Time	30	—	ns
t82	SCK Clock High Time	30	—	ns
t83	Input Frame Sync Hold	30	—	ns
t84	Input Frame Sync Setup	20	—	ns
t85	Input Data Setup	5	—	ns
t86	Input Data Hold	20	—	ns

11 Timing Characteristics and Requirements (continued)

11.11 SIU (continued)



† OCK is the internal active generated bit clock shown for reference purposes only.

Note: It is assumed that the SIU is configured with OCKA (**SCON10**[6]) = 1 for active mode output clock, IFSA(**SCON10**[0]) = 1 and AGSYNC (**SCON12**[14]) = 1 to configure SIFS as an input and to synchronize the active bit clocks and active frame syncs to SIFS, OFSA(**SCON10**[4]) = 1 for active output frame sync, IFSK(**SCON10**[1]) = 1 for inversion of SIFS, OMSB(**SCON0**[10]) = 0 for LSB-first input, OFSDLY[1:0](**SCON2**[9:8]) = 00 for no output frame sync delay, AGEXT (**SCON12**[12]) = 1 for SCK pin as active clock source, SCKK (**SCON12**[13]) = 1 for inversion of SCK, and AGCKLIM[7:0] (**SCON11**[7:0]) = 1 for an active clock divide ratio of 2.

Figure 94. ST-Bus 2x Output Timing Diagram

Table 229. ST-Bus 2x Output Timing Requirements

Abbreviated Reference	Parameter	Min	Max	Unit
t80	SCK Clock Period	60	—	ns
t81	SCK Clock Low Time	30	—	ns
t82	SCK Clock High Time	30	—	ns
t83	Input Frame Sync Hold	30	—	ns
t84	Input Frame Sync Setup	20	—	ns

Table 230. ST-Bus 2x Output Timing Characteristics

Abbreviated Reference	Parameter	Min	Max	Unit
t89	Output Data Delay	1	25	ns
t58	Output Data Hold	0	4	ns

12 Appendix—Naming Inconsistencies

Table 231 lists the inconsistencies for pin names between this document and the *LUXWORKS* debugger.

Table 231. Pin Name Inconsistencies

Data Sheet	Debugger
PRDY	PREADY
PRDYMD	PREADYMD
ERDY	ERREADY

Table 232 lists the inconsistencies for register names between this document and the *LUXWORKS* debugger.

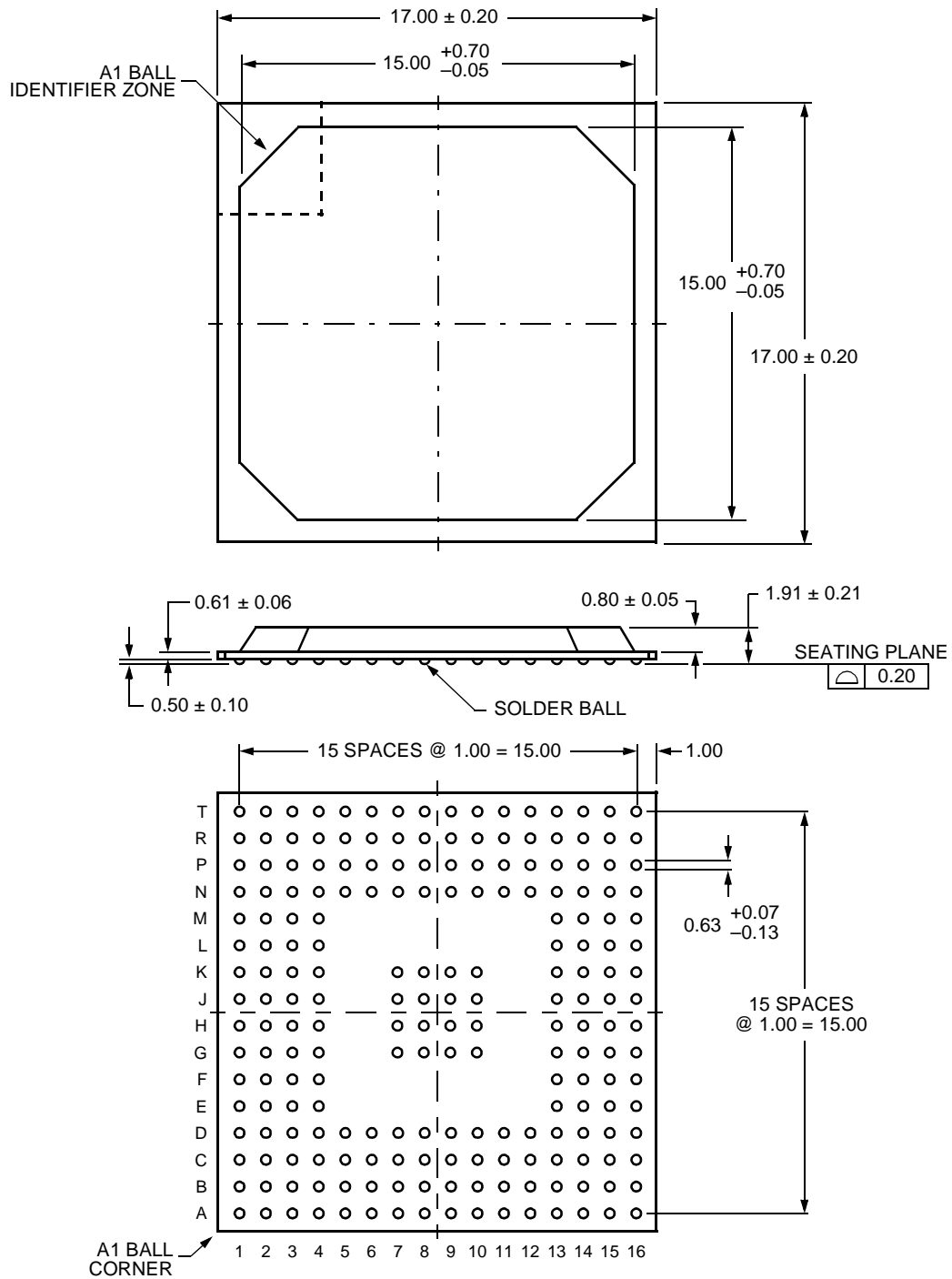
Table 232. Register Name Inconsistencies

Data Sheet	Debugger
ECON0	ECN0
ECON1	ECN1

13 Outline Diagrams

13.1 208-Pin PBGA

All dimensions are in millimeters.

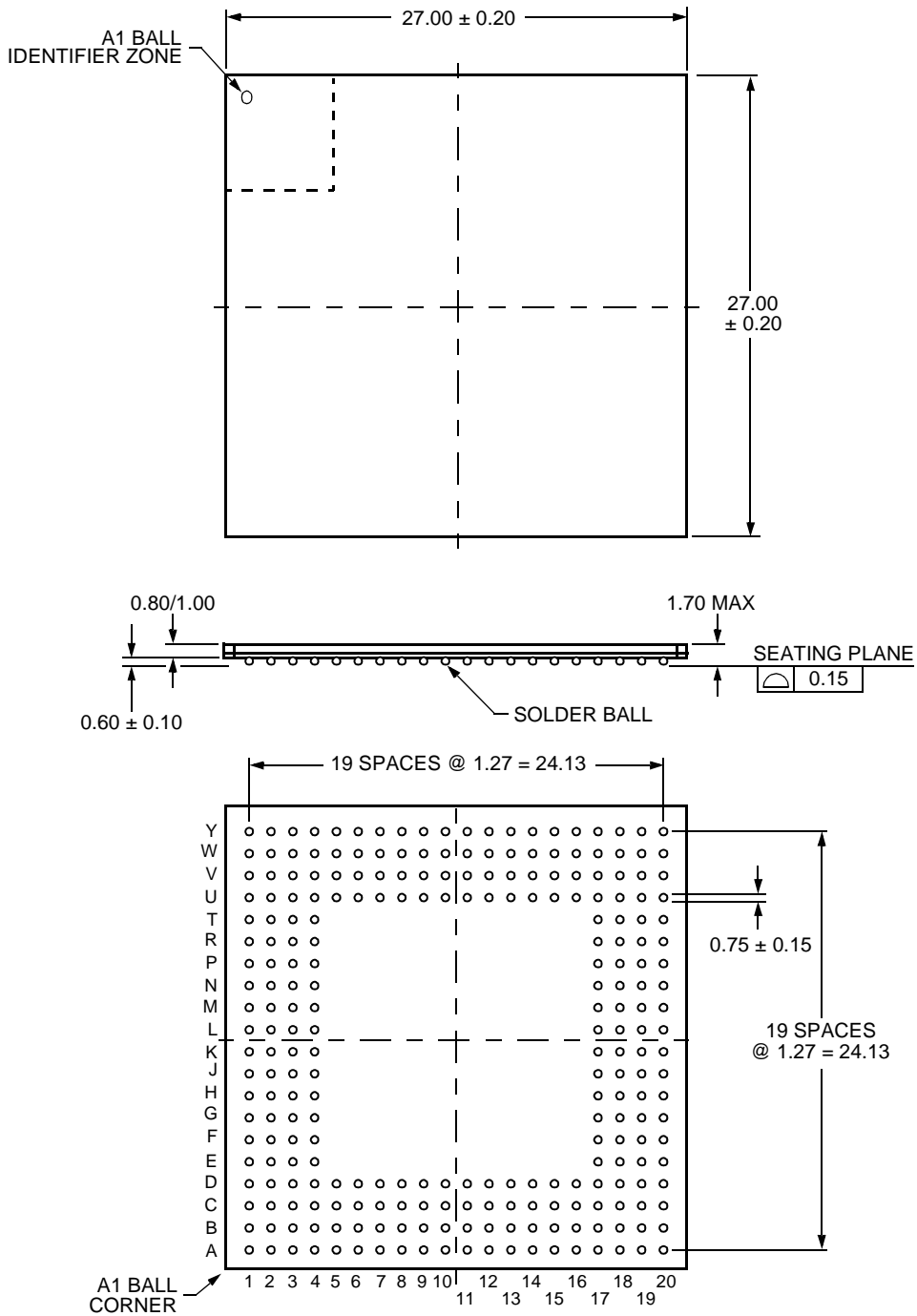


5-7809 (F).b

13 Outline Diagrams (continued)

13.2 256-Pin EPGA

All dimensions are in millimeters.



5-5288 (F).a

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This document, the *DSP16410B Digital Signal Processor Data Sheet* (DS01-070WINF) replaces the *DSP16410 Digital Signal Processor Data Sheet* (DS98-318WTEC) dated July 2000 and the *DSP16410B Digital Signal Processor Data Addendum* (DA00-014WTEC) dated July 2000. This new document is the complete specification for the DSP16410B device and no longer specifies the discontinued DSP16410A device. The following table summarizes the changes to the information in this data sheet since July 2000.

Significant Changes to the *DSP16410B Digital Signal Processor Data Sheet* Since July 2000

Old Page(s)	New Page(s)	Change
155—157	156—158	In Section 4.16.3 , Basic Input Processing, Section 4.16.4 , Basic Output Processing, and Section 4.16.5 , Clock and Frame Sync Generation, notes were added to specify that the combination of passive bit clock and active frame sync is not supported.
156	157	In Section 4.16.4 , Basic Output Processing, it now states “If an output bit clock is active (internally generated), the user program must wait at least four bit clock cycles between changing AGRESET (SCON12 [15]) and clearing ORESET.” (changed from two bit clock cycles).
164	165	In Section 4.16.8 , Basic Frame Structure, a note was added that specifies that if the output section is configured for a one-channel frame and a passive frame sync, the SOFS frame sync interval must be constant and a multiple of the OCK output bit clock.
225	224	In Section 6.2.1 , Directly Program-Accessible (Register-Mapped) Registers, text was added that explains that off-core register-mapped registers cannot be stored to memory in a single instruction. This is due to a design exception that was described in the advisory <i>DSP16410 Design Exception</i> (AY01-004WTEC).
265	263	In Section 8.6 , PIU Interface, the description of the PCSN pin had incorrectly stated that if PCSN = 1, the PIU 3-states POBE, PIBF, PRDY, and PINT. This has been corrected to state that the PIU 3-states only PD[15:0].
267	265	In Section 9.1 , Absolute Maximum Ratings, the maximum solder temperature was changed from 300 °C to 220 °C. In Table 175 , the minimum storage temperature was changed from –65 °C to –40 °C. In Section 9.2 , Handling Precautions, the breakdown voltage was changed from 2000 V to 1000 V.
270	268	The ranges for IOH and IOL were changed in Figure 63 and Figure 64 , respectively.
—	273	A new section was added: Section 10.4 , Power Supply Sequencing Issues. This information had been documented in the advisory <i>DSP16410B and DSP16410C Power Supply Sequencing Recommendations</i> (AY01-002WTEC).
274	276	The temperature range conditions listed for the timing characteristics had been for ambient temperature (TA) and are now for junction temperature (TJ = –40 °C to +120 °C).
285	287	In Figure 77 and Table 198 that describe the SEMI asynchronous read timing, the t94 specification (External Memory Access Time) has been deleted. Instead, a note was added that the external memory access time can be calculated as t90 – (t91 + t92).
286	288	In Table 200 , Timing Characteristics for Asynchronous Memory Write Operations, the specification for t100 has been moved from the “Max” column to the “Min” column.
288, 289	289, 290	In Table 202 , Timing Characteristics for Synchronous Read Operations, and in Table 203 , Timing Characteristics for Synchronous Write Operations, the value for the t106 specification was changed from 0.5 ns to 2.5 ns.
298, 299	300, 301	In Table 220 , Timing Requirements for SIU Active Frame Mode Input, and Table 222 , Timing Requirements for SIU Active Channel Mode Input, the value for the t49 specification was changed from 5 ns to 9 ns.